

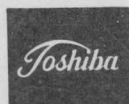
INTEGRATED CIRCUIT TECHNICAL DATA

MICROCOMPUTER

DATA BOOK

2nd Edition

Oct., 1981



TOSHIBA

Q quantum electronics

Box 391262

Bramley

2018

PREFACE

Since LSIs for the microcomputer manufactured first in Japan by Toshiba was put on the market in 1973, Toshiba has devoted efforts in strengthening its semiconductor devices for microcomputer. Toshiba has been developing various highly efficient and low power consumption type LSIs for microcomputers to more and more diversifying application fields, and supplying numerous kinds of new products to users.

This manual covers the technical description of LSIs for microcomputers supplied by Toshiba, including TLCS-43 Series (NMOS), TLCS-46A Series (CMOS) and TLCS-47 Series (NMOS and CMOS) 4-bit single chip microcomputer, TLCS-84 Series (NMOS and CMOS) 8-bit single chip microcomputer and TLCS-85A Family (NMOS) 8-bit microcomputer.

In addition to this manual, the technical description of the microcomputer development system is also available.

Further, examples of application circuits listed in this manual are only for reference in using the LSIs. Toshiba will not assume any responsibility for problem relative to patent rights which may be generated from use of the said application circuits.

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2018

CONTENTS

	Page
4BIT SINGLE CHIP MICROCOMPUTER	
TLCS-43 (NMOS)	
• TMP4310AP/TMP4315BP/TMP4320AP/TMP4300C	7
• TMP4310APL/TMP4310APLL	82
• TMP4321AP	88
• TMP4399C	93
 4BIT SINGLE CHIP MICROCOMPUTER	
TLCS-46A (CMOS)	
• TCP4620AP/TCP4630AP	99
• TCP4620AF/TCP4630AF	173
• TCP4620BP	179
• TCP4621AP	195
• TCP4632BF PRELIMINARY	201
• TCP4600AC	230
 4BIT SINGLE CHIP MICROCOMPUTER	
TLCS-47 (NMOS/CMOS) ADVANCED INFORMATION	
• TMP4700C/TMP4720P/TMP4740P /TMP47C20P/TMP47C40P/TMP47C22F	253
 8BIT SINGLE CHIP MICROCOMPUTER	
TLCS-84 (NMOS/CMOS)	
• TMP8048P/TMP8035P/TMP8048PI/TMP8035PI	261
• TMP8049P/TMP8049P-6/TMP8039P/TMP8039P-6 /TMP8049PI-6/TMP8039PI-6	294
• TMP8243P/TMP8243PI	327
• TMP80C49P-6/TMP80C39P-6 . PRELIMINARY	336

CONTENTS

8BIT MICROPROCESSOR

TLCS-85A (NMOS)

- TMP8085AP 349

8BIT MICROPROCESSOR

PERIPHERALS (NMOS)

- TMP8155/TMP8156P 381
- TMP8355P 398
- TMP8755AC 408

MICROCOMPUTER APPLICATION DEVELOPMENT TOOL 421

- TCP4620AP/TCP4630AP 99
- TCP4620AP/TCP4630AP 173
- TCP4620BP 179
- TCP4621AP 192
- TCP4632BF 201
- TCP4600AC 230

8BIT SINGLE CHIP MICROCOMPUTER

TLCS-43 (NMOS/CMOS) ADVANCED INFORMATION

- TMP4700C/TMP4720P/TMP4740P 223
- TMP4700C/TMP4720P/TMP4740P 223

8BIT SINGLE CHIP MICROCOMPUTER

TLCS-84 (NMOS/CMOS)

- TMP8048P/TMP8032P/TMP8048P/TMP8032P 261
- TMP8048P/TMP8048P-6/TMP8032P/TMP8032P-6 264
- TMP8048P-6/TMP8032P-6 327
- TMP8048P-6/TMP8032P-6 336

TLCS-43 (4 BIT SINGLE CHIP NMOS MICROCOMPUTER)

TLCS-43 SERIES (NMOS)

Device Number	RAM	ROM	I/O	Instruction Cycle Time (Min.)	Power Supply Current (Typ.)	Power Supply	Operating Temperature	Package Type	Alternate Source
TMP4300C	128 × 4	Without ROM	35 Lines	4 μs	70 mA	5V±10%	-10°C ~ 70°C	Ceramic 64 pin	Toshiba Original
TMP4399C	128 × 4	Without ROM	35 Lines	4 μs	70 mA	5V±10%	-10°C ~ 70°C	Ceramic 42 pin	
TMP4310AP	48 × 4	1024 × 8	22 Lines	4 μs	40 mA	5V±10%	-10°C ~ 70°C	Plastic 28 pin	
TMP4315BP	64 × 4	1536 × 8	35 Lines	4 μs	40 mA	5V±10%	-10°C ~ 70°C	Plastic 42 pin	
TMP4320AP	128 × 4	2048 × 8	35 Lines	4 μs	40 mA	5V±10%	-10°C ~ 70°C	Plastic 42 pin	
TMP4321AP	128 × 4	2048 × 8	35 Lines	4 μs	40 mA	5V±10%	-10°C ~ 70°C	Plastic 42 pin	
TMP4310APL	48 × 4	1024 × 8	22 Lines	5 μs	30 mA	5.5V±10%	0°C ~ 55°C	Plastic	
TMP4310APLL				10 μs	15 mA			28 pin	

TLCS-46A (4 BIT SINGLE CHIP CMOS MICROCOMPUTER)

TLCS-46A SERIES (CMOS)

Device Number	RAM	ROM	I/O	Instruction Cycle Time (Min.)	Power Supply Current (Typ.)	Power Supply	Operating Temperature	Package Type	Alternate Source		
TCP4600AC	160 × 4	Without ROM	34 Lines	10 μs	0.15 mA at 100kHz	4 ~ 6V	-10°C ~ 70°C	Ceramic 64 pin	Toshiba Original		
TCP4620AP	96 × 4	2048 × 8			0.4 mA at 400kHz	4 ~ 6V	-30°C ~ 85°C	Plastic			
TCP4620BP								42 pin			
TCP4630AP	160 × 4	3072 × 8					-20°C ~ 70°C	Plastic 43 pin (Flat)			
TCP4620AF	96 × 4	2048 × 8								Plastic 42 pin	
TCP4620BF											Plastic 67 pin (Flat)
TCP4630AF	160 × 4	3072 × 8						Plastic 42 pin			
TCP4621AP	96 × 4	2048 × 8						Plastic 67 pin (Flat)			
TCP4632BF	160 × 4	3072 × 8	57 Lines								

TLCS-47 (4 BIT SINGLE CHIP NMOS/CMOS MICROCOMPUTER)

TLCS-47 SERIES (NMOS/CMOS)

	Device Number	RAM	ROM	I/O	Instruction Cycle Time (Min.)	Power Supply Current (Typ.)	Power Supply	Operating Temperature	Package Type	Alternat Source
NMOS	TMP4700C	256 × 4	Without ROM	35 Lines	2 μs	50 mA	5V±10%	-30°C ~ 70°C	QIC 80 pin	Toshiba Original
	TMP4720P	128 × 4	2048 × 8							
	TMP4740P	256 × 4	4096 × 8		4 μs	5 mA				
	TMP47C20P	128 × 4	2048 × 8							
CMOS	TMP47C40P	256 × 4	4096 × 8	55 Lines	4 μs	5 mA		Plastic 67 pin (Flat)		
	TMP47C22F	192 × 4	2048 × 8							

TLCS-84 (8 BIT SINGLE CHIP NMOS/CMOS MICROCOMPUTER)

TLCS-84 SERIES (NMOS/CMOS)

	Device Number	RAM	ROM	I/O	Instruction Cycle Time (Min.)	Power Supply Current (Max.)	Power Supply	Operating Temperature	Package Type	Alternate Source	
NMOS	TMP8048P	64 × 8	1024 × 8	27 Lines	2.5 μs	135 mA	5V±10%	0°C ~ 70°C	Plastic 40 pin	i8048	
	TMP8035P	64 × 8	—		2.5 μs	135 mA				i8035L	
	TMP8049P-6	128 × 8	2048 × 8		2.5 μs	170 mA				i8039-6	
	TMP8039P-6	128 × 8	—		2.5 μs	170 mA					
	TMP8049P	128 × 8	2048 × 8		1.36 μs	170 mA					i8049
	TMP8039P	128 × 8	—		1.36 μs	170 mA					i8039
	TMP8048PI	64 × 8	1024 × 8		2.5 μs	145 mA		-40°C ~ 85°C		iD8048	
	TMP8035PI	64 × 8	—		2.5 μs	145 mA				iD8035	
	TMP8049PI-6	128 × 8	2048 × 8		2.5 μs	170 mA				iD8049	
	TMP8039PI-6	128 × 8	—		2.5 μs	170 mA				iD8039	
	TMP8243P	I/O Expander for TMP8048P/TMP8049P				20 mA	5V±10%		Plastic 24 pin	i8243	
	TMP8243PI	I/O Expander for TMP8048PI-6/8049PI-6				20 mA	5V±10%	-40°C ~ 85°C	Plastic 24 pin	iD8243	
CMOS	TMP80C49P-6	128 × 8	2048 × 8	27 Lines	2.5 μs	10 mA	5V±10%	-40°C ~ 85°C	Plastic 40 pin		
	TMP80C39P-6	128 × 8	—		2.5 μs	10 mA					

TLCS-85A

• 8 BIT MICROPROCESSOR

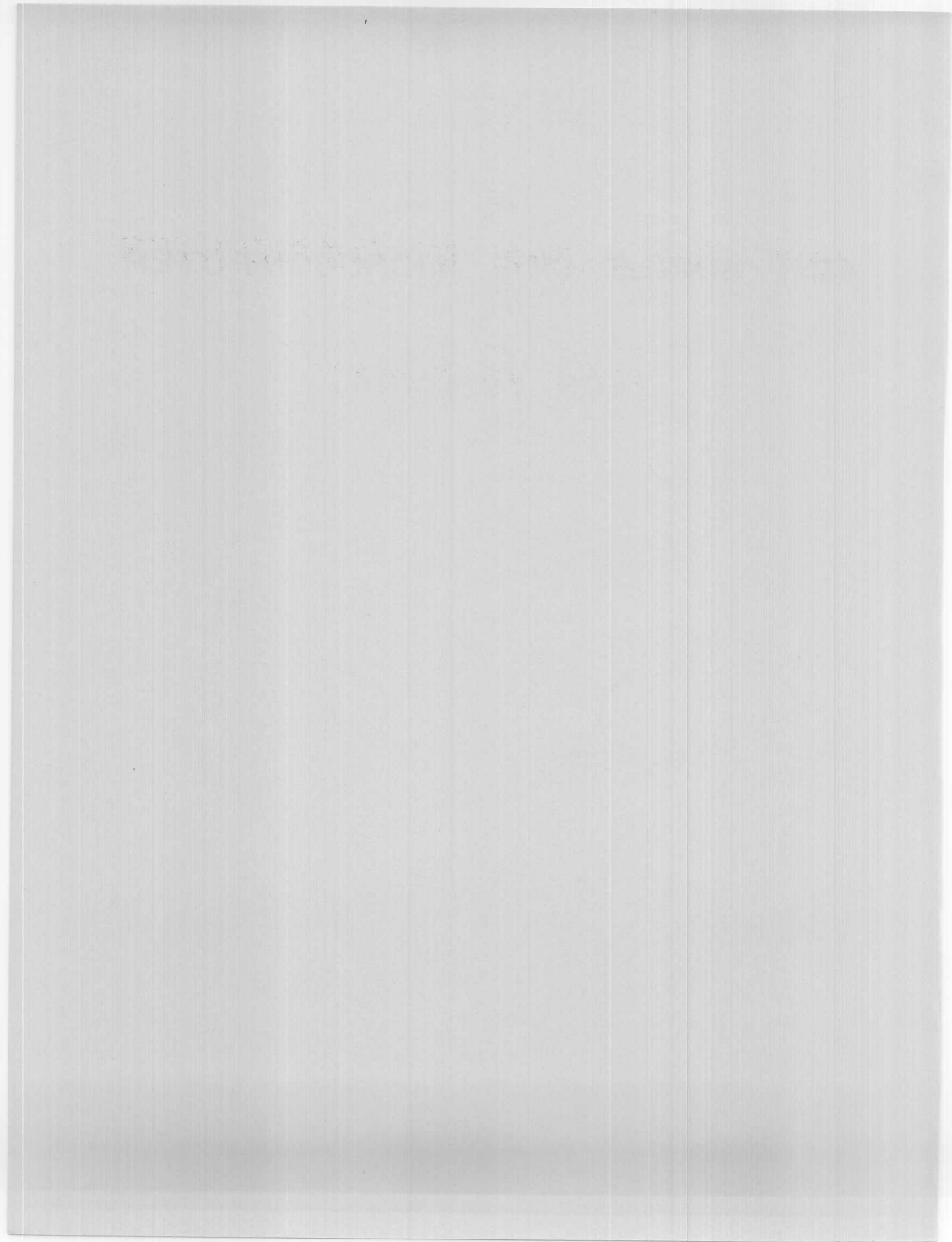
Device Number	Description	Instruction Cycle Time (Min.)	Power Supply Current (Max.)	Power Supply	Operating Temperature	Package Type	Alternate Source
TMP8085AP	8 Bit Microprocessor	1.3 μs	170 mA	5V±10%	0°C ~ 70°C	Plastic 40 pin	i8085A

• PERIPHERALS (NMOS)

Device Number	Description	Power Supply Current (Max.)	Power Supply	Operating Temperature	Package Type	Alternate Source
TMP8155P	256 Byte RAM with I/O Ports and Timer (CE: Active Low)	180 mA	5V±5%	0°C ~ 70°C	Plastic 40 pin	i8155
TMP8156P	256 Byte RAM with I/O Ports and Timer (CE: Active High)	180 mA	5V±5%		Plastic 40 pin	i8156
TMP8355P	2K Byte Mask ROM with I/O Ports	180 mA	5V±5%		Plastic 40 pin	i8355
TMP8755AC	2K Byte EPROM with I/O Ports	180 mA	5V±5%		Ceramic 40 pin	i8755A

4BIT SINGLE CHIP MICROCOMPUTER

TLCS-43(NMOS)





INTEGRATED CIRCUIT

TECHNICAL DATA

TOSHIBA MOS TYPE DIGITAL
INTEGRATED CIRCUIT
TMP4310AP TMP4315BP
TMP4320AP TMP4300C
Silicon Monolithic



N-Channel Silicon Gate Depression Load

GENERAL DESCRIPTION

TLCS-43 is a complete single chip micro computer series having an internal 4 bit parallel processing function which is suitable for controller applications.

It contains ROM (read only memory) which stores the control programs and the fixed data, RAM (read/write memory) which temporarily stores various data and a plural number of input/output ports.

In order to provide for a variety of applications the TLCS-43 provides short instruction execution time, multiple subroutine nesting, and flexible input/output ports.

By combining index instructions with processing instructions, the same instruction can be executed for all the registers and all the input/output ports enabling highly efficient programmes to be written.

In TLCS-43, there are three versions, TMP4310AP, TMP4315BP and TMP4320AP each of which has different memory capacity and different number of input/output lines, so that the optimum version for a specific application can be selected. Furthermore, TMP4300C is available as the evaluator chip.



INTEGRATED CIRCUIT

TECHNICAL DATA

TMP4310AP TMP4315BP
TMP4320AP TMP4300C

TECHNICAL DATA



FEATURES

- o TMP4310AP
 - 1024 x 8 ROM
 - 48 x 4 RAM
 - 22 I/O Lines
 - o TMP4315BP
 - 1536 x 8 ROM
 - 64 x 8 RAM
 - 35 I/O Lines
 - o TMP4320AP
 - 2048 x 8 ROM
 - 128 x 4 RAM
 - 35 I/O Lines
 - o TMP4300C
 - Evaluator Chip for TLCS-43
- o 35 Basic instructions
 - 31 Processing Instructions
 - 4 Index Instructions
 - o 4 Level Subroutine Nesting
 - o Single Level External Interrupt
 - o 4 μ s Instruction Execution Time
 - o Single 5V Supply
 - o ROM Data Readout Instructions
 - o LED Direct Drive Capability
(Except TMP4315BP)



INTEGRATED CIRCUIT

TECHNICAL DATA

TMP4310AP

TMP4315BP

TMP4320AP

TMP4300C

TECHNICAL DATA

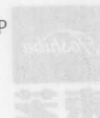


TABLE OF FEATURES

Feature	TMP4310AP	TMP4315BP	TMP4320AP	TMP4300C
ROM Capacity	1,024 Words x 8 Bits	1,536 Words x 8 Bits	2,048 Words x 8 Bits	External connection 2,048 Words x 8 Bits
RAM Capacity	48 Words x 4 Bits	64 Words x 4 Bits	128 Words x 4 Bits	128 Words x 4 Bits
Input Port	1 Port (4 Bits)	3 Port (12 Bits)	3 Port (12 Bits)	3 Ports (12 Bits)
Output Port	2 Port (8 Bits)	4 Port (15 Bits)	4 Port (15 Bits)	3 Port (12 Bits)
Input/Output Port	3 Port (10 Bits)	2 Port (8 Bits)	2 Port (8 Bits)	3 Port (11 Bits)
Subroutine Nesting Level	4 Levels (including interrupt)			
Interrupt Level	1 Level			
Number of Instructions	35 Basic Instructions			
Execution Time of Basic Instruction	4 μ S (1 Cycle Instruction), 8 μ S (2 Cycle Instruction)			
Input/Output Level	TTL Compatible			
Power Supply	5V \pm 10 %			
Power Dissipation	200mW (TYP.)	200mW (TYP.)	200mW (TYP.)	350mW (TYP.)
Operating Ambient Temp.	-10°C to 70°C			
Package	28 Pin Plastic DIP	42 Pin Plastic DIP	42 Pin Plastic DIP	64 Pin Ceramic DIP
Process	N-Channel E/D MOS			



INTEGRATED CIRCUIT

TECHNICAL DATA

TMP4310AP
TMP4320AP

TMP4315BP
TMP4300C



TECHNICAL DATA

TABLE OF FEATURES

PIN CONNECTIONS

Top View

(TMP4310AP)

IN 0 ₀	1	28	VDD
IN 0 ₁	2	27	XIN
IN 0 ₂	3	26	TEST
IN 0 ₃	4	25	IO 1 ₀
OT 0 ₀	5	24	IO 1 ₁
OT 0 ₁	6	23	IO 1 ₂
OT 0 ₂	7	22	IO 1 ₃
OT 0 ₃	8	21	IO 0 ₀
IO 2 ₀	9	20	IO 0 ₁
IO 2 ₁	10	19	IO 0 ₂
OT 1 ₀	11	18	IO 0 ₃
OT 1 ₁	12	17	INT
OT 1 ₂	13	16	RST
GND	14	15	OT 1 ₃

(TMP4300C)

GND	1	64	NC
RST	2	63	INT
XIN	3	62	ID
XOUT	4	61	IO 2 ₂
IO 0 ₃	5	60	IO 2 ₁
IO 0 ₂	6	59	IO 2 ₀
IO 0 ₁	7	58	NC
IO 0 ₀	8	57	OT 0 ₃
IO 1 ₃	9	56	OT 0 ₂
IO 1 ₂	10	55	OT 0 ₁
I ₇	11	54	OT 0 ₀
I ₆	12	53	OT 2 ₃
I ₅	13	52	OT 2 ₂
I ₄	14	51	OT 2 ₁
I ₃	15	50	OT 2 ₀
I ₂	16	49	OT 1 ₃
I ₁	17	48	OT 1 ₂
I ₀	18	47	OT 1 ₁
IO 1 ₁	19	46	OT 1 ₀
IO 1 ₀	20	45	IN 0 ₃
IN 2 ₃	21	44	IN 0 ₂
IN 2 ₂	22	43	IN 0 ₁
IN 2 ₁	23	42	IN 0 ₀
IN 2 ₀	24	41	CLK 1
IN 1 ₃	25	40	A ₀
IN 1 ₂	26	39	A ₁
IN 1 ₁	27	38	A ₂
IN 1 ₀	28	37	A ₃
A ₁₀	29	36	A ₄
A ₉	30	35	A ₅
A ₈	31	34	A ₆
A ₇	32	33	VDD

(TMP4315BP/TMP4320AP)

TEST	1	42	VDD
IN 0 ₀	2	41	IN 1 ₀
IN 0 ₁	3	40	IN 1 ₁
IN 0 ₂	4	39	IN 1 ₂
IN 0 ₃	5	38	IN 1 ₃
OT 0 ₀	6	37	IN 2 ₀
OT 0 ₁	7	36	IN 2 ₁
OT 0 ₂	8	35	IN 2 ₂
OT 0 ₃	9	34	IN 2 ₃
OT 1 ₀	10	33	IO 1 ₀
OT 1 ₁	11	32	IO 1 ₁
OT 1 ₂	12	31	IO 1 ₂
OT 1 ₃	13	30	IO 1 ₃
OT 2 ₀	14	29	IO 0 ₀
OT 2 ₁	15	28	IO 0 ₁
OT 2 ₂	16	27	IO 0 ₂
OT 2 ₃	17	26	IO 0 ₃
OT 3 ₀	18	25	XOUT
OT 3 ₁	19	24	XIN
OT 3 ₂	20	23	RST
GND	21	22	INT



INTEGRATED CIRCUIT

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TECHNICAL DATA

TMP4310AP
TMP4320AP

TMP4315BP
TMP4300C

TECHNICAL DATA



PIN NAMES & PIN DESCRIPTION

Pin Name	Input/ output	Function	4310	4315/ 4320	4300
IN0o-IN03	Input	4-bit Input Port IN0	○	○	○
IN1o-IN13	Input	4-bit Input Port IN1	—	○	○
IN2o-IN23	Input	4-bit Input Port IN2	—	○	○
OT0o-OT03	Output	4-bit Output Port OT0	○	○	○
OT1o-OT13	Output	4-bit Output Port OT1 Large sink current (IOL TYP=20mA, VOL=2V) is possible in TMP4310AP/20AP/00C.	○	○	○
OT2o-OT23	Output	4-bit Output Port OT2 Large sink current (IOL TYP=20mA, VOL=2V) is possible in TMP4320AP/00C.	—	○	○
OT3o-OT32	Output	3-bit Output Port OT3 IO2o-IO22 of TMP4300C are available in evaluation.	—	○	—
IO0o-IO03	Input/ Output	4-bit Input/Output Port IO0	○	○	○
IO1o-IO13	Input/ Output	4-bit Input/Output Port IO1	○	○	○
IO2o-IO22	Input/ Output	3-bit Input/Output Port IO2 2-bit Port (IO2o-IO21) in TMP4310AP	○	—	○
RST	Input	Initialize Signal Input The initialize operation is performed by placing RST terminal at low level for more than four clock cycles.	○	○	○
INT	Input	Interrupt Request Signal Input The interrupt request is accepted by placing INT terminal at low level for more than four clock cycles. The repetitive interrupt should be requested, after keeping INT terminal at high level for two clock cycles or more.	○	○	○
TEST (Note 1)	Input	LSI Test Signal Input TEST should be always kept at high level (open or connect an oscillation resistance in TMP4310AP) except in LSI test mode.	○	○	—

TOSHIBA CORPORATION



INTEGRATED CIRCUIT

TECHNICAL DATA

TMP4310AP
TMP4320AP

TMP4315BP
TMP4300C



TECHNICAL DATA

XIN (Note 1)	Input	Basic Clock Terminal XIN is used as an external clock input pin, or a oscillator connection pin.	○	○	○
XOUT	Output	Basic Clock Terminal XOUT is used as a oscillator connection pin.	—	○	○
A0-A10	Output	ROM Address Output (MSB:A ₁₀ , LSB:A ₀)	—	—	○
I0-I7	Input	ROM Data Input (MSB:I ₇ , LSB:I ₀)	—	—	○
CLK1	Output	Internal Clock Output	—	—	○
ID	Input	Interrupt Operation Inhibit Input ID is a dedicated terminal only for TDS400/43, and should be always kept at low level except in TDS400/43.	—	—	○
V _{DD}		+5V (Power Supply)	○	○	○
GND		0V (Power Supply)	○	○	○

- Note 1
- The basic clock of TMP4310AP
 - Internal oscillation (with resistance externally installed between \overline{XIN} and \overline{TEST}) and external clock supply can be available.
 - \overline{TEST} terminal should be kept open when the basic clock is supplied by an external oscillator circuit.



INTEGRATED CIRCUIT

TECHNICAL DATA

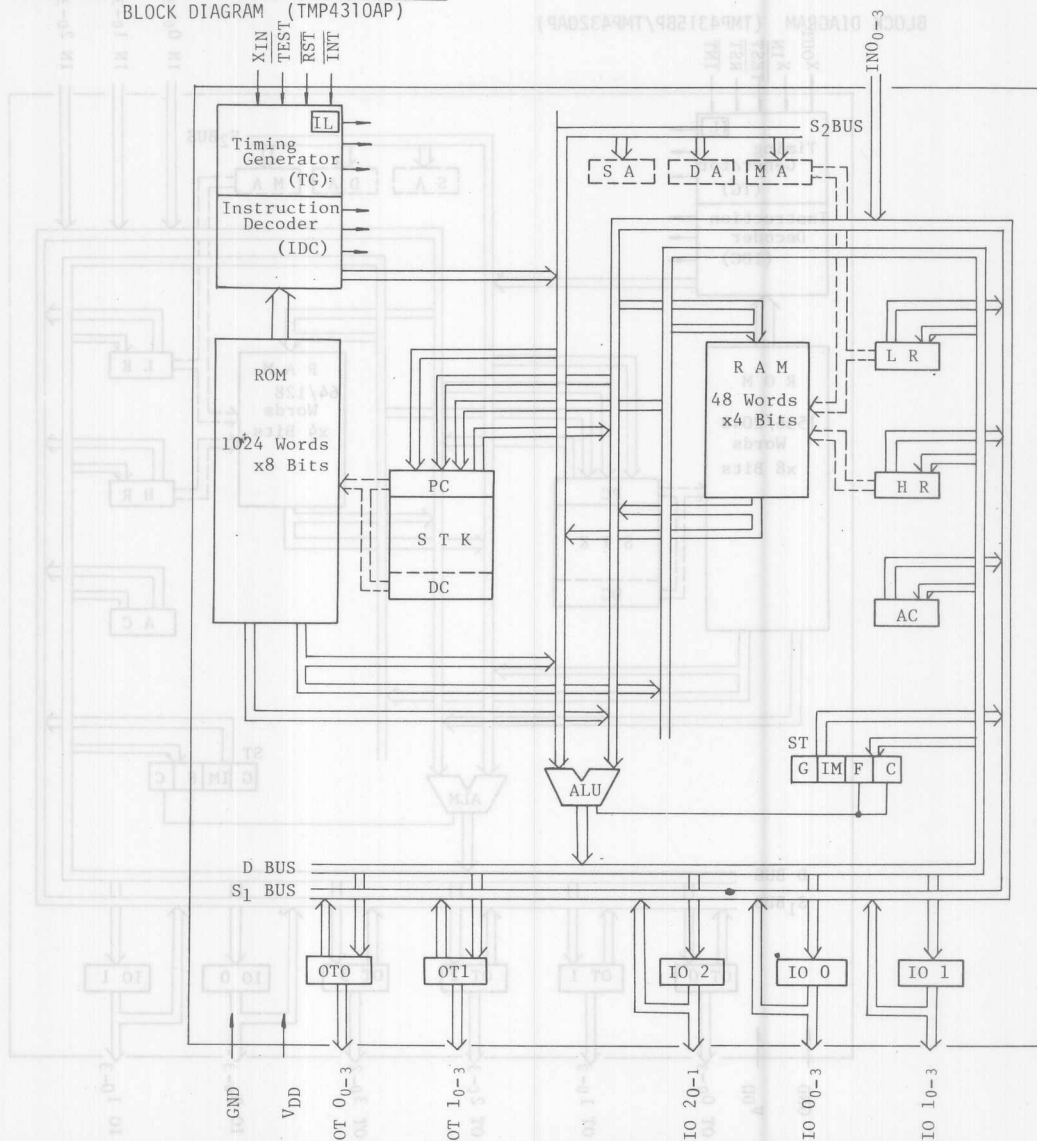
TMP4310AP
TMP4320AP

TMP4315BP
TMP4300C

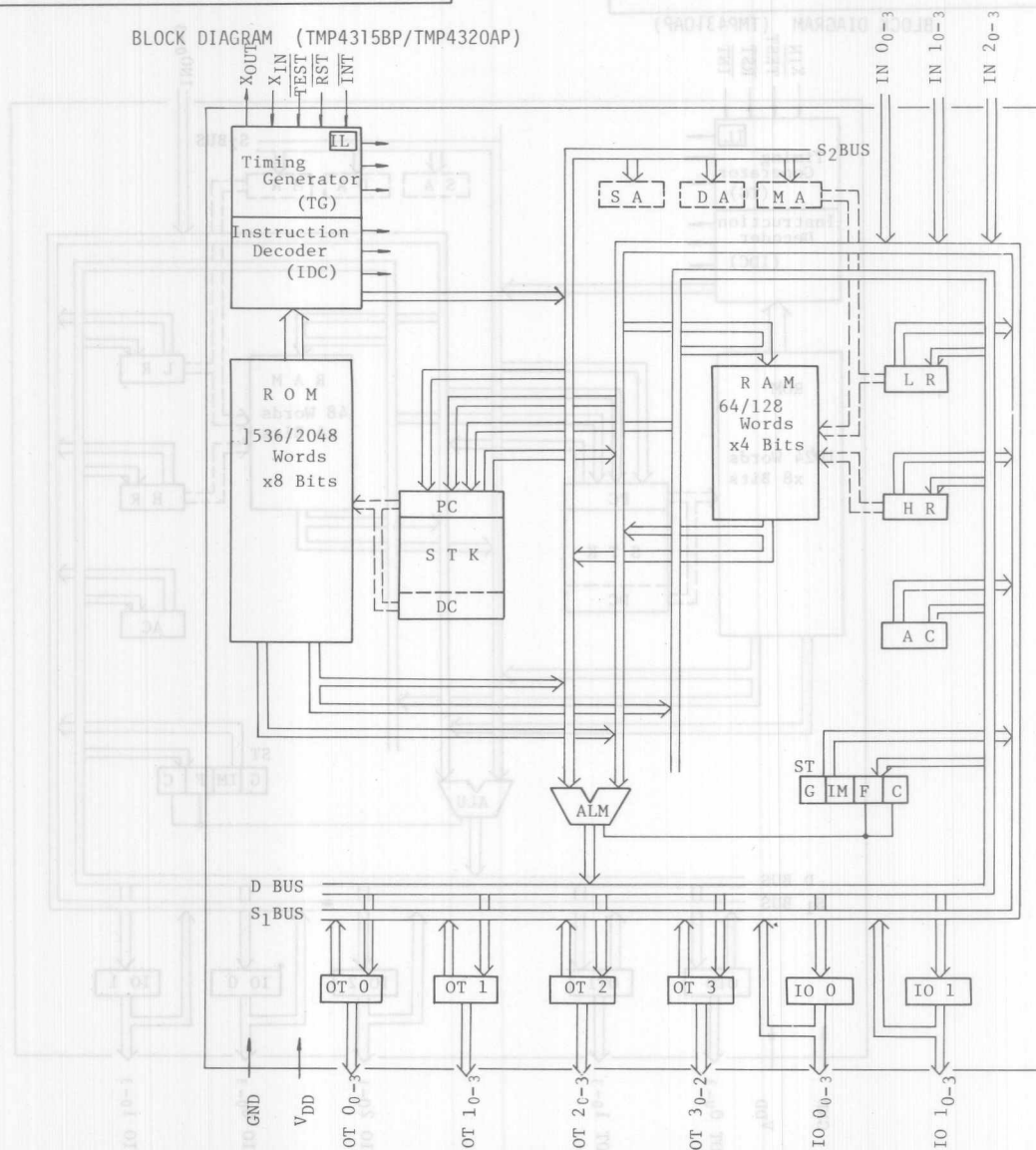
TECHNICAL DATA



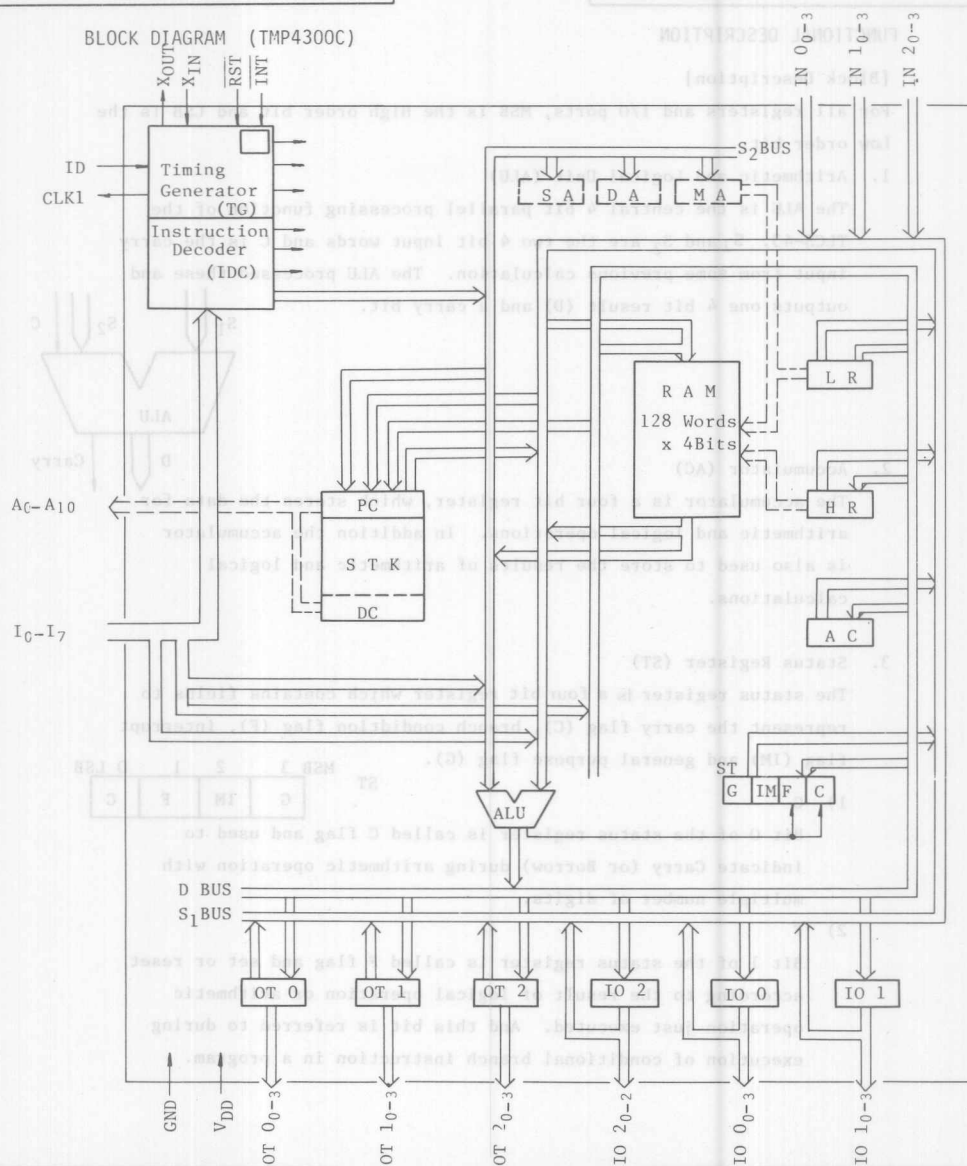
BLOCK DIAGRAM (TMP4310AP)



BLOCK DIAGRAM (TMP4315BP/TMP4320AP)



BLOCK DIAGRAM (TMP4300C)



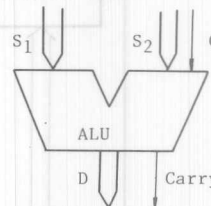
FUNCTIONAL DESCRIPTION

[Block Description]

For all registers and I/O ports, MSB is the High order bit and LSB is the Low order bit.

1. Arithmetic and Logical Unit (ALU)

The ALU is the central 4 bit parallel processing function of the TLCS-43. S_1 and S_2 are the two 4 bit input words and C is the carry input from some previous calculation. The ALU processed these and outputs one 4 bit result (D) and a carry bit.



2. Accumulator (AC)

The accumulator is a four bit register, which stores the data for arithmetic and logical operations. In addition the accumulator is also used to store the results of arithmetic and logical calculations.

3. Status Register (ST)

The status register is a four bit register which contains fields to represent the carry flag (C), branch condition flag (F), interrupt flag (IM) and general purpose flag (G).

ST	MSB 3	2	1	0 LSB
	G	IM	F	C

1) C

Bit 0 of the status register is called C flag and used to indicate Carry (or Borrow) during arithmetic operation with multiple number of digits.

2) F

Bit 1 of the status register is called F flag and set or reset according to the result of logical operation or arithmetic operation just executed. And this bit is referred to during execution of conditional branch instruction in a program.

3) IM

Bit 2 of the status register is the interrupt flag called IM flag which is set or reset by program.

IM flag being "1" indicates the interrupt enabled condition and IM flag is cleared to "0" as soon as an interrupt routine is initiated. This is also cleared to "0" by the initialize operation.

4) G

Bit 3 of the status register is called G flag and this one bit flag is used generally by programs.

4. L Register (LR)

L Register (lower address register) is a four bit register which indicates the lower order 4 bits of RAM address and is used in conjunction with H Register for addressing RAM.

5. H Register (HR)

H Register (Higher address register) is a two bit or three bit register which indicates the higher order two or three bits of RAM address, and used in conjunction with L Register for addressing RAM.

When a program reads, the undefined higher order two bits (bit 3 and bit 2) or one bit (bit 3) are always processed to be zero.

(TMP4310AP/TMP4315BP)

MSB 1 0 LSB

HR

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(TMP4320AP/TMP4300C)

MSB 2 1 0 LSB

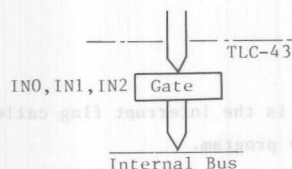
HR

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6. Input Port (INO, IN1, IN2)

All of INO, IN1 and IN2 ports are the dedicated input ports having four bit configuration and read the data sent from outside.

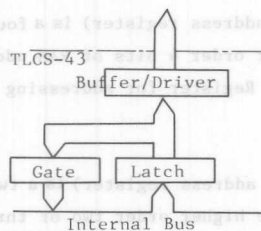
The input ports are non-latch type ports.



7. Output Port (OTO, OT1, OT2, OT3)

OTO, OT1 and OT2 have four bit configuration and OT3 has three bit configuration, all of which are the dedicated output ports. The content of each port is output to outside and retained until replaced with new data. And the content of a port can read by program.

In this case the undefined bit 3 of OT3 port is always processed to be zero. All the bits of all the output ports are set to "1" by the initialize operation.



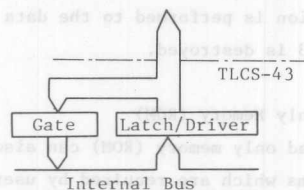
8. Input/Output Port (IO0, IO1, IO2)

IO0 and IO1 have four bit configuration and IO2 has two or three bit configuration, all of which are the input/output ports.

The content of each port is output to outside and retained until replaced with new data. It can also input data from outside. However, the output data must be set to "1" whenever the input operation is performed.

Whenver no data is input from outside, the output data to outside can be read by program. When the output data is read, undefined bit 3 and bit 2 of IO2 port are always processed to be zero.

All bits of the output data are set to "1" by the initialize operation.



9. Program Counter (PC)

The program counter is 11 bit counter which addresses the program stored in ROM (refer to (Note) in the ROM paragraph.)

While the normal instructions are executed, the program counter is incremented by word length of instruction just executed. However, for branch instructions, subroutine call and interrupt operation, the counter is set to the values designated by the instructions. The counter is reset to "0" by the initialize operation.

10. Stack

The stack is a group of 4 words x 11 bits registers including the data counter.

The stack is used as the save area of the program counter during subroutine call and interrupt operation. If it is already occupied up to level 2, the data counter becomes to be the stack area of level 3.

11. Data Counter (DC)

The data counter is an 11 bit counter which addresses fixed data stored in ROM (refer to (Note) in the ROM paragraph.)

The content of the data counter can be set by program. The data counter is also used as the deepest stack level (level 3) and when nesting has been done up to level 2, if further nesting is performed, the content as the data counter is destroyed.

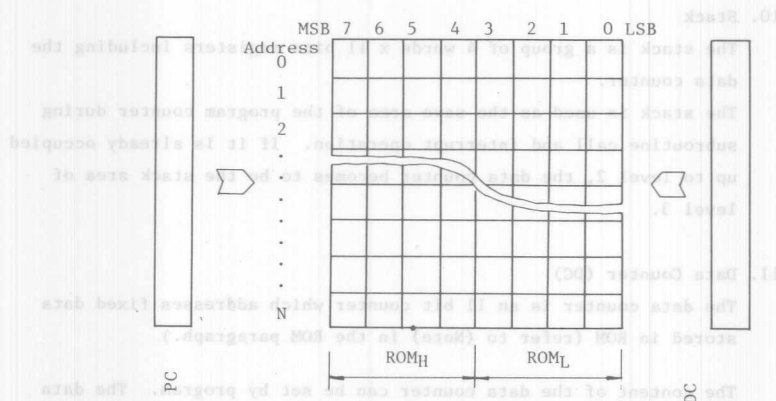
And when the data counter is being used as stack level 3, if setting operation is performed to the data counter, the content as stack level 3 is destroyed.

12. Read Only Memory (ROM)

The read only memory (ROM) can also store fixed data as well as programs which are required by users.

ROM has a maximum capacity of 2,048 words x 8 bits and is independently addressed by the program counter which addresses the storage area for programs and by the data counter which addresses the storage area for fixed data.

For storing programs the ROM is processed as 8 bit words but for fixed data, 8 bit word is divided into the higher order 4 bits and the lower order 4 bits, namely divided to two 4 bit words of ROM_H and ROM_L.



(TMP4310AP).... N=1,023 (TMP4315BP).... N=1,535 (TMP4320AP)... N=2,047

(Note) In the case of TMP4310AP, both of the program counter (PC) and the data counter (DC) are 11 bit counters, and if bit 10 is "1", any contents of ROM are not accessed.



13. Read/Write Memory (RAM)

The read/write memory (RAM) can be used as the working area for data processing.

RAM has the maximum configuration of 128 words x 4 bits and is addressed by H Register which designates a page and L Register which designates an address in a page.

In addition to the above, another addressing method of RAM is to access an address in page 0 using the index instructions (M instructions) which will be explained later. This method is effective to save the contents of registers on the interrupt operation. The configuration of each version is as follows.

(TMP4310AP)

		Address																LR	
Page	0	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0		
	1																		
	2																		
	3																		

(TMP4315BP)

		Address																LR	
Page	0	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0		
	1																		
	2																		
	3																		

(TMP4320AP/TMP4300C)

		Address																LR	
Page	0	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0		
	1																		
	2																		
	3																		
	4																		
	5																		
	6																		
	7																		



14. Timing Generator (TG) and Instruction Decoder (IDC)

The timing generator produces a clock frequency that is dependant on the oscillator connected externally.

Based on this timing the instruction decoder reads and decodes the fields unique to each instruction.

Timing of interrupts, initialize requests etc. are also synchronized by the Timing Generator.

15. Registers Dedicated to Index Instructions (SA, DA and MA)

..... Refer to the paragraph of Index Instructions.

These are 4 bit registers used by the index instructions which are explained later, and there are three kinds, namely SA (Source Address Register), DA (Destination Address Register) and MA (Memory Address Register). Source register code, destination register code and RAM address which are activated by the index instructions are input to SA, DA and MA respectively, and these are temporarily retained until the following one operation instruction is completely executed.

The registers dedicated to the index instructions can not be used by program as additional data registers.

1. Features of TLCS-43 Machine Instructions

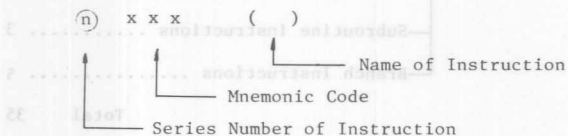
One of the features of the TLCS-43 Machine Instruction set is the existence of index instructions. In the case of processing instructions, usually the source and destination of data have been inherently defined. The index instructions modify the processing instructions to change the source of data to be processed or/and the destination of the processing results. Therefore, it is much simpler to write programs which require sequential operations through an area of memory. The extensive use of index instructions produces efficient programs in terms of the number of program steps.

Another great feature is that the machine instructions with Data Counter (DC) maintaining ROM address in addition to PC have the instructions which can read out the content of ROM directly, which allows a greater amount of fixed data to be efficiently read.

Furthermore, with the addition of four level subroutine nesting ability, the subroutine call instructions of 1 byte length are available. This is effective in reducing overall program size.

2. Format of Machine Instructions

The explanation of each instructions is described according to the following format.



<Symbol Instruction> Mnemonic Operation Code Operand

[Machine Instructions]

TLCS-43 series microcomputer is provided with 35 kinds of machine instructions. Unless otherwise mentioned the machine instructions are described as just instructions.

Among the machine instructions of TLCS-43, 30 instructions are of 1-byte length and 5 instructions are of 2-byte length. As regards the execution time of machine instructions, 28 instructions are of 1-machine cycle and 7 instructions are of 2-machine cycle.

Machine Instructions are classified by their functions as follows:

	Number of Instructions
TLCS-43 Machine Instructions	
Index Instructions.....	4
Processing Instructions	
Data Transfer Instructions	7
Logical Operating Instructions	10
Bit Processing Instructions	3
ROM Readout Instructions	3
Subroutine Instructions	3
Branch Instructions	5
Total	35



INTEGRATEDCIRCUIT

東芝

TECHNICAL DATA

TMP4310AP

TMP4315BP

TMP4320AP

TMP4300C

TECHNICAL DATA



< Machine
Code >

No.1 Byte

MSB								LSB			
7	6	5	4	3	2	1	0	7	6	5	4
x	x	x	x	x	x	x	x	x	x	x	x

No.2 Byte

(Address next to
(+1) No.1 Byte)

MSB								LSB			
7	6	5	4	3	2	1	0	7	6	5	4
x	x	x	x	x	x	x	x	x	x	x	x

< Function >

< Status Flag >

(The correspondence of the operand of
symbol instruction and the machine code
is recorded, if necessary.)

The logical peration performed by this
instruction is explained with symbols.

(F): } The status after the execution
(C): } of status flag is described.

(Dependent on the data when
designated to store data in
status register.)

< Execution
Cycle >

The number of machine cycles necessary
for executing instructions is described.

< Function
Explanation >

The function of instructions is explained.

Modifiable

< Index
Instructions >

In processing instructions, modifiable

index instructions are described.

In this section, the symbols defined in Table A are used more concisely to express the functions of machine instructions. The storage elements, including input ports, related directly to the operation of instructions are collected in Table B.

Table A. Symbol and their Meanings for Instructions

Symbol	Meaning
(a)	The content of storage element "a".
M[(H.L)]	The content of RAM address designated by the contents of H register and L register.
TEMP	Temporary register
ZR	Virtual register of which content is "0".
$i_n i_{n-1} \dots i_0$	Data of n+1 bit
\bar{b}	Values inverted "1" to "0", "0" to "1" every bit of "b".
$a \leftarrow b$	"a" is replaced by the value of "b".
$a + 1$	Value added 1 to "a".
$a + b$	Value added "b" to "a".
$a - b$	Value subtracted "b" from "a".
$a \wedge b$	Value of logical product of "a" and "b" for every bit.
$a \vee b$	Value of logical sum of "a" and "b" for every bit.
$a \oplus b$	Value of exclusive logical sum of "a" and "b" for every bit.



INTEGRATED CIRCUIT

TECHNICAL DATA

TMP4310AP TMP4315BP
TMP4320AP TMP4300C



TECHNICAL DATA

Ones 	4-bit data having 1's at bit positions only indicated by "b" and 0's at all other bit positions.
ROM _H [(DC)]	Higher order 4 bits in the content of ROM address indicated by the content of data counter DC.
ROM _L [(DC)]	Lower order 4 bits in the content of ROM address indicated by the content of data counter DC.
M[a]	Content of address "a" of RAM.
a	Value of bit position "b" of "a".
DC _H	Higher order 3 bits of data counter
DC _M	Intermediate order 4 bits of data counter
DC _L	Lower order 4 bits of data counter
Carry	Carry resulted by operations (overflow)
Borrow	Borrow resulted by operations (underflow)
a = b	"a" equals to "b"
if a then b else c	If the condition of "a" is satisfied, "b" is performed; if not, "c" is performed
\$	ROM address in which instructions are stored (No.1 byte address for 2-byte instruction)

Table B. Storage Elements Related Directly to Operation of Instructions

Name	Mnemonic	Function
Accumulator	AC	4-bit register
Carry flag	C	Carry flag of multiple digit operation
Branch flag	F	Condition flag exclusive for branch



INTEGRATED CIRCUIT

TECHNICAL DATA

TMP4310AP TMP4315BP
TMP4320AP TMP4300C

TECHNICAL DATA



Name	Mnemonic	Function
Interrupt mask flag	IM	Flag masking interrupt-peration In case of "1", interrupt is permitted.
General purpose flag	G	1 bit flag used by program
L register	LR	Register showing lower order 4 bits of RAM address
H register	HR	Rsgister showing higher order 3 bits of RAM address
Input port	INO, IN1, IN2	Ports for input of external data.
Output port	OTO, OT1, OT2, OT3	Ports for output of data
I/O port	I00, I01, I02	Ports for input or output of data
Data counter	DC	Counter to read out ROM contents as data
Program counter	PC	Counter to read out the instruction under program
Stack	STK	Stack storing return address from interrupt routine or subroutine (PC evacuation area)
Read/Write memory	RAM	Memory temporaly maintaing data
Read only memory	ROM	Memory maintaining program or fixed data

3. Index Instructions

The index instructions indicate source or/and destination of data. The data is processed by the instructions following the index instructions. The fixed data source and destination are designated for the instructions themselves, but if the instructions are modified by the index instructions, the data source and destination become those designated by the index instructions.

Since the index instructions cannot process effective data by themselves, they are invariably used in combination with the processing instructions. Therefore, the interrupt operation cannot be performed after execution of the index instructions, but can be done only after completion of the processing instructions.

One processing instruction can be modified by maximum three index instructions. When sources or destinations have been indicated in duplicate, the initially indicated one becomes effective.

- ① S (Designate Source register) : Source Register Index Instruction

< Symbol Instruction >

S r or = r

< Machine Code >

MSB				LSB			
7	6	5	4	3	2	1	0
1	0	1	0	r ₃	r ₂	r ₁	r ₀

Operand r = r₃ r₂ r₁ r₀

< Function > (SA) ← r

< Status Flag > (F) : No change

(C) : No change

< Execution Cycle > 1 Machine Cycle

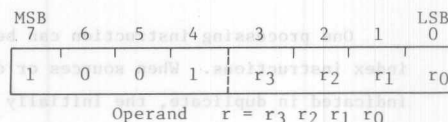
< Explanation of Function > Write address r of register/port, which becomes data source, in the source address register SA. The source register designated by this instruction is effective until the processing instruction is executed. However, if there are plural numbers of instructions indicating the source register before the processing instruction, the initial index is effective.

- ② D (Designate Destination register) : Destination Register, Index Instruction

< Symbol Instruction >

D r or = r

< Machine Code >



< Function >

(DA) ← r

< Status Flag >

(F) : No change

(C) : No change

< Executive Cycle >

1 Machine Cycle

< Explanation of Function >

Write address r of register, which becomes a destination as a result of processing, in destination address register DA. The destination register designated by this instruction is effective until the processing instruction is executed. However, if there were plural numbers of instructions indicating the destination register before the processing instruction, the initial index becomes effective.

- ③ SD (Designate Source and Destination register) : Source & Destination Register Index Instruction

< Simbyl Instruction >

SD r or = r



INTEGRATEDCIRCUIT

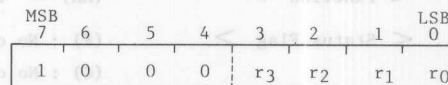
TECHNICAL DATA

TMP4310AP
TMP4320AP

TMP4315BP
TMP4300C



< Machine Code >



Operand r = r₃ r₂ r₁ r₀

< Function >

(SA) ← r

(DA) ← r

< Status Flag >

(F) : No change

(C) : No change

< Executive Cycle >

1 Machine Cycle

< Explanation of Function >

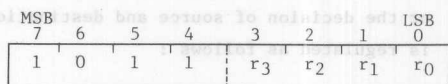
Write address r of the register (same register) becoming data source and destination in source address register SA and destination address register DA. The register designated by this instruction is effective until the processing instruction is executed. However, if the source register or the destination register has been indicated numbers times to one processing instruction in the same way as the instructions of S and D, the index initially made to the respective registers becomes effective.

④ M (Designate RAM address) : RAM Address Index Instruction

< Symbol Instruction >

M r or = r

< Machine Code >



Operand r = r₃ r₂ r₁ r₀

< Function >

(MA) ← r

< Status Flag >

(F) : No change

(C) : No change

< Executive Cycle >

1 Machine Cycle

< Explanation of Function >

RAM address can be directly designated by this instruction without using H register and L register.

The RAM address "r" is written in memory address register MA; however, the RAM which can be designated by this instruction is limited to addressed 0 - 15 (16 words in "0" page). These RAM addresses are effective until the processing instruction is executed; that is, the RAM address of the processing instruction modified by this instruction is designated by the memory address register MA regardless of the content of H register and L register.

There are no changes in the contents of H register and L register.

If there are numbers of RAM address index instructions before the processing instruction the value initially indicated becomes effective.

4. Decision of Source and Destination by Index Instructions

The way of modifying the processing instruction by index instructions, or the decision of source and destination of the processing instruction, is regulated as follows :

- (0) The elements not modified are unique source and destination for each instruction.



(1) Instructions related to registers and RAM (9 instructions)

In regard to the nine instructions, such as LDM, SWP, STR, ADD, ADC, SUB, CND, ORM, and EOR, their sources and destinations can be changed by the index instructions (S, D, and SD). When modified by M instruction, RAM data becomes the addresses (0 - 15) designated by M instruction.

(2) Instructions related to register (13 Instructions)

In regard to the thirteen instructions, such as LDA, LDT, LDI, LLI, CMA, NGT, ADI, ALI, SSB, RSB, LFB, LRL, and LRH, their sources and destinations can be changed by the index instructions (S, D, and SD). When modified by M instruction, the sources and destinations by the S or D instruction become RAM addressed (0 - 15) designated by M instruction.

(3) As for SDC instruction, the source register can be designated to the intermediate order 4 bits of DC by S Instruction. In this case, the logical sum of the designated source register content and the immediate data is set to the intermediate order 4 bits of DC. When modified by M instructions the intermediate order 4 bits of DC become the contents of RAM addressed (0 - 15) designated by M instruction.

(4) Subroutine and branch instructions (8 instructions)

In regard to the eight instructions, such as CAL, CLS, RTN, BCF, BCB, JCS, JCC, and JMP, the index instructions cannot be modified. (If they are modified, their operations cannot be guaranteed.)

The following figure shows diagrammatically the relationship between the above mentioned source and destination selection regulation and hardware.



INTEGRATEDCIRCUIT

TECHNICAL DATA

TMP4310AP TMP4315BP
TMP4320AP TMP4300C

TECHNICAL DATA



The address of source register is stored in source address register SA by S instruction, and the source register is selected by the source selector according to this address.

The data from the selected source register is input into S1 of ALU. Either RAM or ROM is selected by the data selector as data input into S2 of ALU. The selection by this data selector is decided by the instructions.

The address pointer of RAM has HR·LR and memory address register MA. Usually HR·LR is selected, but when modification is made by M instruction, MA is selected. The memory address is stored in MA by M instruction. Since either HR·LR or MA is used as address pointer, if RAM is used as source and destination register, the same address is selected.

The address of destination register is stored in the destination address register DA by D instruction. The destination selector selects destination register according to this address.

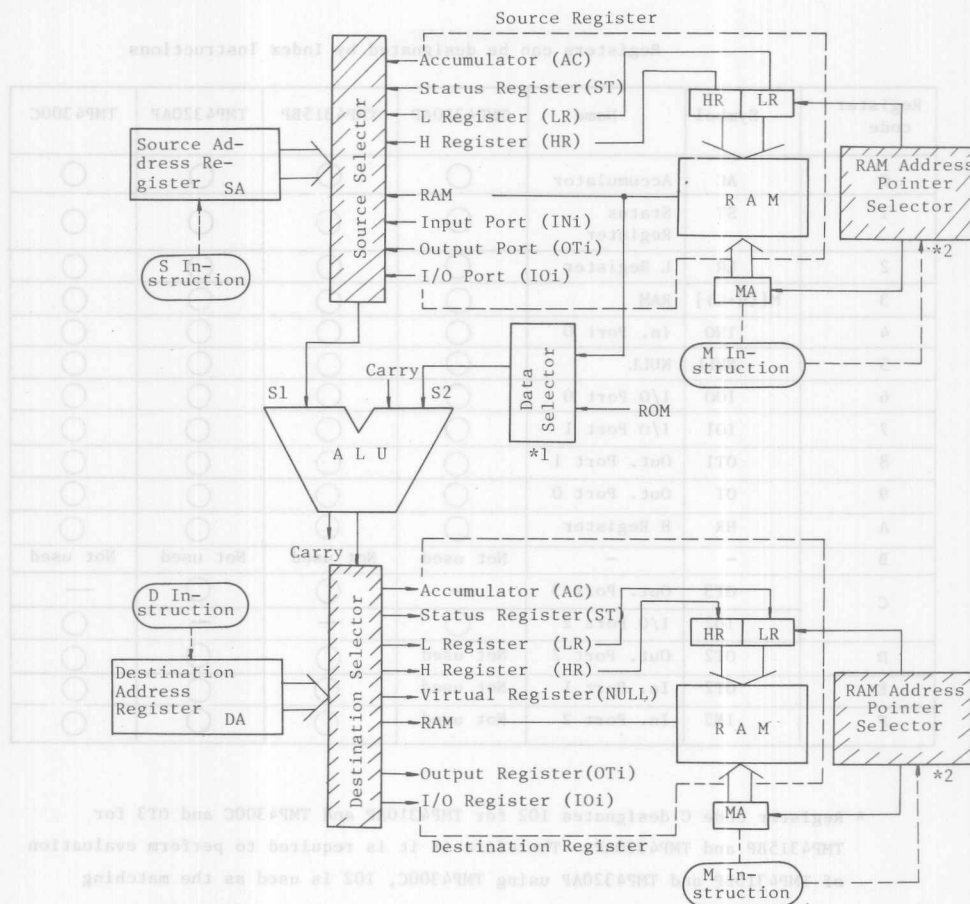
The process results output from ALU are stored in the destination register.

By using SD instruction, the same register address is stored into source address register SA and destination address register DA; therefore, the source register of S1 of ALU and the destination of output of ALU become the same.

As shown in the following figure the selector which changes the flow of processing data according to index instructions has the following three kinds of versions:

- (1) Source selector (Selection of source register)
- (2) Destination selector (Selection of destination register)
- (3) RAM address pointer selector

In the case where no modification is made by index instructions, it may be thought that each selector makes the selection of the source or destination.



*1 Such a selector is determined according to the kind of instruction; in many cases RAM is selected, but in case of ROM readout instruction or immediate instruction, ROM is selected.

*2 Usually HR and LR is selected, but in case of processing instruction that modification is conducted by M instruction, MA is selected.

Registers can be designated by Index Instructions

Register code	Symbol	Name	TMP4310AP	TMP4315BP	TMP4320AP	TMP4300C
0	AC	Accumulator	○	○	○	○
I	ST	Status Register	○	○	○	○
2	LR	L Register	○	○	○	○
3	M[(H·L)]	RAM 1	○	○	○	○
4	INO	In. Port 0	○	○	○	○
5	NULL	NULL	○	○	○	○
6	I00	I/O Port 0	○	○	○	○
7	I01	I/O Port 1	○	○	○	○
8	OT1	Out. Port 1	○	○	○	○
9	OT	Out. Port 0	○	○	○	○
A	HR	H Register	○	○	○	○
B	-	-	Not used	Not used	Not used	Not used
C	OT3	Out. Port 3	—	○	○	—
	I02	I/O Port 2	○	—	—	○
D	OT2	Out. Port 2	Not used	○	○	○
E	OT2	In. Port 1	Not used	○	○	○
F	IN2	In. Port 2	Not used	○	○	○

* Register code C designates I02 for TMP4310AP and TMP4300C and OT3 for TMP4315BP and TMP4320AP. Therefore if it is required to perform evaluation of TMP4315BP and TMP4320AP using TMP4300C, I02 is used as the matching port for OT3.

5. Data Processing Instructions

The data processing instructions are classified in four types, data transfer instruction, logical operation instruction, bit processing instruction, and ROM readout instruction.

5.1 Data transfer instruction

Data is handled in 4-bit units. The use of these instructions provide the setting of immediate data as well as the data transfer between two registers or between a register and RAM.

⑤ LDM (Load from Memory) : Load from Memory Instruction

< Symbol Instruction >

LDM

< Machine Code >

MSB	7	6	5	4	3	2	1	LSB	0
	0	0	1	0	0	1	1		0

< Function >

(AC) ← M[(H·L)]

< Status Flag >

(F) : No change

(C) : No change

< Execution Cycle >

1 Machine cycle

< Explanation of Function

The content of RAM address designated by H register and L register is loaded into accumulator.

Modifiable

< Index Instruction

D, M

⑥ SWP (Swap) : SWAP Instruction

< Symbol Instruction >

SWP

< Machine Code >

MSB	7	6	5	4	3	2	1	LSB	0
	0	0	1	0	0	1	0		1



INTEGRATED CIRCUIT

TECHNICAL DATA

TMP4310AP

TMP4315BP

TMP4320AP

TMP4300C

< Function > (TEMP) \leftrightarrow (AC)
 (AC) \leftarrow M [(H.L)]
 M[(H.L)] \leftarrow (TEMP)

< Status Flag > (F) : No change
 (C) : No change

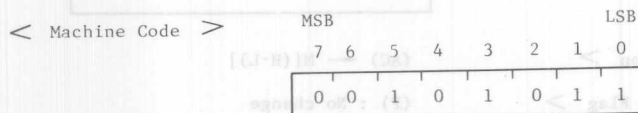
< Execution Cycle > 1 Machine cycle

< Explanation of Function > This instruction exchanges the content of RAM address designated by H register and L register content of the accumulator.

Modifiable
 Index Instruction SD, M

⑦ LDA (Load from Accumulator) : Load from Accumulator Instruction

< Symbol Instruction >



< Function > (AC) \leftarrow (AC)

< Status Flag > (F) : No change
 (C) : No change

< Execution Cycle > 1 Machine cycle

< Explanation of Function > The content of accumulator is loaded into the accumulator. If used independently, this instruction becomes a no-operation instruction.

Modifiable
 Index Instruction S, D, M

⑧ STR (Store) : Store Instruction



INTEGRATED CIRCUIT

TECHNICAL DATA

TMP4310AP TMP4315BP
TMP4320AP TMP4300C



< Symbol Instruction >

STR

< Machine Code >

MSB	7	6	5	4	3	2	1	0	LSB
	0	0	1	0	0	1	0	0	

< Function >

(AC) \leftarrow M[(H·L)]

< Status Flag >

(F) : No change

(C) : No change

< Execution Cycle >

1 Machine cycle

< Explanation of Function >

The content of accumulator is stored in the RAM address designated by H register and L register.

Modifiable

< Index Instruction >

S, M

⑨ LDT (Load and Test) : Load & Test Instruction

< Symbol Instruction >

LDT

< Machine Code >

MSB	7	6	5	4	3	2	1	0	LSB
	0	0	1	0	1	0	1	0	

< Function >

(AC) \leftarrow (AC)

< Status Flag >

If (AC) = 0 then (F) \leftarrow 1, else

(F) \leftarrow 0

(C) : No change

< Execution Cycle >

1 Machine cycle

< Explanation of Function >

The content of accumulator is loaded into the accumulator. If the data is zero, F is set to "1", but if not, F is cleared to "0".

Modifiable

< Index Instruction >

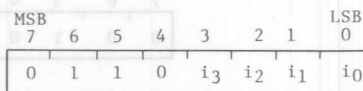
S, D, SD, M

10) LDI (Load Immediate data) : Load Immediate Data Instruction

< Symbol Instruction >

LDI i ($0 \leq i \leq 15$)

< Machine Code >



Operand i = $i_3 i_2 i_1 i_0$

< Function >

(AC) ← i

< Status Flag >

(F) : No change

(C) : No change

< Execution Cycle >

1 Machine cycle

< Explanation of Function >

Immediate Data i is loaded into accumulator.

< Modifiable

< Index >

D, M

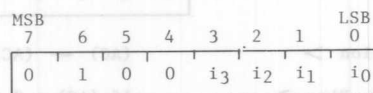
Instruction

11) LLI (Load Immediate data to L register) : Load Immediate Data to L Register Instruction

< Symbol Instruction >

LLI i ($0 \leq i \leq 15$)

< Machine Code >



Operand i = $i_3 i_2 i_1 i_0$

< Function >

(LR) ← i

< Status Flag >

(F) : No change

(C) : No change

< Execution Cycle >

1 Machine cycle

< Explanation of Function >

Immediate Data i is loaded into L Register



< Modifiable
Index
Instruction > D, M

5.2 Logical operation instruction

The instructions of CMA, CND, ORM and EOR are used for logical operation of every bit of 4-bit data. The others are mainly used for arithmetic operation. For 2-operand instruction one data source is a register and another is RAM.

For the nine instructions except CMA, branch condition flag F is set, and for ADC instruction, carry flag C is set.

12) CMA (Complement Accumulator) : Complement Accumulator Instruction

< Symbol Instruction >

< Machine Code >								MSB									LSB
7	6	5	4	3	2	1	0		7	6	5	4	3	2	1	0	
0	0	1	1	1	0	1	1		0	0	1	1	1	0	1	1	

< Function > (AC) \leftarrow $\overline{(AC)}$

< Status Flag > (F) : No change
(C) : No change

< Execution Cycle > 1 Machine cycle

< Explanation of Function > The content of accumulator is loaded into the accumulator after inverting "0" to "1" and "1" to "0" every bit.

< Modifiable
Index
Instruction > S, D, SD, M

13) NGT (Negate) : Negate (2's complement) Instruction

< Symbol Instruction >

NGT

< Machine Code >

MSB	7	6	5	4	3	2	1	0	LSB
	0	0	1	1	1	0	0	1	

< Function >

< Status Flag >

if Carry then (F) ← 1, else (F) ← 0
(C) : No change

< Execution Cycle >

1 Machine cycle

< Explanation of Function >

2's complement of the content of accumulator is loaded into the accumulator. If the original data is 0 ((AC)=0), 2's complement is 0. In this case only, F flag is set to "1", but in the other cases, F flag is cleared to "0". In this case F flag is used in both meanings of carry and zero decision.

Modifiable

< Index Instruction >

S, D, SD, M

14) ADD (Add) : Add Instruction

< Symbol Instruction >

ADD

< Machine Code >

MSB	7	6	5	4	3	2	1	0	LSB
	0	0	1	0	1	1	0	1	

< Function >

(AC) ← (AC) + M [(H·L)]

< Status Flag >

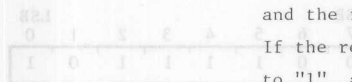
if carry then (F) ← 1, else (F) ← 0
(C) : No change

< Execution Cycle >

1 Machine cycle

< Explanation of Function >

The content of RAM address designated by the contents of H register and L register is added to the content of the accumulator, and the result is loaded into the accumulator. If the resultant carry is "1", F flag is set to "1", and if it is "0", F flag is cleared to "0".



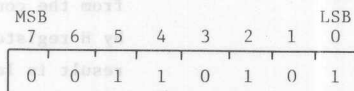
< Modifiable Index Instruction > S, D, SD, M

15) ADC (Add with Carry) : Add with Carry Instruction

< Symbol Instruction >

ADC

< Machine Code >



< Function >

$(AC) \leftarrow (AC) + M[(H \cdot L)] + (C)$

< Status Flag >

if carry then (F) ← 1, (C) ← 1, else (F) ← 0
(C) ← 0

< Execution Cycle >

1 Machine cycle

< Explanation of Function >

The content of RAM address designated by H register and L register and the content of C flag are added to the content of accumulator, and the result is loaded into the accumulator. The conditions of Carry cause F flag and C flag to be set/reset.



< Modifiable Index Instruction > S, D, SD, M

①6 SUB (Subtract) : Subtract Instruction

< Symbol Instruction >

SUB

< Machine Code >

MSB	7	6	5	4	3	2	1	0	LSB
	0	0	1	1	1	1	0	1	

< Function >

$(AC) \leftarrow M[(H \cdot L)] - (AC)$

< Status Flag >

if borrow then $(F) \leftarrow 0$, else $(F) \leftarrow 1$

(C) : No change

< Execution Cycle >

1 Machine cycle

< Explanation of Function >

The content of accumulator is subtracted from the content of RAM address designated by H register and L register, and the result is loaded into the accumulator. The conditions of underflow cause F flag to be set/reset.

< Modifiable Index Instruction >

S, D, SD, M

①7 CND (Complement & AND) : Complement and AND Instruction

< Symbol Instruction >

CND

< Machine Code >

MSB	7	6	5	4	3	2	1	0	LSB
	0	0	1	1	1	1	0	0	

< Function >

$(AC) \leftarrow (AC) \wedge M[(H \cdot L)]$

< Status Flag >

if $(AC) = 0$ then $(F) \leftarrow 1$, else $(F) \leftarrow 0$

(C) : No change

< Execution Cycle >

1 Machine cycle

< Explanation of Function >

The logical product of every bit of the content of accumulators and the 1's complement of the content of RAM address designated by the content of H register and L register is loaded into the accumulator. If the result is "0", F flag is set to "1"; in the other cases, F flag is cleared to "0".

< Modifiable Index Instruction >

S, D, SD, M

⑱ ORM (OR) : OR Instruction

< Symbol Instruction >

ORM

< Machine Code >

MSB	7	6	5	4	3	2	1	0	LSB
	0	0	1	0	1	1	1	0	

< Function >

$(AC) \leftarrow (AC) \vee M[(H \cdot L)]$

< Status Flag >

if $(AC)=0$ then $(F) \leftarrow 1$, else $(F) \leftarrow 0$
(C) : No change

< Execution Cycle >

1 Machine cycle

< Explanation of Function >

The logical sum of every bit of the content of accumulator and the content of RAM address designated by H register and L register is loaded into the accumulator. If the result is "0", F flag is set to "1"; in the other cases, F flag is cleared to "0".

< Modifiable Index Instruction >

S, D, SD, M

⑲ EOR (Exclusive OR) : Exclusive OR Instruction

< Symbol Instruction >

EOR

< Machine Code >

MSB	7	6	5	4	3	2	1	LSB	0
	0	0	1	0	1	1	1		1

< Function >

$(AC) \leftarrow (AC) \vee M[(H \cdot L)]$

< Status Flag >

if $(AC)=0$ then $(F) \leftarrow 1$, else $(F) \leftarrow 0$

(C) : No change

< Execution Cycle >

1 Machine cycle

< Explanation of Function >

The exclusive logical sum of every bit of the content of accumulator and the content of RAM address designated by H register and L register is loaded into the accumulator.

If the result is "0", F flag is set to "1"; in the other cases, F flag is cleared to "0".

< Modifiable Index Instruction >

S, D, SD, M

⑳ ADI (Add Immediate data) : Add Immediate Data Instruction

< Symbol Instruction >

ADI i ($0 \leq i \leq 15$)

< Machine Code >

MSB	7	6	5	4	3	2	1	LSB	0
	0	1	1	1	i ₃	i ₂	i ₁		i ₀

Operand i = i₃ i₂ i₁ i₀

< Function >

$(AC) \leftarrow (AC) + i$

< Status Flag > if Carry then (F) \leftarrow 1, else (F) \leftarrow 0,
(C) : No change

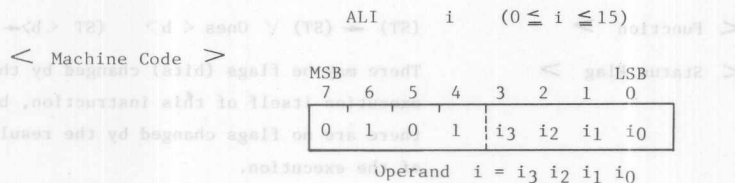
< Execution Cycle > 1 Machine cycle

< Explanation of Function > Immediate data "i" is added to the content of accumulator and the result is loaded into the accumulation.
If the resultant carry is generated, F flag is set to "1"; in the other case, F flag is cleared to "0".

< Modifiable Index Instruction > S, D, SD, M

21 ALI (Add Immediate data to L register) :
Add Immediate Data to L Register Instruction

Symbol Instruction



< Function > (LR) \leftarrow (LR) + i

< Status Flag > if Carry then (F) \leftarrow 1, else (F) \leftarrow 0
(C) : No change

< Execution Cycle > 1 Machine cycle

< Explanation of Function > Immediate data "i" is added to the content of L register, and the result is loaded into L register. If resultant carry is generated, F flag is set to "1"; in the other cases, F flag is cleared to "0".

< Modifiable Index Instruction > S, D, SD, M

5.3 Bit manipulation instruction

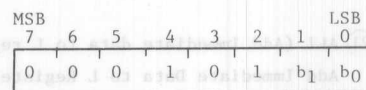
Ordinary data is manipulated as 4-bit units, however the use of these instructions enables the data to be manipulated bit by bit. These instructions are mainly applied to status register ST, but their functions can be extended to arbitrary register, output port and RAM by a combination of index instructions.

22 SSB (Set Status Bit) : Set Status Bit Instruction

< Symbol Instruction >

SSB b ($3 \geq b \geq 0$)

< Machine Code >



Operand b = b₁ b₀

< Function > (ST) ← (ST) ∨ Ones < b > (ST < b > ← 1)

< Status Flag >

There may be flags (bits) changed by the execution itself of this instruction, but there are no flags changed by the result of the execution.

< Execution Cycle >

1 Machine cycle

< Explanation of Function >

The bit field of the status register defined by low order 2 bits "b" of the instruction is set to a "1".

< Modifiable Index Instruction >

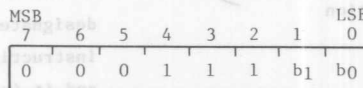
SD, M

23 RSB (Reset Status Bit) : Reset Status Bit Instruction

< Symbol Instruction >

RSB b ($3 \geq b \geq 0$)

< Machine Code >



Operand b = b₁ b₀

< Function >

$(ST) \leftarrow (ST) \wedge \overline{\text{Ones } \langle b \rangle} \quad (ST \langle b \rangle \rightarrow 0)$

< Status Flag >

There may be flags (bits) changed by the execution itself of this instruction; but there are no flags changed by the result of the execution.

< Execution Cycle >

1 Machine cycle

< Explanation of Function >

The bit field of the status register defined by the low order 2 bits "b" of the instruction is set to a "0".

< Modifiable Index Instruction >

SD, M

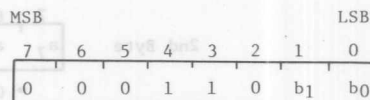
②4 LFB (Load complemented status Bit to F)

Load and Complement Status Bit to F Instruction

< Symbol Instruction >

LFB b (3 ≥ b ≥ 0)

< Machine Code >



Operand b = b₁ b₀

< Function >

$(F) \leftarrow \overline{ST \langle b \rangle}$

< Status Flag >

(F) : According to condition of ST
(C) : No change

< Execution Cycle >

1 Machine cycle

< Explanation of Function >

If the bit content of status register designated by lower order 2 bits of the instruction is 1, it is inverted to 0, and it is 0, it is inverted to 1, and then it is loaded into F bit.

< Modifiable Index Instruction >

S, M

5.4 ROM readout instruction

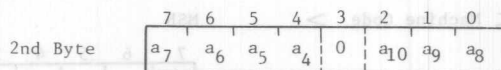
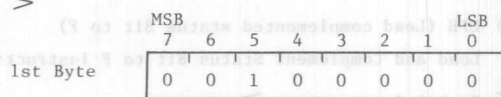
SDC is the instruction by which the address on ROM of fixed data is set into data counter DC. LRL and LRH are the instructions by which ROM data are readout in the 4-bit unit.

(25) SDC (Set Data Counter) : Set Data Counter Instruction

< Symbol Instruction >

SDC a $16 \leq a \leq 2032$, where "a" is
(integral multiples of 16.)
i.e. $a = 16n, 1 \leq n \leq 127$

< Machine Code >



• Operand $a = a_{10} a_9 a_8 a_7 a_6 a_5 a_4 0000$

< Function >

$$\left. \begin{aligned} (DC_H) &\leftarrow a_{10} a_9 a_8 \\ (DC_M) &\leftarrow a_7 a_6 a_5 a_4 \vee (ZR) \\ (DCL) &\leftarrow M[(H \cdot L)] \end{aligned} \right\} \text{ i.e. } (DC) \leftarrow a + M[(H \cdot L)]$$

< Status Flag >

(F) : No change
(C) : No change

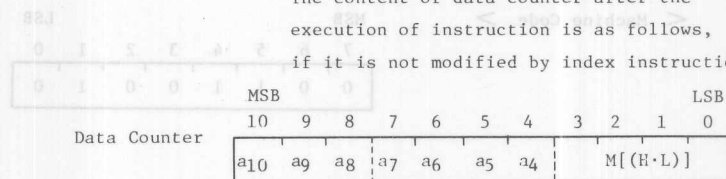
< Execution Cycle >

2 Machine cycle

< Explanation of Function >

This instruction sets ROM address into the data counter. The higher order 3 bits of ROM address to be set are immediate values, and the intermediate 4 bits are the logical sum of intermediate value and virtual source register ZR, of which content is "0", and the lower order 4 bits are the content of RAM address indicated by H register and L register. When source register is designated by the index instructions, ZR OR-ed to the intermediate 4 bits becomes the content of its source register, being effectively activated.

The content of data counter after the execution of instruction is as follows, if it is not modified by index instructions:



< Modifiable Index Instruction >

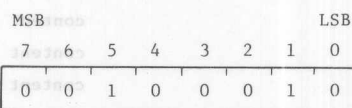
S, M

(26) LRL (Load ROM Lower data) : Load ROM Lower Data Instruction

< Symbol Instruction >

LRL

< Machine Code >



< Function >

(AC) ← ROM_L [(DC)]

< Status Flag >

(F) : No change

(C) : No change

< Execution Cycle >

2 Machine cycle

< Explanation of Function >

This instruction loads the accumulator with the lower order 4 bits of the content of ROM address designated by the content of data counter.

< Modifiable Index Instruction >

D, M

(27) RLH (Load ROM Higher data) : Load ROM Higher Data Instruction

< Symbol Instruction >

LRH

< Machine Code >

MSB

LSB

7	6	5	4	3	2	1	0
0	0	1	1	0	0	1	0

< Function >

(AC) ← ROM_H [(DC)]

(DC) ← (DC) + 1

< Status Flag >

(F) : No change

(C) : No change

< Execution Cycle >

2 Machine cycle

< Explanation of Function >

This instruction loads the accumulator with the higher order 4 bits of the content of ROM address designated by the content of data counter; after-ward, the content of data counter is increased by one.

< Modifiable Index Instruction >

D, M

6. Subroutine Instructions

When subroutine call and interrupt operation are performed, the value of PC should be stored in a stack in order to keep return address. Four levels of PC stacks are provided for the interrupt operation and the subroutine call, enabling four-level nesting to be performed. The 4th stack serves for data counter DC; therefore, when data counter is in use, the operation of nesting should be restricted to three levels. Otherwise, the content of data counter is destroyed, resulting in the deletion of the return address. When the four-level nesting is in operation, no interrupt operation is performed. Also, no storage of PC by call subroutine instruction is performed.

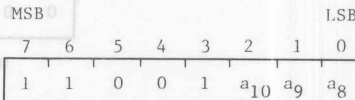
(28) CAL (Call subroutine) : Call Instruction (2 Bytes)

< Symbol Instruction >

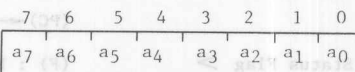
CAL a ($0 \leq a \leq 2047$)

< Machine Code >

1st Byte



2nd Byte



Operand $a = a_{10}a_9a_8a_7a_6a_5a_4a_3a_2a_1a_0$

< Function >

(PC) \rightarrow (STK) push down

(PC) $\leftarrow a$

< Status Flag >

(F) : No change

(C) : No change

< Execution Cycle >

2 Machine cycle

< Explanation of Function >

This is a subroutine call instruction which directly indicates the entry address of subroutine.

The return address is put into a stack,
and the designated value (the entry address
of subroutine) $a=a10a9a8a7a6a5a4a3a2a1a0$ is
set to PC.

The stack of return address is a push down
stack which can be stacked up to 4 levels.
Since the fourth level is a data counter,
precautions for use should be taken.

< Modifiable Index
Instruction >

No instruction

②9 CLS (Call Subroutine by single byte) : Call by Single Byte

Instruction

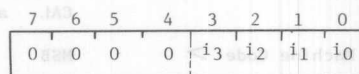
< Symbol Instruction >

CLS i ($0 \leq i \leq 15$)

< Machine Code >

MSB

LSB



Operand $i=i_3i_2i_1i_0$

< Function >

(PC) \rightarrow (STK) push down

(PC) $\leftarrow i \times 8 + 4$

< Status Flag >

(F) : No change

(C) : No change

< Execution Cycle >

1 Machine cycle

< Explanation of
Function >

This instruction stores a return ad-
dress into a stack, calculates $(=000$
 $i_3i_2i_1i_0100) i \times 8 + 4$ as subroutine
entry address from the entry address
No. i designated to the operand, and
sets the result to PC.

The stack of return address is of
push-down stack which can stack as
high as 4 levels.

Since the fourth level is a data counter, precautions for use should be taken.

< Modifiable Index Instruction >

No instruction

③① RTN (Return) : Return Instruction

< Symbol Instruction >

RTN

< Machine Code >

MSB

LSB

7	6	5	4	3	2	1	0
0	0	1	0	0	1	1	1

< Function >

(PC) ← (STK) last in data

< Status Flag >

(F) : No change

(C) : No change

< Execution Cycle >

1 Machine cycle

< Explanation of Function >

This instruction causes a return from an interrupt routine and a subroutine to the main program. The newest return address stored in the stack is loaded into the program counter.

< Modifiable Index Instruction >

No instruction

7 Branch Instruction

Among the branch instructions, there is an on-condition-set/cleared branch instruction of which condition is decided whether or not branch operation is performed depending upon the value of F flag in the program status register; therefore, it should be considered how the value of F flag is changed by the data processing instruction just before the use of the conditional branch instruction. BRC is limited in branch range, but this instruction can reduce the number of bytes of ROM because of a single byte instruction.

The unconditional jump instruction shifts unconditionally the execution flow of the instruction to the address indicated by the address field of this instruction.

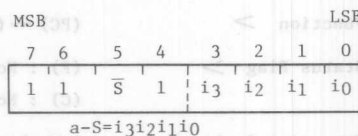
(31) BRC (ranch on Condition set) : Branch on (F) = 1 Forward Instruction

(32) BRC (Branch on Condition set) : Branch on (F) = 1 Backward Instruction

< Symbol Instruction >

BRC a $0 \leq a \leq 2047$,
($-16 \leq a - \$ \leq 15$)

< Machine Code >



$a - \$ \geq 0$, $\bar{S} = 1$... Branch on (F)=1 Forward Instruction

$a - \$ \leq 0$, $\bar{S} = 0$... Branch on (F)=1 Backward Instruction

< Function >

if (F)=1 then (PC) ← a, else No operation ((PC) ← (PC) + 1)

< Status Flag >

(F) : No change
(C) : No change

< Execution Cycle >

1 Machine cycle

< Explanation of Function >

If F flag of status flag is set to "1", the value of program counter is changed to the absolute address "a" defined by the operand field of the instruction. In the other cases, the program counter advances by one and execution of the next instruction will be initiated without any other operations.

The range of absolute address "a" is
-16 - 15 against ROM address "\$" stored
by this instruction itself.

< Modifiable Index > No instruction
< Instruction >

③③ JCS (Jump on Condition Set) : Jump on(F)= 1 Instruction

< Symbol Instruction >

JCS a ($0 \leq a \leq 2047$)

< Machine Code >

MSB LSB

1st Byte

7	6	5	4	3	2	1	0
1	1	1	0	0	a ₁₀	a ₉	a ₈

2nd Byte

7	6	5	4	3	2	1	0
a ₇	a ₆	a ₅	a ₄	a ₃	a ₂	a ₁	a ₀

Operand a=a₁₀a₉a₈a₇a₆a₅a₄a₃a₂a₁a₀

< Function >

if (F)=1 then (PC)←a, else No Operation

< Status Flag >

(F) : No change

(C) : No change

< Execution Cycle >

2 Machine cycle

< Explanation of
Function >

If F flag is set to "1", this instruction
causes to branch to the address "a"
indicated by the lower order 11 bits of
this instruction. In the other cases,
execution of the next instruction with
be initiated without any other operations.

< Modifiable Index >
< Instruction >

No instruction

③④ JCC (Jump on Condition Cleared) : Jump on (F)=0 Instruction

< Symbol Instruction >

JCC a ($0 \leq a \leq 2047$)



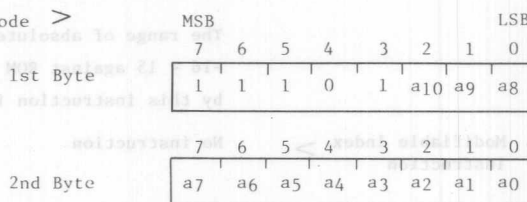
INTEGRATEDCIRCUIT

TECHNICAL DATA

TMP4310AP TMP4315BP
TMP4320AP TMP4300C



< Machine Code >



2nd Byte

Operand a=a₁₀ a₉ a₈ a₇ a₆ a₅ a₄ a₃ a₂ a₁ a₀

< Function >

if (F)=0 then (PC)←a, else No Operation

< Status Flag >

(F) : No change

(C) : No change

< Execution Cycle >

2 Machine cycle

< Explanation of Function >

If F flag is cleared to "0", this instruction causes to branch to the address "a" indicated by the lower order 11 bits of the instruction. In the other cases, execution of the next instruction will be initiated without any other operations.

< Modifiable Index Instruction >

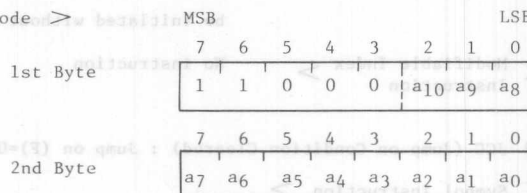
No instruction

③5 JMP (Jump) : Unconditional Jump Instruction

< Symbol Instruction >

JMP a (0 ≤ a ≤ 2047)

< Machine Code >



1st Byte

2nd Byte

Operand a=a₁₀ a₉ a₈ a₇ a₆ a₅ a₄ a₃ a₂ a₁ a₀

< Function >

(PC) ← a

< Status Flag >

(F) : No change

(C) : No change

< Executio Cycle >

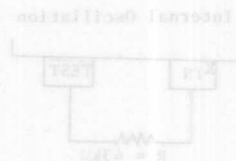
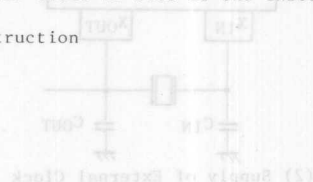
2 Machine cycle

< Explanation of Function >

This instrucion causes an unconditional branch to the address "a" indicated by the lower order 11 bits of the instruction.

< Modifiable Index Instruction >

No instruction



2. Initialize operation

The initialize operation of TMS-43 is performed by placing RST (reset) at the low level as shown below. The minimum time period of four basic clock cycle is required for the low level pulse width.

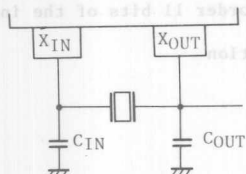


[OPERATION DESCRIPTION]

1. Basic Clock

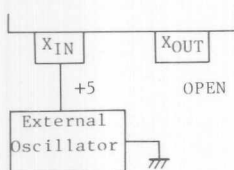
The basic clock generates the basic timing sequences required for the operations of TLCS-43. There are the following methods of options generating the basic clock.

(1) Direct Connection of the Oscillator



When a crystal oscillator, or a ceramic oscillator, or a IFT, is connected as shown at the left, the frequency of TLCS-43 basic clock is equal to that of the oscillator. (Except TMP4310AP)

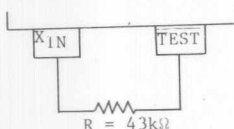
(2) Supply of External Clock



The basic clock of TLCS-43 can also be supplied by an external oscillator circuit as shown at the left.

The external clock input should be sinusoidal or square wave vibrating with levels between 0 volts and 5 volts.

(3) Internal Oscillation



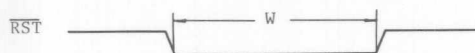
The basic clock of TMP4310AP can be obtained by connecting the resistance as shown in the left figure.

(fosc = 250kHz - 450 kHz at R=43kΩ)

(Except TMP4315BP, TMP4320AP, TMP4300C)

2. Initialize Operation

The initialize operation of TLCS-43 is performed by placing $\overline{\text{RST}}$ terminal at the low level as shown below. The minimum time period of four basic clock cycle is required for the low level pulse width.





INTEGRATED CIRCUIT

TECHNICAL DATA

TMP4310AP TMP4315BP
TMP4320AP TMP4300C



$0 \leq W < 1.5$ cycles	$1.5 \text{ cycles} \leq W < 4$ cycles	$4 \text{ cycles} \leq W$
The initialize operation is not performed.	Whether or not the initialize operation is not definite.	The initialize operation is performed.

One cycle is equal to one cycle of the basic clock.

The initialize operation performs the following functions.

Block	Symbol	Initialize Function
Program counter	PC	Cleared to "0"
Interrupt latch	IL	Cleared
Interrupt flag	IM	Cleared to "0" disabling interrupt.
Output port	OT0	All bits are set to "1".
	OT1	All bits are set to "1".
	OT2	All bits are set to "1".
	OT3	All bits are set to "1".
Input/Output port	IO0	All output bits are set to "1".
	IO1	All output bits are set to "1".
	IO2	All output bits are set to "1".
Stack	STK	Made empty.

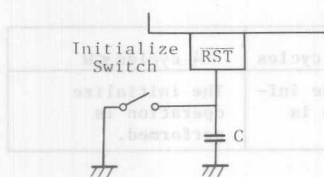
While $\overline{\text{RST}}$ terminal is held at the low level, only the above functions are taken place and other operations, such as execution of program are not performed.

When $\overline{\text{RST}}$ terminal is returned to the high level, the program starting from address 0 is executed.

(Note) C, F and G of the status register are not reset.

Therefore, these must be taken care of by the program.

And any index instructions executed prior to the initialization are ignored.



If a capacitor is connected to $\overline{\text{RST}}$ terminal as shown at the left, the initialize operation is automatically performed when the power supply is turned on. And if it is required to perform the initialize operation manually, a switch should be connected for this purpose.

3. Interrupt Operation

(1) Interrupt Operation

TLCS-43 has the function which allows the interrupt operation to be triggered externally. The interrupt operation is performed by holding $\overline{\text{INT}}$ terminal at the low level for four basic clock cycles or more. However, several conditions must be satisfied to initiate the interrupt operation. Such conditions are as follows.

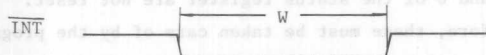
1. Interrupt flag IM has been set and one or more instructions have been executed after the flag was set.
2. Four levels of subroutine nesting have not been performed.

The interrupt request signal from outside is retained in interrupt latch IL located inside and once an interrupt is accepted, IL and interrupt flag IM are cleared.

If it is desired to trigger an interrupt again, $\overline{\text{INT}}$ terminal must be returned to the high level (for two basic clock cycles or more) and must be placed at the low level again. Repetitive interrupts are not accepted keeping $\overline{\text{INT}}$ terminal at the low level.

Setting and repetitive setting of IL by $\overline{\text{INT}}$ signal are performed in the following timings.

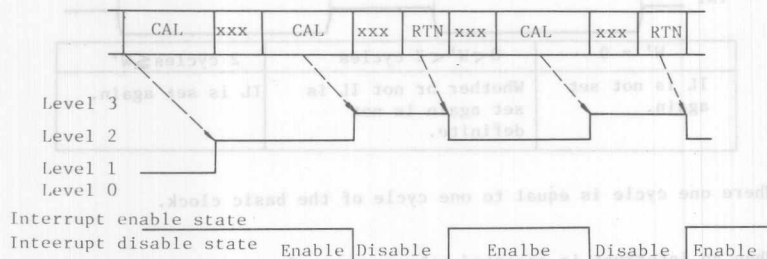
(Setting Timing of IL).



$0 \leq W < 1$ cycle	$1 \text{ cycle} \leq W < 4 \text{ cycles}$	$4 \text{ cycles} \leq W$
IL is not set.	Whether or not IL is set is not definite.	IL is set.

② When stack is used up to the deepest level (level 3)

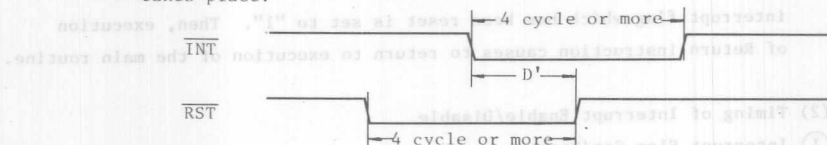
(Assumption: IM flag is set "1" constantly)



Even if IL and IM have been set, if the stack is occupied fully up to the deepest level (level 3), any interrupt are not accepted and must wait until level 3 becomes available.

(3) Relationship between INT Signal and RST Signal

When the interrupt request signal and the initialize signal occur simultaneously, the operation shown in the following examples takes place.



$D' < 1$ cycle The interrupt request is accepted after the initialize operation.

$1 \text{ cycle} \leq D' < 5 \text{ cycles}$... Acceptance of the interrupt request is not definite after the initialize operation.

$D' \geq 5 \text{ cycles}$ Only the initialize operation performed and the interrupt request is not accepted.

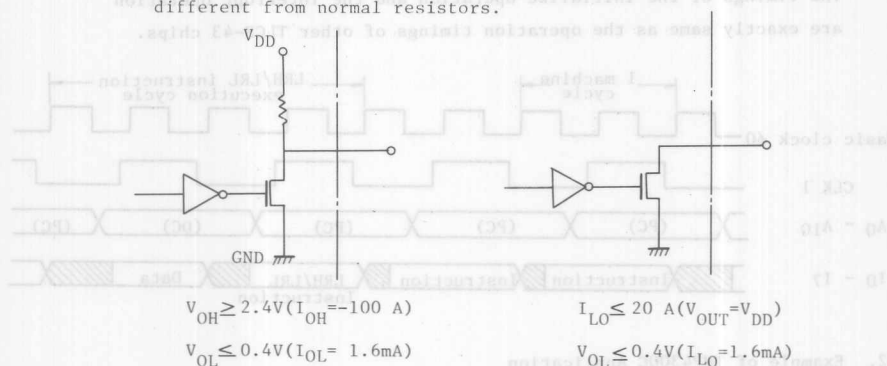
Where one cycle is equal to one cycle of the basic clock.

4. Types of Output Buffers

For the output buffers of output ports and input/output ports, the following types (A) or (B) can be specified by designating a mask option. Since these types are selected by the same mask as the user program mask, these must be specified based on the mask ROM data type format. (Refer to the mask ROM data tape format.)

When data is input from the input/output ports, the output data must have been set to "1" in advance for both (A) and (B) types.

For the electrical characteristics, refer to the paragraphs of ABSOLUTE MAXIMUM RATINGS and DC CHARACTERISTICS. Since the pull-up resistors are provided by MOS transistors, the characteristics are somewhat different from normal resistors.



(A) With Pull-up Resistance

(B) Open Drain

Since all the bits of TMP4300C output ports and input/output ports are the open drain type, the mask option can not be specified.

5. Pull-up Resistors of \overline{RST} Terminal and \overline{INT} Terminal

All versions of TLCS-43 are provided with the pull-up quasi resistors (typical value of 100k ohms) fabricated with MOS transistors for \overline{RST} and \overline{INT} terminals. The guaranteed value of general electrical characteristics of these resistors are $I_{IL2} \text{ MAX.} = -0.1 \text{ mA} (V_{IN} = 0.6V)$. (Refer to DC CHARACTERISTICS.)



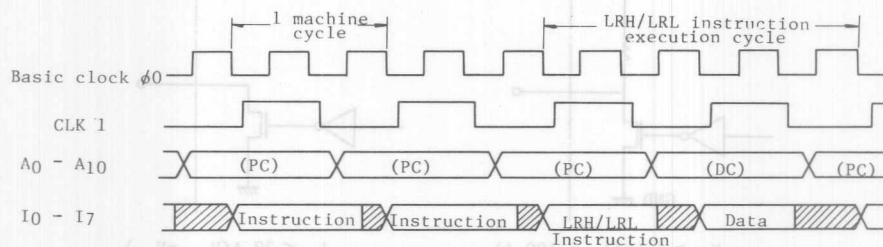
[EVALUATOR CHIP DESCRIPTION]

TMP4300C is the evaluator chip which is used for development of the application systems (or programs) for TLCS-43. For these purposes, some terminals and functions have been added to TMP4300C in addition to those of other TLCS-43 chips.

The terminals and the functions dedicated to TLCS-43 development tool (TDS400/43) are also provided, and refer to the operation manual of TDS400/43 for details.

1. Operation Timing

The normal operation timing of TMP4300C is shown in the figure below. The timings of the initialize operation and the interrupt operation are exactly same as the operation timings of other TLCS-43 chips.



2. Example of TMP4300C Application

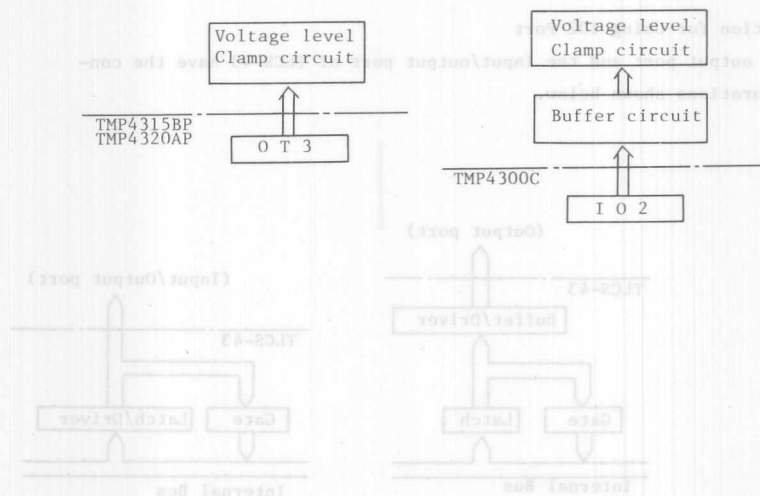
The diagram below illustrates an example of connection with an EPROM, which allows the program confirmation before confirming program to ROM.

* TMM323C is 2716 type EPROM with 16K bits (2,048 words x 8 bits)

Therefore, when a circuit which clamps the output voltage level is directly connected externally to the terminal, and the output data is referenced by the program, it can be correctly read for the output port. However for the input/output ports there is possibility of reading erroneous data if the input voltage level is not secured by the clamp circuit. In order to read the data correctly, the terminals and the clamp circuits are required to be separated by the buffer circuits.

When a system development is conducted for TMP4315BP and TMP4320AP using TMP4300C, the pairing port for the output port OT3 is the input/output port IO2. Therefore, when it is required for a program to reference output data in OT3 port in a system using TMP4315BP or TMP4320AP, care should be taken not to directly connect a circuit which clamps the output level to IO2 port, during the evaluation stage using TMP4300C.

(Circuit of Actual Application) (Circuit of Evaluation Stage)





INTEGRATED CIRCUIT

TECHNICAL DATA

TMP4310AP TMP4315BP
TMP4320AP TMP4300C



TMP4310AP ELECTRICAL CHARACTERISTICS

ABSOLUTE MAXIMUM RATINGS

Symbol	Item	Rating
V _{DD}	V _{DD} Supply Voltage	-0.5V to 7V
V _{DD}	Input Voltage	-0.5 V to 7V
V _{OUT1}	Output Voltage (Except Open Drain Pins)	-0.5V to 7V
V _{OUT2}	Output Voltage (Open Drain Pins)	-0.5V to 10V
I _{OUT1}	Average Output Current (Except OT1)	4mA
I _{OUT2}	Output Current (OT1)	30mA
P _D	Power Dissipation (TA=70°C)	700mW
T _{SOLDER}	Soldering Temperature (Soldering Time 10sec)	260°C
T _{STG}	Storage Temperature	-55°C to 125°C
T _{OPR}	Operating Temperature	-10°C to 70°C

DC CHARACTERISTICS

T_A = -10°C to 70°C, V_{DD} = 5V ± 10 %, Unless Otherwise Noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V _{IH1}	Input High Voltage (I _{NO} , I ₀₀ , I ₀₁ , I ₀₂ , RST)		2.2		V _{DD}	V
V _{IH2}	Input High Voltage (INT)		3.5		V _{DD}	V
V _{IL}	Input Low Voltage		0		0.1	V
V _{CH}	Clock Input High Voltage (X _{IN})	External Drive	3.8		V _{DD}	V
V _{CL}	Clock Input Low Voltage (X _{IN})	External Drive	0		0.6	V
I _{IN1}	Input Current (I _{NO})	V _{IN} = V _{DD}			20	μA
I _{IN2}	Input Current (I ₀₀ , I ₀₁ , I ₀₂)	Open Drain			20	μA
		Pull Up			-	-
I _{IL1}	Input Low Current (I ₀₀ , I ₀₁ , I ₀₂)	Open Drain			-	-
		Pull Up	V _{IN} = 0.6V		-1.6	mA

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unch
I_{IL2}	Input Low Current (RST, INT)	$V_{IN}=0.6V$			-0.1	mA
I_{LO}	Output Load Current (OTO, OTI)	Open Drain	$V_{OUT}=V_{DD}$		20	μA
		Pull Up			-	-
V_{OH}	Output High Voltage	Open Drain			-	-
		Pull Up	$I_{OH}=-100\mu A$	2.4		V
V_{OL}	Output Low Voltage (Note)	$I_{OL}=1.6mA$			0.4	V
I_{DD}	V_{DD} Supply Current			40	80	mA

Note: Output port OTI can sink large current. (I_{OL} TYP.=20mA, $V_{OL}=2.0V$)

While sinking large current, the output low voltage (V_{OL}) limit is the following value.

V_{OL} Max.=0.5V ($I_{OL}=1.6mA$)

AC CHARACTERISTICS

Refer to TIMING WAVEFORMS (1).

$T_A=-10^{\circ}C$ to $70^{\circ}C$, $V_{DD}=5V \pm 10\%$, Unless Otherwise Noted.

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
$t_{\phi 0}$	Clock Cycle Time		2		5	μs
t_s	Input Set up Time		0.9			μs
t_H	Input Hold Time		0.9			μs
t_D	Output Delay Time	$C_L=50PF, R(Pull-up)=50k, 1TTL$			1.8	μs
t_{INT}	INT Low Level Pulse Width		4			Clock Cycle
t_{RST}	RST Low Level Pulse Width		4			Clock Cycle
fOSC	Internal Oscillation Frequency	$R=43k$	250		450	kHz



INTEGRATED CIRCUIT

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TECHNICAL DATA

INTEGRATED CIRCUIT
TMP4310AP TMP4315BP
TMP4320AP TMP4300C



TMP4315BP ELECTRICAL CHARACTERISTICS

ABSOLUTE MAXIMUM RATINGS

Symbol	Item	Rating
V_{DD}	V_{DD} Supply Voltage	-0.5V to 7V
V_{IN}	Input Voltage	-0.5V to 7V
V_{OUT1}	Output Voltage (Except Open Drain Pins)	-0.5V to 7V
V_{OUT2}	Output Voltage (Open Drain Pins)	-0.5V to 10V
I_{OUT1}	Average Output Current	4mA
P_D	Power Dissipation ($T_A=70^\circ\text{C}$)	700mW
T_{SOLDER}	Soldering Temperature (Soldering Time, 10sec.)	260°C
T_{STG}	Storage Temperature	-55°C to 125°C
T_{OPR}	Operating Temperature	-10°C to 70°C

DC CHARACTERISTICS

$T_A=-10^\circ\text{C}$ to 70°C , $V_{DD}=5V \pm 10\%$, Unless Otherwise Noted.

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
V_{IH1}	Input High Voltage ($I_{NO}, I_{N1}, I_{N2}, I_{O0}, I_{O1}, RST$)		2.2		V_{DD}	V
V_{IH2}	Input High Voltage (\overline{INT})		3.5		V_{DD}	V
V_{IL}	Input Low Voltage		0		0.6	V
V_{CH}	Clock Input High Voltage (X_{IN})	External Drive	3.8		V_{DD}	V
V_{CL}	Clock Input Low Voltage (X_{IN})	External Drive	0		0.6	V
I_{IN1}	Input Current (I_{NO}, I_{N1}, I_{N2})	$V_{IN}=V_{DD}$			20	μA
I_{IN2}	Input Current (I_{O0}, I_{O1})	Open Drain			20	μA
		Pull up			-	-
I_{IL1}	Input Low Current (I_{O0}, I_{O1})	Open Drain			-	-
		Pull Up	$V_{IN}=0.6V$		-1.6	mA
I_{IL2}	Input Low Current (RST, \overline{INT})	$V_{IN}=0.6V$			-0.1	mA
I_{LO}	Output Lead Current ($O_{TO}, O_{T1}, O_{T2}, O_{T3}$)	Open Drain			20	μA
		Pull Up			-	-
V_{OH}	Output High Voltage (Except X_{OUT})	Open Drain			-	-
		Pull Up	$I_{OH}=-100\mu\text{A}$	2.4		V
V_{OL}	Low Output Voltage (Except X_{OUT})	$I_{OL}=1.6\text{mA}$			0.4	V
I_{DD}	V_{DD} Supply Current			40	80	mA



INTEGRATED CIRCUIT

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TECHNICAL DATA

TMP4310AP

TMP4315BP

TMP4320AP

TMP4300C



AC CHARACTERISTICS

Refer to TIMING WAVEFORMS (1).

$T_A = -10^\circ\text{C}$ to 70°C , $V_{DD} = 5\text{V} \pm 10\%$, Unless Otherwise Noted.

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
$t_{\phi 0}$	Clock Cycle Time		2		5	μs
t_S	Input Set up Time		0.9			μs
t_H	Input Hold Time		0.9			μs
t_D	Output Delay Time	$C_L = 50\text{PF}$, $R(\text{Pull up}) = 50\text{k}\Omega$, 1TTL			1.8	μs
t_{INT}	INT Low Level Pulse Width		4			Clock Cycle
t_{RST}	RST Low Level Pulse Width		4			Clock Cycle

DC CHARACTERISTICS

$T_A = -10^\circ\text{C}$ to 70°C , $V_{DD} = 5\text{V} \pm 10\%$, Unless Otherwise Noted.

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
V_{IH1}	Input High Voltage (INT, INT1, INT2, INT3, RST)		3.2		V_{DD}	V
V_{IH2}	Input High Voltage (INT)		3.2		V_{DD}	V
V_{IL}	Input Low Voltage		0		0.8	V
V_{CH}	Clock Input High Voltage (X_{IN})	External Drive	3.8		V_{DD}	V
V_{CL}	Clock Input Low Voltage (X_{IN})	External Drive	0		0.8	V
I_{IH1}	Input Current (INT, INT1, INT2)	$V_{IN} = V_{DD}$			20	μA
		$V_{IN} = V_{DD}$			20	μA
I_{IH2}	Input Current (100, 101)	Open Drain			-	-
		Pull up			-	-
I_{IL1}	Input Low Current (100, 101)	Open Drain			-1.6	mA
		Pull up			-0.11	mA
I_{IL2}	Input Low Current (RST, INT)	$V_{IN} = 0.8\text{V}$			-0.11	mA
		$V_{IN} = 0.8\text{V}$			-0.11	mA
I_O	Output Load Current (000, 001, 002, 003)	Open Drain			20	μA
		Pull up			-	-
V_{OH}	Output High Voltage (Except X_{OUT})	Open Drain			-	-
		Pull up			-	-
V_{OL}	Low Output Voltage (Except X_{OUT})	$I_{OL} = 1.5\text{mA}$			0.4	V
		$I_{OL} = 1.5\text{mA}$			0.4	V
I_{DD}	V_{DD} Supply Current	$I_{OH} = -100\mu\text{A}$			2.4	mA
		$I_{OL} = 1.5\text{mA}$			2.4	mA



INTEGRATED CIRCUIT

TECHNICAL DATA

SEMICONDUCTOR

TMP4310AP TMP4315BP
TMP4320AP TMP4300C

TMP4320AP ELECTRICAL CHARACTERISTICS

ABSOLUTE MAXIMUM RATINGS

Symbol	Item	Rating
V _{DD}	V _{DD} Supply Voltage	-0.5V to 7V
V _{IN}	Input Voltage	-0.5V to 7V
V _{OUT1}	Output Voltage (Except Open Drain Pins)	-0.5V to 7V
V _{OUT2}	Output Voltage (Open Drain Pins)	-0.5V to 10V
I _{OUT1}	Average Output Current (Except OT1, OT2)	4mA
I _{OUT2}	Output Current (OT1, OT2)	30mA
P _D	Power Dissipation (TA=70°C)	850mW
T _{SOLDER}	Soldering Temperature (Soldering Time 10sec.)	260°C
T _{STG}	Storage Temperature	-55°C to 125°C
T _{OPR}	Operating Temperature	-10°C to 70°C

DC CHARACTERISTICS

TA=-10°C to 70°C, V_{DD}=5V ± 10 %, Unless Otherwise Noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V _{IH1}	Input High Voltage (INO, IN1, IN2, IO0, IO1, RST)		2.2		V _{DD}	V
V _{IH2}	Input High Voltage (INT)		3.5		V _{DD}	V
V _{IL}	Input Low Voltage		0		0.6	V
V _{CH}	Clock Input High Voltage (X _{IN})	External Drive	3.8		V _{DD}	V
V _{CL}	Clock Input Low Voltage (X _{IN})	External Drive	0		0.6	V
I _{IN1}	Input Current (INO, IN1, IN2)	V _{IN} =V _{DD}			20	μA
I _{IN2}	Input Current (IO0, IO1)	Open Drain			20	μA
		Pull up			-	-
I _{IL1}	Input Low Current (IO0, IO1)	Open Drain			-	-
		Pull Up	V _{IN} =0.6V		-1.6	mA
I _{IL2}	Input Low Current (RST, INT)	V _{IN} =0.6V			-0.1	mA
I _{LO}	Output Lead Current (OTO, OT1, OT2, OT3)	Open Drain			20	μA
		Pull Up			-	-
V _{OH}	Output High Voltage (Except X _{OUT})	Open Drain			-	-
		Pull Up	I _{OH} =-100μA	2.4		V
V _{OL}	Output Low Voltage (Except X _{OUT}) (Note)	I _{OL} =1.6mA			0.4	V
I _{DD}	V _{DD} Supply Current			40	80	mA



SEMICONDUCTOR

TMP4310AP TMP4315BP

TMP4320AP TMP4300C

TECHNICAL DATA

TMP4310AP TMP4315BP

TMP4320AP TMP4300C

TECHNICAL DATA



Note: Output port OT1 and OT2 can sink large current. ($I_{OL.TYP.}=20mA$,
 $V_{OL}=2.0V$)

While sinking large current, the output low voltage (V_{OL}) limit
 is the following value.

$V_{OL} \text{ Max.}=0.5V$ ($I_{OL}=1.6mA$)

AC CHARACTERISTICS

Refer to TIMING WAVEFORMS (1).

$T_A=-10^{\circ}C$ to $70^{\circ}C$, $V_{DD}=5V \pm 10\%$, Unless Otherwise Noted.

SYMBOL	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$t_{\phi 0}$	Clock Cycle Time		2		5	μs
t_s	Input Set up Time		0.9			μs
t_H	Input Hold Time		0.9			μs
t_D	Output Delay Time	$C_L=55pF, R(Pull\ up)=50K\Omega, 1TTL$			1.8	μs
t_{INT}	INT Low Level Pulse Width		4			Clock Cycle
t_{RST}	RST Low Level Pulse Width		4			Clock Cycle



INTEGRATED CIRCUIT

TECHNICAL DATA

TMP4310AP TMP4315BP

TMP4320AP TMP4300C

TECHNICAL DATA



TMP4300C ELECTRICAL CHARACTERISTICS

ABSOLUTE MAXIMUM RATINGS

Symbol	Item	Rating
V _{DD}	V _{DD} Supply Voltage	-0.5V to 7V
V _{IN}	Input Voltage	-0.5V to 7V
V _{OUT1}	Output Voltage (Except Open Drain Pins)	-0.5V to 7V
V _{OUT2}	Output Voltage (Open Drain Pins)	-0.5V to 10V
I _{OUT1}	Average Output Current (Except OT1, OT2)	4mA
I _{OUT2}	Output Current (OT1, OT2)	30mA
P _D	Power Dissipation (TA=70°C)	1W
T _{SOLDER}	Soldering Temperature (Soldering Time 10 sec.)	260°C
T _{STG}	Storage Temperature	-55°C to 125°C
T _{OPR}	Operating Temperature	-10°C to 70°C

DC CHARACTERISTICS

TA=-10°C to 70°C, V_{DD}=5V ± 10 %, Unless Otherwise Noted.

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V _{IH1}	Input High Voltage (Except $\overline{\text{INT}}$, X _{IN}) (Note)		2.2		V _{DD}	V
V _{IH2}	Input High Voltage ($\overline{\text{INT}}$)		3.5		V _{DD}	V
V _{IL}	Input Low Voltage		0		0.6	V
V _{CH}	Clock Input High Voltage (X _{IN})	External Drive	3.8		V _{DD}	V
V _{CL}	Clock Input Low Voltage (X _{IN})	External Drive	0		0.6	V
I _{IN}	Input Current (Except $\overline{\text{RST}}$, $\overline{\text{INT}}$)	V _{IN} =V _{DD}			20	μA
I _{IL2}	Input Low Current ($\overline{\text{RST}}$, $\overline{\text{INT}}$)	V _{IN} =0.6V			-0.1	mA
I _{LO}	Output Load Current (OT0, OT1, OT2)	V _{OUT} =V _{DD}			20	μA
V _{OH}	Output High Voltage (A0-A10, CLK1)	I _{OH} =-100μA	2.4			V
V _{OL}	Output Low Voltage (Except X _{OUT}) (Note)	I _{OL} =1.6mA			0.4	V
I _{DD}	V _{DD} Supply Current			70	120	mA

Note: Output Port OT1 and OT2 can sink large current. (I_{OL} TYP.=20mA, V_{OL}=2.0V) While sinking large current, the Output Low Voltage (V_{OL}) limit and the Input High Voltage (V_{IH1}) limit are the following values.

V_{OL} Max.=0.5V to 0.6V (I_{OL}=1.6mA)V_{IH1} Min.=2.3V to 2.4V

TOSHIBA CORPORATION

AC CHARACTERISTICS

Refer to TIMING WAVEFORMS (1) (2).

 $T_A = -10^\circ\text{C}$ to 70°C , $V_{DD} = 5\text{V} \pm 10\%$, Unless Otherwise Noted.

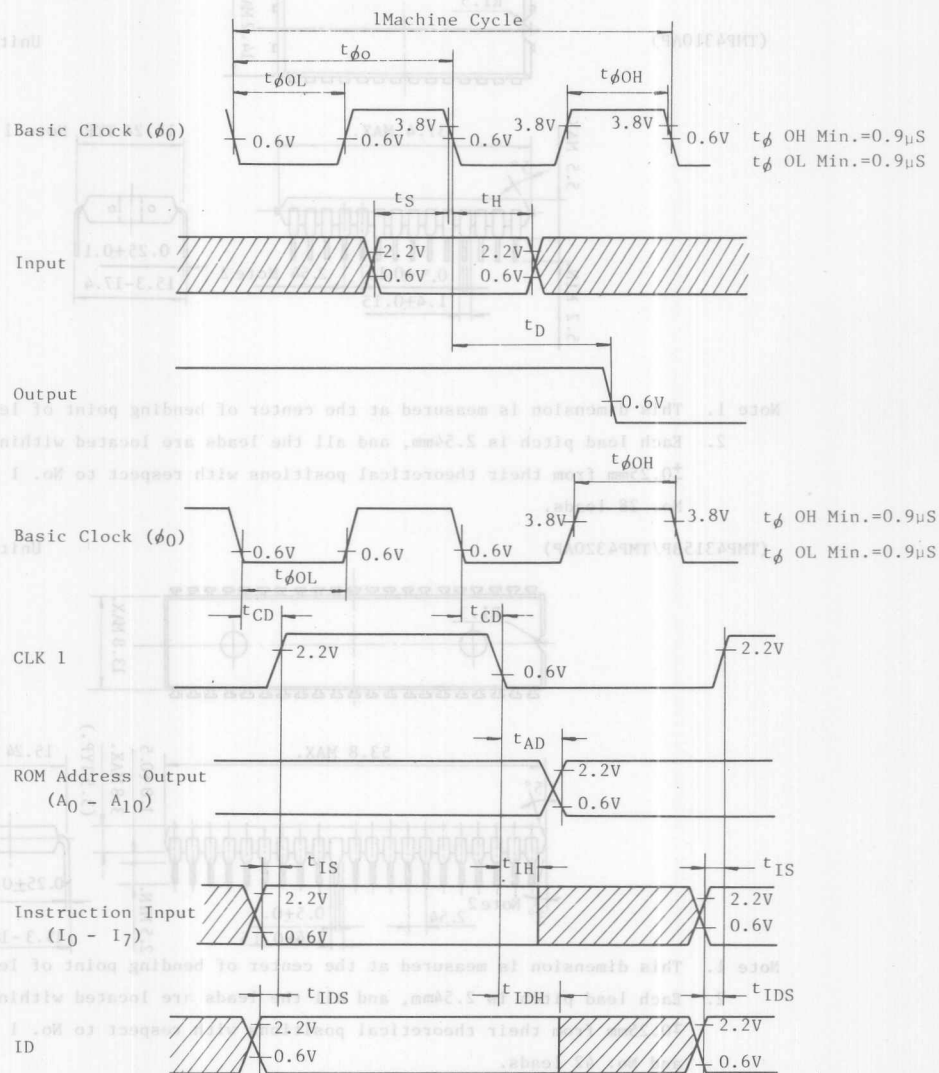
Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units.
$t_{\phi 0}$	Clock Cycle Time		2		5	μs
t_s	Input Set up Time		0.9			μs
t_H	Input Hold Time		0.9			μs
t_D	Output Delay Time	$C_L = 50\text{PF}$, $R(\text{Pull up}) = 50\text{k}\Omega$, 1 TTL			1.8	μs
t_{INT}	INT Low Level Pulse Width		4			Clock Cycle
t_{RST}	RST Low Level Pulse Width		4			Clock Cycle
t_{CD}	Clock Output Delay Time	$C_L = 50\text{PF}$, 1 TIL			0.4	μs
t_{AD}	Address Output Delay Time	$C_L = 50\text{PF}$, 1 TIL			0.95	μs
t_{IS}	Instruction Input Set up Time		0.4			μs
t_{IH}	Instruction Input Hold Time		0			μs
t_{IDS}	ID Input Set up Time		0.4			μs
t_{IDH}	ID Input Hold Time		0.95			μs

V_{CC}	Clock Input Low Voltage (X_{IN})	0
I_{IN}	Input Current (Except RST, INT)	$V_{IN} = V_{DD}$
I_{INT}	Input Low Current (RST, INT)	$V_{IN} = 0.5\text{V}$
I_{IO}	Output Load Current (Q0, Q1, Q2)	$V_{OUT} = V_{DD}$
V_{OH}	Output High Voltage ($V_{OH} = A10, CLK1$)	$I_{OH} = -100\mu\text{A}$
V_{OL}	Output Low Voltage (Except Q0Q1) (Note)	$I_{OL} = 1.0\text{mA}$
I_{DD}	V_{DD} Supply Current	$V_{IN} = 0.5\text{V}$

Note: Output Port Q0 and Q1 can sink large current. (100 TYP. $\sim 50\text{mA}$, $V_{OH} = 3.0\text{V}$) While sinking large current, the Output Low Voltage (V_{OL}) limit and the Input High Voltage (V_{IH}) limit are the following values.

$V_{OH} \text{ Max.} = 0.3\text{V}$ to 0.5V ($I_{OH} = 1.0\text{mA}$)
 $V_{OL} \text{ Min.} = 0.3\text{V}$ to 0.5V

TIMING WAVEFORMS





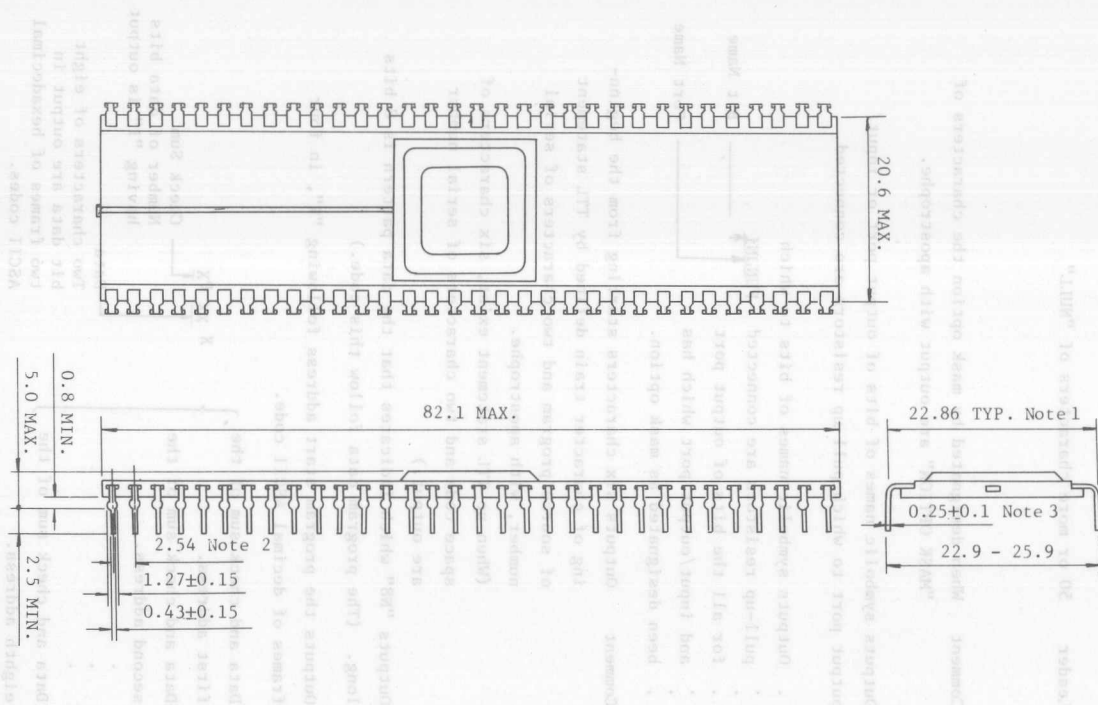
INTEGRATED CIRCUIT

TECHNICAL DATA

(TMP4300C)

TMP4310AP
TMP4315BP
TMP4320AP
TMP4300C

Unit in mm



- Note 1. This dimension is measured at the center of bending point of leads.
- Note 2. Each lead pitch is 2.54mm, and all the leads are located within ±0.25mm from their theoretical positions with respect to No. 1 and No. 64 leads.
- Note 3. The metal on the side of the package is GND Level.

MASK ROM DATA TAPE FORMAT

.	-----	Leader	50 or more characters of "NULL."
'COMMENT'	-----	Comment	When designated by mask option the characters of "MASK OPTION" are output with apostrophe.
(CR) (LF)			
(PUNNNi)	-----	Outputs symbolic names of bits of output port or input/output port to which pull-up resistors are connected.	
(CR) (LF)			
.	.	Outputs symbolic names of bits to which	
.	.	pull-up resistors are connected	PUNNNi Bit Name
.	.	for all the bits of output port	
.	.	and input/output port which has	Port Name
.	.	been designated as mask option.	
'COMMENT'	-----	Comment	Outputs six characters starting from the beginning of character train defined by TTL statement of source program and two characters of serial number, with apostrophe. (When no TTL statement exist, six characters of space code and two characters of serial number are output.)
N8;	-----	Outputs "N8" which indicates that the data pattern is 8 bits long. (The program data follow this code.)	
(CR) (LF)			
RXXXX ;	-----	Outputs the program start address following "R", in four frames of decimal ASCII code.	
x xx Px;	-----	Data and check sum of the first address.	
X XX Px;	-----	Data and check sum of the second address.	
.	.	.	
.	.	.	
X XX Px;	-----	Data and check sum of the eighth address.	Two characters of eight bit data are output in two frames of hexadecimal ASCII codes.
(CR) (LF)			



INTEGRATEDCIRCUIT

TECHNICAL DATA

INTEGRATEDCIRCUIT

TMP4310AP TMP4315BP
TMP4320AP TMP4300C



R XXXX ; ----- Ninth program address.

X XX PX; ----- Data and check sum of the ninth address

Outputs repetitively through the last data.

(CR) (LF)

\$ ----- Outputs symbol "\$" to indicate the end of program data.

Trailer 50 or more characters of "NULL".

Internal oscillation (with resistance externally installed between pin and

TEST) and external clock supply can be available.

1.1 Frequency of external supply clock
1-30MHz to 40MHz (APL) ($V_{DD}=2.5V \pm 30\%$, $T_{op}=0^{\circ}C$ to $55^{\circ}C$)

1-30MHz to 200MHz (APLL)

1.2 Internal oscillation frequency

1-30MHz to 40MHz (APL, RX=36K) ($V_{DD}=2.5V \pm 30\%$, $T_{op}=0^{\circ}C$ to $55^{\circ}C$)

1-11MHz to 200MHz (APLL, RX=110K)

1. Low input voltage and clock low input voltage (at time of external supply)

$V_{IL\ MAX}=V_{CC\ MAX}=0.55V$ ($V_{DD}=2.5V \pm 30\%$, $T_{op}=0^{\circ}C$ to $55^{\circ}C$)

2. High output voltage

$V_{OH\ MIN}=2.4V$ ($V_{DD}=2.5V \pm 30\%$, $T_{op}=0^{\circ}C$ to $55^{\circ}C$, $I_{OH}=20\mu A$)

4. Supply current

$I_{DD\ ITP}=30\mu A$, $I_{DD\ MAX}=45\mu A$ (APL) ($V_{DD}=6.0V$, $T_{op}=55^{\circ}C$)

$I_{DD\ ITP}=15\mu A$, $I_{DD\ MAX}=25\mu A$ (APLL)

2. Pull up resistance of TEST and INT terminals is not contained.

SPECIFICATION OF TMP4310APL/TMP4310APLL

This specification is applied to TMP4310APL/TMP4310APLL, one of versions of TLCS-43.

TMP4310APL/TMP4310APLL is the low power version of TMP4310AP. There are some differences in electrical characteristics between TMP4310APL/TMP4310APLL and TMP4310AP; however, their functions, instructions and pin connections are compatible. When using and examining TMP4310APL/TMP4310APLL, therefore, it is recommended that this specification be used together with the technical data on TMP4310AP.

Main differences in electrical characteristics between AP and APL/APLL are as follows:

1. Basic clock

Internal oscillation (with resistance externally installed between X_{IN} and \overline{TEST}) and external clock supply can be available.

1.1 Frequency of external supply clock

$f=200\text{kHz}$ to 400kHz (APL) ($V_{DD}=5.5V \pm 20\%$, $T_{opr}=0^\circ\text{C}$ to 55°C)

$f=50\text{kHz}$ to 200kHz (APLL)

1.2 Internal oscillation frequency

$f=200\text{kHz}$ to 400kHz (APL, $R_X=56\text{k}\Omega$) ($V_{DD}=5.5V \pm 20\%$, $T_{opr}=0^\circ\text{C}$ to 55°C)

$f=110\text{kHz}$ to 200kHz (APLL, $R_X=110\text{k}\Omega$)

2. Low input voltage and clock low input voltage (at time of external supply)

$V_{IL\text{ MAX.}}=V_{CL\text{ MAX.}}=0.55V$ ($V_{DD}=5.5V \pm 20\%$, $T_{opr}=0^\circ\text{C}$ to 55°C)

3. High output voltage

$V_{OH\text{ MIN.}}=2.4V$ ($V_{DD}=5.5V \pm 20\%$, $T_{opr}=0^\circ\text{C}$ to 55°C , $I_{OH}=-50\mu\text{A}$)

4. Supply current

$I_{DD\text{ TYP.}}=30\text{mA}$, $I_{DD\text{ MAX.}}=45\text{mA}$ (APL) ($V_{DD}=6.0V$, $T_{opr}=25^\circ\text{C}$)

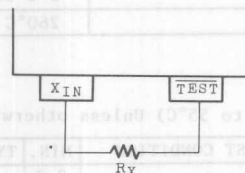
$I_{DD\text{ TYP.}}=15\text{mA}$, $I_{DD\text{ MAX.}}=27\text{mA}$ (APLL)

5. Pull up resistance of \overline{RST} and \overline{INT} terminals is not contained.

TMP4310APL/TMP4310APLL BASIC CLOCK

The methods of generating and supplying the basic clock of TMP4310APL/TMP4310APLL are as follows:

(1) Internal oscillation

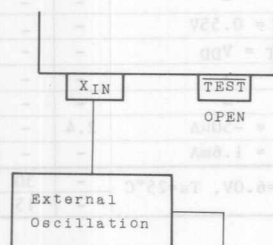


The basic clock of TMP4310APL/TMP4310APLL can be obtained by connecting the resistance as shown in the left figure.

($f_{osc}=200\text{kHz}$ to 400kHz at $R_X=56\text{k}\Omega$, APL)

($f_{osc}=110\text{kHz}$ to 200kHz at $R_X=110\text{k}\Omega$, APPL)

(2) Supply of external clock



The basic clock of TMP4310APL/TMP4310APLL can be supplied from the external oscillation circuit as shown in the left figure.

TMP4310APL/TMP4310APLL ELECTRICAL CHARACTERISTICS

ABSOLUTE MAXIMUM RATING

SYMBOL	I T E M	RATING
V _{DD}	Supply Voltage	-0.5V to 7V
V _{IN}	Input Voltage	-0.5V to 7V
V _{OUT1}	Output Voltage (Except open drain terminal)	-0.5V to 7V
V _{OUT2}	Output Voltage (Open drain terminal)	-0.5V to 10V
T _{stg}	Storage Temperature	-55°C to 125°C
T _{opr}	Operating Temperature	0°C to 55°C
T _{sld}	Soldering Temperature	260°C (10sec.)

D.C. CHARACTERISTICS (V_{DD}=5.5V±20%, T_{opr}=0°C to 55°C) Unless otherwise noted.

SYMBOL	PARAMETER		TEST CONDITION	MIN.	TYP.	MAX.	UNIT
V _{IH1}	Input High Voltage	(I _{NO} , I _{IO} , I _{O1} , I _{O2} , R _{ST})	-	2.2	-	V _{DD}	V
V _{IH2}		(I _{NT})	-	3.5	-	V _{DD}	V
V _{IL}	Input Low Voltage		-	0	-	0.55	V
V _{CH}	Clock Input High Voltage (X _{IN})		External clock supply	3.8	-	V _{DD}	V
V _{CL}	Clock Input Low Voltage (X _{IN})			0	-	0.55	V
I _{IN1}	Input Current (I _{NO} , R _{ST} , I _{NT})		V _{IN} = V _{DD}	-	-	20	μA
I _{IN2}	Input Current (I _{IO} , I _{O1} , I _{O2})	Open Drain	V _{IN} = V _{DD}	-	-	20	μA
		Pull Up	-	-	-	-	-
I _{IL1}	Input Low Current (I _{IO} , I _{O1} , I _{O2})	Open Drain	-	-	-	-	-
		Pull Up	V _{IN} = 0.55V	-	-	-1.6	mA
I _{LO}	Output Leak Current (O _{TO} , O _{T1})	Open Drain	V _{OUT} = V _{DD}	-	-	20	μA
		Pull Up	-	-	-	-	-
V _{OH}	Output High Voltage	Open Drain	-	-	-	-	-
		Pull Up	I _{OH} = -50μA	2.4	-	-	V
V _{OL}	Output Low Voltage		I _{OL} = 1.6mA	-	-	0.4	V
I _{DD}	Supply Current	APL	V _{DD} =6.0V, T _a =25°C	-	30	45	mA
		APLL		-	15	27	mA

Pull-Up resistance of R_{ST} and I_{NT} terminals is not contained.

Low output voltage: It is possible that output port OT1 sinks large output current I_{OL} Typ.=20mA (V_{OL}=2V) for each pins. At the time when OT1 sinks large output current, low output voltage (V_{OL}) becomes V_{OL} Max.=0.5V (I_{OL}=1.6mA).



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INTEGRATED CIRCUIT

TECHNICAL DATA

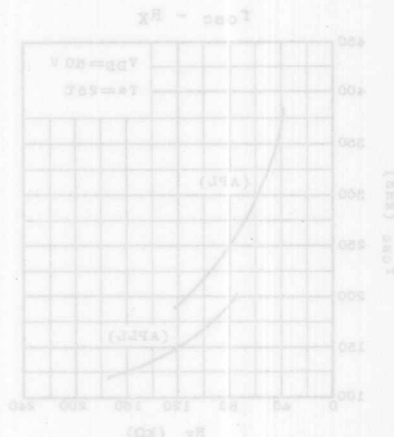
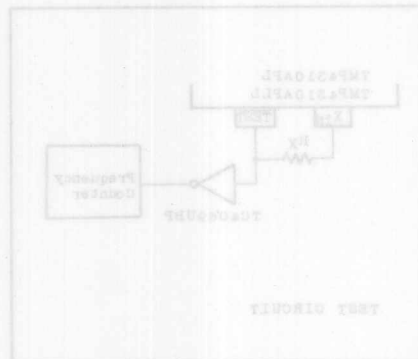
INTEGRATED CIRCUIT
TMP4310APL TMP4310APLL

TECHNICAL DATA

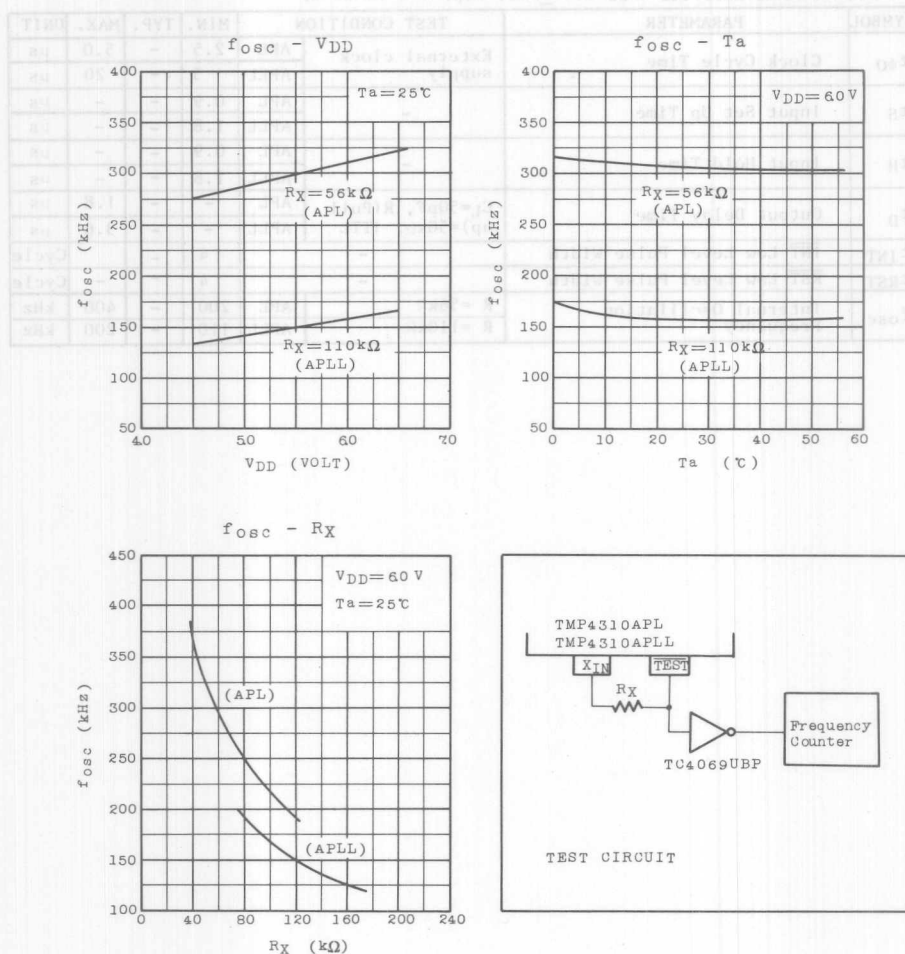


A.C. CHARACTERISTICS (VDD=5.5V±20%, Topr=0°C to 55°C)

SYMBOL	PARAMETER	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
$t_{\phi 0}$	Clock Cycle Time	External clock supply	APL 2.5	-	5.0	μ s
			APLL 5	-	20	μ s
t_S	Input Set Up Time	-	APL 0.9	-	-	μ s
			APLL 1.8	-	-	μ s
t_H	Input Hold Time	-	APL 0.9	-	-	μ s
			APLL 1.8	-	-	μ s
t_D	Output Delay Time	$C_L=50$ pF, R(Pull up)=50k Ω , 1TTL	APL -	-	1.8	μ s
			APLL -	-	3.6	μ s
t_{INT}	INT Low Level Pulse Width	-	4	-	-	Cycle
t_{RST}	RST Low Level Pulse Width	-	4	-	-	Cycle
f_{osc}	Internal Oscillation Frequency	R = 56k Ω	APL 200	-	400	kHz
		R = 110k Ω	APLL 110	-	200	kHz

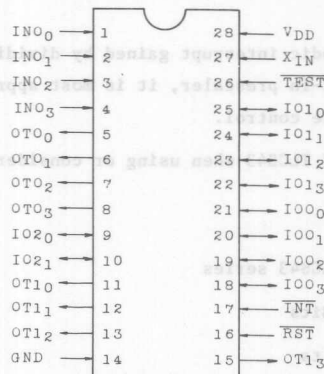


TYPICAL CHARACTERISTICS

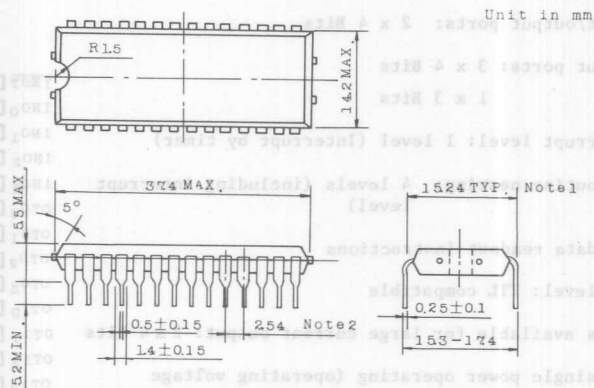


PIN CONNECTIONS

Top View



OUTLINE DRAWINGS



- Note 1. This dimension is measured at the center of bending point of leads.
2. Each lead pitch is 254mm, and all the leads are located within $\pm 0.25\text{mm}$ from their theoretical position with respect to No.1 and No.28 leads.



INTEGRATEDCIRCUIT

TECHNICAL DATA

TMP4321AP

TOSHIBA MOS Digital Integrated Circuit
Silicon Monolithic
N-channel Silicon Gate Depression Load

GENERAL DESCRIPTION

TMP4321AP is one version of single-chip microcomputer TLCS43 series processed with NMOS.

Since TMP4321AP can make periodic interrupt gained by dividing the CPU clock to 512 or 1024 using the built-in prescaler, it is most appropriate for computer control, such as sequence control.

Refer to the technical data of TLCS43 when using or considering TMP4321AP.

FEATURES

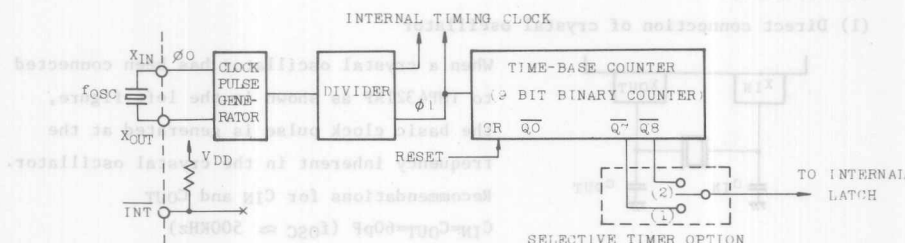
- o Software compatible with TLCS43 series
- o ROM capacity: 2048W x 8 Bits
- o RAM capacity: 128W x 4 Bits
- o Instruction executing rate: 4 μ s
- o Input ports: 3 x 4 Bits
- o Input/output ports: 2 x 4 Bits
1 x 3 Bits
- o Output ports: 3 x 4 Bits
1 x 3 Bits
- o Interrupt level: 1 level (Interrupt by timer)
- o Subroutine nesting: 4 levels (including interrupt level)
- o ROM data readout instructions
- o I/O level: TTL compatible
- o Ports available for large current output: 2 x 4 Bits
- o +5V single power operating (operating voltage margin: 5V \pm 10%)
- o Operating temperature range: -10 \sim 70°C

PIN CONNECTIONS

TEST	1	42	VDD
INO ₀	2	41	IN ₁₀
INO ₁	3	40	IN ₁₁
INO ₂	4	39	IN ₁₂
INO ₃	5	38	IN ₁₃
OTO ₀	6	37	IN ₂₀
OTO ₁	7	36	IN ₂₁
OTO ₂	8	35	IN ₂₂
OTO ₃	9	34	IN ₂₃
OT ₁₀	10	33	IO ₁₀
OT ₁₁	11	32	IO ₁₁
OT ₁₂	12	31	IO ₁₂
OT ₁₃	13	30	IO ₁₃
OT ₂₀	14	29	IO ₀₀
OT ₂₁	15	28	IO ₀₁
OT ₂₂	16	27	IO ₀₂
OT ₂₃	17	26	IO ₀₃
OT ₃₀	18	25	XOUT
OT ₃₁	19	24	XIN
OT ₃₂	20	23	RST
GND	21	22	INT

TIMER INTERRUPT

The following figure shows the configuration of timer interrupt circuit of TMP4321AP.



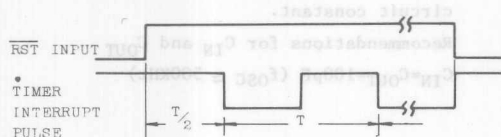
As shown in the above figure, interrupt is not caused by external source via $\overline{\text{INT}}$ pin, but it is only caused by the output divided by the built-in prescaler. The $\overline{\text{INT}}$ pin is usually set to "H" level (open) by the pull-up resistor, but it is not connected with the internal circuit.

Assignment of selective timer option is as follows :

- (1) Option INTDV7 is interrupted at $\frac{1}{f_{\text{osc}}} \times 512(\text{S})$ cycle ($\overline{\text{Q7}}$).
- (2) Option INTDV8 is interrupted at $\frac{1}{f_{\text{osc}}} \times 1024(\text{S})$ cycle ($\overline{\text{Q8}}$).

(Refer to "Mask Option Assignment" in the technical data of TLC543 for further details.)

The relation between timer interrupt and reset is shown in the following figure.



T: INTERRUPT CYCLE BY OPTION ASSIGNMENT

Initial interrupt occurs at $T/2$ interval after the $\overline{\text{RST}}$ input is released, and then repeatedly occurs by every T cycle.

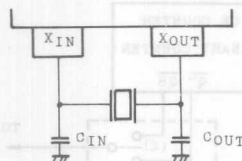
MASK ROM DATA TAPE FORMAT

COMMENT	COMMENT
(CR) (LF)	
(PUNNNL)	PULL-UP
(CR) (LF)	RESISTOR
(INTDV7)	
or	
(INTDV8)	TIMER
(CR) (LF)	
COMMENT	COMMENT
(CR) (LF)	
N8 :	MASK
(CR) (LF)	PATTERN

BASIC CLOCK

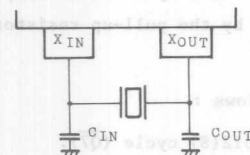
The following are four methods to generate and supply the basic clock pulse in the TMP4321AP.

(1) Direct connection of crystal oscillator



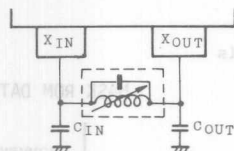
When a crystal oscillator has been connected to TMP4321AP as shown in the left figure, the basic clock pulse is generated at the frequency inherent in the crystal oscillator. Recommendations for C_{IN} and C_{OUT}
 $C_{IN}=C_{OUT}=60\text{pF}$ ($f_{OSC} \approx 500\text{KHz}$)

(2) Direct connection of ceramic oscillator



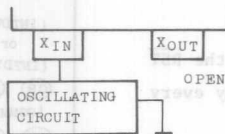
When a ceramic oscillator has been connected to TMP4321AP as shown in the left figure, the basic clock pulse is generated at the frequency inherent in the ceramic oscillator. Recommendations for C_{IN} and C_{OUT}
 $C_{IN}=C_{OUT}=100\text{pF}$ ($f_{OSC} \approx 500\text{KHz}$)

(3) Direct connection of IFT



When a IFT has been connected to TMP4321AP as shown in the left figure, the basic clock pulse is determined according to the circuit constant. Recommendations for C_{IN} and C_{OUT}
 $C_{IN}=C_{OUT}=100\text{pF}$ ($f_{OSC} \approx 500\text{KHz}$)

(4) Supply of external clock



The basic clock pulse of TMP4321AP can be supplied by an external oscillating circuit as shown in the left figure.

MAXIMUM RATINGS

SYMBOL	ITEM	RATING	UNIT
V _{DD}	Supply Voltage	-0.5 ~ 7	V
V _{IN}	Input Voltage	-0.5 ~ 7	V
V _{OUT1}	Output Voltage (except open drain terminal)	-0.5 ~ 7	V
V _{OUT2}	Output Voltage (open drain terminal)	-0.5 ~ 10	V
I _{OUT1}	Output Current (except OT1, OT2)	4	mA
I _{OUT2}	Output Current (OT1, OT2)	30	mA
T _{stg}	Storage Temperature	-55 ~ 125	°C
T _{opr}	Operating Temperature	-10 ~ 70	°C
T _{sld}	Solder Temperature	260 (10 sec.)	°C
P _W	Power Dissipation (T _a = 70°C)	850	mW

D.C. ELECTRICAL CHARACTERISTICS (V_{DD} = 5V±10%, T_{opr} = -10 ~ 70°C)

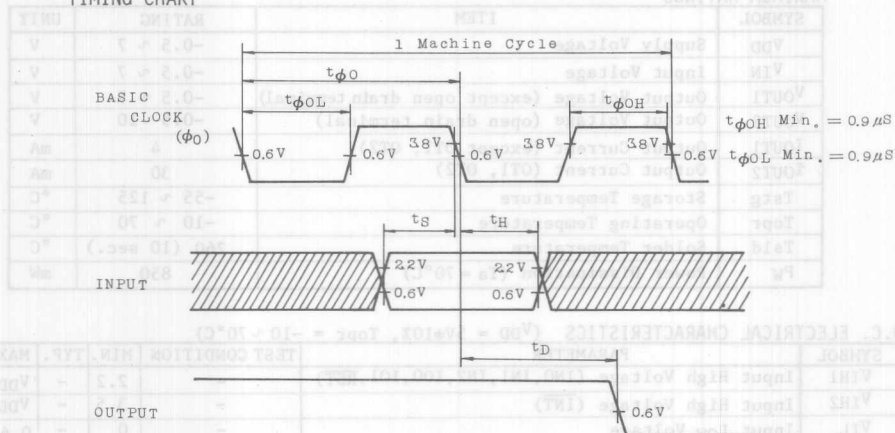
SYMBOL	PARAMETER	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
V _{IH1}	Input High Voltage (IN0, IN1, IN2, IO0, IO1, RST)	-	2.2	-	V _{DD}	V
V _{IH2}	Input High Voltage (INT)	-	3.5	-	V _{DD}	V
V _{IL}	Input Low Voltage	-	0	-	0.6	V
V _{CH}	Input High Clock Voltage (XIN)	-	3.8	-	V _{DD}	V
V _{CL}	Input Low Clock Voltage (XIN)	-	0	-	0.6	V
I _{IN1}	Input Current (IN0, IN1, IN2)	V _{IN} = V _{DD}	-	-	20	μA
I _{IN2}	Input Current (IO0, IO1)	Open Drain	-	-	20	μA
		Pull Up	-	-	-	-
I _{IL1}	Input Low Current (IO0, IO1)	Open Drain	-	-	-	-
		Pull Up	V _{IN} = 0.6V	-	-1.6	mA
I _{IL2}	Input Low Current (RST, INT)	V _{IN} = 0.6V	-	-	-0.1	mA
I _{LO}	Output Leak Current (OT0, OT1, OT2, OT3)	Open Drain	V _{OUT} = V _{DD}	-	20	μA
		Pull Up	-	-	-	-
V _{OH}	Output High Voltage (except XOUT)	Open Drain	-	-	-	-
		Pull Up	I _{OH} = -100μA	2.4	-	V
V _{OL}	Output Low Voltage (except XOUT)	I _{OL} = 1.6 mA	-	-	0.4	V
I _{DD}	Supply Current	-	-	40	80	mA

Output Low Voltage: Output large current I_{OL} TYP.=20mA (V_{OL}=2V) is made possible by output ports OT1, OT2. When output large current sinks, output low voltage becomes V_{OL} MAX.≈0.5V (I_{OL}=1.6mA).

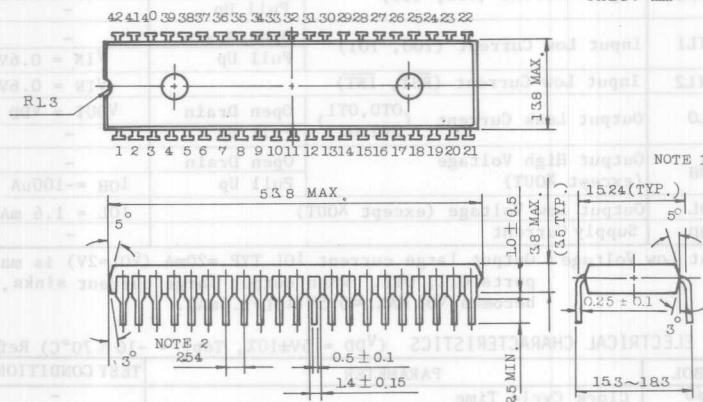
A.C. ELECTRICAL CHARACTERISTICS (V_{DD} = 5V±10%, T_{opr} = -10 ~ 70°C) Refer to Timing Chart.

SYMBOL	PARAMETER	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
t _{φ0}	Clock Cycle Time	-	2	-	5	μS
t _S	Input Setup Time	-	0.9	-	-	μS
t _H	Input Hold Time	-	0.9	-	-	μS
t _D	Output Delay Time	C _L =50pF, R(Pull Up)=50kΩ, 1TTL	-	-	1.8	μS
t _{INT}	INT (Low Level Width)	-	4	-	-	Cycle
t _{RST}	RST (Low Level Width)	-	4	-	-	Cycle

TIMING CHART



EXTERNAL VIEW OF PACKAGE (Plastic Package)



Note 1. The dimension of this external view indicates the lead bending center.

Note 2. Lead pitch is 2.54mm and tolerance is ± 0.25 mm against theoretical center of each lead that is obtained on the basis of No.1 and No.42 leads.



INTEGRATED CIRCUIT

TECHNICAL DATA

TMP4399C

TOSHIBA MOS Digital Integrated Circuit

Silicon Monolithic

N-channel Silicon Gate Depletion Load

DESCRIPTION

TMP4399C is a single-chip microcomputer for evaluation, provided with the general purpose 16K EPROM (TMM323D) inserting socket, being capable of developing and checking hardware and software of TLCS-43 Application System by use of the EPROM.

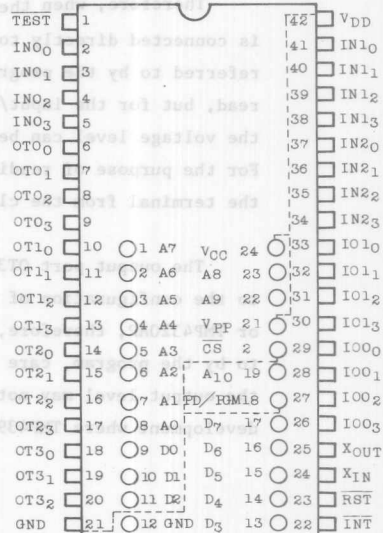
TMP4399C is equipped with a 24-pin socket which may directly mount the general purpose 16K EPROM (TMM323D) on the surface of the package. Therefore, when the fixed program written in the general purpose 16K EPROM is mounted on the package, TMP4399C becomes pin-compatible with TMP4315BP/TMP4320AP as the end product which the program has been written in the mask ROM. The former operates the same as the latter.

TMP4399C can be used within the range of a microcomputer for evaluating the TLCS-43 system as well as for mounting an equipment made on an experimental basis.

PIN CONNECTIONS

FEATURES

- o General purpose 16K EPROM TMM323D (equivalent to INTEL2716) can be used.
- o Compatible with TLCS-43 single-chip microcomputer family TMP4315BP/4320AP in pin.
- o Compatible with TLCS-43 Series in software.
- o ROM 2KW x 8 BIT RAM 128W x 4 BIT
- o Can be operated by +5V single power supply. Voltage margin is $\pm 10\%$ equal to that of mass-produced products.
- o Operating temperature range is $-10 \sim 70^\circ\text{C}$ equal to that of mass-produced products.



(Note) ○ mark: Socket for TMM323D

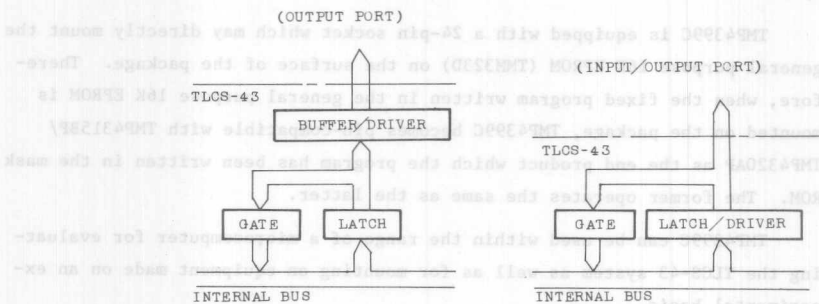
TOSHIBA CORPORATION

93

PRECAUTIONS FOR USING TMP4399C

1. Precautions for using OT3 Output Port

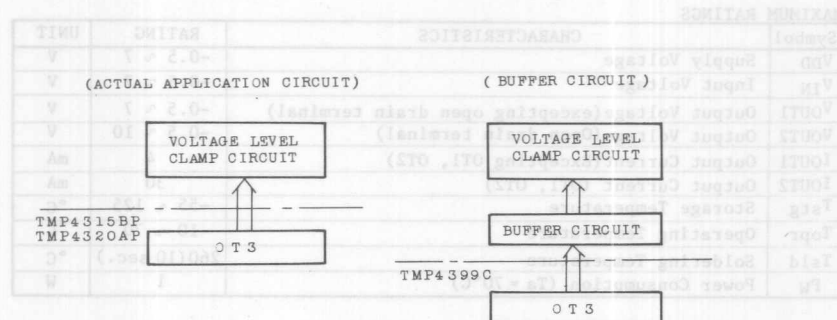
The output port and input/output port of TLCS-43 are composed as shown in the following figures.



Therefore, when the circuit which clamps the output voltage level is connected directly to the outside of terminal, if the output data is referred to by the program, for the output port such data can be normally read, but for the input/output port erroneous data may be read unless the voltage level can be ensured as an input signal by the clamp circuit. For the purpose of reading correct data, it is necessary to separate the terminal from the clamp circuit by the buffer circuit.

The output port OT3 of TMP4399C serves as an input/output port owing to the configuration of the chip. In case of the system using TMP4315BP or TMP4320AP, therefore, if the output data of OT3 Port must be referred to by the program, care should be taken that the circuit which clamps the output level may not be connected directly to OT3 Port at the stage of development where TMP4399C is used.

ELECTRICAL CHARACTERISTICS



Symbol	CHARACTERISTIC	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
V_{IH1}	Input High V. (excluding I_{IH})		2.3			V
V_{OL}	Output Low V. (excluding I_{OL})		0.5			V
I_{IH}	Input High Current			1.5		μA
I_{OL}	Output Low Current			1.5		μA
V_{OH}	Output High V. (excluding I_{OH})				2.4	V
V_{OL}	Output Low V. (excluding I_{OL})				0.5	V
I_{OH}	Output High Current			1.5		μA
I_{OL}	Output Low Current			1.5		μA

2. Precautions for using large output current

In case of TMP4399C, each terminal of the output port OT1 and OT2 may sink large output current $I_{OL} = 20mA$ TYP. ($V_{OL} = 2V$) when there ports sink large output current, a part of the DC electrical characteristics is changed. Attention should be paid to the main characteristics that the high input voltage of V_{IH1} and the low output voltage of V_{OL} at every terminal to be applied will become the valurs shown as follows:

V_{IH1} MIN. $\approx 2.3 \sim 2.4V$
 V_{OL} MAX. $\approx 0.5 \sim 0.6V$ ($I_{OL} = 1.6mA$.)

The maximum rating of large output current is 30 mA.

Symbol	CHARACTERISTIC	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
t_{PH}	Output Delay Time	$C_L = 30pF$			1.8	μs
t_{PL}	Output Delay Time	$C_L = 30pF$			1.8	μs
t_{RST}	Reset Delay Time	$C_L = 30pF$			0.5	μs
t_{RST}	Reset Delay Time	$C_L = 30pF$			0.5	μs
t_{RST}	Reset Delay Time	$C_L = 30pF$			0.5	μs
t_{RST}	Reset Delay Time	$C_L = 30pF$			0.5	μs
t_{RST}	Reset Delay Time	$C_L = 30pF$			0.5	μs
t_{RST}	Reset Delay Time	$C_L = 30pF$			0.5	μs
t_{RST}	Reset Delay Time	$C_L = 30pF$			0.5	μs
t_{RST}	Reset Delay Time	$C_L = 30pF$			0.5	μs

ELECTRICAL CHARACTERISTICS

MAXIMUM RATINGS

Symbol	CHARACTERISTICS	RATING	UNIT
V _{DD}	Supply Voltage	-0.5 ~ 7	V
V _{IN}	Input Voltage	-0.5 ~ 7	V
V _{OUT1}	Output Voltage(excepting open drain terminal)	-0.5 ~ 7	V
V _{OUT2}	Output Voltage(Open drain terminal)	-0.5 ~ 10	V
I _{OUT1}	Output Current(Excepting OT1, OT2)	4	mA
I _{OUT2}	Output Current (OT1, OT2)	30	mA
T _{stg}	Storage Temperature	-55 ~ 125	°C
T _{opr}	Operating Temperature	-10 ~ 70	°C
T _{sl}	Soldering Temperature	260(10 sec.)	°C
P _W	Power Consumption (Ta = 70°C)	1	W

D.C. ELECTRICAL CHARACTERISTICS (V_{DD} = 5V ± 10%, T_{opr} = -10 ~ 70°C)

Symbol	CHARACTERISTICS	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
V _{IH1}	Input High V. (excepting INT, XIN)	-	2.2	-	V _{DD}	V
V _{IH2}	Input High Voltage (INT)	-	3.5	-	V _{DD}	V
V _{IL}	Input Low Voltage	-	0	-	0.6	V
V _{CH}	Clock Input High Voltage (XIN)	-	3.8	-	V _{DD}	V
V _{CL}	Clock Input Low Voltage (XIN)	-	0	-	0.6	V
I _{IN}	Input Current(excepting RST, INT)	V _{IN} = V _{DD}	-	-	20	μA
I _{IL2}	Input Low Current (RST, INT)	V _{IN} = 0.6V	-	-	-0.1	mA
I _{LO}	Output Leak Current(OT0, OT1, OT2)	V _{OUT} = V _{DD}	-	-	20	μA
V _{OH}	Output High Voltage (AO ~ A10)	I _{OH} = -100μA	24	-	-	V
V _{OL}	Output Low V. (excepting XOUT)	I _{OL} = 1.6 mA	-	-	0.4	V
I _{DD}	Supply Voltage	-	-	70	120	mA

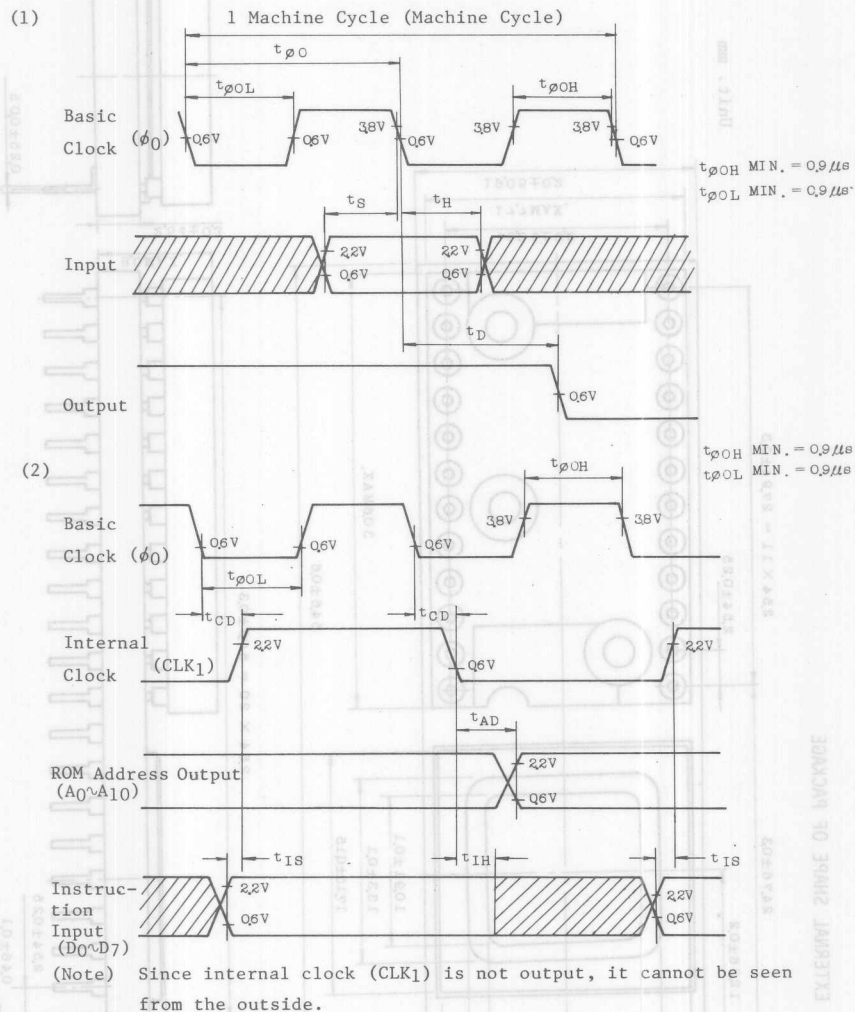
[Operation of Evaluator Chip] Refer to the paragraph entitled "Precautions for Using Large Output Current".

Refer to timing charts (1) and (2).

A.C. ELECTRICAL CHARACTERISTICS (V_{DD} = 5V ± 10%, T_{opr} = -10 ~ 70°C)

Symbol	CHARACTERISTIC	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
t _{φ0}	Clock Cycle Time	-	2	-	5	μs
t _S	Input Setup Time	-	0.9	-	-	μs
t _H	Input Hold Time	-	0.9	-	-	μs
t _D	Output Delay Time	C _L = 50PF R(Pull UP) = 50kΩ, 1TTL	-	-	1.8	μs
t _{INT}	INT Low Level Width	-	4	-	-	Cycle
t _{RST}	RST Low Level Width	-	4	-	-	Cycle
t _{CD}	Clock Output Delay Time	C _L = 50PF, 1TTL	-	-	0.4	μs
t _{AD}	Address Output Delay Time	C _L = 50PF, 1TTL	-	-	0.95	μs
t _{IS}	Instruction Input Setup Time	-	0.4	-	-	μs
t _{IH}	Instruction Input Hold Time	-	0	-	-	μs

TIMING CHART



Technical drawing of a printed circuit board (PCB) showing top, bottom, and side views with dimensions in millimeters.

Top View Dimensions:

- Overall width: 24.76 ± 0.3
- Overall height: $25.4 \times 11 = 27.94 \pm 0.3$
- Inner width: 12.06 ± 0.2
- Inner height: 10.91 ± 0.1
- Distance from top edge to first hole: 17.15 ± 0.15
- Distance from bottom edge to first hole: 13.3 ± 0.1
- Distance between holes: 10.91 ± 0.1
- Distance from left edge to first hole: 13.3 ± 0.1
- Distance from right edge to first hole: 17.15 ± 0.15
- Distance between hole rows: 30.6 MAX.
- Distance from top edge to hole row: 152.4 ± 0.2
- Distance from bottom edge to hole row: 17.7 MAX.
- Overall distance between hole rows: 19.05 ± 0.2
- Distance from left edge to hole row: 54.6 ± 0.6

Bottom View Dimensions:

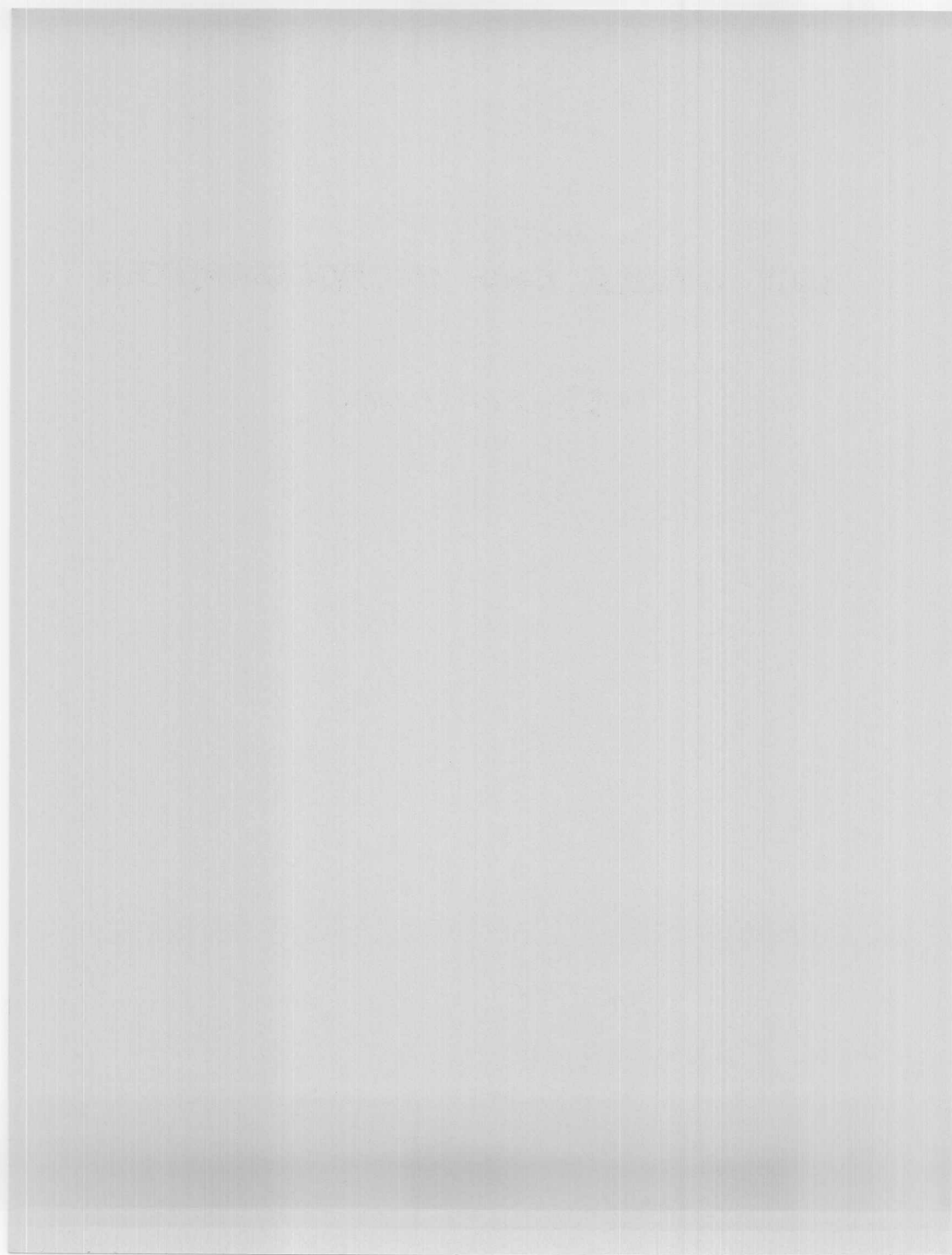
- Overall width: $25.4 \times 20 = 50.8 \pm 0.3$
- Overall height: 1.0 MAX.
- Distance from top edge to first hole: 1.0 MAX.
- Distance from bottom edge to first hole: 1.0 MAX.
- Distance between holes: 2.54 ± 0.25
- Distance from left edge to first hole: 0.46 ± 0.1
- Distance from right edge to first hole: 1.02 ± 0.2

Side View Dimensions:

- Overall height: 25.4 ± 0.3
- Distance from top edge to first hole: 0.25 ± 0.05
- Distance from bottom edge to first hole: 15.24 ± 0.25

4BIT SINGLE CHIP MICROCOMPUTER

TLCS-46A (CMOS)





INTEGRATED CIRCUIT

TECHNICAL DATA

"C²MOS" DIGITAL INTEGRATED CIRCUIT

TCP4620AP

TCP4630AP



SILICON MONOLITHIC

CMOS 4-BIT SINGLE CHIP MICROCOMPUTER

GENERAL DESCRIPTION

TLCS-46A is a C²MOS high speed and low power 4-bit single chip micro-computer for consumer applications.

A single and integral microcomputer has been composed of a 4-bit parallel arithmetic and logical unit (ALU), accumulator (AC), program memory (ROM), data memory (RAM), input/output ports, clock generator, and divider incorporated.

TLCS-46A Family consists of two kinds of chips having different ROM/RAM capacities for mass production and evaluator for system development.

o 32 Instructions

o 46 One Cycle Instructions

o 5 Two Cycle Instructions

o Single Level Subroutine Nesting

o Single Level External Interrupt

o 10µs Instruction Execution Time

o PLA and Decode Matrix for Display Operation

o Many Kinds of Mask Options for Optimum

Application Systems



INTEGRATEDCIRCUIT

TECHNICAL DATA

TCP4620AP
TCP4630AP



FEATURES

- o TCP4620AP
 - 2048 x 8 ROM
 - 96 x 4 RAM
 - 34 I/O Lines
- o TCP4630AP
 - 3072 x 8 ROM
 - 160 x 4 RAM
 - 34 I/O Lines
- o TCP4600AP
 - Evaluator Chip
for TLCS-46A
- o Low Power Dissipation by
Employment of C²MOS Process
 - Typical Supply Current : 400 μ A
(at 400 kHz Basic Clock)
- o Single 5V Supply
 - Wide Operating Range : 3V to 6V
- o Wide Operating Temperature Range: -30°C to 85°C
- o 52 Instructions
 - 46 One Cycle Instructions
 - 6 Two Cycle Instructions
- o Single Level Subroutine Nesting
- o Single Level External Interrupt
- o 10 μ s Instruction Execution Time
- o PLA and Decode Matrix for Display Operation
- o Many Kinds of Mask Options for Optimum
Application Systems



INTEGRATEDCIRCUIT

TECHNICAL DATA

INTEGRATEDCIRCUIT

TCP4620AP

TCP4630AP



PIN CONNECTIONS (TOP VIEW)

Pin Name	Input/Output	Function
PO ₅₄ -PO ₅₀	Output	5-digit output port for display. (Can be used as the general purpose 5-bit output port).
PI ₅₃ -PI ₅₀	Input	4-bit general purpose input port.
PI ₄₃	Input	4-bit general purpose input port (with a
PI ₄₂	Input	4-bit general purpose input port (with a
PI ₄₁	Input	4-bit general purpose input port (with a
PI ₄₀	Input	4-bit general purpose input port (with a
PI ₆₀	Input	4-bit general purpose input port (with a
INT	Input	Interrupt input (with a
RESET	Input	Reset input (with a
TEST	Input	Test input (with a
CK	Input	Clock input (with a
XOUT	Output	External output (with a
CK	Output	Clock output (with a
TEST	Input	Test input (with a
PI ₅₀	Input	4-bit general purpose input port (with a
PO ₅₀	Output	5-digit output port for display. (Can be used as the general purpose 5-bit output port).
GND		Ground

PIN NAMES & PIN DESCRIPTION

Pin Name	Input/Output	Function
PO ₅₃ - PO ₅₀	Input/Output	4-bit general purpose I/O port (I/O is designated by a program).
PI ₅₃ - PI ₅₀	Output	4-bit general purpose output port.
PI ₅₃ - PI ₅₀	Input or Output	4-bit general purpose Input/Output port
PI ₄₃ - PI ₄₀	Input or Output	4-bit general purpose Input/Output port
PO ₅₄ - PO ₅₀	Output	5-digit output port for display. (Can be used as the general purpose 5-bit output port)



INTEGRATEDCIRCUIT

TECHNICAL DATA

INTEGRATEDCIRCUIT

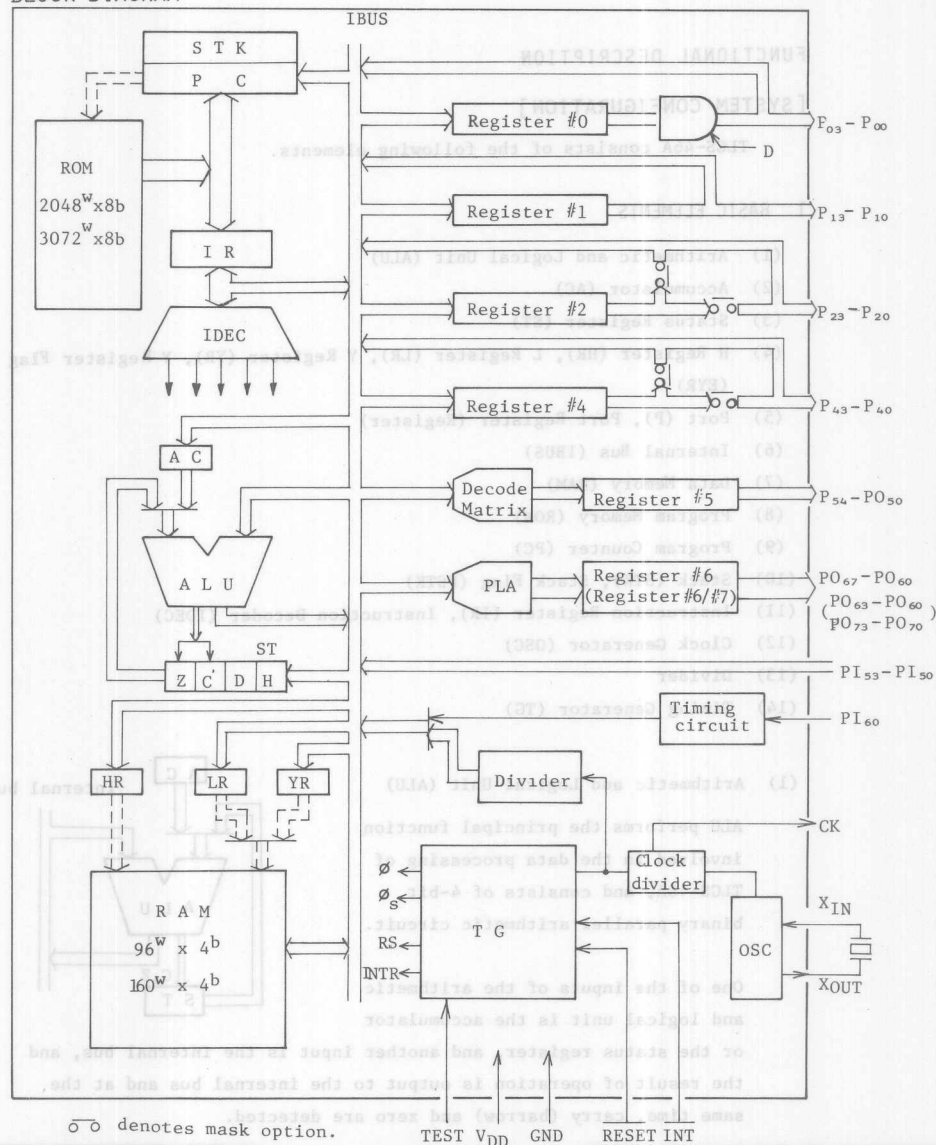
TCP4620AP
TCP4630AP



Pin Name	Input/Output	Function
PO ₆₇ -PO ₆₀	Output	8-segment output port for display (can be used as the general purpose 8-bit output port)
PI ₅₃ -PI ₅₀	Input	4-bit general purpose input port.
PI ₆₀	Input	1-bit general purpose input port (with a internal Schmitt circuit).
$\overline{\text{RESET}}$	Input	Initialize signal input (with a internal Schmitt circuit).
$\overline{\text{INT}}$	Input	Interrupt request signal input (with a inter-internal Schmitt circuit).
X _{IN}	Input	Oscillator connecting terminal
X _{OUT}	Output	Oscillator connecting terminal
CK	Output	External timing output
TEST	Input	LSI test signal input, used by connecting to GND
V _{DD}		Power supply
GND		GND

PIN NAMES & PIN DESCRIPTION		
Pin Name	Input/Output	Function
PO ₆₇ -PO ₆₀	Output	8-bit general purpose I/O port (1/0 is designated by a program).
PI ₅₃ -PI ₅₀	Input/Output	4-bit general purpose I/O port (1/0 is designated by a program).
PI ₆₀	Input	1-bit general purpose I/O port (1/0 is designated by a program).
$\overline{\text{RESET}}$	Input	Initialize signal input (with a internal Schmitt circuit).
$\overline{\text{INT}}$	Input	Interrupt request signal input (with a inter-internal Schmitt circuit).
X _{IN}	Input	Oscillator connecting terminal
X _{OUT}	Output	Oscillator connecting terminal
CK	Output	External timing output
TEST	Input	LSI test signal input, used by connecting to GND
V _{DD}		Power supply
GND		GND

BLOCK DIAGRAM



FUNCTIONAL DESCRIPTION

[SYSTEM CONFIGURATION]

TLCS-46A consists of the following elements.

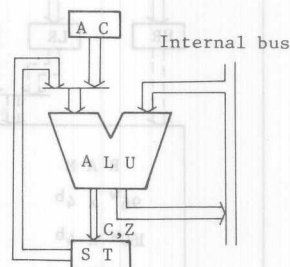
1. BASIC ELEMENTS

- (1) Arithmetic and Logical Unit (ALU)
- (2) Accumulator (AC)
- (3) Status Register (ST)
- (4) H Register (HR), L Register (LR), Y Register (YR), Y Register Flag (EYR)
- (5) Port (P), Port Register (Register)
- (6) Internal Bus (IBUS)
- (7) Data Memory (RAM)
- (8) Program Memory (ROM)
- (9) Program Counter (PC)
- (10) Stack (STK), Stack Flag (FSTK)
- (11) Instruction Register (IR), Instruction Decoder (IDEC)
- (12) Clock Generator (OSC)
- (13) Divider
- (14) Timing Generator (TG)

(1) Arithmetic and Logical Unit (ALU)

ALU performs the principal function involved in the data processing of TLCS-46A, and consists of 4-bit binary parallel arithmetic circuit.

One of the inputs of the arithmetic and logical unit is the accumulator and the status register, and another input is the internal bus, and the result of operation is output to the internal bus and at the same time, carry (barrow) and zero are detected.



(2) Accumulator (AC)

The accumulator is a 4-bit register that temporarily stores data for arithmetic process, arithmetic result and data from/to the input/output ports.

(3) Status Register (ST)

The status register is a 4-bit register having a meaning per bit, and is called H flag, D flag, C flag and Z flag in that order from LSB side.

(MSB)		(LSB)	
3	2	1	0
Z	C	D	H

① Zero Flag (Z)

The zero flag (Z) is set to "1", if the result generated by certain instructions is zero.

The zero flag is cleared, if the result is not zero.

Further, z flag is used not only for judgement of zero but also as a branch condition for program flow.

② C Flag

When an instruction indicating update is executed, C flag is set at "1" if carry is resulted at time of addition and increment, and at "0" if no carry is resulted.

Further C flag is also set at "0" when borrow is resulted at time of subtraction and at "1" when no borrow is resulted.

C flag is used for judging size of data and for multiple digit arithmetic operation.

③ D Flag

D flag is used by a program as an input/output designating signal of the input/output port (Po). When D flag is "0", the input/output port serves as the input port and when D flag is "1", it serves as the output port.

When the input/output port is used exclusively as the output port (specified by mask option), D flag becomes the general purpose flag bit that can be optionally used by user.

D flag is reset at "0" by the initialize operation.

④ H Flag

H flag is used as a control signal for hold operation. When "1" is set on H flag, the timing generator is placed in hold mode and the operation is held suspended. The restart from the hold mode is accomplished by resetting H flag at "0" in the hardware processing, and after released from the hold mode, the process that was held suspended prior to the hold operation is resumed. However, interrupt request is not accepted under the hold operation.

When the hold operation is not used (specified by mask option), H flag becomes a general purpose flag bit that can be optionally used by user.

H flag is reset at "0" by the initialize operation.

(4) H Register (HR), L Register (LR), Y Register (YR), Y Register Flag (EYR)

H register and L register are 4-bit registers and function as an address pointer of the data memory (RAM) or a general purpose register.

When H register and L register are used as an address pointer of the data memory, H register represents high order 4 bits of an address and L register represents low order 4 bits, and they designate an address space of total 8 bits (256 words). Therefore, when 16 words in the address space of the data memory are expressed as one page, H register designates a page address and L register designates an address in the page.

When an undefined region without data memory is read with H register and L register used as address pointers of the data memory, the data memory contents are regarded as being undefined. Further, data write into an undefined region should be avoided.

Y register is a 4-bit register and functions as an address pointer in page 0 of the data memory or a general purpose register.

Y register flag is an 1-bit flag that shows as to whether H register or L register is used as an address pointer of the data memory. When Y register flag is "1" (EYR=1), Y register is selected as an address pointer of the data memory, and when Y register flag is "0" (EYR=0), H register and L register are selected as address pointers.

Y register flag is set at "1" by the execution of Y register data setting instruction. And Y register flag is cleared at "0" by the execution of the instruction which does not set data to data memory. Further, while Y register flag is set at "1", it is kept in interrupt disabled (waiting) state.

Y register flag is reset at "0" by the initialize operation.

(5) Port (P), Port Register (Register)

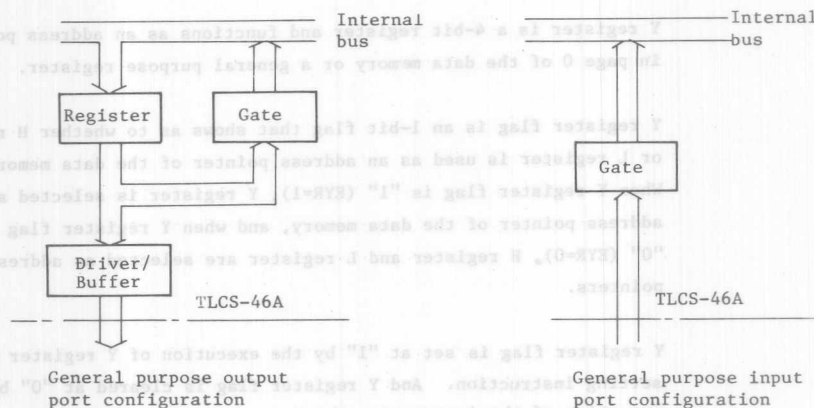
TCP4620AP/TCP4630AP is provided with a total 34 ports; input port, output port, input output port, and input/output port.

When a port is used as input, it is processed as non-latch input, and therefore, it is necessary to hold external input data till completion of read-in.

When a port is used as output, output data is set in the port register by an instruction and contents of this port register are output. On some ports it is possible to read contents of the port registers by an instruction.

Further, the port register is reset at "0" by initialize operation.

In addition, the input level is compatible with CMOS, and the output level is compatible with CMOS/TTL.



Port Configuration

Port Name	Symbol	Pin Name	Register Number	Port Function	Remarks
Input Output port	P ₀	P ₀₃ - P ₀₀	0	Input output port	Control designating of I/O by D flag. This port can be specified as an exclusive use output port by mask option.



INTEGRATED CIRCUIT

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TECHNICAL DATA

INTEGRATED CIRCUIT

TCP4620AP

TCP4630AP



Port Name	Symbol	Pin Name	Register Number	Port Function	Remarks
Output Port	P ₁	P ₁₃ - P ₁₀	1	Output port	General purpose output port. Contents of registers can be read by an instruction.
I/O Port	P ₂	P ₂₃ - P ₂₀	2	I/O port	Input/output is specified by mask option. Contents of registers can be read by instruction at the output mode.
I/O Port	P ₄	P ₄₃ - P ₄₀	4	I/O port	
Key Input Port	PI ₅	PI ₅₃ - PI ₅₀	5	Input port	General purpose input port with a 150KΩ(Typical) resistor. (Pull-up/down can be specified by mask options).
Digit Output Port	PO ₅	PO ₅₄ - PO ₅₀		Output port	Digit output port for dynamic display. Can be specified as a general purpose output port by mask options.
Input Port	PI ₆	PI ₆₀	6	Input port	General purpose input port.
Segment Output Port	PO ₆	PO ₆₇ - PO ₆₀		Output port	8-segment output port for dynamic display. Can be specified as a general purpose output port by mask options.

Generalization of Segment Output Port (Specified by Mask Options)

Port Name	Symbol	Pin Name	Register Number	Port Function	Remarks
Output Port	PO ₆	PO ₆₃ - PO ₆₀	6	Output port	General purpose output port.
Output Port	PO ₇	PO ₇₃ - PO ₇₀	7	Output port	General purpose output port.

① Port 0 (Po)

Port 0 is a 4-bit general purpose input/output port. This port is selected when Register 0 is specified in an instruction.

Input/output designation is made by D flag of the status register. When D flag is "0", this port becomes the input and when D flag is "1", it becomes the output and output the content of Register 0.

Port 0 can be used as an exclusive output port by mask options.

② Port 1 (P₁)

Port 1 is a 4-bit general purpose output port. This port is selected when Register 1 is specified in an instruction and the content of Register 1 is output.

Further, the content of Register 1 can be read by an instruction.

③ Port 2 (P₂), Port 4 (P₄)

Port 2 and Port 4 are 4-bit input/output ports that can be specified as either input or output by mask options. When Register 2 and Register 4 are specified in an instruction, Port 2 and Port 4 are selected, respectively.

In specifying input or output in a mask option, the following combination is possible.

- (a) P2/F/, P4/F/-Port 2 and Port 4 as output.
- (b) P2/F/, P4/3/-Port 2 as output.
High order 2 bits (P43,P42) of Port 4 as input, low order 2 bits (P41, P40) as output.
- (c) P2/0/, P4/F/-Port 2 as input.
Port 4 as output.
- (d) Specify P2/0/, P4/3/-Port 2 as input.
High order 2 bits (P43,P42) of Port 4 as input low order 2 bits (P41, P40) of Port 4 as output.
- (e) Specify P2/0/, P4/0/-Port 2 and P4 as input.

Further, in case of input bits these ports operate as non-latch inputs, and in case of output bits they operate functionally same as in Port 1.

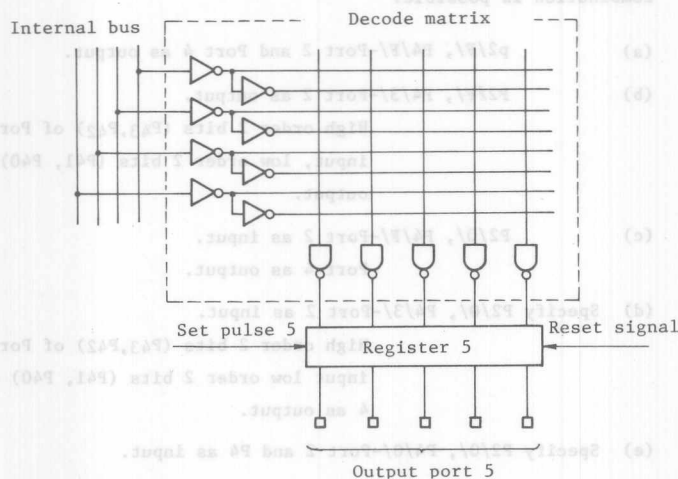
④ Output Port 5 (PO5)

Output Port 5 is a 5-bit output port with the purpose of digit data output in dynamic display.

When an instruction for writing data in Register 5 is executed, 4-bit data on the internal bus is converted into 5-bit data by the decoder matrix, this data is written into the 5-bit Register 5 and further, output to Port 5.

User is able to specify the content of the decode matrix optionally by mask options.

Further, the content of Register 5 cannot be read by an instruction.



⑤ Input Port 5 (PI₅)

Input Port 5 is a 4-bit input port. This port is selected by a Read Register 5 instruction.

Input Port 5 is equipped with a 150k Ω (Typ.) input resistor, and the pull-up/down is specified by mask options.

⑥ Output Port 6 (PO₆), Output Port 7 (PO₇)

Output Port 6 is a 8-bit output port for segment data output in dynamic display.

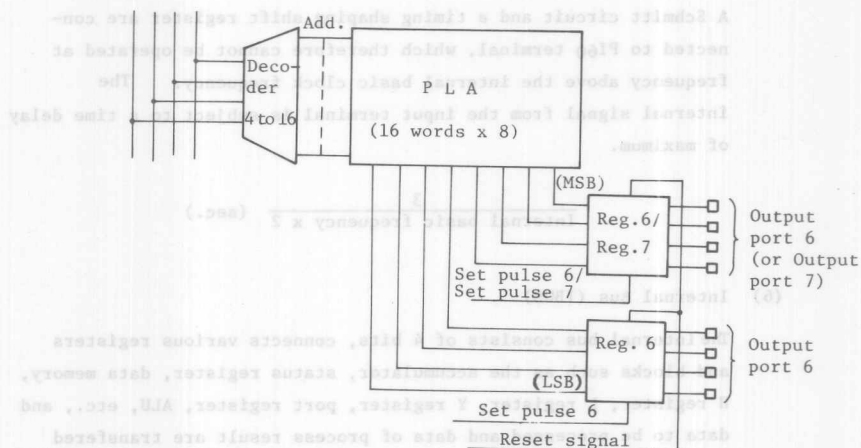
When an instruction for writing data in Register 6 is executed, a output data is read from 16 words x 8 bits PLA with a 4-bit data on the internal bus used as an address, this output data is written into the 8-bit Register 6, and output to Port 6.

User is able to specify the content of PLA optionally by mask options.

Further, it is possible to specify and use output Port 6 as two 4-bit general purpose output ports by mask options. In this case, the 8-bit output port is split into high order 4 bits and low order 4 bits, and the high order 4 bits are assigned to output Port 7 (Register 7) and low order 4 bits to Output Port 6 (Register 6).

The contents of Register 6 (and Register 7) cannot be read by an instruction.

Internal
bus



⑦ Input Port 6 (PI₆), Counter Buffer

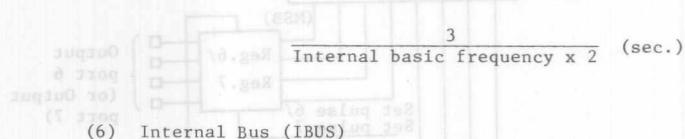
Input Port 6 is the input port of 1 terminal (PI₆₀), but internally it is treated as a 4-bit data in combination with 3-bit data that are output from the divider (refer to Item for Divider).

The read circuit which reads this 4-bit data is called Counter Buffer/Input Port 6 or Counter Buffer simply. This counter buffer is selected by a Read Register 6 instruction and processed as 4-bit parallel non-latch input as in other input ports.

The bit configuration of the counter buffer is such that external input from PI60 terminal is connected to LSB side 1 bit and output from the divider is connected to MSB side 3 bits.

Further, the output stage of the divider to be connected is specified by mask options, but is fixed by a combination of an oscillator to be used and internal basic frequency. (Refer to Item for Divider.)

A Schmitt circuit and a timing shaping shift register are connected to PI60 terminal, which therefore cannot be operated at frequency above the internal basic clock frequency. The internal signal from the input terminal is subject to a time delay of maximum.



(6) Internal Bus (IBUS)

The internal bus consists of 4 bits, connects various registers and blocks such as the accumulator, status register, data memory, H register, L register, Y register, port register, ALU, etc., and data to be processed and data of process result are transferred through the internal bus.

(7) Data Memory (RAM)

TLC5-46A Family has the following internal data memories in order to store user's process data.



INTEGRATED CIRCUIT

TECHNICAL DATA

INTEGRATED CIRCUIT

TCP4620AP

TCP4630AP



Type

Capacity

TCP4620AP

96 words x 4 bits

TCP4630AP

160 words x 4 bits

(TCP4600AC

160 words x 4 bits)

The data memory consists of the static memory cells.


Addressing of the data memory is executed by contents of H register/L register or Y register.

T C P 4 6 2 0 A P

Address	F	E	D	C	B	A	9	8	7	6	5	4	3	2	1	0
0																
1																
2																
3																
4																
5																

T C P 4 6 3 0 A P / (T C P 4 6 0 0 A C)

Address	F	E	D	C	B	A	9	8	7	6	5	4	3	2	1	0
0																
1																
2																
3																
4																
5																
6																
7																
8																
9																

 portion can be referred by Y register.

Addressing of Data Memory

(8) Program Memory (ROM)

TLCS-46A Family has the following internal program memory in order to store user's process programs.

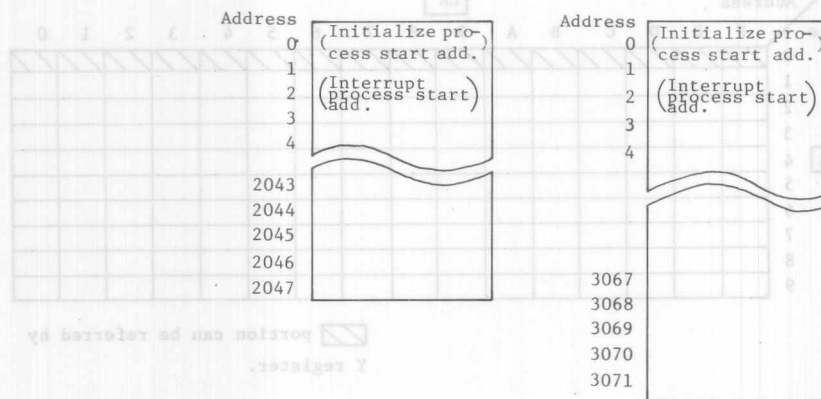
Type	Capacity
TCP4620AP	2048 words x 8 bits
TCP4630AP	3072 words x 8 bits
(TCP4600AC)	No internal ROM

The program memory addressing is executed by the program counter (PC). Inherent meaning is given to Addresses 0 and 2

by the hardware, normal user process programs are place in Address 4 and subsequent addresses.

Further, the program counter consists of 12 bits and is capable of directly specifying addresses up to 4095, however, data in an undefined region having no program memory loaded becomes unstable.

TCP4620AP TCP4630AP



(9) Program Counter (PC)

The program counter consists of a 12-bit binary counter, adds count increment at every instruction fetch, and makes the addressing of a program memory in which an instruction to be executed.

When a branch instruction, an interrupt operation, or subroutine instruction is executed, the contents of the program counter are changed.

Addresses 0 and 2 are compulsorily set in the program counter by a initialize signal and an interrupt request signal, respectively.

(10) Stack (STK), Stack Flag (FSTK)

The stack is used for temporary evacuation of the contents of the program counter when an interrupt request is accepted or a subroutine is to be executed.

The stack flag is a flag indicating whether the contents of the program counter have been evacuated in the stack.

When the contents of the program counter are pushed down in the stack, the stack flag is set at "1" (FSTK=1). And when the contents of the stack are popped up by a RTN instruction and returned to the original program flow, the stack flag is set at "0" (FSTK=0). At time of FSTK=1, the interrupt request becomes the disable (waiting) state.

Further, the stack flag is set at FSTK=1 by the initialize operation.

(11) Instruction Register (IR), Instruction Decoder (IDEC)

The instruction register latches a 8-bit data from the program memory and outputs it to the instruction decoder. (Program memory data may be used for direct internal control.)

The instruction decoder receives data from the instruction register and outputs a control signal required for processing.

(12) Clock Generator (OSC)

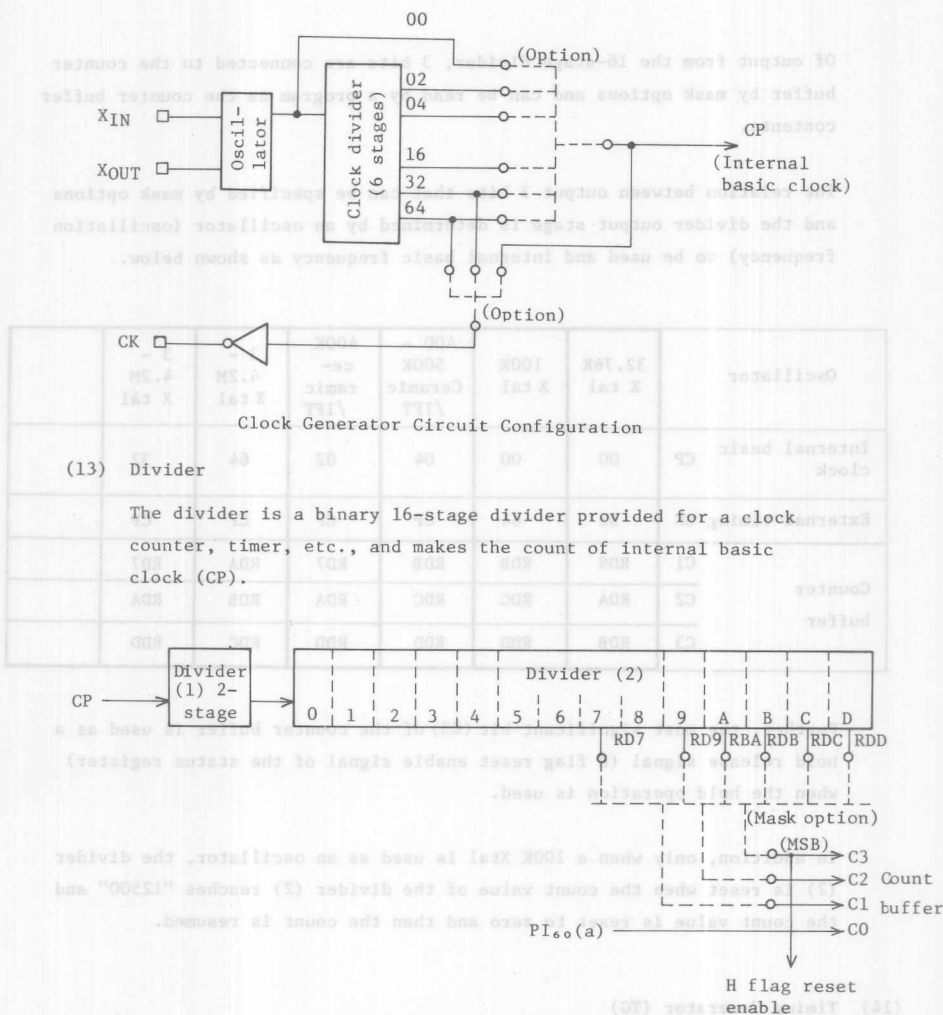
TCP4620AP/TCP4630AP has a internal clock generator. By externally installing a crystal oscillator/ceramic oscillator or a LC oscillator, required clock is easily obtained. Further, clock can be supplied externally, however, in this case, the clock is input through X_{IN} terminal and X_{OUT} terminal is kept open. While TCP4620AP/TCP4630AP starts by \overline{RESET} , the clock should be always continuously supplied.

Oscillation frequency shall be selected from several frequencies ranging from 20KHz to 4.2MHz by mask options.

The clock generator has a internal 6-stage clock divider and specifies the optimum divide ratio to obtain internal basic clock (CP) on the basis of oscillation frequency by mask options.

The clock generator is provided with the output terminal CK for external timing, and output frequency is specified by mask options.

Further, a divide ratio for obtaining internal basic clock and external timing output frequency specified by mask options (refer to Item for Divider) are determined by an oscillator (oscillation frequency) to be used and internal basic clock frequency.



Divider Configuration

Of output from the 16-stage divider, 3 bits are connected to the counter buffer by mask options and can be read by a program as the counter buffer contents.

The relation between output 3 bits that can be specified by mask options and the divider output stage is determined by an oscillator (oscillation frequency) to be used and internal basic frequency as shown below.

Oscillator		32.76K Xtal	100K Xtal	400 - 500K Ceramic /IFT	400K ce- ramic /IFT	3 - 4.2M Xtal	3 - 4.2M Xtal	
Internal basic clock	CP	00	00	04	02	64	32	
External timing	CK	32	64	CP	CP	CP	CP	
Counter buffer	C1	RD9	RDB	RDB	RD7	RDA	RD7	
	C2	RDA	RDC	RDC	RDA	RDB	RDA	
	C3	RDB	RDD	RDD	RDD	RDC	RDD	

Further, the most significant bit (C3) of the counter buffer is used as a hold release signal (H flag reset enable signal of the status register) when the hold operation is used.

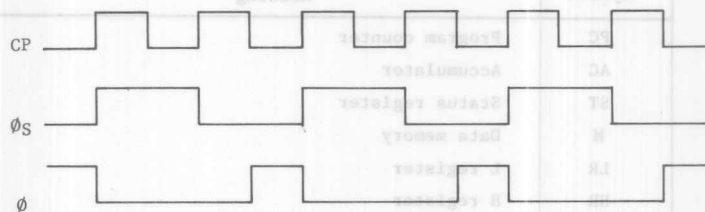
In addition, only when a 100K Xtal is used as an oscillator, the divider (2) is reset when the count value of the divider (2) reaches "12500" and the count value is reset to zero and then the count is resumed.

(14) Timing Generator (TG)

The timing generator consists of the internal timing signal generation circuit, initialize control circuit and interrupt control circuit.

① Internal Timing Signal Generation Circuit

This circuit receives the internal basic clock (CP) from the clock generator and generates two internal basic timing signals ϕ and ϕ_S .



② Initialize Control Circuit

This circuit shapes the timing of external RESET signal and generates an internal initialize signal. This initialize signal is used for internal initialization. (For details of the initialize operation refer to "Operation Description".)

③ Interrupt Control Circuit

This circuit shapes the timing of external interrupt request signal $\overline{\text{INT}}$, store it in the internal interrupt latch, and makes a judgement as to if the internal state is interrupt enable. When it is in enable state, this circuit generates an interrupt request signal internally and starts an interrupt operation, but if it is in disable state, controls the interrupt request to wait till it becomes enables.

(For details of the interrupt operation refer to "Operation Description".)

[MACHINE INSTRUCTION]

1. Symbol Meaning

The explanation of symbols used for the following description is collected in the following table.

Symbol	Meaning
PC	Program counter
AC	Accumulator
ST	Status register
M	Data memory
LR	L register
HR	H register
YR	Y register
EYR	Y register flag
C	C flag of status register
Z	Z flag of status register
R	Port register, Field designating register under instructions
I	Value of immediate data field
G	Field designating bit position under bit processing instructions
AP	Address branched by branch instructions
APH	Field showing higher order 4 bits of AP
APM	Field showing intermediate order 4 bits of AP
APL	Field showing lower order 4 bits of AP
(A)	Content of A
\bar{A}	Values that contents of A are inverted every bit
+	Binary addition
-	Binary subtraction
\wedge	Logical AND for every bit
\vee	Logical OR for every bit

Symbol	Meaning
⊕	Exclusive OR for every bit
=	Value of left side is equalized to that of right side
A<a : b>	Content from b bitth to a bitth of A
°	Value is made into one by connecting two fields
*	Value is updated by operation result
-	Value is not changed by operation result
Push PC	Content of program counter is saved in stack
Pop PC	Content of stack is returned to program counter
Null	No operation

2. Instruction Description

The machine instruction of TLCS-46A consists of 52 kinds of instruction, being divided roughly into 6 kinds as follows:

Machine Instruction (52 kinds)	—	Data Transfer Instruction (19 kinds)
	—	Operation Instruction (18 kinds)
	—	Bit manipulation Instruction (3 kinds)
	—	Branch Instruction (3 kinds)
	—	Interrupt/Subroutine Instruction (3 kinds)
	—	Other Instruction (1 kinds)

In this paragraph, the function of each instruction is described according to the following instruction description format.

Assembler mnemonic	Instruction name	Execution cycle		
	Machine code			
	Function	Z flag after execu- tion	C flag after execu- tion	EYR after execution
	Operation description			

Instruction Description Format

(1) Data Transfer Instruction

The data transfer instruction mainly provides the data transfer among accumulator, status register, memory (RAM), and registers.

Load Accumulator from Register	
LAR R	<div> <div>7</div> <div>0</div> <div>0</div> <div>0</div> <div>0</div> <div>1</div> <div>0</div> <div>R</div> <div>0 ≤ R ≤ 7</div> <div>1</div> </div>
(AC) ← (R)	
The content of register or input port designated by R field is loaded in accumulator.	



INTEGRATED CIRCUIT

TECHNICAL DATA

TCP4620AP
TCP4630AP



L T R R	Load Accumulator from Register and Test										1	
	7	0										
	0	0	0	1	1	R			$0 \leq R \leq 7$			
(AC) \leftarrow (R)										*	-	0
The content of register or input port designated by R field is loaded in accumulator. After execution Z flag is updated.												
L A M	Load Accumulator from Memory										1	
	7	0										
	0	0	0	0	0	1	0	0				
(AC) \leftarrow (M)										-	-	0
The content of memory is loaded in accumulator Note 1												
L T M	Load Accumulator from Memory and Test										1	
	7	0										
	1	0	0	0	0	1	1	1				
(AC) \leftarrow (M)										*	-	0
The content of memory is loaded in accumulator. After execution Z flag is updated. Note 1												

		Load Status-register from Memory	
L S M	7	0	
	0	0	1
	0	0	0
(ST) ← (M)		Note 3 *	Note 3 *
		The content of memory is loaded in status register. Note 1	
		Load Accumulator from L-register	
L A L	7	0	
	0	0	1
	0	0	0
(AC) ← (LR)		-	-
		The content of L register is loaded in accumulator.	
		Load Accumulator from H-register	
L A H	7	0	
	0	0	1
	0	0	0
(AC) ← (HR)		-	-
		The content of H register is loaded in accumulator.	
		Load Accumulator Immediate	
L A I	7	0	
	0	1	0
	0	0	0
(AC) ← I		-	-
		The value of I field is set to accumulator.	



INTEGRATED CIRCUIT

TECHNICAL DATA

TCP4620AP
TCP4630AP

LLI	I	Load L-register Immediate												
		7	0 1 1 0						I	0	0 ≤ I ≤ 15	1		
		(LR) ← I										-	-	0
		The value of I field is set to L register.												
LHI	I	Load H-register Immediate												
		7	0 1 1 1						I	0	0 ≤ I ≤ 15	1		
		(HR) ← I										-	-	0
		The value of I field is set to H register.												
LYI	I	Load Y-register Immediate												
		7	0 1 0 1						I	0	0 ≤ I ≤ 15	1		
		(YR) ← I										-	-	1
		The value of I field is set to Y register. After execution, y register flag is set to "1".												
SAR	R	Store Accumulator to Register												
		7	0 0 1 0 1						R	0	0 ≤ R ≤ 7	1		
		(R) ← (AC)										-	-	0
		The content of accumulator is stored in the register designated by R field.												



INTEGRATED CIRCUIT

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TECHNICAL DATA

INTEGRATED CIRCUIT
TCP4620AP
TCP4630AP

S A M	Store Accumulator to Memory		
	7 0 0 0 0 1 1 0 0 0		1
	(M) ← (AC)	-	-
The content of accumulator is stored in memory. Note 1, Note 2			
S S M	Store Status-register to Memory		
	7 0 0 0 0 1 1 0 1 0		1
	(M) ← (ST)	-	-
The content of status register is stored in memory Note 1, Note 2			
S A L	Store Accumulator to L-register		
	7 0 0 0 0 1 1 1 0 0		1
	(LR) ← (AC)	-	0
The content of accumulator is stored in L register			
S A H	Store Accumulator to H-register		
	7 0 0 0 0 1 1 1 1 0		1
	(HR) ← (AC)	-	0
The content of accumulator is stored in H register.			



INTEGRATED CIRCUIT

TECHNICAL DATA

TCP4620AP
TCP4630AP

		Store Accumulator to Y-register													
S	A	Y	7								0				
			0	0	0	0	1	0	0	0	0	1			
		(YR) + (AC)										-	-	1	
		The content of accumulator is stored in Y register. After execution, Y register flag is set to "1".													
		Store Y-register to Register													
S	Y	R	7								0				
			0	0	1	1	0		R		$4 \leq R \leq 7$	1			
		(R) + (YR)										-	-	0	
		The content of Y register is stored in register designated by R field.													
		Clear Register													
C	L	R	7								0				
			0	0	1	0	0		R		$0 \leq R \leq 7$	1			
		(R) + 0 ($0 \leq R \leq 4$)										-	-	0	
		"0" is written in the register designated by R field ($0 \leq R \leq 4$). For $5 \leq R \leq 7$, decode matrix output or PLA output corresponding to data "0" is written in the register.													



INTEGRATED CIRCUIT

TECHNICAL DATA

TCP4620AP

TCP4630AP

(2) Operation Instruction

Operation instruction has 2 operand instruction and 1 operand instruction, and performs arithmetic operation and logical operation.

		Add Accumulator Immediate											
ADI	I	<div><div>7</div><div>0</div><div>1</div><div>0</div><div>0</div><div>1</div><div>I</div><div>0 ≤ I ≤ 15</div></div>											1
		(AC) ← (AC) + I										*	*
		The value of I field is added to the content of accumulator. After execution of instruction, Z flag and C flag are updated.											
		Add and Store to Accumulator											
A D A		<div><div>7</div><div>0</div><div>1</div><div>0</div><div>0</div><div>0</div><div>0</div><div>0</div><div>0</div><div>0</div></div>											1
		(AC) ← (M) + (AC)										*	*
		The content of accumulator is added to the content of memory, and the result is loaded in accumulator. After execution of instruction, Z flag and C flag are updated.											
		Add and Store to Memory											
A D M		<div><div>7</div><div>0</div><div>1</div><div>0</div><div>0</div><div>0</div><div>1</div><div>0</div><div>0</div><div>0</div></div>											1
		(M) ← (M) + (AC)										*	*
		The content of accumulator is added to the content of memory, and the result is stored in memory. After execution of instruction, Z flag and C flag are updated. Note 1, Note 2											
		Add with Carry and Store to Accumulator											
A C A		<div><div>7</div><div>0</div><div>1</div><div>0</div><div>0</div><div>0</div><div>0</div><div>0</div><div>0</div><div>1</div></div>											1
		(AC) ← (M) + (AC) + (C)										*	*
		The content of accumulator and the content of C flag are added to the content of memory, and the result is loaded in accumulator. After execution of instruction, Z flag and C flag are updated. Note 1											



INTEGRATEDCIRCUIT

TECHNICAL DATA

TCP4620AP

TCP4630AP

Add with Carry and Store to Memory	
ACM	<div>7 0</div> <div>1 0 0 0 1 0 0 1</div> <div>$(M) \leftarrow (M) + (AC) + (C)$</div> <div>The content of accumulator and the content of C flag are added to the content of memory, and the result is stored in memory. After execution of instruction, Z flag and C flag are updated. Note 1, Note 2</div>
Subtract and Store to Accumulator	
SUA	<div>7 0</div> <div>1 0 0 0 0 0 1 0</div> <div>$(AC) \leftarrow (M) - (AC)$</div> <div>The content of accumulator is subtracted from the content of memory, and the result is loaded in accumulator. After execution of instruction, Z flag and C flag are updated. Note 1</div>
Subtract and Store to Memory	
SUM	<div>7 0</div> <div>1 0 0 0 1 0 1 0</div> <div>$(M) \leftarrow (M) - (AC)$</div> <div>The content of accumulator is subtracted from the content of memory, and the result is stored in memory. After execution of instruction, Z flag and C flag are updated. Note 1, Note 2</div>
Or and Store to Accumulator	
ORA	<div>7 0</div> <div>1 0 0 0 0 1 0 0</div> <div>$(AC) \leftarrow (M) \vee (AC)$</div> <div>The logical sum of every bit of the content of memory and the content of accumulator is loaded in accumulator. After execution of instruction, Z flag is updated. Note 1</div>

O R M	Or and Store to Memory			
	7	0		1
	1	0	0	0
E O A	$(M) \leftarrow (M) \vee (AC)$			
	The logical sum of every bit of the content of memory and the content of accumulator is stored in memory. After the execution of instruction, Z flag is updated. Note 1, Note 2			
	Exclusive-or and Store to Accumulator			
E O M	7	0		1
	1	0	0	0
	1	0	0	1
C M A	$(AC) \leftarrow (M) \oplus (AC)$			
	The exclusive OR of every bit of the content of memory and the content of accumulator is loaded in accumulator. After execution of instruction, Z flag is updated. Note 1			
	Exclusive-or and Store to Memory			
E O M	7	0		1
	1	0	0	0
	1	0	0	1
C M A	$(M) \leftarrow (M) \oplus (AC)$			
	The exclusive OR of every bit of the content of memory and the content of accumulator is stored in memory. After execution of instruction, Z flag is updated. Note 1, Note 2			
	Complement Accumulator			
C M A	7	0		1
	1	0	0	0
	1	0	0	1
C M A	$(AC) \leftarrow \overline{(AC)}$			
	The content of accumulator is inverted every bit. After execution of instruction, Z flag is updated.			



INTEGRATEDCIRCUIT

TECHNICAL DATA

TCP4620AP

TCP4630AP

C M M	Complement Accumulator and Store to Memory		
	7 1 0 0 0 1 1 1 0 0		1
	$(M) \leftarrow \overline{(AC)}$ The content of accumulator is inverted every bit, and the result is stored in memory. After execution of instruction, Z flag is updated. Note 1, Note 2		
I C A	Load Accumulator and Increment		
	7 1 0 0 0 0 0 1 1 0		1
	$(AC) \leftarrow (M) + 1$ "1" is added to the content of memory, and the result is loaded in accumulator. After execution of instruction, Z flag and C flag are updated. Note 1.		
I C M	Increment Memory		
	7 1 0 0 0 1 0 1 1 0		1
	$(M) \leftarrow (M) + 1$ "1" is added to the content of memory. After execution of instruction, Z flag and C flag are updated. Note 1, Note 2		
I C L	Increment L-register		
	7 0 0 0 0 0 0 1 0 0		1
	$(LR) \leftarrow (LR) + 1$ "1" is added to the content of L register.		

I C H	Increment H-register			
	7 0	0 0 0 0 0 0 1 1		1
	$(HR) \leftarrow (HR) + 1$		-	0
	"1" is added to the content of H register.			
T S M	Test Memory			
	7 0	1 0 0 0 1 1 1 1		1
	$(M) \leftarrow (M)$		*	-
	Z flag is set according to the content of memory. Note 1, Note 2			

(3) Bit Manipulation Instruction

The bit manipulation instruction is performed to each bit of accumulator or status register.

T B A G	Test a bit for Accumulator			
	7 0	1 0 0 1 0 0 0 0 G	$0 \leq G \leq 3$	1
	$Null \leftarrow (AC) \wedge 2^G$		*	-
	The Z flag is updated, according to the bit of accumulator designated by G field.			



INTEGRATED CIRCUIT

TECHNICAL DATA

INTEGRATED CIRCUIT
TCP4620AP
TCP4630AP

		Tast a bit for Status-register												
TBS	G	<div>7<div>101100</div>0</div> <div>G</div> <div>$0 \leq G \leq 3$</div>										1		
		Null $\leftarrow (ST) \wedge 2^G$										*	-	0
		The Z flag is updated, according to the bit of status register designated by G field.												
		Set a bit for Accumulator												
SBA	G	<div>7<div>101001</div>0</div> <div>G</div> <div>$0 \leq G \leq 3$</div>										1		
		$(AC) \leftarrow (AC) \vee 2^G$										-	-	0
		The bit of accumulator designated by G field is set to "1".												
		Set a bit for Status-register												
SBS	G	<div>7<div>101101</div>0</div> <div>G</div> <div>$0 \leq G \leq 3$</div>										1		
		$(ST) \leftarrow (ST) \vee 2^G$										Note 3 *	Note 3 *	0
		The bit of status-register designated by G field is set to "1".												
		Clear a bit for Accumulator												
CBA	G	<div>7<div>101010</div>0</div> <div>G</div> <div>$0 \leq G \leq 3$</div>										1		
		$(AC) \leftarrow (AC) \wedge 2^G$										-	-	0
		The bit of accumulator designated by G field is cleared to "0".												

Clear a bit for Status register			
CBS G	7 0	0 ≤ G ≤ 3	1
	1 0 1 1 1 0 G		
	(ST) ← (ST) ∧ 2 ^G		
The bit of status register designated by G field is cleared to "0".		Note 3 *	Note 3 *
		0	
Invert a bit for Accumulator			
IBA G	7 0	0 ≤ G ≤ 3	1
	1 0 1 0 1 1 G		
	(AC) ← (AC) ∨ 2 ^G		
The bit of accumulator designated by G field is inverted.		-	-
		0	
Invert a bit for Status register			
IBS G	7 0	0 ≤ G ≤ 3	1
	1 0 1 1 1 1 G		
	(ST) ← (ST) ∨ 2 ^G		
The bit of status register designated by G field is inverted.		Note 3 *	Note 3 *
		0	



INTEGRATEDCIRCUIT

TECHNICAL DATA

TCP4E20AP

TCP4E30AP



(4) Branch instruction

The branch instruction performs unconditional or conditional branch.

Jump				
JMP AP	<div>70158</div> <div><div>1110</div><div>APL</div><div>AP_H</div><div>AP_M</div></div> <div>0 ≤ AP ≤ 4095</div>	2		
	(PC) ← AP	-	-	0
The value of AP field is set to program counter. After execution of instruction, therefore, program sequence changes to the AP address.				
Branch on Condition Set				
BCS AP	<div>70158</div> <div><div>1100</div><div>APL</div><div>AP_H</div><div>AP_M</div></div> <div>0 ≤ AP ≤ 4095</div>	2		
	If Z = 1 then (PC) ← AP, else Null	-	-	0
The content of Z flag is "1", the value of AP field is set to program counter. After execution of instruction, therefore, program sequence changes to the AP address. If the content of Z flag is "0", the program sequence follows the next address without any operation.				
Branch on Condition Clear				
BCC AP	<div>70158</div> <div><div>1101</div><div>APL</div><div>AP_H</div><div>AP_M</div></div> <div>0 ≤ AP ≤ 4095</div>	2		
	If Z = 0 then (PC) ← AP, else Null	-	-	0
The content of Z flag is "0", the value of AP field is set to program counter. After execution of instruction, therefore, program sequence changes to the AP address. If the content of Z flag is "1", the program sequence follows the next address without any operation.				

(5) Interrupt/Subroutine Instruction

The interrupt/subroutine instruction is used for performing a call of subroutine and a return from interrupt routine or subroutine.

In addition NOP instruction is available as one other instruction.

CAL AP	Call Subroutine												2
	<div><div>7</div><div>015</div><div>8</div></div> <div><div>1</div><div>1</div><div>1</div><div>1</div><div>1</div><div>AP_L</div><div>AP_H</div><div>AP_M</div><div>1</div></div> <div>0 ≤ AP ≤ 4095</div>												
	push (PC), and (PC) ← AP												
The content (the next address) of program counter is stored in the stack, and the value of AP field is set to the program counter. The interrupt is placed in disable (queued) state during execution of subroutine.													
RTN	Return												2
	<div><div>7</div><div>0</div></div> <div><div>0</div><div>0</div><div>0</div><div>0</div><div>0</div><div>0</div><div>0</div><div>0</div><div>1</div></div>												
	POP (PC)												
The content of the stack is restored to program counter. After execution of instruction, the interrupt is placed in enable state													
JAC	Jump by Accumulator												2
	<div><div>7</div><div>0</div></div> <div><div>0</div><div>0</div><div>0</div><div>0</div><div>1</div><div>0</div><div>0</div><div>1</div><div>1</div></div>												
	(PC) ← (PC) + 1, and (PC) ← (PC) < 11:4 > ◦ (AC)												
The content (address where JAC instruction is stored, plus 2) of the incremented program counter is taken as the higher 8 bits, and the content of AC is taken as the lower 4 bits; then, the value of 12 bits in total that these contents are connected is set to the program counter.													
NOP	No Operation												1
	<div><div>7</div><div>0</div></div> <div><div>0</div><div>0</div><div>0</div><div>0</div><div>0</div><div>0</div><div>0</div><div>0</div><div>0</div></div>												
	Null												
This is an instruction by which nothing is executed. However, Y register flag is reset to "0".													

3. LIST OF INSTRUCTIONS

	Mnemonic	Machine code		Operation	Update of flag	Remarks
		Hexa-decimal	Binary			
Data Transfer Instruction	LAR	11	00010iii	(AC)+(Register iii)		
	LTR	11	00011iii	(AC)+(Register iii)	Z	
	LAM	04	00000100	(AC)+(M)		
	LTM	87	10000111	(AC)+(M)	Z	
	LSM	05	00000101	(ST)+(M)	ZC	
	LAL	06	00000110	(AC)+(LR)		
	LAH	07	00000111	(AC)+(HR)		
	LAI	41	01001iii	(AC)+iii		
	LLI	61	01101iii	(LR)+iii		
	LHI	71	01111iii	(HR)+iii		
	LYI	51	01011iii	(YR)+iii		EYR is set
	SAR	21	00101iii	(Register iii)+(AC)		
	SAM	0C	00001100	(M) + (AC)		
	SSM	0D	00001101	(M) + (ST)		
	SAL	0E	00001110	(LR)+(AC)		
	SAH	0F	00001111	(HR)+(AC)		
	SAY	08	00001000	(YR)+(AC)		EYR is set
	SYR	31	00110111	(Register 111)+(YR)		
	CLR	21	00100iii	(Register iii)+0		
Operation Instruction	ADI	91	10011iii	(AC)+(AC)+iii	ZC	
	ADA	80	10000000	(AC)+(M)+(AC)	ZC	
	ADM	88	10001000	(M) + (M)+(AC)	ZC	
	ACA	81	10000001	(AC)+(M)+(AC)+(C)	ZC	
	ACM	89	10001001	(M) + (M)+(AC)+(C)	ZC	
	SUA	82	10000010	(AC)+(M)-(AC)	ZC	
	SUM	8A	10001010	(M) + (M)-(AC)	ZC	
	ORA	84	10000100	(AC)+(M)∨(AC)	Z	
	ORM	8C	10001100	(M) + (M)∨(AC)	Z	
	EOA	85	10000101	(AC)+(M)∨(AC)	Z	
	EOM	8D	10001101	(M) + (M)∨(AC)	Z	
	CMA	86	10000110	(AC)+ $\overline{(AC)}$	Z	
	CMM	8E	10001110	(M) + $\overline{(AC)}$	Z	
	ICA	83	10000011	(AC)+(M)+1	ZC	
	ICM	8B	10001011	(M) + (M)+1	ZC	
	ICL	02	00000010	(LR)+(LR)+1		
	ICH	03	00000011	(HR)+(HR)+1		
	TSM	8F	10001111	(M)+(M), if (M)=0 then Z+1 else Z+0	Z	

	Mnemonic	Machine code		Operation	Update of flag	Remarks
		Hexa-decimal	Binary			
Bit Manipulation Instruction	TBA	<u>Ai</u>	101000ii	if (AC)<ii>=0 then Z+1 eles Z+0	Z	
	TBS	<u>Bi</u>	101100ii	if (ST)<ii>=0 then Z+1 eles Z+0	Z	
	SBA	<u>Ai</u>	101001ii	(AC)<ii>+1		Asteris (*) denotes that, when Z flag and C flag are designated, the fags are updated.
	SBS	<u>Bi</u>	101101ii	(ST)<ii>+1	**	
	CBA	<u>Ai</u>	101010ii	(AC)<ii>+0		
	CBS	<u>Bi</u>	101110ii	(ST)<ii>+0	**	
	IBA	<u>Ai</u>	101011ii	(AC)<ii>+(AC)<ii>		
	IBS	<u>Bi</u>	101111ii	(ST)<ii>+(ST)<ii>	**	
Branch Instruction and Others	JMP	Ek	1110kkkk	(PC)+iiiijjjjkkkk		2-byte, 2-cycle instruction
		ij	iiiijjjj			
	BCS	Ck	1100kkkk	if Z=1 then (PC)+iiiijjjjkkkk		"
		ij	iiiijjjj			
	BCC	Dk	1101kkkk	if Z=0 then (PC)+iiiijjjjkkkk		"
		ij	iiiijjjj			
	CAL	Fk	1111kkkk	(PC)+, (PC)+iiiijjjjkkkk		"
		ij	iiiijjjj			
	RTN	01	00000001	(PC)+		1-byte, 2-cycle instruction
	JAC	09	00001001	(PC)+((PC)+1)<11:4>*(AC)		"
	NOP	00	00000000	No Operation		EYR is reset.

Note: Pay attention to the conversion of the underlined machine codes.

4. TLCS-46A Instruction map

L H	0	1	2	3	4	5	6	7	8	9	A	B	C	D	E	F
0	NOP	*1 RTN	ICL	ICH	LAM	LSM	LAL	LAH	SAY	*1 JAC			SAM	SSM	SAL	SAH
1				LAR									LTR			
2				CLR									SAR			
3						SYR										
4							LAI									
5								LYI								
6								LLI								
7								LHI								
8	ADA	ACA	SUA	ICA	ORA	EOA	CMA	LTM	ADM	ACM	SUM	ICM	ORM	EOM	CMH	TSM
9																
A		TBA				SBA					CBA				IBA	
B		TBS				SBS					CBS				IBS	
C																
D																
E																
F																

*1 - 1 byte, 2-cycle instruction

*2 - 2 byte, 2-cycle instruction

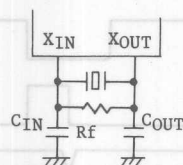
[OPERATION DESCRIPTION]

1. Basic Clock

The basic clock is used to generate the basic timing signals for the operation of TLCS-46A and as the clock for the divider.

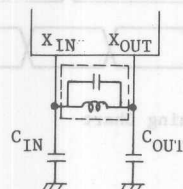
For the generation and supply of basic clock, there are following methods:

(1) Connecting crystal oscillator/ceramic oscillator



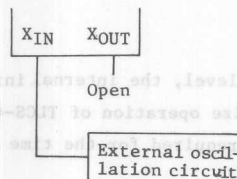
In case the crystal oscillator/ceramic oscillator is connected as shown in the left figure, it is possible to obtain the oscillation frequency characteristic to crystal oscillator/ceramic oscillator.

(2) Connecting IFT



In case the IFT is connected as shown in the left figure, it is possible to obtain the oscillation frequency characteristic to IFT.

(3) Supplying the external clock



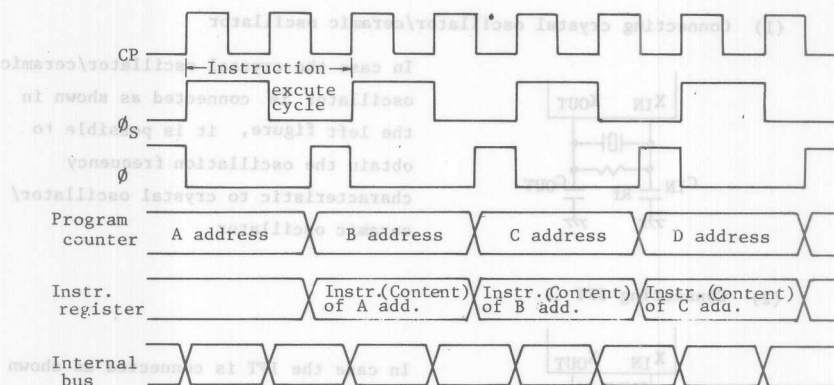
If the external oscillator is connected to XIN terminal as shown in the left figure, it is possible to supply the clock from the external.

In this case, XOUT terminal shall be kept open.

2. Instruction Execute Cycle

The instruction execute cycle consists of two internal timing signals, ϕ_S and ϕ , supplied by the timing generator.

ϕ_S is the signal expressing the instruction execute cycle, while ϕ is the signal which comes to the set timing of data memory, register, etc.

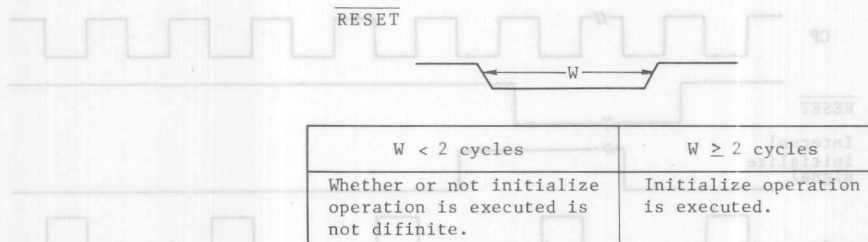


Instruction Execution Timing Chart

3. Initialize operation (System initialization)

The initialize operation is carried out without fail after impressing power source on TLC5-46A, which is returned to the initial state in the interior.

By keeping the RESET terminal to "L" level, the internal initialize signal is formed, whereby the initialize operation of TLC5-46A is executed. At this time, more than 2 cycles are required for the time of "L" level.



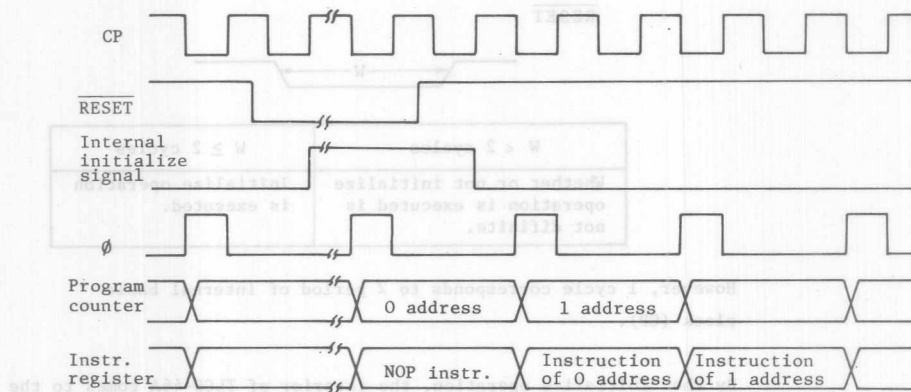
However, 1 cycle corresponds to 2 period of internal basic clock (CP).

By the initialize operation, the interior of TLCS-46A comes to the conditions as given below:

- ① Resetting H flag and D flag of status register to "0".
- ② Resetting the interrupt latch to "0".
- ③ Resetting the port register "0".
(All output pins come to "L" level.)
- ④ Setting the stack flag to "1".
- ⑤ Setting the program counter to 0 address.

There is no influence on accumulator, data memory, H register, L register, Y register, C flag and Z flag of status register, etc.

The program is executed from 0 address when RESET signal comes to "H" level and the internal initialize signal comes to "L" level.



Start from initialization

4. Interrupt Operation

TLCS-46A is provided with the function permitting the external interrupt operation. The interruption is an operation enabling other processing to be preferentially made by suspending the processing underway.

The request for interrupt operation is made by changing INT terminal from "H" level to "L" level and by holding the terminal on "L" level for more than 2 cycles.

There are several conditions enabling TLCS-46A to start the interrupt operation. If the interrupt operation request is made before the conditions are satisfied, the interrupt operation is in standby state to wait until the conditions are satisfied.

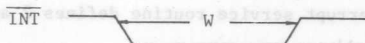
The conditions are as follows:

- ① Data memory is not made reference with Y register.
(EYR = 0)
- ② Stack is empty. (FSTK = 0)
- ③ No hold operation (Interrupt request is ignored in hold operation.)

The external interrupt request signal is preserved in the internal interrupt latch, and the interrupt latch is cleared when the interrupt is accepted.

In case of repetitive interrupt request, it is required to make $\overline{\text{INT}}$ terminal "H" level (more than 2 cycles) and to make $\overline{\text{INT}}$ terminal "L" level. Repetitive interrupt request is not accepted when $\overline{\text{INT}}$ terminal is "L" level without making it "H" level.

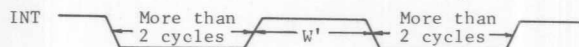
① Internal latch set timing



$W < 2 \text{ cycles}$	$W \geq 2 \text{ cycles}$
Whether or not interruption latch is set is not definite.	Interruption latch is set

However, 1 cycle corresponds to 2 period of internal basic clock (CP).

② Internal latch repetitive set timing



$W' = 0$	$0 < W' < 2$ cycles	$W' \geq 2$ cycles
Interruption latch is not set again.	Whether or not interruption latch is set again is not definite.	Interruption latch is set again

However, 1 cycle corresponds to 2 period of internal basic clock (CP).

When TLCS-46A accepts the interrupt, the following processings are made:

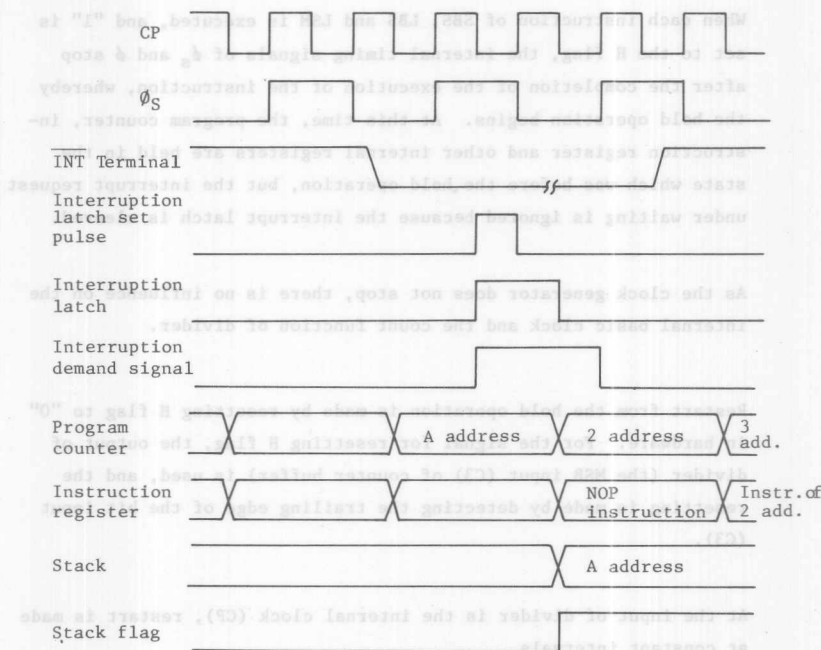
- 1 The content of program counter is stored in a save register (stack).
- 2 The entry address (address 2) is set in the program counter.
- 3 The interrupt latch is cleared.

Therefore, the interrupt service routine defines 2 address of program memory as the top address.

When TLCS-46A returns to the main program by completing the interrupt process, it follows the execution of RTN instruction.

Whether or not interruption latch is set	Whether or not interruption latch is set
--	--





Interrupt Acceptance Timing Chart

5. Hold Operation

In case the hold operation is designated by mask options, the operation state (normal/hold) of TLCS-46A is controlled by the H flag of status register.

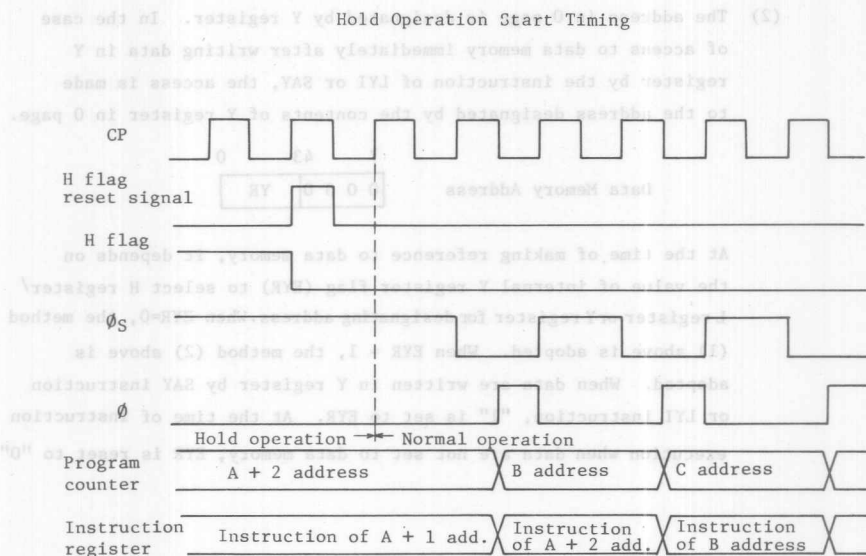
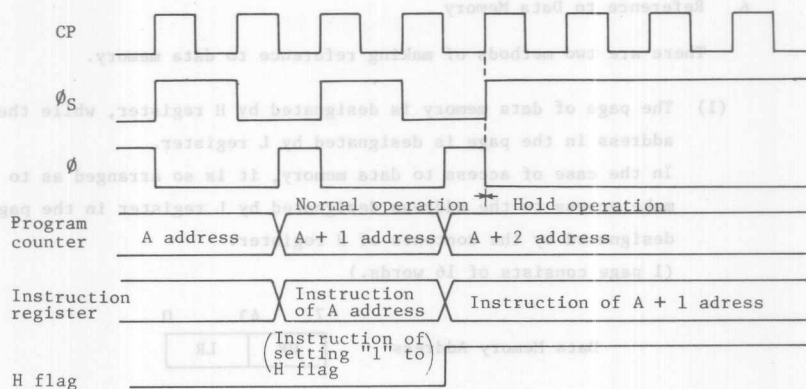
When each instruction of SBS, LBS and LSM is executed, and "1" is set to the H flag, the internal timing signals of ϕ_s and ϕ stop after the completion of the execution of the instruction, whereby the hold operation begins. At this time, the program counter, instruction register and other internal registers are held in the state which was before the hold operation, but the interrupt request under waiting is ignored because the interrupt latch is cleared.

As the clock generator does not stop, there is no influence on the internal basic clock and the count function of divider.

Restart from the hold operation is made by resetting H flag to "0" in hardware. For the signal for resetting H flag, the output of divider (the MSB input (C3) of counter buffer) is used, and the resetting is made by detecting the trailing edge of the bit input (C3).

At the input of divider is the internal clock (CP), restart is made at constant intervals.

When H flag is reset, the internal timing signals of ϕ_s and ϕ start, whereby the execution is continued to start from the condition which is the same as that just before starting the hold operation.



Restart Timing from Hold Operation

6. Reference to Data Memory

There are two methods of making reference to data memory.

- (1) The page of data memory is designated by H register, while the address in the page is designated by L register.

In the case of access to data memory, it is so arranged as to make access to the address designated by L register in the page designated by the contents of H register.

(1 page consists of 16 words.)

Data Memory Address

7	43	0
HR	LR	

- (2) The address in 0 page is designated by Y register. In the case of access to data memory immediately after writing data in Y register by the instruction of LYI or SAY, the access is made to the address designated by the contents of Y register in 0 page.

Data Memory Address

7	43	0
0 0 0 0	YR	

At the time of making reference to data memory, it depends on the value of internal Y register flag (EYR) to select H register/L register or Y register for designating address. When EYR=0, the method (1) above is adopted. When EYR = 1, the method (2) above is adopted. When data are written in Y register by SAY instruction or LYI instruction, "1" is set to EYR. At the time of instruction execution when data are not set to data memory, EYR is reset to "0".

7. Input and Output Timing for Port

The input of data from the input port of TLCS-46A and the output of data to the output port are made by the data transfer instruction between accumulator and each port.

Port Input

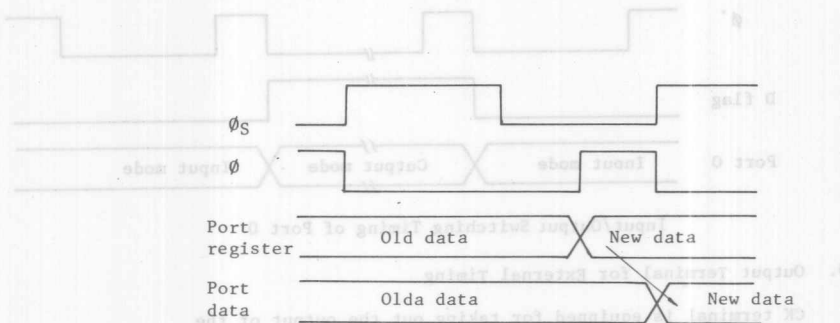
As the input ports of TLCS-46A are all non-latch inputs, the input data is required to be stable until the completion of reading.

At the instruction cycle of LAR or LTR instruction, input data is set to the accumulator.

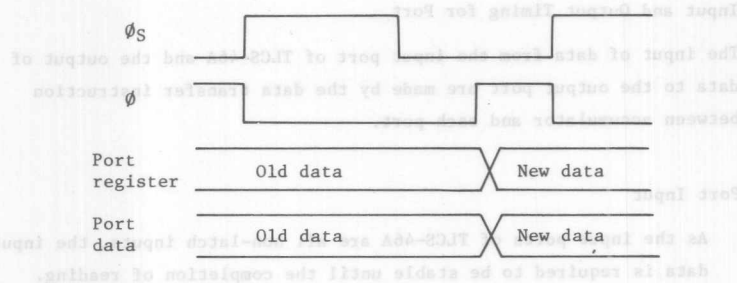
Port Output

The output ports of TLCS-46A output the content of port register. Data are written in the port register when SAR, SYR and CLR instructions are executed.

The digit output port (P05) and segment output port (P06) for display are different in output timing from other output ports.



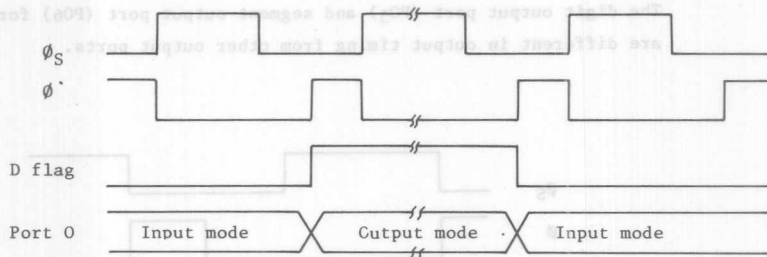
Output Timing (Port5, Port6)



Output Timing (except Port5, Port6)

8. Input/Output Switching of Port 0

The switching of input/output of port 0 is made by the D flag of status register. By each instruction of SBS, CBS, IBS and LSM, the value of D flag is changed, whereby the switching of input/output is carried out.



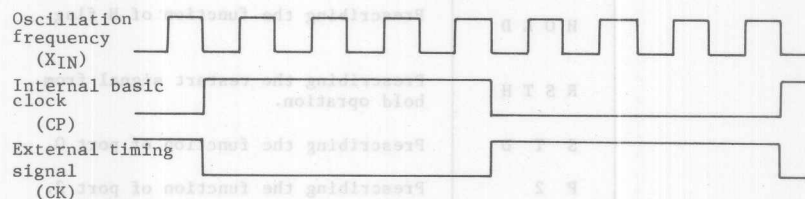
Input/Output Switching Timing of Port 0

9. Output Terminal for External Timing

CK terminal is equipped for taking out the output of the divider of clock generator.

The output frequency is designated by the mask options but is decided by the oscillator (oscillation frequency) used. The output frequency is either 1/32 or 1/64 of oscillation frequency or internal basic clock (CP).

The output signal on CK terminal is generated after inverting the phase of the output of divider.



Example of the internal basic clock and external timing waveform.

The internal basic clock (CP) is 1/4 of the oscillation frequency. The external timing signal is CP.

[Mask Options]

TCP4620AP/TCP4630AP have many kinds of mask options on the clock generator, input output ports, etc. so as to meet the extensive requirements from the users.

Option Name	Function
O S C	Prescribing the oscillator and oscillation frequency.
C P	Prescribing the dividing ratio for obtaining the internal basic clock.

Option Name	Function
C K	Prescribing the output frequency for the external timing.
COUNTER	Prescribing the reset timing of divider.
COUNTER BUFFER	Prescribing the input of counter buffer.
H O L D	Prescribing the function of H flag.
R S T H	Prescribing the restart signal from hold operation.
S T D	Prescribing the function of port 0.
P 2	Prescribing the function of port 2.
P 4	Prescribing the function of port 4.
P I 5	Prescribing the function of input resistance of port 5.
DECODER	Prescribing the contents of decode matrix.
P O 6	Prescribing the function of port 6.
P L A	Prescribing the contents of PLA.

(Note) o The mask options of OSC-RSTH are decided by the oscillator (oscillation frequency) used.

- o Use the designation paper for mask options which is attached to the ES order sheet.
- o Submit to us the designation paper for mask options together with the ES order sheet by the data two weeks prior to the date of submitting the mask tape.



INTEGRATED CIRCUIT

TECHNICAL DATA

TCP4620AP
TCP4630AP



1. Designation of Mask Options

Option Item		Option Name	TYP001	TYP002	TYP003	TYP004	TYP005	TYP006
Oscillation frequency		OSC	003 32.76K Xtal	012 100K Xtal	050 400-500K ceramic /IFT	050 400K ceramic /IFT	400 3-4.2K Xtal	400 3-4.2K Xtal
Dividing ratio for internal clock		CP	00	00	04	02	64	32
External timing output		CK	32	64	CP	CP	CP	CP
Counter-Buffer	Divider 1 Input	PD	CP	CP	CP	CP	CP	CP
	Divider 3 Input	Counter PDR	PD2	PD2	PD2	PD2	PD2	PD2
	Reset timing	PDR	N	/12500/	N	N	N	N
	Buffer 0 Input	C0	PI ₆₀	PI ₆₀	PI ₆₀	PI ₆₀	PI ₆₀	PI ₆₀
	Buffer 1 Input	Counter C1	RD9	RDB	RDB	RD7	RDA	RD7
Buffer	Buffer 2 Input	Buffer C2	RDA	RDC	RDC	RDA	RDB	RDA
	Buffer 3 Input	C3	RDB	RDD	RDD	RDD	RDC	RDD
H flag		HOLD	H	H	H	0	0	0
Restart condition		RSTH	C3	C3	C3	0	0	0
Input/Output port		Port 0	STD	D(PROG)	1(OUT)			
I/O port	Port 2	P2	/F/(OUT)	/F/(OUT)	/O/(IN)	/O/(IN)	/O/(IN)	
	Port 4	P4	/F/(OUT)	/3(IN/OUT)	/F/(OUT)	/3(IN/OUT)	/O/(IN)	
Input resistance (Input port 5)		PI5	0(UP)	1(DOWN)				
Decode matrix	Line 0	DECO	/	/				
	Line 1	DEC1	/	/				
	Line 2	DECODER DEC2	/	/				
	Line 3	DEC3	/	/				
	Line 4	DEC4	/	/				
Output port 6/7		PO6	1(P6/P7)	0(P6)				
P L A	Line 0	PLA0	/ 00 /	/ / /				
	Line 1	PLA1	/ 11 /	/ / /				
	Line 2	PLA2	/ 22 /	/ / /				
	Line 3	PLA3	/ 33 /	/ / /				
	Line 4	PLA4	/ 44 /	/ / /				
	Line 5	PLA5	/ 55 /	/ / /				
	Line 6	PLA6	/ 66 /	/ / /				
	Line 7	PLA7	/ 77 /	/ / /				
	Line 8	PLA8	/ 88 /	/ / /				
	Line 9	PLA9	/ 99 /	/ / /				
	Line A	PLAA	/ AA /	/ / /				
	Line B	PLAB	/ BB /	/ / /				
	Line C	PLAC	/ CC /	/ / /				
	Line D	PLAD	/ DD /	/ / /				
	Line E	PLAE	/ EE /	/ / /				
	Line F	PLAF	/ FF /	/ / /				

Note 1: As to each option item, one of the thick frames horizontally lined shall be selected. (The whole thick frame is enclosed with a circule.)

Note 2: Please enter the data entry mode (decode matrix, PLA) by yourself.

Note 3: The formal name of option is that naming continuously the option name and the data in the designation column of option.

(1) OSC - RSTH Options		Option Name					
OSC-RSTH options can construct six kinds of combination. However, it is impossible to use the options by changing the combinations.		Name of Option	TYP 001	TYP002	TYP 003	TYP 004	TYP 005
		OSC	003	012	050	050	400
		CP	00	00	04	02	64
		CK	32	64	CP	CP	CP
		PD	CP	CP	CP	CP	CP
		COUNTER PDR	PD2	PD2	PD2	PD2	PD2
		PDR	N	/1250Q	N	N	N
		CO	PL ₀	PL ₀	PL ₀	PL ₀	PL ₀
		COUNTER C1	RD9	RDB	RD7	RDA	RD7
		BUFFER C2	RDA	RDC	RDA	RDB	RDA
		C3	RDB	RDD	RDD	RDC	RDD
		HOLD	H	H	0	0	0
		RSTH	C3	C3	0	0	0

① OSC: Prescribing the oscillator and oscillation frequency.

- o OSC003 - 32.768 KHz oscillation by Xtal oscillator.
- o OSC012 - 100 KHz oscillation by Xtal oscillator.
- o OSC050 - 400 KHz (400K~500KHz) oscillation by ceramic oscillator or IFT.
- o OSC400 - 4194.304 KHz oscillation by Xtal oscillator.

Note (1): It is possible to make driving from the external oscillator by opening XOUT terminal and by arranging XIN terminal for input.

Note (2): The formal name of option is that naming continuously the option name and the data in the designation column of option.

- ② CP: Prescribing the frequency dividing ratio for obtaining the internal basic clock.

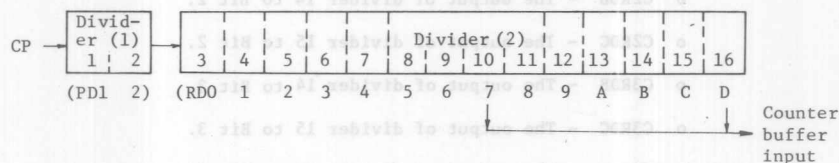
- o CP00 - Oscillation signal is made to clock.
- o CP02 - Signal of dividing oscillation frequency into 2.
- o CP04 - Signal of dividing oscillation frequency into 4.
- o CP32 - Signal of dividing oscillation frequency into 32.
- o CP64 - Signal of dividing oscillation frequency into 64.

- ③ CK: Prescribing the output frequency for external timing

- o CK32 - Signal of dividing oscillation frequency into 32.
- o CK64 - Signal of dividing oscillation frequency into 64.
- o CKCP - Signal of the internal basic clock frequency.

- ④ COUNTER: Dividers

The divider consists of 16-stage divider and can be disassembled into the basic construction of the front 2 stages [divider (1)] and the rear 14 stages [divider (2)].



- o PDCP - Setting the input of divider (1) to the internal basic clock (CP).
- o PDRPD2 - Setting the input of divider (2) to the output of divider (1).
- o PDRN - Setting the function of divider (1) and divider (2) as the usual binary counters.
- o PDR/12500/- This is the designation only at the time of use of 100K Xtal. When the count value of divider (2) is "12500", the divider (2) is reset to return the count value to "0".

⑤ COUNTER BUFFER : Prescribing the input of counter buffer

The counter buffer is composed of 4 bits, which are marked C0, C1, C2 and C3 from LSB side (Bit 0).

- o C0PI60 - PI60 terminal input to Bit 0.
- o C1RD7 - The output of divider 10 to Bit 1.
- o C1RD9 - The output of divider 12 to Bit 1.
- o C1RDA - The output of divider 13 to Bit 1.
- o C1RDB - The output of divider 14 to Bit 1.
- o C2RDA - The output of divider 13 to Bit 2.
- o C2RDB - The output of divider 14 to Bit 2.
- o C2RDC - The output of divider 15 to Bit 2.
- o C3RDB - The output of divider 14 to Bit 3.
- o C3RDC - The output of divider 15 to Bit 3.
- o C3RDD - The output of divider 16 to Bit 3.

⑥ HOLD, RSTH: Prescribing the function of H flag and the signal for restart from the hold state.



- o HOLDH - Hold control is carried out by H flag.
- o HOLDO - No hold is maintained. H flag is capable of being used as the general flag.
- o RSTHC3 - Interlocking with HOLDH. Counter buffer bit 3 is used as the hold restart signal.
- o RSTHO - Interlocking with HOLDO. No hold is maintained.

(2) STD-PI5 Options

STL-PI5 options prescribe the state of input/output of port. It is possible to independently designate STD and PI5 options respectively.

Option names	Designation of option				
STD	D(PROG)	1 (OUT)			
P2	/F/(OUT)	/F/(OUT)	/O/(IN)	/O/(IN)	/O/(IN)
P4	/F/(OUT)	/3/(IN/OUT)	/F/(OUT)	/3/(IN/OUT)	/O/(IN)
PI5	O(UP)	1(DOWN)			

- ① STD: Prescribing the function of port 0.
 - o STDD - Switching input/output of port 0 is made according to the contents of D flag.
 - o STD1 - Using as the output of port 0. In this case, D flag can be used as the general flag.
- ② P2, P4: Prescribing the function of port 2 and port 4.

Port 2 and port 4 are the 4-bit ports to which the input or the output can be designated.

The 4-bit ports are expressed by the one-figure numeric characters of hexadecimal digit by defining the input as "0" and the output as "1" for each bit.



INTEGRATEDCIRCUIT

TECHNICAL DATA

TC4620AP

TC4630AP



(Example)

(MSB)

(LSB)

Bit 3 2 1 0

0	0	1	1
---	---	---	---

0 : Input
1 : Output

Hexadecimal = 3

o P2/F/, P4/F/ - Prescribing both port 2 and port 4 as the output.

o P2/F/, P4/3/ - Prescribing the upper 2 bits of port 4 the input, with the others being the output.

o P2/0/, P4/F/ - Prescribing port 2 as the input and port 4 as the output.

o P2/0/, P4/3/ - Prescribing the lower 2 bits of port 4 as the output, with the others being the input.

o P2/0/, P4/0/ - Prescribing both port 2 and port 4 as the input.

③ P15: Prescribing the function of the input resistance at port 5.

o PI50 - Input port 5 comes to the input with pull-up resistance.

o PI51 - Input port 5 comes to the input with pull-down resistance.

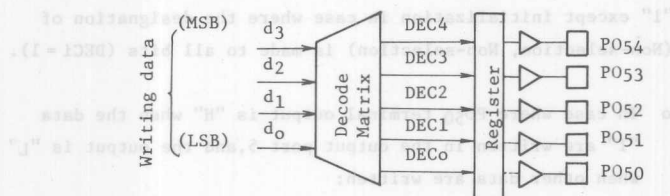
(3) DECODER - PLA Options

The decoder and PLA options are the data writing mode in which user designates the data. P06 option is used according to the function of PLA.

Option Names	Designation of Options	
DECODER	Data writing mode	
P06	1 (P6/P7)	0 (P6)
PLA	General output port	Data writing mode

1-1 DECODER: Prescribing the contents of decode matrix.

Operation processing and internal data are processed with 4 bits. However, at the output port 5, 5-bit data are produced as the output after the conversion into 5 lines by the decode matrix.



The following explanation is made for the purpose of explaining the contents of decode matrix and has no direct relations with the design patterning in the actual LSI. Give your kind attention to this point.

The logic of decode matrix can be expressed by the following formula. (See the above diagram.)

$$\left[\begin{array}{l} \text{DEC}i = D_3 \cdot D_2 \cdot D_1 \cdot D_0 \quad (i = 0-4) \\ \text{Where, the selection is practicable as to} \\ D_j (j = 0-3) = d_j \text{ or } \overline{d_j} \text{ or } 1 \end{array} \right]$$

As to the designation of decode matrix, it is possible to define the selection as "1", to define non-selection as "0", and to express $\overline{d}_3, d_3, \overline{d}_2, d_2, \overline{d}_1, d_1, \overline{d}_0, d_0$ as the continuous 8-bit data (\overline{d}_3 shall be MSB) with the figures of hexadecimal two digits.

\bar{d}_3, d_3	\bar{d}_2, d_2	\bar{d}_1, d_1	\bar{d}_0, d_0	
x	x	x	x	x = 1 (Selection) or 0 (Non-selection)
Hexadecimal two digits				

Note: $D_j = \bar{d}_j \rightarrow (\bar{d}_j, d_j) = (\text{Selection}, \text{Non-selection}) = (1, 0)$

$D_j = d_j \rightarrow (\bar{d}_j, d_j) = (\text{Non-selection}, \text{Selection}) = (0, 1)$

$D_j = 1 \rightarrow (\bar{d}_j, d_j) = (\text{Non-selection}, \text{Non-selection}) = (0, 0)$

It is meaningless to select both \bar{d}_j and d_j

Attention shall be given to the fact that the output comes to "1" except initialization in case where the designation of (Non-selection, Non-selection) is made to all bits (DECI=1).

- o In case where PO₅₀ terminal output is "H" when the data "1" are written in the output port 5, and the output is "L" when other data are written:

Logic: $\text{DECO} = \bar{d}_3 \cdot \bar{d}_2 \cdot \bar{d}_1 \cdot d_0$

Designation: $\text{DECO} = \begin{bmatrix} \bar{d}_3 & d_3 & \bar{d}_2 & d_2 & \bar{d}_1 & d_1 & \bar{d}_0 & d_0 \\ 1 & 0 & 1 & 0 & 1 & 0 & 0 & 1 \end{bmatrix} = \text{'X' A9'}$

- o In case where PO₅₄ terminal output is "H" when the data "C" "F" are written in the output port 5, and the output is "L" when other data are written:

Logic: $\text{DEC4} = d_3 \cdot d_2$

Designation: $\text{DEC4} = \begin{bmatrix} \bar{d}_3 & d_3 & \bar{d}_2 & d_2 & \bar{d}_1 & d_1 & \bar{d}_0 & d_0 \\ 0 & 1 & 0 & 1 & 0 & 0 & 0 & 0 \end{bmatrix} = \text{'X' 50'}$

- o In the case of PO₅₁ terminal when the output of data written in the output port 5 is desired:

Logic: $DEC = d1$

Designation: $DEC1 = \begin{bmatrix} \overline{d3} & \overline{d3} & \overline{d2} & d2 & \overline{d1} & d1 & \overline{d0} & d0 \\ 0 & 0 & 0 & 0 & 0 & 1 & 0 & 0 \end{bmatrix} = X' 04$

* Refer to the examples of data designation.

* Refer to the examples of data designation.

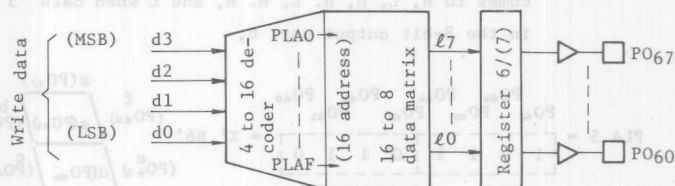
② P06: Prescribing the function of port 6.

- o P060 - Port 6 is used as the 8-bit PLA data output port.
- o P061 - Port 6 is used as the two 4-bit general output port.

(No designation can be made as to the contents of PLA.)

③ PLA: Prescribing the contents of PLA.

Operation processing and internal data are processed with 4 bits. However, at the output port 6, 8-bit data are produced as the output after the conversion into 8 lines by PLA.



The following explanation is made for the purpose of explaining the contents of PLA and has no direct relations with the design patterning in the actual LSI.

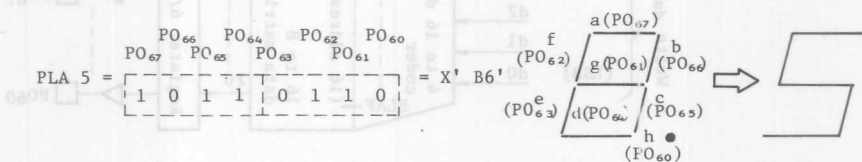
Give your kind attention to this point.

PLA can be expressed as the 16 words x 8 bits memory. (Refer to the above diagram.) Namely, the 4-bit write data is the address of PLA, and the 8-bit data read out from PLA comes to the output data on the output port terminals.

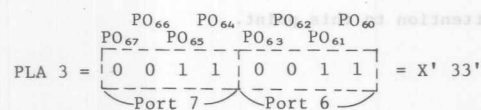
Write data	Address	Write data	Address	Write data	Address	Write data	Address
0	PLA0	4	PLA4	8	PLA8	12	PLAC
1	PLA1	5	PLA5	9	PLA9	13	PLAD
2	PLA2	6	PLA6	10	PLAA	14	PLAE
3	PLA3	7	PLA7	11	PLAB	15	PLAF

The designation of PLA data is made to addresses by expressing the 8-bit data, which are MSB in PO₆₇ terminal output and LSB in PO₆₀ terminal output, with 2-figure numeric characters of hexadecimal digit.

- o In case each output between PO₆₇ terminal and PO₆₀ terminal comes to H, L, H, H, L, H, H, and L when data "5" are written in the 8-bit output port 6,



- o In case data "3" are written in output port 6 or output port 7 to use it as the 4-bit general output port,



Therefore, if data "3" are written in output port 7, each output between P067 terminal and P064 terminal comes to L, L, H, and H. At this time, each input to register 6 (connected to P063 terminal- P060 terminal) comes likewise to 0, 0, 1, and 1, but each output does not change because no setting is made to the register. This applies to the reverse case comes likewise.

- o Refer to the examples of the designation of data.

Examples of the Designation of Data for Decode Matrix and PLA

	Examples of General port	Examples of 5-1 Fig. dynamic indication	General port	Examples of segment display
Logic	DECO = d0	DECO = $\overline{d3} \overline{d2} \overline{d1} d0$	PLA 0 = /00/	PLA 0 = /FC/
	DEC1 = d1	DEC1 = $\overline{d3} \overline{d2} d1 \overline{d0}$	PLA 1 = /11/	PLA 1 = /60/
	DEC2 = d2	DEC2 = $\overline{d3} \overline{d2} d1 d0$	PLA 2 = /22/	PLA 2 = /DA/
	DEC3 = d3	DEC3 = $\overline{d3} d2 \overline{d1} \overline{d0}$	PLA 3 = /33/	PLA 3 = /F2/
	DEC4 = $\overline{d3}$	DEC4 = $\overline{d3} d2 \overline{d1} d0$	PLA 4 = /44/	PLA 4 = /66/
Designated Data	DECO = /01/	DECO = /A9/	PLA 5 = /55/	PLA 5 = /B6/
	DEC1 = /04/	DEC1 = /A6/	PLA 6 = /66/	PLA 6 = /BE/
	DEC2 = /10/	DEC2 = /A5/	PLA 7 = /77/	PLA 7 = /E4/
	DEC3 = /40/	DEC3 = /9A/	PLA 8 = /88/	PLA 8 = /FE/
	DEC4 = /80/	DEC4 = /99/	PLA 9 = /99/	PLA 9 = /F6/
			PLA A = /AA/	PLA A = /FD/
			PLA B = /BB/	PLA B = /00/ (blank)
			PLA C = /CC/	PLA C = /02/
			PLA D = /DD/	PLA D = /CE/
			PLA E = /EE/	PLA E = /9E/
			PLA F = /FF/	PLA F = /8E/

(Evaluator built-in option)

(Evaluator built-in option)

MASK ROM DATA TAPE FORMAT

.....	Leader	Output of more than 50 characters of "NULL" (No other symbols than "NULL" should be existent.)
'COMMENT' (CR) (LF) Comment	Output of six characters starting from the beginning of character train defined by TTL statement of source program and two characters of serial number, with apostrophe. (when no TTL statement exist, output of six characters of space code and two characters of serial number.)
N8 ; (CR) (LF)	Output of "N8" indicating that the data pattern is 8 bits long. (The program data follow this code.)
RXXXX ;	Output of the program start address following "R" in four frames of decimal ASCII code.
XXX Px ;	1st address data and check sum
XXX Px ;	2nd address data and check sum
XXX Px ;	8th address data and check sum
RXXXX ;	9th program address
XXX Px ;	9th address data and check sum
(CR) (LF)		Repeated output through the last data
\$	Output of indicating the end of program data
		Trailer: Output of more than 50 characters of "NULL".

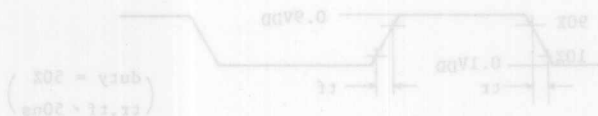
ELECTRICAL CHARACTERISTICS

ABSOLUTE MAXIMUM RATINGS

SYMBOL	ITEM	RATING
V _{DD}	Supply Voltage	-0.3V to +7.0V
V _{IN}	Input Voltage	-0.3V to V _{DD} + 0.3V
V _{OUT}	Output Voltage	-0.3V to V _{DD} + 0.3V
P _D	Power Dissipation	600 mW
T _{sol}	Soldering Temperature	260°C (10 SEC)
T _{stg}	Storage Temperature	-55°C to +125°C
T _{opr}	Operating Temperature	-30°C to +85°C

ALLOWABLE OPERATING CONDITIONS

SYMBOL	ITEM	Condition	
		V _{DD} = 3V to 6V	V _{DD} = 4V to 6V
T _a	Ambient Temperature	-30°C to +85°C	-30°C to 85°C
V _{OH}	Output High Voltage	Min. V _{DD} - 3.5V (≥1.5V)	Min. V _{DD} - 3.5V (≥1.5V)
V _{OL}	Output Low Voltage	Max. 3V	Max. 3V
f _x	Xtal Operating Frequency	20KHz to 2MHz	20KHz to 4.2MHz
t _{cy}	Cycle Time	40μs to 100μs	10μs to 100μs



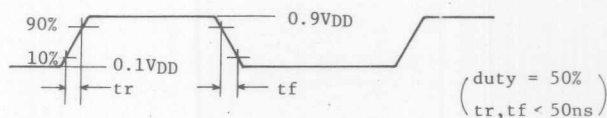
DC CHARACTERISTICS (Ta=-30°C to +85°C, VDD=3V to 6V)

SYMBOL	PARAMETER	TEST CONDITION	MIN.	TYP. (Note 1)	MAX.	UNIT
V _{IH}	Input High Voltage	VDD ≥ 4V	VDD×0.75	-	VDD	V
V _{IHS}	Input High Voltage (Schmitt)	VDD ≥ 4V	VDD×0.7	VDD×0.55	VDD	
V _{IHC}	Input High Voltage(X _{IN} Input)		VDD×0.9	VDD×0.75	VDD	
V _{IHL}	Input Low Voltage		VDD×0.85	-	VDD	
V _{IILS}	Input Low Voltage (Schmitt)	VDD ≥ 4V	VDD×0.75	-	VDD	
V _{IILC}	Input Low Voltage (X _{IN} Input)		0	VDD×0.45	VDD×0.3	
I _{IH}	Input High Current	VDD=6V, V _{IN} =6V	0	VDD×0.35	VDD×0.1	μA
I _{IL}	Input Low Current	VDD=6V, V _{IN} =0V	0	-	VDD×0.15	
R _{IN}	Input Resistance (PI5)	VDD=5V	0	-	VDD×0.25	kΩ
V _{OH}	Output High Voltage	VDD=5V, Output Open	4.7	4.9	-	V
V _{OL}	Output Low Voltage		-	0.1	0.3	
I _{OH}	Output High Current	VDD=4.5V, V _{OH} =2.4V	-0.7	-2	-	mA
I _{OH1}	Output High Current (P05, P06)	VDD=5V, V _{OH} =4.2V	-2.5	-6	-	
I _{OL}	Output Low Current	VDD=4.5V, V _{OL} =0.45V	-1.1	-2.5	-	
I _{OL1}	Output Low Current (P05,P06)		1.6	4	-	
I _{DDO}	VDD Supply Current in	VDD=6V V _{IN} =5.9V/0.1V (All valid)	3.5	8	-	μA
	(fx=32.8 KHz)		-	50	300	
	(fx=100 KHz)		-	150	450	
	Normal Operation		-	400	1200	
I _{DIH}	(fx=4.19 MHz)	PI5 Open C _L = 50pF (Note 3)	-	1000	3000	
	VDD Supply Current in		-	15	80	
	Hold		-	40	120	
	Operation		-	150	450	

Note 1: Typical values are at Ta=25°C and VDD=5V.

Note 2: Output characteristic excludes X_{OUT} terminal.

Note 3: X_{IN} input waveform at the time of measuring VDD supply current.



AC CHARACTERISTICS ($T_a = -30^\circ\text{C}$ to $+85^\circ\text{C}$, $V_{DD} = 3\text{V}$ to 6V)

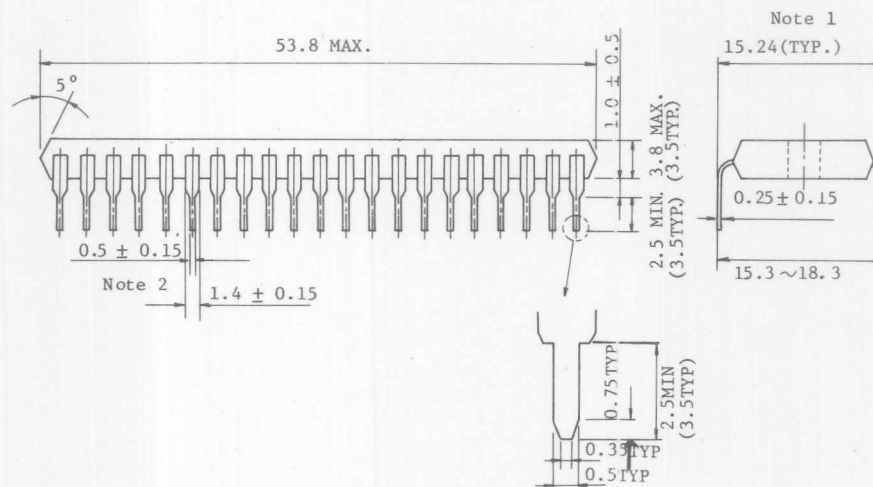
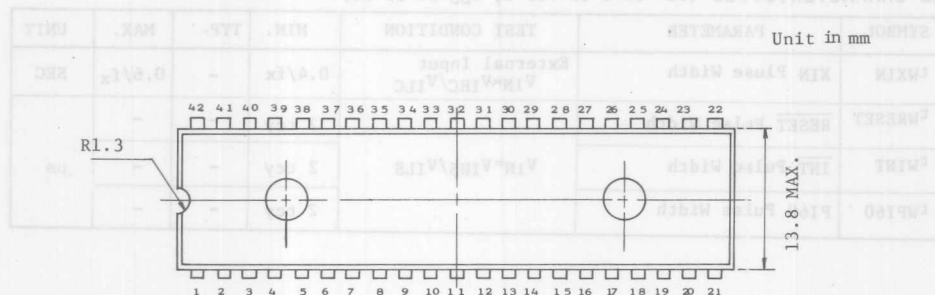
SYMBOL	PARAMETER	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
t_{WXIN}	XIN Pulse Width	External Input $V_{IN} = V_{IHC}/V_{ILC}$	$0.4/f_x$	-	$0.6/f_x$	SEC
t_{WRESET}	RESET Pulse Width	$V_{IN} = V_{IHS}/V_{ILS}$	$2 t_{cy}$	-	-	μs
t_{WINT}	INT Pulse Width		$2 t_{cy}$	-	-	
t_{WPI60}	PI60 Pulse Width		$2 t_{cy}$	-	-	



Note 1: This dimension is measured at the center of bending point of leads.

Note 2: Each lead pitch is 1.27mm, and all the leads are located within ±0.12mm from their theoretical positions with respect to No.1 and No.62 leads.

OUTLINE DRAWINGS



Note 1: This dimension is measured at the center of bending point of leads.

Note 2: Each lead pitch is 2.54mm, and all the leads are located within ±0.25mm from their theoretical positions with respect to No.1 and No.42 leads.



INTEGRATEDCIRCUIT

TECHNICAL DATA

"C²MOS" DIGITAL INTEGRATED CIRCUIT

TCP4620AF
TCP4630AF

SILICON MONOLITHIC

CMOS 4-BIT SINGLE CHIP MICROCOMPUTER

This is the specification for TCP4620AF/TCP4630AF in the TLCS-46A family.

TCP4620AF/TCP4630AF is a flat package version of TCP4620AP/TCP4630AP. There are some differences in electrical characteristics between TCP4620AF/TCP4630AF and TCP4620AP/TCP4630AP; however, their function, instruction, and pin description are compatible.

When using and examining TCP4620AF/TCP4630AF, therefore, it is recommended that this specification be used together with the technical data on TCP4620AP/TCP4630AP.

The differences in electrical characteristics between the two are as follows:

ITEM	SYMBOL
1. Power Dissipation	$P_D = 400 \text{ mW MAX}$
2. Operating Temperature and Ambient Temperature	$T_{opr} = -20 \text{ to } 70^\circ\text{C}$ $T_a = -20 \text{ to } 70^\circ\text{C}$



INTEGRATEDCIRCUIT

TECHNICAL DATA

INTEGRATEDCIRCUIT
TCP4620AF
TCP4630AF
TECHNICAL DATA

TCP4620AF /TCP4630AF ELECTRICAL CHARACTERISTICS

ABSOLUTE MAXIMUM RATINGS

SYMBOL	ITEM	Rating
V _{DD}	Supply Voltage	-0.3V to +7.0V
V _{IN}	Input Voltage	-0.3V to V _{DD} +0.3V
V _{OUT}	Output Voltage	-0.3V to V _{DD} +0.3V
P _D	Power Dissipation	400mW
T _{sol}	Soldering Temperature	260°C(10 SEC)
T _{stg}	Storage Temperature	-55°C to +125°C
T _{opr}	Operating Temperature	-20°C to +70°C

ALLOWABLE OPERATING CONDITION

SYMBOL	ITEM	Condition	
		V _{DD} =3V to 6V	V _{DD} =4V to 6V
T _a	Ambient Temperature	-20°C to +70°C	-20°C to +70°C
V _{OH}	Output High Voltage	Min. V _{DD} -3.5V(>1.5V)	Min. V _{DD} -3.5V(>1.5V)
V _{OL}	Output Low Voltage	Max. 3V	Max. 3V
f _x	Xtal Operating Frequency	20KHz to 2MHz	20KHz to 4.2MHz
t _{cy}	Cycle Time	40μs to 100μs	10μs to 100μs

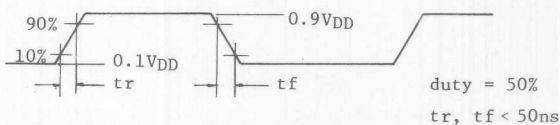
DC CHARACTERISTICS (Ta=-20°C to 70°C, VDD=3V to 6V)

SYMBOL	PARAMETER	TEST CONDITION	MIN.	TYP. (Note 1)	MAX.	UNIT
V _{IH}	Input High Voltage	VDD ≥ 4V	VDDx0.75	-	VDD	V
V _{IHS}	Input High Voltage (Schmitt)	VDD ≥ 4V	VDDx0.7	VDDx0.55	VDD	
V _{IHC}	Input High Voltage (X _{IN} Input)	VDD ≥ 4V	VDDx0.85	-	VDD	
V _{IL}	Input Low Voltage		0	VDDx0.45	VDDx0.3	
V _{ILS}	Input Low Voltage (Schmitt)	VDD ≥ 4V	0	VDDx0.35	VDDx0.1	
V _{ILC}	Input Low Voltage (X _{IN} Input)		0	-	VDDx0.25	
I _{IH}	Input High Current	VDD=6V, V _{IN} =6V	-	-	20	μA
I _{IL}	Input Low Current	VDD=6V, V _{IN} =0V	-	-	-20	
R _{IN}	Input Resistance (PI5)	VDD=5V	75	150	350	KΩ
V _{OH}	Output High Voltage	VDD=5V, Output Open	4.7	4.9	-	V
V _{OL}	Output Low Voltage		-	0.1	0.3	
I _{OH}	Output High Current	VDD=4.5V, V _{OH} =2.4V	-0.7	-2	-	mA
I _{OH1}	Output High Current (PO5, PO6)	VDD=5V, V _{OH} =4.2V	-2.5	-6	-	
I _{OL}	Output Low Current		-1.1	-2.5	-	
I _{OL1}	Output Low Current (PO5, PO6)	VDD=4.5V, V _{OL} =0.45V	1.6	4	-	
I _{DDO}	VDD Supply Current in Normal Operation	(fx=32.8 KHz)	3.5	8	-	μA
		(fx=100 KHz)	-	50	300	
		(fx=400 KHz)	-	150	450	
		(fx=4.19 MHz)	-	400	1200	
I _{DDH}	VDD Supply Current in Hold Operation	PI5 Open	-	1000	3000	
		(fx=32.8 KHz)	-	15	80	
		(fx=100 KHz)	-	40	120	
		(fx=400 KHz)	-	150	450	

Note 1: Typical values are at Ta=25°C and VDD=5V.

Note 2: Output characteristic excludes X_{OUT} terminal.

Note 3: X_{IN} input waveform at the time of measuring VDD Supply Current.



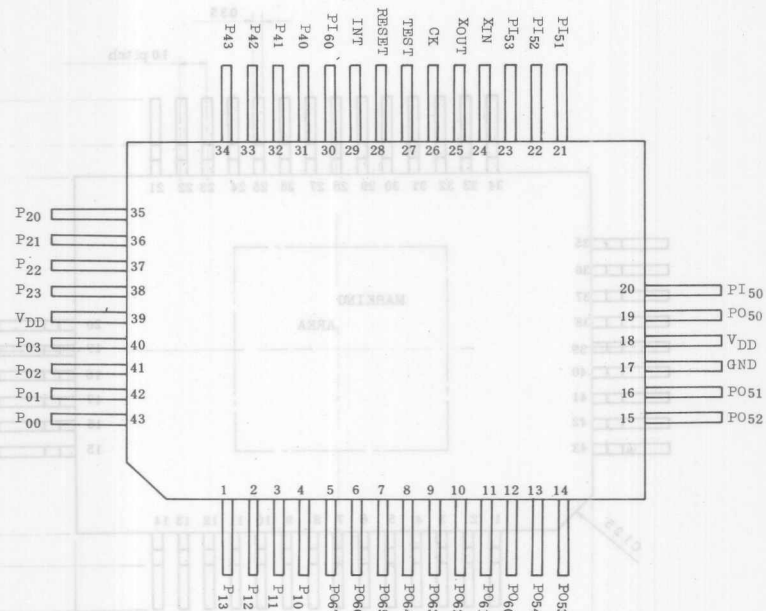
AC CHARACTERISTICS ($T_a = -20^{\circ}\text{C}$ to $+70^{\circ}\text{C}$, $V_{DD} = 3\text{V}$ to 6V)

SYMBOL	PARAMETER	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
t_{WXIN}	XIN Pluse Width	External Input $V_{IN}=V_{IHC}/V_{ILC}$	0.4/f _x	—	0.6/f _x	SEC
t_{WRESET}	\overline{RESET} Pulse Width	$V_{IN}=V_{IHS}/V_{ILS}$	2 tcy	—	—	μs
t_{WINT}	\overline{INT} Pulse Width		2 tcy	—	—	
t_{WPI60}	PI60 Pulse Width		2 tcy	—	—	

Note: Flat packages have a merit in assembly space, but they should be installed in better humidity and temperature environment than

DIP's.

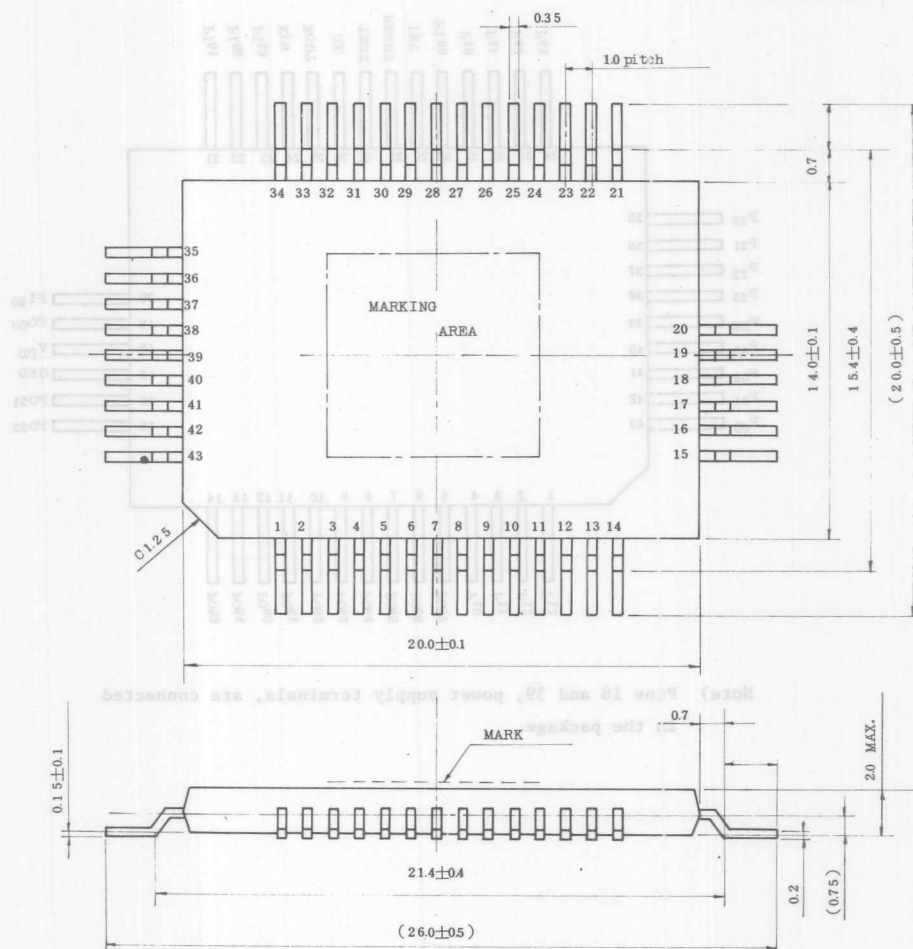
PIN CONNECTIONS (TOP VIEW)



Note) Pins 18 and 39, power supply terminals, are connected in the package.

OUTLINE DRAWINGS

Unit in mm



CMOS 4-BIT SINGLE CHIP MICROCOMPUTER

GENERAL DESCRIPTION

This is the specification for TCP4620BP in TLCS-46A family.

TCP4620BP is one version of TLCS-46A developed for the purpose of reducing the power consumption at hold operation so as to correspond to the applications having utilized the features of a CMOS microcomputer. TCP4620BP has realized the following characteristics.

Supply Current in hold operation $I_{DDHS} \text{ TYP.} = 0.1\mu\text{A} (V_{DDHS} = 2\text{V})$

Hold voltage in hold operation $V_{DDHS} = 2\text{V to } 6\text{V}$

TCP4620BP is a version of TCP4620AP to which the oscillation control (stop/start) function of a clock generator in hold operation has been added. There are some differences in function, pin description, electrical characteristics, and mask option concerning hold operation and oscillation control between TCP4620BP and TCP4620AP; however, other functions, electrical characteristics, instructions, and pin connections are compatible.

When using and examining TCP4620BP, therefore, it is recommended that this specification be used together with the technical data on TCP4620AP.

Main differences with TCP4620AP are as follows:

1. Function

- o In hold operation, the input level of PI60 terminal makes possible the oscillation control (stop/start) of the oscillator, and the oscillation stop enables the power consumption to be reduced.

Supply Current in hold operation (Oscillation stop)

$I_{DDHS} \text{ TYP.} = 0.1\mu\text{A} (T_a = 25^\circ\text{C}, V_{DDHS} = 2\text{V})$

Hold Voltage in hold operation (Oscillation stop)

$V_{DDHS} = 2\text{V to } 6\text{V}$

2. Pin Description

- o In hold operation, PI60 terminal will function as an oscillation control terminal.

PI60 = "H" Oscillation stop

PI60 = "L" Oscillation start (Continued.)

- o In either case of normal operation/hold operation, PI60 terminal is the reset input terminal of the divider (2).

PI60 = "H" The divider (2) is reset.

PI60 = "L" The divider (2) is not reset. (Reset is released.)

- o No Schmitt circuits are built in the following two terminals:

PI60, INT

3. Mask Option

The contents only indicated on the mask option sheet of TCP4620BP can be designated.. 400 KHz ceramic oscillator/IFT oscillator can be used.

PIN NAMES AND PIN DESCRIPTION

Pin Name	Input/Output	Function
P03 P00	Input/Output	4-bit general purpose I/O port (I/O is designated by a programme). Can be used as a dedicated output port. (Designated by mask options.)
P13 P10	Output	4-bit general purpose output port.
P23 P20	Input or Output	4-bit general purpose Input/Output port. Input/Output is design ted by mask options.
P43 P40	Input or Output	
P54 P50	Output	5-digit output port for display. (Can be used as the general purpose output port.)
P67 P60	Output	8-segment output port for display. (Can be used as the general purpose 8-bit output port (4-bit x 2))
PI53 PI50	Input	4-bit general purpose input port.
PI60*	Input	1-bit general purpose input port/reset input of divider(2) [Note 1] (without Schmitt circuit). During hold operation this input functions as an input for stopping the oscillation and for controlling restart of the oscillator. *
RESET	Input	Reset signal input
INT	Input	Interrupt request signal input (without Schmitt circuit).
XIN	Input	Oscillator connecting terminal.
XOUT	Output	Oscillator connecting terminal.
CK	Output	External timing output.
TEST	Input	LSI test signal input, used by connection to GND.
VDD		Power Supply
GND		GND

Note 1) In either case of normal operation or hold operation, the divider (2) is reset at "H" level input.

Note 2) * denotes the differences between TCP4620BP and TCP4620AP/TCP4630AP.

HOLD OPERATION

The hold operation of TCP4620BP is performed by setting "1" to H flag. In other words, immediately when "1" is set to H flag by execution of SBS, IBS, and LSM instructions, the internal timing signals ϕ_s and ϕ are stopped and TCP4620BP begins hold operation. (Refer to Figs. 1 and 3.)

During hold operation the program counter, instruction register, data memory, and other internal registers hold the contents stored before hold operation. However, the interrupt latch is cleared during hold operation, the waiting interrupt request and a new interrupt request are ignored.

The oscillation of oscillator is suspended by holding PI60 terminal to "H" level during hold operation, so that the power consumption may be saved greatly. That is, while $H \text{ flag} \wedge PI60 = 1$, the oscillation is suspended. (Refer to Fig. 3.)

TCP4620BP is restarted from hold operation due to reset of H flag to "0" by the rising signal of the counter buffer C2 bit.

Since the counter buffer is the output of the divider (2) which is counting the internal basic clock (cp), TCP4620BP is restarted at regular intervals if oscillation is not suspended during hold operation. (Refer to Fig. 2.) This is the same operation as the hold operation of TCP4620AP/TCP4630AP. (However, there is a difference in nothing but restart condition by mask option between them.)

When the oscillation is suspended during hold operations, restart operation begins in the lapse of a certain period of time after a start of oscillation by holding PI60 terminal to "L" level. (Refer to Fig. 4.) Special attention should be paid to the fact that in TCP4620BP the divider (2) is reset to "0" by holding PI60 terminal to "H" level.

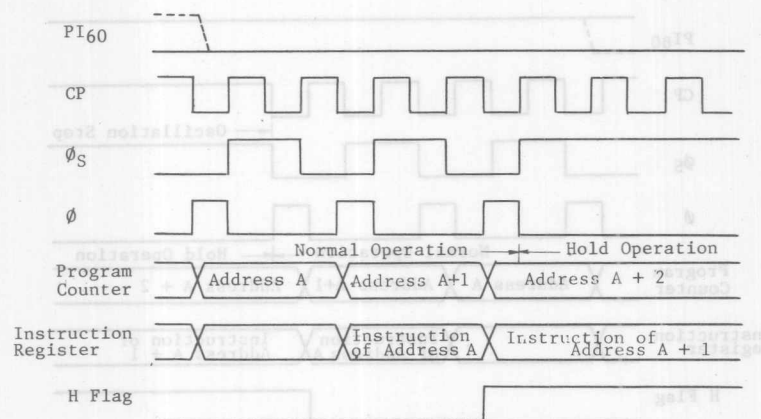


Fig. 1 Timing to Hold Operation (Oscillation Continuity)

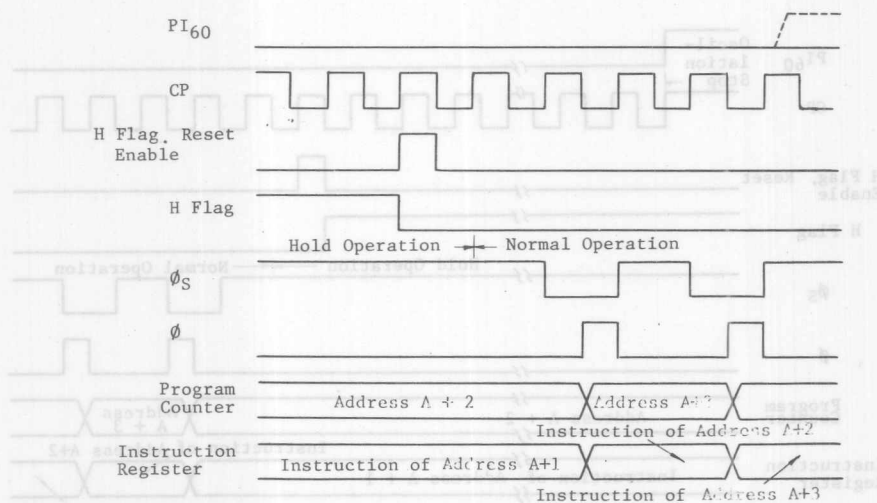


Fig. 2 Restart Timing from Hold Operation (Oscillation Continuity)

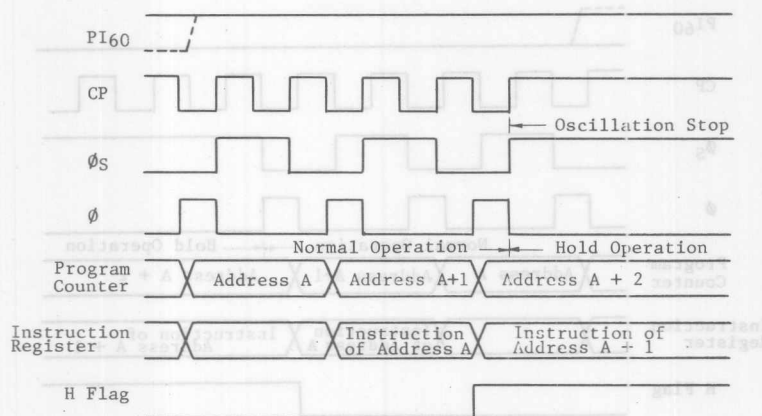


Fig. 3 Timing to Hold Operation (Oscillation Stop)

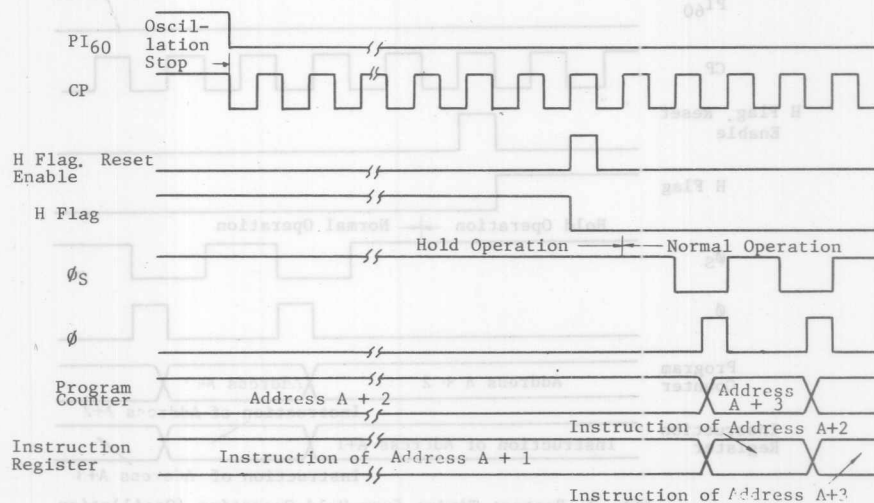


Fig. 4 Restart Timing from Hold Operation (Oscillation Stop)

TCP4620BP MASK OPTION

		TYP011	
Oscillating Frequency	OSC	0.50 400K Ceramic IFT	
Frequency division for internal clock	CP	02	
Ext. timing output	CK	CP	
Divider 1 input	PD	CP	
COUNTER Divider 3 input	COUNTER PDR	PD2	
Reset Timing	PDR	N	
Buffer 0 input	CO	PI60	
COUNTER Buffer 1 input	COUNTER C1	RD7	
BUFFER Buffer 2 input	BUFFER C2	RDA	
Buffer 3 input	C3	RDD	
H Flag	HOLD	H	
Restart Signal	RSTH	C2 Rise	
I/O Port Port 0	STD	D(PROG)	1 (OUT)
Input/Output Port 2	P2	/F/(OUT)	/F/(OUT)
port Port 4	P4	/F/(OUT)	/3/(IN/OUT)
Input resistance (input port 5)	PI5	0 (UP)	1 (DOWN)
Line 0	DECO	/	/
Line 1	DEC1	/	/
Line 2	DEC2	/	/
Line 3	DEC3	/	/
Line 4	DEC4	/	/
Output Port 6/7	P06	1(P6/P7)	0 (P6)
Line 0	PLA0	/ 0 0 /	/ /
Line 1	PLA1	/ 1 1 /	/ /
Line 2	PLA2	/ 2 2 /	/ /
Line 3	PLA3	/ 3 3 /	/ /
Line 4	PLA4	/ 4 4 /	/ /
Line 5	PLA5	/ 5 5 /	/ /
Line 6	PLA6	/ 6 6 /	/ /
Line 7	PLA7	/ 7 7 /	/ /
Line 8	PLA8	/ 8 8 /	/ /
Line 9	PLA9	/ 9 9 /	/ /
Line A	PLAA	/ A A /	/ /
Line B	PLAB	/ B B /	/ /
Line C	PLAC	/ C C /	/ /
Line D	PLAD	/ D D /	/ /
Line E	PLAE	/ E E /	/ /
Line F	PLAF	/ F F /	/ /

- o INT and PI60 are normal input terminal containing no Schmitt circuit.
- o In Hold operation, oscillation is stopped at PI60="H" and started at PI60="L".
- o Divider (2) is reset at PI60="H".

ELECTRICAL CHARACTERISTICS

ABSOLUTE MAXIMUM RATINGS

SYMBOL	ITEM	RATING
V_{DD}	Supply Voltage	-0.3V to +7.0V
V_{IN}	Input Voltage	-0.3V to $V_{DD}+0.3V$
V_{OUT}	Output Voltage	-0.3V to $V_{DD}+0.3V$
P_D	Power Dissipation	600 mW
T_{sol}	Soldering Temperature	260°C(10 SEC)
T_{stg}	Storage Temperature	-55°C to +125°C
T_{opr}	Operating Temperature	-30°C to + 85°C

ALLOWABLE OPERATING CONDITIONS

SYMBOL	ITEM	CONDITION
V_{DD}	Supply Voltage	4V to 6V
T_a	Ambient Temperature	-30°C to +85°C
V_{OH}	Output High Voltage	Min. $V_{DD}-3.5V(\geq 1.5V)$
V_{OL}	Output Low Voltage	Max. 3V
f_X	Xtal Operating Frequency	40KHz to 400KHz
t_{cy}	Cycle Time	10 μ s to 100 μ s
V_{DDHC}	Hold Voltage at Hold Operation (Oscillation Stop)	2V to 6V

Normal Operation

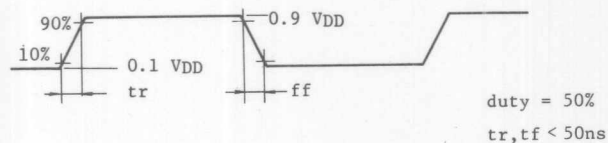
DC CHARACTERISTICS ($T_a = -30^\circ\text{C}$ to $+85^\circ\text{C}$, $V_{DD} = 4\text{V}$ to 6V)

UNIT	SYMBOL	PARAMETER	TEST CONDITION	MIN.	TYP. (Note1)	MAX.	UNIT
V	V_{IH}	Input High Voltage		$V_{DD} \times 0.7$	—	V_{DD}	V
	V_{IHS}	Input High Voltage (Schmitt)		$V_{DD} \times 0.85$	—	V_{DD}	
	V_{IHC}	Input High Voltage (X_{IN})		$V_{DD} \times 0.75$	—	V_{DD}	
	V_{IL}	Input Low Voltage		0	—	$V_{DD} \times 0.3$	
	V_{ILS}	Input Low Voltage (Schmitt)		0	—	$V_{DD} \times 0.15$	
	V_{ILC}	Input Low Voltage (X_{IN})		0	—	$V_{DD} \times 0.25$	
μA	I_{IH}	Input High Current	$V_{DD} = 6\text{V}, V_{IN} = 6\text{V}$	—	—	20	μA
	I_{IL}	Input Low Current	$V_{DD} = 6\text{V}, V_{IN} = 0\text{V}$	—	—	-20	
$\text{k}\Omega$	R_{IN}	Input Resistance (P_{I5})	$V_{DD} = 5\text{V}$	75	150	350	$\text{k}\Omega$
V	V_{OH}	Output High Voltage	$V_{DD} = 5\text{V}, \text{Output Open}$	4.7	4.9	—	V
	V_{OL}	Output Low Voltage	$V_{DD} = 5\text{V}, \text{Output Open}$	—	0.1	0.3	
mA	I_{OH}	Output High Current	$V_{DD} = 4.5\text{V}, V_{OH} = 2.4\text{V}$	-0.7	-2	—	mA
	I_{OH1}	Output High Current (P_{O5}, P_{O6})	$V_{DD} = 5\text{V}, V_{OH} = 2.4\text{V}$	-2.5	-6	—	
			$V_{DD} = 5\text{V}, V_{OH} = 4.2\text{V}$	-1.1	-2.5	—	
	I_{OL}	Output Low Current	$V_{DD} = 4.5\text{V}, V_{OL} = 0.45\text{V}$	1.6	4	—	
μA	I_{OL1}	Output Low Current (P_{O5}, P_{O6})	$V_{DD} = 4.5\text{V}, V_{OL} = 0.45\text{V}$	3.5	8	—	μA
	I_{DDO}	V_{DD} Supply Current in Normal Operation	$V_{DD} = 6\text{V}, f_X = 400\text{kHz}$ $V_{IN} = 5.9\text{V}/0.1\text{V}$	—	400	1200	
	I_{DDH}	V_{DD} Supply Current in Hold operation (Oscillation Cont.)	P_{I5} Open, $CL = 50\text{pF}$ (Note 3)	—	150	450	μA

Note : Typical values are at $T_a = 25^\circ\text{C}$

Note : Output characteristic excludes X_{OUT} terminal.

Note : X_{IN} input waveform at the time of measuring V_{DD} Supply Current



Normal Operation

AC CHARACTERISTICS (Ta=-30°C to +85°C, V_{DD}=4V to 6V)

SYMBOL	PARAMETER	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
t_{WXIN}	XIN Pluse Width	External Input $V_{IN}=V_{IHC}/V_{ILC}$	0.4/fx	—	0.6/fx	SEC
t_{WRESET}	\overline{RESET} Pulse Width	$V_{IN}=V_{IHS}/V_{ILS}$	2 tcy	—	—	μs
t_{WINT}	\overline{INT} Pulse Width	$V_{IN} = V_{IH}/V_{IL}$	2 tcy	—	—	
t_{WPI60}	P160 Pulse Width (Note 1)		2tcy	—	—	

Note 1 : PI₆₀ terminal used for general purpose input port.

Pin	Function	Symbol	Value	Unit
12pin	VDD Supply Current in Hold operation (Operation Cont.)	I_{DDH}	-	mA
10pin	VDD Supply Current in Hold operation (Note 3)	I_{DDH}	-	mA
10pin	Normal operation	I_{DDN}	120	mA
10pin	VDD Supply Current in Normal operation	I_{DDN}	400	mA
10pin	VDD Supply Current in Normal operation	I_{DDN}	1200	mA
10pin	Output Low Current (P02, P06)	I_{OL}	3.3	mA
10pin	Output Low Current	I_{OL}	8	mA
10pin	Output Low Current	I_{OL}	1.6	mA
10pin	(P02, P06)	I_{OH}	-1.1	mA
10pin	Output High Current	I_{OH}	-2.3	mA
10pin	Output High Current	I_{OH}	-5.2	mA
10pin	Output High Current	I_{OH}	-0.7	mA
10pin	Output Low Voltage	V_{OL}	0.3	V
10pin	Output High Voltage	V_{OH}	4.2	V
10pin	Input Resistance (P12)	R_{in}	75	kΩ
11pin	Input Low Current	I_{IL}	350	μA
11pin	Input High Current	I_{IH}	20	μA

Note 1 : P10 terminal used for general purpose input port.



INTEGRATEDCIRCUIT

TECHNICAL DATA

TCP4620BP

TECHNICAL DATA



Hold Operation (Oscillation stop)

DC CHARACTERISTICS (Ta=-30°C to 85°C, VDD=2V to 6V)

SYMBOL	PARAMETER	TEST CONDITION	MIN.	TYP. (Note1)	MAX.	UNIT
VDD	Hold Voltage in Hold operation		2.0	-	6.0	V
IDDHS	VDD Supply Current in Hold Mode	VDDHS=2V, VIN=1.9V/ 0.1V PI5 Open VRESET=VDDHS	-	0.1	T.B.D.	μA
		VDDHS=5V, VIN=4.9V/ 0.1V PI5 Open VRESET=VDDHS	-	0.2	T.B.D.	
VIHHS	Input High Voltage (PI60)	VDDHS=2V	1.9	-	-	V
RIN	Input Resistance (PI5)		75	150	350	KΩ
IOHHS	Output High Current	VDDHS=2V, VOH=1V	-	-0.4	-	mA
IOHHS	Output High Current (PI5, PI6)	VDDHS=2V, VOH=1V	-	-0.9	-	mA
IOLHS	Output High Current	VDDHS=2V, VOL=0.45V	-	2.0	-	mA
IOLHS	Output High Current (PO5, PO6)	VDDHS=2V, VOL=0.45V	-	3.5	-	mA

Note 1 : Typical values are at Ta=25°C.

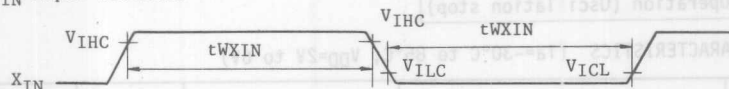
Note 2 : The limits of VIHHS, IOHHS, IOLHS and IOLHS are equal to the limits of VIH, IOH, IOH1 and IOL1 in [Normal Operation] respectively.
(VDDHS 4V)

AC CHARACTERISTICS (Ta=-30°C to 85°C)

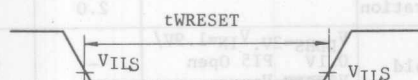
SYMBOL	PARAMETER	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
tWRST	Restort Internal from Hold operation	VIN=VIH/VIL VDD=4V to 6V	-	2050tcy	-	μS

TIMING WAVEFORMS

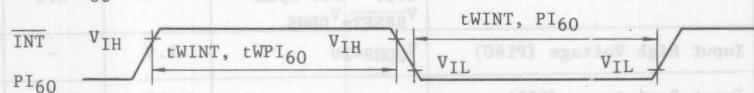
(1) X_{IN} Input Waveform



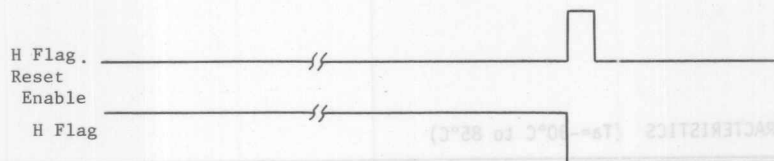
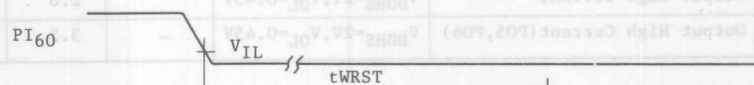
(2) RESET Input Waveform



(3) INT, PI₆₀ Input Waveform



(4) Restart timing from Hold Operation after Oscillation Stop.



SYMBOL	PARAMETER	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
t _W	Reset Interval from Hold	V _{IN} =V _{IL} , V _{OUT} =V _{OH}	-	2000	-	ns

APPLICATION EXAMPLES

[1] Battery Backup

It is thinkable that there is a backup method which utilizes a battery and a capacitor, as application of the system required to uninterruptedly resume the process before cutting-off of the power supply when the power supply has been restored after the power supply was cut off during the operation of the system.

Fig. 1 shows the example of utilizing a battery and Fig. 2 shows the example of utilizing a capacitor. In both the cases, the operations are almost identical. Let us explain the circuit operation of the example (Fig. 1) of utilizing a battery.

Under the condition of "Main Power Voltage > Backup Voltage," the power (V_{DD}) of TCP420BP is supplied from the main power supply. When Q1 is ON, "L" level is applied to PI60 terminal.

In other words, the oscillator is in oscillation state, and the operation of TCP4620BP depends on a program.

Under the condition of "Main Power Voltage < Backup Voltage," the power (V_{DD}) of TCP4620BP is supplied from the battery, and when Q1 comes into OFF state, "H" level is applied to PI60 terminal.

In other words, the oscillator depends on the operating state of TCP4620BP, and if it is in hold state, oscillation is stopped.

When TCP4620BP is put to hold state immediately after the power supply has been cut off, the oscillation is stopped, permitting a backup for a long period time.

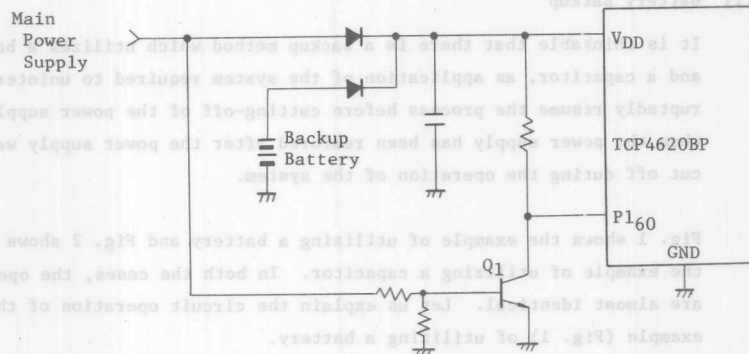


Fig. 1 Example of Backup Circuit by Use of Battery

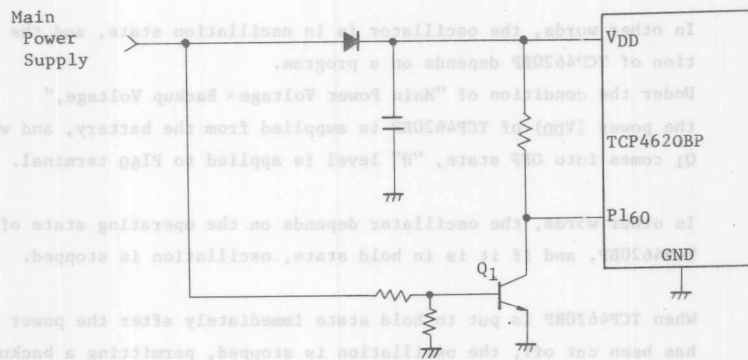


Fig. 2 Example of Backup Circuit by Use of Capacitor

[2] Restart by Key Input

The possibility of a remote control system utilizing TCP4620BP can be considered as application of a system which operates only when the key is fed.

Let us explain the example of application in Fig. 3. Usually TCP4620BP is in hold state, and only when the key is fed, the hold state is released to perform the process according to the input data.

In other words, TCP4620BP is put to hold state after data X'F' has been output (putting SW1 to SW16 to selection state) to its output port 1 (P1).

When the keys (SW1 to SW16) are depressed in this state, "L" level is applied to PI60 terminal and the hold state is released after certain period of time.

The keys are scanned after the release of hold state, and the process is performed according to the key input data. After processing, the data output (X'F') to the output port 1 (P1) and a hold state are established.

In such an application, TCP4620BP operates only when a key is depressed, permitting a sharp reduction in power consumption and a better display of the functions of TCP4620BP.

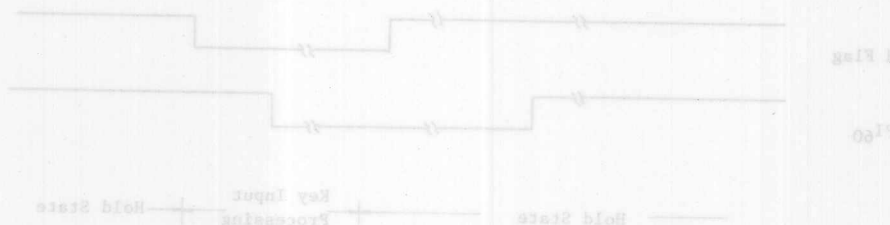


Fig. 3 Example of Circuit (Fig. 3) Timing Chart

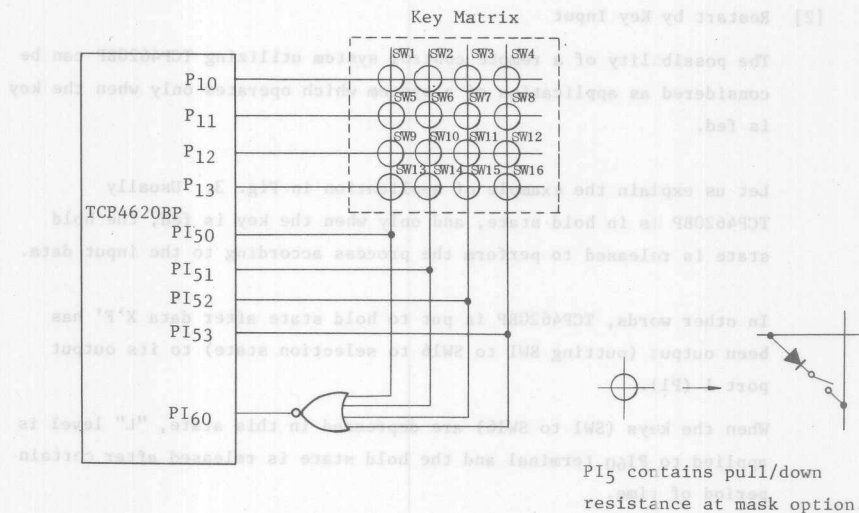


Fig. 3 Example of Restart Circuit by Key Input

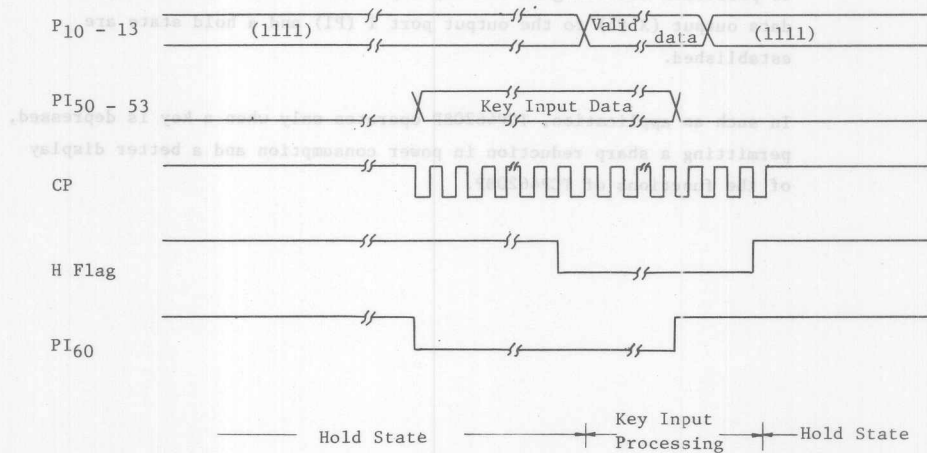


Fig. 4 Example of Circuit (Fig. 3) Timing Chart



INTEGRATED CIRCUIT

TECHNICAL DATA

TCP4621AP

C²-MOS DIGITAL INTEGRATED CIRCUIT

SILICON MONOLITHIC

GENERAL DESCRIPTION

The TCP4621AP is a CMOS 4-bit single chip microcomputer most suitable for applications of driving fluorescent display tubes and of interfacing with high voltage circuits.

Output high breakdown voltage:

$V_{DD} - 32V$ (Absolute max. rating $V_{DD} - 35V$)

Output high breakdown voltage port:

14 ports (P_{060} to P_{067} , P_{050} to P_{054} , P_{10})

The TCP4621AP has adopted the P-channel Open Drain structure of some output ports of the TCP4620AP, resulting in high breakdown voltage. There are some difference between the TCP4620AP and the TCP4621AP in electrical characteristics, pin functions, and mask options, but the other functions, electrical characteristics, instructions, and pin connections of the TCP4621AP are compatible with those of the TCP4620AP. For the use and study of this device, use jointly with TCP4620AP Technical Data.

The following items are the points of difference in electrical characteristics.

1. Operating temperature and ambient temperature

$T_{opr} = -20$ to $+70^{\circ}C$

$T_a = -20$ to $+70^{\circ}C$

2. Output high breakdown voltage port and output high level current

$IOH1$ (P_{060} to P_{067}) = $-1mA$ MIN. ($V_{DD}=4.5V$, $V_{OH}=2.5V$)

$IOH1$ (P_{050} to P_{054} , P_{10}) = $-7mA$ MIN. ($V_{DD}=4.5V$, $V_{OH}=2.5V$)

3. Mask option

The contents only which are shown on the TCP4621AP mask option sheet can be designated. 400 KHz ceramic/IFT can be used as an oscillator.

PIN NAMES & PIN DESCRIPTION

Pin Name	Pin No.	Input/Output	Function
P ₀₃ to P ₀₀	4	Input/Output	4-bit general purpose I/O port (I/O is changed over by a program.) This port can be used as a dedicated output. (I/O is designated by mask options.)
P ₁₃ to P ₁₀	4	Output	4-bit general purpose output port * P ₁₀ only is a output high breakdown voltage port
P ₂₃ to P ₂₀	4	Input or Output	4-bit general purpos Input/Output port
P ₄₃ to P ₄₀	4	Input or Output	Input/Output is designated by mask options.
P ₀₅₄ to P ₀₅₀	5	Output	* 5-digit Output high breakdown voltage port for display. (Can be used as the general purpose output port.)
P ₀₆₇ to P ₀₆₀	8	Output	* 8-segment output high breakdown port for display [Can be used as the general purpose 8-bit output port (4×2 bits).]
P _{I53} to P _{I50}	4	Input	4-bit general purpose input port
P _{I60}	1	Input	1-bit general purpose input port (with an internal Schmitt circuit)
RESET	1	Input	Reset input terminal (with an internal Schmitt circuit)
INT	1	Input	Interrupt request input terminal (with an internal Schmitt circuit)
X _{IN}	1	Input	Oscillator connecting terminal
X _{OUT}	1	Output	Oscillator connecting terminal
C K	1	Output	External timing output
TEST	1	Input	Used by connecting to GND at all times
V _{DD}	1		Power supply
GND	1		GND

Note) The asterisk(*) indicates the points of difference between the TCP4620AP and this device.

Output high breakdown voltage ports are of P-channel open drain structure.

TCP4621AP MASK OPTIONS

			TYP021	TYP022			
Oscillation			050	050			
frequency			400K ceramic	400K ceramic			
			1FT	1FT			
Dividing ratio for internal clock			CP	02	02		
External timing output			CK	CP	PD2		
Counter	Divider 1 Input	PD	CP	CP			
	Divider 3 Input	COUNTER	PD2	PD2			
	Reset timing	PDR	N	/12500/			
Counter Buffer	Buffer 0 Input	CO	PI60	PI60			
	Buffer 1 Input	COUNTER	C1	RD7	RDB		
	Buffer 2 Input	BUFFER	C2	RDA	RDC		
	Buffer 3 Input	C3	RDD	RDD			
H flag			HOLD	O	H		
Restart condition			RSTH	O	C3		
Input/Output port		Port 0	STD	D(PROG)	1 (OUT)		
I/O Port	Port 2	P2	/F/(OUT)	/F/(OUT)	/O/(IN)	/O/(IN)	/O/(IN)
	Port 4	P4	/F/(OUT)	/3/(IN/OUT)	/F/(OUT)	/3/(IN/OUT)	/O/(IN)
Input resistance (Input port 5)			P15	0 (UP)	1 (DOWN)		
Decode matrix (PO5)	Line 0	DECO	/	/			
	Line 1	DEC1	/	/			
	Line 2	DEC2	/	/			
	Line 3	DEC3	/	/			
	Line 4	DEC4	/	/			
Output port		6/7	PO6	1(P6/P7)	0 (P6)		
P L A (PO6)	Line 0	PLA0	/ 00 /	/ / /			
	Line 1	PLA1	/ 11 /	/ / /			
	Line 2	PLA2	/ 22 /	/ / /			
	Line 3	PLA3	/ 33 /	/ / /			
	Line 4	PLA4	/ 44 /	/ / /			
	Line 5	PLA5	/ 55 /	/ / /			
	Line 6	PLA6	/ 66 /	/ / /			
	Line 7	PLA7	/ 77 /	/ / /			
	Line 8	PLA8	/ 88 /	/ / /			
	Line 9	PLA9	/ 99 /	/ / /			
	Line A	PLAA	/ AA /	/ / /			
	Line B	PLAB	/ BB /	/ / /			
	Line C	PLAC	/ CC /	/ / /			
	Line D	PLAD	/ DD /	/ / /			
	Line E	PLAE	/ EE /	/ / /			
	Line F	PLAF	/ FF /	/ / /			

ABSOLUTE MAXIMUM RATINGS

SYMBOL	ITEM	RATING	UNIT
V _{DD}	Supply Voltage	-0.3 to +7.0	V
V _{IN}	Input Voltage	-0.3 to V _{DD} +0.3	V
V _{OUT1}	Output Voltage (except P05, P06, P10)	-0.3 to V _{DD} +0.3	V
V _{OUT2}	Output Voltage (P05, P06, P10)	V _{DD} -35 to V _{DD} +0.3	V
P _D	Power Dissipation	600	mW
T _{sol}	Soldering Temperature·Time	260 (10 SEC)	°C
T _{stg}	Storage Temperature	-55 to +125	°C
T _{opr}	Operating Temperature	-20 to +70	°C

ALLOWABLE OPERATING CONDITIONS

SYMBOL	ITEM	RATING	UNIT
		V _{DD} = 4 to 6V	
T _a	Ambient Temperature	-20 to +70	°C
V _{OUT}	Output Voltage (P06, P05, P10)	Max. V _{DD} - 32	V
f _x	X'tal Operating Frequency	40 to 400	KHz
t _{cy}	Cycle Time	10 to 100	μs

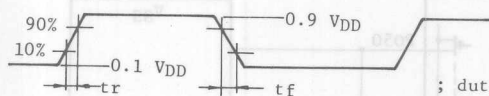
DC CHARACTERISTICS ($T_a = -20^{\circ}\text{C}$ to $+70^{\circ}\text{C}$, $V_{DD} = 4\text{V}$ to 6V)

SYMBOL	PARAMETER	TEST CONDITION	RATING			UNIT
			MIN.	TYP.	MAX.	
V_{IH}	Input High Voltage		$V_{DD} \times 0.7$	$V_{DD} \times 0.55$	V_{DD}	V
V_{IHS}	Input High Voltage (Schmitt)		$V_{DD} \times 0.85$	$V_{DD} \times 0.75$	V_{DD}	
V_{IHC}	Input High Voltage (XIN input)		$V_{DD} \times 0.75$	—	V_{DD}	
V_{IL}	Input Low Voltage		0	$V_{DD} \times 0.45$	$V_{DD} \times 0.3$	
V_{ILS}	Input Low Voltage (Schmitt)		0	$V_{DD} \times 0.35$	$V_{DD} \times 0.15$	
V_{ILC}	Input Low Voltage (XIN input)		—	—	$V_{DD} \times 0.25$	
I_{IH}	Input High Current	$V_{DD}=6\text{V}$, $V_{IN}=6\text{V}$	—	—	20	μA
I_{IL}	Input Low Current	$V_{DD}=6\text{V}$, $V_{IN}=0\text{V}$	—	—	-20	
R_{IN}	Input Resistance (PI5)	$V_{DD}=5\text{V}$	75	150	350	$\text{k}\Omega$
V_{OH}	Output High Voltage	$V_{DD}=5\text{V}$, Output Open	4.7	4.9	—	V
V_{OL}	Output Low Voltage		—	0.1	0.3	
I_{OH}	Output High Current	$V_{DD}=4.5\text{V}$, $V_{OH}=2.4\text{V}$	-0.7	—	—	mA
I_{OH1}	Output High Current (PO6, P10)	$V_{DD}=4.5\text{V}$, $V_{OH}=2.5\text{V}$	-1	—	—	
		$V_{DD}=4.5\text{V}$, $V_{OH}=2.5\text{V}$	-7	—	—	
I_{OL}	Output Low Current	$V_{DD}=4.5\text{V}$, $V_{OL}=0.45\text{V}$	1.6	—	—	
I_{LO}	Output Leak Current (PO5, PO6, P10)	$V_{DD}=6\text{V}$, $V_{OUT}=-26\text{V}$	—	—	-20	μA
I_{DDO}	VDD Supply Current in Normal Operation ($f_X = 400\text{kHz}$)	$V_{DD}=6\text{V}$, $V_{IN}=5.9\text{V}/0.1\text{V}$ (all valid)	—	400	1200	μA
I_{DDH}	VDD Supply Current in Hold Operation ($f_X = 400\text{kHz}$)	PI5 Open $C_L=50\text{pF}$ Output Open	—	150	450	

Note 1: Typical values are at $T_a=25^{\circ}\text{C}$ and $V_{DD}=5\text{V}$.

2: Output characteristic excludes X_{OUT} terminal.

3: X_{IN} input waveform at the time of measuring V_{DD} supply current.

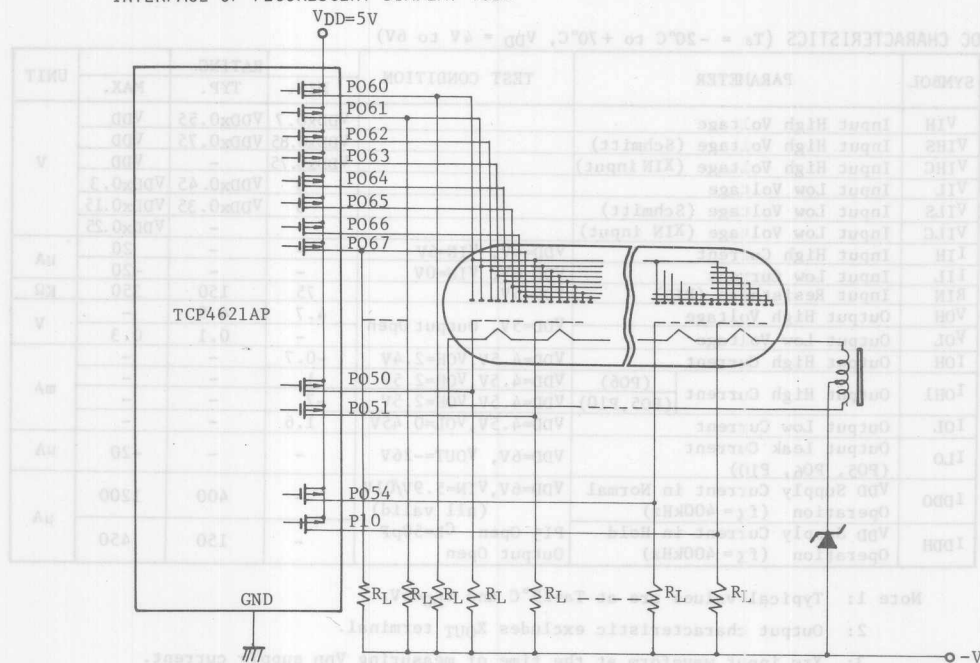


; duty = 50%

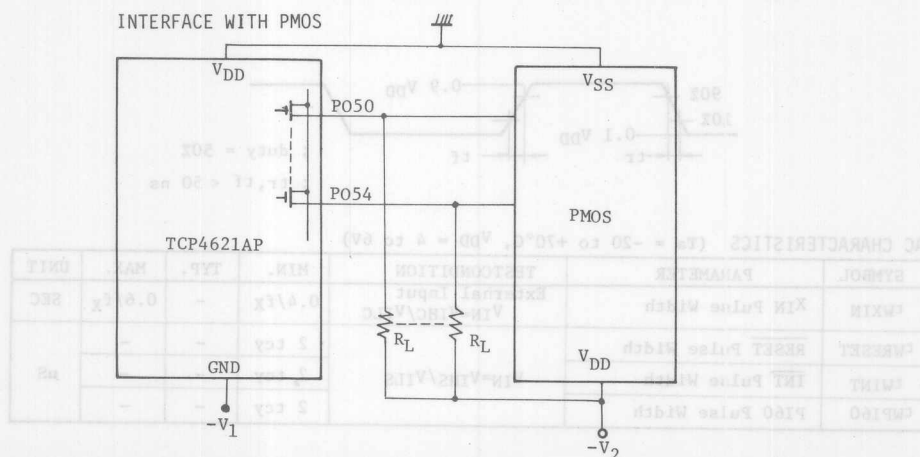
; $t_r, t_f < 50\text{ ns}$

AC CHARACTERISTICS ($T_a = -20$ to $+70^{\circ}\text{C}$, $V_{DD} = 4$ to 6V)

SYMBOL	PARAMETER	TESTCONDITION	MIN.	TYP.	MAX.	UNIT
t_{WXIN}	XIN Pulse Width	External Input $V_{IN}=V_{IHC}/V_{ILC}$	$0.4/f_X$	—	$0.6/f_X$	SEC
t_{WRESET}	RESET Pulse Width	$V_{IN}=V_{IHS}/V_{ILS}$	2 tcy	—	—	μS
t_{WINT}	INT Pulse Width		2 tcy	—	—	
t_{WPI60}	PI60 Pulse Width		2 tcy	—	—	

$V_{DD}=5V$ 

INTERFACE WITH PMOS





INTEGRATED CIRCUIT

TECHNICAL DATA

TCP4632BF

C²-MOS DIGITAL INTEGRATED CIRCUIT
SILICON MONOLITHIC

PRELIMINARY

GENERAL DESCRIPTION

The TCP4632BF is a C²MOS 4-bit single-chip microcomputer capable of directly driving liquid crystal display provided with 1/3 or 1/4 duty, and is most suitable for use in a wide range of application fields, such as a system requiring low power dissipation.

The TCP4632BF contains the controller and driver for driving the liquid crystal display (hereinafter referred to as LCD) to the TCP4630AP. For the use and study of this device, refer to the technical data for the TCP4630AP in addition to this technical data.

FEATURES

- o C²MOS 4-bit single-chip microcomputer of low power dissipation
- o Memory capacity
 - Program region (ROM) 3072 words x 8-bit
 - Data region (RAM) 160 words x 4-bit (including RAM for display)
- o Instruction execution time: 10 μ s (400kHz ceramic oscillator/IFT)
- o 52 instructions
- o Built-in LCD controller
 - 1/3 or 1/4 duty (designated by mask options)
- o Built-in LCD direct driver
 - Common output 4 pins
 - Segment output 24 pins
- o Input/Output port
 - I/O port 1 x 4-bit (I/O can be switched by programs.)
 - 1 x 4-bit (I/O can be designated by mask options.)
 - 1 x 4-bit (I/O can be designated by mask options.)



INTEGRATED CIRCUIT

TECHNICAL DATA

TCP4632BF

PRELIMINARY

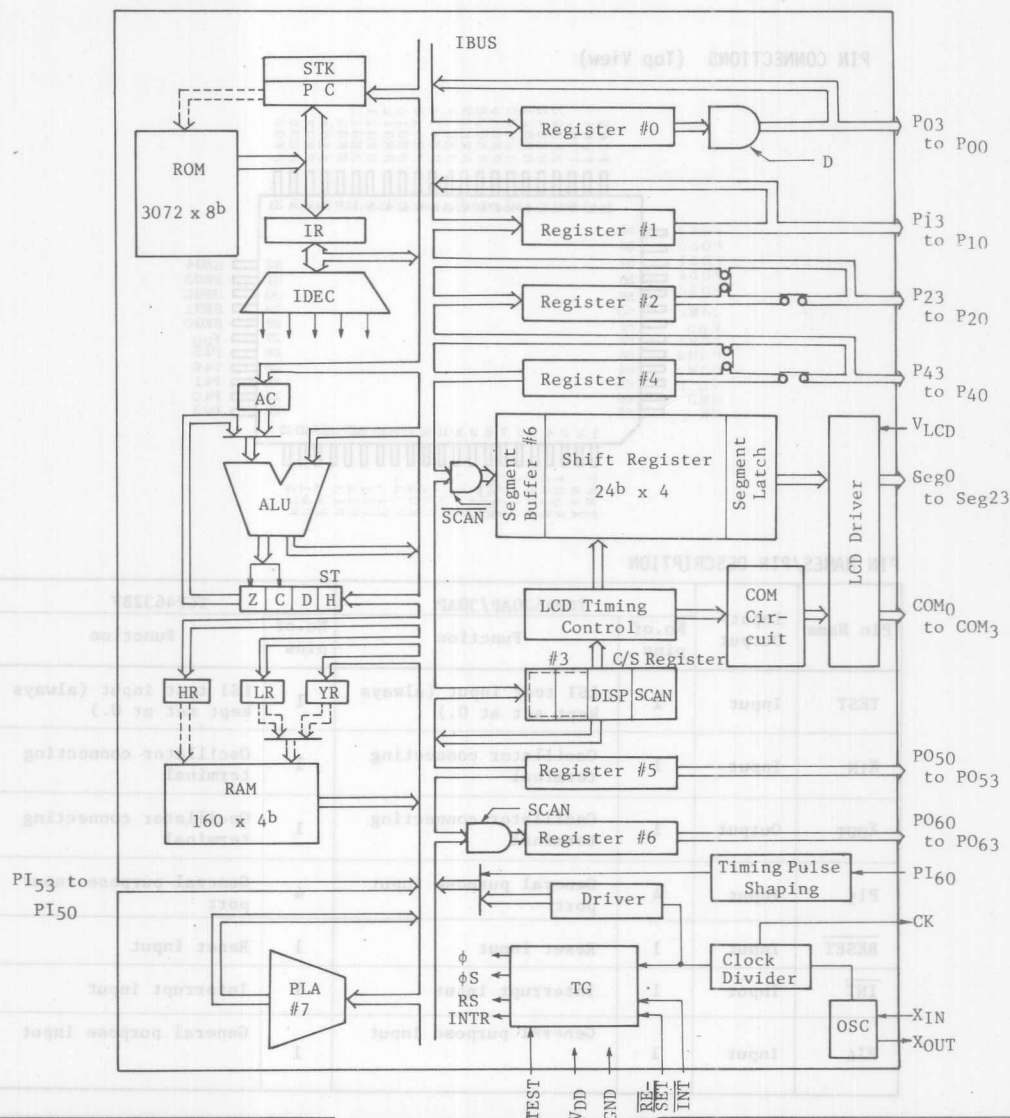
Output port 3 x 4-bit (General purpose output port)

Input port 1 x 4-bit (Pull-up/Pull-down resistor with input resistance can be selected.)

1 x 4-bit

- o External power supply is available for LCD (V_{LCD})
- o Built-in display decoder (Can be designated by mask options with decoder data.)
- o Blanking operation
- o Hold operation (LCD can be displayed during hold operation.)
- o Power-down mode (Display blanking)
- o 67-pin plastic package

BLOCK DIAGRAM





INTEGRATED CIRCUIT

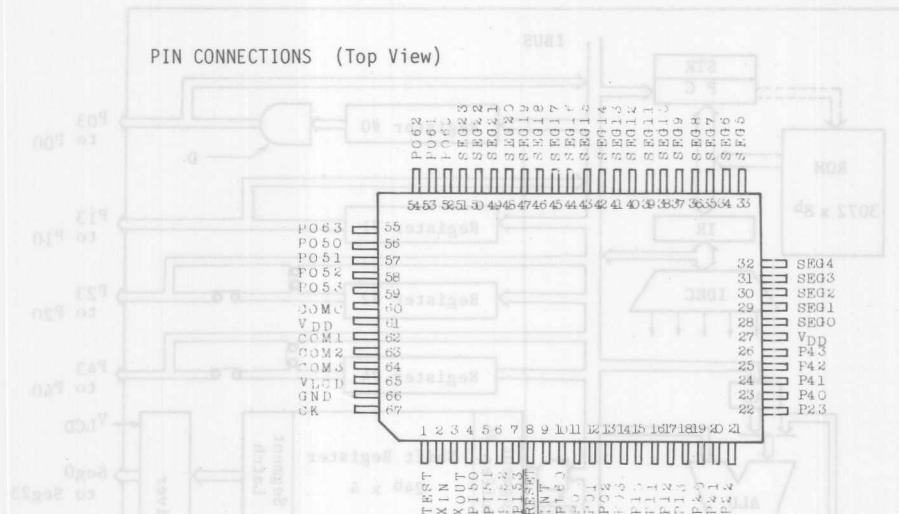
TECHNICAL DATA

TCP4632BF

TECHNICAL DATA

PRELIMINARY

PIN CONNECTIONS (Top View)



PIN NAMES/PIN DESCRIPTION

Pin Name	Input/Output	TCP4620AP/30AP		TCP4632BF	
		No. of pins	Function	No. of pins	Function
TEST	Input	1	LSI test input (always kept set at 0.)	1	LSI test input (always kept set at 0.)
XIN	Input	1	Oscillator connecting terminal	1	Oscillator connecting terminal
XOUT	Output	1	Oscillator connecting terminal	1	Oscillator connecting terminal
PI5	Input	4	General purpose input port	4	General purpose input port
RESET	Input	1	Reset input	1	Reset input
INT	Input	1	Interrupt input	1	Interrupt input
PI6	Input	1	General purpose input	1	General purpose input



INTEGRATED CIRCUIT

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TECHNICAL DATA

TCP4632BF

TECHNICAL DATA

PRELIMINARY

Pin Name	Input/ Output	TCP4620AP/30AP		TCP4632BF	
		No. of pins	Function	No. of pins	Function
P0	I/O	4	I/O port	4	I/O port
P1	Output	4	General purpose output port	4	General purpose output port
P2	Input/ Output	4	General purpose input/ output port	4	General purpose input/ output port
P4	Input/ Output	4	General purpose input/ output port	4	General purpose input/ output port
VDD		1	Power supply	2	Power supply
SEG0~23	Output			24	LCD segment driver out- put
P06	Output	4	PLA output port	4	General purpose output port
P07	Output	4	PLA output port		
P05	Output	5	Decode matrix output port	4	General purpose output port
COM0~3				4	LCD common driver output
V _{LCD}				1	LCD external power sup- ply terminal
GND		1	GND	1	GND
CK	Output	1	External*timing output	1	External timing output



CONFIGURATION OF PORT AND REGISTER

	Name	Sym- bol	Pin Name	Reg. No.	Function	Remarks
*	I/O Port	P ₀	P03 to P00	0	I/O Port	I/O switching is controlled by D flag of ST. This port can be designated as a dedicated output port by mask options.
	Output Port	P ₁	P13 to P10	1	Output Port	General purpose output port. The contents of register can be referred to by a program.
*	Input/ Output Port	P ₂	P23 to P20	2	Input/ Output Port	Input/output can be designated by mask options. The contents of register can be referred to by a program.
*	Command Register	C/S	—	3	Command Register	LCD display is controlled by a 2-bit register. The contents of register can be referred to by a program.
*	Input/ Output Port	P ₄	P43 to P40	4	Input/ Output Port	Input/output can be designated by mask options. The contents of register can be referred to by a program.
	Input Port	PI ₅	PI53 to PI50	5	Input Port	General purpose input port with 150kΩ (TYP.) resistance. Pull-up/Pull-down designation can be made by mask options.
*	Output Port	PO ₅	PO53 to PO50		Output Port	General purpose output port. The contents of register can not be referred to by a program.
	Input Port	PI ₆	PI60	6	Input Port	1-bit general purpose input port. (Built-in Schmitt circuit).
*	Output Port	PO ₆	PO63 to PO60		Output Port	General purpose output port. The contents of register can not be referred to by a program.
*	PLA	PLA	—	7	PLA	PLA. PLA can be used as a display data decoder or a data decoder. The contents of decode is designated by mask options.



INTEGRATED CIRCUIT

TECHNICAL DATA

TCP4632BF

PRELIMINARY

Note The asterisk (*) indicates the points of difference between TCP 4620AP/TCP4630AP and this device.

- (a) Neither command register nor PLA (available for reference by a program) is contained in the TCP4620AP/TCP4630AP.
- (b) Since PO_3 and PO_6 contain neither decode matrix nor PLA, the number of output pins of each port is 4.
- (c) Care should be taken to the fact that PO_0 , PO_2 , PO_4 , PO_5 and PO_6 of this device are different from those of TCP4620AP/TCP4630AP in electrical characteristics.

LCD CONTROLLER/DRIVER

The TCP4632BF contains a driver circuit capable of directly, dynamically driving the LCD provided with 1/3 or 1/4 duty by the 1/3 bias method.

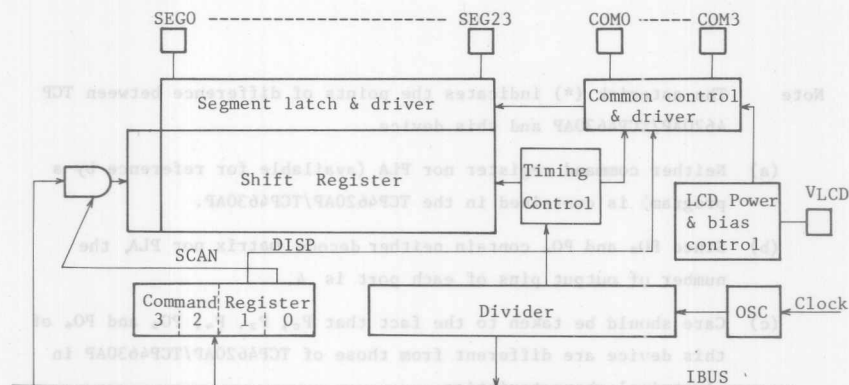
LCD connection terminals amount to 29 in total as follows:

Common driver output (COM0 to COM3)	4
Segment driver output (SEG0 to SEG23)	24
VLCD terminal as LCD driving power terminal	1

The display ability makes it possible directly to drive the following LCDs according to the number of time divisions:

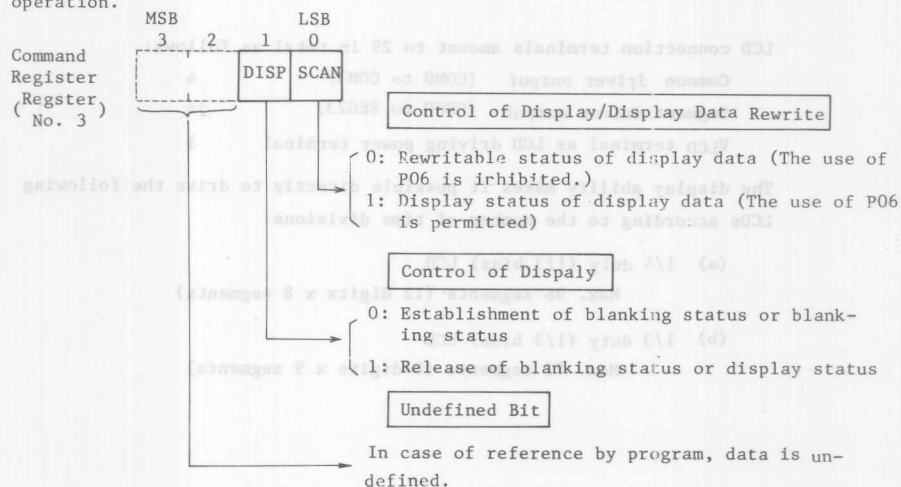
- (a) 1/4 duty (1/3 bias) LCD
Max. 96 segments (12 digits x 8 segments)
- (b) 1/3 duty (1/3 bias) LCD
Max. 72 segments (8 digits x 9 segments)

BLOCK DIAGRAM OF LCD DRIVE CONTROLLER



CONTROL OF DRIVE CIRCUIT

The operation of LCD drive circuit is controlled by the contents of command register. The command register is a 2-bit register and is accessed as register No. '3'. Both of two bits are reset to "0" by an initialize operation.





INTEGRATED CIRCUIT

TECHNICAL DATA

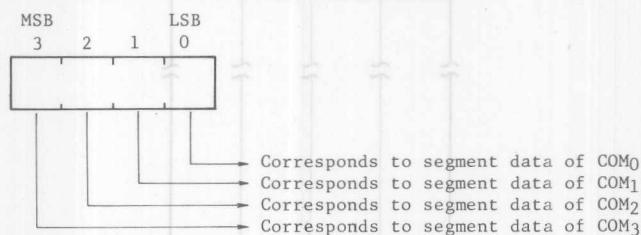
TCP4632BF

PRELIMINARY

DISPLAY OPERATION

SETUP OF DISPLAY DATA

The TCP4632BF internal processing data corresponds to LCD drive terminal in such a way as bit 0, bit 1, bit 2 and bit 3 of the processing data correspond to each segment data of COM0, COM1, COM2, and COM3, respectively.



The conversion of LCD display data is arbitrarily set up by a program or by a built-in PLA register (setup of the contents by mask options).

TRANSFER OF DISPLAY DATA

LCD display data setup by a program or PLA register is displayed by transferring it to the shift register of LCD driver by the program.

The transfer method is divided into two categories: one is that the converted data is transferred as it is, and another is that a displaying data region set up in the data memory (RAM) is transferred after it has been once stored. Even by either method, each bit of LCD segment (dot) and TCP4632BF internal processing data corresponds to each other by one to one.



INTEGRATED CIRCUIT

TECHNICAL DATA

TCP4632BF

PRELIMINARY

Bit Address	MSB 3	2	1	LSB 0	
0					(SEG ₀)
1					(SEG ₁)
2					(SEG ₂)
3					(SEG ₃)
⋮					
22					(SEG ₂₂)
23					(SEG ₂₃)
⋮					
(COM ₃) (COM ₂) (COM ₁) (COM ₀)					

In case data memory is provided with display region

Bit Register	MSB 3	2	1	LSB 0	
					(SEG ₁)
⋮					
(COM ₃) (COM ₂) (COM ₁) (COM ₀) (i = 0 to 23)					

In case processing data intact is transferred

Each bit of display data expresses data of segment (dot) equivalent to (SEG_i COM_j : $0 \leq i \leq 23, 0 \leq j \leq 3$). When the data displays "1", the display lights. In case of the use of LCD with 1/3 duty (COM₀ to COM₂), the data of bit 3 (MSB) has no meaning as a LCD display data.



Transfer and rewrite of display data is made by a program as follows:

First, clear SCAN bit to '0'. (Immediately after initialization, the bit is at '0'.) Next, transfer 4-bit data equivalent to SEG. 23 to Register No. 6 (SAR 6), and then transfer 4-bit data equivalent to SEG 22. Continuously transfer 4-bit data in sequence by programs until the transfer of data equivalent to SEG. 0 is completed.

This operation allows 4×24-bit data to be written into the shift register within LCD drive circuit. After the data transfer of 24 words has been finished, SCAN bit is set to '1'. When SCAN bit goes to '1', writing into the shift register is inhibited, and LCD begins to be driven by the data newly held. Data switching is made from COMj to come next (data output equivalent to bit j to SEGi) and is automatically scanned to the next COMj+1.

In the case that the period (period of SCAN = 0) of 24-word data transfer by means of a program is within the one COM period (1/4fF), the blank period does not come into the transfer period, and the display contents are switched. However, in the case that the period (period of SCAN = 0) of 24-word data transfer by means of a program crosses switching of COM (this phenomenon presents by timing of data transfer period or it presents when the data transfer period becomes longer than one COM period), no correct display data is secured during the period; thus, a blank is automatically inserted in the period.

When the display data is transferred to a shift register equivalent to Register No.6 during the period of SCAN = 0, all of 24 words must be transferred to the shift register. However, if SEGO to SEGk-1 outputs only, not all of SEGO ~ SEG23 outputs, are used, k word only can be transferred.



INTEGRATED CIRCUIT

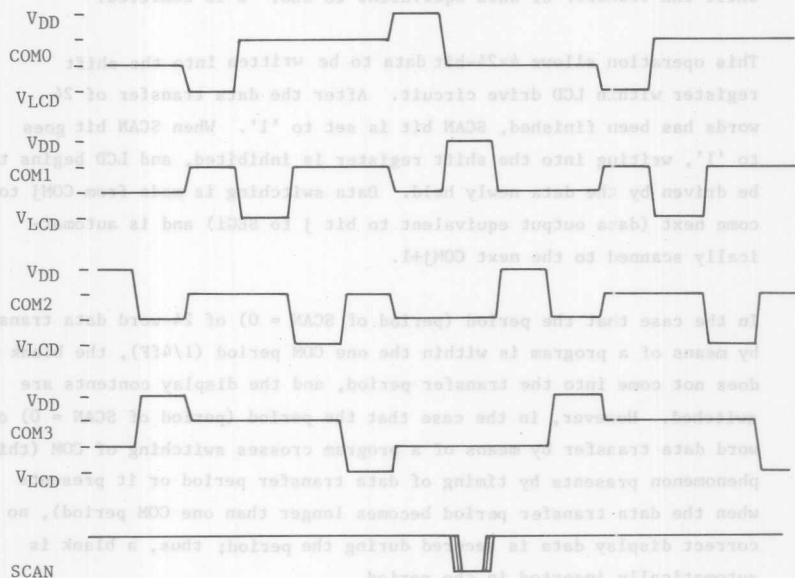
TECHNICAL DATA

TC4632BF

TECHNICAL DATA

PRELIMINARY

In case of SCAN = 0, write in Register No. 6 (SAR = 6) means write in the shift register as a display data. In case of SCAN = 1, however, it means write in output port P06.



As the display data transfer period is short, it does not come in the blanking period.



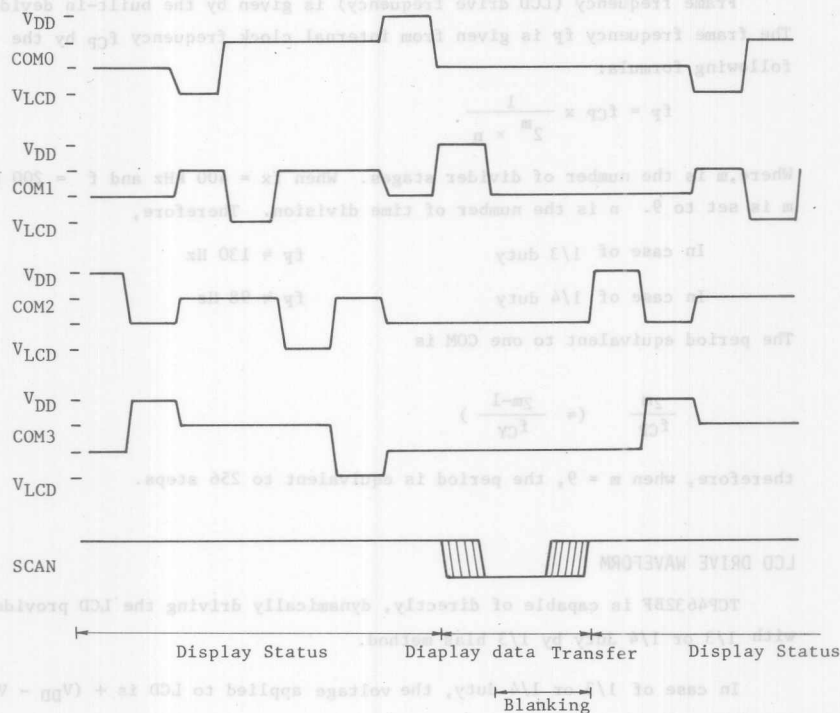
INTEGRATED CIRCUIT

TECHNICAL DATA

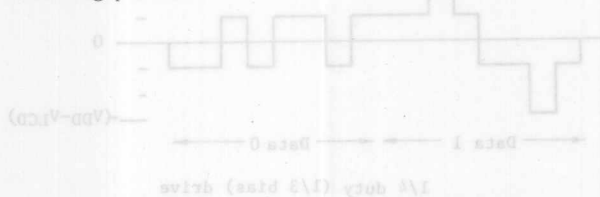
TCP4632BF

TECHNICAL DATA

PRELIMINARY



As the display data transfer period is long, it comes in the blanking period.



LCD FRAME FREQUENCY

Frame frequency (LCD drive frequency) is given by the built-in divider. The frame frequency f_F is given from internal clock frequency f_{CP} by the following formula:

$$f_F = f_{CP} \times \frac{1}{2^m \times n}$$

Where, m is the number of divider stages. When $f_x = 400$ kHz and $f = 200$ kHz, m is set to 9. n is the number of time division. Therefore,

In case of 1/3 duty $f_F \approx 130$ Hz

In case of 1/4 duty $f_F \approx 98$ Hz

The period equivalent to one COM is

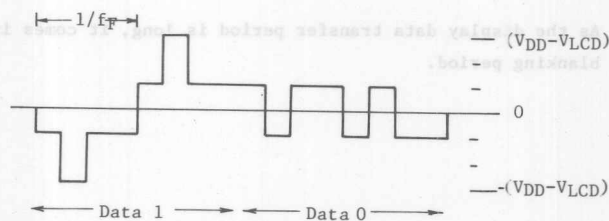
$$\frac{2^m}{f_{CP}} \quad (\approx \frac{2^m - 1}{f_{CY}})$$

therefore, when $m = 9$, the period is equivalent to 256 steps.

LCD DRIVE WAVEFORM

TCP4632BF is capable of directly, dynamically driving the LCD provided with 1/3 or 1/4 Duty by 1/3 bias method.

In case of 1/3 or 1/4 duty, the voltage applied to LCD is $+(V_{DD} - V_{LCD})$ to $-(V_{DD} - V_{LCD})$.



1/4 duty (1/3 bias) drive



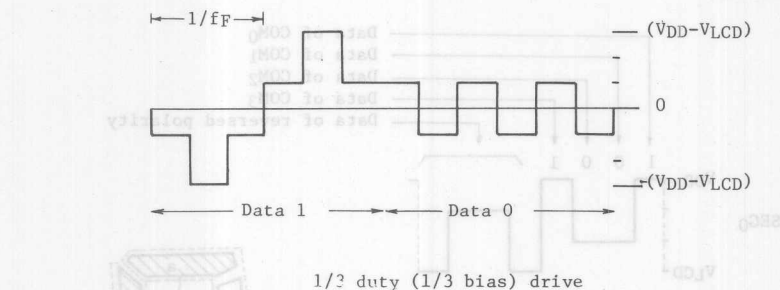
INTEGRATED CIRCUIT

TECHNICAL DATA

INTEGRATED CIRCUIT
TCP4632BF
TECHNICAL DATA

PRELIMINARY

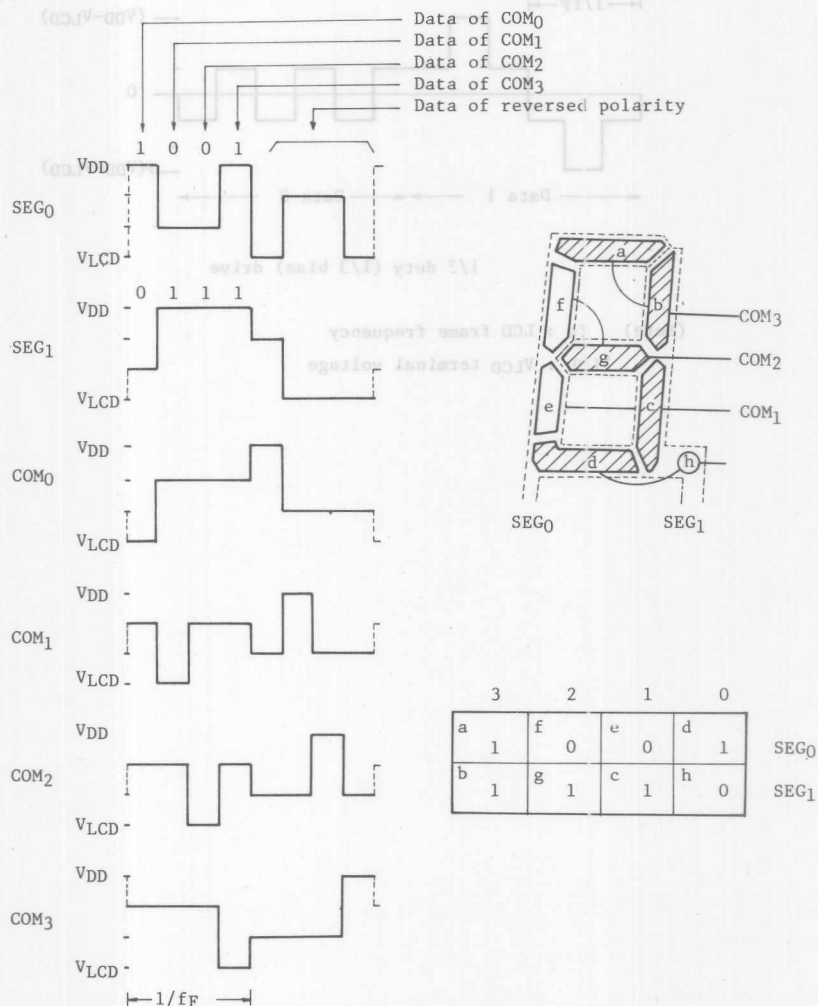
Each terminal waveform in case of displaying data "3" at 1/3 duty is as follows:



(Note) f_F : LCD frame frequency
 V_{LCD} : VLCD terminal voltage

	0	1	2	3
a	d	e	f	a
b	1	0	0	1
c	0	1	1	0

Each terminal waveform in case of displaying data "3" at 1/4 duty is as follows:





INTEGRATED CIRCUIT

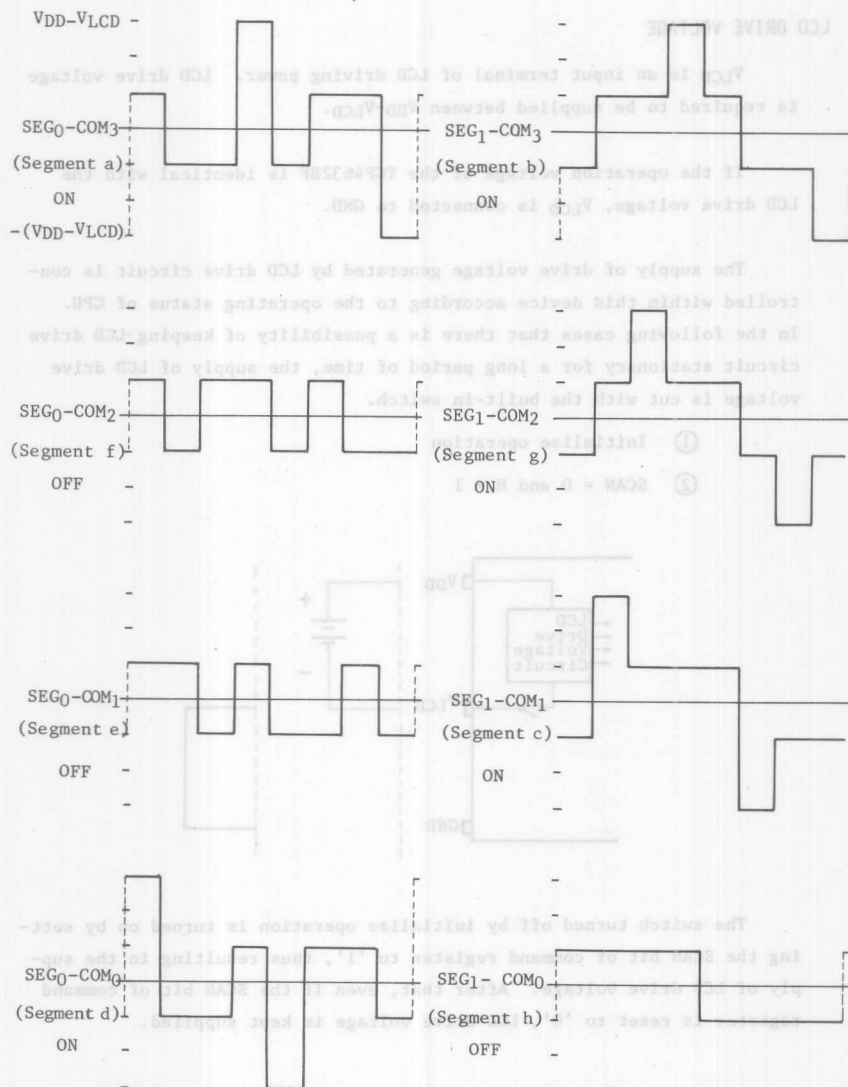
TECHNICAL DATA

TCP4632BF

TECHNICAL DATA

PRELIMINARY

The voltage between each SEG - COM is as follows:



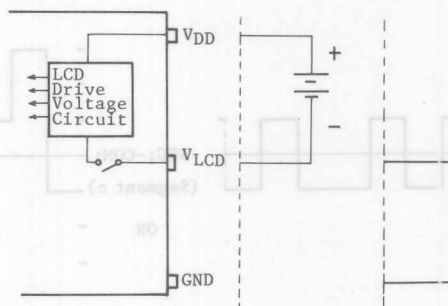
LCD DRIVE VOLTAGE

V_{LCD} is an input terminal of LCD driving power. LCD drive voltage is required to be supplied between V_{DD} - V_{LCD} .

If the operation voltage of the TCP4632BF is identical with the LCD drive voltage, V_{LCD} is connected to GND.

The supply of drive voltage generated by LCD drive circuit is controlled within this device according to the operating status of CPU. In the following cases that there is a possibility of keeping LCD drive circuit stationary for a long period of time, the supply of LCD drive voltage is cut with the built-in switch.

- ① Initialize operation
- ② SCAN = 0 and H = 1



The switch turned off by initialize operation is turned on by setting the SCAN bit of command register to '1', thus resulting in the supply of LCD drive voltage. After that, even if the SCAN bit of command register is reset to '0', LCD drive voltage is kept supplied.



For performing hold operation, H must be set to '1' in a state of SCAN = 1 and at time of normal LCD display because rewrite of display data has been already finished. In this case, LCD drive circuit is still in operation to continue display. However, while display data is being rewritten, if H is set to '1' at time of SCAN = 0, the supply of LCD drive voltage is cut.

When the supply of LCD drive voltage is cut with the built-in switch, all of SEG and COM outputs attain V_{DD} level.

OUTPUT PORT (P05, P06)

P05 and P06 are 4-bit general purpose output ports. Each port is provided with a latch, and its contents are held until they are rewritten by a program. Each bit is reset to "0" by initialize operation, but the contents being held cannot be referred to by the program.

The authorization/inhibit of content rewrite by the program of P06 is controlled by SCAN bit of command register.

Command register SCAN	Object of content rewrite by program
0	Output to shift register (LCD segment data)
1	Output to P06

Unlike P05 and P06 of TCP4630AP, those of TCP4632BF do not contain decode matrix, and PLA; therefore, there is difference between them in output timing.



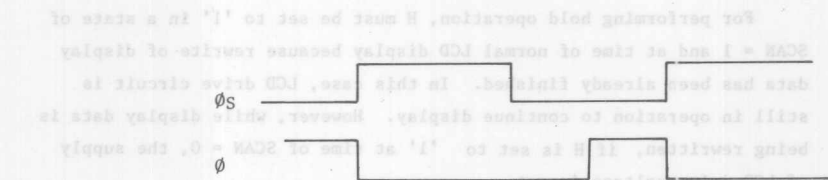
INTEGRATED CIRCUIT

TECHNICAL DATA

TCP4632BF

TECHNICAL DATA

PRELIMINARY



Port data Old data New data

Output timing of P05 and P06 of TCP4630AP

Port data Old data New data

Output timing of P05 and P06 of TCP4632BF

PLA

A program can make reference of PLA by use of a decoder for display data or the like. If 4-bit BCD data is written in PLA (Register No.7) by a program, one of sixteen addresses is selected by 4-to-16 decoder within PLA, and the corresponding 8-bit data is written in PLA register.

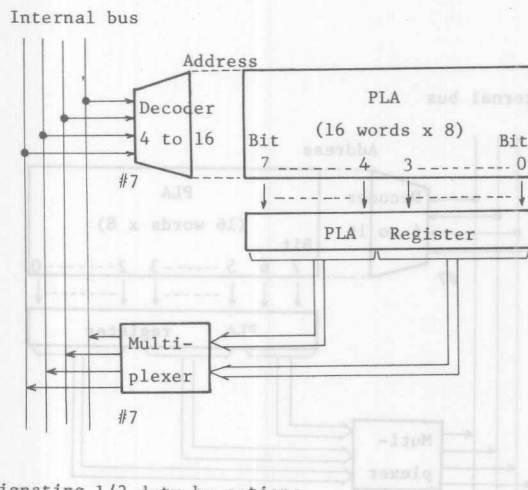
PLA contents of PLA register can be read out by executing the instruction for making reference of PLA. How to read out 8-bit data of PLA register varies with option designation of 1/3 duty or 1/4 duty. PLA register is not affected by reset operations.

(a) Designating 1/4 duty by options

The 8-bit data can be read out by executing the instruction for making reference of PLA register two times. In other words, 4-bit (bit 3 to 0) data on the lower level can be read out by the first execution of the instruction (LAR 7) for making reference of PLA

after BCD data has been written in PLA (SAR 7), and similarly 4-bit (bit 7 to 4) data on the higher level can be read out by the second execution of the same instruction.

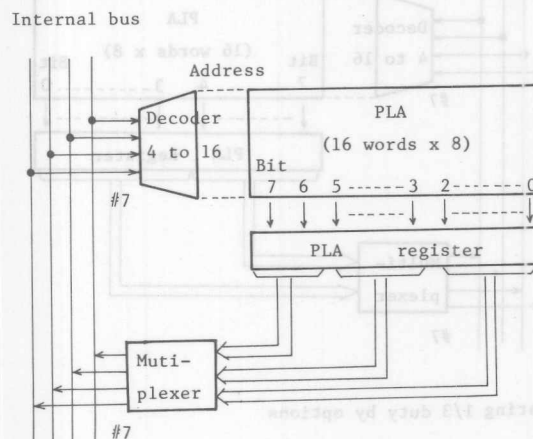
When the same data is read out again, and when PLA register is required to be updated, the reabout must be performed after BCD data has been written in the PLA over again.



(b) Designating 1/3 duty by options

The 8-bit data can be read out by executing the instruction for making reference of PLA register three times. In other words, 3-bit (bit 2 to 0) data on the lower level can be read out by the first execution of the instruction (LAR 7) for making reference of PAL after BCD data has been written in PLA (SAR 7), and similarly 3-bit (bit 5 to 3) data on the intermediate level can be read out by the second execution of the same instruction, and also 2-bit (bit 7 to 6) data on the higher level by the third execution of the same instruction, respectively.

While the reference instruction above mentioned is being executed, 1 bit (bit 3) on MSB side of the lower or intermediate level and 2 bits (bit 3 and 2) on MSB side of the higher level are always read out as zero. When the same data is read out again, and when PLA register is required to be updated, the readout is performed after BCD data has been written in the PLA over again.





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TECHNICAL DATA

TCP4632BF

ATAG JAHINHGT

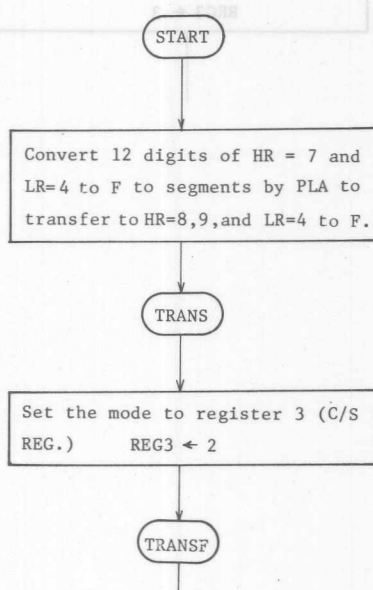
PRELIMINARY

LCD DATA TRANSFER PROGRAM - EXAMPLE

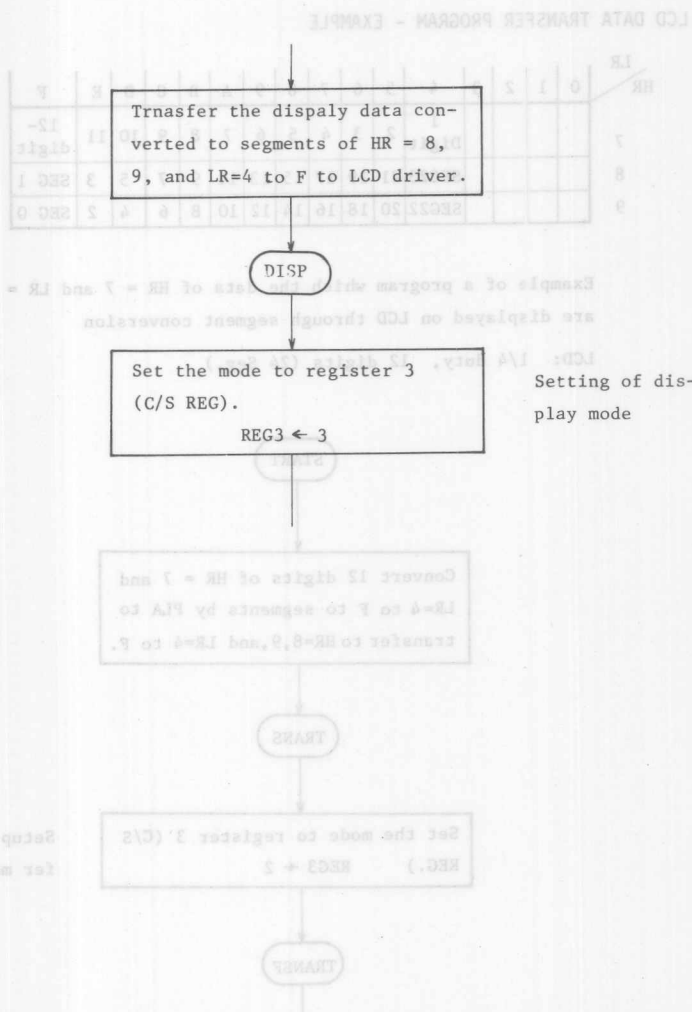
LR \ HR	0	1	2	3	4	5	6	7	8	9	A	B	C	D	E	F
7					1 Digit	2	3	4	5	6	7	8	9	10	11	12- digit
8					SEG23	21	19	17	15	13	11	9	7	5	3	SEG 1
9					SEG22	20	18	16	14	12	10	8	6	4	2	SEG 0

Example of a program which the data of HR = 7 and LR = 4 to F are displayed on LCD through segment conversion

LCD: 1/4 duty, 12 digits (24 Seg.)



Setup of transfer mode





INTEGRATED CIRCUIT

TECHNICAL DATA

TCP4632BF

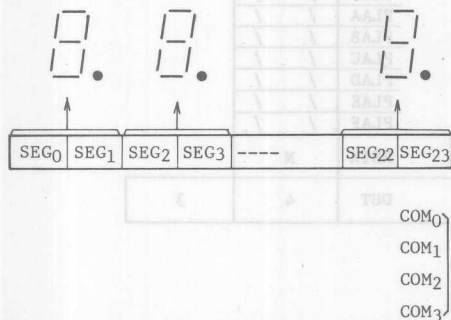
TECHNICAL DATA

PRELIMINARY

```

10 ; *** TCP4632BF LCD DATA TRANSFER PROGRAM
20 ;
0100 30 ORG 100H
0100 64 40 START: LLI 4
0101 77 50 NEXT: LHI 7
0102 04 60 LAM
0103 2F 70 SAR 7
0104 78 80 LHI 8
0105 17 90 LAR 7
0106 0C 100 SAM
0107 79 110 LHI 9
0108 17 120 LAR 7
0109 0C 130 SAM
010A 02 140 ICL
010B 06 150 LAL
010C 90 160 ADI 0
010D D110 170 BCC NEXT
010F 42 180 TRANS: LAI 2
0110 2B 190 SAR 3 ; DISP=1,SCAN=0 SET
0111 64 200 LLI 4
0112 78 210 TRANSF: LHI 8
0113 04 220 LAM
0114 2E 230 SAR 6
0115 79 240 LHI 9
0116 04 250 LAM
0117 2E 260 SAR 6
0118 02 270 ICL
0119 06 280 LAL
011A 90 290 ADI 0
011B D211 300 BCC TRANSF
011D 43 310 DISP: LAI 3
011E 2B 320 SAR 3 ; DISP=SCAN=1 SET
330 ;
340 ;

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INTEGRATED CIRCUIT

東芝

TECHNICAL DATA

TCP4632BF

TECHNICAL DATA

PRELIMINARY

TCP4632BF MASK OPTIONS

Oscillation frequency	OSC	TYP032					
		050 400K ceramic IFT					
Dividing ratio for internal clock	CP	02					
External timing output	CK	C1					
Counter	Divider 1 Input	PD	CP				
	Divider 3 Input	COUNTER PDR	PD2				
Buffer	Reset timing	PDR	N				
	Buffer 0 Input	C0	PI60				
	Buffer 1 Input	COUNTER C1	RD7				
	Buffer 2 Input	BUFFER C2	RDA				
	Buffer 3 Input	C3	RDD				
H flag	HOLD	H					
Restart condition	RSTH	C3					
Input/Output port	Port 0	STD	D(PROG)	1 (OUT)			
Input/Output port	Port 2	P2	/F/(OUT)	/F/(OUT)	/O/(IN)	/O/(IN)	/O/(IN)
Input/Output port	Port 4	P4	/F/(OUT)	/3/(IN/OUT)	/F/(OUT)	/3/(IN/OUT)	/O/(IN)
Input resistance (Input port 5)	P15	0 (UP)	1 (DOWN)				
P L A (#7)	Line 0	PLA0	/	/			
	Line 1	PLA1	/	/			
	Line 2	PLA2	/	/			
	Line 3	PLA3	/	/			
	Line 4	PLA4	/	/			
	Line 5	PLA5	/	/			
	Line 6	PLA6	/	/			
	Line 7	PLA7	/	/			
	Line 8	PLA8	/	/			
	Line 9	PLA9	/	/			
	Line A	PLAA	/	/			
	Line B	PLAB	/	/			
	Line C	PLAC	/	/			
	Line D	PLAD	/	/			
Line E	PLAE	/	/				
Line F	PLAF	/	/				
Oscillation Stop Control	PI60	RSTX	N				
LCD Duty	DUT	4	3				



INTEGRATED CIRCUIT

TECHNICAL DATA

INTEGRATED CIRCUIT

TCP4632BF

TECHNICAL DATA

PRELIMINARY

ABSOLUTE MAXIMUM RATINGS

SYMBOL	ITEM	RATING	UNIT
V _{DD}	Supply Voltage	-0.3 to +7.0	V
V _{IN}	Input Voltage	-0.3 to V _{DD} + 0.3	V
V _{OUT}	Output Voltage	-0.3 to V _{DD} + 0.3	V
P _D	Power Dissipation	400	mW
T _{sol}	Soldering Temperature-Time	260 (10 SEC)	°C
T _{slg}	Storage Temperature	-55 to +125	°C
T _{opr}	Operating Temperature	-20 to +70	°C

ALLOWABLE OPERATING CONDITIONS

SYMBOL	ITEM	RATING	UNIT
V _{DD}	Supply Voltage	4 to 6	V
T _a	Ambient Temperature	-20 to +70	°C
I _{OUT}	Max. Output Current	±3	mA
f _x	X'tal Operating Frequency	40 to 400	kHz
t _{CY}	Cycle Time	10 to 100	μs
V _{LCD}	LCD Supply Voltage (V _{LCD} is with respect to V _{DD})	-V _{DD} to -2.7	V



INTEGRATED CIRCUIT

TECHNICAL DATA

TCP4632BF

TECHNICAL DATA

PRELIMINARY

DC CHARACTERISTICS ($T_a = -20$ to $+70^\circ\text{C}$, $V_{DD} = 4$ to 6V)

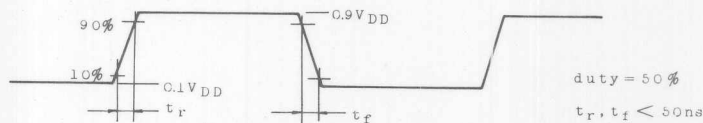
SYMBOL	PARAMETER	TEST CONDITION	MIN.	(Note 1) TYP.	MAX.	UNIT
V_{IH}	Input High Voltage		$V_{DD} \times 0.7$	-	V_{DD}	V
V_{IHS}	Input High Voltage (Schmitt)		$V_{DD} \times 0.85$	-	V_{DD}	
V_{IHC}	Input High Voltage (X_{IN} Input)		$V_{DD} \times 0.75$	-	V_{DD}	
V_{IL}	Input Low Voltage		0	-	$V_{DD} \times 0.3$	
V_{ILS}	Input Low Voltage (Schmitt)		0	-	$V_{DD} \times 0.15$	
V_{ILC}	Input Low Voltage (X_{IN} Input)		0	-	$V_{DD} \times 0.25$	μA
I_{IH}	Input High Current	$V_{DD}=6\text{V}$, $V_{IN}=6\text{V}$	-	-	20	
I_{IL}	Input Low Current	$V_{DD}=6\text{V}$, $V_{IN}=0\text{V}$	-	-	-20	$\text{k}\Omega$
R_{IN}	Input Resistance (P_{I5})	$V_{DD}=5\text{V}$	75	150	350	
V_{OH}	Output High Voltage (Port)	$V_{DD}=5\text{V}$, Output open	4.7	4.9	-	V
V_{OL}	Output Low Voltage (Port)	$V_{DD}=5\text{V}$, Output open	-	0.1	0.3	
I_{OH}	Output High Current (P_1)	$V_{DD}=4.5\text{V}$, $V_{OH}=2.4\text{V}$	-0.7	-	-	mA
I_{OH2}	Output High Current (P_0, P_2, P_4, CK)	$V_{DD}=4.5\text{V}$, $V_{OH}=2.4\text{V}$	-0.35	-	-	
I_{OH3}	Output High Current (P_5, P_6)	$V_{DD}=4.5\text{V}$, $V_{OH}=2.4\text{V}$	-0.15	-	-	
I_{OL}	Output Low Current (P_1)	$V_{DD}=4.5\text{V}$, $V_{OL}=0.45\text{V}$	1.6	-	-	
I_{OL2}	Output Low Current (P_0, P_2, P_4, CK)	$V_{DD}=4.5\text{V}$, $V_{OL}=0.45\text{V}$	0.8	-	-	
I_{OL3}	Output Low Current (P_5, P_6)	$V_{DD}=4.5\text{V}$, $V_{OL}=0.45\text{V}$	0.4	-	-	$\text{k}\Omega$
R_{OS3}, R_{OS0}	Output Impedance (SEG)	$V_{DD}=5\text{V}$, $V_{DD}-V_{LCD}=3\text{V}$ (Note 5)	-	2	T.B.D	
R_{OC3}, R_{OC0}	Output Impedance (COM)	$V_{OUT}=V_{LCD}+0.5\text{V}/$ $V_{DD}-0.5\text{V}$	-	2	T.B.D	
R_{OS2}, R_{OS1}	Output Impedance (SEG)	$V_{DD}=5\text{V}$, $V_{DD}-V_{LCD}=3\text{V}$ (Note 5)	-	20	T.B.D	
R_{OC2}, R_{OC1}	Output Impedance (COM)	$V_{OUT}=3+0.5\text{V}/$ $4-0.5\text{V}$	-	20	T.B.D	
V_{OS1}	Output Intermediate	$V_{DD}=5\text{V}$, $V_{DD}-V_{LCD}=3\text{V}$	3 - 0.2	3	3 + 0.2	V
V_{OS2}	Voltage (SEG, COM)		4 - 0.2	4	4 + 0.2	
I_{DD0}	V_{DD} Supply Current in Normal Operation	(Note 4) $f_x = 400\text{ kHz}$	-	600	T.B.D	μA
I_{DDH}	V_{DD} Supply Current in Hold operation		-	250	T.B.D	

Note 1) Typical values are at $T_a=25^\circ\text{C}$ and $V_{DD}=5\text{V}$.

2) Output characteristic excludes X_{OUT} terminal.

3) Output current at the time when other terminals than those to be tested are open.

4) Test conditions of current dissipation
 $V_{DD} = 6\text{V}$, $V_{IN} = V_{IH}/V_{IL}$ (all valid), P_{I5} Open, $C_L = 50\text{pF}$
 X_{IN} Input waveform



5) When supplying V_{LCD} power, When switching input/output.



INTEGRATED CIRCUIT

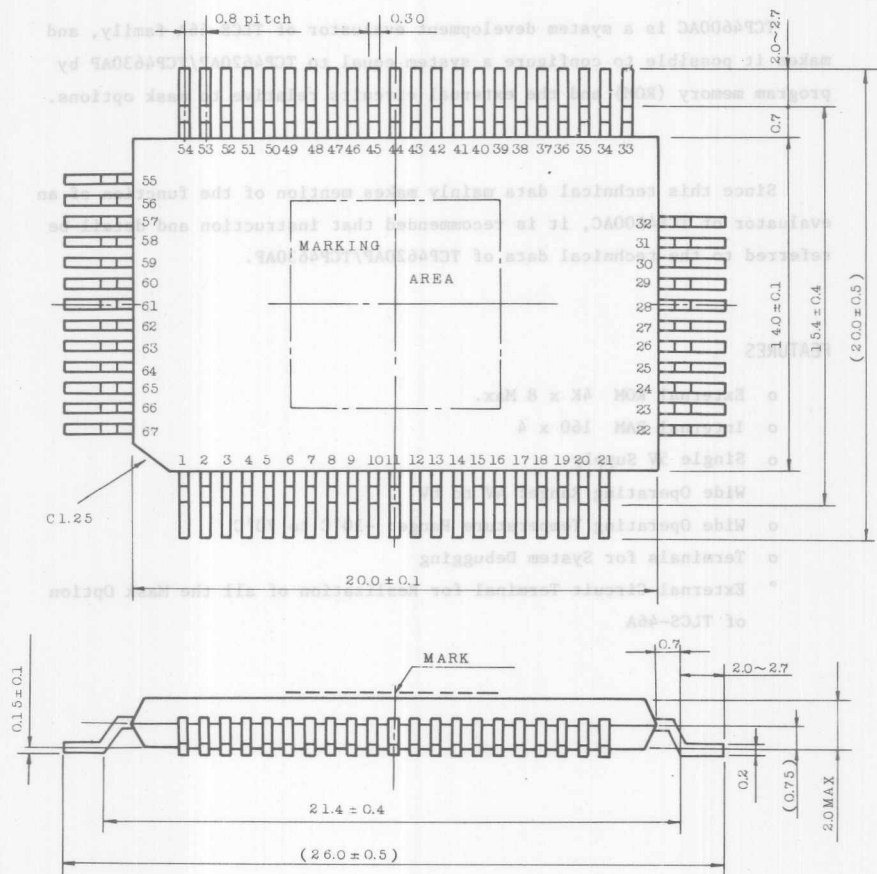
TECHNICAL DATA

TCP4632BF

TECHNICAL DATA

PRELIMINARY

OUTLINE DRAWINGS





INTEGRATEDCIRCUIT

TECHNICAL DATA

"C²MOS" DIGITAL INTEGRATED CIRCUIT

TCP4600AC

SILICON MONOLITHIC

CMOS 4-BIT SINGLE CHIP MICROCOMPUTER

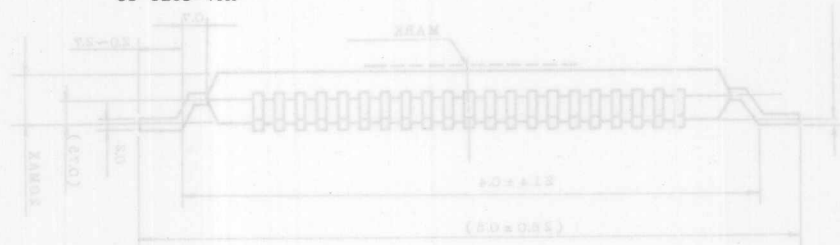
GENERAL DESCRIPTION

TCP4600AC is a system development evaluator of TLCS-46A family, and makes it possible to configure a system equal to TCP4620AP/TCP4630AP by program memory (ROM) and the external circuits relative to mask options.

Since this technical data mainly makes mention of the function of an evaluator of TCP4600AC, it is recommended that instruction and detail be referred to the technical data of TCP4620AP/TCP4630AP.

FEATURES

- o External ROM 4K x 8 Max.
- o Internal RAM 160 x 4
- o Single 5V Supply
- Wide Operating Range: 4V to 6V
- o Wide Operating Temperature Range: -10°C to 70°C
- o Terminals for System Debugging
- o External-Circuit Terminal for Realization of all the Mask Option of TLCS-46A





INTEGRATED CIRCUIT

TECHNICAL DATA

TCPC400AC



PIN CONNECTIONS (TOP VIEW)

Pin No.		Symbol	Function
64	1	P ₀₀	Power
63	2	P ₀₁	Power
62	3	P ₀₂	Power
61	4	P ₀₃	Power
60	5	RD/DI ₀	Read/Decompress
59	6	RD/DI ₁	Read/Decompress
58	7	RD/DI ₂	Read/Decompress
57	8	RD/DI ₃	Read/Decompress
56	9	RD ₄	Read
55	10	RD ₅	Read
54	11	RD ₆	Read
53	12	RD ₇	Read
52	13	R/H	Read/High
51	14	INTH	Interrupt High
50	15	MH	Master High
49	16	RS	Reset
48	17	SEL ₂	Select 2
47	18	SEL ₃	Select 3
46	19	SEL ₄	Select 4
45	20	SEL ₅	Select 5
44	21	SEL ₆	Select 6
43	22	SEL ₇	Select 7
42	23	INT	Interrupt
41	24	RESET	Reset
40	25	Ø	Open
39	26	Ø	Open
38	27	CP	Control
37	28	ST(H)	Status High
36	29	HOLD	Hold
35	30	RSTH	Reset High
34	31	PO ₅₀	Power
33	32	GND	Ground
64	1	VDD	Power
63	2	P ₁₃	Power
62	3	P ₁₂	Power
61	4	P ₁₁	Power
60	5	P ₁₀	Power
59	6	PC ₁₁	Power
58	7	PC ₁₀	Power
57	8	PC ₉	Power
56	9	PC ₈	Power
55	10	PC ₇	Power
54	11	PC ₆	Power
53	12	PC ₅	Power
52	13	PC ₄	Power
51	14	PC/DO ₃	Power
50	15	PC/DO ₂	Power
49	16	PC/DO ₁	Power
48	17	PC/DO ₀	Power
47	18	PCH	Power
46	19	ST(D)	Status Data
45	20	WEN	Write Enable
44	21	PO ₆₇	Power
43	22	PO ₆₆	Power
42	23	PO ₆₅	Power
41	24	PO ₆₄	Power
40	25	PO ₆₃	Power
39	26	PO ₆₂	Power
38	27	PO ₆₁	Power
37	28	PO ₆₀	Power
36	29	PO ₅₄	Power
35	30	PO ₅₃	Power
34	31	PO ₅₂	Power
33	32	PO ₅₁	Power

PIN NAMES & PIN DESCRIPTION

Pin Name	Input/Output	Function
$P_{03} - P_{00}$	Input/Output	4-bit general purpose I/O port State of input/output is designated by WEN terminal input. (common to TLCS-46A family)
$P_{13} - P_{10}$	Output	4-bit general purpose output port (common to TLCS-46A family)
$PO_{54} - PO_{50}$	Output	5-digit output port for display Content of built-in decode matrix is already designated (common to TLCS-46A family)
$PO_{67} - PO_{60}$	Output	8-segment output port for display Built-in PLA is already designated (common to TLCS-46A family)
$\overline{\text{RESET}}$	Input	Initialize Signal Input (without Schmitt circuit) (common to TLCS-46A family)
$\overline{\text{INT}}$	Input	Interrupt request signal input (without Schmitt circuit) (common to TLCS-46A family)
$PC_{11} - PC_4$	Output	The higher order 8-bit address output to external ROM
$PC/DO_3 - PC/DO_0$	Output	The lower order 4-bit address output to external ROM/Port data output
$RD_7 - RD_4$	Input	The higher order 4-bit data input from external ROM
$RD/DI_3 - RD/DI_0$	Input	The lower order 4-bit data input from external ROM/Input port
$\overline{\text{SEL}}_7 - \overline{\text{SEL}}_2$	Output	Selection signal output for external port register and input port



INTEGRATEDCIRCUIT

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TECHNICAL DATA

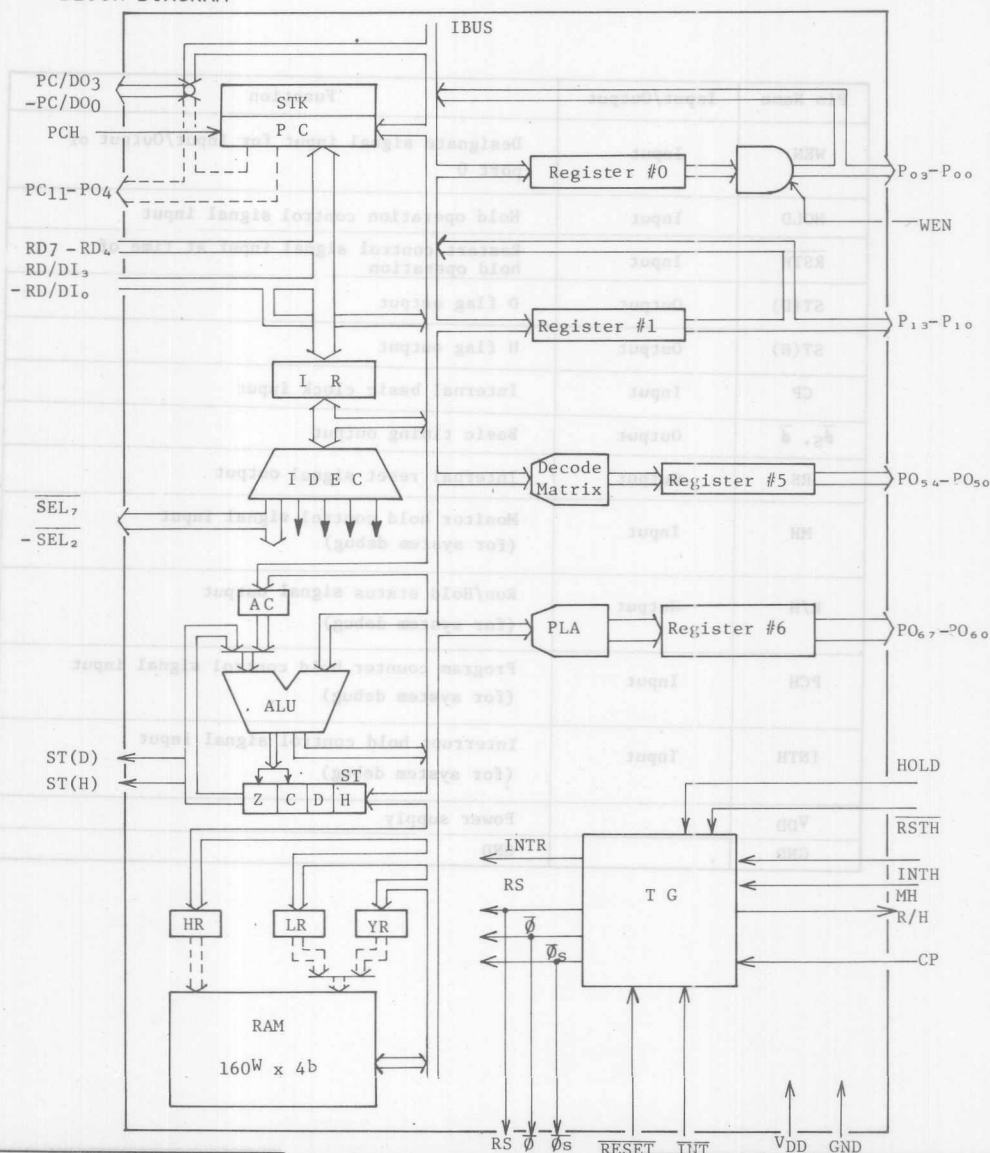
TCP4600AC

TECHNICAL DATA



Pin Name	Input/Output	Function
WEN	Input	Designate signal input for Input/Output of port 0
HOLD	Input	Hold operation control signal input
RSTH	Input	Restart control signal input at time of hold operation
ST(D)	Output	D flag output
ST(H)	Output	H flag output
CP	Input	Internal basic clock input
ϕ_S, ϕ	Output	Basic timing output
RS	Output	Internal reset signal output
MH	Input	Monitor hold control signal input (for system debug)
R/H	Output	Run/Hold status signal output (for system debug)
PCH	Input	Program counter hold control signal input (for system debug)
INTH	Input	Interrupt hold control signal input (for system debug)
VDD		Power supply
GND		GND

BLOCK DIAGRAM



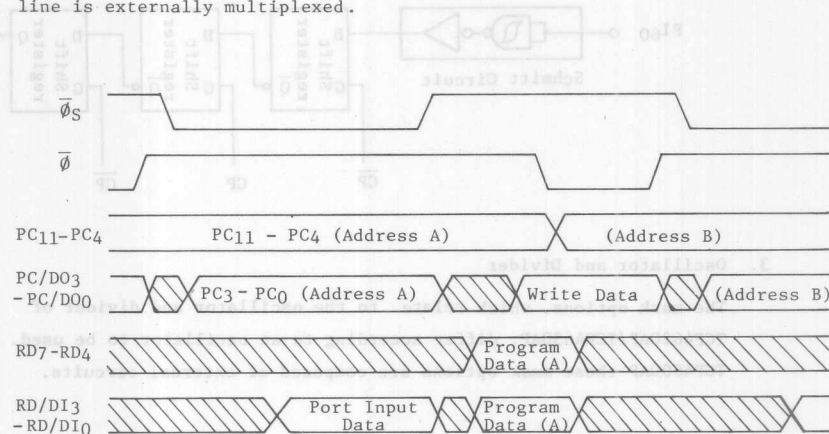
FUNCTIONAL DESCRIPTION

TCP4600AC is a system development evaluator which is used for developing TLCS-46A application system (program) and for confirming its operation. This makes it possible to form a configuration equal to TCP4620AP/TCP4630AP by program memory (hereinafter called ROM) and the external circuits relative to mask options.

1. Connection of Program Memory

Program counter (PC, 12 bits) output is used as address signal of external ROM (maximum capacity is 4096 words x 8 bits). Since the lower order 4 bits of address signal is multiplexed with the output of port data, it is necessary that they are externally separated.

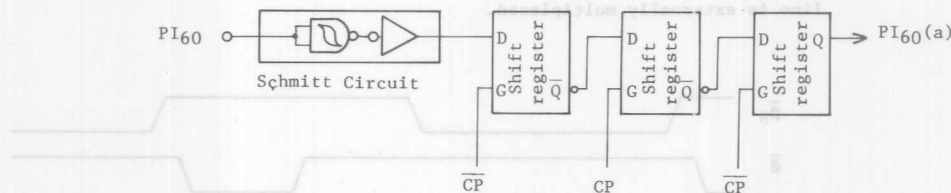
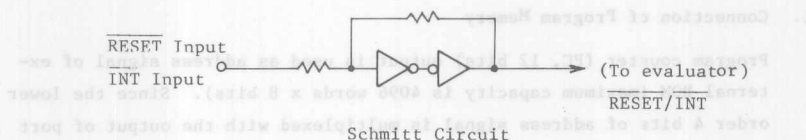
The data (8 bits) read out of ROM is read as instruction code in TCP4600AC. At this time, the data line of the lower order 4 bits is also used as port input data, so that it is necessary that data line is externally multiplexed.



2. Schmitt Circuit

Each terminal of $\overline{\text{RESET}}$, $\overline{\text{INT}}$, and PI60 of TCP4620AP/TCP4630AP are input terminals with Schmitt circuit. However, since no Schmitt circuit is contained in TCP4600AC, the circuit must be externally configured.

It is necessary to add shift register for timing shaping to PI60 terminal.



3. Oscillator and Divider

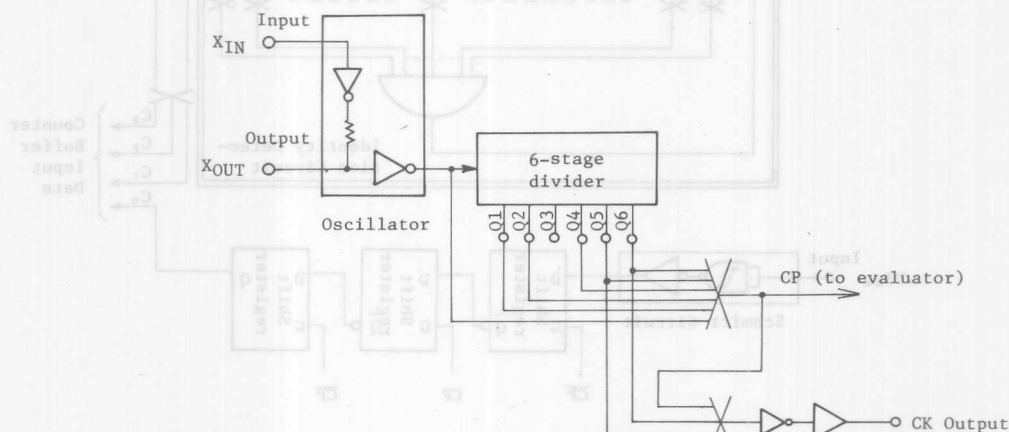
The mask options, which relate to the oscillator and divider of TCP4620AP/TCP4630AP, differ according to an oscillator to be used. For TCP4600AP these mask options are composed of external circuits.

(1) Oscillator

The basic clock (CP) of TCP4600AC is externally supplied. In this case, the divider forming the basic clock as well as the oscillation circuits of the oscillator to be used are externally composed, and the output of a divider suitable for oscillation frequency is supplied, as a basic clock, to the CP terminal of TCP4600AC.

Since TCP4600AC is not provided with the CK terminal for external timing, a signal equivalent to the CK terminal must be also composed of external circuit.

While the power is being supplied to the evaluator chip, the clock must be being supplied to the CP terminal at all times.

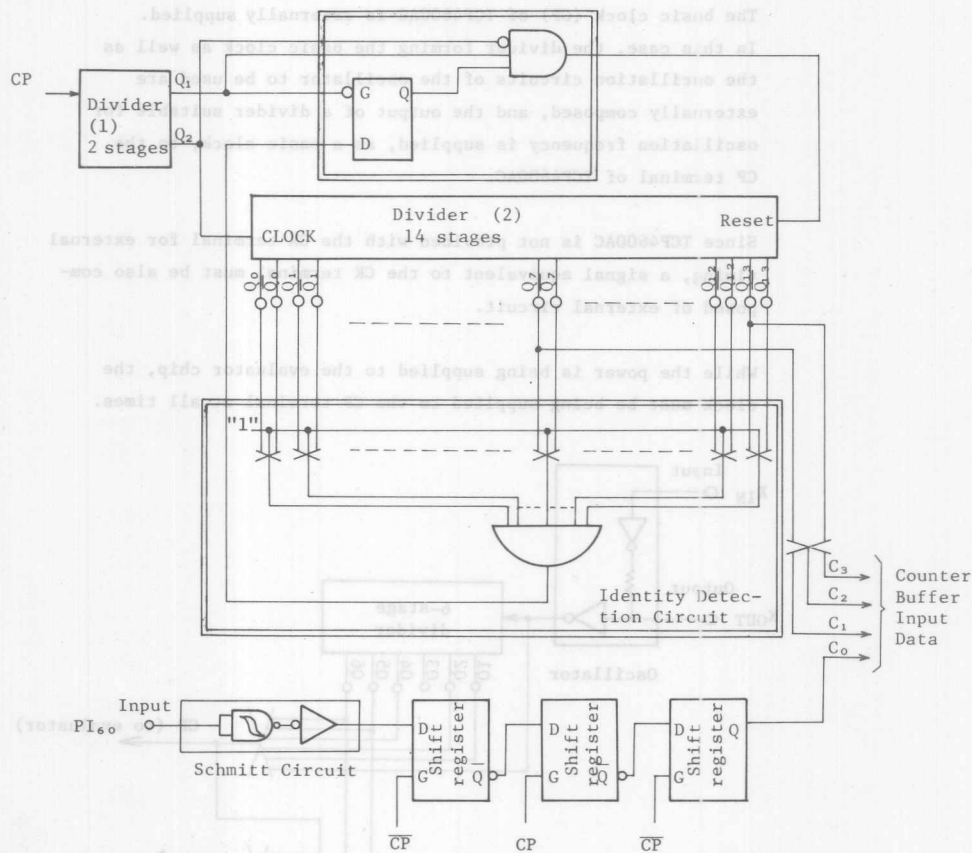



(Note) "X" means that either is connected.

(So with the following figures.)

(2) Divider

An example of circuit configuration around a divider is shown as follows:



The portion of  is required only when 100K Xtal is designated by mask options of mass production chip, and further 14-stage divider (2) is used as a resettable divider of count value "12500".

4. Input Port and Output Port

The input port and output port in TCP4620AP/TCP4630AP have plentiful mask options. In TCP4600AC, such mask options are composed of external circuits.

(1) Input port

The data of input port is input from RD/DI terminal. When the data of input port (port No. i) is input to RD/DI terminal during the period of time when the equation,

$$SEL_i \cdot \bar{\phi}_s = 1 \quad (i : \text{port No.}),$$

holds, TCP4600AC starts reading it as input port data.

(2) Output port

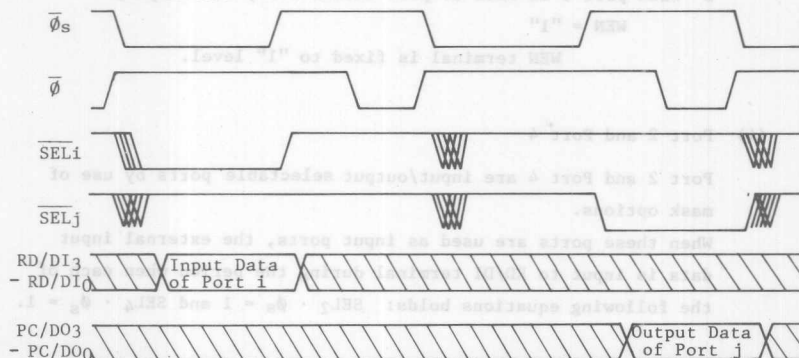
The data of output port is output from PC/D0 terminal.

Since TCP4600AC outputs the data of output port (port No. i) from PC/D0 terminal during the period of time when the equation,

$$SEL_i \cdot \phi = 1 \quad (i : \text{port No.}),$$

hold, this data is written in the externally installed register.

Further, since at time of system reset an internal initialize signal is output from RS terminal, it is necessary to clear (all "0") the port register by use of this signal and to initialize it.



(3) Port 0

Port 0 is a port that can make switching of input/output by program (D flag of ST), and can be designated to a port exclusively used for output by mask options.

In TCP4600AC, the mask option of this port can be realized by use of each terminal of WEN and ST(D).

WEN terminal is an input line that defines whether port 0 is placed in an output mode or an input mode. When the terminal is at "1" level, it places port 0 in an output mode and when it is at "0" level, it places port 0 in an input mode.

A state of D flag of status register is output from ST (D) terminal.

- o When input and output are switched by use of program,

$$\text{WEN} = \text{ST(D)}$$

WEN terminal is externally connected to ST(D) terminal.

- o When port 0 is used as port exclusively for output,

$$\text{WEN} = "1"$$

WEN terminal is fixed to "1" level.

(4) Port 2 and Port 4

Port 2 and Port 4 are input/output selectable ports by use of mask options.

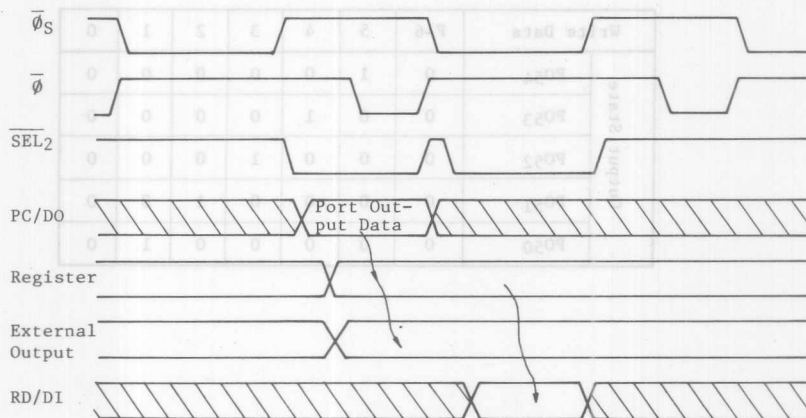
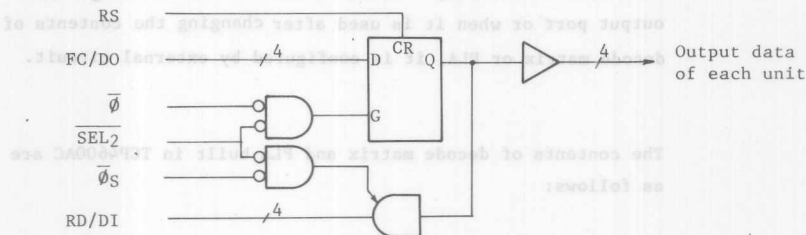
When these ports are used as input ports, the external input data is input to RD/DI terminal during the period when each of the following equations holds: $\text{SEL}_2 \cdot \phi_S = 1$ and $\text{SEL}_4 \cdot \phi_S = 1$.

On the other hand, when these ports are used as output ports, output data are output to PC/D0 terminal during the period when each of the following equations holds:

$$\text{SEL}_2 \cdot \bar{\phi} = 1 \text{ and } \text{SEL}_4 \cdot \bar{\phi} = 1.$$

Therefore, this data is written in the register externally installed, and is output to the outside through a buffer.

And, at the time when the equations, such as $\text{SEL}_2 \cdot \bar{\phi}_S = 1$ and $\text{SEL}_4 \cdot \bar{\phi}_S = 1$, hold, the outputs of respective registers are input to RD/DI terminal. The externally installed register must be cleared (all "0") by the internal initialize signal from RS. terminal.





(5) Port 3

Port 3 is I/O port exclusively used for TCP4600AC. The function of port 3 is the same as the function of other ports.

This port is designated as register No. "3" even in case where it is used as either of input port or output port.

(6) Output port 5 and output port 6 (output port 7)

For TCP4600AC, each output terminal of P05 and P03 is available as output for display. However, when it is used as general output port or when it is used after changing the contents of decode matrix or PLA, it is configured by external circuit.

The contents of decode matrix and PLA built in TCP4600AC are as follows:

Contents of Decode Matrix

Write Data		F-6	5	4	3	2	1	0
Output State	P054	0	1	0	0	0	0	0
	P053	0	0	1	0	0	0	0
	P052	0	0	0	1	0	0	0
	P051	0	0	0	0	1	0	0
	P050	0	0	0	0	0	1	0

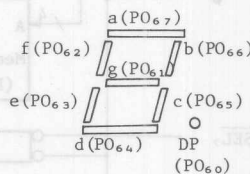
PLA

PLA can be expressed as memory of 16 words x 8 bits.

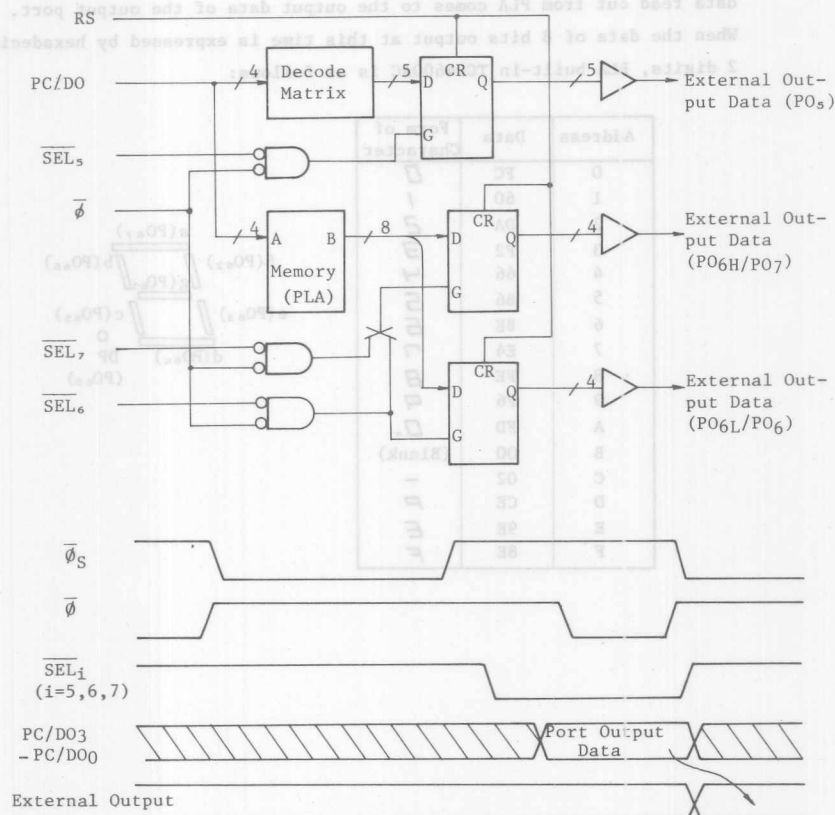
The 4-bit write data for port 6 is the address of PLA, and the 8-bit data read out from PLA comes to the output data of the output port.

When the data of 8 bits output at this time is expressed by hexadecimal 2 digits, PLA built-in TCP4600AC is as follows:

Address	Data	Form of Character
0	FC	0
1	60	1
2	DA	2
3	F2	3
4	66	4
5	B6	5
6	BE	6
7	E4	7
8	FE	8
9	F6	9
A	FD	0.
B	00	(Blank)
C	02	-
D	CE	P
E	9E	E
F	8E	F



When the built-in decode matrix and PLA are used changing their contents or are used as general output ports, they are externally configured by use of data output PC/DO, select signals $\overline{\text{SEL}}_5$, $\overline{\text{SEL}}_6$ and $\overline{\text{SEL}}_7$ and timing signal $\overline{\phi}$.



Output Timing of P05, P06 (P07)

5. Hold Operation

TCP4620AP/TCP4630AP is provided with hold function. In TCP4600AC, this function is configured by each terminal of HOLD, RSTH and ST(H), and the signal of C₃ which is MSB of counter buffer input configured by external circuits. (For C₃, refer to the figure of divider.)

In case hold operation is performed:

HOLD = ST(H) : Designation of hold operation application

RSTH = C₃ : Designation of hold operation release signal

Each terminal of HOLD and ST(H) is externally connected.

C₃ signal that is MSB of counter buffer is input to RSTH terminal.

In case hold operation is not performed:

HOLD = "0" : Designation of no use of hold operation

RSTH = "0" : Designation of no use of hold operation

Each terminal of HOLD and RSTH is fixed to the "0" level.

CONTROL TERMINALS FOR DEBUG

There are some functions and terminals to make easy the development of TLCS-46A application system (program).

(1) MH terminal (Monitor hold control input)

Monitor hold function stops the operation of TCP4600AC by unit of execution instruction.

The operation stops after completion of current execution instruction by inputting "1" level into MH terminal. However, during "1" period of Y register flag (EYR = 1), the operation does not stop. When the system enters into the interrupt service routine, if stop request is made, the system stops after having jumped to the interrupt service routine.

In the stop state, program counter output the next address. Restart is made by inputting "0" level into MH terminal, and the first cycle makes instruction fetch and at the same time executes NOP instruction internally.

(2) R/H terminal (Run/Hold status output)

Run/Hold monitor function is the response signal of monitor hold function. During stop of operation by monitor hold function, "0" level is output from R/H terminal (which is reset by the instruction cycle just short of stopping by MH signal), and during normal operation "1" level is output from R/H terminal.

(3) PCH terminal (Program counter hold control input)

Program counter hold function holds the previous state without updating the value of program counter. This function is operated by inputting "1" level into PCH terminal.

(4) INTH terminal (Interrupt hold control input)

Interrupt hold function is a function to make interrupt request waiting. Even if interrupt latch is set by inputting "1" level into INTH terminal, jump to interrupt routine is not performed. In this case, interrupt request is kept waiting until "0" level is input into INTH terminal.



INTEGRATED CIRCUIT

TECHNICAL DATA

TCP4600AC

TECHNICAL DATA



ELECTRICAL CHARACTERISTICS

ABSOLUTE MAXIMUM RATINGS

SYMBOL	ITEM	RATING
V_{DD}	Supply Voltage	-0.3V to +7.0V
V_{IN}	Input Voltage	-0.3V to $V_{DD}+0.3V$
V_{OUT}	Output Voltage	-0.3V to $V_{DD}+0.3V$
P_D	Power Dissipation	600 mW
T_{sol}	Soldering Temperature & Time	260°C (10 SEC)
T_{stg}	Storage Temperature	-55°C to +125°C
T_{opr}	Operating Temperature	-10°C to +70°C

ALLOWABLE OPERATING CONDITIONS

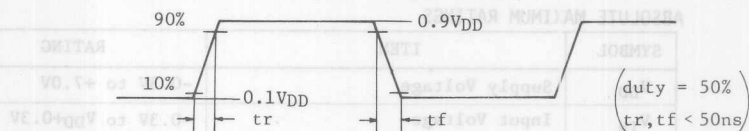
SYMBOL	PARAMETER	RATING
T_a	Ambient Temperature	-10°C to +70°C
V_{DD}	Supply Voltage	4V to 6V
V_{OH}	Output High Voltage	Min. $V_{DD}-3.5V (\geq 1.5V)$
V_{OL}	Output Low Voltage	Max. 3V
fcp	Basic Clock Frequency	20KHz to 200KHz

DC CHARACTERISTICS ($T_a=-10^\circ\text{C}$ to 70°C , $V_{DD}=4\text{V}$ to 6V)

SYMBOL	PARAMETER	TEST CONDITIONS	MIN.	TYP. (Note1)	MAX.	UNIT
V_{IH}	Input High Voltage		$V_{DD} \times 0.7$	$V_{DD} \times 0.55$	V_{DD}	V
V_{IL}	Input Low Voltage		0	$V_{DD} \times 0.45$	$V_{DD} \times 0.3$	
I_{IH}	Input High Current	$V_{DD}=6V$, $V_{IN}=6V$	-	-	20	μA
I_{IL}	Input Low Current	$V_{DD}=6V$, $V_{IN}=0V$	-	-	-20	
V_{OH}	Output High Voltage	$V_{DD}=5V$, Output Open	4.7	4.9	-	V
V_{OL}	Output Low Voltage		-	0.1	0.3	
I_{OH}	Output High Current	$V_{DD}=4.5V$, $V_{OH}=2.4V$	-0.7	-2	-	mA
I_{OHI}	Output High Current (P05, P06)	$V_{DD}=5V$, $V_{OH}=4.2V$	-2.5 -1.1	-6 -2.5	-	
I_{OL}	Output Low Current		1.6	4	-	
I_{OL1}	Output Low Current (P05, P06)	$V_{DD}=4.5V$, $V_{OL}=0.45V$	3.2	8	-	
I_{DDO}	V_{DD} Supply Current in Normal Operation	$V_{DD}=6V$, fcp=100KHz	-	150	450	μA
I_{DDH}	V_{DD} Supply Current in Hold Operation	Output Open $V_{IN}=5.9V/OLV$ (Note 2)	-	40	120	

Note1: Typical values are at $T_a=25^\circ\text{C}$ and $V_{DD}=5V$.

Note 2: CP input waveform at the time of V_{DD} Supply Current

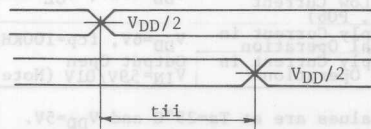


AC CHARACTERISTICS ($T_a = -10^\circ\text{C}$ to $+70^\circ\text{C}$, $V_{DD} = 4\text{V}$ to 6V)

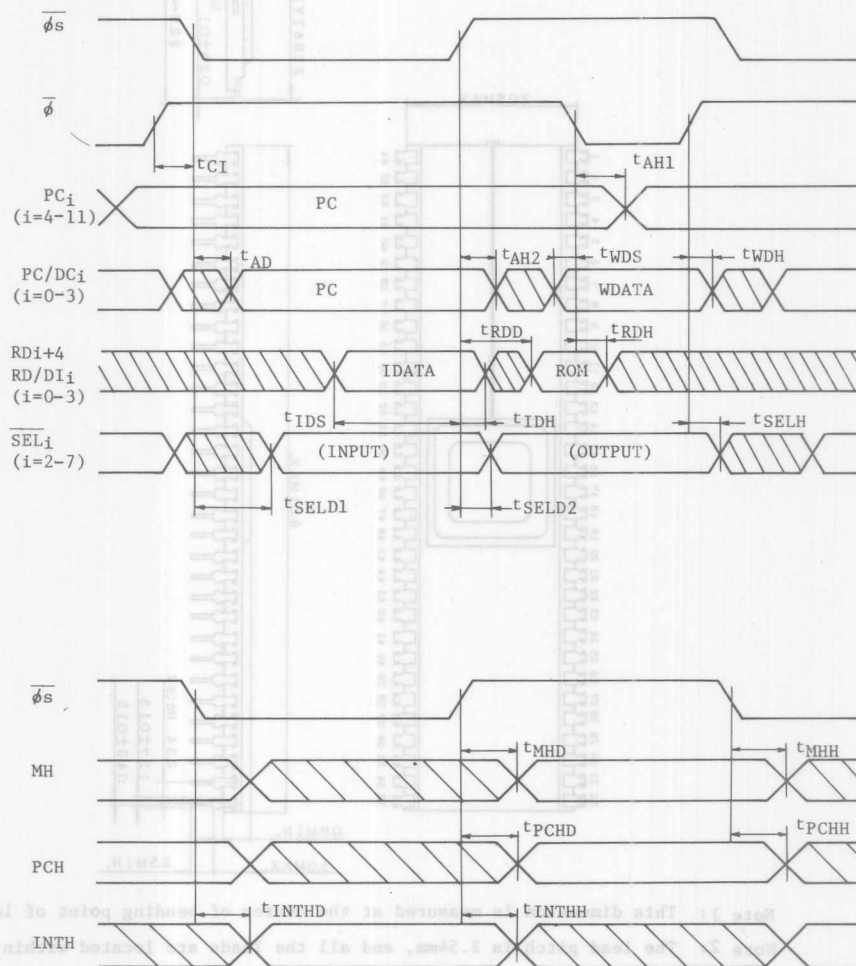
SYMBOL	PARAMETER	TEST CONDITION	MIN.	TYP. (NOTE 1)	MAX.	UNIT
t_{CI}	Timing Signal Inhibit Time		150	-	1500	ns
t_{AD}	Address Delay Time		-	-	2000	ns
t_{AH1}	Address Hold Time	$CL = 50\text{ pF}$	80	-	-	ns
t_{AH2}	"		200	-	-	ns
t_{RDD}	Data Delay Time		-	-	1000	ns
t_{RDH}	Data Hold Time	(Note 2)	80	-	-	ns
t_{SELD1}	SEL Delay Time (for Input)		-	-	1000	ns
t_{SELD2}	SEL Delay Time (for Output)		100	-	500	ns
t_{SELH}	SEL Hold Time		300	-	-	ns
t_{WDS}	Write Data Set Up Time		500	-	-	ns
t_{WDH}	Write Data Hold Time		300	-	-	ns
t_{IDS}	Read Data Set Up Time		1000	-	-	ns
t_{IDH}	Read Data Hold Time		100	-	-	ns
t_{MHD}	MH Input Delay Time		-	-	500	ns
t_{MHH}	MH Input Hold Time		100	-	-	ns
t_{PCHD}	PCH Input Delay Time		-	-	500	ns
t_{PCHH}	PCH Input Hold Time		100	-	-	ns
t_{INTHD}	INTH Input Delay Time		-	-	500	ns
t_{INTHH}	INTH Input Hold Time		100	-	-	ns
t_{WCP}	CP Pulse Width	$V_{IN} = V_{IH}/V_{IL}$	$0.4/f_{CP}$	-	$0.6/f_{CP}$	SEC
t_{WRESET}	RESET Pulse Width		2 tcy	-	-	μs
t_{WINT}	INT Pulse Width		2 tcy	-	-	μs

Note 1: Typical values are at $T_a = 25^\circ\text{C}$ and $V_{DD} = 5\text{V}$.

Note 2: AC test condition

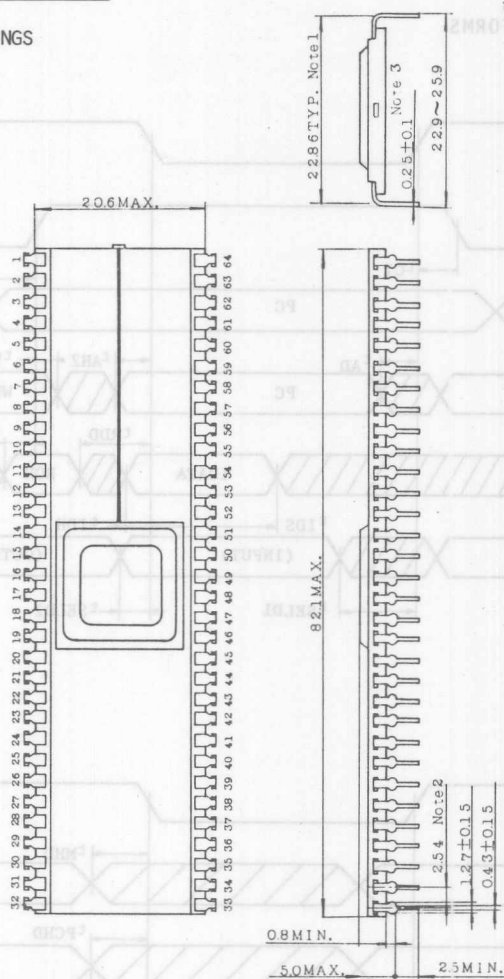


TIMING WAVEFORMS



OUTLINE DRAWINGS

Unit in mm



Note 1: This dimension is measured at the center of bending point of leads.

Note 2: The lead pitch is 2.54mm, and all the leads are located within ± 0.25 mm from their theoretical positions with respect to No. 1 and No. 64 leads.

Note 3: The metal on the side of the package is GND level.

PRECAUTIONS FOR USE

(1) Clock at time of power supplied

When TLCS-46A starts by RESET, clock must be always supplied. There is no problem when clock is obtained by externally mounting the oscillator of crystal, celamic or IFT by use of internal clock generator in TCP4620AP/TCP4630AP, but care should be exercised when clock is externally supplied or when TCP4600AC is used.

(2) Control of I/O port

In port 0, Input/Output can be switched by program; therefore, care should be taken not to become driver short between the port and external circuit.

(3) Current capacity of output port

Each of output port 5 and output port 6 has a large current capacity as port for display. However, if the output port is supplied with a large current exceeding its capacity, it may cause destruction or deterioration in character.

(4) Handling of unused terminal

When an unused input terminal is left open, it may cause malfunction and increase in power dissipation; therefore, insure to connect the terminals to V_{DD} or GND level. (It is the safest method to connect terminal via resistance.)

Further, insure to connect TEST terminal to GND because this terminal is installed for LSI testing.

PRECAUTIONS FOR USE

(5) Electrostatic destruction

In TLCS-46A series, the input circuit is provided with protective resistance and protective diode for preventing electrostatic destruction. However, the surge equivalent weight is small as compared with discrete resistance and diode; therefore, carry TLCS-46A series in a conductive container so as not to add the surge directly into the system, when required.

(6) Latch-up phenomenon

When the voltage lower than GND or the voltage higher than V_{DD} is applied to input terminal and output terminal, a phenomenon called latch-up characteristic of CMOS presents. This phenomenon may cause destruction and degradation of elements; therefore, care should be taken not to apply the voltage exceeding the maximum rating to the input terminal and output terminal.

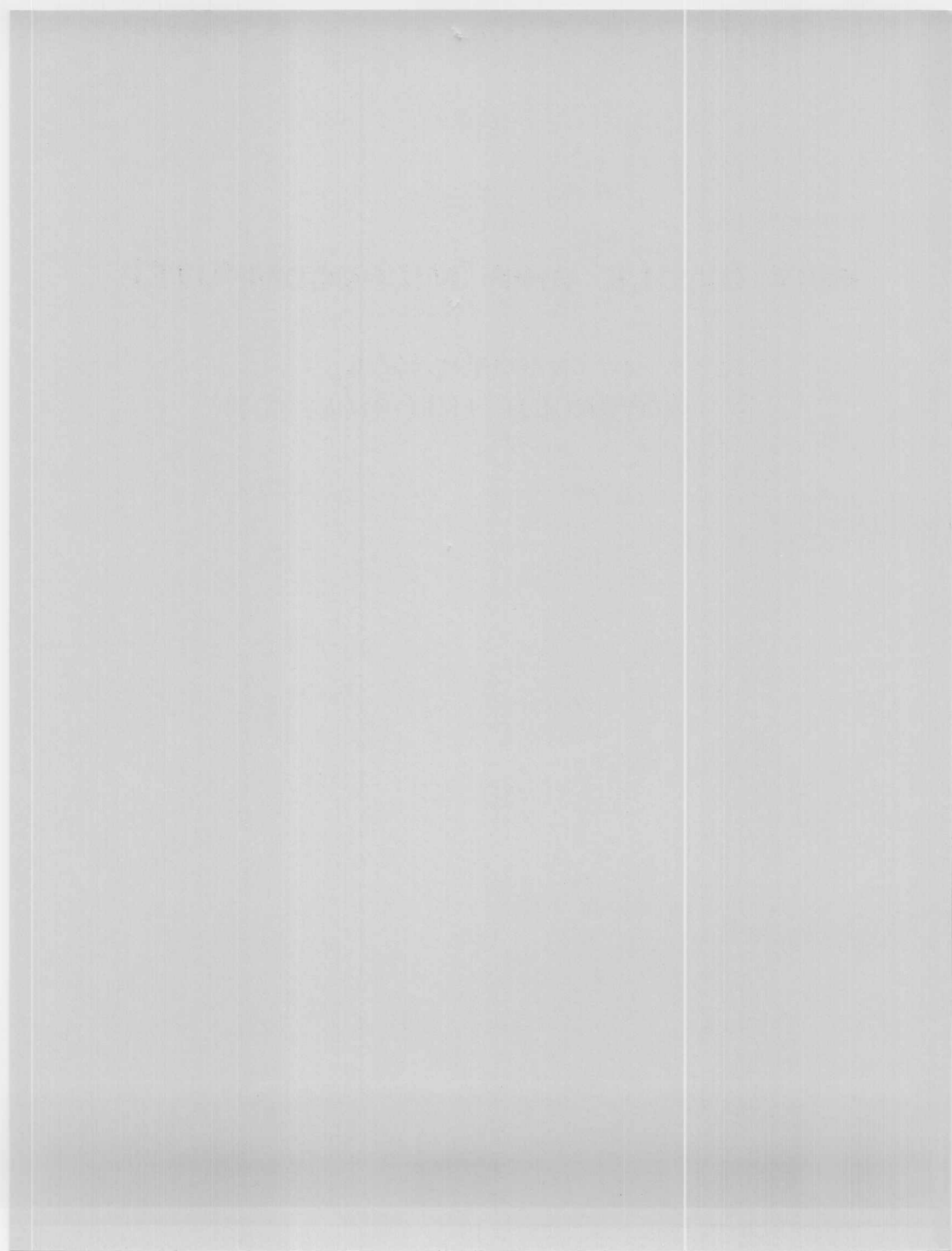
(4) Handling of unused terminal

When an unused input terminal is left open, it may cause malfunction and increase in power dissipation; therefore, insure to connect the terminals to V_{DD} or GND level. (It is the safest method to connect terminals via resistance.)
Further, insure to connect TEST terminal to GND because this terminal is installed for I&T testing.

4BIT SINGLE CHIP MICROCOMPUTER

TLCS-47 (NMOS/CMOS)

ADVANCED INFORMATION



TLCS-47

TLCS-47

(4 BIT SINGLE CHIP CMOS AND NMOS MICROCOMPUTER)

GENERAL DESCRIPTION

TLCS-47 are Toshiba 4 bit single chip CMOS and NMOS microcomputer series designed for general purposes use, which are software compatible each other.

TLCS-47 are high-speed and high performance 4 bit single chip microcomputer.

ARCHITECTURE TABLE OF TLCS-47 (NEW 4 BIT SINGLE CHIP MICROCOMPUTER)

Item	Device Number	Version		Version		Evaluation Chip	
		NMOS	CMOS				
		TMP4720P	TMP4740P	TMP47C20P	TMP47C40P	TMP47C22F	TMP4700C
ROM Size		2 KB	4 KB	2 KB	4 KB	2 KB	4 KB Externally
RAM Size		128 × 4 Bit	256 × 4 Bit	128 × 4 Bit	256 × 4 Bit	192 × 4 Bit	256 × 4 Bit
Instruction Execution Time		2 μs		4 μs			2 μs
Number of Instruction		90					
Subroutine Nesting		15 Levels					
Interrupt		6 (External × 2/Internal × 4)					
Timer / Counter		12 Bit × 2					
Serial I/O Port		YES					
Number of Input Port		1 (4 Bit)			1 (4 Bit)	1 (4 Bit)	1 (4 Bit)
PLA Output Port		2 (8 Bit)			0	2 (8 Bit)	2 (8 Bit)
Number of I/O Port		6 (23 Bit)			6 (23 Bit)	6 (23 Bit)	6 (23 Bit)
High Current Drive Capability		YES (8 Bit)		----			YES (8 Bit)
LCD Driver		----		----		YES	----
RAM Back up		YES		YES		YES	YES
Supply Voltage		5V±10%					
Operating Temperature		-30°C to 70°C					
Package		42 Pin DIP				67 Pin PP	80 Pin QIC

FEATURES OF TLCS-47N (NMOS)

FEATURES

- Single Power Supply : 5V±10%
- 2μs Instruction Cycle (4 MHz clock operation)
- 6 Events Interrupt Capability (external 2, internal 4)
- 15 Level Subroutine Nestings
- Table Look Up Function

Features	TLCS-47N		TLCS-47		TLCS-47N	
	Instruction	RAM	Instruction	RAM	Instruction	RAM
◦ 90 Instructions	90	128	90	128	90	128
◦ 12 bit 2 channel Timer/Counter	12 bit	2 channel	12 bit	2 channel	12 bit	2 channel
◦ Serial Input/Output Port	Serial I/O	Serial I/O	Serial I/O	Serial I/O	Serial I/O	Serial I/O
◦ High Current Capability (8 pins)	High Current	High Current	High Current	High Current	High Current	High Current
◦ RAM Data Back up	RAM Data Back up	RAM Data Back up	RAM Data Back up	RAM Data Back up	RAM Data Back up	RAM Data Back up
◦ Internal Character Converter for 8-Segment Display	Internal Character Converter	Internal Character Converter	Internal Character Converter	Internal Character Converter	Internal Character Converter	Internal Character Converter
◦ 35 Bit I/O Ports	35 Bit I/O Ports	35 Bit I/O Ports	35 Bit I/O Ports	35 Bit I/O Ports	35 Bit I/O Ports	35 Bit I/O Ports
◦ Software Compatible with TLCS-47C	Software Compatible	Software Compatible	Software Compatible	Software Compatible	Software Compatible	Software Compatible

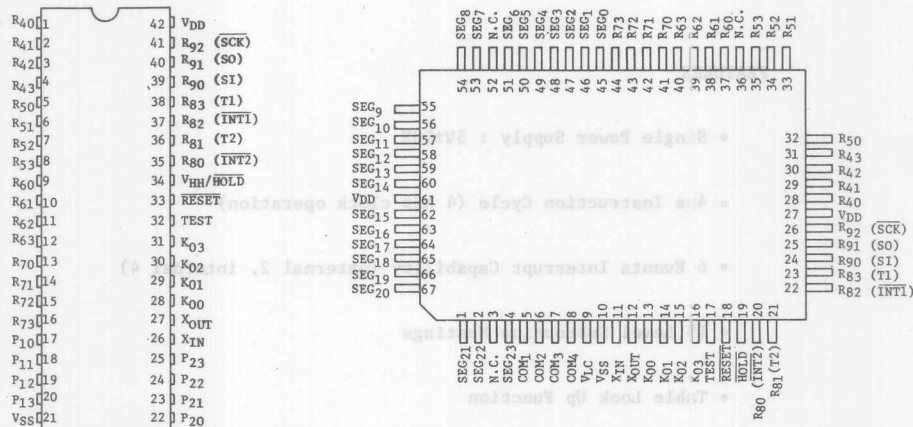
FEATURES

PIN CONNECTION (Top View)

TMP4740P/TMP4720P

(TMP47C22F)

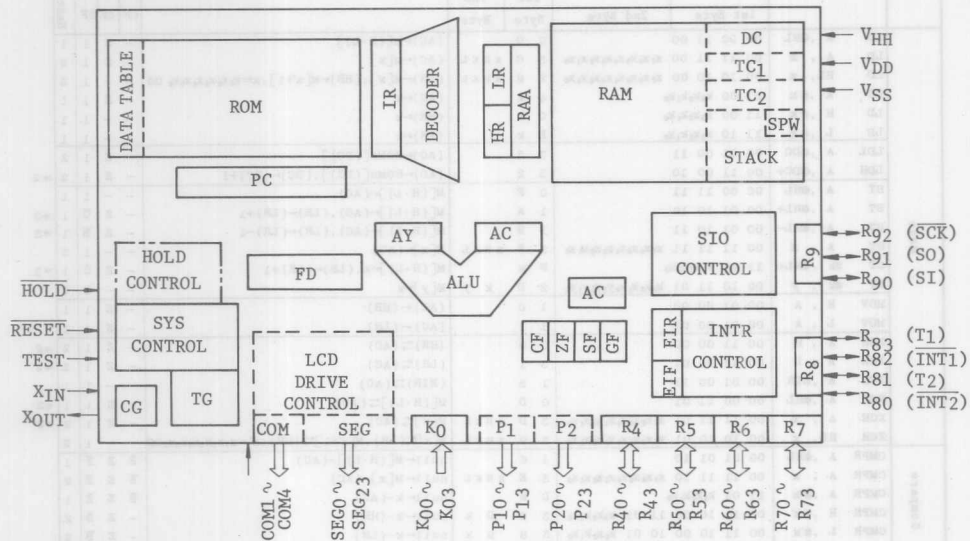
TMP47C40P/TMP47C20P



PIN NAMES AND DESCRIPTION

SYMBOL	No. of PIN	I/O	FUNCTION	NOTE
K03-K00	4	Input	Input Port	
P13-P10	4	Output	Output Port (PLA)	
P23-P20	4	Output	Output Port (PLA)	
R43-R40	4	I/O	I/O Port	
R53-R50	4	I/O	I/O Port	
R63-R60	4	I/O	I/O Port	
R73-R70	4	I/O	I/O Port	
R83 (T1)	1	I/O	I/O Port or Timer/Counter Input	
R82 (INT1)	1	I/O	I/O Port or Interrupt Input	
R81 (T2)	1	I/O	I/O Port or Timer/Counter Input	
R80 (INT2)	1	I/O	I/O Port or Interrupt Input	
R92 (SCK)	1	I/O	I/O Port or Shift Clock for SIO	
R91 (SO)	1	I/O	I/O Port or Serial Output	
R90 (SI)	1	I/O	I/O Port or Serial Input	
SEG23-SEG0	24	Output	LCD Segment Driver Output	TMP47C22F
COM4-COM1	4	Output	LCD Common Driver Output	TMP47C22F
XIN, XOUT	2	Input	Clock Frequency Input	
RESET	1	Input	Reset Input	
HOLD	1	Input	Hold Input	Only CMOS
TEST	1	Input	To be connected to VSS	
VDD	1	Power	+5 Volts	
VSS	1	Power	Ground Reference	
VHH	1	Power	+5 Volts for RAM Back-up	Only NMOS
VLC	1	Power	Power Supply for LCD	TMP47C22F

BLOCK DIAGRAM



(Note) : CMOS version built-in

 : TMP47C22F

Includes direct driver for liquid crystal display, but not include Port 1 (P1) and Port 2 (P2).

	Assembler Mnemonic	Object Code				Function	Flags			Execution Cycle
		Binary		HEX			CF	ZF	SF	
		1st Byte	2nd Byte	1st Byte	2nd Byte					
Move	LD A, @HL	00 00 11 00		0 C		(AC) ← M[(H·L)]	-	Z 1 1	1	
	LD A, x	00 11 11 00	x ₇ x ₆ x ₅ x ₄ x ₃ x ₂ x ₁ x ₀	3 C	x H x L	(AC) ← M[x]	-	Z 1 2	2	
	LD HL, x	00 10 10 00	x ₇ x ₆ x ₅ x ₄ x ₃ x ₂ x ₁ x ₀	2 8	x H x L	(LR) ← M[x], (HR) ← M[x+1], x ← x ₇ x ₆ x ₅ x ₄ x ₃ x ₂ x ₁ x ₀	-	- 1 2	2	
	LD A, #k	01 00	k ₃ k ₂ k ₁ k ₀	4 k		(AC) ← k	-	Z 1 1	1	
	LD H, #k	11 00	k ₃ k ₂ k ₁ k ₀	C k		(HR) ← k	-	- 1 1	1	
	LD L, #k	11 10	k ₃ k ₂ k ₁ k ₀	E k		(LR) ← k	-	- 1 1	1	
	LDL A, @DC	00 11 00 11		3 3		(AC) ← ROML[(DC)]	-	Z 1 2	2	
	LDH A, @DC+	00 11 00 10		3 2		(AC) ← ROMH[(DC)], (DC) ← (DC)+1	-	Z 1 2	*2	
	ST A, @HL	00 00 11 11		0 F		M[(H·L)] ← (AC)	-	- 1 1	1	
	ST A, @HL+	00 01 10 10		1 A		M[(H·L)] ← (AC), (LR) ← (LR)+1	-	Z 0 1	*3	
	ST A, @HL-	00 01 10 11		1 B		M[(H·L)] ← (AC), (LR) ← (LR)-1	-	Z 0 1	*3	
	ST A, x	00 11 11 11	x ₇ x ₆ x ₅ x ₄ x ₃ x ₂ x ₁ x ₀	3 F	x H x L	M[x] ← (AC)	-	- 1 2	2	
	ST #k, @HL+	11 11	k ₃ k ₂ k ₁ k ₀	F k		M[(H·L)] ← k, (LR) ← (LR)+1	-	Z 0 1	*3	
	ST #k, y	00 10 11 01	k ₃ k ₂ k ₁ k ₀ y ₃ y ₂ y ₁ y ₀	2 D	k y	M[y] ← k	-	- 1 2	2	
	MOV H, A	00 01 00 00		1 0		(AC) ← (HR)	-	Z 1 1	1	
	MOV L, A	00 01 00 01		1 1		(AC) ← (LR)	-	Z 1 1	1	
	Compare	XCH A, H	00 11 00 00		3 0		(HR) ↔ (AC)	-	Z 1 2	*2
		XCH A, L	00 11 00 01		3 1		(LR) ↔ (AC)	-	Z 1 2	*2
XCH A, EIR		00 01 00 11		1 3		(EIR) ↔ (AC)	-	- 1 1	1	
XCH A, @HL		00 00 11 01		0 D		M[(H·L)] ↔ (AC)	-	Z 1 1	*2	
XCH A, x		00 11 11 01	x ₇ x ₆ x ₅ x ₄ x ₃ x ₂ x ₁ x ₀	3 D	x H x L	M[x] ↔ (AC)	-	Z 1 2	*2	
XCH HL, x		00 10 10 01	x ₇ x ₆ x ₅ x ₄ x ₃ x ₂ x ₁ x ₀	2 9	x H x L	M[x] ↔ (LR), M[x+1] ↔ (HR), x ← x ₇ x ₆ x ₅ x ₄ x ₃ x ₂ x ₁ x ₀	-	- 1 2	2	
CMPR A, @HL		00 01 01 10		1 6		null ← M[(H·L)] - (AC)	B	Z Z 1	1	
Arithmetic	CMPR A, x	00 11 11 10	x ₇ x ₆ x ₅ x ₄ x ₃ x ₂ x ₁ x ₀	3 E	x H x L	null ← M[x] - (AC)	B	Z Z 2	2	
	CMPR A, #k	11 01	k ₃ k ₂ k ₁ k ₀	D k		null ← k - (AC)	B	Z Z 1	1	
	CMPR H, #k	00 11 10 00 11 01	k ₃ k ₂ k ₁ k ₀	3 8	D k	null ← k - (HR)	-	Z B 2	2	
	CMPR L, #k	00 11 10 00 10 01	k ₃ k ₂ k ₁ k ₀	3 8	9 k	null ← k - (LR)	-	Z B 2	2	
	CMPR y, #k	00 10 11 10	k ₃ k ₂ k ₁ k ₀ y ₃ y ₂ y ₁ y ₀	2 E	k y	null ← k - M[y]	B	Z Z 2	2	
	INC A	00 00 10 00		0 8		(AC) ← (AC)+1	-	Z 0 1	1	
	INC L	00 01 10 00		1 8		(LR) ← (LR)+1	-	Z 0 1	1	
Logical	INC @HL	00 00 10 10		0 A		M[(H·L)] ← M[(H·L)]+1	-	Z 0 1	1	
	DEC A	00 00 10 01		0 9		(AC) ← (AC)-1	-	Z B 1	1	
	DEC L	00 01 10 01		1 9		(LR) ← (LR)-1	-	Z B 1	1	
	DEC @HL	00 00 10 11		0 B		M[(H·L)] ← M[(H·L)]-1	-	Z B 1	1	
	ADDC A, @HL	00 01 01 01		1 5		(AC) ← (AC)+M[(H·L)]+(CF)	0	Z 0 1	1	
	ADP A, @HL	00 01 01 11		1 7		(AC) ← (AC)+M[(H·L)]	-	Z 0 1	1	
	ADD A, #k	00 11 10 00 00 00	k ₃ k ₂ k ₁ k ₀	3 8	0 k	(AC) ← (AC)+k	-	Z 0 2	2	
	ADD H, #k	00 11 10 00 11 00	k ₃ k ₂ k ₁ k ₀	3 8	C k	(HR) ← (HR)+k	-	Z 0 2	2	
	ADD L, #k	00 11 10 00 10 00	k ₃ k ₂ k ₁ k ₀	3 8	8 k	(LR) ← (LR)+k	-	Z 0 2	2	
	ADD @HL, #k	00 11 10 00 01 00	k ₃ k ₂ k ₁ k ₀	3 8	4 k	M[(H·L)] ← M[(H·L)]+k	-	Z 0 2	2	
	ADD y, #k	00 10 11 11	k ₃ k ₂ k ₁ k ₀ y ₃ y ₂ y ₁ y ₀	2 F	k y	M[y] ← M[y]+k	-	Z 0 2	2	
	SUBRC A, @HL	00 01 01 00		1 4		(AC) ← M[(H·L)] - (AC) - (CF)	B	Z B 1	1	
	SUBR A, #k	00 11 10 00 00 01	k ₃ k ₂ k ₁ k ₀	3 8	1 k	(AC) ← k - (AC)	-	Z B 2	2	
	SUBR @HL, #k	00 11 10 00 01 01	k ₃ k ₂ k ₁ k ₀	3 8	5 k	M[(H·L)] ← k - M[(H·L)]	-	Z B 2	2	
Logical	ROLC A	00 00 01 01		0 5		(CF) ← (AC) (rotate left by 1 bit)	0	Z 0 1	*4	
	RORC A	00 00 01 11		0 7		(AC) ← (CF) (rotate right by 1 bit)	0	Z 0 1	*4	
	AND A, @HL	00 01 11 10		1 E		(AC) ← (AC) ∧ M[(H·L)]	-	Z Z 1	1	
	AND A, #k	00 11 10 00 00 11	k ₃ k ₂ k ₁ k ₀	3 8	3 k	(AC) ← (AC) ∧ k	-	Z Z 2	2	
	AND @HL, #k	00 11 10 00 01 11	k ₃ k ₂ k ₁ k ₀	3 8	7 k	M[(H·L)] ← M[(H·L)] ∧ k	-	Z Z 2	2	
	OR A, @HL	00 01 11 01		1 D		(AC) ← (AC) ∨ M[(H·L)]	-	Z Z 1	1	
	OR A, #k	00 11 10 00 00 10	k ₃ k ₂ k ₁ k ₀	3 8	2 k	(AC) ← (AC) ∨ k	-	Z Z 2	2	
	OR @HL, #k	00 11 10 00 01 10	k ₃ k ₂ k ₁ k ₀	3 8	6 k	M[(H·L)] ← M[(H·L)] ∨ k	-	Z Z 2	2	
	XOR A, @HL	00 01 11 11		1 F		(AC) ← (AC) ∨ M[(H·L)]	-	Z Z 1	1	

	Assembler	Object Code				Function	Flags			Execution Cycle
		Binary		HEX			CF	ZF	SF	
		Mnemonic	1st Byte	2nd Byte	1st Byte					
bit manipulation	TEST CF	00 00 01 10	0 8	(SF) \leftarrow (CF), (CF) \leftarrow 0	0	-	*	1		
	TEST A, b	01 01 11 b ₁ b ₀	5 C+b	(SF) \leftarrow (AC)	-	-	*	1		
	TEST @HL, b	01 01 10 b ₁ b ₀	5 8+b	(SF) \leftarrow M[(H·L)]	-	-	*	1		
	TEST y, b	00 11 10 01 10 b ₁ b ₀ y ₃ y ₂ y ₁ y ₀	3 9 8+b y	(SF) \leftarrow M[y]	-	-	*	2		
	TEST #p, b	00 11 10 11 10 b ₁ b ₀ p ₃ p ₂ p ₁ p ₀	3 B 8+b p	(SF) \leftarrow P[p]	-	-	*	2		
	TEST @L	00 11 01 11	3 7	(SF) \leftarrow P[(LR)<3:2>+4]<(LR)<1:0>>	-	-	*	2		
	TESTP CF	00 00 01 00	0 4	(SF) \leftarrow (CF), (CF) \leftarrow 1	1	-	*	1		
	TESTP ZF	00 00 11 10	0 E	(SF) \leftarrow (ZF)	-	-	*	1		
	TESTP GF	00 00 00 01	0 1	(SF) \leftarrow (GF)	-	-	*	1		
	TESTP y, b	00 11 10 01 11 b ₁ b ₀ y ₃ y ₂ y ₁ y ₀	3 9 C+b y	(SF) \leftarrow M[y]	-	-	*	2		
	TESTP #p, b	00 11 10 11 11 b ₁ b ₀ p ₃ p ₂ p ₁ p ₀	3 B C+b p	(SF) \leftarrow P[p]	-	-	*	2		
	SET GF	00 00 00 11	0 3	(GF) \leftarrow 1	-	-	1	1		
	SET @HL, b	01 01 00 b ₁ b ₀	5 b	M[(H·L)] \leftarrow 1	-	-	1	1		
	SET y, b	00 11 10 01 00 b ₁ b ₀ y ₃ y ₂ y ₁ y ₀	3 9 b y	M[y] \leftarrow 1	-	-	1	2		
	SET #p, b	00 11 10 00 00 b ₁ b ₀ p ₃ p ₂ p ₁ p ₀	3 B b p	P[p] \leftarrow 1	-	-	1	2		
	SET @L	00 11 01 00	3 4	P[(LR)<3:2>+4]<(LR)<1:0>> \leftarrow 1	-	-	1	2		
Input/output	CLR GF	00 00 00 10	0 2	(GF) \leftarrow 0	-	-	1	1		
	CLR @HL, b	01 01 01 b ₁ b ₀	5 4+b	M[(H·L)] \leftarrow 0	-	-	1	1		
	CLR y, b	00 11 10 01 01 b ₁ b ₀ y ₃ y ₂ y ₁ y ₀	3 9 4+b y	M[y] \leftarrow 0	-	-	1	2		
	CLR #p, b	00 11 10 11 01 b ₁ b ₀ p ₃ p ₂ p ₁ p ₀	3 B 4+b p	P[p] \leftarrow 0	-	-	1	2		
	CLR @L	00 11 01 01	3 5	P[(LR)<3:2>+4]<(LR)<1:0>> \leftarrow 0	-	-	1	2		
	CLR IL, r	00 11 01 10 11 r ₃ r ₂ r ₁ r ₀	3 6 C+rHrL	(INTL)<5:0> \leftarrow (INTL)<5:0>Ar<5:0>	-	-	1	2		
	EIOCLR IL, r	00 11 01 10 01 r ₃ r ₂ r ₁ r ₀	3 6 4+rHrL	(EIF) \leftarrow 1, (INTL)<5:0> \leftarrow (INTL)<5:0>Ar<5:0>	-	-	1	2		
	DIOLCLR IL, r	00 11 01 10 10 r ₃ r ₂ r ₁ r ₀	3 6 8+rHrL	(EIF) \leftarrow 0, (INTL)<5:0> \leftarrow (INTL)<5:0>Ar<5:0>	-	-	1	2		
	IN #p, A	00 11 10 10 00 10 p ₃ p ₂ p ₁ p ₀	3 A 2 p	(AC) \leftarrow P[p]	-	Z	2	2		
	IN #p, @HL	00 11 10 10 01 10 p ₃ p ₂ p ₁ p ₀	3 A 6 p	M[(H·L)] \leftarrow P[p]	-	Z	2	2		
	OUT A, #p	00 11 10 10 10 p ₃ p ₂ p ₁ p ₀	3 A 8+2#p	P[p] \leftarrow (AC), p = p ₃ p ₂ p ₁ p ₀	-	-	1	2		
	OUT @HL, #p	00 11 10 10 11 p ₃ p ₂ p ₁ p ₀	3 A C+2#p	P[p] \leftarrow M[(H·L)], p = p ₃ p ₂ p ₁ p ₀	-	-	1	2		
	OUT #k, #p	00 10 11 00 k ₃ k ₂ k ₁ k ₀ p ₃ p ₂ p ₁ p ₀	2 C k p	P[p] \leftarrow k	-	-	1	2		
	OUTB @HL	00 01 00 10	1 2	P[2]·P[1] \leftarrow ROM[F·(E·(CF))·M[(H·L)]]	-	-	1	2		
	branch-subroutine	BS a	01 10 a ₁ a ₀ a ₃ a ₂ a ₁ a ₀ a ₃ a ₂ a ₁ a ₀	6 aH aM aL	If SF=1 then (PC) \leftarrow a else null	-	-	1	2	
		BSS a	10 d ₃ d ₂ d ₁ d ₀	8+dH dL	If SF=1 then (PC) \leftarrow a else null, a=(PC)<11:6> d	-	-	1	2	
CALL a		00 10 0a ₃ a ₂ a ₁ a ₀ a ₃ a ₂ a ₁ a ₀	2 aH aM aL	STACK[(SPW)] \leftarrow (PC), (SPW) \leftarrow (SPW)-1 (PC) \leftarrow a, a ₀ \geq 2047	-	-	-	2		
CALLS a		01 11 n ₃ n ₂ n ₁ n ₀	7 n	STACK[(SPW)] \leftarrow (PC), (SPW) \leftarrow (SPW)-1 (PC) \leftarrow a, a=8n+6(n \neq 0), 134(n=0)	-	-	-	2 *5		
RET		00 10 10 10	2 A	(SPW) \leftarrow (SPW)+1, (PC) \leftarrow STACK[(SPW)]	-	-	-	2 *5		
RETI		00 10 10 11	2 B	(SPW) \leftarrow (SPW)+1, (FLAG·PC) \leftarrow STACK[(SPW)], (EIF) \leftarrow 1	-	-	*	2 *5		
	NOP	00 00 00 00	0 0	no operation	-	-	-	1		

Note 1 : Setting Condition of Flag

"C" indicates the carry output from the highest significant position in the addition operation, and "B" indicates the borrow from the highest significant position in the subtraction operation. "Z" indicates the zero detection signal to which "1" is applied only when all of the 4-bit data transferred to the accumulator or the ALU output, which is the result obtained by an arithmetic operation or data processing, are cleared zero. The flag is set to "C", "Z", "B", "2", "1", or "0" according to the data processing result. "*" mark denotes that the value specified by function is set, and "-" mark other than it denotes that the flag makes no change.

Note 2 : This is the data set in the accumulator. In this case, the zero flag is set in the accumulator.

Note 3 : The flags (ZF and SF) are set in the accumulator depending on the increment or decrement result of the L register.

Note 4 : The data shifted out of the accumulator becomes the carry.

Note 5 : The contents of program counter indicate the next address of the instruction in execution.

8BIT SINGLE CHIP MICROCOMPUTER

TLCS-84 (NMOS/CMOS)

1. The first part of the paper is devoted to a review of the literature on the topic.

2. The second part of the paper is devoted to a review of the literature on the topic.



INTEGRATED CIRCUIT

TECHNICAL DATA

TOSHIBA MOS DIGITAL INTEGRATED CIRCUIT

TMP8048P/8048PI

TMP8035P/8035PI

8-BIT SINGLE-CHIP MICROCOMPUTER

N-CHANNEL SILICON GATE MOS

GENERAL DESCRIPTION

The TMP8048P, from here on referred to as the TMP8048, is a single chip microcomputer fabricated in N-channel Silicon Gate MOS technology which provides internal 8-bit parallel architecture.

The following basic architectural functions of a computer have been included in a single chip; an 8-bit CPU, 64×8 RAM data memory, $1K \times 8$ ROM program memory, 27 I/O lines and an 8-bit timer/event counter.

The TMP8048 is particularly efficient as a controller. It has extensive bit handling capability as well as facilities for both binary and BCD arithmetic.

The TMP8035P is the equivalent of a TMP8048 without ROM program memory on chip. By using this device with external EPROM or RAM, software debugging becomes easy.

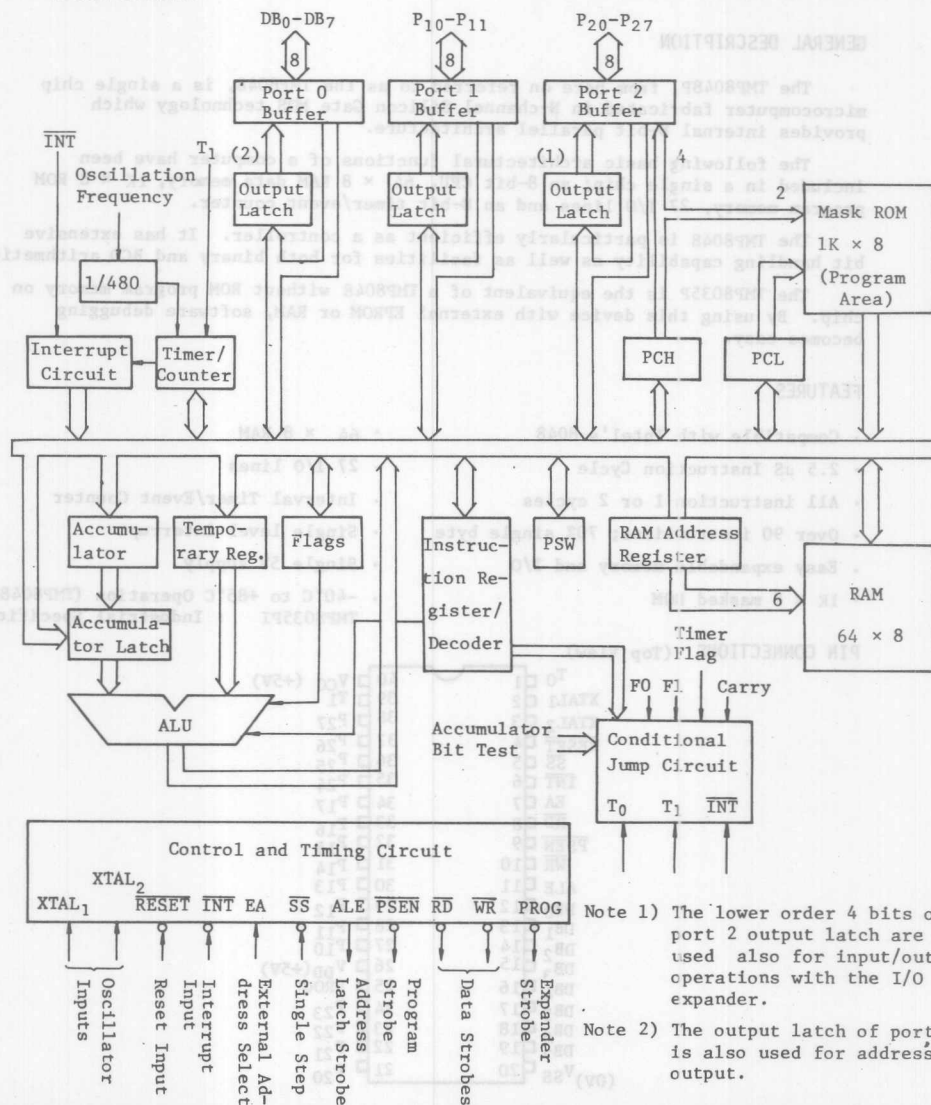
FEATURES

- Compatible with Intel's 8048
- $2.5 \mu\text{s}$ Instruction Cycle
- All instruction 1 or 2 cycles
- Over 90 instructions; 70% single byte
- Easy expandable memory and I/O
- $1K \times 8$ masked ROM
- 64×8 RAM
- 27 I/O lines
- Interval Timer/Event Counter
- Single level interrupt
- Single 5V supply
- -40°C to $+85^\circ\text{C}$ Operation (TMP8048PI/
TMP8035PI : Industrial Specification)

PIN CONNECTIONS (Top View)

To	1	40	V _{CC} (+5V)
XTAL1	2	39	T1
XTAL2	3	38	P27
RESET	4	37	P26
SS	5	36	P25
INT	6	35	P24
EA	7	34	P17
RD	8	33	P16
PSEN	9	32	P15
WR	10	31	P14
ALE	11	30	P13
DB0	12	29	P12
DB1	13	28	P11
DB2	14	27	P10
DB3	15	26	V _{DD} (+5V)
DB4	16	25	PROG
DB5	17	24	P23
DB6	18	23	P22
DB7	19	22	P21
(0V) V _{SS}	20	21	P20

BLOCK DIAGRAM



Note 1) The lower order 4 bits of port 2 output latch are used also for input/output operations with the I/O expander.

Note 2) The output latch of port 0 is also used for address output.



INTEGRATED CIRCUIT

TECHNICAL DATA

TMP8048P/8048PI

TMP8035P/8035PI

PIN NAMES AND PIN DESCRIPTION

V_{SS} (Power Supply)

Circuit GND potential.

V_{DD} (Power Supply)

+5V during operation Low power standby pin for TMP8048 RAM

V_{CC} (Main Power Supply)

+5V during operation

PROG (Output)

Output strobe for the TMP8243P I/O expander

P₁₀-P₁₇ (Input/Output) Port 1

8-bit quasi-bidirectional port (Internal Pullup $\approx 50K\Omega$).

P₂₀-P₂₇ (Input/Output) Port 2

8-bit quasi-bidirectional port (Internal Pullup $\approx 50K\Omega$).

P₂₀-P₂₃ Contain the four high order program counter bits during an external program memory fetch and serve as a 4-bit I/O expander bus for the TMP8243P.

DB₀-DB₇ (Input/Output, 3 State)

8-bit bidirectional port which can be written or read synchronously using the RD, WR strobes. The port can also be statically latched. Contains the 8 low order program counter bits during an external program memory fetch, and receives the addressed instruction under the control of PSEN. Also contains the address and data during an external RAM data store instruction, under control of ALE, RD, and WR.

T₀ (Input/Output)

Input pin testable using the conditional transfer instructions JTO and JNTO. T₀ can be designated as a clock output using ENT0 CLK instruction.

T₁ (Input)

Input pin testable using the JTI and JNTI instruction. Can be designated the event counter input using the timer/STRT CNT instruction.

INT (Input)

External interrupt input. Initiates an interrupt if interrupt is enabled. Interrupt is disabled after a reset. Also testable with conditional jump instruction. (Active Low)

RD (Output)

Output strobe activated during a Bus read. Can be used to enable data onto the Bus from an external device. Used as a Read Strobe to External Data Memory (Active Low).

WR (Output)

Output strobe during a Bus write (Active Low) Used as a Write Strobe to External Data Memory.

RESET (Input)

Active Low signal which is used to initialize the Processor. Also used during Power down.

ALE (Output)

Address Latch Enable. This signal occurs once during each cycle and is useful as a clock output. The negative edge of ALE strobes address into external data and program memory.

PSEN (Output)

Program Store Enable. This output occurs only during a fetch to external program memory (Active Low).

SS (Input)

Single step input can be used in conjunction with ALE to "single step" processor through each instruction when SS is low the CPU is placed into a wait state after it has completed the instruction being executed.

EA (Input)

External Access input which forces all program memory fetches to reference external memory. Useful for emulation and debug and essential for testing and program verification. (Active High).

XTAL 1 (Input)

One side of crystal input for internal oscillator. Also input for external source.

XTAL 2 (Input)

Other side of crystal input.

FUNCTIONAL DESCRIPTION

1. System Configuration

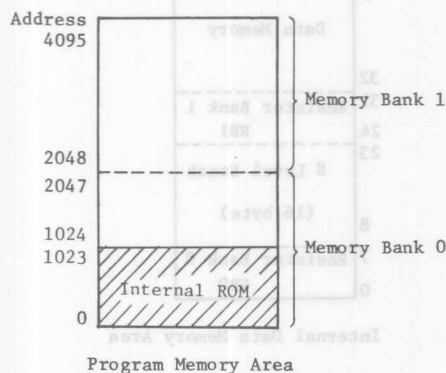
The following system functions of the TMP8048 are described in detail.

- | | |
|-------------------------------|-------------------------------|
| (1) Program Memory | (6) Stack (Stack Pointer) |
| (2) Data Memory | (7) Flag 0, Flag 1 |
| (3) I/O Port | (8) Program Status Word (PSW) |
| (4) Timer/Counter | (9) Reset |
| (5) Interrupt Control Circuit | (10) Oscillator Circuit |

(1) Program Memory

The maximum memory that can be directly addressed by the TMP8048 is 4096 bytes. The first 1024 bytes from location 0 through 1023 can be internal resident mask ROM. The rest of the 3072 bytes of addressable memory are external to the chip. The TMP8035 has no internal resident memory; all memory must be external.

- There are three locations in Program Memory of special importance.

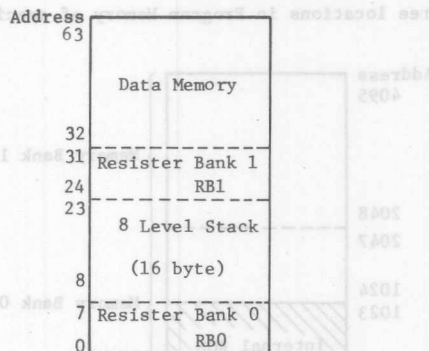


- Location 0
Activating the Reset line of the processor causes the first instruction to be fetched from Location 0.
- Location 3
Activating the interrupt line of the processor (if interrupt enabled) causes a jump to subroutine defined by address held in Location 3.
- Location 7
A timer/counter interrupt resulting from a timer/counter overflow (if enabled) causes a jump to a subroutine defined by address held in Location 7.
- Program addresses 0-2047 and 2048-4095 are called memory banks 0 and 1 respectively. Switching of memory banks is achieved by changing the most significant bit of the program counter (PC) during execution of an unconditional jump instruction or call instruction executed after using SEL MB0 or SEL MB1.

Reset operation automatically selects Bank 0.

(2) Data Memory

- Resident Data Memory (volatile RAM) is organized as 64 words by 8-bits wide.
- The first 8 locations (0 - 7) of the memory array are designated as working registers and are directly addressable by several instructions. By executing a Register Bank switch instruction (SEL RB1) locations 24 - 31 are designated as the working registers in place of 0 - 7.



Internal Data Memory Area

- RAM locations 8 - 23 serve a dual role in that they contain the program counter stack which is a stack 2 bytes wide by 8 levels deep. These locations store returning addresses from subroutines. If the level of subroutine nesting is less than the permitted 8, you free up 2 bytes of RAM for general use for every level of nesting not utilized.
- ALL 64 locations are indirectly addressable through either of two RAM Pointer Registers which reside at R0 and R1 of the Register array.
- The TMP8048 architecture allows extension of the Data Memory to 256 words.

(3) Input/Output Ports

- The TMP8048 has 27 I/O lines which can be used for either input or output. These I/O lines are grouped into 3 ports each having 8 bidirectional lines and 3 "test" inputs which can alter program sequences when tested by conditional jump instructions.
- Ports 1 and 2 are each 8-bits wide and have identical characteristics. Data written to these ports is statically latched and remains unchanged until rewritten. As input ports these lines are non-latching, i.e., inputs must be present until read by an input instruction.
- All lines of Ports 1 and 2 are called quasi-bidirectional because of a special output circuit structure (illustrated in Figure 1). Each line is continuously pulled to a +5V level through a high impedance resistive device (50K Ω) which is sufficient to provide the source current for a TTL high level yet can be pulled low by a standard TTL gate thus allowing the same pin to be used for both input and output. In order to speed up the "0" to "1" transition a low impedance device (5K Ω) is switched in momentarily whenever a "1" is written to line. When a "0" is written to line a low impedance device overcomes the pullup and provides TTL current sinking capability.

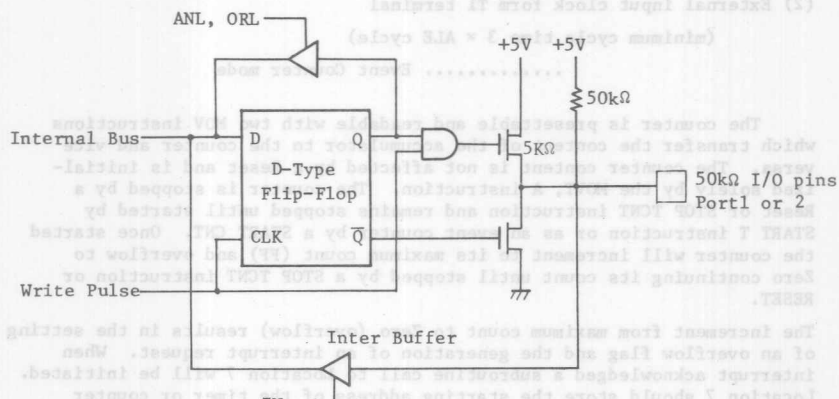


Fig.1 Input/Output Circuit of Port 1, Port 2

- Reset initializes all lines to a high impedance "1" state.
- When external data memory area is not addressed during execution of an internal program, Port 0 (DB0 - DB7) becomes a true bidirectional port (bus) with associated input and output strobes. If bidirectional feature not needed Bus can serve as either a statically latched output port or a non-latched input port. However, I/O lines of this port cannot be intermixed.
- As a static port data is written and latched using the OUTL instruction and inputted using the INS instruction these two commands generate pulses on the corresponding RD and WR strobe lines.
- As a bidirectional port the MOVX instructions are used to read and write the port which generate the WR RD strobes.
- When not being written or read, the Bus lines are in a high impedance state.

(4) Timer/Event Counter

- The 8-bit binary up counter can use either of the following frequency inputs

(1) Internal clock (1/480 of OSC frequency)

..... Timer mode

Fig.2 Concept of Timer Circuit

(2) External input clock form T1 terminal
(minimum cycle time $3 \times \text{ALE cycle}$)

..... Event Counter mode

The counter is presetable and readable with two MOV instructions which transfer the content of the accumulator to the counter and vice versa. The counter content is not affected by a Reset and is initialized solely by the MOV T, A instruction. The counter is stopped by a Reset or STOP TCNT instruction and remains stopped until started by START T instruction or as an event counter by a START CNT. Once started the counter will increment to its maximum count (FF) and overflow to Zero continuing its count until stopped by a STOP TCNT instruction or RESET.

The increment from maximum count to Zero (overflow) results in the setting of an overflow flag and the generation of an interrupt request. When interrupt acknowledged a subroutine call to Location 7 will be initiated. Location 7 should store the starting address of the timer or counter service routine. The state of the overflow flag is testable with the conditional JUMP (JTF). The flag is reset by executing a JTF or by RESET. Figure 2 illustrates the concept of the timer circuit.

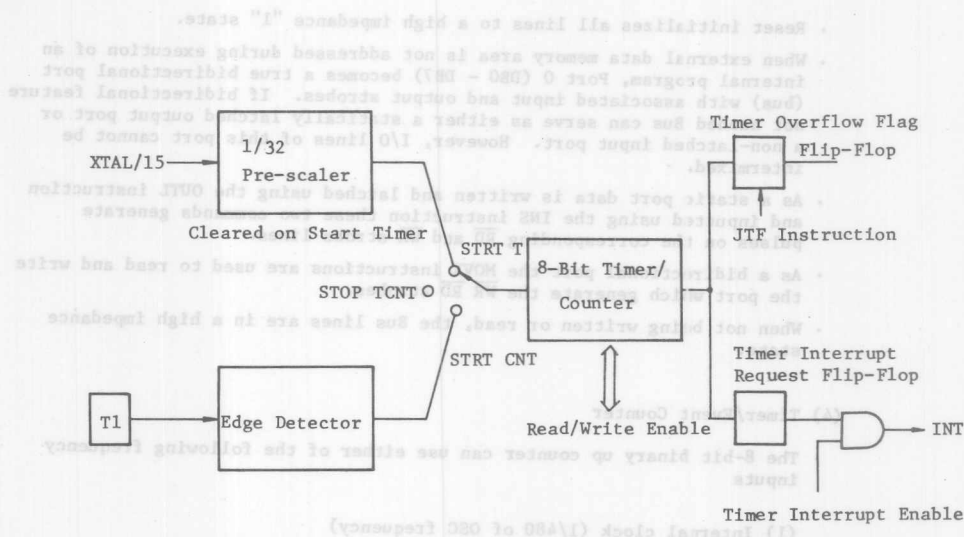


Fig.2 Concept of Timer Circuit

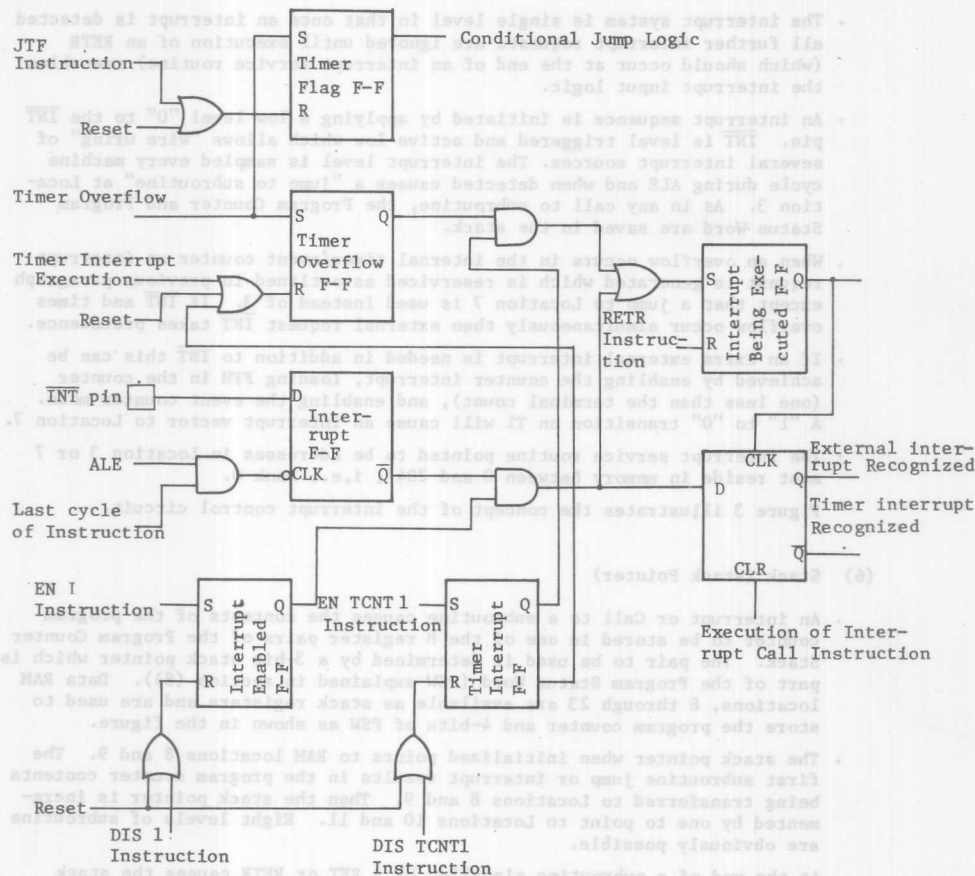


Fig. 3 Concept of Interrupt Control Circuit

(5) Interrupt Control Circuit

There are two distinct types of Interrupts in the TMP8048.

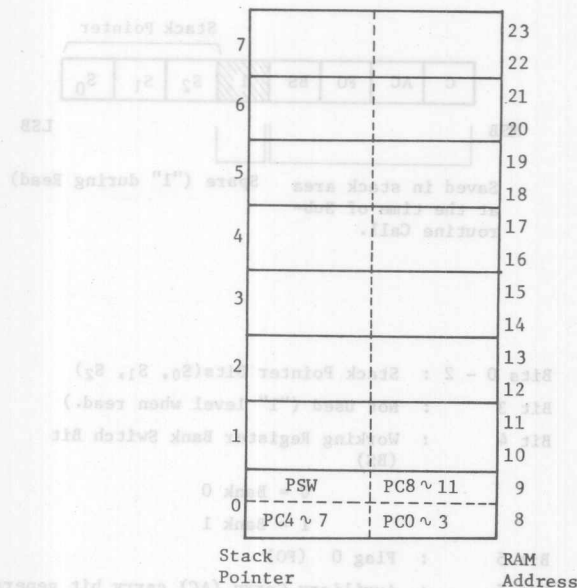
- (1) External Interrupt from the $\overline{\text{INT}}$ terminal
- (2) Timer Interrupt caused by timer overflow

- The interrupt system is single level in that once an interrupt is detected all further interrupt requests are ignored until execution of an RETR (which should occur at the end of an interrupt service routine) reenables the interrupt input logic.
- An interrupt sequence is initiated by applying a low level "0" to the $\overline{\text{INT}}$ pin. $\overline{\text{INT}}$ is level triggered and active low which allows "Wire Oring" of several interrupt sources. The interrupt level is sampled every machine cycle during ALE and when detected causes a "jump to subroutine" at Location 3. As in any call to subroutine, the Program Counter and Program Status Word are saved in the stack.
- When an overflow occurs in the internal timer/event counter an interrupt request is generated which is rescheduled as outlined in previous paragraph except that a jump to Location 7 is used instead of 3. If $\overline{\text{INT}}$ and times overflow occur simultaneously then external request $\overline{\text{INT}}$ takes precedence.
- If an extra external interrupt is needed in addition to $\overline{\text{INT}}$ this can be achieved by enabling the counter interrupt, loading FFH in the counter (one less than the terminal count), and enabling the event counter mode. A "1" to "0" transition on T1 will cause an interrupt vector to Location 7.
- The interrupt service routine pointed to be addresses in Location 3 or 7 must reside in memory between 0 and 2047, i.e., Bank 0.

Figure 3 illustrates the concept of the interrupt control circuit.

(6) Stack (stack Pointer)

- An interrupt or Call to a subroutine causes the contents of the program counter to be stored in one of the 8 register pairs of the Program Counter Stack. The pair to be used is determined by a 3-bit stack pointer which is part of the Program Status Word (PSW explained in section (8)). Data RAM locations, 8 through 23 are available as stack registers and are used to store the program counter and 4-bits of PSW as shown in the figure.
- The stack pointer when initialized points to RAM locations 8 and 9. The first subroutine jump or interrupt results in the program counter contents being transferred to Locations 8 and 9. Then the stack pointer is incremented by one to point to Locations 10 and 11. Eight levels of subroutine are obviously possible.
- At the end of a subroutine signalled by a RET or RETR causes the stack pointer to be decremented by one and the contents of the resulting pair to be transferred to the Program Counter.

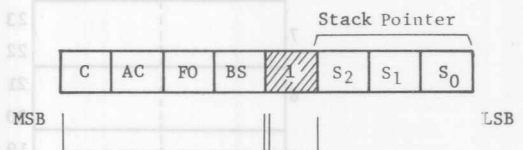


(7) Flag 0, Flag 1, (F0, F1)

- The TMP8048 has two flags F0 and F1 which are used for conditional jump. These flags can be set, reset and tested with the conditional jump instruction JFO.
- F0 is a part of the program status word (PSW) and is saved in the stack area when a subroutine is called.

(8) Program Status Word (PSW)

- An 8-bit status word which can be loaded to and from the accumulator exists called the Program Status Word (PSW). The PSW is read by a MOV A, PSW and written to by a MOV PSW, A. The information available in the PSW is shown in the diagram below.



Saved in stack area at the time of Sub-routine Call. Spare ("1" during Read)

Bits 0 - 2 : Stack Pointer Bits(S_0 , S_1 , S_2)

Bit 3 : Not used ("1" level when read.)

Bit 4 : Working Register Bank Switch Bit (BS)

0 = Bank 0

1 = Bank 1

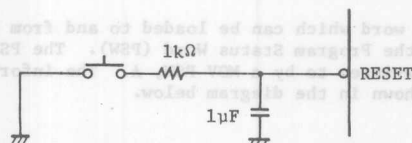
Bit 5 : Flag 0 (FO)

Bit 6 : Auxiliary Carry (AC) carry bit generated by an ADD instruction and used by the decimal adjust instruction DA, A (AC)

Bit 7 : Carry (C) flag which indicates that the previous operation has resulted in the accumulator. (C)

(9) Reset

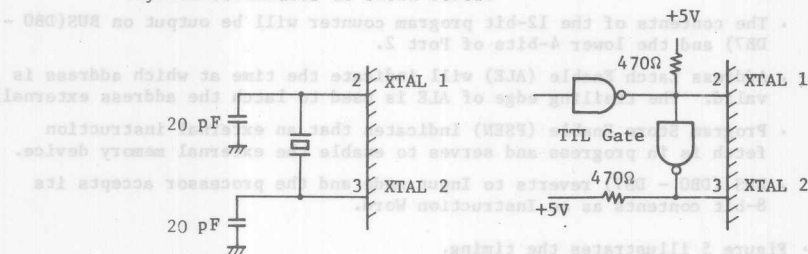
The reset input provides a means for initialization of the processor. This Schmitt trigger input has an internal pullup resistor which in combination with an external $1\mu\text{F}$ capacitor provides an internal reset pulse sufficient length to guarantee that all internal logic is initialized.



- If the pulse is generated externally the reset pin must be held at ground ($\leq 0.5V$) for at least 50mS after the power supply is within tolerance.
- Reset performs the following functions within the chip:
 - (i) Sets PC to Zero.
 - (ii) Sets Stack Pointer to Zero.
 - (iii) Selects Register Bank 0.
 - (iv) Selects Memory Bank 0.
 - (v) Sets BUS (DB0 - DB7) to high impedance state. (Except when EA = 5V)
 - (vi) Sets Ports 1 and 2 to input mode.
 - (vii) Disables interrupts (timer and external).
 - (viii) Stops Timer.
 - (ix) Clears Timer Flag.
 - (x) Clears F0 and F1.
 - (xi) Disables clock output from T0.

(10) Oscillator Circuit

- TMP8048 can be operated by the external clock input in addition to crystal oscillator as shown below.



2. Basic Operation and Timing

The following basic operations and timing are explained

- (1) Instruction Cycle
- (2) External Memory Access Timing
- (3) Interface with I/O Expander TMP8243P
- (4) Internal Program Verify (Read) Timing
- (5) Single Step Operation Timing
- (6) Low Power Stand-by Mode

(1) Instruction Cycle

- The instructions of TMP8048 are executed in one or two machine cycles, and one machine cycle consists of five states.
- Fig.4 illustrates its relationship with the clock input to CPU.
- $\phi 2$ clock shown in Fig.4 is derived to outside by ENTO CLK instruction.
- ALE can be also used as the clock to indicate the machine cycle as well as giving the external address latch timing.

(2) External Memory Access Timing

(i) Program Memory Access

- TMP8048 programs are executed in the following three modes.

- (1) Execution of internal program only.
- (2) Execution of both external and internal programs.
- (3) Execution of external program only.

The external program memory is accessed (instructions are fetched) automatically when the internal ROM address is exceeded in mode (2) and from initial start address 0 in mode (3).

- In the external program memory access operation, the following will occur
 - The contents of the 12-bit program counter will be output on BUS(DB0 - DB7) and the lower 4-bits of Port 2.
 - Address Latch Enable (ALE) will indicate the time at which address is valid. The trailing edge of ALE is used to latch the address externally.
 - Program Store Enable (PSEN) indicates that an external instruction fetch is in progress and serves to enable the external memory device.
 - BUS (DB0 - DB7) reverts to Input mode and the processor accepts its 8-bit contents as an Instruction Word.
- Figure 5 illustrates the timing.

(ii) Access of External Data Memory

- In the extended data memory access operation during READ/WRITE cycle the following occurs
 - The contents of R0 R1 is output onto BUS (DB0 - DB7).
 - ALE indicates address is valid. The trailing edge of ALE is used to latch the address externally.
 - A read \overline{RD} or write \overline{WR} pulse on the corresponding output pins indicates the type of data memory access in progress. Output data valid at trailing edge of \overline{WR} and input data must be valid at trailing edge of \overline{RD} .
 - Data (8-bits) is transferred over BUS.

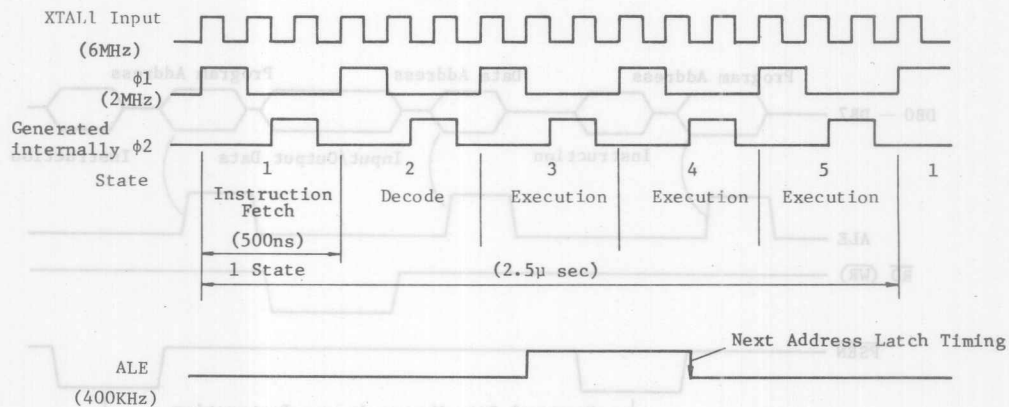


Fig.4 Instruction Cycle Timing

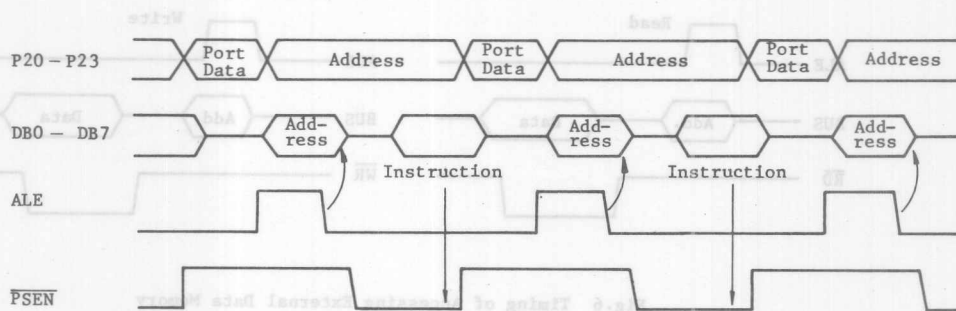
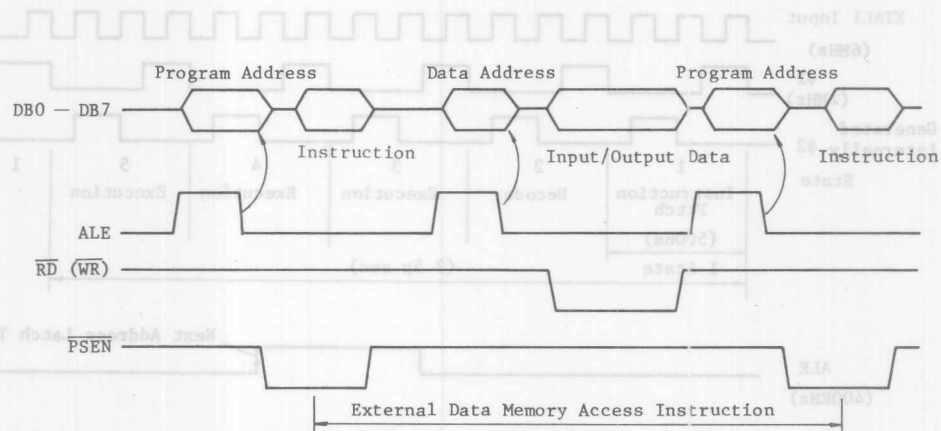


Fig.5 Timing of External Program Memory Access



Suggest we have two diagrams

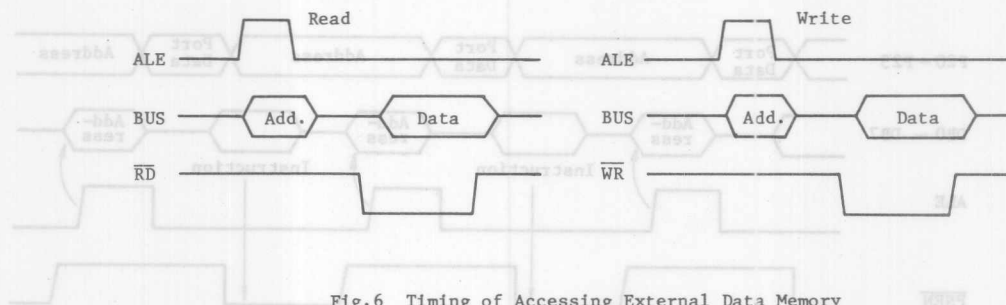


Fig.6 Timing of Accessing External Data Memory

- Figure 6 illustrates the timing of accessing the external data memory during execution of external program.

(3) Interface with I/O Expander (TMP8243P)

- The TMP8048 I/O can be easily expanded using the TMP8243 I/O Expander. This device uses only the lower half 4-bits of Port 2 for communication with the TMP8048. The TMP8243 contains four 4-bit I/O ports which serve as extensions of one chip I/O and are addressed as Ports (4-7). All communication takes place over the lower half of Port 2 (P20 - P23) with timing provided by an output pulse on the PROG pin. Each transfer consists of two 4-bit nibbles the first containing the "OP Code" and port address and the second containing the actual 4-bits of data.

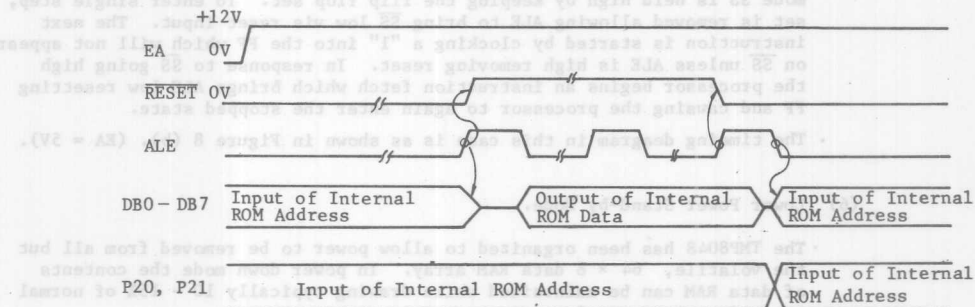


Fig.7 Timing of Reading Internal Program Memory

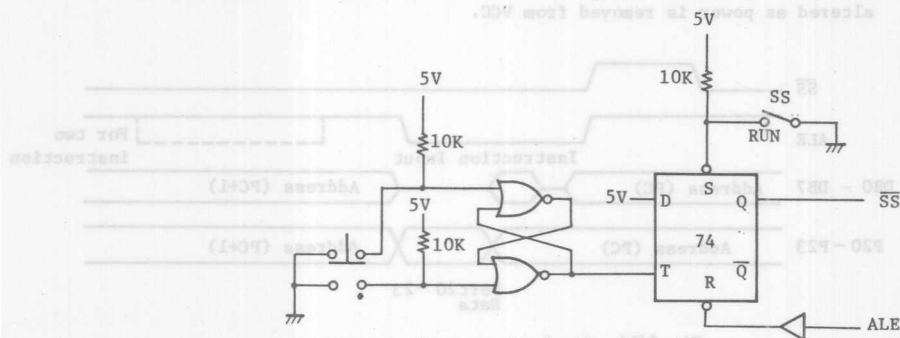


Fig.8(a) Single Step Circuit

(4) Reading of Internal Program Memory

- The processor is placed in the READ mode by applying +12V to the EA pin and 0V to the RESET pin. The address of the location to be read is then applied to BUS and the low order 2-bits of Port 2. The address is latched by a 0 to 1 transition on RESET and the high level causes the contents of program memory location addressed to appear on the eight lines of BUS.
- Figure 7 illustrates the timing diagram for this operation.

(5) Single Step Operation.

- A single step feature useful for debug can be implemented by utilizing a circuit shown in Figure 8 (a) combined with the \overline{SS} pin and ALE pin.
- A D-type flip flop with set and reset is used to generate \overline{SS} . In the run mode \overline{SS} is held high by keeping the flip flop set. To enter single step, set is removed allowing ALE to bring \overline{SS} low via reset input. The next instruction is started by clocking a "1" into the FF which will not appear on \overline{SS} unless ALE is high removing reset. In response to \overline{SS} going high the processor begins an instruction fetch which brings ALE low resetting FF and causing the processor to again enter the stopped state.
- The timing diagram in this case is as shown in Figure 8 (b). (EA = 5V).

(6) Lower Power Stand-by Mode.

- The TMP8048 has been organized to allow power to be removed from all but the volatile, 64×8 data RAM array. In power down mode the contents of data RAM can be maintained while drawing typically 10 - 15% of normal operating power requirements.

VCC serves as the 5V supply for the bulk of the TMP8048 while the VDD supplies only the RAM array. In standby mode VCC is reduced to 0V but VDD is kept at 5V. Applying a low level to reset inhibits any access to the RAM by the processor and guarantees that RAM cannot be inadvertently altered as power is removed from VCC.

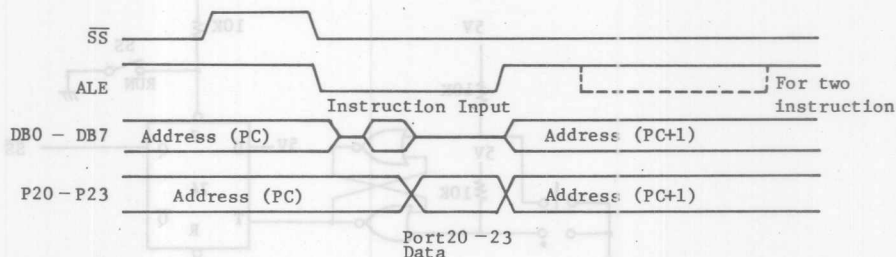


Fig.8(b) Single Step Operation Timing

INSTRUCTION

ACCUMULATOR INSTRUCTION

Mnemonic	Instruction Code								Operation	Bytes	Cycles	Flag	
	D7	D6	D5	D4	D3	D2	D1	D0				C	AC
ADD A,Rr	0	1	1	0	1	r	r	r	(A)←(A)+(Rr) r = 0-7	1	1	○	○
ADD A,@Rr	0	1	1	0	0	0	0	r	(A)←(A)+(Rr) r = 0, 1	1	1	○	○
ADD A,#Data	0	0	0	0	0	0	1	1	(A)←(A)+Data	2	2	○	○
ADDC A,Rr	d7	d6	d5	d4	d3	d2	d1	d0	(A)←(A)+(Rr)+(C) r = 0-7	1	1	○	○
ADDC A,@Rr	0	1	1	1	0	0	0	r	(A)←(A)+((Rr))+(C) r = 0, 1	1	1	○	○
ADDC A,#Data	0	0	0	1	0	0	1	1	(A)←(A)+Data+(C)	2	2	○	○
ANL A,Rr	d7	d6	d5	d4	d3	d2	d1	d0	(A)←(A)^(Rr) r = 0-7	1	1	-	-
ANL A,@Rr	0	1	0	1	0	0	0	r	(A)←(A)^(Rr) r = 0, 1	1	1	-	-
ANL A,#Data	0	1	0	1	0	0	1	1	(A)←(A)^Data	2	2	-	-
ORL A,Rr	0	1	0	0	1	r	r	r	(A)←(A)^(Rr) r = 0-7	1	1	-	-
ORL A,@Rr	0	1	0	0	0	0	0	r	(A)←(A)^(Rr) r = 0, 1	1	1	-	-
ORL A,#Data	0	1	0	0	0	0	1	1	(A)←(A)^Data	2	2	-	-
XRL A,Rr	1	1	0	1	1	r	r	r	(A)←(A)^(Rr) r = 0-7	1	1	-	-
XRL A,@Rr	1	1	0	1	0	0	0	r	(A)←(A)^(Rr) r = 0, 1	1	1	-	-
XRL A,#Data	1	1	0	1	0	0	1	1	(A)←(A)^Data	2	2	-	-
INC A	0	0	0	1	0	1	1	1	(A)←(A)+1	1	1	-	-
DEC A	0	0	0	0	0	1	1	1	(A)←(A)-1	1	1	-	-
CLR A	0	0	1	0	0	1	1	1	(A)←0	1	1	-	-
CPL A	0	0	1	1	0	1	1	1	(A)←NOT (A)	1	1	-	-
DA A	0	1	0	1	0	1	1	1	Decimal Adjust Accumulator	1	1	○	-
SWAP A	0	1	0	0	0	1	1	1	(A4-7)↔(A0-3)	1	1	-	-

Mnemonic	Instruction Code								Operation	Bytes	Cycles	Flag	
	D7	D6	D5	D4	D3	D2	D1	D0				C	AC
RL A	1	1	1	0	0	1	1	1	(An+1)←(An) n = 0 - 6 (A0)←(A7)	1	1	-	-
RLC A	1	1	1	1	0	1	1	1	(An+1)←(An) n = 0 - 6 (C)←(A7) (A0)←(C)	1	1	-	-
RR A	0	1	1	1	0	1	1	1	(An)←(An+1) n = 0 - 6 (A7)←(A0)	1	1	-	-
RRC A	0	1	1	0	0	1	1	1	(An)←(An+1) n = 0 - 6 (C)←(A0) (A7)←(C)	1	1	-	-

Input/Output Instruction

Mnemonic	Instruction Code								Operation	Bytes	Cycles	Flag	
	D7	D6	D5	D4	D3	D2	D1	D0				A	AC
IN A,Pp	0	0	0	0	1	0	P	P	(A)←(Pp) P = 1, 2	1	2	-	-
OUTL Pp,A	0	0	1	1	1	0	P	P	(Pp)←(A) P = 1, 2	1	2	-	-
ANL Pp,#Data	1 d7	0 d6	0 d5	1 d4	1 d3	0 d2	P d1	P d0	(Pp)←(Pp)∧Data P = 1, 2	2	2	-	-
ORL Pp,#Data	1 d7	0 d6	0 d5	0 d4	1 d3	0 d2	P d1	P d0	(Pp)←(Pp)∨Data P = 1, 2	2	2	-	-
INS A,BUS	0	0	0	0	1	0	0	0	(A)←(BUS)	1	2	-	-
OUTL BUS,A	0	0	0	0	0	0	1	0	(BUS)←(A)	1	2	-	-
ANL BUS,#Data	1 d7	0 d6	0 d5	1 d4	1 d3	0 d2	0 d1	0 d0	(BUS)←(BUS)∧Data	2	2	-	-
ORL BUS,#Data	1 d7	0 d6	0 d5	0 d4	1 d3	0 d2	0 d1	0 d0	(BUS)←(BUS)∨Data	2	2	-	-
MOVD A,Pp	0	0	0	0	1	1	P	P	(A0-3)←(Pp) (A4-7)←0 P = 4 - 7	1	2	-	-
MOVD Pp,A	0	0	1	1	1	1	P	P	(Pp)←(A0-3) P = 4 - 7	1	2	-	-



INTEGRATED CIRCUIT

TECHNICAL DATA

TMP8048P/8048PI

TMP8035P/8035PI

TECHNICAL DATA

Mnemonic	Instruction Code								Operation	Bytes	Cycles	Flag	
	D7	D6	D5	D4	D3	D2	D1	D0				C	AC
ANLD Pp,A	1	0	0	1	1	1	P	P	$(Pp) \leftarrow (Pp) \wedge (A0-3)$ $P = 4-7$	1	2	-	-
ORLD Pp,A	1	0	0	0	1	1	P	P	$(Pp) \leftarrow (Pp) \vee (A0-3)$ $P = 4-7$	1	2	-	-

Register Instruction

Mnemonic	Instruction Code								Operation	Bytes	Cycles	Flag	
	D7	D6	D5	D4	D3	D2	D1	D0				C	AC
INC Rr	0	0	0	1	1	r	r	r	$(Rr) \leftarrow (Rr) + 1$ $r = 0-7$	1	1	-	-
INC @Rr	0	0	0	1	0	0	0	r	$((Rr)) \leftarrow ((Rr)) + 1$ $r = 0, 1$	1	1	-	-
DEC Rr	1	1	0	0	1	r	r	r	$(Rr) \leftarrow (Rr) - 1$ $r = 0-7$	1	1	-	-

Branch Instruction

Mnemonic	Instruction Code								Operation	Bytes	Cycles	Flag	
	D7	D6	D5	D4	D3	D2	D1	D0				C	AC
JMP Address	a10 a7	a9 a6	a8 a5	1 a4	0 a3	1 a2	0 a1	0 a0	$(PC0-7) \leftarrow (a0-7)$ $(PC8-10) \leftarrow (a8-10)$ $(PC11) \leftarrow DBF$	2	2	-	-
JMPP @A	1	0	1	1	0	0	1	1	$(PC0-7) \leftarrow ((A))$	1	2	-	-
DJNZ Rr, Address	1 a7	1 a6	1 a5	0 a4	1 a3	r a2	r a1	r a0	$(Rr) \leftarrow (Rr) - 1$ if Rr not 0 $(PC0-7) \leftarrow (a0-7)$	2	2	-	-
JC Address	1 a7	1 a6	1 a5	1 a4	0 a3	1 a2	1 a1	0 a0	$(PC0-7) \leftarrow (a0-7)$ if C = 1 $(PC) \leftarrow (PC) + 2$ if C = 0	2	2	-	-
JNC Address	1 a7	1 a6	1 a5	0 a4	0 a3	1 a2	1 a1	0 a0	$(PC0-7) \leftarrow (a0-7)$ if C = 0 $(PC) \leftarrow (PC) + 2$ if C = 1	2	2	-	-



Mnemonic	Instruction								Operation	Bytes	Cycles	Flag	
	D7	D6	D5	D4	D3	D2	D1	D0				C	AC
JZ Address	1 a7	1 a6	0 a5	0 a4	0 a3	1 a2	1 a1	0 a0	(PC0-7)+(a0-7) if (A) = 0 (PC)+(PC)+2 if (A) = 0	2	2	-	-
JNZ Address	1 a7	0 a6	0 a5	1 a4	0 a3	1 a2	1 a1	0 a0	(PC0-7)+(a0-7) if (A) ≠ 0 (PC)+(PC)+2 if (A) = 0	2	2	-	-
JTO Address	0 a7	0 a6	1 a5	1 a4	0 a3	1 a2	1 a1	0 a0	(PC0-7)+(a0-7) if TO = 1 (PC)+(PC)+2 if TO = 0	2	2	-	-
JNTO Address	0 a7	0 a6	1 a5	0 a4	0 a3	1 a2	1 a1	0 a0	(PC0-7)+(a0-7) if TO = 0 (PC)+(PC)+2 if TO = 1	2	2	-	-
JT1 Address	0 a7	1 a6	0 a5	1 a4	0 a3	1 a2	1 a1	0 a0	(PC0-7)+(a0-7) if T1 = 1 (PC)+(PC)+2 if T1 = 0	2	2	-	-
JNT1 Address	0 a7	1 a6	0 a5	0 a4	0 a3	1 a2	1 a1	0 a0	(PC0-7)+(a0-7) if T1 = 0 (PC)+(PC)+2 if T1 = 1	2	2	-	-
JFO Address	1 a7	0 a6	1 a5	1 a4	0 a3	1 a2	1 a1	0 a0	(PC0-7)+(a0-7) if FO = 1 (PC)+(PC)+2 if FO = 0	2	2	-	-
JF1 Address	0 a7	1 a6	1 a5	1 a4	0 a3	1 a2	1 a1	0 a0	(PC0-7)+(a0-7) if F1 = 1 (PC)+(PC)+2 if F1 = 0	2	2	-	-
JTF Address	0 a7	0 a6	0 a5	1 a4	0 a3	1 a2	1 a1	0 a0	(PC0-7)+(a0-7) if TF = 1 (PC)+(PC)+2 if TF = 0	2	2	-	-
JN1 Address	1 a7	0 a6	0 a5	0 a4	0 a3	1 a2	1 a1	0 a0	(PC0-7)+(a0-7) if INT = 0 (PC)+(PC)+2 if INT = 1	2	2	-	-
JBb Address	b2 a7	b1 a6	b0 a5	1 a4	0 a3	0 a2	1 a1	0 a0	(PC0-7)+(a0-7) if Bb = 1 (PC)+(PC)+2 if Bb = 0 (b = 0 - 7)	2	2	-	-

Subroutine Instruction

Mnemonics.	Instruction Code								Operation	Bytes	Cycles	Flag	
	D7	D6	D5	D4	D3	D2	D1	D0				C	AC
CALL Address	a10 a7	a9 a6	a8 a5	1 a4	0 a3	1 a2	0 a1	0 a0	((SP))+ (PC), (PSW4-7) (SP)+(SP)+1 (PC8-10)+(a8-10) (PC0-7)+(a0-7) (PC11)+DBF	2	2	-	-
RET	1	0	0	0	0	0	1	1	(SP)+(SP)-1 (PC)+((SP))	1	2	-	-
RETR	1	0	0	1	0	0	1	1	(SP)+(SP)-1 (PC)+((SP)) (PSW4-7)+((SP))	1	2	-	-

Flag Manipulation Instruction

Mnemonics	Instruction Code								Operation	Bytes	Cycles	Flag	
	D7	D6	D5	D4	D3	D2	D1	D0				C	AC
CLR C	1	0	0	1	0	1	1	1	(C)+0	1	1	○	-
CPL C	1	0	1	0	0	1	1	1	(C)+NOT(C)	1	1	○	-
CLR FO	1	0	0	0	0	1	0	1	(FO)+0	1	1	-	-
CPL FO	1	0	0	1	0	1	0	1	(FO)+NOT(FO)	1	1	-	-
CLR F1	1	0	1	0	0	1	0	1	(F1)+0	1	1	-	-
CPL F1	1	0	1	1	0	1	0	1	(F1)+NOT(F1)	1	1	-	-

Data Transfer Instruction

Mnemonics	Instruction Code								Operation	Bytes	Cycles	Flag	
	D7	D6	D5	D4	D3	D2	D1	D0				C	AC
MOV A, Rr	1	1	1	1	1	r	r	r	(A)+(Rr) r = 0-7	1	1	-	-
MOV A, @Rr	1	1	1	1	0	0	0	r	(A)+((Rr)) r = 0, 1	1	1	-	-
MOV A, #Data	0 d7	0 d6	1 d5	0 d4	0 d3	0 d2	1 d1	1 d0	(A)+Data	2	2	-	-
MOV Rr, A	1	0	1	0	1	r	r	r	(Rr)+(A) r = 0-7	1	1	-	-

Mnemonics	Instruction Code								Operation	Bytes	Cycles	Flag	
	D7	D6	D5	D4	D3	D2	D1	D0				C	AC
MOV @Rr,A	1	0	1	0	0	0	0	r	((Rr))+ (A) r = 0, 1	1	1	-	-
MOV Rr, #Data	1 d7	0 d6	1 d5	1 d4	1 d3	r d2	r d1	r d0	(Rr)+Data r = 0-7	2	2	-	-
MOV @Rr, #Data	1 d7	0 d6	1 d5	1 d4	0 d3	0 d2	0 d1	r d0	((Rr))+Data r = 0, 1	2	2	-	-
MOV A, PSW	1	1	0	0	0	1	1	1	(A)+(PSW)	1	1	-	-
MOV PSW,A	1	1	0	1	0	1	1	1	(PSW)+(A)	1	1	-	-
XCH A, Rr	0	0	1	0	1	r	r	r	(A)↔(Rr) r = 0-7	1	1	-	-
XCH A,@Rr	0	0	1	0	0	0	0	r	(A)↔((Rr)) r = 0, 1	1	1	-	-
XCHD A,@Rr	0	0	1	1	0	0	0	r	(A0-3)↔((Rr0-3)) r = 0, 1	1	1	-	-
MOVX A,@Rr	1	0	0	0	0	0	0	r	(A)+((Rr)) r = 0, 1	1	2	-	-
MOVX @Rr,A	1	0	0	1	0	0	0	r	((Rr))+ (A) r = 0, 1	1	2	-	-
MOVP A,@A	1	0	1	0	0	0	1	1	(PC0-7)+(A) (A)+((PC))	1	2	-	-
MOVP3 A,@A	1	1	1	0	0	0	1	1	(PC0-7)+(A) (PC8-11)+0011 (A)+((PC))	1	2	-	-

Timer/Counter Instruction

Mnemonics	Instruction Code								Operation	Bytes	Cycles	Flag	
	D7	D6	D5	D4	D3	D2	D1	D0				C	AC
MOV A,T	0	1	0	0	0	0	1	0	(A)+(T)	1	1	-	-
MOV T,A	0	1	1	0	0	0	1	0	(T)+(A)	1	1	-	-
STRT T	0	1	0	1	0	1	0	1	Counting is started in the timer mode	1	1	-	-
STRT CNT	0	1	0	0	0	1	0	1	Counting is started in the event counter mode	1	1	-	-



INTEGRATEDCIRCUIT

TECHNICAL DATA

TMP8048P/8048PI

TMP8035P/8035PI

Mnemonics	Instruction Code								Operation	Bytes	Cycles	Flag	
	D7	D6	D5	D4	D3	D2	D1	D0				C	AC
STOP TCNT	0	1	1	0	0	1	0	1	Stop both time accumulation and event counting	1	1	-	-
EN TCNT1	0	0	1	0	0	1	0	1	Timer interrupt is enabled	1	1	-	-
DIS TCNT1	0	0	1	1	0	1	0	1	Timer interrupt is disabled	1	1	-	-

Control Instruction

Mnemonics	Instruction Code								Operation	Bytes	Cycles	Flag	
	D7	D6	D5	D4	D3	D2	D1	D0				C	AC
EN I	0	0	0	0	0	1	0	1	External interrupt is enabled	1	1	-	-
DIS I	0	0	0	1	0	1	0	1	External interrupt is disabled	1	1	-	-
SEL RB0	1	1	0	0	0	1	0	1	(BS)+0	1	1	-	-
SEL RB1	1	1	0	1	0	1	0	1	(BS)+1	1	1	-	-
SEL MB0	1	1	1	0	0	1	0	1	(DBF)+0	1	1	-	-
SEL MB1	1	1	1	1	0	1	0	1	(DBF)+1	1	1	-	-
ENTO CLK	0	1	1	1	0	1	0	1	T ₀ is enabled to act as the clock output	1	1	-	-
NOP	0	0	0	0	0	0	0	0	No operation	1	1	-	-

TMP8048P / 8035P

ABSOLUTE MAXIMUM RATINGS

SYMBOL	ITEM	RATING
V _{DD}	V _{DD} Supply Voltage (with respect to GND (V _{SS}))	-0.5V to +7V
V _{CC}	V _{CC} Supply Voltage (with respect to GND (V _{SS}))	-0.5V to +7V
V _{INA}	Input Voltage (Except EA)	-0.5V to +7V
V _{INB}	Input Voltage (Only EA)	-0.5V to +13V
P _D	Power Dissipation (T _a =70°C)	1.5W
T _{SOLDER}	Soldering Temperature (Soldering Time 10 sec)	260°C
T _{STG}	Storage Temperature	-55°C to 150°C
T _{OPR}	Operating Temperature	0°C to 70°C

DC CHARACTERISTICS

T_A=0°C to 70°C, V_{CC}=V_{DD}=+5V±10%, V_{SS}=0V, Unless Otherwise Noted.

SYMBOL	PARAMETER	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
V _{IL}	Input Low Voltage (Except XTAL1, XTAL2, RESET)		-0.5	-	0.8	V
V _{IL1}	Input Low Voltage (XTAL1, XTAL2, RESET)		-0.5	-	0.6	V
V _{IH}	Input High Voltage (Except XTAL1, XTAL2, RESET)		2.0	-	V _{CC}	V
V _{IH1}	Input High Voltage (XTAL1, XTAL2, RESET)		3.8	-	V _{CC}	V
V _{OL}	Output Low Voltage (BUS)	I _{OL} =2.0mA	-	-	0.45	V
V _{OL1}	Output Low Voltage (RD, WR, PSEN, ALE)	I _{OL} =1.8mA	-	-	0.45	V
V _{OL2}	Output Low Voltage (PROG)	I _{OL} =1.0mA	-	-	0.45	V
V _{OL3}	Output Low Voltage (For other output pins)	I _{OL} =1.6mA	-	-	0.45	V
V _{OH}	Output High Voltage (BUS)	I _{OH} =-400μA	2.4	-	-	V
V _{OH1}	Output High Voltage (RD, WR, PSEN, ALE)	I _{OH} =-100μA	2.4	-	-	V
V _{OH2}	Output High Voltage (For other output pins)	I _{OH} =-40μA	2.4	-	-	V
I _{LI}	Input Leak Current (T1, INT)	V _{SS} ≤V _{IN} ≤V _{CC}	-	-	±10	μA
I _{LI1}	Input Leak Current (P10-17, P20-P27, EA, SS)	V _{SS} +0.45≤V _{IN} ≤V _{CC}	-	-	-500	μA
I _{LO}	Output Leak Current (BUS, T0) (High impedance condition)	V _{SS} +0.45≤V _{IN} ≤V _{CC}	-	-	±10	μA
I _{DD}	V _{DD} Supply Current		-	-	15	mA
I _{DD} +I _{CC}	Total Supply Current		-	-	135	mA



INTEGRATEDCIRCUIT

TECHNICAL DATA

TMP8048P/8048PI

TMP8035P/8035PI

AC CHARACTERISTICS TA=0°C to 70°C, V_{CC}=V_{DD}=+5V±10%, V_{SS}=0V, Unless otherwise Noted.

SYMBOL	PARAMETER	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
t _{LL}	ALE Pulse Width		400	-	-	ns
t _{AL}	Address Setup Time (ALE)		120	-	-	ns
t _{LA}	Address Hold Time (ALE)		80	-	-	ns
t _{CC}	Control Pulse Width (PSEN, RD, WR)		700	-	-	ns
t _{DW}	Data Setup Time (WR)		500	-	-	ns
t _{WD}	Data Hold Time (WR)		120	-	-	ns
t _{CY}	Cycle Time		2.5	-	15.0	μs
t _{DR}	Data Hold Time (PSEN, RD)	C _L =20pF	0	-	200	ns
t _{RD}	Data Input Read Time (PSEN, RD)		-	-	500	ns
t _{AW}	Address Setup Time (WR)		230	-	-	ns
t _{AD}	Address Setup Time (Data Input)		-	-	950	ns
t _{AFC}	Address Float Time (RD, PSEN)		0	-	-	ns
t _{CA}	Internal between Control Pulse and ALE		10	-	-	ns
t _{CP}	Port Control Setup Time (PROG)		110	-	-	ns
t _{PC}	Port Control Hold Time (PROG)		100	-	-	ns
t _{PR}	Port 2 Input Data Set Time (PROG)		-	-	810	ns
t _{DP}	Output Data Setup Time (PROG)		250	-	-	ns
t _{PD}	Output Data Hold Time (PROG)		65	-	-	ns
t _{PF}	Port2 Input Data Hold Time (PROG)		0	-	150	ns
t _{PP}	PROG Pulse Width		1200	-	-	ns
t _{PL}	Port2 I/O Data Setup Time		350	-	-	ns
t _{LP}	Port2 I/O Data Hold Time		150	-	-	ns

Note : t_{CY}=2.5μs, Control Output: C_L=80 pF, BUS Output: C_L=150pF, PORT20 - 23: C_L=80pF.



INTEGRATED CIRCUIT

TECHNICAL DATA

TMP8048P/8048PI

TMP8035P/8035PI

TMP8048PI/8035PI : INDUSTRIAL SPECIFICATION

ABSOLUTE MAXIMUM RATINGS

SYMBOL	ITEM	RATING
V_{DD}	V_{DD} Supply Voltage (with respect to GND (V_{SS}))	-0.5V to +7V
V_{CC}	V_{CC} Supply Voltage (with respect to GND (V_{SS}))	-0.5V to +7V
V_{INA}	Input Voltage (Except EA)	-0.5V to +7V
V_{INB}	Input Voltage (Only EA)	-0.5V to +13V
P_D	Power Dissipation ($T_a=70^\circ\text{C}$)	1.5W
T_{SOLDER}	Soldering Temperature (Soldering Time 10 sec.)	260°C
T_{STG}	Storage Temperature	-55°C to 150°C
T_{OPR}	Operating Temperature	-40°C to 85°C

DC CHARACTERISTICS $T_A=-40^\circ\text{C}$ to 85°C , $V_{CC}=V_{DD}=+5V\pm10\%$, $V_{SS}=0V$, Unless otherwise Noted.

SYMBOL	PARAMETER	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
V_{IL}	Input Low Voltage (Except XTAL1, XTAL2, RESET)		-0.5	-	0.7	V
V_{IL1}	Input Low Voltage (XTAL1, XTAL2, RESET)		-0.5	-	0.6	V
V_{IH}	Input High Voltage (Except XTAL1, XTAL2, RESET)		2.2	-	V_{CC}	V
V_{IH1}	Input High Voltage (XTAL1, XTAL2, RESET)		3.8	-	V_{CC}	V
V_{OL}	Output Low Voltage (BUS)	$I_{OL}=1.6\text{mA}$	-	-	0.45	V
V_{OL1}	Output Low Voltage (RD, WR, PSEN, ALE)	$I_{OL}=1.6\text{mA}$	-	-	0.45	V
V_{OL2}	Output Low Voltage (PROG)	$I_{OL}=0.8\text{mA}$	-	-	0.45	V
V_{OL3}	Output Low Voltage (For other output pins)	$I_{OL}=1.2\text{mA}$	-	-	0.45	V
V_{OH}	Output High Voltage (BUS)	$I_{OH}=-280\mu\text{A}$	2.4	-	-	V
V_{OH1}	Output High Voltage (RD, WR, PSEN, ALE)	$I_{OH}=-80\mu\text{A}$	2.4	-	-	V
V_{OH2}	Output High Voltage (For other output pins)	$I_{OH}=-30\mu\text{A}$	2.4	-	-	V
I_{LI}	Input Leak Current ($T_1, \overline{\text{INT}}$)	$V_{SS}\leq V_{IN}\leq V_{CC}$	-	-	± 10	μA
I_{LI1}	Input Leak Current (P10-17, P20-27, EA, SS)	$V_{SS}+0.45\leq V_{IN}\leq V_{CC}$	-	-	-600	μA
I_{LO}	Output Leak Current (BUS, T_0) (High impedance condition)	$V_{SS}+0.45\leq V_{IN}\leq V_{CC}$	-	-	± 10	μA
I_{DD}	V_{DD} Supply Current		-	-	20	mA
$I_{DD}+I_{CC}$	Total Supply Current		-	-	145	mA



INTEGRATED CIRCUIT

TECHNICAL DATA

TMP8048P/8048PI

TMP8035P/8035PI

AC CHARACTERISTICS

$T_A = -40^{\circ}\text{C}$ to 85°C , $V_{CC} = V_{DD} = +5\text{V} \pm 10\%$, $V_{SS} = 0\text{V}$, Unless otherwise Noted.

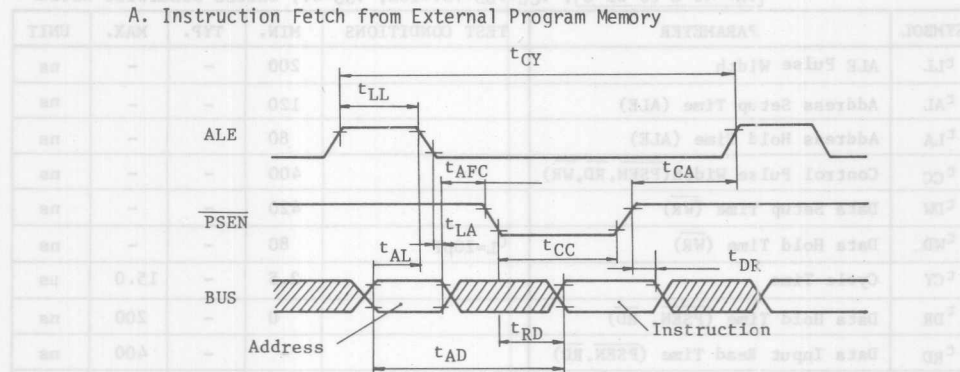
SYMBOL	PARAMETER	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
t_{LL}	ALE Pulse Width		200	-	-	ns
t_{AL}	Address Setup Time (ALE)		120	-	-	ns
t_{LA}	Address Hold Time (ALE)		80	-	-	ns
t_{CC}	Control Pulse Width ($\overline{\text{PSEN}}$, $\overline{\text{RD}}$, $\overline{\text{WR}}$)		400	-	-	ns
t_{DW}	Data Setup Time ($\overline{\text{WR}}$)		420	-	-	ns
t_{WD}	Data Hold Time ($\overline{\text{WR}}$)	$C_L = 20\text{pF}$	80	-	-	ns
t_{CY}	Cycle Time		2.5	-	15.0	μs
t_{DR}	Data Hold Time ($\overline{\text{PSEN}}$, $\overline{\text{RD}}$)		0	-	200	ns
t_{RD}	Data Input Read Time ($\overline{\text{PSEN}}$, $\overline{\text{RD}}$)		-	-	400	ns
t_{AW}	Address Setup Time ($\overline{\text{WR}}$)		230	-	-	ns
t_{AD}	Address Setup Time (Data Input)		-	-	600	ns
t_{AFC}	Address Float Time ($\overline{\text{RD}}$, $\overline{\text{PSEN}}$)		-40	-	-	ns
t_{CA}	Internal between Control Pulse and ALE		10	-	-	ns
t_{CP}	Port Control Setup Time (PROG)		115	-	-	ns
t_{PC}	Port Control Hold Time (PROG)		65	-	-	ns
t_{PR}	Port 2 Input Data Set Time (PROG)		-	-	860	ns
t_{DP}	Output Data Setup Time (PROG)		230	-	-	ns
t_{PD}	Output Data Hold Time (PROG)		25	-	-	ns
t_{Pf}	Port2 Input Data Hold Time (PROG)		0	-	160	ns
t_{PP}	PROG Pulse Width		920	-	-	ns
t_{PL}	Port 2 I/O Data Setup Time		300	-	-	ns
t_{LP}	Port 2 I/O Data Hold Time		120	-	-	ns

Note : $t_{cy} = 2.5\mu\text{s}$, Control Output: $C_L = 80\text{pF}$, BUS Output: $C_L = 150\text{pF}$, PORT 20 - 23:

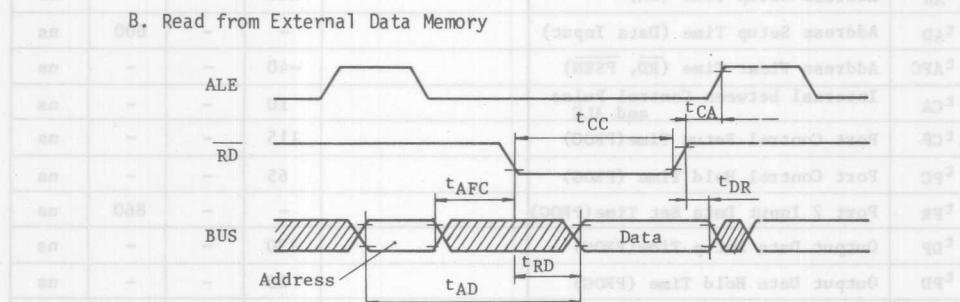
$C_L = 80\text{pF}$.

TIMING WAVEFORM

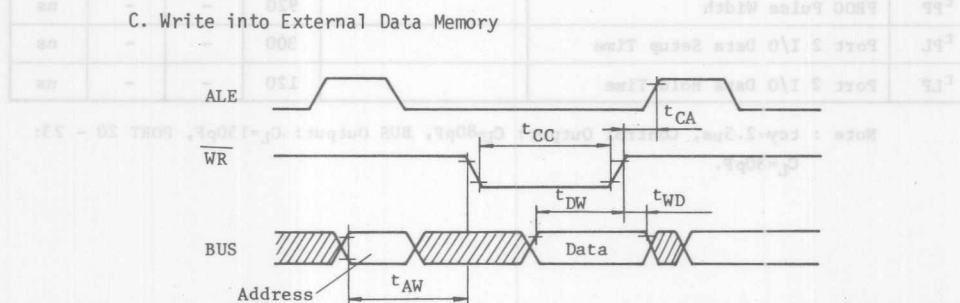
A. Instruction Fetch from External Program Memory



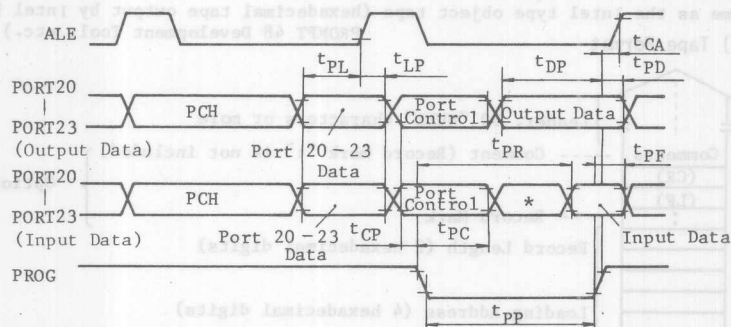
B. Read from External Data Memory



C. Write into External Data Memory



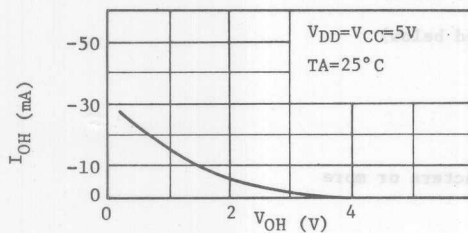
D. Timing of Port 2 during Expander Instruction Execution



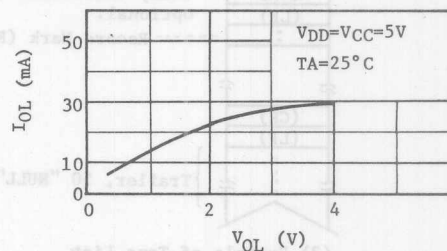
* Input Enabled State

TYPICAL CHARACTERISTICS

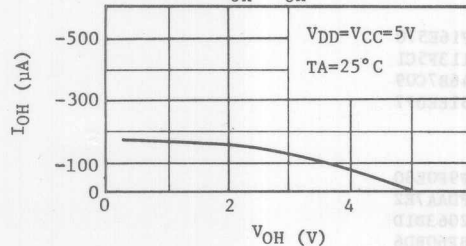
1) BUS: $I_{OH} - V_{OH}$



3) BUS, P1, P2: $I_{OL} - V_{OL}$



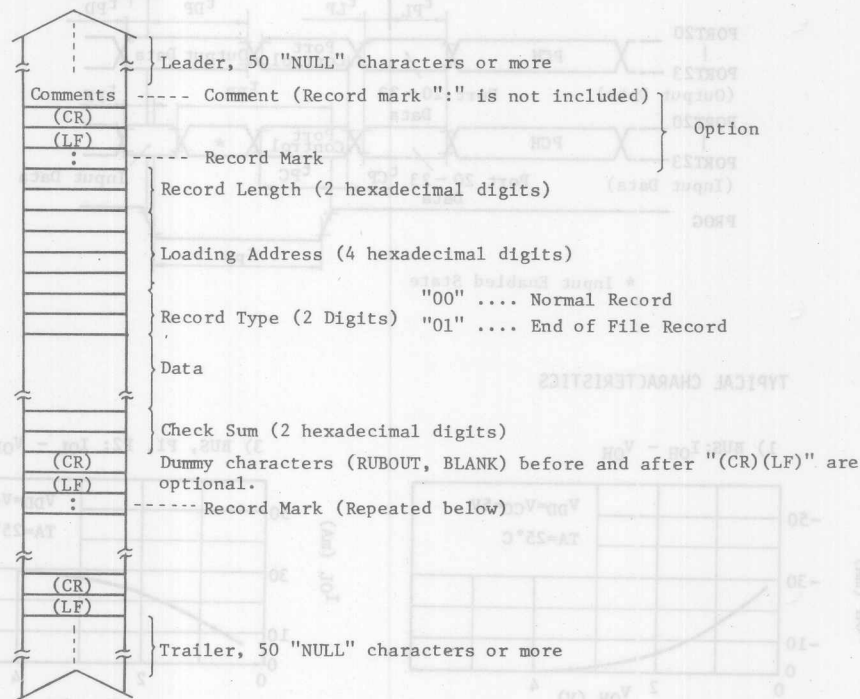
2) P1, P2: $I_{OH} - V_{OH}$



PROGRAM TAPE FORMAT

TMP8084 programs are delivered in the form of paper tape with the following format and it is required to attach the tape list. The format of paper tape is same as the Intel type object tape (hexadecimal tape output by Intel MDS system, PROMPT 48 Development Tool, etc.)

(1) Tape Format



(2) Example of Tape List

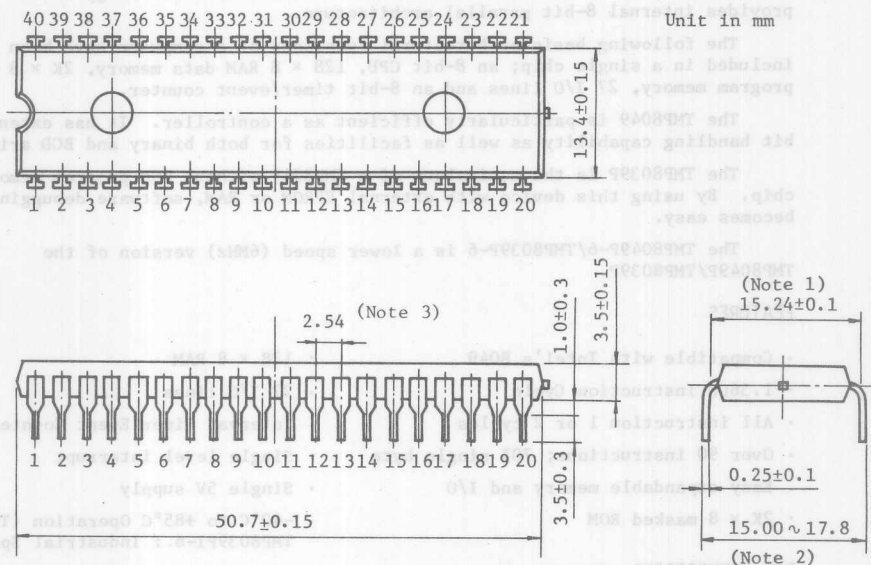
TOSHIBA MICRO COMPUTER TLCS-84

```
:100000000665C7D79CF50F3F951FED55A8FF16E570
:1000100088884DDE67D31F5D8ABA6DF292F113F5C1
:100020004FF1FB5DFFDAA96A99CF7DF94A346B7C09
:10003000197352F729F12F79AA9C057C5B851EED77
```

...

```
:1003C0005DFDB5E556A67277F61A51C631CF9F0E80
:1003D000BD2F6F20E8BB1977E3FB5AD1F41FDAA7E2
:1003E000B53D42E0EC32546025B7308CDD52063D1D
:1003F000B4BE9E9E345B6138060B20VC372BF60BD6
:00000001FF
```

OUTLINE DRAWING



- Note :
1. This dimension shows the center of curvature of leads.
 2. This dimension shows spread of leads.
 3. The pitch of leads is 2.54 and the tolerance is ± 0.25 from the theoretical center of each lead obtained having No.1 lead and No. 40 lead as the reference.

Note : Toshiba does not assume any responsibility for use of any circuitry described; no circuit patent licenses are implied, and Toshiba reserves the right, at any time without notice, to change said circuitry.



INTEGRATED CIRCUIT

TECHNICAL DATA

TOSHIBA MOS DIGITAL INTEGRATED CIRCUIT

TMP8049P/8049P-6/8049PI-6

TMP8039P/8039P-6/8039PI-6

N-CHANNEL SILICON GATE MOS

8-BIT SINGLE-CHIP MICROCOMPUTER

GENERAL DESCRIPTION

The TMP8049P, from here on referred to as the TMP8049, is a single chip microcomputer fabricated in N-channel Silicon Gate MOS technology which provides internal 8-bit parallel architecture.

The following basic architectural functions of a computer have been included in a single chip; an 8-bit CPU, 128×8 RAM data memory, $2K \times 8$ ROM program memory, 27 I/O lines and an 8-bit timer/event counter.

The TMP8049 is particularly efficient as a controller. It has extensive bit handling capability as well as facilities for both binary and BCD arithmetic.

The TMP8039P is the equivalent of a TMP8049 without ROM program memory on chip. By using this device with external EPROM or RAM, software debugging becomes easy.

The TMP8049P-6/TMP8039P-6 is a lower speed (6MHz) version of the TMP8049P/TMP8039P.

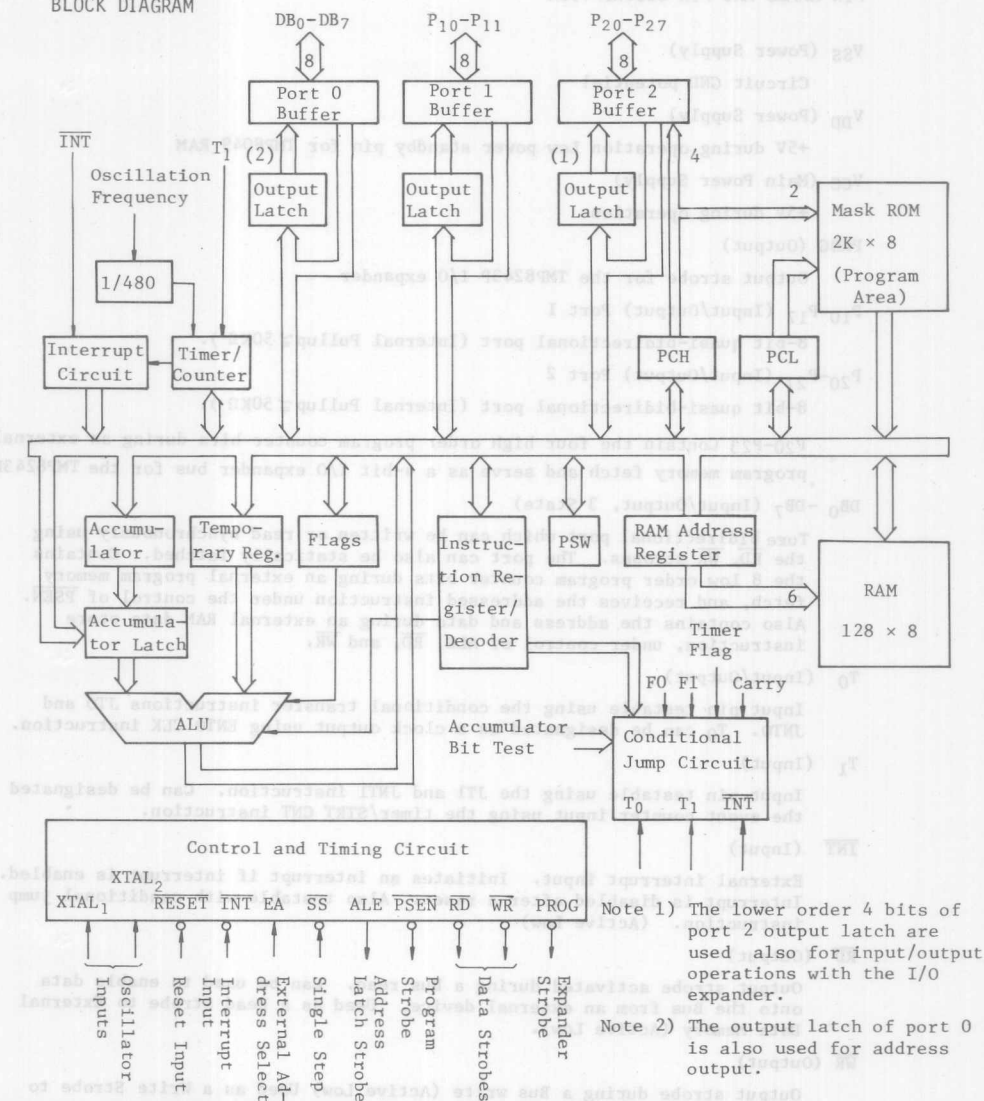
FEATURES

- Compatible with Intel's 8049
- 1.36 μ S Instruction Cycle
- All instruction 1 or 2 cycles
- Over 90 instructions; 70% single byte
- Easy expandable memory and I/O
- $2K \times 8$ masked ROM
- 128×8 RAM
- 27 I/O lines
- Interval Timer/Event Counter
- Single level interrupt
- Single 5V supply
- -40°C to +85°C Operation (TMP8049PI-6/
TMP8039PI-6 : Industrial Specification)

PIN CONNECTIONS (Top View)

T0	1	40	V _{CC} (+5V)
XTAL1	2	39	T1
XTAL2	3	38	P27
RESET	4	37	P26
SS	5	36	P25
INT	6	35	P24
EA	7	34	P17
RD	8	33	P16
PSEN	9	32	P15
WR	10	31	P14
ALE	11	30	P13
DB0	12	29	P12
DB1	13	28	P11
DB2	14	27	P10
DB3	15	26	V _{DD} (+5V)
DB4	16	25	PROG
DB5	17	24	P23
DB6	18	23	P22
DB7	19	22	P21
(0V) VSS	20	21	P20

BLOCK DIAGRAM





PIN NAMES AND PIN DESCRIPTION

VSS (Power Supply)

Circuit GND potential

VDD (Power Supply)

+5V during operation Low power standby pin for TMP8049 RAM

VCC (Main Power Supply)

+5V during operation

PROG (Output)

Output strobe for the TMP8243P I/O expander

P₁₀-P₁₇ (Input/Output) Port 18-bit quasi-bidirectional port (Internal Pullup $\cong 50K\Omega$).P₂₀-P₂₇ (Input/Output) Port 28-bit quasi-bidirectional port (Internal Pullup $\cong 50K\Omega$).P₂₀-P₂₃ Contain the four high order program counter bits during an external program memory fetch and serve as a 4-bit I/O expander bus for the TMP8243P.DB₀-DB₇ (Input/Output, 3 State)

True bidirectional port which can be written or read synchronously using the RD, WR strobes. The port can also be statically latched. Contains the 8 low order program counter bits during an external program memory fetch, and receives the addressed instruction under the control of PSEN. Also contains the address and data during an external RAM data store instruction, under control of ALE, RD, and WR.

T₀ (Input/Output)Input pin testable using the conditional transfer instructions JTO and JNT0. T₀ can be designated as a clock output using ENT0 CLK instruction.T₁ (Input)

Input pin testable using the JTI and JNT1 instruction. Can be designated the event counter input using the timer/STRT CNT instruction.

INT (Input)

External interrupt input. Initiates an interrupt if interrupt is enabled. Interrupt is disabled after a reset. Also testable with conditional jump instruction. (Active Low)

RD (Output)

Output strobe activated during a Bus read. Can be used to enable data onto the Bus from an external device. Used as a Read Strobe to External Data Memory (Active Low).

WR (Output)

Output strobe during a Bus write (Active Low) Used as a Write Strobe to External Data Memory.



INTEGRATED CIRCUIT

TECHNICAL DATA

TMP8049P/8049P-6/8049PI-6

TMP8039P/8039P-6/8039PI-6

TECHNICAL DATA

RESET (Input)

Active Low signal which is used to initialize the Processor. Also used during Power down.

ALE (Output)

Address Latch Enable. This signal occurs once during each cycle and is useful as a clock output. The negative edge of ALE strobes address into external data and program memory.

PSEN (Output)

Program Store Enable. This output occurs only during a fetch to external program memory (Active Low).

SS (Input)

Single step input can be used in conjunction with ALE to "single step" processor through each instruction when SS is low the CPU is placed into a wait state after it has completed the instruction being executed.

EA (Input)

External Access input which forces all program memory fetches to reference external memory. Useful for emulation and debug and essential for testing and program verification. (Active High).

XTAL 1 (Input)

One side of crystal input for internal oscillator. Also input for external source.

XTAL 2 (Input)

Other side of crystal input.

FUNCTIONAL DESCRIPTION

1. System Configuration

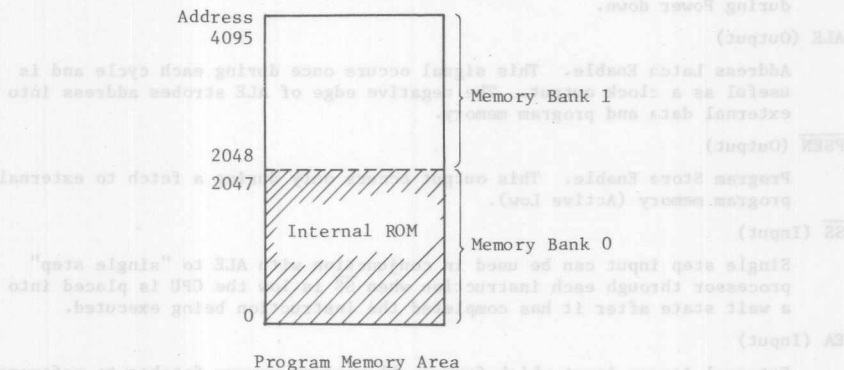
The following system functions of the TMP8049 are described in detail.

- | | |
|-------------------------------|-------------------------------|
| (1) Program Memory | (6) Stack (Stack Pointer) |
| (2) Data Memory | (7) Flag 0, Flag 1 |
| (3) I/O Port | (8) Program Status Word (PSW) |
| (4) Timer/Counter | (9) Reset |
| (5) Interrupt Control Circuit | (10) Oscillator Circuit |

(1) Program Memory

- The maximum memory that can be directly addressed by the TMP8049 is 4096 bytes. The first 2048 bytes from location 0 through 2047 can be internal resident mask ROM. The rest of the 2048 bytes of addressable memory are external to the chip. The TMP8039 has no internal resident memory; all memory must be external.

- There are three locations in Program Memory of special importance.

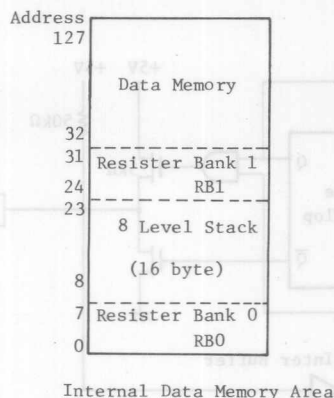


- Location 0
Activating the Reset line of the processor causes the first instruction to be fetched from Location 0.
- Location 3
Activating the interrupt line of the processor (if interrupt enabled) causes a jump to subroutine defined by address held in Location 3.
- Location 7
A timer/counter interrupt resulting from a timer/counter overflow (if enabled) causes a jump to a subroutine defined by address held in Location 7.
- Program addresses 0-2047 and 2048-4095 are called memory banks 0 and 1 respectively. Switching of memory banks is achieved by changing the most significant bit of the program counter (PC) during execution of an unconditional jump instruction or call instruction executed after using SEL MB0 or SEL MB1.

Reset operation automatically selects Bank 0.

(2) Data Memory

- Resident Data Memory (volatile RAM) is organized as 128 words by 8-bits wide.
- The first 8 locations (0 - 7) of the memory array are designated as working registers and are directly addressable by several instructions. By executing a Register Bank switch instruction (SEL RBL) locations 24 - 31 are designated as the working registers in place of 0 - 7.



- RAM locations 8 - 23 serve a dual role in that they contain the program counter stack which is a stack 2 bytes wide by 8 levels deep. These locations store returning addresses from subroutines. If the level of subroutine nesting is less than the permitted 8, you free up 2 bytes of RAM for general use for every level of nesting not utilized.
- ALL 128 locations are indirectly addressable through either of two RAM Pointer Registers which reside at R0 and R1 of the Register array.
- The TMP8049 architecture allows extension of the Data Memory to 256 words.

(3) Input/Output Ports

- The TMP8049 has 27 I/O lines which can be used for either input or output. These I/O lines are grouped into 3 ports each having 8 bidirectional lines and 3 "test" inputs which can alter program sequences when tested by conditional jump instructions.
- Ports 1 and 2 are each 8-bits wide and have identical characteristics. Data written to these ports is statically latched and remains unchanged until rewritten. As input ports these lines are non-latching, i.e., inputs must be present until read by an input instruction.
- All lines of Ports 1 and 2 are called quasi-bidirectional because of a special output circuit structure (illustrated in Figure 1). Each line is continuously pulled to a +5V level through a high impedance resistive device (50K Ω) which is sufficient to provide the source current for a TTL high level yet can be pulled low by a standard TTL gate thus allowing the same pin to be used for both input and output. In order to speed up the "0" to "1" transition a low impedance device (5K Ω) is switched in momentarily whenever a "1" is written to line. When a "0" is written to line a low impedance device overcomes the pullup and provides TTL current sinking capability.

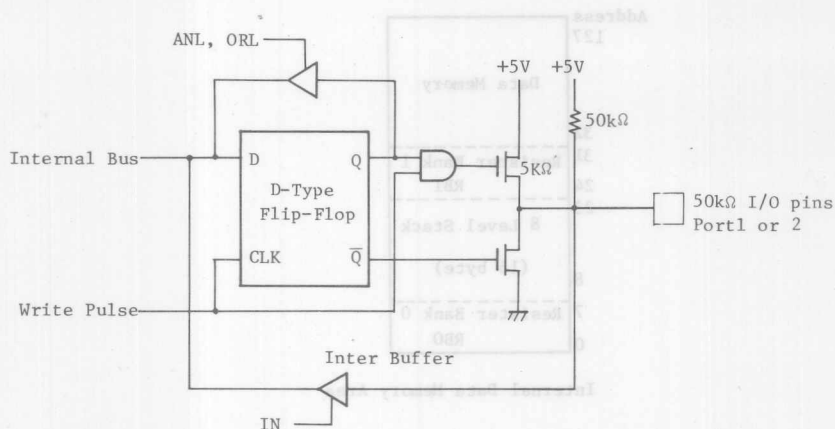


Fig.1 Input/Output Circuit of Port 1, Port 2

- Reset initializes all lines to a high impedance "1" state.
- When external data memory area is not addressed during execution of an internal program, Port 0 (DB0 - DB7) becomes a true bidirectional port (bus) with associated input and output strobes. If bidirectional feature not needed Bus can serve as either a statically latched output port or a non-latched input port. However, I/O lines of this port cannot be intermixed.
- As a static port data is written and latched using the OUTL instruction and inputted using the INS instruction these two commands generate pulses on the corresponding \overline{RD} and \overline{WR} strobe lines.
- As a bidirectional port the MOVX instructions are used to read and write the port which generate the \overline{WR} \overline{RD} strobes.
- When not being written or read, the Bus lines are in a high impedance state.

(4) Timer/Event Counter

- The 8-bit binary up counter can use either of the following frequency inputs

(1) Internal clock (1/480 of OSC frequency)

..... Timer mode

(2) External input clock form T1 terminal
(minimum cycle time $3 \times \text{ALE cycle}$)

..... Event Counter mode

The counter is presetable and readable with two MOV instructions which transfer the content of the accumulator to the counter and vice versa. The counter content is not affected by a Reset and is initialized solely by the MOV T, A instruction. The counter is stopped by a Reset or STOP TCNT instruction and remains stopped until started by START T instruction or as an event counter by a START CNT. Once started the counter will increment to its maximum count (FF) and overflow to Zero continuing its count until stopped by a STOP TCNT instruction or RESET.

The increment from maximum count to Zero (overflow) results in the setting of an overflow flag and the generation of an interrupt request. When interrupt acknowledged a subroutine call to Location 7 will be initiated. Location 7 should store the starting address of the timer or counter service routine. The state of the overflow flag is testable with the conditional JUMP (JTF). The flag is reset by executing a JTF or by RESET. Figure 2 illustrates the concept of the timer circuit.

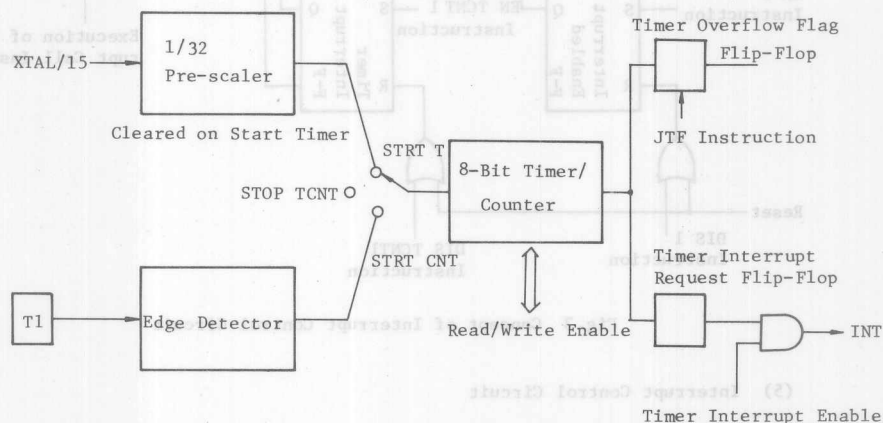


Fig.2 Concept of Timer Circuit

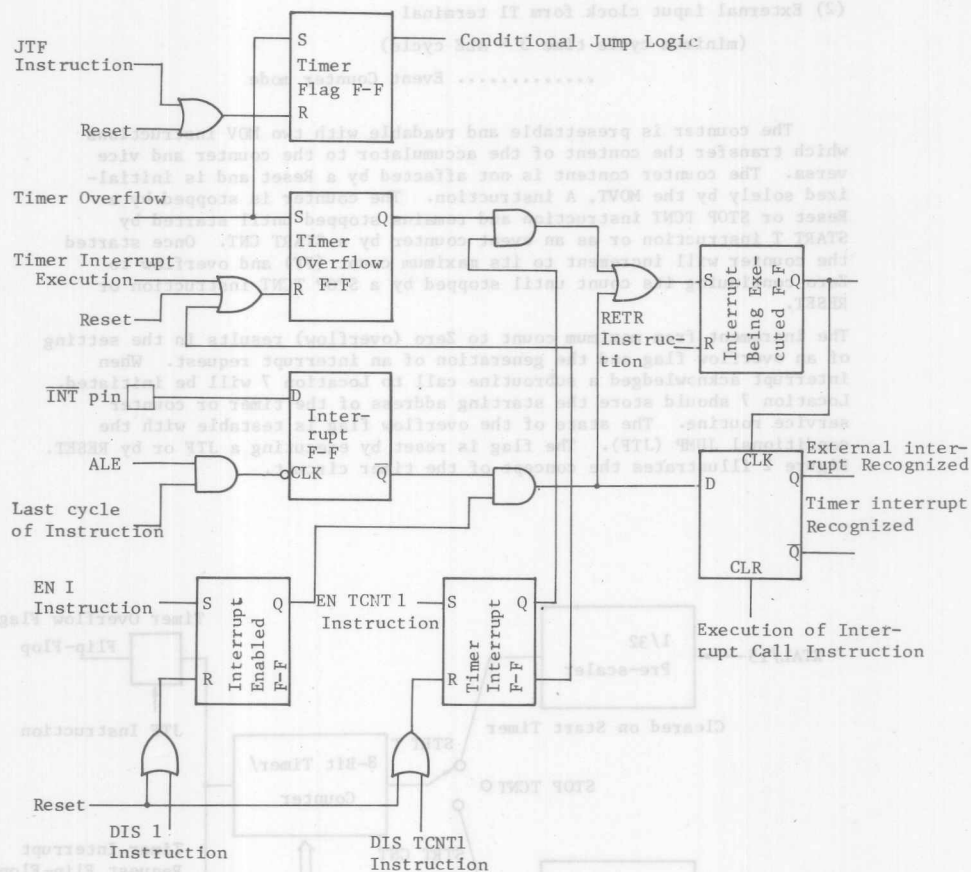


Fig. 3 Concept of Interrupt Control Circuit

(5) Interrupt Control Circuit

There are two distinct types of Interrupts in the TMP8049.

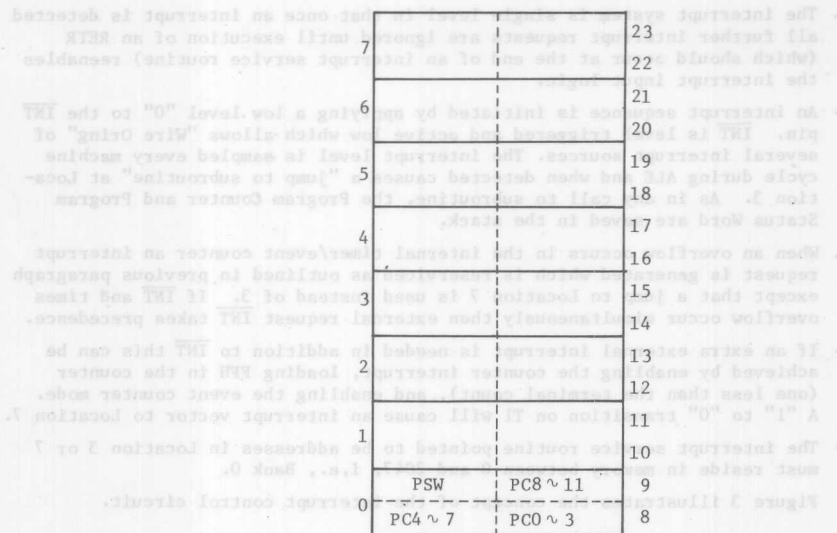
- (1) External Interrupt from the $\overline{\text{INT}}$ terminal
- (2) Timer Interrupt caused by timer overflow

- The interrupt system is single level in that once an interrupt is detected all further interrupt requests are ignored until execution of an RETR (which should occur at the end of an interrupt service routine) reenables the interrupt input logic.
- An interrupt sequence is initiated by applying a low level "0" to the $\overline{\text{INT}}$ pin. $\overline{\text{INT}}$ is level triggered and active low which allows "Wire Oring" of several interrupt sources. The interrupt level is sampled every machine cycle during ALE and when detected causes a "jump to subroutine" at Location 3. As in any call to subroutine, the Program Counter and Program Status Word are saved in the stack.
- When an overflow occurs in the internal timer/event counter an interrupt request is generated which is rescheduled as outlined in previous paragraph except that a jump to Location 7 is used instead of 3. If $\overline{\text{INT}}$ and times overflow occur simultaneously then external request $\overline{\text{INT}}$ takes precedence.
- If an extra external interrupt is needed in addition to $\overline{\text{INT}}$ this can be achieved by enabling the counter interrupt, loading FFH in the counter (one less than the terminal count), and enabling the event counter mode. A "1" to "0" transition on T1 will cause an interrupt vector to Location 7.
- The interrupt service routine pointed to be addresses in Location 3 or 7 must reside in memory between 0 and 2047, i.e., Bank 0.

Figure 3 illustrates the concept of the interrupt control circuit.

(6) Stack (stack Pointer)

- An interrupt or Call to a subroutine causes the contents of the program counter to be stored in one of the 8 register pairs of the Program Counter Stack. The pair to be used is determined by a 3-bit stack pointer which is part of the Program Status Word (PSW explained in section (8)). Data RAM locations, 8 through 23 are available as stack registers and are used to store the program counter and 4-bits of PSW as shown in the figure.
- The stack pointer when initialized points to RAM locations 8 and 9. The first subroutine jump or interrupt results in the program counter contents being transferred to Locations 8 and 9. Then the stack pointer is incremented by one to point to Locations 10 and 11. Eight levels of subroutine are obviously possible.
- At the end of a subroutine signalled by a RET or RETR causes the stack pointer to be decremented by one and the contents of the resulting pair to be transferred to the Program Counter.



Stack
Pointer

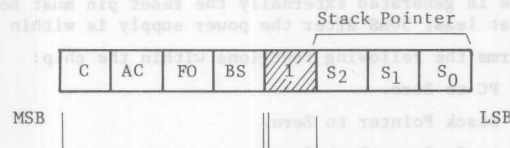
RAM
Address

(7) Flag 0, Flag 1, (F0, F1)

- The TMP8049 has two flags F0 and F1 which are used for conditional jump. These flags can be set, reset and tested with the conditional jump instruction JF0.
- F0 is a part of the program status word (PSW) and is saved in the stack area when a subroutine is called.

(8) Program Status Word (PSW)

- An 8-bit status word which can be loaded to and from the accumulator exists called the Program Status Word (PSW). The PSW is read by a MOV A, PSW and written to by a MOV PSW, A. The information available in the PSW is shown in the diagram below.



Saved in stack area Spare ("1" during Read)
at the time of Sub-
routine Call.

- Bits 0 - 2 : Stack Pointer Bits(S₀, S₁, S₂)
- Bit 3 : Not used ("1" level when read.)
- Bit 4 : Working Register Bank Switch Bit (BS)

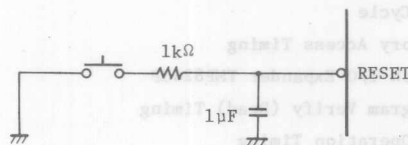
0 = Bank 0

1 = Bank 1

- Bit 5 : Flag 0 (FO)
- Bit 6 : Auxiliary Carry (AC) carry bit generated by an ADD instruction and used by the decimal adjust instruction DA, A (AC)
- Bit 7 : Carry (C) flag which indicates that the previous operation has resulted in the accumulator. (C)

(9) Reset

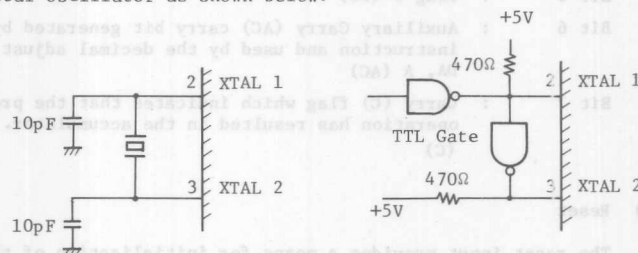
- The reset input provides a means for initialization of the processor. This Schmitt trigger input has an internal pullup resistor which in combination with an external 1μF capacitor provides an internal reset pulse sufficient length to guarantee that all internal logic is initialized.



- If the pulse is generated externally the reset pin must be held at ground ($\leq 0.5V$) for at least 50mS after the power supply is within tolerance.
- Reset performs the following functions within the chip:
 - (i) Sets PC to Zero.
 - (ii) Sets Stack Pointer to Zero.
 - (iii) Selects Register Bank 0.
 - (iv) Selects Memory Bank 0.
 - (v) Sets BUS (DB0 - DB7) to high impedance state. (Except when EA = 5V)
 - (vi) Sets Ports 1 and 2 to input mode.
 - (vii) Disables interrupts (timer and external).
 - (viii) Stops Timer.
 - (ix) Clears Timer Flag.
 - (x) Clears F0 and F1.
 - (xi) Disables clock output T0.

(10) Oscillator Circuit

- TMP8049 can be operated by the external clock input in addition to crystal oscillator as shown below.



2. Basic Operation and Timing

The following basic operations and timing are explained

- (1) Instruction Cycle
- (2) External Memory Access Timing
- (3) Interface with I/O Expander TMP8243P
- (4) Internal Program Verify (Read) Timing
- (5) Single Step Operation Timing
- (6) Low Power Stand-by Mode



(1) Instruction Cycle

- The instructions of TMP8049 are executed in one or two machine cycles, and one machine cycle consists of five states.
- Fig.4 illustrates its relationship with the clock input to CPU.
- $\phi 2$ clock shown in Fig.4 is derived to outside by ENTO CLK instruction.
- ALE can be also used as the clock to indicate the machine cycle as well as giving the external address latch timing.

(2) External Memory Access Timing

(i) Program Memory Access

- TMP8049 programs are executed in the following three modes.

- (1) Execution of internal program only.
- (2) Execution of both external and internal programs.
- (3) Execution of external program only.

The external program memory is accessed (instructions are fetched) automatically when the internal ROM address is exceeded in mode (2) and from initial start address 0 in mode (3).

- In the external program memory access operation, the following will occur
 - The contents of the 12-bit program counter will be output on BUS (DB0 - DB7) and the lower 4-bits of Port 2.
 - Address Latch Enable (ALE) will indicate the time at which address is valid. The trailing edge of ALE is used to latch the address externally.
 - Program Store Enable (PSEN) indicates that an external instruction fetch is in progress and serves to enable the external memory device.
 - BUS (DB0 - DB7) reverts to Input mode and the processor accepts its 8-bit contents as an Instruction Word.
- Figure 5 illustrates the timing.

(ii) Access of External Data Memory

- In the extended data memory access operation during READ/WRITE cycle the following occurs
 - The contents of R0 R1 is output onto BUS (DB0 - DB7).
 - ALE indicates address is valid. The trailing edge of ALE is used to latch the address externally.
 - A read \overline{RD} or write \overline{WR} pulse on the corresponding output pins indicates the type of data memory access in progress. Output data valid at trailing edge of \overline{WR} and input data must be valid at trailing edge of \overline{RD} .
 - Data (8-bits) is transferred over BUS.

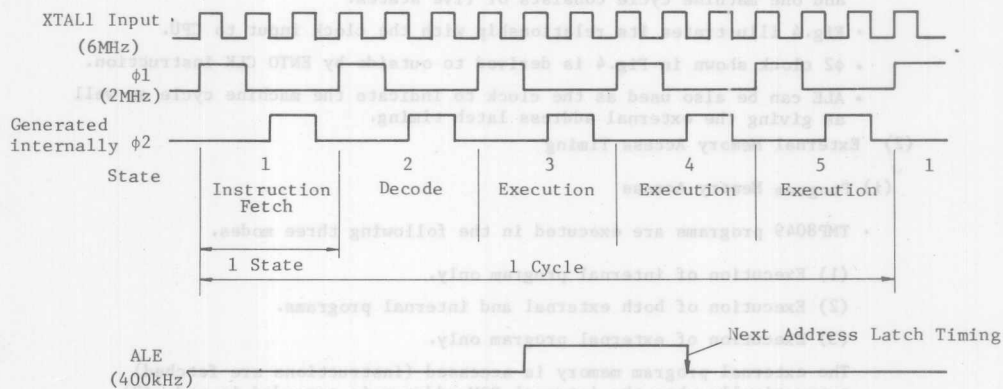


Fig.4 Instruction Cycle Timing

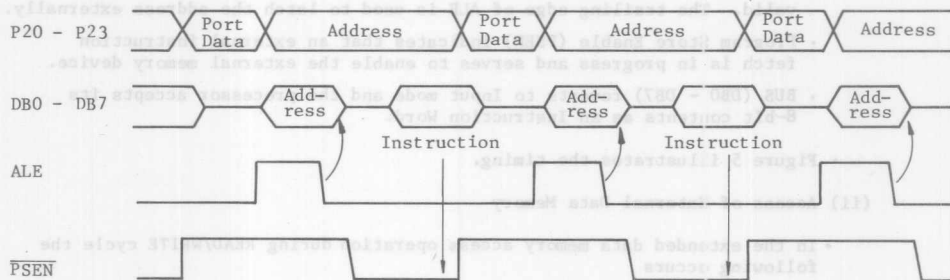
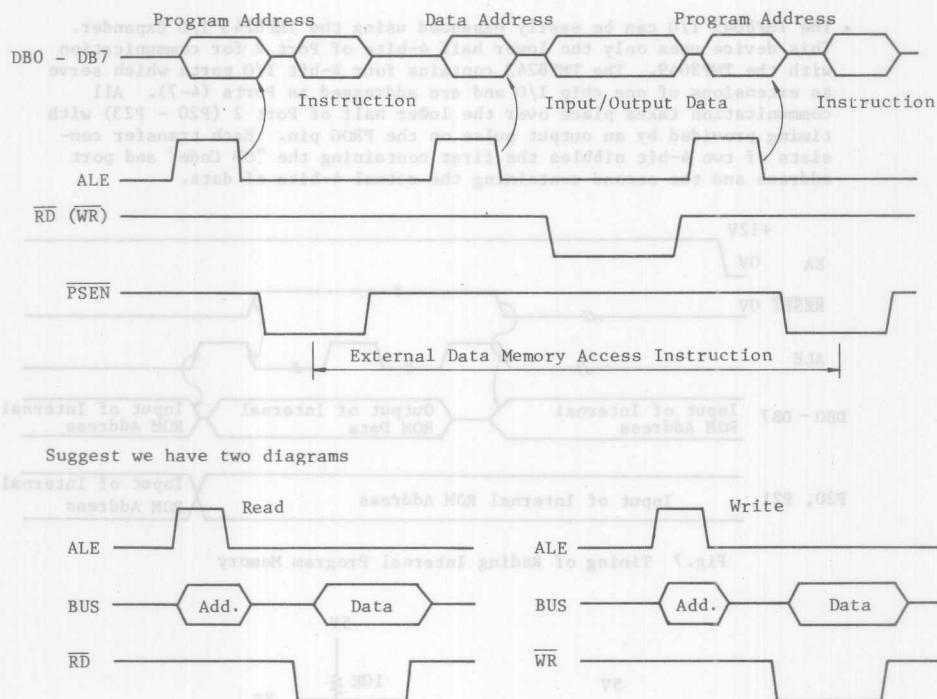


Fig.5 Timing of External Program Memory Access



Suggest we have two diagrams

Fig. 6 Timing of Accessing External Data Memory

• Figure 6 illustrates the timing of accessing the external data memory during execution of external program.

(3) Interface with I/O Expander (TMP8243P)

- The TMP8049 I/O can be easily expanded using the TMP8243 I/O Expander. This device uses only the lower half 4-bits of Port 2 for communication with the TMP8049. The TMP8243 contains four 4-bit I/O ports which serve as extensions of one chip I/O and are addressed as Ports (4-7). All communication takes place over the lower half of Port 2 (P20 - P23) with timing provided by an output pulse on the PROG pin. Each transfer consists of two 4-bit nibbles the first containing the "OP Code" and port address and the second containing the actual 4-bits of data.

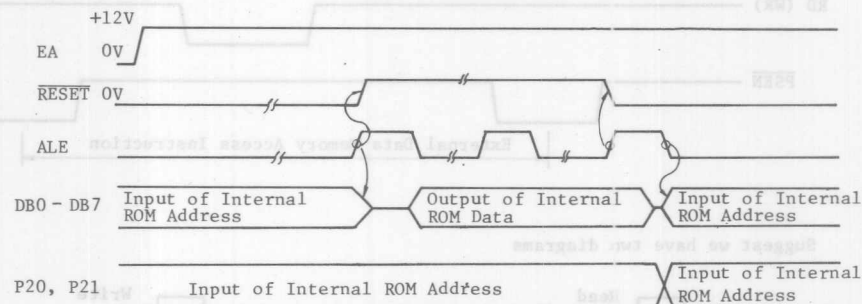


Fig.7 Timing of Reading Internal Program Memory

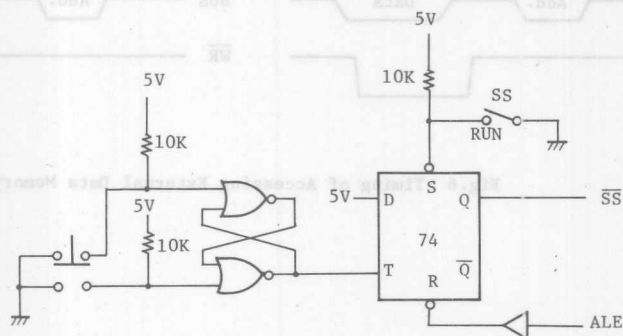


Fig.8(a) Single Step Circuit

(4) Reading of Internal Program Memory

- The processor is placed in the READ mode by applying +12V to the EA pin and 0V to the RESET pin. The address of the location to be read is then applied to BUS and the low order 2-bits of Port 2. The address is latched by a 0 to 1 transition on RESET and the high level causes the contents of program memory location addressed to appear on the eight lines of BUS.
- Figure 7 illustrates the timing diagram for this operation.

(5) Single Step Operation.

- A single step feature useful for debug can be implemented by utilizing a circuit shown in Figure 8 (a) combined with the SS pin and ALE pin.
- A D-type flip flop with set and reset is used to generate \overline{SS} . In the run mode \overline{SS} is held high by keeping the flip flop set. To enter single step, set is removed allowing ALE to bring \overline{SS} low via reset input. The next instruction is started by clocking a "1" into the FF which will not appear on \overline{SS} unless ALE is high removing reset. In response to \overline{SS} going high the processor begins an instruction fetch which brings ALE low resetting FF and causing the processor to again enter the stopped state.
- The timing diagram in this case is as shown in Figure 8 (b). (EA = 5V).

(6) Lower Power Stand-by Mode.

- The TMP8049 has been organized to allow power to be removed from all but the volatile, 128 × 8 data RAM array. In power down mode the contents of data RAM can be maintained while drawing typically 10 - 15% of normal operating power requirements.

VCC serves as the 5V supply for the bulk of the TMP8049 while the VDD supplies only the RAM array. In standby mode VCC is reduced to 0V but VDD is kept at 5V. Applying a low level to reset inhibits any access to the RAM by the processor and guarantees that RAM cannot be inadvertently altered as power is removed from VCC.

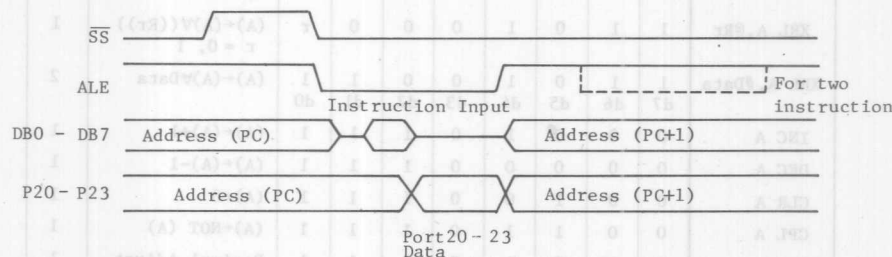


Fig.8(b) Single Step Operation Timing

INSTRUCTION

ACCUMULATOR INSTRUCTION

Mnemonic	Instruction Code								Operation	Bytes	Cycles	Flag	
	D7	D6	D5	D4	D3	D2	D1	D0				C	AC
ADD A,Rr	0	1	1	0	1	r	r	r	(A)+(A)+(Rr) r = 0 - 7	1	1	○	○
ADD A,@Rr	0	1	1	0	0	0	0	r	(A)+(A)+(Rr) r = 0, 1	1	1	○	○
ADD A,#Data	0 d7	0 d6	0 d5	0 d4	0 d3	0 d2	1 d1	1 d0	(A)+(A)+Data	2	2	○	○
ADDC A,Rr	0	1	1	1	1	r	r	r	(A)+(A)+(Rr)+(C) r = 0 - 7	1	1	○	○
ADDC A,@Rr	0	1	1	1	0	0	0	r	(A)+(A)+((Rr))+(C) r = 0, 1	1	1	○	○
ADDC A,#Data	0 d7	0 d6	0 d5	1 d4	0 d3	0 d2	1 d1	1 d0	(A)+(A)+Data+(C)	2	2	○	○
ANL A,Rr	0	1	0	1	1	r	r	r	(A)+(A)^(Rr) r = 0 - 7	1	1	-	-
ANL A,@Rr	0	1	0	1	0	0	0	r	(A)+(A)^(Rr) r = 0, 1	1	1	-	-
ANL A,#Data	0 d7	1 d6	0 d5	1 d4	0 d3	0 d2	1 d1	1 d0	(A)+(A)^Data	2	2	-	-
ORL A,Rr	0	1	0	0	1	r	r	r	(A)+(A)^(Rr) r = 0 - 7	1	1	-	-
ORL A,@Rr	0	1	0	0	0	0	0	r	(A)+(A)^(Rr) r = 0, 1	1	1	-	-
ORL A,#Data	0 d7	1 d6	0 d5	0 d4	0 d3	0 d2	1 d1	1 d0	(A)+(A)^Data	2	2	-	-
XRL A,Rr	1	1	0	1	1	r	r	r	(A)+(A)^(Rr) r = 0 - 7	1	1	-	-
XRL A,@Rr	1	1	0	1	0	0	0	r	(A)+(A)^(Rr) r = 0, 1	1	1	-	-
XRL A,#Data	1 d7	1 d6	0 d5	1 d4	0 d3	0 d2	1 d1	1 d0	(A)+(A)^Data	2	2	-	-
INC A	0	0	0	1	0	1	1	1	(A)+(A)+1	1	1	-	-
DEC A	0	0	0	0	0	1	1	1	(A)+(A)-1	1	1	-	-
CLR A	0	0	1	0	0	1	1	1	(A)+0	1	1	-	-
CPL A	0	0	1	1	0	1	1	1	(A)+NOT (A)	1	1	-	-
DA A	0	1	0	1	0	1	1	1	Decimal Adjust Accumulator	1	1	○	-
SWAP A	0	1	0	0	0	1	1	1	(A4-7)↔(A0-3)	1	1	-	-



INTEGRATED CIRCUIT

TECHNICAL DATA

TMP8049P/8049P-6/8049PI-6

TMP8039P/8039P-6/8039PI-6

Mnemonic	Instruction Code								Operation	Bytes	Cycles	Flag	
	D7	D6	D5	D4	D3	D2	D1	D0				C	AC
RL A	1	1	1	0	0	1	1	1	$(An+1) \leftarrow (An)$ $n = 0-6$ $(A0) \leftarrow (A7)$	1	1	-	-
RLC A	1	1	1	1	0	1	1	1	$(An+1) \leftarrow (An)$ $n = 0-6$ $(C) \leftarrow (A7)$ $(A0) \leftarrow (C)$	1	1	-	-
RR A	0	1	1	1	0	1	1	1	$(An) \leftarrow (An+1)$ $n = 0-6$ $(A7) \leftarrow (A0)$	1	1	-	-
RRC A	0	1	1	0	0	1	1	1	$(An) \leftarrow (An+1)$ $n = 0-6$ $(C) \leftarrow (A0)$ $(A7) \leftarrow (C)$	1	1	-	-

Input/Output Instruction

Mnemonic	Instruction Code								Operation	Bytes	Cycles	Flag	
	D7	D6	D5	D4	D3	D2	D1	D0				A	AC
IN A, Pp	0	0	0	0	1	0	P	P	$(A) \leftarrow (Pp)$ $P = 1, 2$	1	2	-	-
OUTL Pp, A	0	0	1	1	1	0	P	P	$(Pp) \leftarrow (A)$ $P = 1, 2$	1	2	-	-
ANL Pp, #Data	1	0	0	1	1	0	P	P	$(Pp) \leftarrow (Pp) \wedge \text{Data}$ $P = 1, 2$	2	2	-	-
ORL Pp, #Data	1	0	0	0	1	0	P	P	$(Pp) \leftarrow (Pp) \vee \text{Data}$ $P = 1, 2$	2	2	-	-
INS A, BUS	0	0	0	0	1	0	0	0	$(A) \leftarrow (\text{BUS})$	1	2	-	-
OUTL BUS, A	0	0	0	0	0	0	1	0	$(\text{BUS}) \leftarrow (A)$	1	2	-	-
ANL BUS, #Data	1	0	0	1	1	0	0	0	$(\text{BUS}) \leftarrow (\text{BUS}) \wedge \text{Data}$	2	2	-	-
ORL BUS, #Data	1	0	0	0	1	0	0	0	$(\text{BUS}) \leftarrow (\text{BUS}) \vee \text{Data}$	2	2	-	-
MOVD A, Pp	0	0	0	0	1	1	P	P	$(A0-3) \leftarrow (Pp)$ $(A4-7) \leftarrow 0$ $P = 4-7$	1	2	-	-
MOVD Pp, A	0	0	1	1	1	1	P	P	$(Pp) \leftarrow (A0-3)$ $P = 4-7$	1	2	-	-

Mnemonic	Instruction Code								Operation	Bytes	Cycles	Flag	
	D7	D6	D5	D4	D3	D2	D1	D0				C	AC
ANLD Pp,A	1	0	0	1	1	1	P	P	$(Pp) \leftarrow (Pp) \wedge (A0-3)$ $P = 4-7$	1	2	-	-
ORLD Pp,A	1	0	0	0	1	1	P	P	$(Pp) \leftarrow (Pp) \vee (A0-3)$ $P = 4-7$	1	2	-	-

Register Instruction

Mnemonic	Instruction Code								Operation	Bytes	Cycles	Flag	
	D7	D6	D5	D4	D3	D2	D1	D0				C	AC
INC Rr	0	0	0	1	1	r	r	r	$(Rr) \leftarrow (Rr) + 1$ $r = 0-7$	1	1	-	-
INC @Rr	0	0	0	1	0	0	0	r	$((Rr)) \leftarrow ((Rr)) + 1$ $r = 0, 1$	1	1	-	-
DEC Rr	1	1	0	0	1	r	r	r	$(Rr) \leftarrow (Rr) - 1$ $r = 0-7$	1	1	-	-

Branch Instruction

Mnemonic	Instruction Code								Operation	Bytes	Cycles	Flag	
	D7	D6	D5	D4	D3	D2	D1	D0				C	AC
JMP Address	a10 a7	a9 a6	a8 a5	1 a4	0 a3	1 a2	0 a1	0 a0	$(PC0-7) \leftarrow (a0-7)$ $(PC8-10) \leftarrow (a3-10)$ $(PC11) \leftarrow DBF$	2	2	-	-
JMPP @A	1	0	1	1	0	0	1	1	$(PC0-7) \leftarrow ((A))$	1	2	-	-
DJNZ Rr, Address	1 a7	1 a6	1 a5	0 a4	1 a3	r a2	r a1	r a0	$(Rr) \leftarrow (Rr) - 1$ if Rr not 0 $(PC0-7) \leftarrow (a0-7)$	2	2	-	-
JC Address	1 a7	1 a6	1 a5	1 a4	0 a3	1 a2	1 a1	0 a0	$(PC0-7) \leftarrow (a0-7)$ if C = 1 $(PC) = (PC) + 2$ if C = 0	2	2	-	-
JNC Address	1 a7	1 a6	1 a5	0 a4	0 a3	1 a2	1 a1	0 a0	$(PC0-7) \leftarrow (a0-7)$ if C = 0 $(PC) \leftarrow (PC) + 2$ if C = 1	2	2	-	-



INTEGRATED CIRCUIT

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TECHNICAL DATA

TMP8049P/8049P-6/8049PI-6

TMP8039P/8039P-6/8039PI-6

Mnemonic	Instruction								Operation	Bytes	Cycles	Flag	
	D7	D6	D5	D4	D3	D2	D1	D0				C	AC
JZ Address	1 a7	1 a6	0 a5	0 a4	0 a3	1 a2	1 a1	0 a0	(PC0-7)+(a0-7) if (A) = 0 (PC)+(PC)+2 if (A) ≠ 0	2	2	-	-
JNZ Address	1 a7	0 a6	0 a5	1 a4	0 a3	1 a2	1 a1	0 a0	(PC0-7)+(a0-7) if (A) ≠ 0 (PC)+(PC)+2 if (A) = 0	2	2	-	-
JTO Address	0 a7	0 a6	1 a5	1 a4	0 a3	1 a2	1 a1	0 a0	(PC0-7)+(a0-7) if TO = 1 (PC)+(PC)+2 if TO = 0	2	2	-	-
JNTO Address	0 a7	0 a6	1 a5	0 a4	0 a3	1 a2	1 a1	0 a0	(PC0-7)+(a0-7) if TO = 0 (PC)+(PC)+2 if TO = 1	2	2	-	-
JT1 Address	0 a7	1 a6	0 a5	1 a4	0 a3	1 a2	1 a1	0 a0	(PC0-7)+(a0-7) if T1 = 1 (PC)+(PC)+2 if T1 = 0	2	2	-	-
JNT1 Address	0 a7	1 a6	0 a5	0 a4	0 a3	1 a2	1 a1	0 a0	(PC0-7)+(a0-7) if T1 = 0 (PC)+(PC)+2 if T1 = 1	2	2	-	-
JFO Address	1 a7	0 a6	1 a5	1 a4	0 a3	1 a2	1 a1	0 a0	(PC0-7)+(a0-7) if FO = 1 (PC)+(PC)+2 if FO = 0	2	2	-	-
JF1 Address	0 a7	1 a6	1 a5	1 a4	0 a3	1 a2	1 a1	0 a0	(PC0-7)+(a0-7) if F1 = 1 (PC)+(PC)+2 if F1 = 0	2	2	-	-
JTF Address	0 a7	0 a6	0 a5	1 a4	0 a3	1 a2	1 a1	0 a0	(PC0-7)+(a0-7) if TF = 1 (PC)+(PC)+2 if TF = 0	2	2	-	-
JN1 Address	1 a7	0 a6	0 a5	0 a4	0 a3	1 a2	1 a1	0 a0	(PC0-7)+(a0-7) if INT = 0 (PC)+(PC)+2 if INT = 1	2	2	-	-
JBb Address	b2 a7	b1 a6	b0 a5	1 a4	0 a3	0 a2	1 a1	0 a0	(PC0-7)+(a0-7) if Bb = 1 (PC)+(PC)+2 if Bb = 0 (b = 0-7)	2	2	-	-

Subroutine Instruction

Mnemonics	Instruction Code								Operation	Bytes	Cycles	Flag	
	D7	D6	D5	D4	D3	D2	D1	D0				C	AC
CALL Address	a10 a7	a9 a6	a8 a5	1 a4	0 a3	1 a2	0 a1	0 a0	((SP))+ (PC), (PSW4-7) (SP)+(SP)+1 (PC8-10)+(a8-10) (PC0-7)+(a0-7) (PC11)+DBF	2	2	-	-
RET	1	0	0	0	0	0	1	1	(SP)+(SP)-1 (PC)+((SP))	1	2	-	-
RETR	1	0	0	1	0	0	1	1	(SP)+(SP)-1 (PC)+((SP)) (PSW4-7)+((SP))	1	2	-	-

Flag Manipulation Instruction

Mnemonics	Instruction Code								Operation	Bytes	Cycles	Flag	
	D7	D6	D5	D4	D3	D2	D1	D0				C	AC
CLR C	1	0	0	1	0	1	1	1	(C)+0	1	1	○	-
CPL C	1	0	1	0	0	1	1	1	(C)+NOT(C)	1	1	○	-
CLR FO	1	0	0	0	0	1	0	1	(FO)+0	1	1	-	-
CPL FO	1	0	0	1	0	1	0	1	(FO)+NOT(FO)	1	1	-	-
CLR F1	1	0	1	0	0	1	0	1	(F1)+0	1	1	-	-
CPL F1	1	0	1	1	0	1	0	1	(F1)+NOT(F1)	1	1	-	-

Data Transfer Instruction

Mnemonics	Instruction Code								Operation	Bytes	Cycles	Flag	
	D7	D6	D5	D4	D3	D2	D1	D0				C	AC
MOV A, Rr	1	1	1	1	1	r	r	r	(A)+(Rr) r = 0-7	1	1	-	-
MOV A, @Rr	1	1	1	1	0	0	0	r	(A)+((Rr)) r = 0, 1	1	1	-	-
MOV A, #Data	0 d7	0 d6	1 d5	0 d4	0 d3	0 d2	1 d1	1 d0	(A)+Data	2	2	-	-
MOV Rr, A	1	0	1	0	1	r	r	r	(Rr)+(A) r = 0-7	1	1	-	-

Mnemonics	Instruction Code								Operation	Bytes	Cycles	Flag	
	D7	D6	D5	D4	D3	D2	D1	D0				C	AC
MOV @Rr,A	1	0	1	0	0	0	0	r	((Rr))+ (A) r = 0, 1	1	1	-	-
MOV Rr,#Data	1	0	1	1	1	r	r	r	(Rr)+Data r = 0-7	2	2	-	-
MOV @Rr,#Data	1	0	1	1	0	0	0	r	((Rr))+Data r = 0, 1	2	2	-	-
MOV A,PSW	1	1	0	0	0	1	1	1	(A)+(PSW)	1	1	-	-
MOV PSW,A	1	1	0	1	0	1	1	1	(PSW)+(A)	1	1	-	-
XCH A,Rr	0	0	1	0	1	r	r	r	(A)↔(Rr) r = 0-7	1	1	-	-
XCH A,@Rr	0	0	1	0	0	0	0	r	(A)↔((Rr)) r = 0, 1	1	1	-	-
XCHD A,@Rr	0	0	1	1	0	0	0	r	(A0-3)↔((Rr0-3)) r = 0, 1	1	1	-	-
MOVX A,@Rr	1	0	0	0	0	0	0	r	(A)+((Rr)) r = 0, 1	1	2	-	-
MOVX @Rr,A	1	0	0	1	0	0	0	r	((Rr))+ (A) r = 0, 1	1	2	-	-
MOVP A,@A	1	0	1	0	0	0	1	1	(PC0-7)+(A) (A)+((PC))	1	2	-	-
MOVP3 A,@A	1	1	1	0	0	0	1	1	(PC0-7)+(A) (PC8-11)+0011 (A)+((PC))	1	2	-	-

Timer/Counter Instruction

Mnemonics	Instruction Code								Operation	Bytes	Cycles	Flag	
	D7	D6	D5	D4	D3	D2	D1	D0				C	AC
MOV A,T	0	1	0	0	0	0	1	0	(A)+(T)	1	1	-	-
MOV T,A	0	1	1	0	0	0	1	0	(T)+(A)	1	1	-	-
STRT T	0	1	0	1	0	1	0	1	Counting is started in the timer mode	1	1	-	-
STRT CNT	0	1	0	0	0	1	0	1	Counting is started in the event counter mode	1	1	-	-

Mnemonics	Instruction Code								Operation	Bytes	Cycles	Flag	
	D7	D6	D5	D4	D3	D2	D1	D0				C	AC
STOP TCNT	0	1	1	0	0	1	0	1	Stop both time accumulation and event counting	1	1	-	-
EN TCNT1	0	0	1	0	0	1	0	1	Timer interrupt is enabled	1	1	-	-
DIS TCNT1	0	0	1	1	0	1	0	1	Timer interrupt is disabled	1	1	-	-

Control Instruction

Mnemonics	Instruction Code								Operation	Bytes	Cycles	Flag	
	D7	D6	D5	D4	D3	D2	D1	D0				C	AC
EN I	0	0	0	0	0	1	0	1	External interrupt is enabled	1	1	-	-
DIS I	0	0	0	1	0	1	0	1	External interrupt is disabled	1	1	-	-
SEL RBO	1	1	0	0	0	1	0	1	(BS)+0	1	1	-	-
SEL RB1	1	1	0	1	0	1	0	1	(BS)+1	1	1	-	-
SEL MBO	1	1	1	0	0	1	0	1	(DBF)+0	1	1	-	-
SEL MB1	1	1	1	1	0	1	0	1	(DBF)+1	1	1	-	-
ENTO CLK	0	1	1	1	0	1	0	1	T ₀ is enabled to act as the clock output	1	1	-	-
NOP	0	0	0	0	0	0	0	0	No operation	1	1	-	-



INTEGRATEDCIRCUIT

TECHNICAL DATA

TMP8049P/8049P-6/8049PI-6

TMP8039P/8039P-6/8039PI-6

TMP8049P/8039P/8049P-6/8039P-6

ABSOLUTE MAXIMUM RATINGS

SYMBOL	ITEM	RATING
V _{DD}	V _{DD} Supply Voltage (with respect to GND (V _{SS}))	-0.5V to +7V
V _{CC}	V _{CC} Supply Voltage (with respect to GND (V _{SS}))	-0.5V to +7V
V _{INA}	Input Voltage (Except EA)	-0.5V to +7V
V _{INB}	Input Voltage (Only EA)	-0.5V to +13V
P _D	Power Dissipation (Ta=25°C)	1.5W
T _{SOLDER}	Soldering Temperature (Soldering Time 10 sec.)	260°C
T _{STG}	Storage Temperature	-55°C to 150°C
T _{OPR}	Operating Temperature	0°C to 70°C

DC CHARACTERISTICS

 TA=0°C to 70°C, V_{CC}=V_{DD}=+5V±10%, V_{SS}=0V, Unless Otherwise Noted.

SYMBOL	PARAMETER	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
V _{IL}	Input Low Voltage		-0.5	-	0.8	V
V _{IH}	Input High Voltage (Except XTAL1, XTAL2, RESET)		2.0	-	V _{CC}	V
V _{IH1}	Input High Voltage (XTAL1, XTAL2, RESET)		3.8	-	V _{CC}	V
V _{OL}	Output Low Voltage (BUS)	I _{OL} =2.0mA	-	-	0.45	V
V _{OL1}	Output Low Voltage (RD, WR, PSEN, ALE)	I _{OL} =1.8mA	-	-	0.45	V
V _{OL2}	Output Low Voltage (PROG)	I _{OL} =1.0mA	-	-	0.45	V
V _{OL3}	Output Low Voltage (For other output pins)	I _{OL} =1.6mA	-	-	0.45	V
V _{OH}	Output High Voltage (BUS)	I _{OH} =-400μA	2.4	-	-	V
V _{OH1}	Output High Voltage (RD, WR, PSEN, ALE)	I _{OH} =-100μA	2.4	-	-	V
V _{OH2}	Output High Voltage (For tothe output pins)	I _{OH} =-40μA	2.4	-	-	V
I _{LI}	Input Leak Current (T1, INT)	V _{SS} ≤V _{IN} ≤V _{CC}	-	-	±10	μA
I _{LI1}	Input Leak Current (P10-17, P20-P27, EA, SS)	V _{SS} +0.45≤V _{IN} ≤V _{CC}	-	-	-500	μA
I _{LO}	Output Leak Current (BUS, TO) (High impedance condition)	V _{SS} +0.45≤V _{IN} ≤V _{CC}	-	-	±10	μA
I _{DD}	V _{DD} Supply Current		-	-	50	mA
I _{DD} +I _{CC}	Total Supply Current		-	-	170	mA



INTEGRATEDCIRCUIT

TECHNICAL DATA

TMP8049P/8049P-6/8049PI-6

TMP8039P/8039P-6/8039PI-6

AC CHARACTERISTICS

 TA=0°C to 70°C, V_{CC}=V_{DD}=+5V±10%, V_{SS}=0V, Unless Otherwise Noted.

SYMBOL	PARAMETER	TEST CONDITION	TMP8049P/ TMP8039P		TMP8049P-6/ TMP8039P-6		UNITS
			MIN.	MAX.	MIN.	MAX.	
t _{LL}	ALE Pulse Width		150	-	400	-	ns
t _{AL}	Address Setup Time (ALE)		70	-	150	-	ns
t _{LA}	Address Hold Time (ALE)		50	-	80	-	ns
t _{CC}	Control Pulse Width (PSEN, RD, WR)		300	-	700	-	ns
t _{DW}	Data Setup Time (WR)		250	-	500	-	ns
t _{WD}	Data Hold Time (WR)	C _L =20pF	40	-	120	-	ns
t _{CY}	Cycle Time	11MHz XTAL (6MHz XTAL for -6)	1.36	15.0	2.5	15.0	μs
t _{DR}	Data Hold Time (PSEN, RD)		0	100	0	200	ns
t _{RD}	Data Input Read Time (PSEN, RD)		-	200	-	500	ns
t _{AW}	Address Setup Time (WR)		200	-	230	-	ns
t _{AD}	Address Setup Time (Data Input)		-	400	-	950	ns
t _{AFC}	Address Float Time (RD, PSEN)		-10	-	0	-	ns
t _{CP}	Port Control Setup Time (PROG)		100	-	110	-	ns
t _{PC}	Port Control Hold Time (PROG)		60	-	130	-	ns
t _{PR}	Port 2 Input Data Set Time (PROG)		-	650	-	810	ns
t _{DP}	Output Data Setup Time (PROG)		200	-	220	-	ns
t _{PD}	Output Data Hold Time (PROG)		20	-	65	-	ns
t _{PF}	Port 2 Input Data Hold Time (PROG)		0	150	0	150	ns
t _{PP}	PROG Pulse Width		700	-	1510	-	ns
t _{PL}	Port 2 I/O Data Setup Time		250	-	500	-	ns
t _{LP}	Port 2 I/O Data Hold Time		120	-	150	-	ns

 Control Outputs : C_L=80pF, BUS Outputs : C_L=150pF



INTEGRATED CIRCUIT

TECHNICAL DATA

TMP8049P/8049P-6/8049PI-6

TMP8039P/8039P-6/8039PI-6

TMP8049PI-6/8039PI-6 : INDUSTRIAL SPECIFICATION.

ABSOLUTE MAXIMUM RATINGS

SYMBOL	ITEM	RATING
V _{DD}	V _{DD} Supply Voltage (with respect to GND (V _{SS}))	-0.5V to +7V
V _{CC}	V _{CC} Supply Voltage (with respect to GND (V _{SS}))	-0.5V to +7V
V _{INA}	Input Voltage (Except EA)	-0.5V to +7V
V _{INB}	Input Voltage (Only EA)	-0.5V to +13V
P _D	Power Dissipation (Ta=25°C)	1.5W
T _{SOLDER}	Soldering Temperature (Soldering Time 10 sec.)	260°C
T _{STG}	Storage Temperature	-55°C to 150°C
T _{OPR}	Operating Temperature	-40°C to 85°C

DC CHARACTERISTICS

TA=-40°C to 85°C, V_{CC}=V_{DD}+5V±10%, V_{SS}=0V, Unless Otherwise Noted.

SYMBOL	PARAMETER	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
V _{IL}	Input Low Voltage		-0.5	-	0.6	V
V _{IH}	Input High Voltage (Except XTAL1, XTAL2, RESET)		2.2	-	V _{CC}	V
V _{IH1}	Input High Voltage (XTAL1, XTAL2, RESET)		3.8	-	V _{CC}	V
V _{OL}	Output Low Voltage (BUS)	I _{OL} =1.6mA	-	-	0.45	V
V _{OL1}	Output Low Voltage (RD, WR, PSEN, ALE)	I _{OL} =1.6mA	-	-	0.45	V
V _{OL2}	Output Low Voltage (PROG)	I _{OL} =0.8mA	-	-	0.45	V
V _{OL3}	Output Low Voltage (For other output pins)	I _{OL} =1.2mA	-	-	0.45	V
V _{OH}	Output High Voltage (BUS)	I _{OH} =-80μA	2.4	-	-	V
V _{OH1}	Output High Voltage (RD, WR, PSEN, ALE)	I _{OH} =-80μA	2.4	-	-	V
V _{OH2}	Output High Voltage (For other output pins)	I _{OH} =-30μA	2.4	-	-	V
I _{LI}	Input Leak Current (T1, INT)	V _{SS} ≤V _{IN} ≤V _{CC}	-	-	±10	μA
I _{LI1}	Input Leak Current (P10-17, P20-P27, EA, SS)	V _{SS} +0.45≤V _{IN} ≤V _{CC}	-	-	-700	μA
I _{LO}	Output Leak Current (BUS, TO) (High impedance condition)	V _{SS} +0.45≤V _{IN} ≤V _{CC}	-	-	±10	μA
I _{DD}	V _{DD} Supply Current		-	-	50	mA
I _{DD} +I _{CC}	Total Supply Current		-	-	170	mA



INTEGRATED CIRCUIT

TECHNICAL DATA

TMP8049P/8049P-6/8049PI-6

TMP8039P/8039P-6/8039PI-6

AC CHARACTERISTICS

TA=-40°C to 85°C, VCC=VDD=+5V±10%, VSS=0V, Unless otherwise Noted.

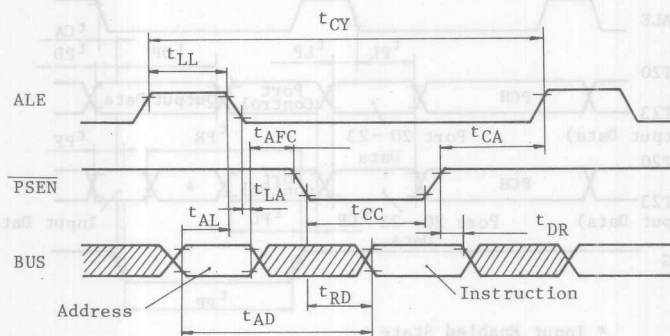
SYMBOL	PARAMETER	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
t _{LL}	ALE Pulse Width		200	-	-	ns
t _{AL}	Address Setup Time (ALE)		120	-	-	ns
t _{LA}	Address Hold Time (ALE)		80	-	-	ns
t _{CC}	Control Pulse Width(PSEN, RD, WR)		400	-	-	ns
t _{DW}	Data Setup Time (WR)		420	-	-	ns
t _{WD}	Data Hold Time (WR)	C _L =20pF	80	-	-	ns
t _{CY}	Cycle Time		2.5	-	15.0	μs
t _{DR}	Data Hold Time (PSEN, RD)		0	-	200	ns
t _{RD}	Data Input Read Time (PSEN, RD)		-	-	400	ns
t _{AW}	Address Setup Time (WR)		230	-	-	ns
t _{AD}	Address Setup Time (Data Input)		-	-	600	ns
t _{AFC}	Address Float Time (RD, PSEN)		-40	-	-	ns
t _{CA}	Internal between Control Pulse and ALE		10	-	-	ns
t _{CP}	Port Control Setup Time (PROG)		115	-	-	ns
t _{PC}	Port Control Hold Time (PROG)		65	-	-	ns
t _{PR}	Port 2 Input Data Set Time (PROG)		-	-	860	ns
t _{DP}	Output Data Setup Time (PROG)		230	-	-	ns
t _{PD}	Output Data Hold Time (PROG)		25	-	-	ns
t _{PF}	Port 2 Input Data Hold Time (PROG)		0	-	160	ns
t _{PP}	PROG Pulse Width		920	-	-	ns
t _{PL}	Port 2 I/O Data Setup Time		300	-	-	ns
t _{LP}	Port 2 I/O Data Hold Time		120	-	-	ns

Note : t_{cy}=2.5μs, Control Output: C_L=80pF, BUS Output: C_L=150pF, PORT 20-23:

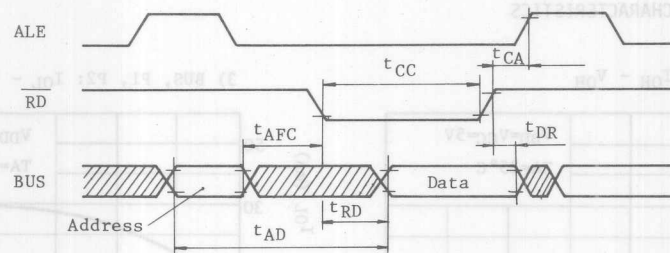
C_L=80pF.

TIMING WAVEFORM

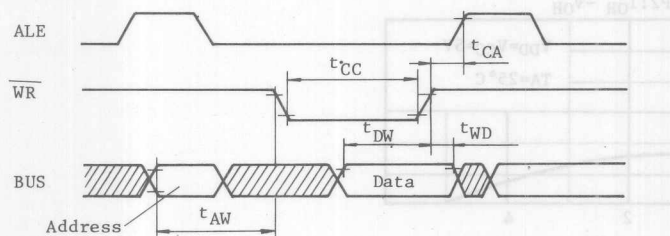
A. Instruction Fetch from External Program Memory



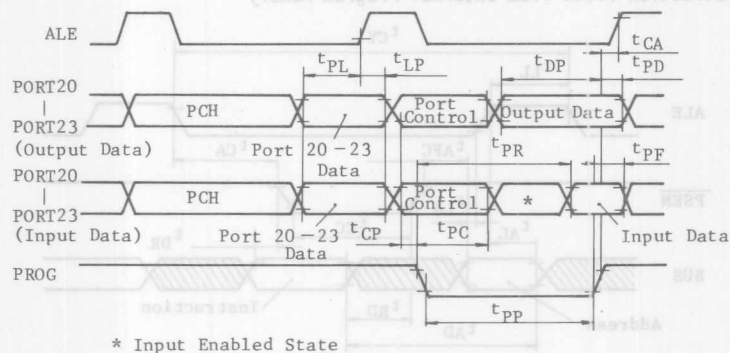
B. Read from External Data Memory



C. Write into External Data Memory

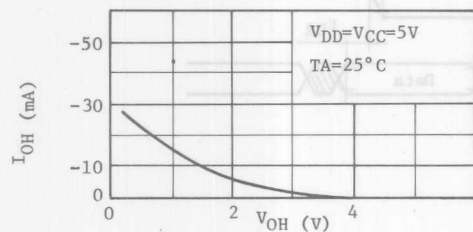


D. Timing of Port 2 during Expander Instruction Execution

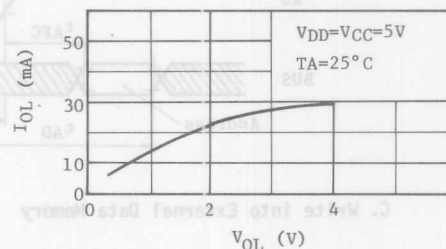


TYPICAL CHARACTERISTICS

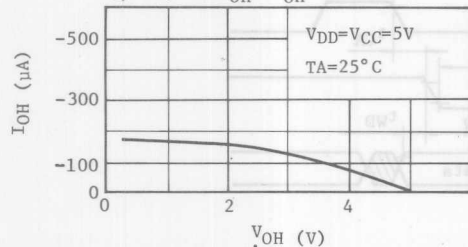
1) BUS: $I_{OH} - V_{OH}$



3) BUS, P1, P2: $I_{OL} - V_{OL}$



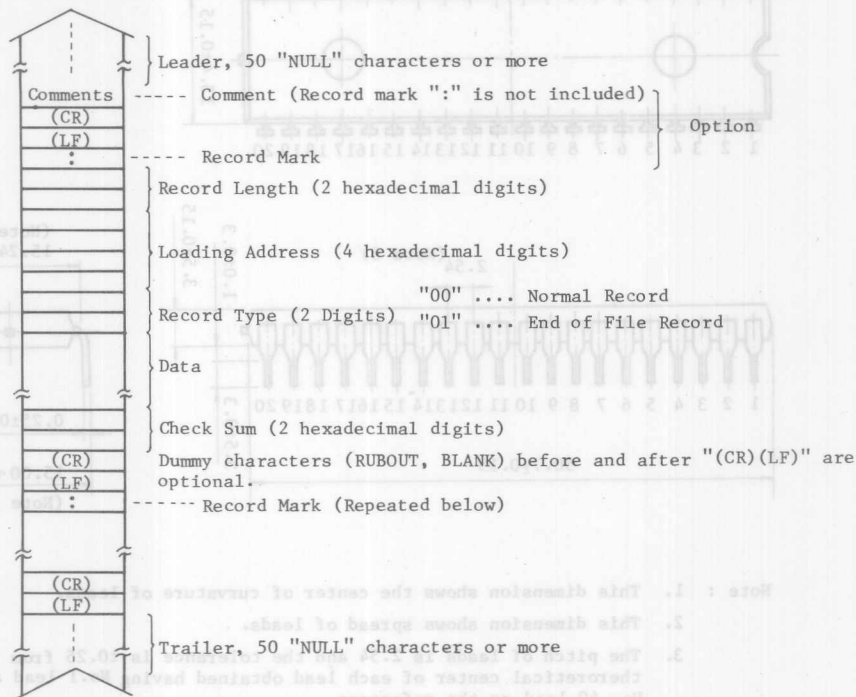
2) P1, P2: $I_{OH} - V_{OH}$



PROGRAM TAPE FORMAT

TMP8049 programs are delivered in the form of paper tape with the following format and it is required to attach the tape list. The format of paper tape is same as the Intel type object tape (hexadecimal tape output by Intel MDS system, PROMPT 48 Development Tool, etc.)

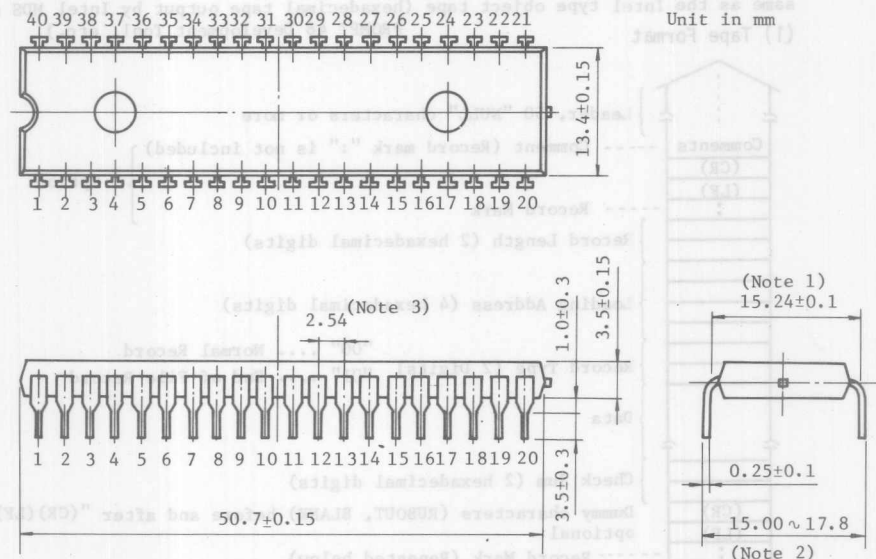
(1) Tape Format



(2) Example of Tape List

TOSHIBA MICRO COMPUTER TLCS-84
:100000000665C7D79CF50F3F951FED55A8FF16E570
:1000100088884DDE67D31F5D8ABA6DF292F113F5C1
:100020004FF1FB5DFDDAA96A99CF7DF94A346B7C09
:10003000197352F729F12F79AA9C057C5B851EED77
:
:
:
:1003C0005DFDB5E556A67277F61A51C631CF9F0E80
:1003D000BD2F6F20E8BB1977E3FB5AD1F41FDA7E2
:1003E000B53D42E0EC32546025B7308CDD52063D1D
:1003F000B4BE9E9E345B6138060B20VC372BF60BD6
.:00000001FF

OUTLINE DRAWING



- Note :
1. This dimension shows the center of curvature of leads.
 2. This dimension shows spread of leads.
 3. The pitch of leads is 2.54 and the tolerance is ± 0.25 from the theoretical center of each lead obtained having No.1 lead and No. 40 lead as the reference.

Note : Toshiba does not assume any responsibility for use of any circuitry described; no circuit patent licenses are implied, and Toshiba reserves the right, at any time without notice, to change said circuitry.



INTEGRATED CIRCUIT

TECHNICAL DATA

TOSHIBA MOS DIGITAL INTEGRATED CIRCUIT

TMP8243P/TMP8243PI

N-CHANNEL SILICON GATE MOS

INPUT/OUTPUT EXPANDER

GENERAL DESCRIPTION

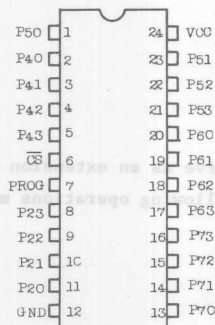
The TMP8243P is an input/output expander designed specifically to provide a low cost means of I/O expansion for the TLCS-84 family.

The I/O ports of the TMP8243P serve as a direct extension of the resident I/O facilities of the TLCS-84 microcomputers and are accessed by their own MOVD, ANLD, and ORLD instructions.

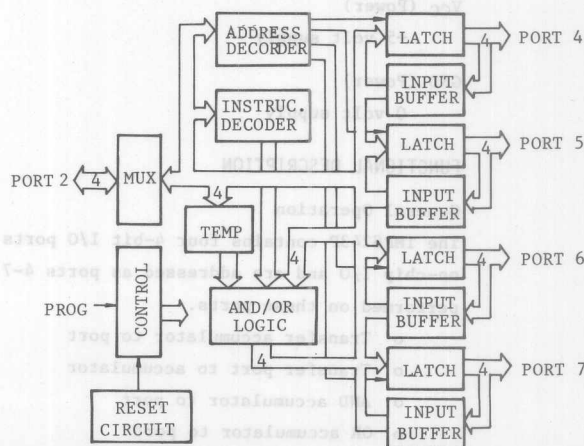
FEATURES

- o Low cost
- o Simple interface to TLCS-84 microcomputers
- o Four 4-bit I/O ports
- o AND and OR directly to ports
- o Single 5V supply
- o High output drive
- o Direct extension of resident TMP8048P/TMP8049P I/O ports.
- o Compatible with intel's 8243
- o -40°C to +85°C Operation (TMP8243PI: Industrial Specification)

PIN CONNECTION (TOP VIEW)



BLOCK DIAGRAM





PIN NAMES AND PIN DESCRIPTION

PROG (Input)

Clock Input. A high to low transition on PROG signifies that address and control are available on P20-23, and a low to high transition signifies that data is available on P20-23.

 $\overline{\text{CS}}$ (Input)

Chip Select Input. A high on CS inhibits any change of output or internal status.

P20-23 (Input/Output, 3-state)

Four (4) bit bi-directional port contains the address and control bits on a high to low transition of PROG. During a low to high transition contains the data for a selected output port if a write operation, or the data from a selected port before the low to high transition if a read operation.

P40-43, P50-53, P60-63, P70-73 (Input/Output, 3-state)

Four (4) bit bi-directional I/O ports. May be programmed to be input (during read), low impedance latched output (after write) or a 3-state (after read). Data on pins P20-23 may be directly written, ANDed or ORed with previous data.

VCC (Power)

+5 volt supply

GND (Power)

0 volt supply

FUNCTIONAL DESCRIPTION

General Operation

The TMP8243P contains four 4-bit I/O ports which serve as an extension of the on-chip I/O and are addressed as ports 4-7. The following operations may be performed on these ports.

- o Transfer accumulator to port
- o Transfer port to accumulator
- o AND accumulator to port
- o OR accumulator to port

All communication between the TMP8048P and the TMP8243P occurs over Port 2 (P20-23) with timing provided by an output pulse on the PROG pin of the processor. Each transfer consists of two 4-bit nibbles.

A high to low transition of the PROG line indicates that address is present while a low to high transition indicates the presence of data. Additional TMP8243P'S may be added to the 4-bit bus and chip selected using additional output lines from the TMP8048P/8035P.

Power On Initialization

Initial application of power to the device forces input/output ports 4, 5, 6, and 7 to the tri-state and port 2 to the input mode. The PROG pin may be either high or low when power is applied. The first high to low transition of PROG causes device to exit power on mode. The power on sequence is initiated if VCC drops below 1V.

P21	P20	Address Code	P23	P22	Instruction Code
0	0	Port 4	0	0	Read
0	1	Port 5	0	1	Write
1	0	Port 6	1	0	ORLD
1	1	Port 7	1	1	ANLD

Write Modes

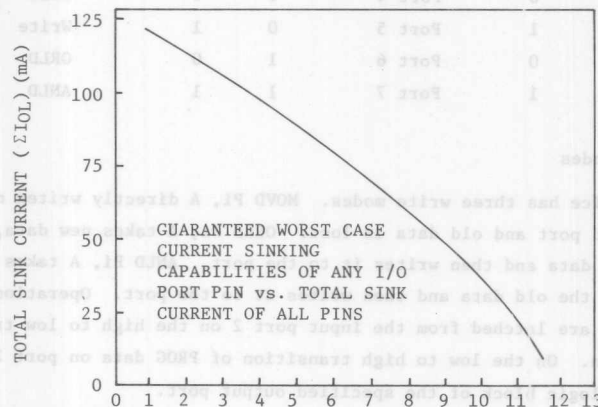
The device has three write modes. MOVD Pi, A directly writes new data into the selected port and old data is lost. ORLD Pi, A takes new data, OR's it with the old data and then writes it to the port. ANLD Pi, A takes new data AND's it with the old data and then writes it to the port. Operation code and port address are latched from the input port 2 on the high to low transition of the PROG pin. On the low to high transition of PROG data on port 2 is transferred to the logic block of the specified output port.

After the logic manipulation is performed, the data is latched and outputted. The old data remains latched until new valid outputs are entered.

Read Mode

The device has one read mode. The operation code and port address are latched from the input port 2 on the high to low transition of the PROG pin. As soon as the read operation and port address are decoded, the appropriate outputs are 3-stated, and the input buffers switched on. The read operation is terminated by a low to high transition of the PROG pin. The port (4, 5, 6 or 7) that was selected is switched to the 3-stated mode while port 2 is returned to the input mode.

Normally, a port will be in an output (write mode) or input (read mode). If modes are changed during operation, the first read following a write should be ignored; all following reads are valid. This is to allow the external driver on the port to settle after the first read instruction removes the low impedance drive from the TMP8243P output. A read of any port will leave that port in a high impedance state.



MAXIMUM SINK CURRENT ON ANY PIN@.45V
MAXIMUM IOL WORST CASE PIN(mA)



Sink Capability

The TMP8243P can sink 5 mA@.45V on each of its 16 I/O lines simultaneously. If, however, all lines are not sinking simultaneously or all lines are not fully loaded, the drive capability of any individual line increases as is shown by the accompanying curve.

For example, if only 5 of the 16 lines are to sink current at one time, the curve shows that each of those 5 lines is capable of sinking 9 mA@.45V (if any lines are to sink 9 mA the total IOL must not exceed 45 mA or five 9 mA loads).

Example: How many pins can drive 5 TTL loads (1.6 mA) assuming remaining pins are unloaded?

$$I_{OL} = 5 \times 1.6 \text{ mA} = 8 \text{ mA}$$

$$\epsilon I_{OL} = 60 \text{ mA from curve}$$

$$\# \text{pins} = 60 \text{ mA} \div 8 \text{ mA/pin} = 7.5 = 7$$

In this case, 7 lines can sink 8 mA for a total of 56 mA. This leaves 4 mA sink current capability which can be divided in any way among the remaining 9 I/O lines of the TMP8243P.

Example: This examples shows now the use of the 20 mA sink capability of port 7 affects the sinking capability of the other I/O lines.

An TMP8243P will drive the following loads simultaneously.

2 loads - 20 mA@1V (port 7 only)

8 loads - 4 mA@.45V

6 loads - 3.2 mA@.45V

Is this within the specified limits?

$\epsilon I_{OL} = (2 \times 20) + (8 \times 4) + (6 \times 3.2) = 91.2 \text{ mA}$. From the curve: for $I_{OL} = 4 \text{ mA}$, $\epsilon I_{OL} = 93 \text{ mA}$ since $91.2 \text{ mA} < 93 \text{ mA}$ the loads are within specified limits.

Although the 20 mA@1V load are used in calculating ϵI_{OL} , it is the largest current required @.45V which determines the maximum allowable ϵI_{OL} .

TMP8243P

ABSOLUTE MAXIMUM RATINGS

Symbol	Item	Rating
V _{CC}	V _{CC} Supply Voltage with Respect to GND	-0.5V to +7.0V
V _{IN}	Input Voltage with Respect to GND	-0.5V to +7.0V
V _{OUT}	Output Voltage with Respect to GND	-0.5V to +7.0V
P _D	Power Dissipation	800mW
T _{SOLDER}	Soldering Temperature (Soldering Time 10 sec.)	260°C
T _{STG}	Storage Temperature	-55°C to +150°C
T _{OPR}	Operating Temperature	0°C to +70°C

D.C. CHARACTERISTICS T_A = 0°C to 70°C, V_{CC} = 5V ± 10%

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
V _{IL}	Input Low Voltage		-0.5		0.8	V
V _{IH}	Input High Voltage		2.0		V _{CC} + 0.5	V
V _{OL1}	Output Low Voltage Ports 4-7	I _{OL} = 5mA*			0.45	V
V _{OL2}	Output Low Voltage Port 7	I _{OL} = 20mA			1	V
V _{OL3}	Output Low Voltage Port 2	I _{OL} = 0.6mA			0.45	V
V _{OH1}	Output High Voltage Ports 4-7	I _{OH} = -240μA	2.4			V
V _{OH2}	Output High Voltage Port 2	I _{OH} = -100μA	2.4			V
I _{IL1}	Input Leakage Port 4-7	0V ≤ V _{IN} ≤ V _{CC}	-10		20	μA
I _{IL2}	Input Leakage Port 2, \overline{CS} , PROG	0V ≤ V _{IN} ≤ V _{CC}	-10		10	μA
I _{CC}	V _{CC} Supply Current			10	20	mA
I _{OL}	Sum of all I _{OL} of 16 Outputs	5 mA Each Pin			80	mA

* See following graph for additional sink current capability

A.C. CHARACTERISTICS T_A = 0°C to 70°C, V_{CC} = 5V ± 10%

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
t _A	Code Valid Before PROG	C _L = 80pF	100			ns
t _B	Code Valid After PROG	C _L = 20pF	60			ns
t _C	Data Valid Before PROG	C _L = 80pF	200			ns
t _D	Data Valid After PROG	C _L = 20pF	20			ns
t _H	Floating After PROG	C _L = 20pF	0		150	ns
t _K	PROG Negative Pulse Width		700			ns
t _{CS}	\overline{CS} Valid Before/After PROG		50			ns
t _{PO}	Ports 4-7 Valid After PROG	C _L = 100pF			700	ns
t _{LPI}	Ports 4-7 Valid Before/After PROG		100			ns
t _{ACC}	Port 2 Valid After PROG	C _L = 80pF			650	ns

TMP8243PI : INDUSTRIAL SPECIFICATION

ABSOLUTE MAXIMUM RATINGS

Symbol	Item	Rating
V_{CC}	V_{CC} Supply Voltage with Respect to GND	-0.5V to +7.0V
V_{IN}	Input Voltage with Respect to GND	-0.5V to +7.0V
V_{OUT}	Output Voltage with Respect to GND	-0.5V to +7.0V
P_D	Power Dissipation	800mW
T_{SOLDER}	Soldering Temperature (Soldering Time 10 sec.)	260°C
T_{STG}	Storage Temperature	-55°C to +150°C
T_{OPR}	Operating Temperature	-40°C to +85°C

D.C. CHARACTERISTICS $T_A = -40^\circ\text{C}$ to 85°C , $V_{CC} = 5V \pm 10\%$

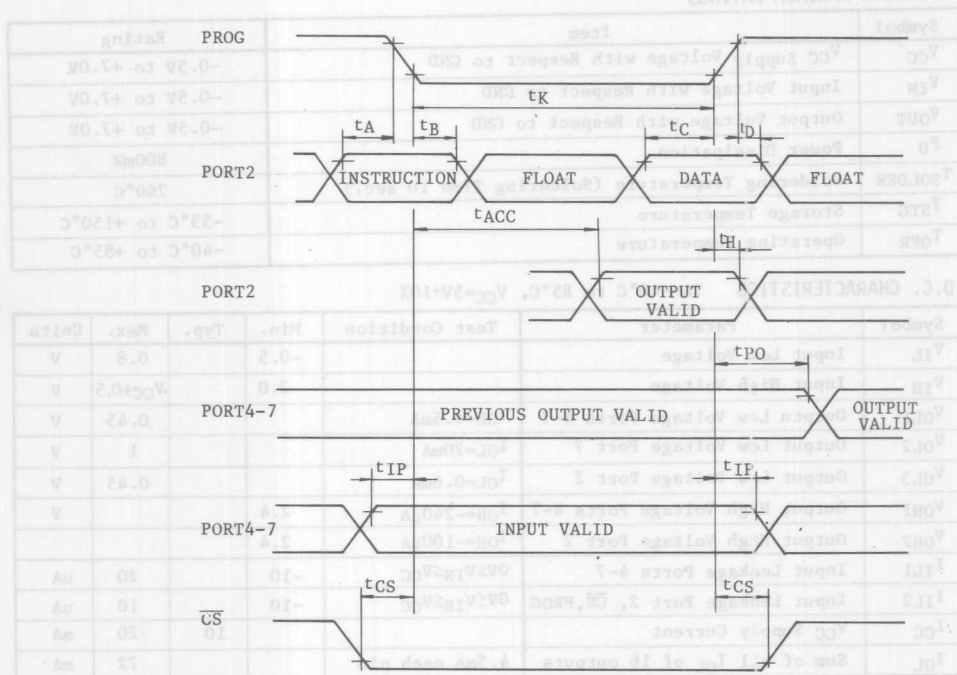
Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
V_{IL}	Input Low Voltage		-0.5		0.8	V
V_{IH}	Input High Voltage		2.0		$V_{CC} + 0.5$	V
V_{OL1}	Output Low Voltage Ports 4-7	$I_{OL} = 4.5\text{mA}$			0.45	V
V_{OL2}	Output Low Voltage Port 7	$I_{OL} = 20\text{mA}$			1	V
V_{OL3}	Output Low Voltage Port 2	$I_{OL} = 0.6\text{mA}$			0.45	V
V_{OH1}	Output High Voltage Ports 4-7	$I_{OH} = -240\mu\text{A}$	2.4			V
V_{OH2}	Output High Voltage Port 2	$I_{OH} = -100\mu\text{A}$	2.4			V
I_{IL1}	Input Leakage Ports 4-7	$0V \leq V_{IN} \leq V_{CC}$	-10		20	μA
I_{IL2}	Input Leakage Port 2, \overline{CS} , PROG	$0V \leq V_{IN} \leq V_{CC}$	-10		10	μA
I_{CC}	V_{CC} Supply Current			10	20	mA
I_{OL}	Sum of all I_{OL} of 16 outputs	4.5mA each pin			72	mA

* See following graph for additional sink current capability

A.C. CHARACTERISTICS $T_A = -40^\circ\text{C}$ to 85°C , $V_{CC} = 5V \pm 10\%$

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
t_A	Code Valid before PROG	$C_L = 80\text{pF}$	100			ns
t_B	Code Valid after PROG	$C_L = 20\text{pF}$	60			ns
t_C	Data Valid before PROG	$C_L = 80\text{pF}$	200			ns
t_D	Data Valid after PROG	$C_L = 20\text{pF}$	20			ns
t_H	Floating after PROG	$C_L = 20\text{pF}$	0		150	ns
t_K	PROG Negative Pulse Width		700			ns
t_{CS}	\overline{CS} Valid before/after PROG		50			ns
t_{PO}	Ports 4-7 Valid after PROG	$C_L = 100\text{pF}$			700	ns
t_{LP1}	Ports 4-7 Valid before/after PROG		100			ns
t_{ACC}	Port 2 Valid after PROG	$C_L = 80\text{pF}$			650	ns

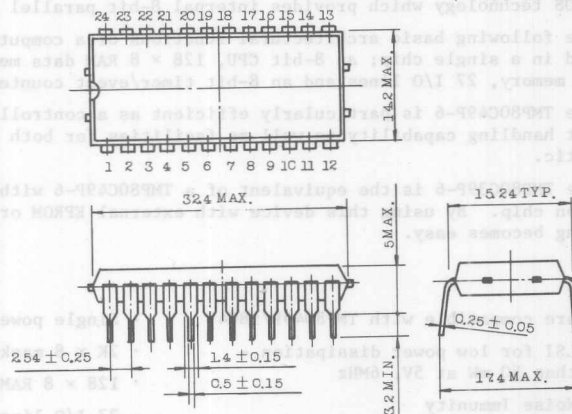
TIMING WAVEFORM



Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
t_A	Code Valid before PROG	$C_L = 80pF$	100			ns
t_B	Code Valid after PROG	$C_L = 80pF$	50			ns
t_C	Data Valid before PROG	$C_L = 80pF$	200			ns
t_D	Data Valid after PROG	$C_L = 80pF$	50			ns
t_E	Floating after PROG	$C_L = 80pF$	0		120	ns
t_F	PROG Negative Pulse Width		200			ns
t_G	CS Valid before/after PROG		50			ns
t_H	Port 4-7 Valid after PROG	$C_L = 100pF$		200		ns
t_I	Port 4-7 Valid before/after PROG		100			ns
t_J	Port 2 Valid after PROG	$C_L = 80pF$			820	ns

OUTLINE DRAWINGS

Unit in mm



Note: Each lead pitch is 2.54mm. All leads are located within 0.25mm of their true longitudinal position with respect to No.1 and No.24 leads.

All dimensions are in millimeters.



INTEGRATED CIRCUIT

TECHNICAL DATA

TOSHIBA MOS TYPE DIGITAL
INTEGRATED CIRCUIT
TMP80C49P-6, TMP80C39P-6
Silicon Monolithic
CMOS Silicon Gate

PRELIMINARY

8-BIT SINGLE-CHIP MICROCOMPUTER

GENERAL DESCRIPTION

The TMP80C49P-6 is a single chip microcomputer fabricated in Silicon Gate CMOS technology which provides internal 8-bit parallel architecture.

The following basic architectural functions of a computer have been included in a single chip; an 8-bit CPU, 128×8 RAM data memory, $2K \times 8$ ROM program memory, 27 I/O lines and an 8-bit timer/event counter.

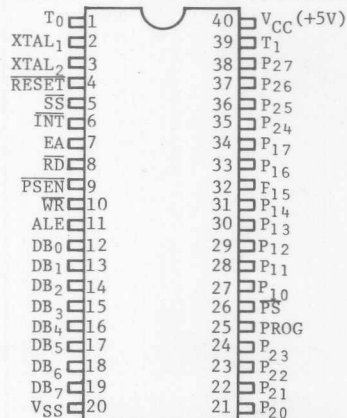
The TMP80C49P-6 is particularly efficient as a controller. It has extensive bit handling capability as well as facilities for both binary and BCD arithmetic.

The TMP80C39P-6 is the equivalent of a TMP80C49P-6 without ROM program memory on chip. By using this device with external EPROM or RAM, software debugging becomes easy.

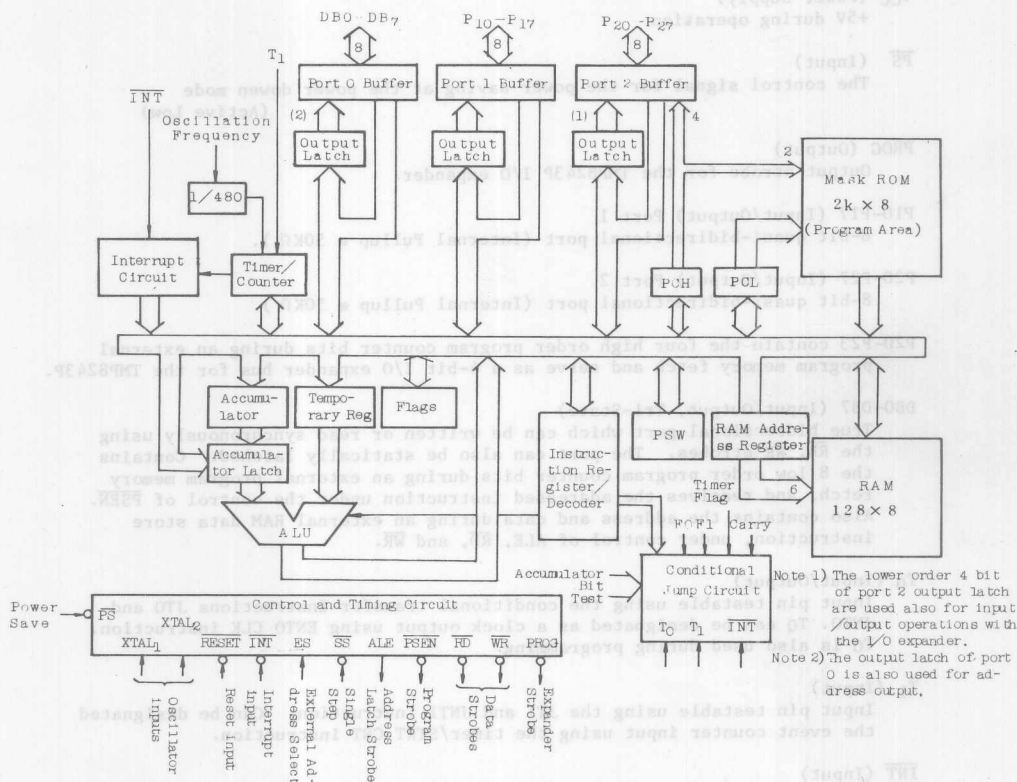
FEATURES

- Software compatible with TMP8049P/18049
- CMOS/LSI for low power dissipation - less than 50 mW at 5V, 6MHz
- High Noise Immunity
- 2.5μs Instruction Cycle
- Extended temperature operation: -40°C to +85°C
- Single power supply
- $2K \times 8$ masked ROM
- 128×8 RAM
- 27 I/O lines
- Interval Timer/Event Counter
- Power Down Mode

PIN CONNECTIONS (TOP VIEW)



BLOCK DIAGRAM



Note 1) The lower order 4 bit of port 2 output latch are used also for input/output operations with the I/O expander.

Note 2) The output latch of port 0 is also used for address output.



INTEGRATED CIRCUIT

TECHNICAL DATA

TMP80C49P-6

TMP80C39P-6

PRELIMINARY

PIN NAMES AND PIN DESCRIPTION

VSS (Power Supply)
Circuit GND potential

VCC (Power Supply)
+5V during operation

\overline{PS} (Input)
The control signal for the power saving at the power down mode
(Active Low)

PROG (Output)
Output strobe for the TMP8243P I/O expander.

P10-P17 (Input/Output) Port 1
8-bit quasi-bidirectional port (Internal Pullup $\approx 50k\Omega$).

P20-P27 (Input/Output) Port 2
8-bit quasi-bidirectional port (Internal Pullup $\approx 50k\Omega$).

P20-P23 contain the four high order program counter bits during an external program memory fetch and serve as a 4-bit I/O expander bus for the TMP8243P.

DB0-DB7 (Input/Output, Tri-State)
True bidirectional port which can be written or read synchronously using the \overline{RD} , \overline{WR} strobes. The port can also be statically latched. Contains the 8 low order program counter bits during an external program memory fetch, and receives the addressed instruction under the control of \overline{PSEN} . Also contains the address and data during an external RAM data store instruction, under control of ALE, \overline{RD} , and \overline{WR} .

T₀ (Input/Output)
Input pin testable using the conditional transfer instructions JTO and JNTO. T₀ can be designated as a clock output using ENT0 CLK instruction. T₀ is also used during programming.

T₁ (Input)
Input pin testable using the JTI and JNTI instruction. Can be designated the event counter input using the timer/STRT CNT instruction.

\overline{INT} (Input)
External interrupt input. Initiates an interrupt if interrupt is enabled. Interrupt is disabled after a reset. Also testable with conditional jump instruction. (Active low)

\overline{RD} (Output)
Output strobe activated during a Bus read. Can be used to enable data onto the Bus from an external device. Used as a Read Strobe to External Data Memory (Active Low).



INTEGRATED CIRCUIT

TECHNICAL DATA

INTEGRATED CIRCUIT
TMP80C49P-6
TECHNICAL DATA
TMP80C39P-6

PRELIMINARY

\overline{WR} (Output)

Output strobe during a Bus write (Active Low). Used as a Write Strobe to External Data Memory.

RESET (Input)

Active Low signal which is used to initialize the Processor. Also used during the power down mode.

ALE (Output)

Address Latch Enable. This signal occurs once during each cycle and is useful as a clock output. The negative edge of ALE strobes address into external data and program memory.

PSEN (Output)

Program Store Enable. This output occurs only during a fetch to external program memory (Active Low).

SYMBOL	PARAMETER	TEST CONDITIONS	MIN.	MAX.	UNITS
V_{CC}	V _{CC} Supply Voltage (with respect to GND (V _{SS}))		-0.5V	+7V	V
V_{IH}	Input Voltage (Except EA)		-0.5V		V
V_{OL}	Output Low Voltage			0.4V	V
V_{OH}	Output High Voltage		2.4V		V
I_{IL}	Input Low Current (T ₁ , T ₂ , RA, PS)		-25 μ A		μ A
I_{IH}	Input High Current (RES, RESET)		-25 μ A		μ A
I_{OL}	Output Low Current (BUS, IO) (High impedance condition)		-25 μ A		μ A
I_{OH}	Output High Current (BUS, IO)		25 μ A		μ A
I_{CS}	V _{CC} Supply Current			10 mA	mA
V_{DD1}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD2}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD3}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD4}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD5}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD6}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD7}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD8}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD9}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD10}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD11}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD12}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD13}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD14}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD15}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD16}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD17}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD18}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD19}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD20}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD21}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD22}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD23}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD24}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD25}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD26}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD27}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD28}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD29}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD30}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD31}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD32}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD33}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD34}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD35}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD36}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD37}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD38}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD39}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD40}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD41}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD42}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD43}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD44}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD45}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD46}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD47}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD48}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD49}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD50}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD51}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD52}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD53}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD54}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD55}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD56}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD57}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD58}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD59}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD60}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD61}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD62}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD63}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD64}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD65}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD66}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD67}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD68}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD69}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD70}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD71}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD72}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD73}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD74}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD75}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD76}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD77}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD78}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD79}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD80}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD81}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD82}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD83}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD84}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD85}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD86}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD87}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD88}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD89}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD90}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD91}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD92}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD93}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD94}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD95}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD96}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD97}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD98}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD99}	Output High Voltage (P10-P17, P20-P27)		2.4V		V
V_{DD100}	Output High Voltage (P10-P17, P20-P27)		2.4V		V



INTEGRATEDCIRCUIT

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TECHNICAL DATA

TMP80C49P-6

TMP80C39P-6

PRELIMINARY

ABSOLUTE MAXIMUM RATINGS

SYMBOL	ITEM	RATING
V_{CC}	V_{CC} Supply Voltage (with respect to GND (V_{SS}))	-0.5V to +7V
V_{INA}	Input Voltage (Except EA)	-0.5V to $V_{CC}+0.5V$
V_{INB}	Input Voltage (Only EA)	-0.5V to +13V
P_D	Power Dissipation ($T_a=85^\circ C$)	250mW
T_{SOLDER}	Soldering Temperature (Soldering Time 10 sec)	260°C
T_{STG}	Storage Temperature	-65°C to 150°C
T_{OPR}	Operating Temperature	-40°C to 85°C

DC CHARACTERISTICS (I)

$T_{OPR}=-40^\circ C$ to $85^\circ C$, $V_{CC}=+5V \pm 10\%$, $V_{SS}=0V$, Unless Otherwise Noted.

SYMBOL	PARAMETER	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
V_{IL}	Input Low Voltage		-0.5	-	0.8	V
V_{IH}	Input High Voltage (Except XTAL1, XTAL2, RESET)		2.2	-	V_{CC}	V
V_{IH1}	Input High Voltage (XTAL1, XTAL2, RESET)		3.3	-	V_{CC}	V
V_{OL}	Output Low Voltage (Except P10-P17, P20-P27)	$I_{OL}=1.6mA$	-	-	0.45	V
V_{OL1}	Output Low Voltage (P10-P17, P20-P27)	$I_{OL}=1.2mA$	-	-	0.45	V
V_{OH11}	Output High Voltage (Except P10-P17, P20-P27)	$I_{OH}=-1.6mA$	2.4	-	-	V
V_{OH12}	Output High Voltage (Except P10-P17, P20-P27)	$I_{OH}=-400\mu A$	V_{CC} -0.8	-	-	V
V_{OH21}	Output High Voltage (P10-P17, P20-P27)	$I_{OH}=-50\mu A$	2.4	-	-	V
V_{OH22}	Output High Voltage (P10-P17, P20-P27)	$I_{OH}=-25\mu A$	V_{CC} -0.8	-	-	V
I_{LI}	Input Leak Current (T1, INT, EA, PS)	$V_{SS} \leq V_{IN} \leq V_{CC}$	-	-	± 10	μA
I_{LI1}	Input Leak Current (SS, RESET)	$V_{SS} \leq V_{IN} \leq V_{CC}$	-	-	-50	μA
I_{LI2}	Input Leak Current (P10-17, P20-27)	$V_{SS}+0.45V \leq V_{IN} \leq V_{CC}$	-	-	-500	μA
I_{LO}	Output Leak Current (BUS, TO) (High impedance condition)	$V_{SS}+0.45V \leq V_{IN} \leq V_{CC}$	-	-	± 10	μA
I_{CC}	V_{CC} Supply Current	$V_{CC}=5V$, $f_{XTAL}=6MHz$ $V_{IH}=V_{CC}-0.2V$, $V_{IL}=0.2V$, $C_{X2}=0pF$	-	-	10	mA



INTEGRATEDCIRCUIT

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TECHNICAL DATA

TMP80C49P-6

TMP80C39P-6

TECHNICAL DATA

PRELIMINARY

DC CHARACTERISTICS (II)

 $T_{OPR} = -40^{\circ}\text{C}$ to 85°C , $V_{CC} = +5\text{V} \pm 20\%$, $V_{SS} = 0\text{V}$, Unless Otherwise Noted.

SYMBOL	PARAMETER	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
V_{IL}	Input Low Voltage		-0.5	-	$0.15 V_{CC}$	V
V_{IH}	Input High Voltage (Except XTAL1, XTAL2, RESET)		$0.5 V_{CC}$	-	V_{CC}	V
V_{IH1}	Input High Voltage (XTAL1, XTAL2, RESET)		$0.7 V_{CC}$	-	V_{CC}	V
V_{OL}	Output Low Voltage (Except P10-P17, P20-P27)	$I_{OL} = 1.6\text{mA}$	-	-	0.45	V
V_{OL1}	Output Low Voltage (P10-P17, P20-P27)	$I_{OL} = 1.2\text{mA}$	-	-	0.45	V
V_{OH12}	Output High Voltage (Except P10-P17, P20-P27)	$I_{OH} = -400\mu\text{A}$	V_{CC} -0.8	-	-	V
V_{OH22}	Output High Voltage (P10-P17, P20-P27)	$I_{OH} = -25\mu\text{A}$	V_{CC} -0.8	-	-	V
I_{LI}	Input Leak Current (T1, INT, EA, PS)	$V_{SS} \leq V_{IN} \leq V_{CC}$	-	-	± 10	μA
I_{LI1}	Input Leak Current (SS, RESET)	$V_{SS} \leq V_{IN} \leq V_{CC}$	-	-	$\frac{V_{CC}}{0.1}$	μA
I_{LI2}	Input Leak Current (P10-17, P20-P27)	$V_{SS} + 0.45\text{V} \leq V_{IN} \leq V_{CC}$	-	-	$\frac{V_{CC}}{0.01}$	μA
I_{LO}	Output Leak Current (BUS, TO) (High impedance condition)	$V_{SS} + 0.45\text{V} \leq V_{IN} \leq V_{CC}$	-	-	± 10	μA
I_{CC}	V_{CC} Supply Current	$V_{CC} = 5\text{V}$, $f_{XTAL} = 6\text{MHz}$ $V_{IH} = V_{CC} - 0.2\text{V}$, $V_{IL} = 0.2\text{V}$, $C_{X2} = 0\text{pF}$	-	-	10	mA



INTEGRATED CIRCUIT

TECHNICAL DATA

TMP80C49P-6

TMP80C39P-6

PRELIMINARY

AC CHARACTERISTICS

 $T_{OPR} = -40^{\circ}\text{C to } 85^{\circ}\text{C}$, $V_{CC} = +5\text{V} \pm 10\%$, $V_{SS} = 0\text{V}$, Unless Otherwise Noted.

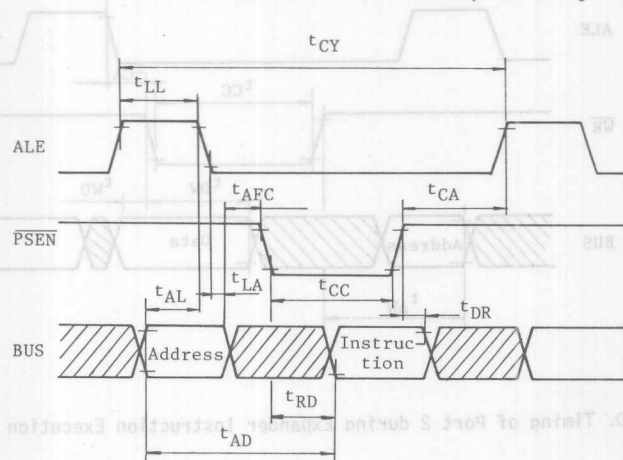
SYMBOL	PARAMETER	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
t_{LL}	ALE Pulse Width		400	-	-	ns
t_{AL}	Address Setup Time (ALE)		150	-	-	ns
t_{LA}	Address Hold Time (ALE)		80	-	-	ns
t_{CC}	Control Pulse Width ($\overline{\text{PSEN}}$, $\overline{\text{RD}}$, $\overline{\text{WR}}$)		700	-	-	ns
t_{DW}	Data Setup Time ($\overline{\text{WR}}$)		500	-	-	ns
t_{WD}	Data Hold Time ($\overline{\text{WR}}$)	$C_L = 20\text{pF}$	120	-	-	ns
t_{CY}	Cycle Time		2.5	-	15.0	μs
t_{DR}	Data Hold Time ($\overline{\text{PSEN}}$, $\overline{\text{RD}}$)		0	-	200	ns
t_{RD}	Data Input Read Time ($\overline{\text{PSEN}}$, $\overline{\text{RD}}$)		-	-	500	ns
t_{AW}	Address Setup Time ($\overline{\text{WR}}$)		230	-	-	ns
t_{AD}	Address Setup Time (Data Input)		-	-	950	ns
t_{AFC}	Address Float Time ($\overline{\text{RD}}$, $\overline{\text{PSEN}}$)		0	-	-	ns
t_{CP}	Port Control Setup Time (PROG)		110	-	-	ns
t_{PC}	Port Control Hold Time (PROG)		130	-	-	ns
t_{PR}	Port 2 Input Data Set Time (PROG)		-	-	810	ns
t_{DP}	Output Data Setup Time (PROG)		220	-	-	ns
t_{PD}	Output Data Hold Time (PROG)		65	-	-	ns
t_{PF}	Port 2 Input Data Hold Time (PROG)		0	-	150	ns
t_{PP}	PROG Pulse Width		1510	-	-	ns
t_{PL}	Port 2 I/O Data Setup Time		600	-	-	ns
t_{LP}	Port 2 I/O Data Hold Time		150	-	-	ns

 Note : $t_{CY} = 2.5\mu\text{s}$ ($f_X = 6\text{MHz}$)

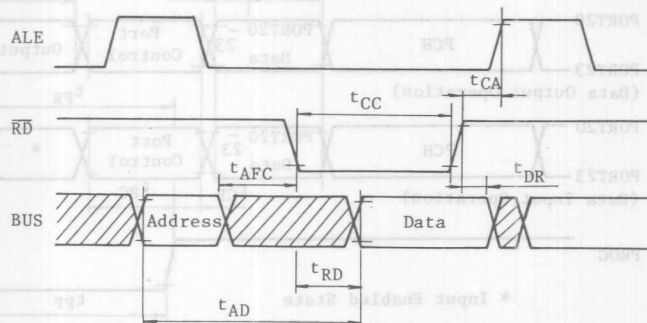
 Control Outputs : $C_L = 80\text{pF}$, BUS Outputs : $C_L = 150\text{pF}$

TIMING WAVEFORM

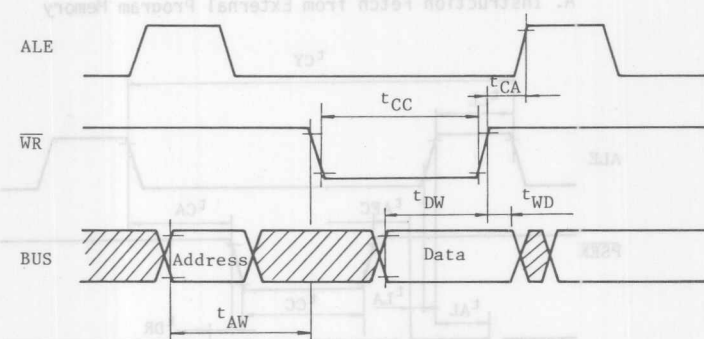
A. Instruction Fetch from External Program Memory



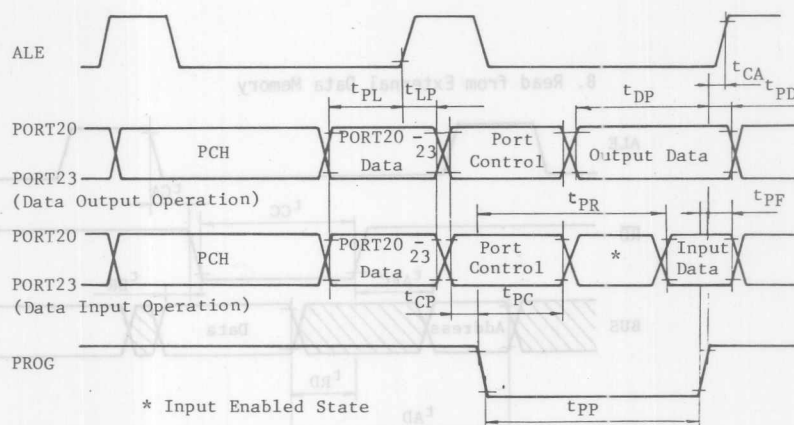
B. Read from External Data Memory



C. Write into External Data Memory



D. Timing of Port 2 during Expander Instruction Execution





INTEGRATEDCIRCUIT

TECHNICAL DATA

TMP80C49P-6

TMP80C39P-6

PRELIMINARY

POWER DOWN MODE (I) ----- Data Hold Mode in RAM -----

The operation of oscillation circuit is suspended by setting \overline{PS} terminal to low level after \overline{RESET} terminal has been set to low level. Consequently, all the data in RAM area can be held in low power consumption.

The minimum hold voltage of V_{CC} in this mode is 2V.

\overline{PS} terminal is set to high level to resume oscillation after V_{CC} has been reset to 5V, and then \overline{RESET} terminal is set to high level, thus, the normal mode is restarted from the initialize operation (address 0).

DC CHARACTERISTICS ($T_{OPR} = -40^{\circ}\text{C}$ to 85°C , $V_{SS} = 0\text{V}$)

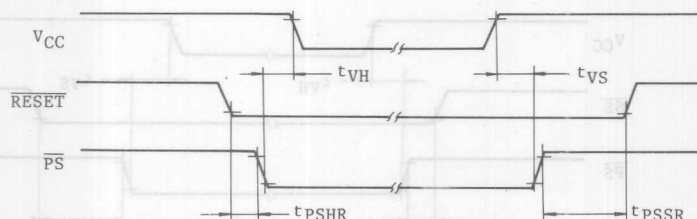
SYMBOL	PARAMETER	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
V_{SB1}	Standby Voltage(1)		2.0	-	6.0	V
I_{SB1}	Standby Current(1)	$V_{CC} = 2\text{V}, V_{IH} = V_{CC} - 0.2\text{V}, V_{IL} = 0.2\text{V}$	-	-	T.B.D.	μA

AC CHARACTERISTICS ($T_{OPR} = -40^{\circ}\text{C}$ to 85°C , $V_{CC} = 5\text{V} \pm 10\%$, $V_{SS} = 0\text{V}$)

SYMBOL	PARAMETER	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
t_{PSHR}	Power Save Hold Time (\overline{RESET})		10	-	-	μS
t_{PSSR}	Power Save Setup Time (\overline{RESET})		10	-	-	mS
t_{VH}	V_{CC} Hold Time (\overline{PS})		5	-	-	μS
t_{VS}	V_{CC} Setup Time (\overline{PS})		5	-	-	μS

Note : $t_{cy} = 2.5\mu\text{s}$ ($f_x = 6\text{MHz}$)

TIMING WAVEFORM





INTEGRATED CIRCUIT

TECHNICAL DATA

TMP80C49P-6

TMP80C39P-6

PRELIMINARY

POWER DOWN MODE (II) ----- All Data Hold Mode

The operation of oscillation circuit is suspended by setting \overline{PS} terminal to low level after \overline{SS} terminal has been set to low level. Consequently, all data can be held in low power consumption.

The minimum hold voltage of V_{CC} in this mode is 3V.

\overline{PS} terminal is set to high level to resume oscillation after V_{CC} has been reset to 5V, and then \overline{SS} terminal is set to high level, thus, the normal mode is restarted continuously from the state just before the power down mode (II).

DC CHARACTERISTICS ($T_{OPR} = -40^{\circ}\text{C}$ to 85°C , $V_{SS} = 0\text{V}$)

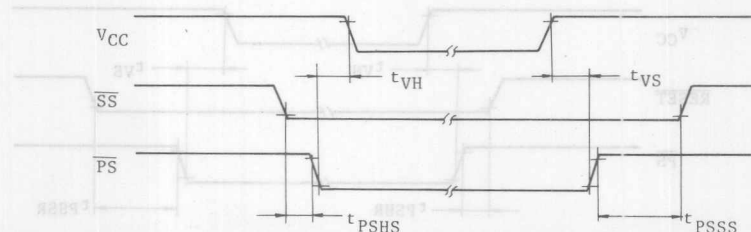
SYMBOL	PARAMETER	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
V_{SB2}	Standby Voltage(2)		3.0	-	6.0	V
I_{SB2}	Standby Current(2)	$V_{CC} = 3\text{V}, V_{IH} = V_{CC} - 0.2\text{V}, V_{IL} = 0.2\text{V}$	-	-	T.B.D.	μA

AC CHARACTERISTICS ($T_{OPR} = -40^{\circ}\text{C}$ to 85°C , $V_{CC} = 5\text{V} \pm 10\%$, $V_{SS} = 0\text{V}$)

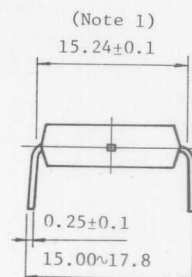
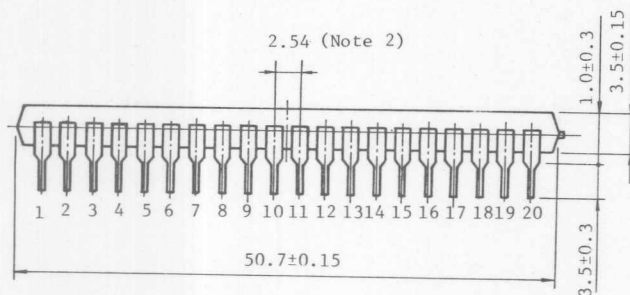
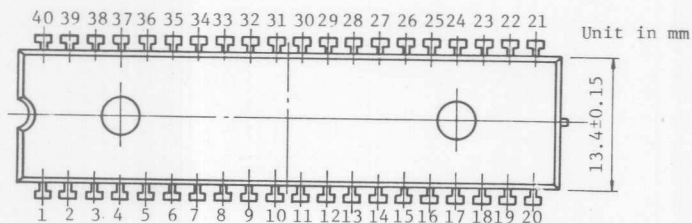
SYMBOL	PARAMETER	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
t_{PSHS}	Power Save Hold Time (\overline{SS})		5	-	-	μS
t_{PSSS}	Power Save Setup Time (\overline{SS})		10	-	-	mS
t_{VH}	V_{CC} Hold Time (\overline{PS})		5	-	-	μS
t_{VS}	V_{CC} Setup Time (\overline{PS})		5	-	-	μS

Note : $t_{CY} = 2.5\mu\text{s}$ ($f_X = 6\text{MHz}$)

TIMING WAVEFORM



OUTLINE DRAWING



- Note : 1. This dimension is measured at the center of bending point of leads
2. Each lead pitch is 2.54mm, and all the leads are located within ± 0.25 mm from their theoretical positions with respect to No.1 and No.42 leads.

8BIT MICROPROCESSOR

TLCS-85A (NMOS)



INTEGRATED CIRCUIT

TECHNICAL DATA

TOSHIBA MOS DIGITAL INTEGRATED CIRCUIT

TMP8085AP

N-CHANNEL SILICON GATE MOS

8-BIT SINGLE CHIP MICROPROCESSOR

GENERAL DESCRIPTION

The TMP8085AP, from here on referred to as the TMP8085A, is a new generation, complete 8 bit parallel central processing unit (CPU). Its instruction set is 100% software compatible with the TMP9080A (8080A) microprocessor, and it is designed to improve the present 9080's performance by higher system speed. Its high level of system integration allows a minimum system of there IC's : TMP8085A (CPU), TMP8155P/TMP8156P (RAM/IO) and TMP8755AC (EPROM/IO)/ TMP8355P (ROM/IO). The TMP8085A uses a multiplexed data bus. The address is split between the 8 bit address bus and the 8 bit data bus. The on-chip address latches of TMP8155P/TMP8156P/TMP8755AC/TMP8355P memory products allow a direct interface with TMP8085P.

FEATURES

- 100% Software Compatible with TMP9080A
- 1.3 s Instruction Cycle
- Single +5V Power Supply
- On-Chip Clock Generator (with External Crystal or RC Network)
- On-Chip System Controller; Advanced Cycle status information available for Large System Control
- 4 Vectored Interrupts (One is Non-Maskable) Plus an TMP9080A compatible interrupt
- Decimal, Binary and Double Precision Arithmetic
- Serial In/Serial Out Port
- Direct Addressing Capability to 64K Bytes of Memory
- Compatible with Intel's 8085A

PIN CONNECTION (TOP VIEW)

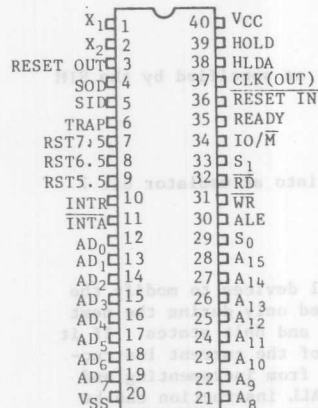


FIGURE 2. TMP8085A PINOUT
DIAGRAM

BLOCK DIAGRAM

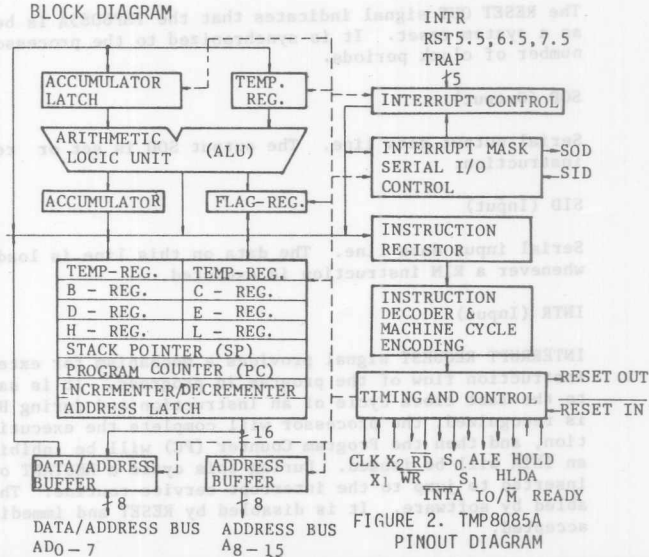


FIGURE 2. TMP8085A
PINOUT DIAGRAM



INTEGRATED CIRCUIT

TECHNICAL DATA

TMP8035AP

TECHNICAL DATA

PIN NAME AND PIN DESCRIPTION

X₁, X₂ (Input)

Crystal, LC, or RC network are connected to X₁ and X₂ to drive the internal clock generator. X₁ and X₂ can also be driven from an externally derived frequency source. The input frequency is divided by 2 to give the processor's internal operating frequency.

CLK (Output)

Clock Output for use as a system clock. The period of CLK is twice the X₁, X₂ input period.

RESET IN (Input)

The RESET Input initialize the processor by clearing the program counter, instruction register, SOD latch, Interrupt Enable flip-flop and HLDA flip-flop. The address and data buses and the control lines are 3-stated during RESET and because of the asynchronous nature of RESET, the processor's internal registers and flags may be altered by RESET with unpredictable results. RESET IN is a Schmitt-triggered input, allowing connection to an RC network for power on RESET delay. The TMP8085A is held in the reset condition as long as RESET IN is applied.

RESET OUT (OUTPUT)

The RESET OUT signal indicates that the TMP8085A is being reset. It can be used as a system reset. It is synchronized to the processor clock and lasts an integral number of clock periods.

SOD (Output)

Serial output data line. The output SOD is set or reset as specified by the SIM instruction.

SID (Input)

Serial input data line. The data on this line is loaded into accumulator bit 7 whenever a RIM instruction is executed.

INTR (Input)

INTERRUPT REQUEST signal provides a mechanism for external devices to modify the instruction flow of the program in progress. It is sampled only during the next to the last clock cycle of an instruction and during Hold and Halt states. If it is recognized, the processor will complete the execution of the current instruction, and then the Program Counter (PC) will be inhibited from incrementing and an INTA will be issued. During this cycle a RESTART or CALL instruction can be inserted to jump to the interrupt service routine. The INTR is enabled and disabled by software. It is disabled by RESET and immediately after an interrupt is accepted.



INTEGRATED CIRCUIT

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TECHNICAL DATA

INTEGRATED CIRCUIT

TMP8085AP

TECHNICAL DATA



INTA (Output)

INTERRUPT ACKNOWLEDGE: Occurs in response to an Interrupt input and indicates that the processor will be ready for an interrupt instruction on the data bus. It is used instead of (and has the same timing as) RD during the instruction cycle after an INTR is accepted.

RST 5.5 }
RST 6.5 } (Inputs)
RST 7.5 }

RESTART INTERRUPTS: These three inputs have the same timing as INTR except they cause an internal RESTART to be automatically inserted. These interrupts have a higher priority than INTR. The priority of these interrupts is ordered as shown Table 1. They may be individually masked out using the SIM instruction.

TRAP (Input)

Trap interrupt is a nonmaskable RESTART interrupt. It is sampled at the same timing as INTR or RST 5.5 - 7.5. It is unaffected by any mask or Interrupt Enable. It has the highest priority of any interrupt.

AD0 - AD7 (Input/Output, 3-state)

Lower 8 bits of the memory address (or I/O address) appear on the bus during the first clock cycle (T₁ state) of a machine cycle. It then becomes the data bus during the second and third clock cycles.

A8 - A15 (Output, 3-state)

The most significant 8 bits of the memory address or the 8 bits of the I/O address, 3-stated during Hold and Halt modes and during RESET.

S0, S1, and IO/M (Output)

Machine cycle status:

IO/M	S1	S0	Status
0	1	1	Opcode fetch
0	1	0	Memory read
0	0	1	Memory write
1	1	0	I/O read
1	0	1	I/O write
1	1	1	Interrupt Acknowledge
TS	0	0	Halt
TS	X	X	Hold
TS	X	X	Reset

Note: TS = 3-state (high impedance)

X = unspecified

TOSHIBA CORPORATION

351



INTEGRATED CIRCUIT

TECHNICAL DATA

INTEGRATED CIRCUIT

TECHNICAL DATA

TMP8085AP



ALE (Output)

Address Latch Enable: It occurs during the first clock state of a machine cycle and enables the address to get latched into the on-chip latch of peripherals. The falling edge of ALE can be used to strobe the status information. ALE is never 3-stated.

$\overline{\text{WR}}$ (Output, 3-state)

WRITE control: A low level on $\overline{\text{WR}}$ indicates the data on the Data Bus is to be written into the selected memory or I/O location. Data is set up at the trailing edge of $\overline{\text{WR}}$. It is 3-stated during Hold and Halt modes and during RESET.

$\overline{\text{RD}}$ (Output, 3-state)

READ control: A low level on $\overline{\text{RD}}$ indicates the selected memory or I/O device to be read and that the Data Bus is available for the data transfer, 3-stated during Hold and Halt modes and during RESET.

READY (Input)

When READY is absent (low), indicating the external operation is not complete, the processor will enter the Wait state. It will wait an integral number of clock cycles for READY to go high before completing the read or write cycle.

HOLD (Input)

The Hold input allows an external signal to cause the processor to relinquish control over the address bus and the data bus. When Hold goes active, the processor completes its current operation, activates the HLDA output, and puts the Address, Data, $\overline{\text{RD}}$, $\overline{\text{WR}}$, and IO/M lines into their high-impedance state. Internal processing can continue. The Holding device can then utilize the address and data buses without interference. The processor can regain the bus only after the Hold is removed.

HLDA (Output)

The Hold Acknowledge output signal is a response to a Hold input. It indicates that the processor has received the HOLD request and it will relinquish the bus in the next cycle. HLDA goes low after the Hold request is moved. The processor takes the bus one half clock cycle after HLDA goes low.

VCC

+5 volt supply

VSS

Ground Reference

FUNCTIONAL DESCRIPTION

The TMP8085A is a complete 8-bit parallel central processor. Its basic clock speed is 3 MHz. Also it is designed to fit into a minimum system of three IC's: The CPU (TMP8085A), a RAM I/O (TMP8155P or TMP8156P), and a ROM or EPROM I/O chip (TMP8355P or TMP8755AC).

The TMP8085A is provided with internal 8-bit registers and 16-bit registers. The TMP8085A has eight addressable 8-bit registers. Six of them can be used either as 8-bit registers or as 16-bit register pairs. In addition to the register pairs, the TMP8085A contains two more 16-bit registers. The TMP8085A register set is as follows:

- The accumulator (A Register) is the focus of all of the accumulator instructions, which include arithmetic, logic, load and store, and I/O instructions.
- The program counter (PC) always points to the memory location of the next instruction to be executed.
- General - purpose registers BC, DE, and HL may be used as 8-bit registers or as three 16-bit registers, interchangeably, depending on the instruction being performed.
- The stack pointer (sp) is a special data pointer that always points to the stack top (next available stack address).
- The flag register contains five one-bit flags, each of which records processor status information and may also control processor operation.

The five flags in the TMP8085A CPU are shown below:

(MSB)							
D7	D6	D5	D4	D3	D2	D1	D0
S	Z		AC		P		C

- The carry flag (C) is set and reset by arithmetic operations. An addition operation that results in an overflow out of the high-order bit of the accumulator sets the carry flag. The carry flag also acts as a "borrow" flag for subtract instruction.
- The auxiliary carry flag (AC) indicates overflow out of bit 3 of the accumulator in the same way that C flag indicates overflow out of bit 7. This flag is commonly used in BCD arithmetic.
- The sign flag (S) is set to the condition of the most significant (MSB) bit of the accumulator following the execution of arithmetic or logic instructions.
- The zero flag (Z) is set if the result generated by certain instructions is zero. The zero flag is cleared if the result is not zero.
- The parity flag (P) is set to 1 if the parity (number of 1-bits) of the accumulator is even. If odd, it is cleared.

In the TMP8085A microprocessor are contained the functions of clock generation, system bus control, and interrupt priority selection, in addition to execution of the instruction set. The TMP8085A uses a multiplexed Data Bus. The address is split between the higher 8-bit Address Bus and the lower 8-bit Address/Data Bus. During the first T state (T_1 clock cycle) of a machine cycle the lower order address is sent out on the Address/Data Bus. These lower 8 bits may be latched externally by the Address Latch Enable signal (ALE). During the rest of the machine cycle the data bus is used for memory or I/O data.

INTERRUPT AND SERIAL I/O

The TMP8085A has 5 interrupt inputs: INTR, RST 5.5, RST 6.5, RST 7.5, and TRAP. INTR is identical in function to 9080A INT. Each of three RESTART inputs 5.5, 6.5, 7.5, has a programmable mask. TRAP is also a RESTART interrupt but it is nonmaskable.

The three RESTART interrupts cause the internal execution of RESTART if the interrupts are enabled and if the interrupt mask is not set. The nonmaskable TRAP causes internal execution independent of the state of the interrupt enable or masks.

There are two different types of inputs in the restart interrupts. RST 5.5 and RST 6.5 are high level sensitive like INTR and are recognized with the same timing as INTR. RST 7.5 is rising edge-sensitive.

For RST 7.5, only a pulse is required to set an internal flip-flop which generates the interrupt request. The RST 7.5 request flip-flop remains set until the request is serviced. Then it is reset automatically. This flip-flop may also be reset by using the SIM instruction or by issuing a RESET IN to the TMP8085A. The RST 7.5 internal flip-flop will be set by a pulse on the RST 7.5 pin even when the RST 7.5 interrupt is masked out.

The interrupts are arranged in a fixed priority that determines which interrupt is to be recognized if more than one is pending: TRAP-highest priority. RST 7.5, RST 6.5, RST 5.5, INTR - lowest priority. This priority scheme does not take into account the priority of a routine that was started by a higher priority interrupt. RST 5.5 can interrupt a RST 7.5 routine if the interrupts were reenabled before the end of the RST 7.5 routine.

The TRAP interrupt is useful for catastrophic errors such as power failure or bus error. It is not affected by any flag or mask. The TRAP input is both edge and level sensitive. The TRAP input must go high and remain high until it is acknowledged. It will not be recognized again until it goes low, then high again. This avoids any false triggering due to noise or logic glitches.

TABLE 1. INTERRUPT PRIORITY, RESTART ADDRESS, AND SENSITIVITY

Name	Priority	Address Branched to When Interrupt Occurs	Type Trigger
TRAP	1	24 (Hex.)	Rising edge and high level until sampled.
RST 7.5	2	3C (Hex.)	Rising edge (latched).
RST 6.5	3	34 (Hex)	High level until sampled.
RST 5.5	4	2C (Hex.)	High level until sampled.
INTR	5	See Note (2)	High level until sampled.

Notes: (1) The processor pushes the PC on the stack before branching to the indicated address.

(2) The address branched to depends on the instruction provided to the TMP8085A when the interrupt is acknowledged.

The TRAP interrupt is special in that it disables interrupts, but preserves the previous interrupt enable status. Performing the first RIM instruction following a TRAP interrupt allows you to determine whether interrupts were enabled or disabled prior to the TRAP. All subsequent RIM instruction provide current interrupt enable status. Performing a RIM instruction following INTR, or RST 5.5-7.5 will provide current interrupt enable status, revealing that interrupts are disabled.

The serial I/O system is also controlled by the RIM and SIM instructions. SID is read by RIM, and SIM sets the SOD date.

BASIC TIMING

The execution of each instruction by the TMP8085A consists of a sequence of from one to five machine cycles, and each machine cycle consists of a minimum of from three to six clock cycles. Most machine cycles consist of three T states, (cycles of the CLK output) with the exception of opcode fetch, which normally has either four or six T states (unless WAIT or HOLD states are forced by the receipt of READY or HOLD inputs). Any T state must be one of ten possible states, shown in Table 3. At the beginning of every machine cycle, the TMP8085A sends out three status signals (IO/M, S₁, S₀) that define what type of machine cycle is about to take place. The TMP8085A also sends out a 16-bit address at the beginning of every machine cycle to identify the particular memory location or I/O port that the machine cycle applies to.

The special timing signal, ADDRESS LATCH ENABLE (ALE), is used a strobe to sample the lower 8-bits of address on the AD₀-AD₇ lines. ALE is present during T₁ of every machine cycle. Control lines RD (INTA) and WR become active later, at the time when the transfer of data is to take place.

Figure 3 shows an instruction fetch, memory read and I/O write cycle (as would occur during processing of the OUT instruction).

TABLE 2. TMP8085A MACHINE CYCLE CHART

MACHINE CYCLE	IO/ \overline{M}	S ₁	S ₀	\overline{RD}	\overline{WR}	\overline{INTA}
OPCODE FETCH	0	1	1	0	1	1
MEMORY READ	0	1	0	0	1	1
MEMORY WRITE	0	0	1	1	0	1
I/O READ	1	1	0	0	1	1
I/O WRITE	1	0	1	1	0	1
ACKNOWLEDGE OF INTR	1	1	1	1	1	0
BUS IDLE : DAD	0	1	0	1	1	1
ACK. OF	1	1	1	1	1	1
RST, TRAP	1	1	1	1	1	1
HALT	TS	0	0	TS	TS	1

NOTE: 0 = Logic "0", 1 = Logic "1", TS = High Impedance

TABLE 3. TMP8085A MACHINE STATE CHART

MACHINE STATE	S ₁ , S ₀	IO/ \overline{M}	A ₈ -A ₁₅	AD ₀ -AD ₇	\overline{RD} , \overline{WR}	\overline{INTA}	ALE
T ₁	X	X	X	X	1	1	1°
T ₂	X	X	X	X	X	X	0
T _{WAIT}	X	X	X	X	X	X	0
T ₃	X	X	X	X	X	X	0
T ₄	1	0†	X	TS	1	1	0
T ₅	1	0†	X	TS	1	1	0
T ₆	1	0†	X	TS	1	1	0
T _{RESET}	X	TS	TS	TS	TS	1	0
T _{HALT}	0	TS	TS	TS	TS	1	0
T _{HOLD}	X	TS	TS	TS	TS	1	0

NOTES: (1) 0 = Logic "0", 1 = Logic "1", TS = High Impedance, X = Unspecified

(2) °ALE not generated during 2nd and 3rd machine cycles of DAD instruction

(3) † IO/ \overline{M} = 1 during T₄ - T₆ of INA machine cycle



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INTEGRATED CIRCUIT

TECHNICAL DATA

TMP8085AP

TECHNICAL DATA

2TU9M1 SX GMA IX 2MT 2MTV18M

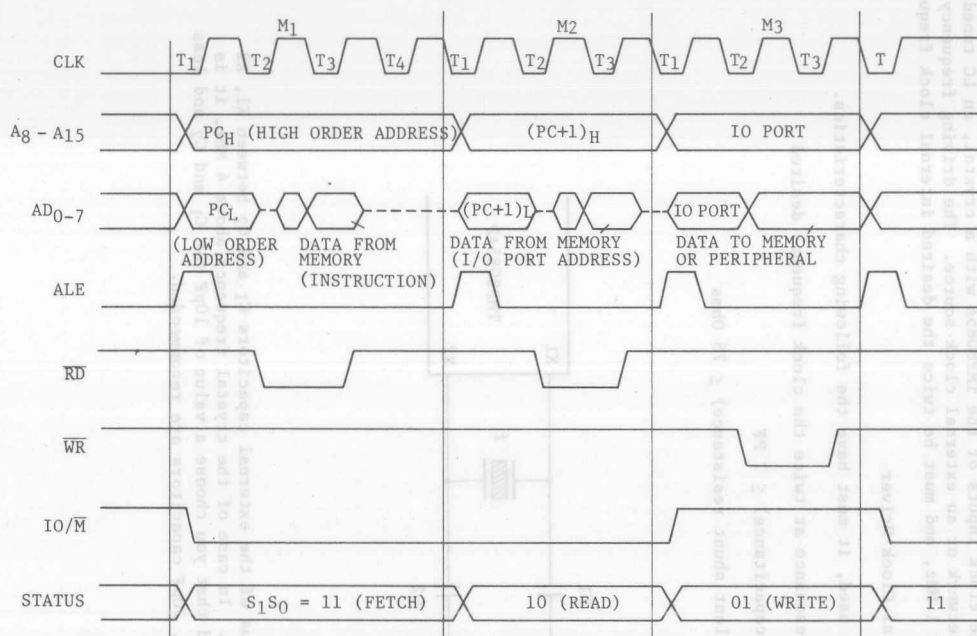


FIGURE 3. TMP8085A BASIC SYSTEM TIMING

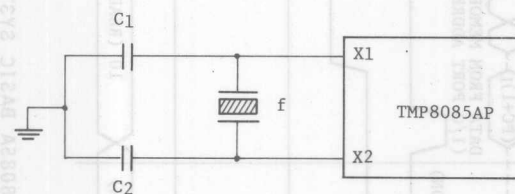
DRIVING THE X1 AND X2 INPUTS

You may drive the clock inputs of the TMP8085A with a crystal, an LC tuned circuit, an RC network or an external clock source. The driving frequency must be at least 1 MHz, and must be twice the desired internal clock frequency.

A. Quartz Crystal Clock Driver

If a crystal used, it must have the following characteristics.

- Parallel resonance at twice the clock frequency desired
- C_S (shunt capacitance) ≤ 7 PF
- R_S (equivalent shunt resistance) ≤ 75 Ohms



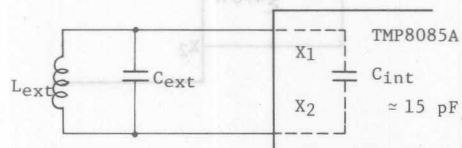
Note a value of the external capacitors C_1 and C_2 between X1, X2 and ground. In case of the crystal frequency above 4 MHz, it is recommended that you choose a value of 10pF for C_1 and C_2 and less than 4 MHz, 20pF capacitors are recommended.

B. LC Turned Circuit Clock Driver

A parallel-resonant LC circuit may be used as the frequency-determining network for the TMP8085A, providing that its frequency tolerance of approximately 10% is acceptable. The components are chosen from the formula.

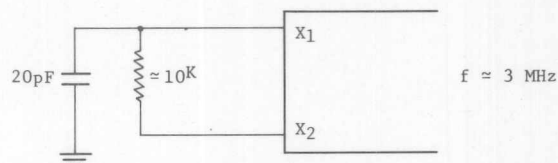
$$f = \frac{1}{2\pi \sqrt{L (C_{ext} + C_{int})}}$$

The use of an LC circuit is not recommended for frequencies higher than approximately 5 MHz.

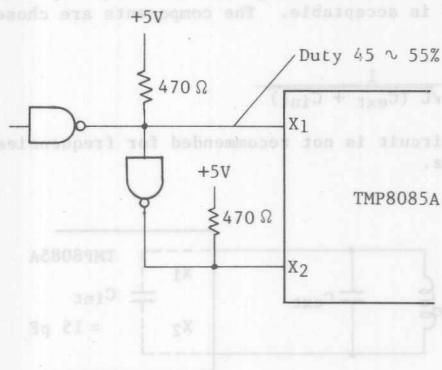


C. RC Circuit Clock Driver

An RC circuit may be used as the frequency - determining network for the TMP 8085A if maintaining a precise clock frequency is of no importance. Variations in the on-chip timing generation can cause a wide variation in frequency when using RC circuit. The driving frequency generated by the circuit shown is approximately 3 MHz. It is not recommended that frequencies greatly higher or lower than this be attempted.



D. External clock Driver Circuit



POWER ON AND RESET IN

The TMP 8085A is not guaranteed to work until 10 ms after V_{CC} reaches 4.75 V. It is suggested that RESET IN be kept low during this period. Note that the 10 ms period does not include the time it takes for the power supply to reach its 4.75 V level.



INSTRUCTION SET

Symbols and Abbreviations

SYMBOLS	DEFINITION
ddd,sss	The bit pattern designating one of the registers A,B,C,D,E,H,L (ddd=destination, sss=source):
ddd or sss	REGISTER NAME
111	A
000	B
001	C
010	D
011	E
100	H
101	L
110	M (Memory)
r,r1,r2	One of the registers A,B,C,D,E,H,L
d8	8-bit data quantity
d16	16-bit data quantity
addr8	8-bit address of an I/O device
addr	16-bit address quantity
RP	The bit pattern designating one of the register pairs B,D,H,SP:
RP	REGISTER PAIR (rpH)(rpL)
00	B-C
01	D-E
10	H-L
11	SP
B ₂	The second byte of the instruction
B ₃	The third byte of the instruction
O	Affected
S	Set
R	Reset
-	Not affected

Data Transfer

Mnemonic	Instruction Code	Operation	Bytes	States	Flag
	D ₇ D ₆ D ₅ D ₄ D ₃ D ₂ D ₁ D ₀				C Z S P AC
MOV r ₁ , r ₂	0 1 d d d S S S	(r ₁) ← (r ₂)	1	4	- - - - -
MOV M, r	0 1 1 1 0 S S S	[(H)(L)] ← (r)	1	7	- - - - -
MOV r, M	0 1 d d d 1 1 0	(r) ← [(H)(L)]	1	7	- - - - -
MVI r, d8	0 0 d d d 1 1 0 B ₂	(r) ← (B ₂)	2	7	- - - - -
MVI M, d8	0 0 1 1 0 1 1 0 B ₂	[(H)(L)] ← (B ₂)	2	10	- - - - -
LDA addr	0 0 1 1 1 0 1 0 B ₂ B ₃	(A) ← [(B ₃)(B ₂)]	3	13	- - - - -
LDAX B	0 0 0 0 1 0 1 0	(A) ← [(B)(C)]	1	7	- - - - -
LDAX D	0 0 0 1 1 0 1 0	(A) ← [(D)(E)]	1	7	- - - - -
LHLD addr	0 0 1 0 1 0 1 0 B ₂ B ₃	(L) ← [(B ₃)(B ₂)] (H) ← [(B ₃)(B ₂)+1]	3	16	- - - - -
LXI H, d16	0 0 1 0 0 0 0 1 B ₂ B ₃	(H) ← (B ₃) (L) ← (B ₂)	3	10	- - - - -
LXI D, d16	0 0 0 1 0 0 0 1 B ₂ B ₃	(D) ← (B ₃) (E) ← (B ₂)	3	10	- - - - -
LXI B, d16	0 0 0 0 0 0 0 1 B ₂ B ₃	(B) ← (B ₃) (C) ← (B ₂)	3	10	- - - - -
LXI SP, d16	0 0 1 1 0 0 0 1 B ₂ B ₃	(SP) _H ← (B ₃) (SP) _L ← (B ₂)	3	10	- - - - -
SHLD addr	0 0 1 0 0 0 1 0 B ₂ B ₃	[(B ₃)(B ₂)] ← (L) [(B ₃)(B ₂)+1] ← (H)	3	16	- - - - -
STA addr	0 0 1 1 0 0 1 0 B ₂ B ₃	[(B ₃)(B ₂)] ← (A)	3	13	- - - - -

Mnemonic	Instruction Code								Operation	Bytes	States	Flag				
	D ₇	D ₆	D ₅	D ₄	D ₃	D ₂	D ₁	D ₀				C	Z	S	P	AC
STAX B	0	0	0	0	0	0	1	0	$[(B)(C)] \leftarrow (A)$	1	7	-	-	-	-	-
STAX D	0	0	0	1	0	0	1	0	$[(D)(E)] \leftarrow (A)$	1	7	-	-	-	-	-
SPHL	1	1	1	1	1	0	0	1	$(SP) \leftarrow (H)(L)$	1	6	-	-	-	-	-
XCHG	1	1	1	0	1	0	1	1	$(H) \leftrightarrow (D)$ $(L) \leftrightarrow (E)$	1	4	-	-	-	-	-
XTHL	1	1	1	0	0	0	1	1	$(L) \leftrightarrow [(SP)]$ $(H) \leftrightarrow [(SP)+1]$	1	16	-	-	-	-	-
IN addr8	1	1	0	1	1	0	1	1	$(A) \leftarrow (data)$	2	10	-	-	-	-	-
OUT addr8	1	1	0	1	0	0	1	1	$(data) \leftarrow (A)$	2	10	-	-	-	-	-

Branch

Mnemonic	Instruction Code								Operation	Bytes	States	Flag				
	D ₇	D ₆	D ₅	D ₄	D ₃	D ₂	D ₁	D ₀				C	Z	S	P	AC
JMP addr	1	1	0	0	0	0	1	1	$(PC) \leftarrow (B_3)(B_2)$	3	10	-	-	-	-	-
JNZ addr	1	1	0	0	0	0	1	0	If Z = 0 $(PC) \leftarrow (B_3)(B_2)$, If Z = 1 $(PC) \leftarrow (PC) + 3$	3	7/10	-	-	-	-	-
JZ addr	1	1	0	0	1	0	1	0	If Z = 1 $(PC) \leftarrow (B_3)(B_2)$, If Z = 0 $(PC) \leftarrow (PC) + 3$	3	7/10	-	-	-	-	-
JNC addr	1	1	0	1	0	0	1	0	If C = 0 $(PC) \leftarrow (B_3)(B_2)$, If C = 1 $(PC) \leftarrow (PC) + 3$	3	7/10	-	-	-	-	-
JC addr	1	1	0	1	1	0	1	0	If C = 1 $(PC) \leftarrow (B_3)(B_2)$, If C = 0 $(PC) \leftarrow (PC) + 3$	3	7/10	-	-	-	-	-



INTEGRATEDCIRCUIT

TECHNICAL DATA

TMP8035AP

Mnemonic	Instruction Code								Operation	Bytes	States	Flag			
	D ₇	D ₆	D ₅	D ₄	D ₃	D ₂	D ₁	D ₀				C	Z	S	P AC
JPO addr	1	1	1	0	0	0	1	0	If P=0 (PC) ← (B ₃)(B ₂), If P=1 (PC) ← (PC) + 3	3	7/10	-	-	-	-
JPE addr	1	1	1	0	1	0	1	0	If P=1 (PC) ← (B ₃)(B ₂), If P=0 (PC) ← (PC) + 3	3	7/10	-	-	-	-
JP addr	1	1	1	1	0	0	1	0	If S=0 (PC) ← (B ₃)(B ₂), If S=1 (PC) ← (PC) + 3	3	7/10	-	-	-	-
JM addr	1	1	1	1	1	0	1	0	If S=1 (PC) ← (B ₃)(B ₂), If S=0 (PC) ← (PC) + 3	3	7/10	-	-	-	-
CALL addr	1	1	0	0	1	1	0	1	[(SP)-1] ← (PCH) [(SP)-2] ← (PCL) (SP) ← (SP) - 2 (PC) ← (B ₃)(B ₂)	3	18	-	-	-	-
CNZ addr	1	1	0	0	0	1	0	0	If Z=0, the actions specified in the CALL instruction are performed. If Z=1 (PC) ← (PC) + 3	3	9/18	-	-	-	-
CZ addr	1	1	0	0	1	1	0	0	If Z=1, the actions specified in the CALL instruction are performed. If Z=0, (PC) ← (PC) + 3	3	9/18	-	-	-	-



INTEGRATED CIRCUIT

TECHNICAL DATA

INTEGRATED CIRCUIT

TMP8085AP

TECHNICAL DATA



Mnemonic	Instruction Code								Operation	Bytes	States	Flag				
	D ₇	D ₆	D ₅	D ₄	D ₃	D ₂	D ₁	D ₀				C	Z	S	P	AC
CNC addr	1	1	0	1	0	1	0	0	If C = 0, the actions specified in the CALL instruction are performed. If C = 1 (PC) ← (PC) + 3	3	9/18	-	-	-	-	-
CC addr	1	1	0	1	1	1	0	0	If C = 1, the actions specified in the CALL instruction are performed. If C = 0 (PC) ← (PC) + 3	3	9/18	-	-	-	-	-
CPO addr	1	1	1	0	0	1	0	0	If P = 0, the actions specified in the CALL instruction are performed. If P = 1 (PC) ← (PC) + 3	3	9/18	-	-	-	-	-
CPE addr	1	1	1	0	1	1	0	0	If P = 1, the actions specified in the CALL instruction are performed. If P = 0 (PC) ← (PC) + 3	3	9/18	-	-	-	-	-
CP addr	1	1	1	1	0	1	0	0	If S = 0, the actions specified in the CALL instruction are performed. If S = 1 (PC) ← (PC) + 3	3	9/18	-	-	-	-	-

Mnemonic	Instruction Code								Operation	Bytes	States	Flag				
	D ₇	D ₆	D ₅	D ₄	D ₃	D ₂	D ₁	D ₀				C	Z	S	P	AC
CM addr	1	1	1	1	1	1	0	0	If S=1, the actions specified in the CALL instruction are performed. If S=0 (PC) ← (PC) + 3	3	9/18	-	-	-	-	-
RET	1	1	0	0	1	0	0	1	(PCL) ← [(SP)] (PCH) ← [(SP)+1] (SP) ← (SP) + 2	1	10	-	-	-	-	-
RNZ	1	1	0	0	0	0	0	0	If Z=0, the actions specified in the RET instruction are performed. If Z=1 (PC) ← (PC) + 1	1	6/12	-	-	-	-	-
RZ	1	1	0	0	1	0	0	0	If Z=1, the actions specified in the RET instruction are performed. If Z=0 (PC) ← (PC) + 1	1	6/12	-	-	-	-	-
RNC	1	1	0	1	0	0	0	0	If C=0, the actions specified in the RET instruction are performed. If C=1 (PC) ← (PC) + 1	1	6/12	-	-	-	-	-



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TMP8085AP
TECHNICAL DATA



Mnemonic	Instruction Code								Operation	Bytes	States	Flag			
	D ₇	D ₆	D ₅	D ₄	D ₃	D ₂	D ₁	D ₀				C	Z	S	P
RC	1	1	0	1	1	0	0	0	If C=1, the actions specified in the RET instruction are performed. If C=0 (PC) ← (PC) + 1	1	6/12	-	-	-	-
RPO	1	1	1	0	0	0	0	0	If P=0, the actions specified in the RET instruction are performed. If P=1 (PC) ← (PC) + 1	1	6/12	-	-	-	-
RPE	1	1	1	0	1	0	0	0	If P=1, the actions specified in the RET instruction are performed. If P=0 (PC) ← (PC) + 1	1	6/12	-	-	-	-
RP	1	1	1	1	0	0	0	0	If S=0, the actions specified in the RET instruction are performed. If S=1 (PC) ← (PC) + 1	1	6/12	-	-	-	-
RM	1	1	1	1	1	0	0	0	If S=1, the actions specified in the RET instruction are performed. If S=0 (PC) ← (PC) + 1	1	6/12	-	-	-	-



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TECHNICAL DATA

TMP8085AP

Mnemonic	Instruction Code								Operation	Bytes	States	Flag				
	D ₇	D ₆	D ₅	D ₄	D ₃	D ₂	D ₁	D ₀				C	Z	S	P	AC
PCHL	1	1	1	0	1	0	0	1	(PCH) ← (H) (PCL) ← (L)	1	6	-	-	-	-	-
RST	1	1	A	A	A	1	1	1	[(SP)-1] ← (PCH) [(SP)-2] ← (PCL) (SP) ← (SP) - 2 (PC) ← (00000000 00AAAA000)	1	12	-	-	-	-	-

Arithmetic

Mnemonic	Instruction Code								Operation	Bytes	States	Flag				
	D ₇	D ₆	D ₅	D ₄	D ₃	D ₂	D ₁	D ₀				C	Z	S	P	AC
ADD r	1	0	0	0	0	S	S	S	(A) ← (A) + (r)	1	4	0	0	0	0	0
ADC r	1	0	0	0	1	S	S	S	(A) ← (A) + (r) + (C)	1	4	0	0	0	0	0
ADD M	1	0	0	0	0	1	1	0	(A) ← (A) + [(H)(L)]	1	7	0	0	0	0	0
ADC M	1	0	0	0	1	1	1	0	(A) ← (A) + [(H)(L)] + (C)	1	7	0	0	0	0	0
ADI d8	1	1	0	0	0	1	1	0	(A) ← (A) + (B ₂)	2	7	0	0	0	0	0
ACI d8	1	1	0	0	1	1	1	0	(A) ← (A) + (B ₂) + (C)	2	7	0	0	0	0	0
DAD rp	0	0	R	P	1	0	0	1	(H)(L) ← (H)(L) + (rH)(rL)	1	10	0	-	-	-	-
SUB r	1	0	0	1	0	S	S	S	(A) ← (A) - (r)	1	4	0	0	0	0	0
SBB r	1	0	0	1	1	S	S	S	(A) ← (A) - (r) - (C)	1	4	0	0	0	0	0
SUB M	1	0	0	1	0	1	1	0	(A) ← (A) - [(H)(L)]	1	7	0	0	0	0	0
SBB M	1	0	0	1	1	1	1	0	(A) ← (A) - [(H)(L)] - (C)	1	7	0	0	0	0	0
SUI d8	1	1	0	1	0	1	1	0	(A) ← (A) - (B ₂)	2	7	0	0	0	0	0
SBI d8	1	1	0	1	1	1	1	0	(A) ← (A) - (B ₂) - (C)	2	7	0	0	0	0	0

Mnemonic	Instruction Code								Operation	Bytes	States	Flag				
	D ₇	D ₆	D ₅	D ₄	D ₃	D ₂	D ₁	D ₀				C	Z	S	P	AC
DAA	0	0	1	0	0	1	1	1	The 8-bit number in the accumulator is adjusted to form two 4-bit BCD digits by the following process.	1	4	0	0	0	0	0
									Accumulator							
									<div> <div>7</div> <div>4</div> <div>3</div> <div>0</div> </div> <div> <div>X</div> <div>Y</div> </div>							
									<div> <div>C</div> <div>AC</div> </div>							
									1. If $Y \geq 10$ or $AC=1$,							
									$(A) \leftarrow (A) + 6$							
									2. If $X \geq 10$ or $C=1$,							
									$(A)_{4-7} \leftarrow (A)_{4-7} + 6$							

Logical Instruction

Mnemonic	Instruction Code								Operation	Bytes	States	Flag				
	D ₇	D ₆	D ₅	D ₄	D ₃	D ₂	D ₁	D ₀				C	Z	S	P	AC
ANA r	1	0	1	0	0	S	S	S	(A) ← (A) ∧ (r)	1	4	R	0	0	0	S
ANA M	1	0	1	0	0	1	1	0	(A) ← (A) ∧ [(H)(L)]	1	7	R	0	0	0	S
ANI d8	1	1	1	0	0	1	1	0	(A) ← (A) ∧ (B ₂)	2	7	R	0	0	0	S
					B ₂											
XRA r	1	0	1	0	1	S	S	S	(A) ← (A) ∨ (r)	1	4	R	0	0	0	R
XRA M	1	0	1	0	1	1	1	0	(A) ← (A) ∨ [(H)(L)]	1	7	R	0	0	0	R
XRI d8	1	1	1	0	1	1	1	0	(A) ← (A) ∨ (B ₂)	2	7	R	0	0	0	R
					B ₂											
ORA r	1	0	1	1	0	S	S	S	(A) ← (A) V (r)	1	4	R	0	0	0	R
ORA M	1	0	1	1	0	1	1	0	(A) ← (A) V [(H)(L)]	1	7	R	0	0	0	R
ORI d8	1	1	1	1	0	1	1	0	(A) ← (A) V (B ₂)	2	7	R	0	0	0	R
					B ₂											
CMP r	1	0	1	1	1	S	S	S	(A) - (r)	1	4	0	0	0	0	0
CMP M	1	0	1	1	1	1	1	0	(A) - [(H)(L)]	1	7	0	0	0	0	0
CPI d8	1	1	1	1	1	1	1	0	(A) - (B ₂)	2	7	0	0	0	0	0
					B ₂											
CMA	0	0	1	0	1	1	1	1	(A) ← (A)	1	4	-	-	-	-	-
RLC	0	0	0	0	0	1	1	1	(An+1) ← (An) (A ₀) ← (A ₇) (C) ← (A ₇)	1	4	0	-	-	-	-
RRC	0	0	0	0	1	1	1	1	(An) ← (An+1) (A ₇) ← (A ₀) (C) ← (A ₀)	1	4	0	-	-	-	-
RAL	0	0	0	1	0	1	1	1	(An+1) ← (An) (C) ← (A ₇) (A ₀) ← (C)	1	4	0	-	-	-	-
RAR	0	0	0	1	1	1	1	1	(An) ← (An+1) (C) ← (A ₀) (A ₇) ← (C)	1	4	0	-	-	-	-

Increment and Decrement

Mnemonic	Instruction Code								Operation	Bytes	States	Flag				
	D ₇	D ₆	D ₅	D ₄	D ₃	D ₂	D ₁	D ₀				C	Z	S	P	AC
INR r	0	0	d	d	d	1	0	0	$(r) \leftarrow (r) + 1$	1	4	-	0	0	0	0
INR M	0	0	1	1	0	1	0	0	$[(H)(L)] \leftarrow [(H)(L)] + 1$	1	10	-	0	0	0	0
INX rp	0	0	R	P	0	0	1	1	$(rH)(rL) \leftarrow (rH)(rL) + 1$	1	6	-	-	-	-	-
DCR r	0	0	d	d	d	1	0	1	$(r) \leftarrow (r) - 1$	1	4	-	0	0	0	0
DCR M	0	0	1	1	0	1	0	1	$[(H)(L)] \leftarrow [(H)(L)] - 1$	1	10	-	0	0	0	0
DCX rp	0	0	R	P	1	0	1	1	$(rH)(rL) \leftarrow (rH)(rL) - 1$	1	6	-	-	-	-	-

Stack

Mnemonic	Instruction Code								Operation	Bytes	States	Flag				
	D ₇	D ₆	D ₅	D ₄	D ₃	D ₂	D ₁	D ₀				C	Z	S	P	AC
PUSH rp	1	1	R	P	0	1	0	1	$[(SP) - 1] \leftarrow (rH)$ $[(SP) - 2] \leftarrow (rL)$ $(SP) \rightarrow (SP) - 2$ Note: Register pair $rp=SP$ may not be specified.	1	12	-	-	-	-	-
PUSH PSW	1	1	1	1	0	1	0	1	$[(SP) - 1] \leftarrow (A)$ $[(SP) - 2] \leftarrow$ $D_7D_6D_5D_4D_3D_2D_1D_0$ <div style="border: 1px solid black; padding: 2px; display: inline-block;"> S Z X A C X P X C </div> MSB $(SP) \leftarrow (SP) - 2$	1	12	-	-	-	-	-
POP rp	1	1	R	P	0	0	0	1	$(rL) \leftarrow [(SP)]$ $(rH) \leftarrow [(SP) + 1]$ $(SP) \leftarrow (SP) + 2$	1	10	-	-	-	-	-
POP PSW	1	1	1	1	0	0	0	1	$(C) \leftarrow [(SP)]_0$ $(P) \leftarrow [(SP)]_2$ $(AC) \leftarrow [(SP)]_4$ $(Z) \leftarrow [(SP)]_6$ $(S) \leftarrow [(SP)]_7$ $(A) \leftarrow [(SP) + 1]$ $(SP) \leftarrow (SP) + 2$	1	10	0	0	0	0	0

Control

Mnemonic	Instruction Code								Operation	Bytes	States	Flag				
	D ₇	D ₆	D ₅	D ₄	D ₃	D ₂	D ₁	D ₀				C	Z	S	P	AC
HLT	0	1	1	1	0	1	1	0	Halt	1	5	-	-	-	-	-
STC	0	0	1	1	0	1	1	1	(C) + 1	1	4	0	-	-	-	-
CMC	0	0	1	1	1	1	1	1	(C) + (\bar{C})	1	4	0	-	-	-	-
EI	1	1	1	1	1	0	1	1	Enable interrupts	1	4	-	-	-	-	-
									Note: Interrupts are not recognized during the EI instruction.							
DI	1	1	1	1	0	0	1	1	Disable interrupts	1	4	-	-	-	-	-
									Note: Interrupts are not recognized during the DI instruction.							
NOP	0	0	0	0	0	0	0	0	No operation is performed.	1	4	-	-	-	-	-
RIM	0	0	1	0	0	0	0	0	(A) ← d ₇ = SID d ₆ = I ₇ d ₅ = I ₆ d ₄ = I ₅ d ₃ = I _E d ₂ = M ₇ d ₁ = M ₆ d ₀ = M ₅	1	4	-	-	-	-	-
SIM	0	0	1	1	0	0	0	0	IF(A) ₆ = 1; SOD + (A) ₇ IF(A) ₃ = 1; M ₇ + (A) ₂ M ₆ + (A) ₁ M ₅ + (A) ₀ IF(A) ₄ = 1; RST7.5 RESET	1	4	-	-	-	-	-



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ABSOLUTE MAXIMUM RATINGS

Symbol	Item	Ratings
V_{CC}	V_{CC} Supply Voltage	-0.5V to 7.0V
V_{IN}	Input Voltage with Respect to V_{SS}	-0.5V to 7.0V
V_{OUT}	Output Voltage with Respect to V_{SS}	-0.5V to 7.0V
P_D	Power Dissipation	1.5W
T_{solder}	Soldering Temperature (Soldering Time 10 sec.)	260°C
T_{stg}	Storage Temperature	-55°C to 150°C
T_{opr}	Operating Temperature	0°C to 70°C

DC CHARACTERISTICS

 $T_A = 0^\circ\text{C to } 70^\circ\text{C}$, $V_{CC} = 5V \pm 5\%$

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V_{IL}	Input Low Voltage		-0.5		0.8	V
V_{IH}	Input High Voltage		2.0		$V_{CC} + 0.5$	V
V_{OL}	Output Low Voltage	$I_{OL} = 2\text{mA}$			0.45	V
V_{OH}	Output High Voltage	$I_{OH} = -400\mu\text{A}$	2.4			V
I_{CC}	Power Supply Current				170	mA
I_{IL}	Input Leakage	$V_{IN} = V_{CC}$			± 10	μA
I_{LO}	Output Leakage	$0.45 \leq V_{OUT} \leq V_{CC}$			10	μA
V_{ILR}	Input Low Level (RESET)		-0.5		0.8	V
V_{IHR}	Input High Level (RESET)		2.4		$V_{CC} + 0.5$	V
V_{HY}	Hysteresis (RESET)		0.25			V

AC CHARACTERISTICS

TA = 0°C to 70°C, VCC = 5V ± 5%, VSS = 0V, Unless Otherwise Noted.

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
tCYC	CLK Cycle Period		320		2000	ns
tL	CLK Low Time - Standard 150pF Loading - Lightly Loaded [2]		80 100			ns ns
tH	CLK High Time - Standard 150pF Loading - Lightly Loaded [2]		120 150			ns ns
t _r , t _f	CLK Rise and Fall Time				30	ns
tXKR	X ₁ Rising to CLK Rising		30		120	ns
tXKF	X ₁ Rising to CLK Falling		30		150	ns
tAC	A ₈₋₁₅ Valid to Leading Edge of Control [1]		270			ns
tACL	A ₀₋₇ Valid to Leading of Control		240			ns
tAD	A ₀₋₁₅ Valid to Valid Data In				575	ns
tAFR	Address Float after Leading Edge of READ (INTA)				0	ns
tAL	A ₈₋₁₅ Valid before Trailing Edge of ALE [1]	C _L =150pF	115			ns
tALL	A ₀₋₇ Valid before Trailing Edge of ALE		90			ns
tARY	READY Valid from Address Valid	tCYC=320ns			220	ns
tCA	Address (A ₈₋₁₅) Valid after Control		120			ns
tCC	Width of Control Low (RD, WR, INTA) Edge of ALE		400			ns
tCL	Trailing Edge of Control to Leading Edge of ALE		50			ns
tDW	Data Valid to Trailing Edge of WRITE		420			ns
tHABE	HLDA to Bus Enable				210	ns
tHABF	Bus Float after HLDA				210	ns
tHACK	HLDA Valid to Trailing Edge of CLK		110			ns
tHDH	HOLD Hold Time		0			ns
tHDS	HOLD Setup Time to Trailing Edge of CLK		170			ns
tINH	INTR Hold Time		0			ns

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
t_{INS}	INTR, RST and TRAP Setup Time to Falling Edge of CLK		160			ns
t_{LA}	Address Hold Time after ALE		100			ns
t_{LC}	Trailing Edge of ALE to Leading Edge of Control		130			ns
t_{LCK}	ALE Low during CLK High		100			ns
t_{LDR}	ALE to Valid Data during Read				460	ns
t_{LDW}	ALE to Valid Data during Write				200	ns
t_{LL}	ALE Width		140			ns
t_{LRY}	ALE to READY Stable				110	ns
t_{RAE}	Trailing Edge of READ to Re-Enabling of Address		150			ns
t_{RD}	\overline{READ} (or \overline{INTA}) to Valid Data				300	ns
t_{RV}	Control Trailing Edge to Leading Edge of Next Control		400			ns
t_{RDH}	Data Hold Time After \overline{READ} \overline{INTA}		0			ns
t_{RYH}	READY Hold Time		0			ns
t_{RYS}	READY Setup Time to Leading Edge of CLK		110			ns
t_{WD}	Data Valid After Trailing Edge of WRITE		100			ns
t_{WDL}	LEADING Edge of WRITE to Data Valid				40	ns

- Notes:
1. A8-15 address specs apply to $\overline{IO}/\overline{M}$, S_0 and S_1 except A8-15 are undefined during $T_4 - T_6$ of OF cycle whereas $\overline{IO}/\overline{M}$, S_0 , and S_1 are stable.
 2. Loading equivalent to 50 pF + 1 TTL input.
 3. All timings are measured at output voltage
 $V_L = 0.8 \text{ V}$, $V_H = 2.0 \text{ V}$.
 4. To calculate timing specifications at other value of t_{CYC} use Table 4.

TABLE 4. BUS TIMING SPECIFICATION AS A T_{CYC} DEPENDENT

Symbol	Unit	Symbol	Unit	Symbol	Unit
t_{INT}	ns	t_{INT}	ns	t_{INT}	ns
t_{LA}	ns	t_{LA}	ns	t_{LA}	ns
t_{LC}	ns	t_{LC}	ns	t_{LC}	ns
t_{LL}	ns	t_{LL}	ns	t_{LL}	ns
t_{LCK}	ns	t_{LCK}	ns	t_{LCK}	ns
t_{LC}	ns	t_{LC}	ns	t_{LC}	ns
t_{AD}	ns	t_{AD}	ns	t_{AD}	ns
t_{RD}	ns	t_{RD}	ns	t_{RD}	ns
t_{RAE}	ns	t_{RAE}	ns	t_{RAE}	ns
t_{CA}	ns	t_{CA}	ns	t_{CA}	ns
t_{DW}	ns	t_{DW}	ns	t_{DW}	ns
t_{WD}	ns	t_{WD}	ns	t_{WD}	ns
t_{CC}	ns	t_{CC}	ns	t_{CC}	ns
t_{CL}	ns	t_{CL}	ns	t_{CL}	ns
t_{ARY}	ns	t_{ARY}	ns	t_{ARY}	ns
t_{HACK}	ns	t_{HACK}	ns	t_{HACK}	ns
t_{HABF}	ns	t_{HABF}	ns	t_{HABF}	ns
t_{HABE}	ns	t_{HABE}	ns	t_{HABE}	ns
t_{AC}	ns	t_{AC}	ns	t_{AC}	ns
t_L	ns	t_L	ns	t_L	ns
t_H	ns	t_H	ns	t_H	ns
t_{RV}	ns	t_{RV}	ns	t_{RV}	ns
t_{LDR}	ns	t_{LDR}	ns	t_{LDR}	ns

Note: N is equal to the total WAIT states.

$$T = t_{CYC}$$

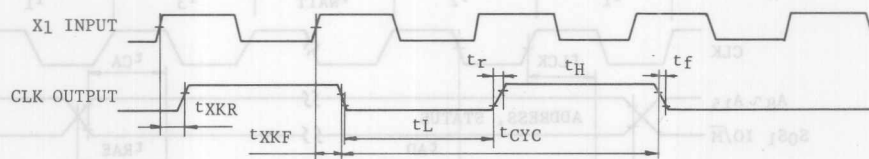


FIGURE 4. CLOCK TIMING WAVEFORM

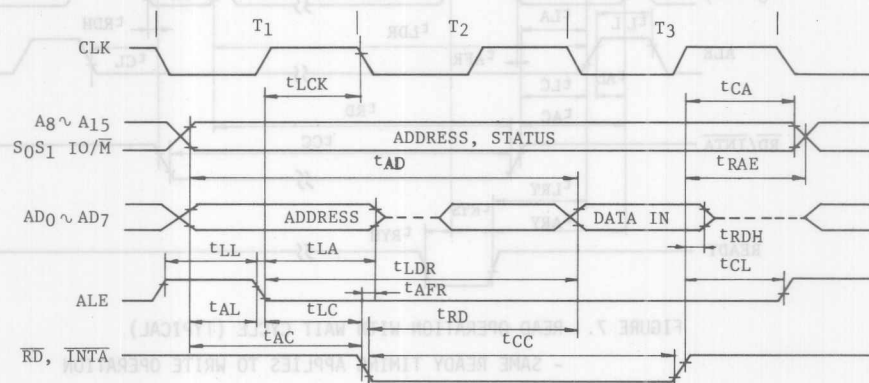


FIGURE 5. READ OPERATION

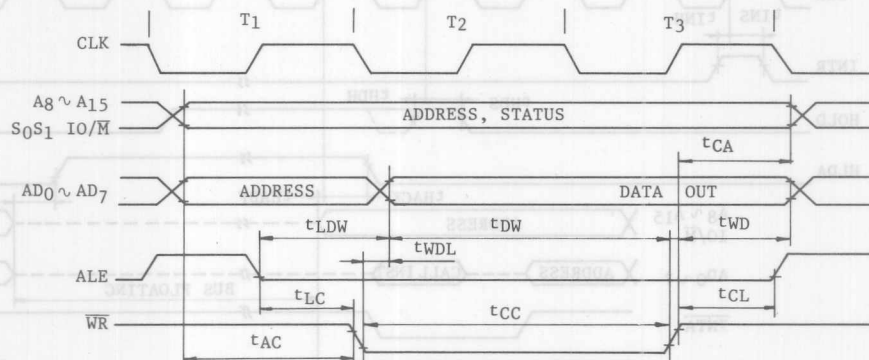


FIGURE 6. WRITE OPERATION

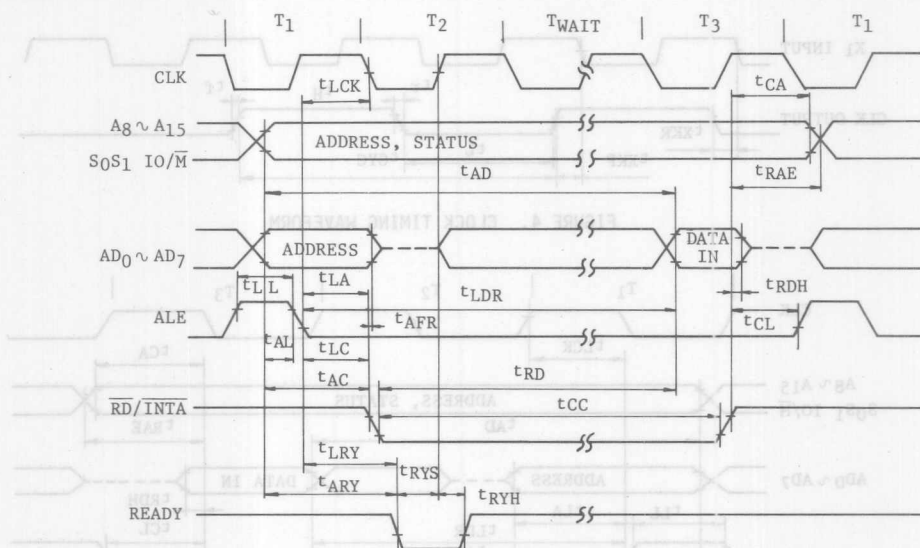


FIGURE 7. READ OPERATION WITH WAIT CYCLE (TYPICAL)

- SAME READY TIMING APPLIES TO WRITE OPERATION

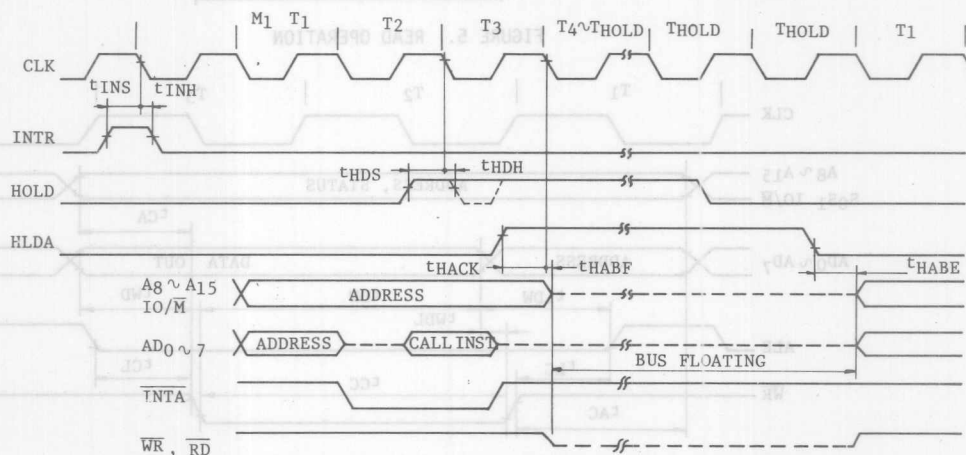
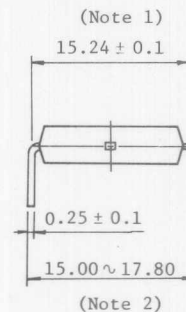
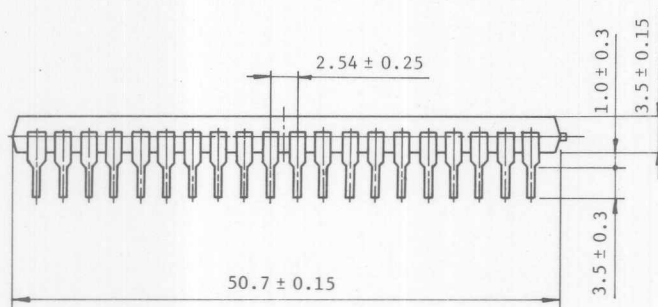
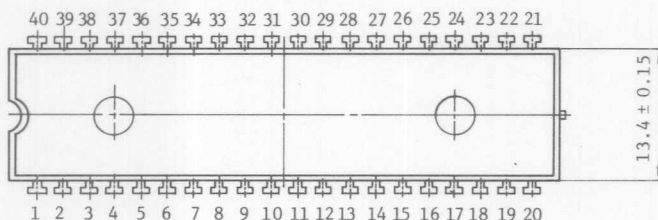


FIGURE 8. INTERRUPT AND HOLD TIMING

OUTLINE DRAWING

40 Pins Plastic Package

Unit in mm



- Notes:
1. This dimension shows the center of curvature of leads
 2. This dimension shows spread of leads.
 3. All dimensions are in millimeters.

8BIT MICROPROCESSOR

PERIPHERALS (NMOS)



INTEGRATEDCIRCUIT

TECHNICAL DATA

TOSHIBA MOS DIGITAL INTEGRATED CIRCUIT

TMP8155P

TMP8156P

N-CHANNEL SILICON GATE MOS

2048 BIT STATIC MOS RAM WITH I/O PORTS AND TIMER

GENERAL DESCRIPTION

The TMP 8155P/8156P are RAM including I/O ports and counter/timer on the chip for using in the TLCS-85A microcomputer system. The RAM portion is designed with 2K bit static cells organized as 256 x 8. The 14 bit programmable counter/timer is the down counter. It provides either a square wave or terminal count pulse for the cpu system depending on timer mode.

The I/O portion consists of 2 programmable 8 bit I/O ports and 1 programmable 6 bit I/O port. The programmable I/O ports can be operated by BASIC MODE and STROBE MODE.

FEATURES

- Compatible with Intel's 8155/8516
- Single +5 V Power Supply
- Access Time: 400 ns (MAX.)
- Internal Address Latch
- 2 Programmable 8 Bit I/O Ports and 1 Programmable 6 Bit I/O Port.
- 256 Word x 8 Bits RAM
- Programmable 14 Bit Binary Counter/Timer
- Multiplexed Address and Data Bus
- Chip Enable Active High (TMP8156P) or Low (TMP8155P)
- 40 pin DIP

PIN CONNECTION (TOP VIEW)

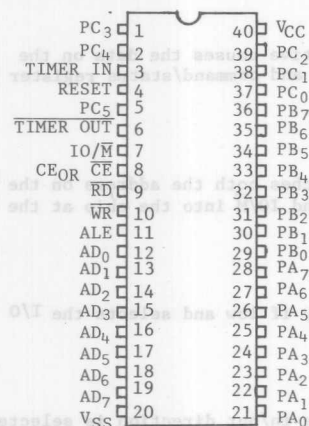


FIGURE 1 TMP8155P/8156P PINOUT DIAGRAM

BLOCK DIAGRAM

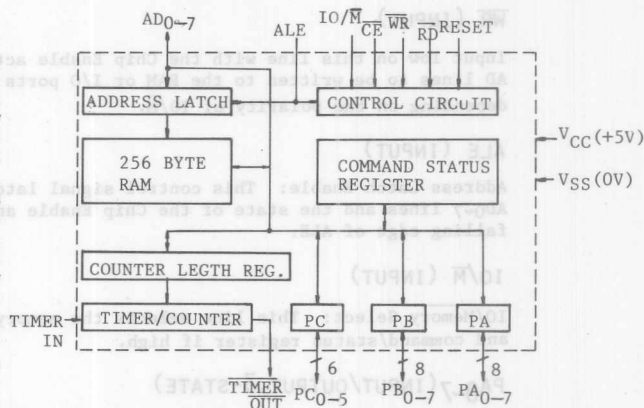


FIGURE 2 TMP8155P/8156P FUNCTIONAL BLOCK DIAGRAM

PIN NAMES AND PIN DESCRIPTION

RESET (INPUT)

The Reset signal is a pulse provided by the TMP8085A to initialize the system. Input high on this line resets the chip and initializes the three I/O ports to input mode. The width of RESET pulse should typically be two TMP8085A clock cycle times.

AD_{0~7} (INPUT / OUTPUT, 3-STATE)

These are 3-state Address/Data lines that interface with the CPU lower 8-bit Address/Data Bus. The 8-bit address is latched into the address latch on the falling edge of the ALE. The address can be applied to the memory section or the I/O section depending on the polarity of the I/O_M input signal. The 8-bit data is either written into the chip or read from the chip depending on the status of WR or RD input signal.

CE OR $\overline{\text{CE}}$ (INPUT)

Chip Enable: On the TMP8155P, this pin is $\overline{\text{CE}}$ and is ACTIVE LOW. On the TMP8156P, this pin is CE and is ACTIVE HIGH.

$\overline{\text{RD}}$ (INPUT)

Input low on this line with the Chip Enable active enables the AD_{0~7} buffers. If I/O_M pin is low, the RAM content will be read out to the AD bus. Otherwise the content of the selected I/O port or command/status register will be read to the AD bus.

$\overline{\text{WR}}$ (INPUT)

Input low on this line with the Chip Enable active causes the data on the AD lines to be written to the RAM or I/O ports and command/status register depending on the polarity of I/O_M.

ALE (INPUT)

Address Latch Enable: This control signal latches both the address on the AD_{0~7} lines and the state of the Chip Enable and I/O_M into the chip at the falling edge of ALE.

I/O_M (INPUT)

I/O/Memory Select: This line selects the memory if low and selects the I/O and command/status register if high.

PA_{0~7} (INPUT/OUTPUT, 3-STATE)

These 8 pins are general purpose I/O pins. The in/out direction is selected by programming the Command Register.

PB0~7 (INPUT/OUTPUT, 3-STATE)

These 8 pins are general purpose I/O pins. The in/out direction is selected by programming the Command Register.

PC0~5 (INPUT/OUTPUT, 3-STATE)

These 6 pins can function as either input port, output port, or as control signal for PA and PB. Programming is done through the Command Register. When PC0~5 are used as control signals, they are defined the following:

- PC0 - A INTR (Port A Interrupt)
- PC1 - A BF (Port A Buffer Full)
- PC2 - A STB (Port A Strobe)
- PC3 - B INTR (Port B Interrupt)
- PC4 - B BF (Port B Buffer Full)
- PC5 - B STB (Port B Strobe)

TIMER IN (INPUT)

This is the input to the counter-timer.

TIMER OUT (OUTPUT)

This pin is the timer output. This output can be either a square wave or a pulse depending on the timer mode.

V_{CC} (Power)

+5 volt supply

V_{SS} (Power)

Ground Reference

FUNCTIONAL DESCRIPTION

PROGRAMMING OF THE COMMAND REGISTER

The command register consists of eight latches. Four bits (0-3) define the mode of the ports, two bits (4-5) enable or disable the interrupt from port C when it acts as control port, and the last two bits (6-7) are for the timer.

The command register contents can be altered at any time by using the I/O address XXXX000 during a WRITE operation. The function of each bit of the command byte is defined in FIGURE 3.

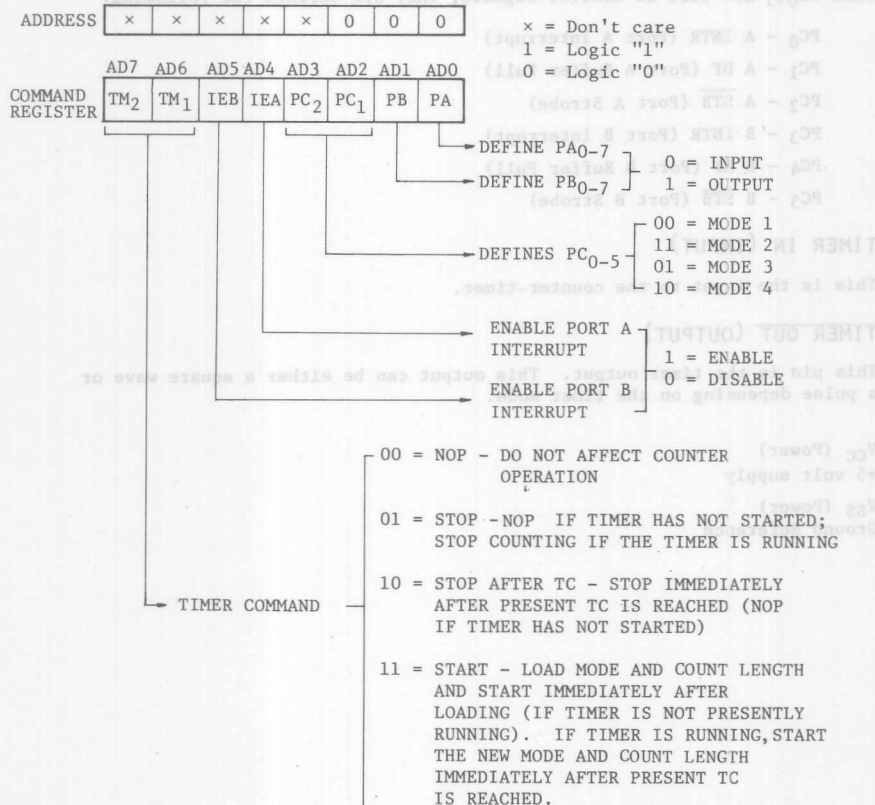


FIGURE 3 COMMAND REGISTER BIT ASSIGNMENT

INPUT/OUTPUT SECTION

COMMAND/STATUS REGISTER (C/S)

Both register have the common address XXXXX000 . When the C/S registers are selected during WRITE operation, a command is written into the C/S register. The contents of this register are not accessible through the pins. When the C/S is selected during a READ operation, the status information of the I/O ports and the timer becomes available on the AD_{0-7} lines.

- PA Register — This register can be programmed to be either input or output ports depending on the status of the contents of the C/S Register. Also depending on the command, this port can operate in either the basic mode or the strobed mode (See timing diagram). The I/O pins assigned in relation to this register are PA_{0-7} . The address of this register is XXXXX001 .
- PB Register — This register functions the same as PA Register. The I/O pins assigned are PB_{0-7} . The address of this register is XXXXX010 .
- PC Register — This register has the address XXXXX011 and contains only 6-bits. The 6-bits can be programmed to be either input ports, output ports or as control signals for PA and PB by properly programming the AD_2 and AD_3 bits of the C/S register.

When PC_{0-5} is used as a control port, 3-bits are assigned for Port A and 3 for Port B. The first bit is an interrupt that the TMP8155P/8156P issues.

The second is an output signal indicating whether the buffer is full or empty, and the third is an input pin to accept a strobe for the strobed input mode. See Table 2.

When the port C is programmed to either MODE 3 or MODE 4, the control signals for PA and PB are initialized as follows:

MODE \ CONTROL	BF	INTR	STB
INPUT MODE	Low	Low	Input Control
OUTPUT MODE	Low	High	Input Control

To summarize, the register's assignments are shown TABLE 1.

TABLE 1 I/O PORT ADDRESSING SCHEME

I/O ADDRESS								P INOUTS	SELECT ION	NO. OF BITS
A ₇	A ₆	A ₅	A ₄	A ₃	A ₂	A ₁	A ₀			
X	X	X	X	X	0	0	0	Internal	Command/Status Register	8
X	X	X	X	X	0	0	1	PA ₀₋₇	General Purpose I/O Port A	8
X	X	X	X	X	0	1	0	PB ₀₋₇	General Purpose I/O Port B	8
X	X	X	X	X	0	1	1	PC ₀₋₇	General Purpose I/O Port or Control	6
X	X	X	X	X	1	0	0		Low-Order 8 bits of Timer Count	
X	X	X	X	X	1	0	1		High 6 bits/2 bits of Timer Count	

TABLE 2 TABLE OF PORT CONTROL ASSIGNMENT

Pin	MODE 1	MODE 2	MODE 3	MODE 4
PC0	Input Port	Output Port	A INTR (Port A Interrupt)	A INTR (Port A Interrupt)
PC1	Input Port	Output Port	A BF (Port A Buffer Full)	A BF (Port A Buffer Full)
PC2	Input Port	Output Port	A $\overline{\text{STB}}$ (Port A strobe)	A $\overline{\text{STB}}$ (Port A Strobe)
PC3	Input Port	Output Port	Output Port	B INTR (Port B Interrupt)
PC4	Input Port	Output Port	Output Port	B BF (Port B Buffer Full)
PC5	Input Port	Output Port	Output Port	B $\overline{\text{STB}}$ (Port B Strobe)

TIMER SECTION

The timer is a 14-bit down-counter that counts the 'timer input' pulses and provides either a square wave or pulse when terminal count (TC) is reached.

The timer has the I/O address XXXXX100 for the low order byte of the register and the I/O address XXXXX101 for the high order byte of the register.

To program the timer, the COUNT LENGTH REGISTER is loaded first, one byte at a time, by selecting the timer addresses. Bits 0-13 will specify the length of the next count and bits 14-15 will specify the timer output mode. The value loaded into the count length register can have any value from 2H through 3FFFH in bits 0-13.

time, by selecting the timer addresses. Bits 0-13 will specify the length next count and bits 14-15 will specify the timer output mode. The value loaded into the count length register can have any value from 2_H through 3FFF_H in bits 0-13.

TIMER MODE	MSB OF COUNT LENGTH
0	0
1	1
2	2
3	3
4	4
5	5
6	6
7	7
8	8
9	9
10	10
11	11
12	12
13	13
14	14
15	15

FIGURE 5 TIMER FORMAT

FIGURE 5 TIMER FROMAT

FIGURE 6 ASYMMETRICAL SQUARE-WAVE OUTPUT RESULTING FROM COUNT OF 5



Bits 6-7 (TM2 and TM1) of command register contents are used to start and stop the counter. There are four commands to choose from;

TM2	TM1	
0	0	NOP: Do not affect counter operation.
0	1	STOP: NOP if timer has not started; stop counting if the timer is running.
1	0	STOP AFTER TC: Stop immediately after present TC is reached. (NOP if timer has not started)
1	1	START: Load mode and count length and start immediately after loading (if timer is not presently running). If timer is running, start the new mode and count length immediately after present TC is reached.

Note that while the counter is counting, you may load a new count and mode into the count length registers. Before the new count and mode will be used by the counter, you must issue a START command to the counter. This applies even though you may only want to change the count and use the previous mode.

The counter in the TMP8155P/8156P is not initialized to any particular mode or count when hardware RESET occurs, but RESET does stop the counting. Therefore you must issue a START command via the C/S register, because counting cannot begin following RESET.

Please note that the timer circuit on the TMP8155P/8156P chip is designed to be a square-wave timer, not an event counter. To achieve this, it counts down by twos twice in completing one cycle. Thus, its registers do not contain values directly representing the number of TIMER IN pulses received. You cannot load an initial value of 1 into the count register and cause the timer to operate, as its terminal count value is 10 (binary). After the timer has started counting down, the values residing in the count registers can be used to calculate the actual number of TIMER IN pulses required to complete the timer cycle if desired. To obtain the remaining count, perform the following operations in order:

1. Stop the count.
2. Read in the 16-bit value from the count length registers.
3. Reset the upper two mode bits.
4. Reset the carry and rotate right one position all 16 bits through carry.
5. If carry is set, add 1/2 of the full original count (1/2 full count-1 if full count is odd.)

Note: If you started with an odd count and you read the count length register before the third count pulse occurs, you will not be able to discern whether one or two counts has occurred. Regardless of this, the TMP8155P/8156P always counts out the right number of pulses in generating the TIMER OUT waveforms.



INTEGRATED CIRCUIT

TECHNICAL DATA

TMP8155P, TMP8156P

ABSOLUTE MAXIMUM RATINGS

Symbol	Item	Rating
V _{CC}	V _{CC} Supply Voltage with Respect to V _{SS}	-0.5V to +7.0V
V _{IN}	Input Voltage with Respect to V _{SS}	-0.5V to +7.0V
V _{OUT}	Output Voltage with Respect to V _{SS}	-0.5V to +7.0V
P _D	Power Dissipation	1.5W
T _{SOLDER}	Soldering Temperature (Soldering Time 10 sec.)	260°C
T _{STG}	Storage Temperature	-55°C to +150°C
T _{OPR}	Operating Temperature	0°C to +70°C

D.C. CHARACTERISTICS

T_A = 0°C to +70°C, V_{CC} = +5V ± 5%

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V _{IL}	Input Low Voltage		-0.5		0.8	V
V _{IH}	Input High Voltage		2.0		V _{CC} +0.5	V
V _{OL}	Output Low Voltage	I _{OL} = 2mA			0.45	V
V _{OH}	Output High Voltage	I _{OH} = -400μA	2.4			V
I _{IL}	Input Leakage	V _{IN} = V _{CC} to 0V			±10	μA
I _{LO}	Output Leakage Current	0.45V ≤ V _{OUT} ≤ V _{CC}			±10	μA
I _{CC}	V _{CC} Supply Current				180	mA
I _{IL} (CE)	Chip Enable Leakage					
	8155 8156	V _{IN} = V _{CC} to 0V.			+100 -100	μA μA

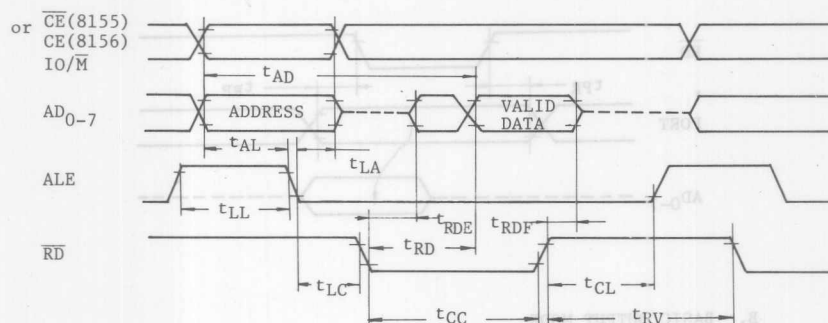
A.C. CHARACTERISTICS

TA=0°C to +70°C, VCC=+5V±5%

Symbol	Parameters	Test Condition	Min.	Typ.	Max.	Units
t _{AL}	Address to Latch Set Up Time		50			ns
t _{LA}	Address Hold Time after Latch		80			ns
t _{LC}	Latch to READ/WRITE Control		100			ns
t _{RD}	Valid Data out Delay from READ Control				170	ns
t _{AD}	Address Stable to Data Out Valid				400	ns
t _{LL}	Latch Enable Width		100			ns
t _{RDF}	Data Bus Float After READ		0		100	ns
t _{CL}	READ/WRITE control Latch Enable		20			ns
t _{CC}	READ/WRITE Control Width		250			ns
t _{DW}	Data In to WRITE Set Up Time		150			ns
t _{WD}	Data in Hold Time After WRITE	150pF Load	0			ns
t _{RV}	Recovery Time Between Controls		300			ns
t _{WP}	WRITE to Port Output				400	ns
t _{PR}	Port Input Setup Time		70			ns
t _{RP}	Port Input Hold Time		50			ns
t _{SBF}	Strobe to Buffer Full				400	ns
t _{SS}	Strobe Width		200			ns
t _{RBE}	READ to Buffer Empty				400	ns
t _{SI}	Strobe to INTR On				400	ns
t _{RDI}	READ to INTR Off				400	ns
t _{PSS}	Port Setup Time to Strobe		50			ns
t _{PHS}	Port Hold Time After Strobe		120			ns
t _{SBE}	Strobe to Buffer Empty				400	ns
t _{WBF}	WRITE to Buffer Full				400	ns
t _{WI}	WRITE to INTR Off				400	ns
t _{TL}	TIMER-IN to TIMER-OUT Low				400	ns
t _{TH}	TIMER-IN to TIMER-OUT High				400	ns
t _{RDE}	Data Bus Enable from READ Control		10			ns
t _L	TIMER-IN Low Time		80			ns
t _H	TIMER-IN High Time		120			ns

TIMING WAVEFORMS

A. READ CYCLE



B. WRITE CYCLE

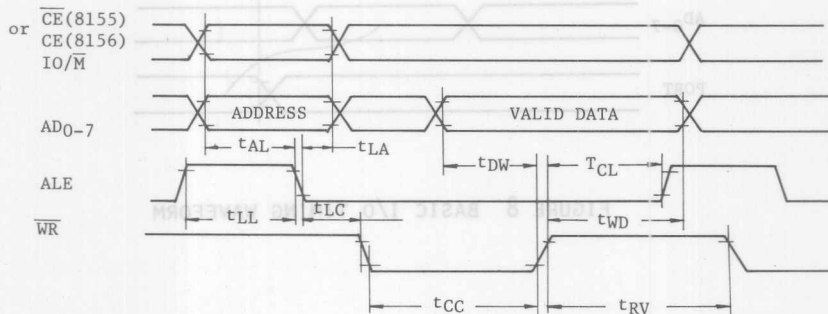
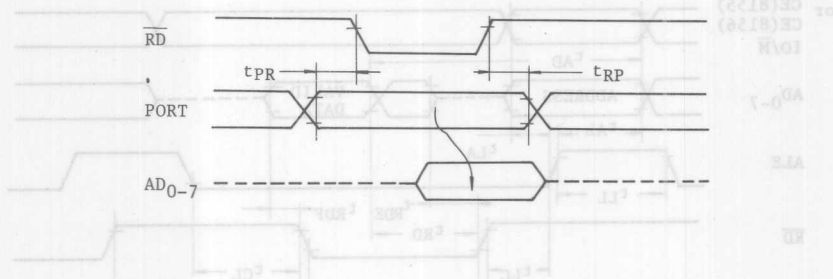


FIGURE 7 READ/WRITE TIMING DIAGRAMS

A. BASIC INPUT MODE



B. BASIC OUTPUT MODE

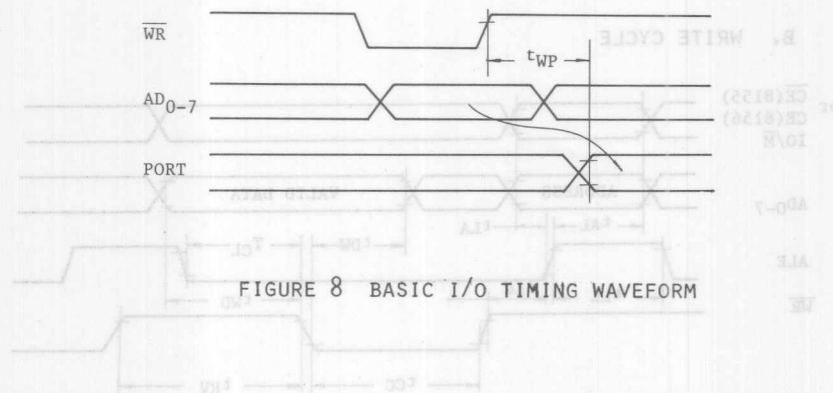
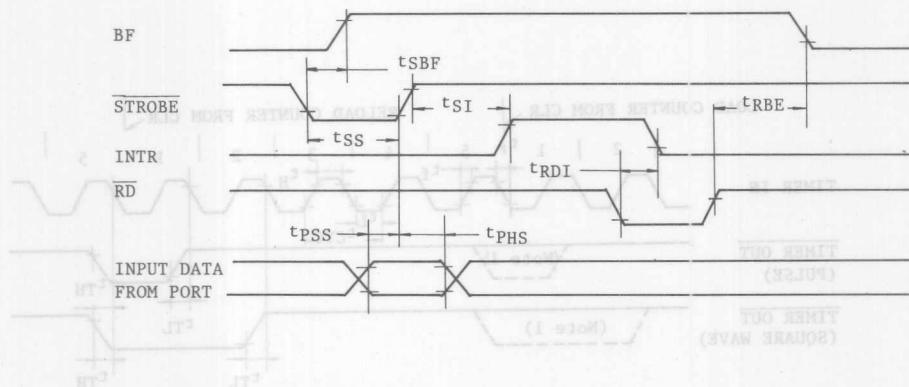


FIGURE 8 BASIC I/O TIMING WAVEFORM

A. STROBED INPUT MODE



B. STROBED OUTPUT MODE

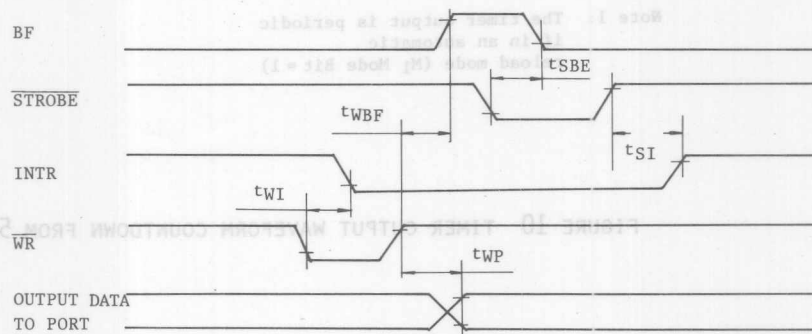
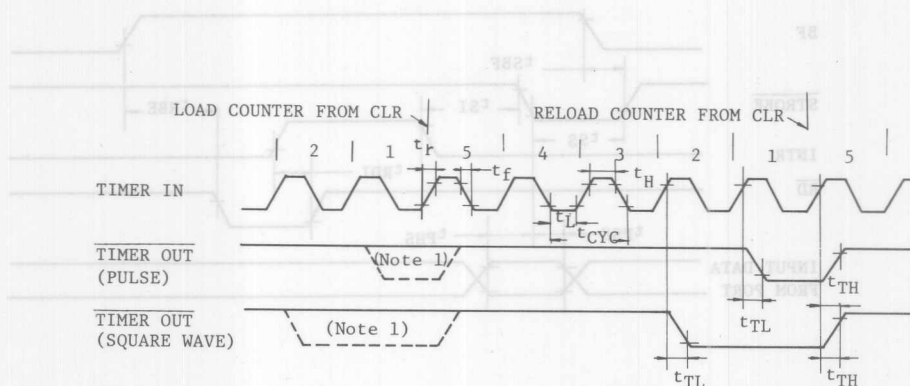


FIGURE 9 STROBED I/O TIMING WAVEFORM

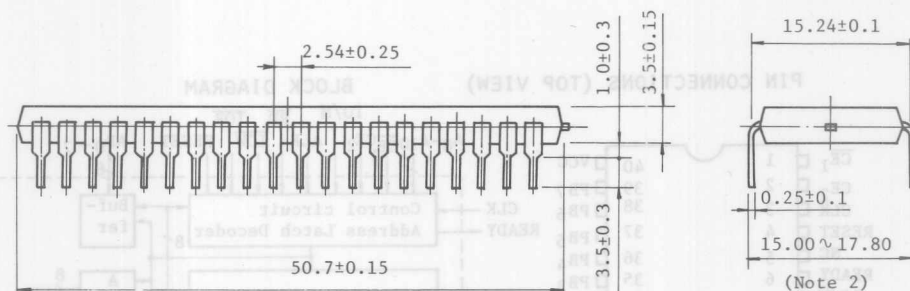
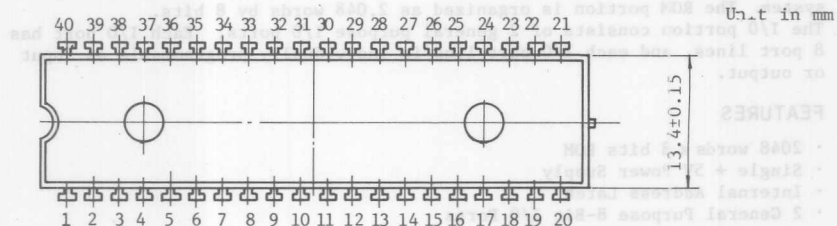


Note 1: The timer output is periodic
if in an automatic
reload mode (M_1 Mode Bit = 1)

FIGURE 10 TIMER OUTPUT WAVEFORM COUNTDOWN FROM 5 TO 1

OUTLINE DRAWING

40 Pins Plastic Package



- Note: 1. This dimension shows the center of curvature of leads.
2. This dimension shows spread of leads.
3. All dimensions are in millimeters.



INTEGRATED CIRCUIT

TECHNICAL DATA

TOSHIBA MOS DIGITAL INTEGRATED CIRCUIT

TMP8355P

N-CHANNEL SILICON GATE MOS

16,384 BIT ROM WITH I/O PORTS

GENERAL DESCRIPTION

The TMP8355P is a ROM and I/O chip to be used in the TLCS-85A microcomputer system. The ROM portion is organized as 2,048 words by 8 bits.

The I/O portion consists of 2 general purpose I/O ports. Each I/O port has 8 port lines, and each I/O port line is individually programmable as input or output.

FEATURES

- 2048 words x 8 bits ROM
- Single + 5V Power Supply
- Internal Address Latch
- 2 General Purpose 8-Bit I/O Ports
- Access Time : 400 ns (MAX.)
- Each I/O Port Line Individually Programmable as Input or Output
- Multiplexed Address and Data Bus
- 40 pin DIP
- Compatible with Intel's 8355

PIN CONNECTIONS (TOP VIEW)

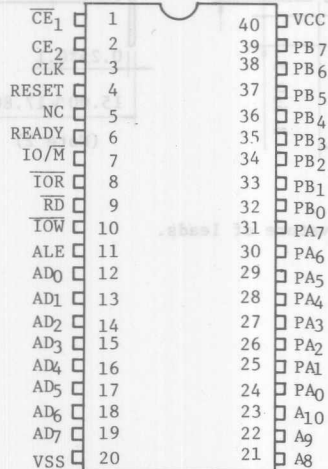


FIGURE 1 TMP8355P PINOUT DIAGRAM

BLOCK DIAGRAM

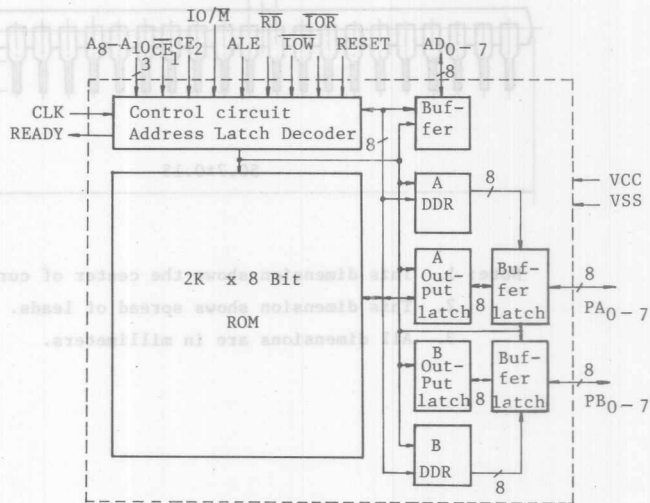


FIGURE 2 TMP8355P FUNCTIONAL BLOCK DIAGRAM

PIN NAMES AND PIN DESCRIPTION

ALE (INPUT)

When Address Latch Enable goes high, AD_{0-7} , IO/\overline{M} , A_{8-10} , CE_2 , and \overline{CE}_1 enter the address latches. The signals (AD_{0-7} , IO/\overline{M} , A_{8-10} , CE_2 , \overline{CE}_1) are latched in at the trailing edge of ALE.

AD_{0-7} (INPUT/OUTPUT, 3-STATE)

Bi-directional Address/Data bus. The lower 8-bits of the ROM or I/O address are applied to the bus lines when ALE is high. During an I/O cycle, Port A or B are selected based on the latched value of AD_0 . If \overline{RD} or \overline{IOR} is low when the latched Chip Enables are active, the output buffers present data on the bus.

A_{8-10} (INPUT)

These are the high order bits of the ROM address. They do not affect I/O operations.

\overline{CE}_1 , CE_2 (INPUT)

CHIP ENABLE INPUTS: \overline{CE}_1 is active low and CE_2 is active high. Both chip enables must be active to permit accessing the ROM.

IO/\overline{M} (INPUT)

If the latched IO/\overline{M} is high when \overline{RD} is low, the output data comes from an I/O port. If it is low the output data comes from the ROM.

\overline{RD} (INPUT)

If the latched Chip Enables are active when \overline{RD} goes low, the AD_{0-7} output buffers are enabled and output either the selected ROM location or I/O port. When both \overline{RD} and \overline{IOR} are high, the AD_{0-7} output buffers are 3-stated.

\overline{IOW} (INPUT)

If the latched Chip Enables are active, a low on \overline{IOW} causes the output port pointed to by the latched value of AD_0 to be written with the data on AD_{0-7} . The state of IO/\overline{M} is ignored.

CLK (INPUT)

The CLK is used to force the READY into its high state after it has been forced low by \overline{CE}_1 low, CE_2 high, and ALE high.



READY (OUTPUT, 3-STATE)

READY is a 3-state output controlled by \overline{CE}_1 , CE_2 , ALE and CLK.

READY is forced low when the Chip Enables are active during the time ALE is high, and remains low until the rising edge of the next CLK.

PA₀ - PA₇ (INPUT/OUTPUT, 3-STATE)

These are general purpose I/O pins. Their input/output direction is determined by the contents of Data Direction Register (DDR). Port A is selected for write operations when the Chip Enables are active, and \overline{IOW} is low and a 0 was previously latched from AD₀.

Read operation is selected by either \overline{IOR} low, active Chip Enables and AD₀ low, or \overline{IOW} high, \overline{RD} low, active Chip Enables, and AD₀ low.

PB₀ - PB₇ (INPUT/OUTPUT, 3-STATE)

This general purpose I/O port is identical to Port A except that it is selected by a 1 latched from AD₀.

RESET (INPUT)

In normal operation, an input high on RESET causes all pins in Ports A and B to assume input mode (clear DDR register).

 \overline{IOR} (INPUT)

When the Chip Enables are active, a low on \overline{IOR} will output the selected I/O port onto the AD bus. \overline{IOR} low performs the same function as the combination of \overline{IOW} high and \overline{RD} low. When \overline{IOR} is not used in a system, \overline{IOR} should be tied to V_{CC} "1".

V_{CC} (POWER)

+5 volt supply.

V_{SS} (POWER)

Ground Reference



INTEGRATED CIRCUIT

TECHNICAL DATA

TMP8355P

TECHNICAL DATA



FUNCTIONAL DESCRIPTION

ROM SECTION

The TMP8355P contains an 8-bit address latch which allows it to interface directly to TLCS-85A microcomputer system without additional hardware.

The ROM portion of the chip is addressed by the 11-bit address (A8-10, AD₀₋₇) and CE. The address, IO/ \overline{M} , CE₂ and $\overline{CE_1}$ are latched into the address latches on falling edge of ALE. If the Chip Enables (CE₂ and $\overline{CE_1}$) are active and IO/ \overline{M} is low when \overline{RD} goes low, the contents of the ROM location addressed by the latched address are put out on the AD₀₋₇ lines.

I/O SECTION

The I/O port portion consists of two 8-bit I/O ports and two 8-bit Data Direction Registers (DDR). The I/O portion of the chip is addressed by the latched value of AD₀ and AD₁. Contents of Port A and Port B can be read and written, but the contents of DDR's cannot be read. The contents of the selected I/O port can be read out when the latched Chip Enable are active and either \overline{RD} goes low with IO/ \overline{M} high, or \overline{IOR} goes low.

The two 8-bit DDR's (DDRA and DDRB) are used to determine the input/output status of each pin in the corresponding port.

A '0' specifies an input mode and a '1' specifies an output mode.

The two 8-bit DDR's are cleared by RESET signal. The table 1 summarize Port and DDR designation.

TABLE 1, SELECTION OF PORT AND DDR DESIGNATION

AD ₁	AD ₀	Selection
0	0	Port A
0	1	Port B
1	0	Port A Data Direction Register (DDR A)
1	1	Port B Data Direction Register (DDR B)



INTEGRATED CIRCUIT

TECHNICAL DATA

TMP8355P

TECHNICAL DATA

ABSOLUTE MAXIMUM RATINGS

Symbol	Item	Rating
V_{CC}	V_{CC} Supply Voltage with Respect to V_{SS}	-0.5V to 7.0V
V_{IN}	Input Voltage with Respect to V_{SS}	-0.5V to 7.0V
V_{OUT}	Output Voltage with Respect to V_{SS}	-0.5V to 7.0V
P_D	Power Dissipation	1.5W
T_{SOLDER}	Soldering Temperature (Soldering Time 10sec.)	260°C
T_{STG}	Storage Temperature	-55°C to +150°C
T_{OPR}	Operating Temperature	0°C to +70°C

D.C. CHARACTERISTICS

 $T_A = 0^\circ\text{C to } 70^\circ\text{C}$, $V_{CC} = 5V \pm 5\%$

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V_{IL}	Input Low Voltage		-0.5		0.8	V
V_{IH}	Input High Voltage		2.0		$V_{CC} + 0.5$	V
V_{OL}	Output Low Voltage	$I_{OL} = 2\text{mA}$			0.45	V
V_{OH}	Output High Voltage	$I_{OH} = -400\mu\text{A}$	2.4			V
I_{IL}	Input Leakage Current	$V_{IN} = V_{CC} \text{ to } 0V$			± 10	μA
I_{LO}	Output Leakage Current	$0.45 \leq V_{out} \leq V_{CC}$			± 10	μA
I_{CC}	V_{CC} Supply Current				180	mA

TABLE 1. SELECTION OF PORT AND DOR DESCRIPTION

AD ₀	AD ₁	Selection
0	0	Port A
0	1	Port B
1	0	Port A Data Direction Register (DDR A)
1	1	Port B Data Direction Register (DDR B)



INTEGRATEDCIRCUIT

TECHNICAL DATA

TMP8355P

TECHNICAL DATA

A.C. CHARACTERISTICS

 $T_A = 0^\circ\text{C to } 70^\circ\text{C}$, $V_{CC} = 5\text{V} \pm 5\%$

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
t_{CYC}	Clock Cycle Time		320			ns
t_L	CLK Low Width		80			ns
t_H	CLK High Width		120			ns
t_r, t_f	CLK Rise and Fall Time				30	ns
t_{AL}	Address to Latch Set Up Time		50			ns
t_{LA}	Address Hold Time after Latch		80			ns
t_{LC}	Latch to READ/WRITE Control		100			ns
t_{RD}	Valid Data Out Delay from READ Control	150pF			170	ns
t_{AD}	Address Stable to Data Out Valid	Load			400	ns
t_{LL}	Latch Enable Width		100			ns
t_{RDF}	Data Bus Float after READ		0		100	ns
t_{CL}	READ/WRITE Control to Latch Enable		20			ns
t_{CC}	READ/WRITE Control Width		250			ns
t_{DW}	Data In to WRITE Set Up Time		150			ns
t_{WD}	Data In Hold Time after WRITE		10			ns
t_{WP}	WRITE to Port Output				400	ns
t_{PR}	Port Input Set Up Time		50			ns
t_{RP}	Port Input Hold Time		50			ns
t_{RYH}	READY Hold Time		0		160	ns
t_{ARY}	ADDRESS (CE) to READY				160	ns
t_{RV}	Recovery Time between Controls		300			ns
t_{RDE}	Data Out Delay from READ Controls		10			ns
t_{LCK}	ALE Low during CLK High		100			ns

TIMING WAVEFORMS

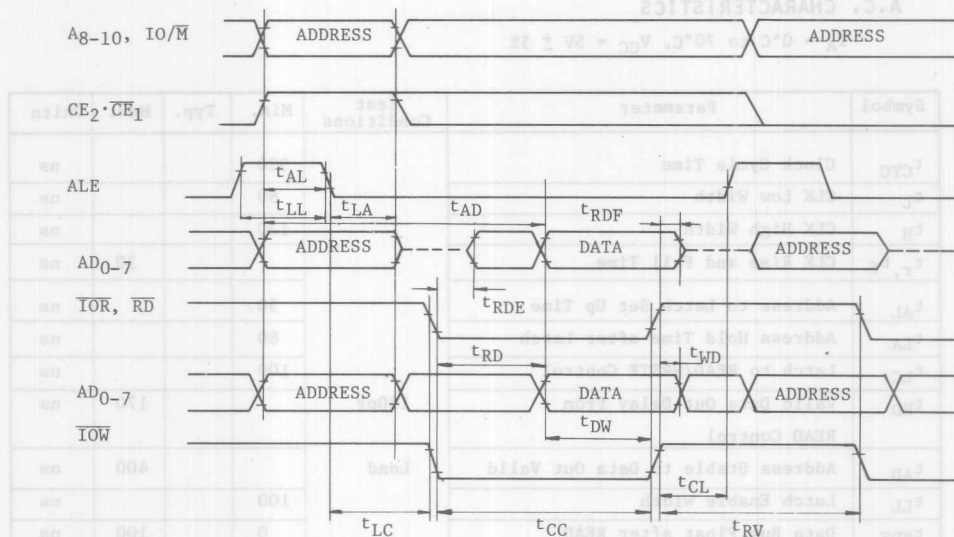


FIGURE 3 PROM READ, I/O READ, AND WRITE TIMING

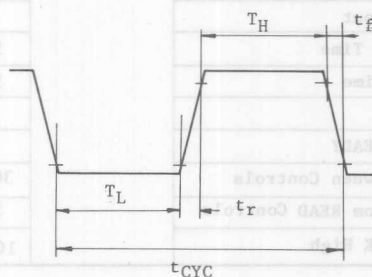


FIGURE 4 CLOCK SPECIFICATION FOR TMP8355P

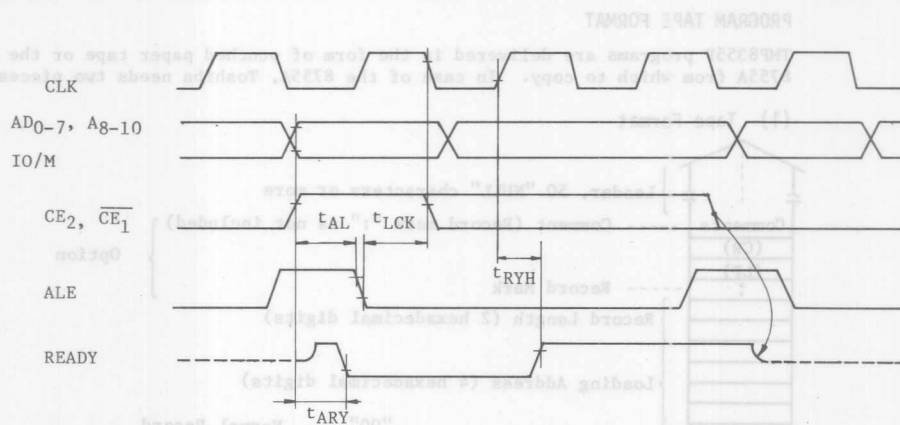
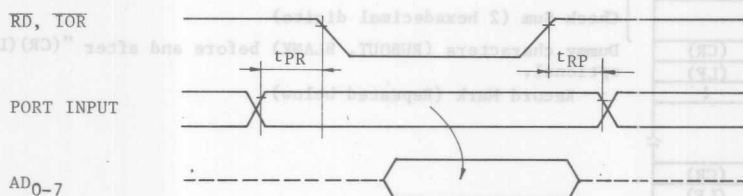


FIGURE 5 WAIT STATE TIMING (READY = 0)

A. INPUT MODE



B. OUTPUT MODE

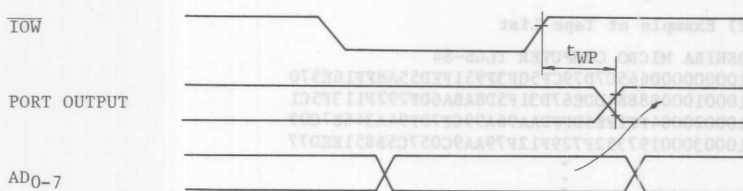
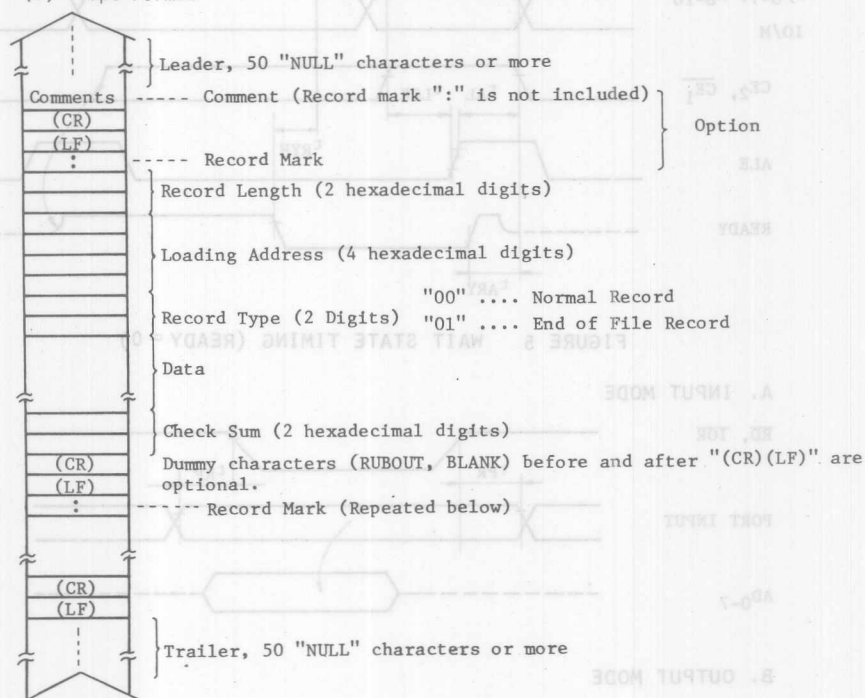


FIGURE 6 I/O PORT TIMING

PROGRAM TAPE FORMAT

TMP8355P programs are delivered in the form of punched paper tape or the 8755A from which to copy. In case of the 8755A, Toshiba needs two pieces.

(1) Tape Format



(2) Example of Tape List

TOSHIBA MICRO COMPUTER TLCS-84

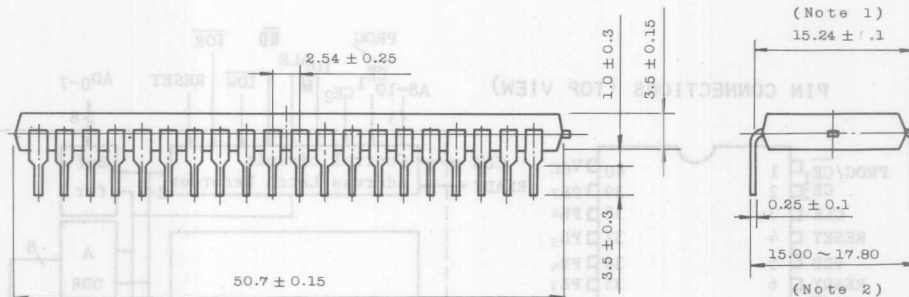
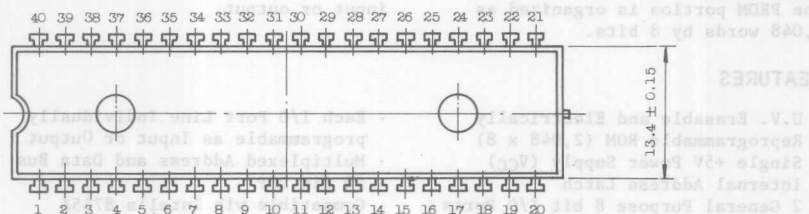
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:10003000197352F729F12F79AA9C057C5B851EED77
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⋮

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:1003E000B53D42E0EC32546025B7308CDD52063D1D
:1003F000B4BE9E9E345B6138060B20VC372BF60BD6
:00000001FF
```

OUTLINE DRAWING

40 Pins Plastic Package



- Note: 1. This dimension shows the center of curvature of leads.
2. This dimension shows spread of leads.
3. All dimensions are in millimeters.



INTEGRATED CIRCUIT

TECHNICAL DATA

TOSHIBA MOS DIGITAL INTEGRATED CIRCUIT

TMP8755AC

N-CHANNEL SILICON GATE MOS

16,384 BIT EPROM WITH I/O PORTS

GENERAL DESCRIPTION

The TMP8755AC is an erasable and electrically reprogrammable ROM (EPROM) and I/O chip to be used in the TLCS-85A microcomputer system. The PROM portion is organized as 2,048 words by 8 bits.

The I/O portion consists of two general purpose I/O ports. Each I/O port has eight port lines; and each I/O port line is individually programmable as input or output.

FEATURES

- U.V. Erasable and Electrically Reprogrammable ROM (2,048 x 8)
- Single +5V Power Supply (VCC)
- Internal Address Latch
- 2 General Purpose 8 bit I/O Ports
- Access Time: 450 ns (MAX.)
- Each I/O Port Line Individually programmable as Input or Output.
- Multiplexed Address and Data Bus
- 40 pin DIP
- Compatible with Intel's 8755A

BLOCK DIAGRAM

PIN CONNECTIONS (TOP VIEW)

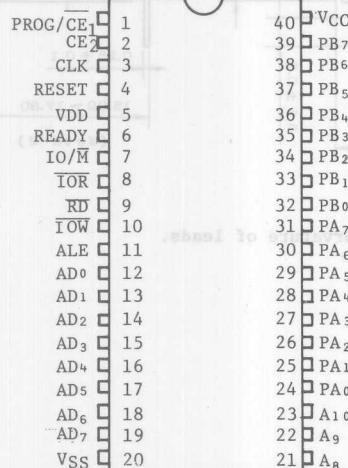


FIGURE 1 TMP8755AC PINOUT DIAGRAM

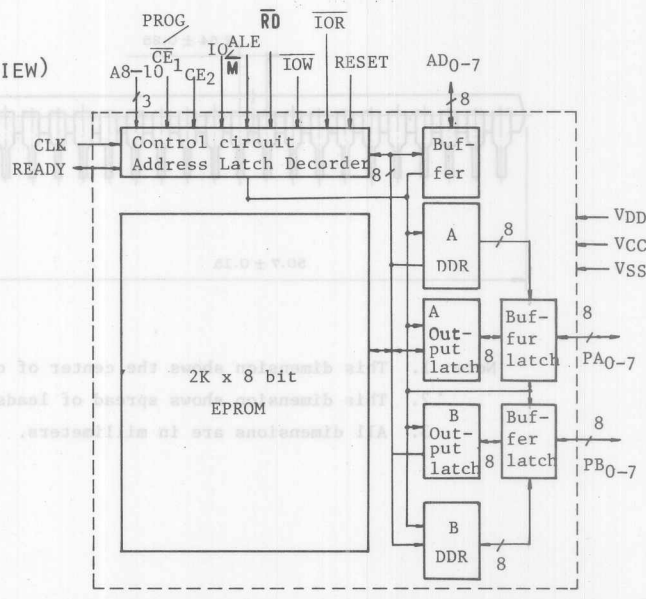


FIGURE 2 TMP8755AC FUNCTIONAL BLOCK DIAGRAM

PIN NAMES AND PIN DESCRIPTION

ALE (Input)

When Address Latch Enable goes high, AD_{0-7} , IO/\overline{M} , A_{8-10} , CE_2 , and \overline{CE}_1 enter the address latches. The signals (AD_{0-7} , IO/\overline{M} , A_{8-10} , CE) are latched in at the trailing edge of ALE.

AD_{0-7} (Input/Output, 3-state)

Bi-directional Address/Data bus. The lower 8-bit of the PROM or I/O address are applied to the bus lines when ALE is high. During an I/O cycle, Port A or B are selected based on the latched value of AD_0 . If \overline{RD} or \overline{IOR} is low when the latched Chip Enables are active, the output buffers present data on the bus.

A_{8-10} (Input)

These are the high order bits of the PROM address. They do not affect I/O operations.

$\overline{PROG}/\overline{CE}_1$, CE_2 (Input)

CHIP ENABLE INPUTS: \overline{CE}_1 is active low and CE_2 is active high. Both chip enables must be active to permit accessing the PROM. \overline{CE}_1 is also used as a programming pin.

IO/\overline{M} (Input)

If the latched IO/\overline{M} is high when \overline{RD} is low, the output data comes from an I/O port. If it is low the output data comes from the PROM.

\overline{RD} (Input)

If the latched Chip Enables are active when \overline{RD} goes low, the AD_{0-7} output buffers are enabled and output either the selected PROM location or I/O ports. When both \overline{RD} and \overline{IOR} are high, the AD_{0-7} output buffers are 3-stated.

\overline{IOW} (Input)

If the latched Chip Enables are active, a low on \overline{IOW} causes the output port pointed to by the latched value of AD_0 to be written with the data on AD_{0-7} . The state of IO/\overline{M} is ignored.

CLK (Input)

The CLK is used to force the READY into its high state after it has been forced low by \overline{CE}_1 low, CE_2 high, and ALE high.



INTEGRATED CIRCUIT

TECHNICAL DATA

TMP8755AC

TECHNICAL DATA



READY (Output, 3-state)

READY is a 3-state output controlled by \overline{CE}_1 , CE_2 , ALE and CLK. READY is forced low when the Chip Enables are active during the time ALE is high, and remains low until the rising edge of the next CLK.

PA0 - PA7 (Input/Output, 3-state)

These are general purpose I/O pins. Their input/output direction is determined by the contents of Data Direction Register (DDR). Port A is selected for write operations when the Chip Enables are active and IOW is low and a 0 was previously latched from AD₀, AD₁. Read operation is selected by either IOR low and active Chip Enables and AD₀ and AD₁ low, or IO/M high, RD low, active Chip Enables, and AD₀ and AD₁ low.

PB0 - PB7 (Input/Output, 3-state)

This general purpose I/O port is identical to Port A except that it is selected by a 1 latched from AD₀ and a 0 from AD₁.

RESET (Input)

In normal operation, an input high on RESET causes all pins in Ports A and B to assume input mode (clear DDR register).

 \overline{IOR} (Input)

When the Chip Enables are active, a low on \overline{IOR} will output the selected I/O port onto the AD bus. \overline{IOR} low performs the same function as the combination of IO/M high and RD low. When IOR is not used in a system, IOR should be tied to VCC "1".

V_{CC} (Power)
+5 volt supply

V_{SS} (Power)
Ground Reference

V_{DD} (Power)

V_{DD} is a programming voltage and must be tied to +5V when the TMP8755AC is being read. For programming, a high voltage is supplied with V_{DD}=25V, typical.

FUNCTIONAL DESCRIPTION

PROM SECTION

The TMP8755AC contains an 8-bit address latch which allows it to interface directly to TLCS-85A microcomputer system without additional hardware. The PROM portion of the chip is addressed by the 11-bit address (A8-10, AD₀₋₇) and CE. The address, IO/M and CE are latched into the address latches on the falling edge of ALE. If the Chip Enables (CE₂ and CE₁) are active and IO/M is low when RD goes low, the contents of the EPROM location addressed by latched address are output onto the AD₀₋₇ lines.

I/O SECTION

The I/O port portion consists of two 8-bit I/O ports and two 8-bit Data Direction Registers (DDR). The I/O portion of the chip is addressed by the latched value of AD₀ and AD₁. Contents of Port A and Port B can be read and written, but those of DDR's cannot be read. A port can be read out when the latched Chip Enables are active and either RD goes low with IO/M high, or IOR goes low. The two 8-bit DDR's (DDRA and DDRB) are used to determine the input/output status of each pin in the corresponding port. A '0' specifies an input mode and a '1' specifies an output mode. The two 8-bit DDR's are cleared by RESET signal. The table 1 summarizes Port and DDR designation.

TABLE 1 SELECTION OF PORT AND DDR DESIGNATION

AD ₁	AD ₀	Selection
0	0	Port A
0	1	Port B
1	0	Port A Data Direction Register (DDR A)
1	1	Port B Data Direction Register (DDR B)

ERASURE CHARACTERISTICS

The TMP8755AC can be erased by applying light with wavelengths shorter than 4000 Å. (1Å = 10^{-8} cm). Sunlight and the fluorescent lamps may include 3000 ~ 4000 Å wavelength components consequently when used under such lighting for extended periods of time, an opaque seal will be required to protect the TMP8755AC. Generally, ultraviolet light with a wavelength of 2537 Å is recommended for TMP8755AC-erasing, and in this case the integrated does (ultraviolet light intensity $[W/cm^2] \times \text{time} [\text{sec}]$) should be over 15 $[W \cdot \text{sec} / cm^2]$.

If the Toshiba sterilizing lamp GL-15 is used and the device is exposed at a distance of 1-cm from the lamp surface, erasure should be completed in about 60 minutes.

And using a lamp whose ultraviolet light intensity is a 12000 $[\mu W/cm^2]$ will reduce the exposure time to about 20 minutes. (In this case the integrated dose should be 12000 $[\mu W/cm^2] \times (20 \times 60)[\text{sec}] \approx 15 [W \cdot \text{sec}/cm^2]$.)

PROGRAMMING

Initially when received by customers all bits of the TMP8755AC are in the "1" state which is the erased state. Therefore programming is carried out by electrically writing in the "0" state at the desired bit locations.

A programmed "0" can only be changed to a "1" by ultraviolet erasure.

The program mode itself consists of programming a single address at a time, giving a single 50 ms pulse for every address.

Preliminary timing diagrams and parameter values pertaining to the TMP8755AC programming operation are contained in Figure 7.

TABLE 1 SELECTION OF PORT AND DDR DESIGNATION

Selection	AD ₁	AD ₀
Port A	0	0
Port B	1	0
Port A Data Direction Register (DDR A)	0	1
Port B Data Direction Register (DDR B)	1	1

ABSOLUTE MAXIMUM RATINGS

Symbol	Item	Rating
V _{CC}	V _{CC} Supply Voltage with Respect to V _{SS}	-0.5V to +7.0V
V _{DD}	V _{DD} Supply Voltage for Programming with Respect to V _{SS}	-0.5V to +26.5V
V _{IN}	Input Voltage with Respect to V _{SS}	-0.5V to +7.0V
V _{OUT}	Output Voltage with Respect to V _{SS}	-0.5V to +7.0V
P _D	Power Dissipation	1.5 W
T _{SOLDER}	Soldering Temperature (Soldering Time 10 sec.)	260°C
T _{STG}	Storage Temperature	-55°C to +150°C
T _{OPR}	Operating Temperature	0°C to +70°C

D.C. CHARACTERISTICS

TA = 0°C to 70°C, V_{CC} = 5V ± 5%, V_{DD} = V_{CC} ± 0.6V

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V _{IL}	Input Low Voltage		-0.5		0.8	V
V _{IH}	Input High Voltage		2.0		V _{CC} +0.5	V
V _{OL}	Output Low Voltage	I _{OL} = 2mA			0.45	V
V _{OH}	Output High Voltage	I _{OH} = -400µA	2.4			V
I _{IL}	Input Leakage Current	V _{IN} = V _{CC} to 0V			±10	µA
I _{LO}	Output Leakage Current	0.45 ≤ V _{out} ≤ V _{CC}			±10	µA
I _{CC}	V _{CC} Supply Current				180	mA

A.C. CHARACTERISTICS

TA = 0°C to 70°C, VCC = 5V ± 5% VDD = VCC ± 0.6V

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
tCYC	Clock Cycle time		320			ns
tL	CLK Low Width		80			ns
tH	CLK High Width		120			ns
tR, tF	CLK Rise and Fall Time				30	ns
tAL	Address to Latch Set Up Time		50			ns
tLA	Address Hold Time after Latch		80			ns
tLC	Latch to READ/WRITE Control		100			ns
tRD	Valid Data Out Delay from READ Control	150pF			170	ns
tAD	Address Stable to Data Out Valid	Load			450	ns
tLL	Latch Enable Width		100			ns
tRDF	Data Bus Float after READ		0		100	ns
tCL	READ/WRITE Control to Latch Enable		20			ns
tCC	READ/WRITE Control Width		250			ns
tDW	Data In to WRITE Set Up time		150			ns
tWD	Data In Hold Time after WRITE		30			ns
tWP	WRITE TO Port Output				400	ns
tPR	Port Input Set Up Time		50			ns
tRP	Port Input Hold Time		50			ns
tRYH	READY Hold Time		0		160	ns
tARY	Address (CE) to READY				160	ns
tRV	Recovery Time between Controls		300			ns
tRDE	Data Out Delay from READ Controls		10			ns
tLD	ALE to Data Out Valid				350	ns
tLCK	ALE Low during CLK high		100			ns

D.C. CHARACTERISTICS FOR PROGRAMMING

$T_A = 25^\circ\text{C} \pm 5^\circ\text{C}$, $V_{CC} = 5\text{V} \pm 5\%$, $V_{SS} = 0\text{V}$

Symbol	Parameter	Min.	Typ.	Max.	Units
V_{DD}	Supply Voltage for programming	24	25	26	V
I_{DD}	Supply Current			30	mA

A.C. CHARACTERISTICS FOR PROGRAMMING

$T_A = 25^\circ\text{C} \pm 5^\circ\text{C}$, $V_{CC} = 5\text{V} \pm 5\%$, $V_{SS} = 0\text{V}$

Symbol	Parameter	Min.	Typ.	Max.	Units
t_{PS}	Data Set Up Time	10			ns
t_{PD}	Data Hold Time	0			ns
t_S	Program Pulse Set Up Time	2			μs
t_H	Program Pulse Hold Time	2			μs
t_{PR}	Program Pulse Rise Time	10	2000		ns
t_{PF}	Program Pulse Fall Time	10	2000		ns
t_{PRG}	Program Pulse Width	45	50		ms

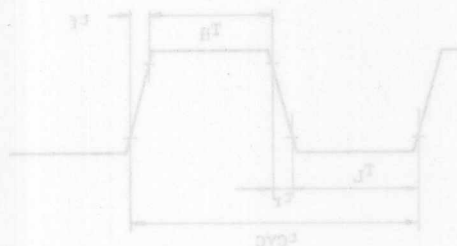
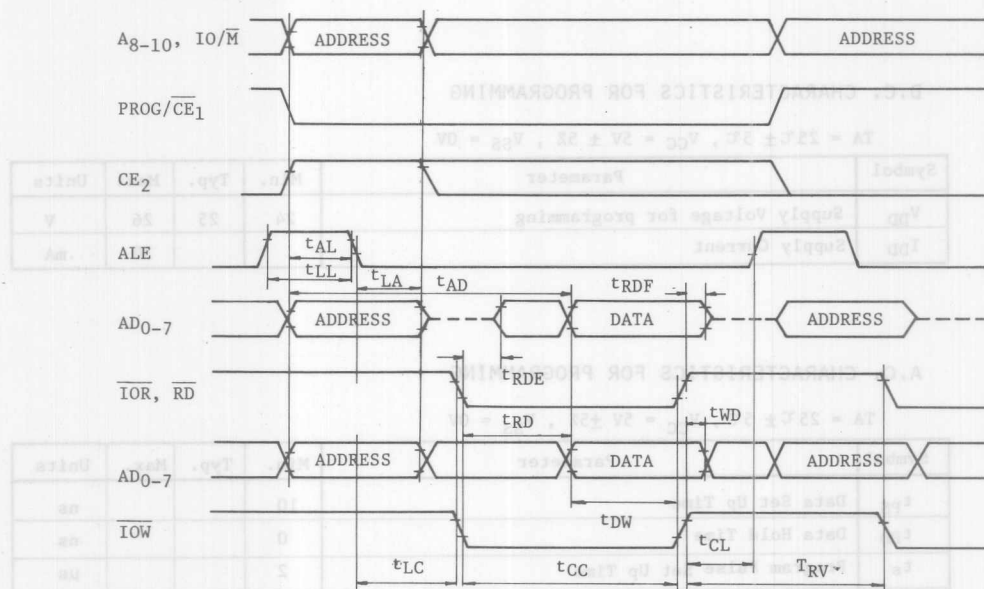


FIGURE 4 CLOCK SPECIFICATION FOR TMP8755AC

TIMING WAVEFORMS



Note: \overline{CE}_1 must remain low for the entire cycle.

FIGURE 3 PROM READ, I/O READ, AND WRITE TIMING

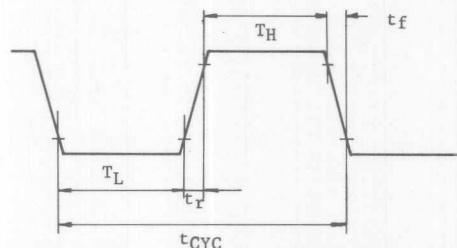


FIGURE 4 CLOCK SPECIFICATION FOR TMP8755AC

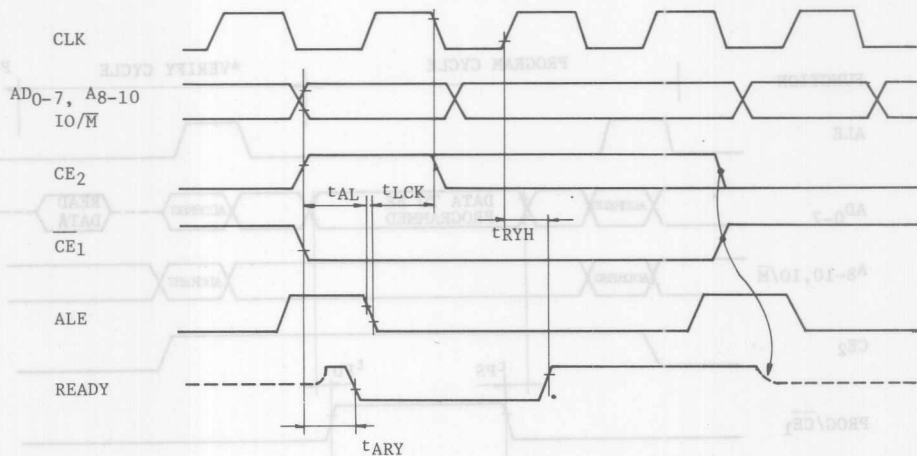
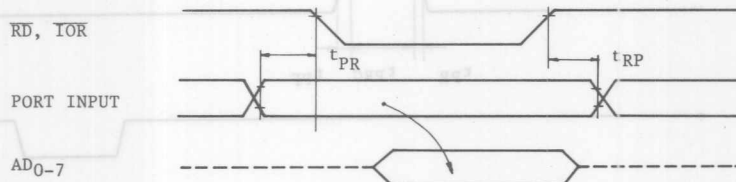


FIGURE 5 WAIT STATE TIMING (READY=0)

A. INPUT MODE



B. OUTPUT MODE

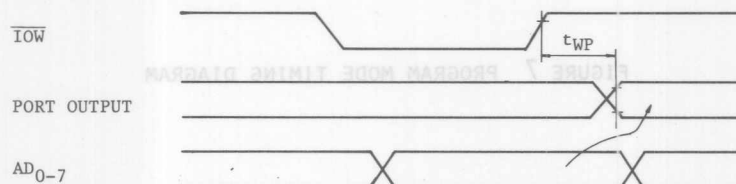
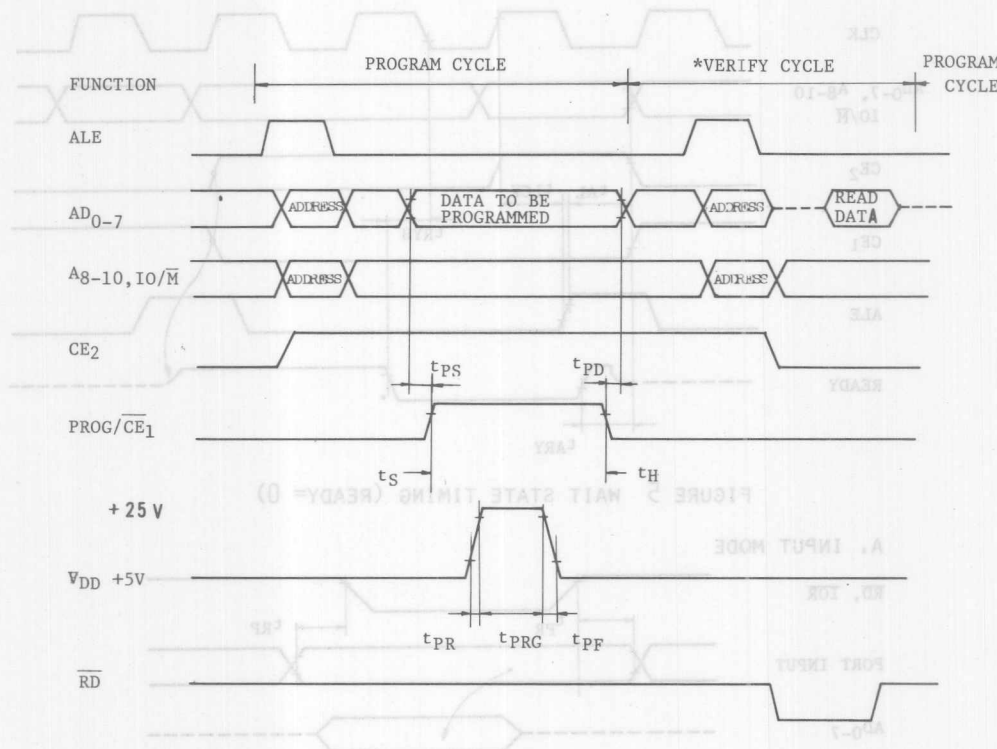


FIGURE 6 I/O PORT TIMING

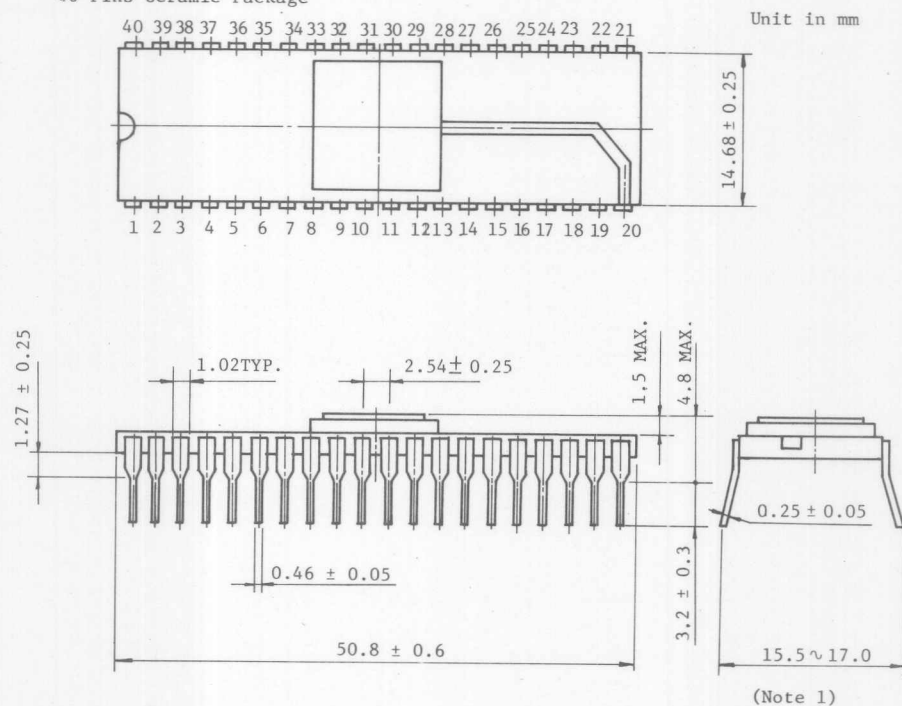


* VERIFY CYCLE IS A REGULAR MEMORY READ CYCLE
(WITH $V_{DD} = 5V$ FOR TMP8755AC)

FIGURE 7 PROGRAM MODE TIMING DIAGRAM

OUTLINE DRAWING

40 Pins Ceramic Package



Note 1. This dimension shows spread of leads.

2. All dimensions are in millimeters.

MICROCOMPUTER APPLICATION
DEVELOPMENT TOOL



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TECHNICAL DESCRIPTION



DEVELOPMENT TOOLS

Toshiba's Microcomputer Technical Description
 TMS400 microcomputer application development system and the dedicated
 debugging system.

MICROCOMPUTER APPLICATION DEVELOPMENT TOOL

GENERAL DESCRIPTION

MICROCOMPUTER APPLICATION DEVELOPMENT SYSTEM TMS400
 By exchanging portions of the control board and software, the TMS400
 system can be changed into the following development systems:

- (1) TMS400/43 TICS-43 Application Development System
- (2) TMS400/46 TICS-46A Application Development System
- (3) TMS400/84 TICS-84 Application Development System

The TMS400 system is hereinafter described under the name of the
 TMS400/xx (xx denotes the name of the microcomputer series of 43, 46 or 84).

DEDICATED DEBUGGING SYSTEM

The dedicated debugging system can be realized by combining the
 debugging board and the emulation board, consisting of the following
 products.

- (1) BM304 TICS-43 debugging board + BM303 TICS-43 emulation board
- (2) BM404 TICS-46A debugging board + BM403B TICS-46A emulation board
- (3) BM8404 TICS-84 debugging board + BM8403 TICS-84 emulation board



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DEVELOPMENT TOOLS

Toshiba's single-chip microcomputer development tool has the TDS400 microcomputer application development system and the dedicated debugging system.

MICROCOMPUTER APPLICATION DEVELOPMENT SYSTEM TDS400

By exchanging portions of the control board and software, the TDS400 system can be changed into the following development systems:

- (1) TDS400/43 TLCS-43 Application Development System
- (2) TDS400/46 TLCS-46A Application Development System
- (3) TDS400/84 TLCS-84 Application Development System

The TDS400 system is hereinafter described under the name of the TDS400/xx (xx denotes the name of the microcomputer series of 43, 46 or 84).

DEDICATED DEBUGGING SYSTEM

The dedicated debugging system can be realized by combining the debugging board and the emulation board, consisting of the following products.

- (1) BM4304 TLCS-43 debugging board + BM4303 TLCS-43 emulation board
- (2) BM4604 TLCS-46A debugging board + BM4603B TLCS-46A emulation board
- (3) BM8404 TLCS-84 debugging board + BM8403 TLCS-84 emulation board



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TECHNICAL DESCRIPTION



1. MICROCOMPUTER APPLICATION DEVELOPMENT SYSTEM TDS400

1.1 SYSTEM CONCEPT

The TDS400/xx system is the application program development support system of Toshiba's single-chip microcomputer. Micro-computer application program development is divided into two main categories, programming and real time debugging. These functions can be performed consecutively through the TDS400/xx system.

o Programming:

(1) Programming and editing of source program

(2) Assembling source program (converting to machine code)

(3) Loading, modifying and writing into EPROM in the object program

o Real time debugging:

(1) Allows to execute and debug program at a state with the application circuit. (direct modification with machine codes)

(5) Monitoring and revising of internal status during program execution.

(6) Data exchange with EPROM (read/write)

The following manuals are available as system documents relative to the functions and operating instructions of the TDS400/xx:

(A) Operating Instructions (Description of the functions and operations of the above-mentioned (1) to (6).

(B) Instruction Manuals (configuration description of hardware).



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1.2 HARDWARE CONFIGURATION

The TDS400/xx is a system which a microcomputer consists of TMP8085A MPU, 16 K-byte ROM, and 48K-byte RAM has been equipped with various auxiliary memories and input/output interfaces. To ensure a more useful development system, it is provided with 16K EPROM writer, emulation board, program memory (4 K-byte RAM) which can be substituted with ROM, and dedicated debugging console.

The TDS400/xx hardware configuration is given in Fig.1, and its conceptual system view in Fig.2, respectively. In Fig.1 solid line boxes show basic configuration units, while dotted line boxes indicate optional units. The units enclosed with broken lines are supplied by users, as required. Shaded boxes indicate the specific units depending on the series of a microcomputer. Other units are common to both.

When used as a programming system, this system requires a minimum of one console I/O device for input/output of commands and application program data. When the system is used as a real-time debugging tool, operation is made through the attached debugging console. Real time execution can be obtained by removing the single chip microprocessor from the application circuit (user system) and plugging in the DIP socket from the emulation board.

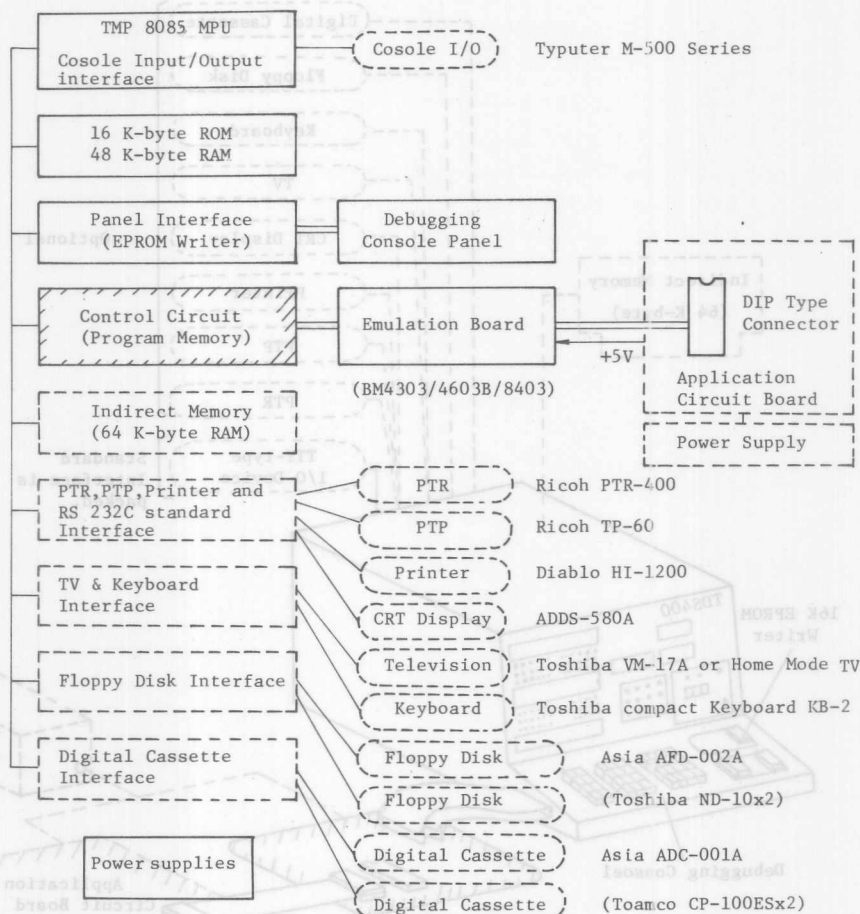


Fig. 1 TDS400/xx Hardware Configuration

Solid line boxes: basic configuration Dotted lines: Optional units
 Broken lines: user-supplied Shaded line boxes: specific to microcomputer

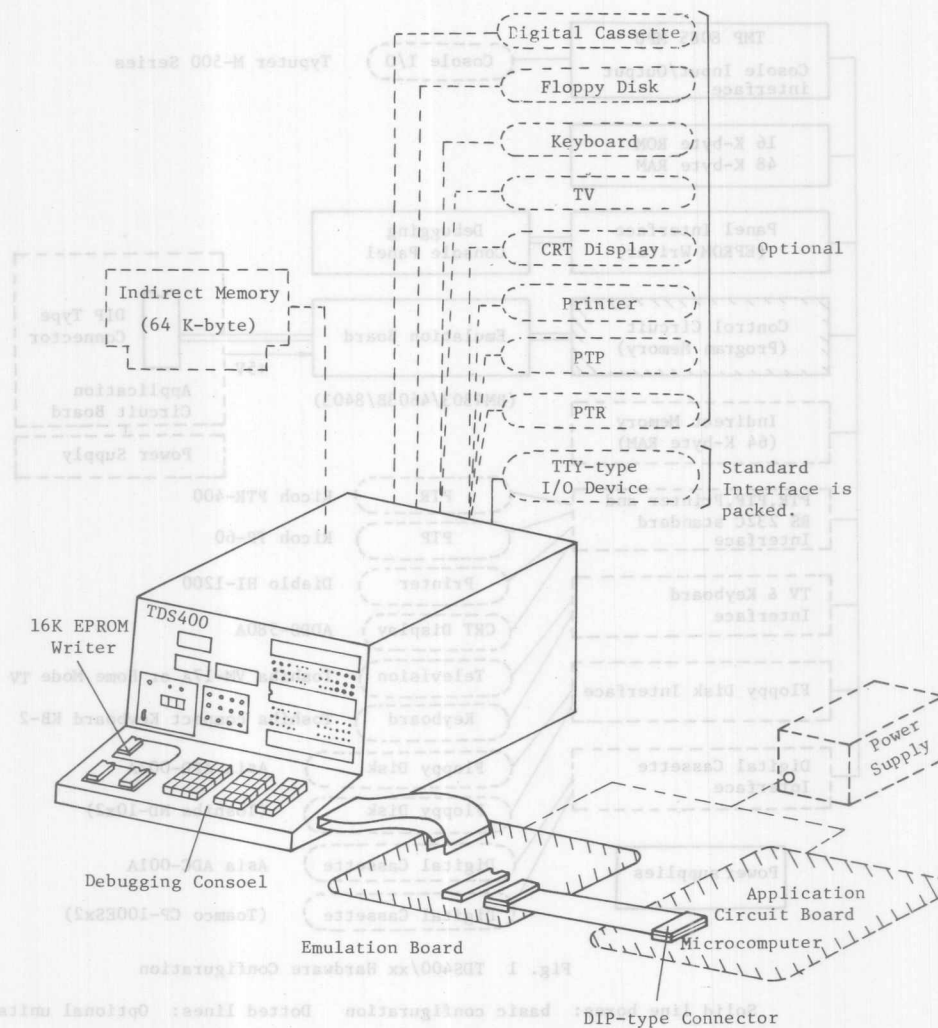


Fig. 2 Conceptual System View of TDS400/xx System

1.3 SOFTWARE CONFIGURATION

As shown in Fig. 3, the TDS400/xx system software consists of a programming system segment and debugging console control segment. Shaded portions indicate the specific program depending on the microcomputer series. Other programs are common to both.

These programs are firmwared in 16 K-byte ROM within the main memory of the TMP8085A system: therefore, no loading of system programs is required, thus programs being able to be immediately operated. However, for operating option programs, such as assembler programs, the programs must be separately loaded. The system program uses a 2 K-byte as dedicated data area. Furthermore, a 4K-byte RAM is designated as dedicated area (called the back-up memory) for internal save and transmission in the program memory. The remaining 42 K-byte RAM area is a free area used as user programs, symbol tables, current file, or assembler program. (See Fig. 4)

1.4 PROCESS FLOW OF APPLICATION PROGRAM DATA

Fig. 5 shows a conceptual flow chart of the application program data for application program development and evaluation by using the TDS400/xx system (as programming system or debugging console)

1.5 PROGRAMMING SYSTEM

The programming system is provided for facilitating the programming work (development) of application software.

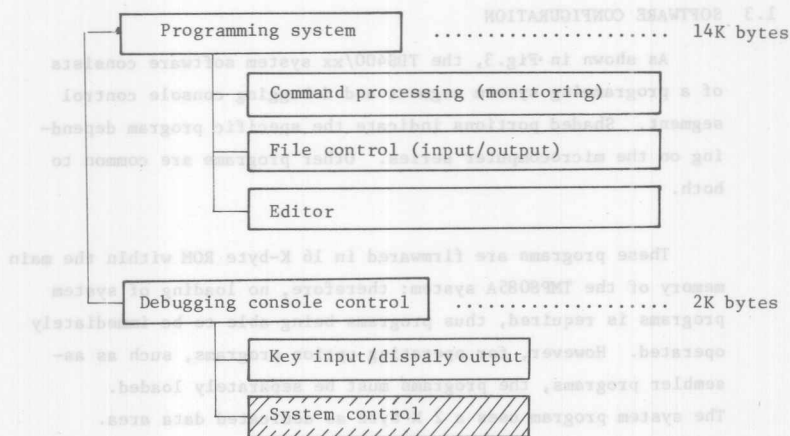


Fig. 3 TDS400/xx System Program Configuration

Shaded element: Portions depending to microcomputer series

Address (hexadecimal)	Purpose of using main memory	
0000	System program (16 K-byte ROM)	ROM 16K bytes
3FFF		
4000		
47FF	System data (2K bytes)	
4800		
FFFF F000 5 FFFF	User program, Symbol table, Current files, or Assembler program, (42K Bytes)	RAM 48K bytes
	Back-up memory (4K bytes)	

Fig. 4 TDS400/xx Main Memory Configuration

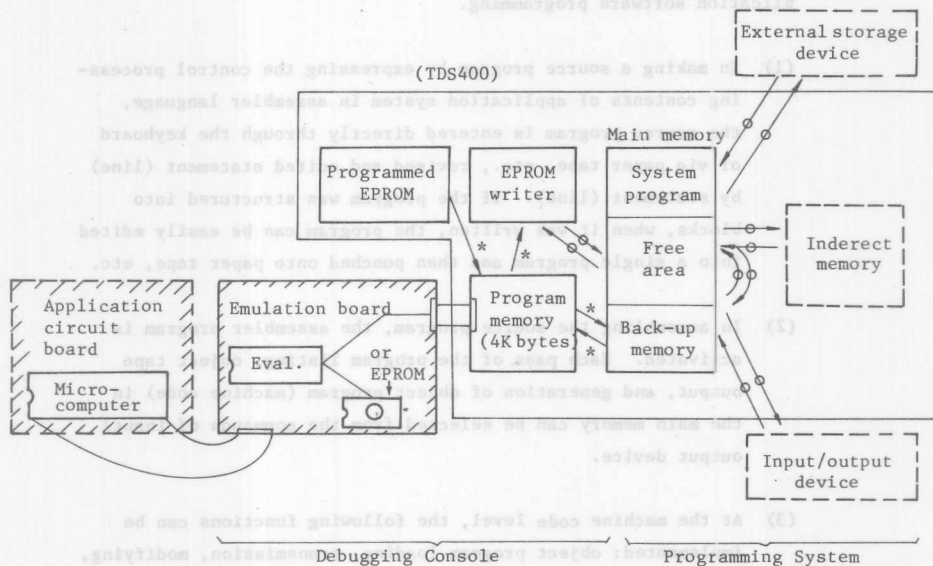


Fig. 5 Data Flow of Application Program

* : Operation from the debugging console.

o : Operation through the programming system.



The TDS400/xx programming system operates according to an input command from the input/output device. The following outline shows the outline of utilization form at each step in application software programming.

- (1) In making a source program by expressing the control processing contents of application system in assembler language, the source program is entered directly through the keyboard or via paper tape, etc., revised and edited statement (line) by statement (line). If the program was structured into blocks, when it was written, the program can be easily edited into a single program and then punched onto paper tape, etc.
- (2) In assembling the source program, the assembler program is activated. Each pass of the program listing, object tape output, and generation of object program (machine code) in the main memory can be selected from the commands of input/output device.
- (3) At the machine code level, the following functions can be implemented: object program loading, transmission, modifying, dumping, format change on the paper tape and writing into 16K EPROM.

The entire programming system can be operated from a single input/output device¹⁾, but for performing the operation at high-speed, multiple input/output devices can also be utilized.

Note 1) Can use teletype, CRT display, or TV-keyboard



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TECHNICAL DESCRIPTION



- (a) 64 K-byte indirect memory --- can be used as a temporary file memory. For example, if the paper tape source program is once stored in this memory, the program will become much faster and easier to execute. The source program, however, is restricted to about $1.5 \sim 2$ K-byte because of memory capacity.
- (b) Floppy disk --- a file memory (random file) similar to indirect memory. Memory capacity is approximately 250 K-byte. Each disc can store $6 \sim 8$ K-step source program. The processing rate is lower than that of indirect memory.
- (c) Paper tape reader and Paper tape punch --- allows faster processing of paper tape.
Printer -- speeds up program listing output
CRT display -- convenient for editing and modifying application programs.
- (d) Digital cassette --- can be used as a sequential file, instead of paper tape. This eliminates the bother of rewinding and remounting paper tape, improving speed and ease of handling.
- (e) Television receiver and simple keyboard --- useful as low cost input/output devices.

1.6 DEBUGGING CONSOLE

The debugging console is designed for easy real time debugging of the application system.

The debugging console, mounted in the front panel of the TDS400, is a dedicated console. Major functions performed by this console are as follows:



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- (1) Real time emulation can be performed. For application program memory, the user can select either program memory (RAM) within the TDS400/xx or external memory (EPROM) within the emulation board.
- (2) Program memory read and write is done directly through the debugging console.
- (3) Loading to program memory:
 - (i) The program can be loaded directly from program EPROM.
 - (ii) The program can also be loaded from the back-up memory within the development system ^{Note 2)}.
- (4) Contents of the program memory:
 - (i) Can be written directly into 16K EPROM.
 - (ii) Can be compared with the contents of programmed EPROM.
 - (iii) Can be transferred and saved to the back-up memory
- (5) Direct read and write can be performed with RAM or register built into the single-chip microcomputer just as with program memory.
- (6) Application programs can be initiated from any address.
- (7) Application programs may be stopped at any time while in operation.
- (8) Address-stop function provided.

Note 2) The back-up memory is a point of contact between the debugging console function and the programming system function. The programming system can load the back-up memory with an object program, and the contents of the back-up memory can be put out onto paper tape, etc. (in various formats).



- (9) Single-step operation possible.
- (10) Dummy interrupt signal can be entered through the debugging console.
- (11) Logical levels of all pins of microcomputer chip are always indicated. Voltage of the threshold value can be seen at any level.

1.7 EMULATION BOARD

In the last step of application system development, it becomes extremely important to be able to check the system operations as close to the end product as possible. For answering this need, emulation board (BM4303/BM603B/BM8403) is available, as shown in Table 1. These emulation boards are integrated with the evaluator chip and are designed to use EPROM in the program memory section. Fig. 6 shows the conceptualized drawings of these emulation boards.

Besides the circuits attached to the evaluator chip, the emulation board has interface circuits for connecting to the application development system TDS400 and free space for mounting a small number of peripheral circuits. For the program memory, 24-pin DIP sockets are provided so as to make it possible to use 16K EPROM TMM323 (2716) unit.

When this emulation board is connected with the TDS400, the user can choose to put the application program either into program memory (RAM) within the TDS400/xx or into EPROM on the emulation board. The former freely permits reading and reloading of program memory contents through the TDS400/xx debugging console, making debugging of the application program during development very convenient.



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The latter does not permit reading and writing of the application program contents. However, in either case the application program can easily be checked by using the function of the debugging console of TDS400/xx while monitoring or changing internal status of the microcomputer.

When the emulation board is disconnected from the TDS400, EPROM within the board is automatically used as program memory and the board can be used as an independent emulation board.

The BM4302/4602A makes a compact emulation boards, equipped with one/two 16K EPROM TMM323 · (2716) as program memory. This board is useful for field-testing the applied product, but lacks free space and an interface to TDS400.

Each emulation board provides each microcomputer chip and a DIP-type equivalent connector. With the microcomputer chip removed from the application circuit (user system) and this connector connected with its place, operations can be performed as if a single-chip microcomputer were mounted.

When the application circuit is simple and no application circuit board has been provided, system development and evaluation can be accomplished by mounting a peripheral circuit in the free space on the emulation board.

Fig. 7 illustrates a conceptualized view of each using situation of these emulation boards. Optimum emulation board and evaluation means can be selected according to the evaluation objectives of the application system.

Table 1 Single-chip Microcomputer Emulation Board

Board Name	Evaluator Chip	Program memory EPROM		Oscillator (Hz)	Free Space	Power Supply Required	Remarks
		EPROM	Qt. of Socket				
BM4303	TMP4300C	16 K (one)	1	I F T (455K)	Yes	5V	Can be used individually or connected TDS400/43
BM4603B	TCP4600AC	16 K (two)	2	I F T (400K)	Yes	5V	Can be used individually or connected TDS400/46
BM8403	TMP8039-6	16 K (two)	2	Crystal 6M	Yes	5V	Can be used individually or connected TDS400/84

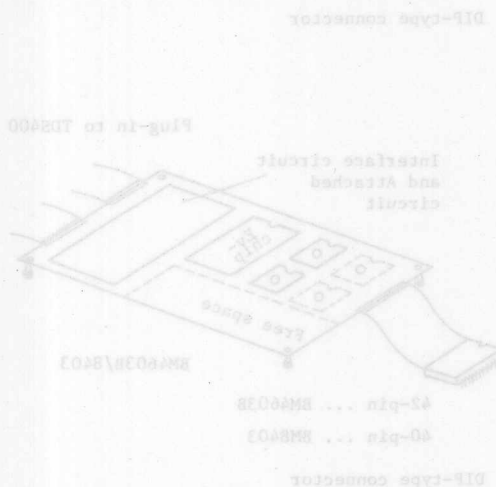
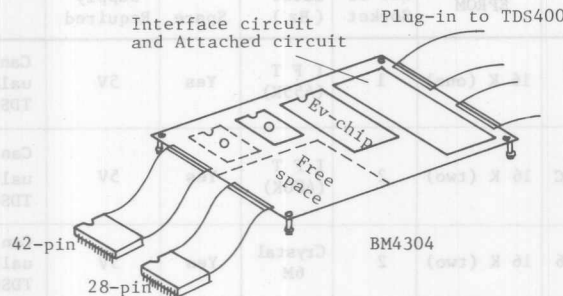


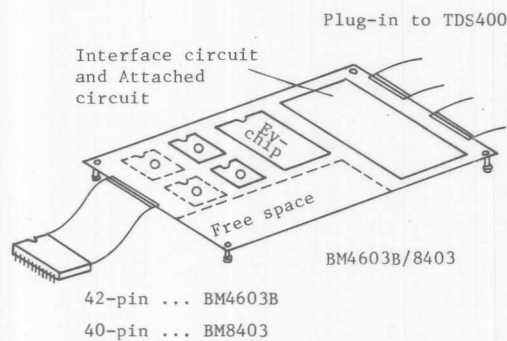
Fig. 6 Emulation Board — Conceptual Drawing
(Note: Ev-chip is an abbreviation of evaluator chip.)

Table 1 Single-chip Microcomputer Emulation Board

Board Name	Emulator Chip	Program Memory (Kbytes)	ROM or EPROM	Deci-Byte	Power Supply	Remarks
BM4303	TP4300C	16	16	1	5V	Can be used individually or connected
BM4603B	TP4600AC	16 K (two)	16	1	5V	Can be used individually or connected
BM8403	TP8403-A	16 K (two)	16	1	5V	Can be used individually or connected



DIP-type connector



42-pin ... BM4603B

40-pin ... BM8403

DIP-type connector

Fig. 6 Emulation Boards --- Conceptualized Drawings

(Note: Ev-chip is an abbreviation of evaluator chip.)

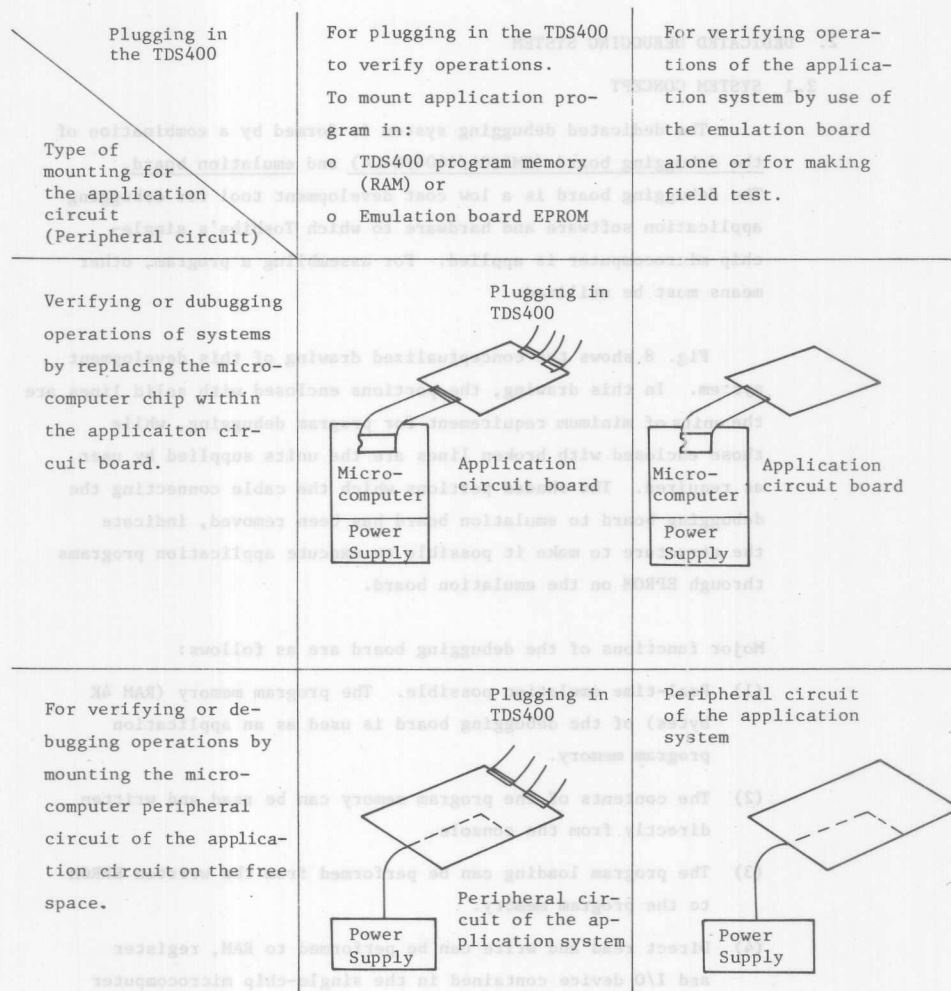


Fig. 7 Examples of Emulation Board Usage



2. DEDICATED DEBUGGING SYSTEM

2.1 SYSTEM CONCEPT

The dedicated debugging system is formed by a combination of the debugging board (BM4304/4604/8404) and emulation board.

The debugging board is a low cost development tool for debugging application software and hardware to which Toshiba's single-chip microcomputer is applied. For assembling a program, other means must be utilized.

Fig. 8 shows the conceptualized drawing of this development system. In this drawing, the portions enclosed with solid lines are the units of minimum requirement for program debugging, while those enclosed with broken lines are the units supplied by user as required. The shaded portions which the cable connecting the debugging board to emulation board has been removed, indicate the structure to make it possible to execute application programs through EPROM on the emulation board.

Major functions of the debugging board are as follows:

- (1) Real-time emulation possible. The program memory (RAM 4K bytes) of the debugging board is used as an application program memory.
- (2) The contents of the program memory can be read and written directly from the console.
- (3) The program loading can be performed from the written EPROM to the program memory.
- (4) Direct read and write can be performed to RAM, register and I/O device contained in the single-chip microcomputer in the same way as the program memory.



- (5) Application programs can be initiated from any address.
- (6) Application programs can be stopped at any time while in operation.
- (7) Address-stop function provided.
- (8) Single-step operation possible.
- (9) Pseudo interrupt signal can be entered through the debugging console.

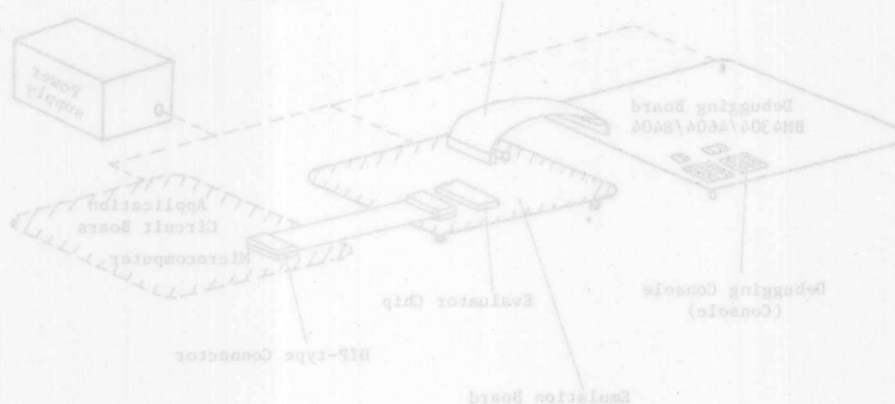


Fig. 8 Conceptualized Drawing of Dedicated Debugging System

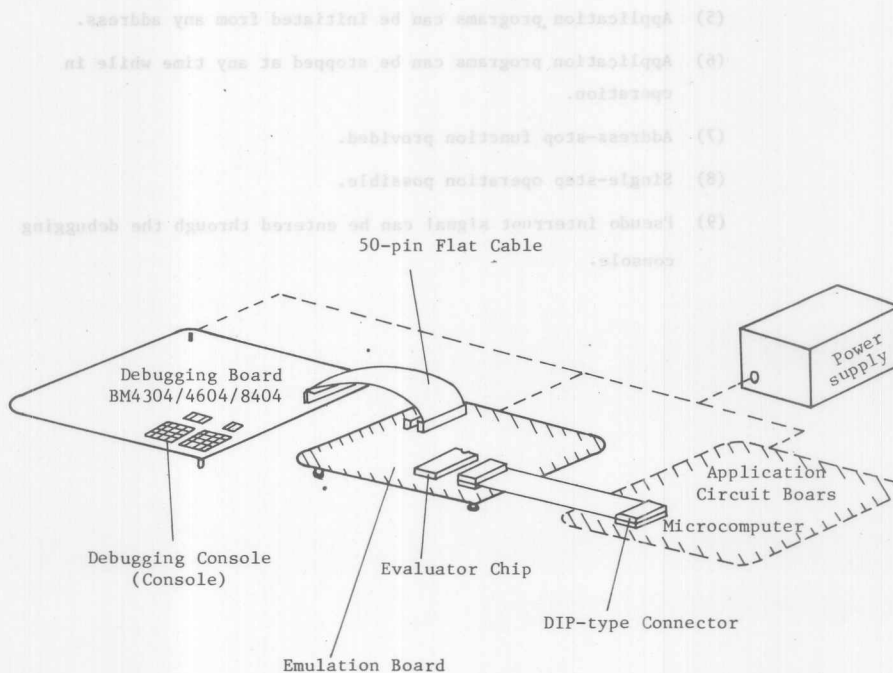


Fig. 8 Conceptualized Drawing of Dedicated Debugging System

3. PRODUCTS CONFIGURATION FOR APPLICATION DEVELOPMENT SUPPORT SYSTEM

Depending on the user's needs, the TDS400 and emulation board can be converted or expanded. For example, conversion of the TDS400/43 system to the TDS400/46 system can be accomplished by replacing BM4301A + BM4303 + SW4323 with BM4601A + BM4603B + SW4623, and vice versa.

The optional I/O interface boards are common to all the TDS400 development systems. These interfaces can be attached directly to the supposed standard I/O equipment and/or auxiliary memory devices (See Fig. 1). Further, these equipment and devices are so designed as to be used without modification of the system software.

Therefore, it is very convenient for user to keep various kinds of several emulation boards at hand in order to forward verification work of application systems smoothly.

Model No.	Emulation Board	Optional I/O Interface	Optional Memory
BM4000	BM4000/43	BM4000/43	BM4000/43
BM4001	BM4001/43	BM4001/43	BM4001/43
BM4002	BM4002/43	BM4002/43	BM4002/43
BM4003	BM4003/43	BM4003/43	BM4003/43
BM4004	BM4004/43	BM4004/43	BM4004/43
BM4005	BM4005/43	BM4005/43	BM4005/43
BM4006	BM4006/43	BM4006/43	BM4006/43
BM4007	BM4007/43	BM4007/43	BM4007/43
BM4008	BM4008/43	BM4008/43	BM4008/43
BM4009	BM4009/43	BM4009/43	BM4009/43
BM4010	BM4010/43	BM4010/43	BM4010/43
BM4011	BM4011/43	BM4011/43	BM4011/43
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BM4097	BM4097/43	BM4097/43	BM4097/43
BM4098	BM4098/43	BM4098/43	BM4098/43
BM4099	BM4099/43	BM4099/43	BM4099/43
BM4100	BM4100/43	BM4100/43	BM4100/43

PRODUCTS CONFIGURATION FOR APPLICATION DEVELOPMENT TOOL

Family	Model No.	Description	Configuration of Products	Accompanying Materials	Remarks
Common to	TDS400	Microcomputer application system 400 (Toshiba MDS model 400)	BM4006A + SW4006A Optional board (BM4001 ~ 5)	Refer to each system component	Products name of combined system, peripheral equipment is supplied by user.
	SW0051	Paper tape output program/ACOS (PT output program on ACOS)	Card image magnetic tape (9 tracks) of source program (FORTRAN)	SW0051 Instruction manual	For object output of cross assembler (SWxx53)
	SW0061	Paper tape output program/NOVA (PT output program on NOVA)	Paper tape (ASCII code) of source program (FORTRAN)	SW0061 Instruction manual	For object output of cross assembler (SWxx63)
	BM4001	64KB Indirect memory	Board module (1)	BM4001 Instruction manual	Mounted on BM4006A
	BM4002	General I/O interface	Board module (1), intra-board connection cable (2), connector board(1)	BM4002 Instruction manual	Ditto RS232C, PTR, PTP & Printer
	BM4003	TV·Keyboard interface	Board module (1), keyboard (1), intra-board connection cable (2), connector board (1)	BM4003 Instruction manual	Ditto Connected to NTSC type of TV set
	BM4004	Floppy disk interface	Board module (1), intra-board connection cable (1) connector board (1)	BM4004 Instruction manual	Ditto Can be connected to two FD drives of single-sided single density



MICROCOMPUTER
TECHNICAL DESCRIPTION

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Family	Model No.	Description	Configuration of Products	Accompanying Materials	Remarks
Common to	BM4005	Digital cassette interface	Board module (1), intra-board connection cable (2), connector board (1)	BM4005 Instruction manual	Mounted on BM4006A Can be connected to two 10"/sec DC handlers
	BM4006A	TDS400 hardware main frame	A set of TDS400 basic hardware with power supply in cabinet	BM4006A Instruction manual	EPROM writer with debugging console, serial port (1)
	SW4006A	TDS400 system A monitor program	EPROM (8) (monitor program, 16K bytes)	TDS400 System A operation manual, SW4006A instruction manual	System control program packed in main memory region of BM4006A
43	TDS400/43	Toshiba MDS400 for TLCS-43	TDS400 + BM4301A + BM4303 + SW4323	Refer to each system component	Products name of combined system. Peripheral equipment is supplied by user
	BM4301A	TDS400/43 controller	Board module (1), EPROM (1), (control program, 2K bytes)	TDS400/43 debugger operation manual, BM4301A Instruction manual	EPROM is replaced with a part of SW4006A in main memory area
	BM4303	TLCS-43 emulation board	Board module (1), EPROM (1), Cables (2) to LSI socket	BM4303 Instruction manual	Board with functions equivalent to LSI of TLCS-43. With interface to TDS400
	BM4304	TLCS-43 debugging board	Board module (1), cable (1) connecting with BM4303	BM4303 debugging board operation manual. BM4303 instruction manual	Used for debugging by connecting with BM4303

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TECHNICAL DESCRIPTION

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MULTIPROCESSOR SYSTEM

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MICROCOMPUTER

TECHNICAL DESCRIPTION

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Fam-ily	Model No.	Description	Configuration of Products	Accompanying Materials	Remarks
43	SW4323	TLCS-43 assembler on TDS400	EPROM (3) (Assembler program 6K bytes)	TLCS-43 assembly language manual. SW4323 Instruction manual	Loaded from EPROM writer (/reader) of TDS400
	SW4353	TLCS-43 cross assembler on ACOS	Card image magnetic tape (9 tracks) of source program (FORTRAN)	TLCS-43 assembly language manual. SW4353 Instruction manual	Used together with SW0051
	SW4363	TLCS-43 cross assembler on NOVA	Paper tape(ASCII code) of source program (FORTRAN)	TLCS-43 assembly language manual. SW4363 Instruction manual	Used together with SW0061
	SW4393S SW4393D	TLCS-43 assembler/IMDS	Diskette(1) (ISIS-II file) S: single side single density. D: single side double density.	TLCS-43 assembly language manual. SW4393S, D instruction manual	Operates under ISIS-II
46A	TDS400/46	TLCS-46A application development	TDS400 + BM4601A + BM4603B + SW4623	Refer to each system component	Products name of combined system, peripheral equipment is supplied by user.
	BM4601A	TDS400/46 controller)	Board module (1), EPROM (1) (control program 2K bytes)	TDS400/46 debugger operation manual. BM4601A instruction manual	EPROM is replaced with a part of SW4006A in main memory area

Fam-ily	Model No.	Description	Configuration of Products	Accompanying Materials	Remarks
46A	BM4603B	TLCS-46A emulation board	Board module (1), EPROM (2), Cable (1) to LSI socket	BM4603B Instruction manual	Board with functions equivalent to LSI of TLCS-46A. With interface to TDS400
	BM4604	TLCS-46A debugging board	Board module (1), Cable (1) to BM4603B	BM4604 debugging board Operation manual. BM4604 instruction manual	Used for debugging by connecting with BM4603B
	SW4623	TLCS-46A assembler on TDS400	EPROM (3) (assembler program 6K bytes)	TLCS-46A assembly language manual. SW4623 instruction manual	Loaded from EPROM writer (/reader) of TDS400
	SW4653	TLCS-46A cross assembler on ACOS	Card image magnetic tape (9 tracks) of source program (FORTRAN)	TLCS-46A assembly language manual. SW4653 instruction manual	Used together with SW0051
	SW4663	TLCS-46A cross assembler on NOVA	Paper tape (ASCII code) of source program (FORTRAN)	TLCS-46A assembly language manual. SW4663 instruction manual	Used together with SW0061
	SW4693S SW4693D	TLCS-46A assembler on iMDS	Diskette (1) (ISIS-II file) S: single side single density. D: single side double density.	TLCS-46A assembly language manual. SW4693S, D instruction manual	Operates under ISIS-II
84	TDS400/84	Toshiba MDS400 for TLCS-84	TDS400 + BM8401A + BM8403 + SW8423A	Refer to each system component	Products name of combined system peripheral equipment is supplied by user.



TECHNICAL DESCRIPTION

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MICROCOMPUTER TECHNICAL DESCRIPTION

Fam-ily	Model No.	Description	Configuration of Products	Accompanying Materials	Remarks
84	BM8401A	TDS400/84 controller	Board module (1), EPROM (1) (control program 2K bytes)	TDS400/84 debugging operation manual. BM8401A instruction manual	EPROM is replaced with a part of SW4006A in main memory region
	BM8403	TLCS-84 emulation board	Board module (1), EPROM (1). Cable (1) to LSI socket	BM8403 Instruction manual	Board with functions equivalent to TMP8048, 8049-6. With interface to TDS400
	BM8404	TLCS-84 debugging board	Board module (1), Cable (1) to BM8403	BM8404 debugging board operation manual. BM8404 instruction manual	Used for debugging by connecting with BM8403
	SW8423A	TLCS-84 assembler on TDS400	EPROM (5) (assembler program 10K bytes)	TLCS-84 assembly language manual. SW8423A instruction manual	Loaded from EPROM writer (/reader) of TDS400
	SW8453	TLCS-84 cross assembler on ACOS	Card image magnetic tape (9 tracks) of source program (FORTRAN)	TLCS-84 assembly language manual. SW8453 instruction manual	Used together with SW0051
85	SW8553	TLCS-85 cross assembler on ACOS	Card image magnetic tape (9 tracks) of source program (FORTRAN)	TLCS-85 assembly language manual. SW8553 instruction manual	Used together with SW0051

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 MICROCOMPUTER
 TECHNICAL DESCRIPTION

SW0051 PAPER TAPE OUTPUT PROGRAM / ACOS

GENERAL DESCRIPTION

This program outputs the object program translated with a cross assembler to the paper tape with various formats.

The program can be loaded on the general-purpose computer ACOS600 or 700.

PRODUCT CONFIGURATION

- o Magnetic tape (9 tracks) 1
(Card (IBM29 code) image of a source program written in FORTRAN (JIS7000, partially GMAP)).
- o SW0051 Instruction manual 1



FEATURES AND MAIN SPECIFICATIONS

- (1) Using this program, paper tapes can be made up to be used for various EPROM writers, production system of masked ROMs, and application development system.
- (2) The formats of the object paper tape are divided broadly into 1-bit BNPF format and 4-bit hexadecimal expressing format.
- (3) For the hexadecimal format, 8 formats can be specified by selecting the output system such as start and end symbols of data, and addressing and checksum modes.
- (4) Output range and block length can be specified.

OPERATING ENVIRONMENT (Host Machine)

Processing unit: ACOS600/700 with more than 64K words (more than 17-bit words)
Operating system: ACOS-6
Peripheral equipment: Magnetic disk, magnetic tape, line printer, card reader, paper tape punch, etc.

OPERATING PROCEDURE

Compile the program first and load it in the host system. According to OS from the host machine, specify the file and output format to operate the program.

TECHNICAL MATERIALS

- (1) SW4353, SW4653, SW8453, SW8553 Instruction Manuals
- (2) ACOS600/700 FORTRAN Language Description
- (3) ACOS600/700 Job Control Language (JCL) Description
- (4) ACOS600/700 IMCV Editing Program Manual

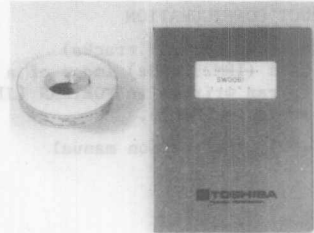
SW0061 PAPER TAPE OUTPUT PROGRAM / NOVA

GENERAL DESCRIPTION

This program outputs the object program translated with a cross assembler to the paper tape with various formats.
The program can be loaded on the micromputer NOVA.

PRODUCT CONFIGURATION

- o Magnetic tape (ASCII code) 1
(Source program written in FORTRAN
(JIS7000))
- o SW0061 Instruction Manual 1



FEATURES AND MAIN SPECIFICATIONS

- (1) Using this program, paper tapes can be made up to be used for various EPROM writers, production system of masked ROMs, and application development systems.
- (2) The formats of the object paper tape are divided broadly into 1-bit BNPF format and 4-bit hexadecimal expressing format.
- (3) For the hexadecimal format, 8 formats can be specified by selecting the output systems such as start and end symbols of data, and addressing and checksum modes.
- (4) Output range and block length can be specified.

OPERATING ENVIRONMENT (Host Machine)

Processing unit: NOVA with more than 64K words (more than 16-bit words)
Operating system: RDOS
Peripheral equipment: Magnetic disk, line printer, console typewriter, paper tape reader, paper tape punch, etc.

OPERATING PROCEDURE

Compile the program first and load it in the host system. According to OS from the host machine, specify the file and output format to operate the program.

TECHNICAL MATERIALS

- (1) SW4363, SW4663 Instruction Manuals
- (2) NOVA FORTRAN IV Description Manual (Data General)
- (3) NOVA RDOS Description Manual, CLI Series (Ditto)
- (4) NOVA RDOS Description Manual, System Utility Series (Ditto)

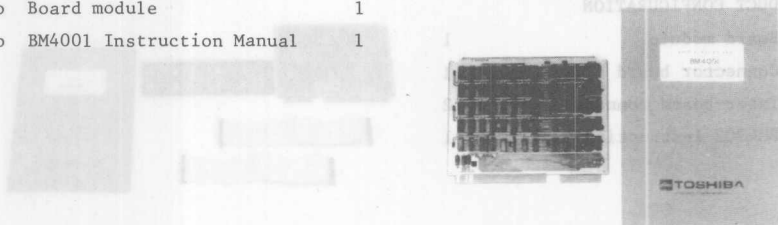
BM4001 64KB INDIRECT MEMORY

GENERAL DESCRIPTION

A memory board of 64,536 bytes (64KB) to be mounted in TDS400 (BM4006A). Generally this board is used as an auxiliary memory.

PRODUCT CONFIGURATION

- o Board module 1
- o BM4001 Instruction Manual 1



FEATURES AND MAIN SPECIFICATIONS

- (1) This memory can be used as a high-speed file memory.
- (2) Assembling or the like is simple and fast if this memory is used as a file to store a source program or an object program.
- (3) OS can specify this memory as a main memory.
- (4) Thirty-two 16K dRAMs (TMM416P-3) are provided for BM4001.
- (5) Module dimensions are 180mm x 230mm x approx. 15mm with edge connector of 144 pins.
- (6) Approx. power dissipation is 5V x 1A, -5V x 1mA, or 12V x 0.1A.

OPERATING CONDITIONS

The indirect memory is inserted in the slot "MEM2" within the TDS400 (BM4006A), being operated by OS (control program) from SW4006A or the like.

TECHNICAL MATERIALS

- (1) TDS400 System A Operation Manual
- (2) BM4006A Instruction Manual

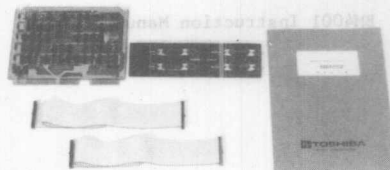
BM4002 GENERAL I/O INTERFACE

GENERAL DESCRIPTION

An interface board through which RS232C type I/O device, PTR, PTP, and printer are connected to the TDS400. The connectors for four I/O devices are provided separately.

PRODUCT CONFIGURATION

- o Board module 1
- o Connector board 1
- o Inter-board connection cable 2
- o BM4002 Instruction Manual 1



FEATURES AND MAIN SPECIFICATIONS

- (1) Processing capability of the TDS400 can be sharply increased by the high-speed I/O device.
- (2) RS232C ports are available for console I/O devices.
- (3) 15 versions (50 - 9600 baud) can be selected for the baud rate of RS232C ports.
- (4) RS232C type I/O devices (e.g. ADD's Model ADDS580) can be directly connected.
- (5) Paper tape reader PTR-400 (Ricoh Denshi Industry Co.) can be directly connected.
- (6) Paper tape punch TP-60 (Ricoh Denshi Industry Co.) can be directly connected.
- (7) Printer 1200Hy Type 1 (Diablo System Inc.) can be directly connected.
- (8) Module dimensions are 180mm × 230mm × approx. 15mm with edge connector of 144 pins.
- (9) Approx. power dissipation is 5V × 0.7A, 12V × 0.1A, or -12V × 0.1A.

OPERATING CONDITIONS

The interface board is inserted in the slot "GIO" within the TDS400 (BM4006A). Mount the connector board on the back panel of the TDS400 and connect each unit with the inter-board connection cable. Each I/O device must be connected to the connector board with the dedicated cable (user's supplied connector for the TDS400 has 25 pins). The interface board is operated by OS (control program) of SW4006A or the like.

TECHNICAL MATERIALS

- (1) TDS400 System A Operation Manual
- (2) BM4006A Instruction Manual
- (3) CRT Terminal Model 580 Instruction Manual (Matsushita Electric Trading Co.)
- (4) RICOH PTR-400 READER Specifications (Ricoh Denshi Industry Co.)
- (5) RICOH TP-60 PERFORATOR Specification and Operating Manual (Ricoh Denshi Industry Co.)
- (6) Model 1200 Hytype 1 Printer Maintenance Manual (Diablo System Inc.)

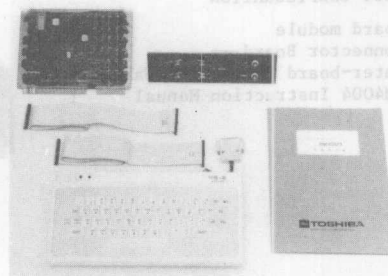
BM4003 TV-KEYBOARD INTERFACE

GENERAL DESCRIPTION

An interface board through which the NTSC system TV screen and a full keyboard are connected to the TDS400. That is, a CRT input/output device can be configured at low cost.

PRODUCT CONFIGURATION

- o Board module 1
- o Connector board with RF module 1
- o Inter-board connection cable 2
- o Full keyboard with a cable 1
- o BM4003 Instruction Manual 1



FEATURES AND MAIN SPECIFICATIONS

- (1) A low cost CRT input/output device usable for a console can be configured.
- (2) Using BM4003, NTSC system home TV set or a monitoring TV set can be directly connected to the TDS400.
- (3) Full keyboard (KB-2) with touch-key system is packed. (ASCII specification)
- (4) Module dimensions are 180mm × 230mm × approx. 15mm with edge connector of 144 pins.
- (5) Keyboard dimensions are 176mm × 345mm × 55mm.
- (6) Approx. power dissipation is 5V × 0.7A, -5V × 30mA, or 12V × 50mA.

OPERATING CONDITIONS

The interface board is inserted in the slot "TV" within the TDS400 (BM4006A). The connector board is installed on the back panel of the TDS400 to connect each unit with the inter-board connection cables. Then user's TV set (the cable is user-supplied) and full keyboard are connected. This makes the TDS400 operate as a console I/O device or TV (similar to CRT display) output device.

TECHNICAL MATERIALS

- (1) TDS400 System A Operation Manual
- (2) BM4006A Instruction Manual
- (3) Toshiba Color TV 20G600 Instruction Manual

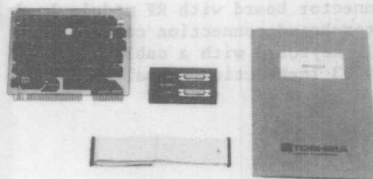
BM4004 FLOPPY DISK INTERFACE

GENERAL DESCRIPTION

An interface board through which two floppy disk drives (standard 8" single-sided single density) are connected to the TDS400.

PRODUCT CONFIGURATION

- o Board module 1
- o Connector Board 1
- o Inter-board connection cable 1
- o BM4004 Instruction Manual 1



FEATURES AND MAIN SPECIFICATIONS

- (1) Mass storage (256K bytes/disk) random file can be made up by using BM4004 floppy disk interface.
- (2) BM4004 controls two sets of floppy disk drive ND-10 (standard 8" single-sided single density).
- (3) At least four sets of floppy disk drive can be controlled by using two boards of BM4004. However, the drivers, to the number of two, can be used for SW4006A.
- (4) Available is a couple of floppy disk drive AFD-002 (Asia Mfg. Co.) which can be directly connected to the TDS400.
- (5) Module dimensions are 180mm x 230mm x approx. 15mm with edge connector of 144 pins.
- (6) Approx. power dissipation is 5V x 0.5A.

OPERATING CONDITIONS

The interface board is inserted in the slot "FDC1" within the TDS400 (BM4006A). The connector board is installed on the back panel of the TDS400 to connect each unit with the inter-board connection cable. The drive units, such as AFD-002A, are connected to the TDS400. The drive units are operated by a command from the console I/O device.

TECHNICAL MATERIALS

- (1) TDS400 System A Operation Manual
- (2) BM4006A Instruction Manual
- (3) AFD-002A Instruction Manual (Asia Mfg. Co.)

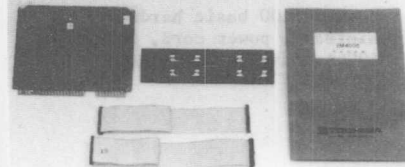
BM4005 DIGITAL CASSETTE INTERFACE

GENERAL DESCRIPTION

An interface board through which two digital cassette handlers (10"/sec) are connected to the TDS400.

PRODUCT CONFIGURATION

- o Board module 1
- o Connector board 1
- o Inter-board connection cable 2
- o BM4005 Instruction Manual 1



FEATURES AND MAIN SPECIFICATIONS

- (1) Mass storage sequential file can be made up by using BM4005 digital cassette interface.
- (2) Two sets of digital cassette handlers CP-100EB (Toshiba-Ampex 800BPI, 10"/sec) can be controlled by using the BM4005.
- (3) Available is a couple of digital cassette handler ADC-001A (Asia Mfg. Co.) which can be directly connected to the TDS400.
- (4) Module dimensions are 180mm x 230mm x approx. 15mm with edge connector of 144 pins.
- (5) Approx. power dissipation is 5V x 0.8A.

OPERATING CONDITIONS

The interface board is inserted in the slot "DCC" within the TDS400 (BM4006A). The connector board is installed on the back panel of TDS400 to connect each unit with the inter-board connection cable. Then the handler, such as model ADC-001A, is connected to the TDS400. The handler is operated by a command from the console I/O device.

TECHNICAL MATERIALS

- (1) TDS400 System A Operation Manual
- (2) BM4006A Instruction Manual
- (3) ADC-001A Instruction Manual (Asia Mfg. Co.)

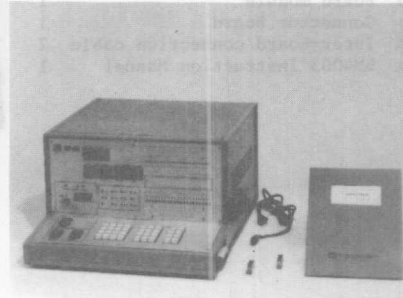
BM4006A TDS400 HARDWARE MAINFRAME

GENERAL DESCRIPTION

A basic hardware of microcomputer development system used for developing various microcomputer application system and application softwares. The system configuration is convenient for consecutively performing application software production, edit assembling, application system debugging, and test evaluation, etc.

PRODUCT CONFIGURATION

- o Set of TDS400 basic hardware (mainframe, power cord, connector)
- o BM4006A Instruction Manual 1



FEATURES AND MAIN SPECIFICATIONS

- (1) The control display panel of debugging console is provided in front of the mainframe.
- (2) Reader/writer for EPROM (equivalent to TMM323, 2714) is equipped with the TDS400.
- (3) Console I/O interface (serial transmission, 50 ~ 9,600 baud) is provided in the TDS400.
- (4) The main memory consists of 48K-byte RAM and 16K-byte EPROM (socket). A monitor program (e.g. SW4006, option) is mounted in the EPROM.
- (5) By installing optional interface boards, various peripheral equipment can be connected to the mainframe.
- (6) Real-time debugging of application system, such as TLCS-43/46A/84, is available by exchanging some interface boards of EPROMs (control programs).
- (7) Frame dimensions are 470mm (W) × 580mm (L) × 295mm (H).
- (8) Approx. power dissipation is AC100V (50 or 60Hz), 350VA (Max.).

OPERATING CONDITIONS

By loading TDS400 monitor program (SW4006A) for system control, and by connecting the console I/O device such as teletypewriter (user-supplied), a minimum system can be configured. A system more usable can be built up by mounting various interface boards and by connecting peripheral equipment.

TECHNICAL MATERIALS

- (1) TDS400 System A Operation Manual
- (2) SW4006A Instruction Manual
- (3) BM4001, BM4002, BM4003, BM4004 and BM4005 Instruction Manuals
- (4) BM4301A, BM4601A and BM8401 Instruction Manuals
- (5) Typewriter MODEL-502 Type Specification (CASIO Computer)

SW4006A TDS400 SYSTEM A MONITOR PROGRAM

GENERAL DESCRIPTION

A resident program within the EPROM of the TDS400 main memory. This system program can be used for various processing operations according to the command from the console I/O device.

PRODUCT CONFIGURATION

- | | |
|------------------------------------|---|
| o EPROM (TMM323) | 8 |
| (16K-byte program) | |
| o TDS400 System A Operation Manual | 1 |
| o SW4006A Instruction Manual | 1 |



FEATURES AND MAIN SPECIFICATIONS

- (1) This program facilitates creation, modification, and edit of source program for application systems.
- (2) Control programs for the peripheral equipment, such as floppy disk, are contained in the monitor program.
- (3) Assemblers and compilers are provided for various types of microcomputers (option).
- (4) Loading or modifying the object programs of application systems as well as reading or writing into EPROM can be performed.
- (5) This is a resident program within a main memory EPROM, so that it operates immediately after the power is turned on.

OPERATING ENVIRONMENT

- | | |
|--------------------------------|---|
| Processor | : BM4006A (48K-byte RAM) and optional board modules. |
| Console I/O device | : Teletypewriter, etc. |
| Optional peripheral equipment: | Floppy disk, CRT, printer, PTR, PTP, digital cassette, etc. |

OPERATING PROCEDURE

Insert the eight EPROMs in EPROM sockets, according to their corresponding numbers, on the BM4008 board of "MEM1" slot within BM 4006A. Select the I/O device used as a system console, and input the command from this console to control the operating system.

TECHNICAL MATERIALS

- (1) BM4006A Instruction Manual
- (2) BM4001, BM4002, BM4003, BM4004 and BM4005 Instruction Manuals

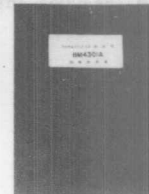
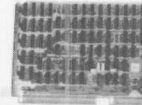
BM4301A TDS400/43 CONTROLLER

GENERAL DESCRIPTION

A special module for making the TDS400 to the TDS400/43 debugger. It can debug the application systems (software and hardware) of the TLCS-43 by connecting BM4303 (TLCS-43 emulation board).

PRODUCT CONFIGURATION

- | | |
|---------------------------------------|---|
| o Board module | 1 |
| o EPROM (TMM323) (Control program) | 1 |
| o TDS400/43 debugger operation manual | 1 |
| o BM4301A Instruction Manual | 1 |



FEATURES AND MAIN SPECIFICATIONS

- (1) Application program can be executed with real-time operation by loading it in the dedicated program memory (RAM) within this board or in the EPROM on BM4303.
- (2) Programs can be transmitted to and from EPROM or the back-up memory (a part of TDS400 main memory). Information stored in the back-up memory can be output to the paper tape, etc. in various formats (TDS400 function).
- (3) Direct read/write of the registers and RAMs contained in the CPU, and program memory (corresponding to ROM) within this board can be performed.
- (4) Various functions, such as execution and halt of programs, address stopping, single-step operation, and dummy interrupt signal input, are provided.
- (5) Module dimensions are 180mm × 230mm × approx. 15mm with edge connector of 144 pins.
- (6) Approx. power dissipation is 5V × 1.3A, -5V × 30mA, or 12V × 50mA.

OPERATING CONDITIONS

This board is inserted in slot "43C/46C" within the TDS400 (BM4006A). The control program is loaded in the BM4008 board of slot "MEM1" where EPROM No. 7 is mounted after having removed EPROM. BM4303 and application system (board) are connected to this board, which is operated by controlling the TDS400 debugging console.

TECHNICAL MATERIALS

- (1) BM4006A Instruction Manual
- (2) BM4303 Instruction Manual
- (3) TDS400 System A Operation Manual

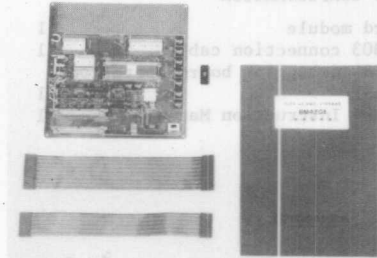
BM4303 TLCS-43 EMULATION BOARD

GENERAL DESCRIPTION

This is an emulation board that can be performed as equivalent to the single-chip microcomputer LSI of TLCS-43 series. Interface circuit is provided in this board for being connected to the host system (TDS400, BM4304). EPROM (for 2K bytes) can be installed as a program ROM.

PRODUCT CONFIGURATION

- o Board module 1
- o EPROM (TMM323) 1
- o LSI socket connection cable 2
- o BM4303 Instruction Manual 1



FEATURES AND MAIN SPECIFICATIONS

- (1) This is an emulation board that can be replaced directly with TMP4310, TMP4315 or TMP4320.
- (2) 2 K-byte EPROM can be installed as a program ROM.
- (3) Interface circuit to be connected to the TDS400 (BM4301A) or BM4304, and free space (for mounting application system circuit or interface) are provided in the board.
- (4) As a program memory, this emulation board can select EPROM within the board or memory in the host system to execute the application program stored on these units.
- (5) This emulation board has a function capable of executing the application program while monitoring or modifying the internal status on of the microcomputer under the control by the host system.
- (6) When the emulation board is disconnected from the host system, it is also operated as an independent emulation board.
- (7) Module dimensions are 230mm x 230mm x approx. 30mm.
- (8) Power dissipation is less than 5V ($\pm 5\%$) x 0.5A. (Extra 12V and -5V power supplies are required when using 8K-bit EPROM.)

OPERATING CONDITIONS

EPROM, in which the application program has been written, is mounted on this board, and two cables from the board is inserted in the sockets of the microcomputer LSI of application system. The power supply (user-supplied) and host system (TDS400 or BM4304) are connected to the board for operation.

TECHNICAL MATERIALS

- (1) TLCS-43 Integrated Circuit Technical Data
- (2) TLCS-43 System Manual
- (3) TDS400/43 Debugger Operation Manual, BM4301A Instruction Manual
- (4) BM4304 Debugging Board Operation Manual, BM4304 Instruction Manual

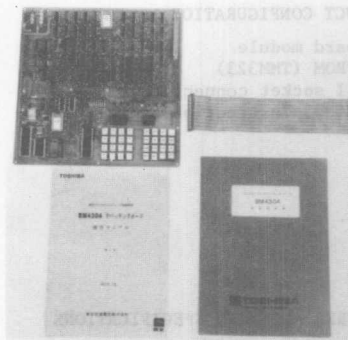
BM4304 TLCS-43 DEBUGGING BOARD

GENERAL DESCRIPTION

This board is a control board for debugging of the application system (or program) of the TLCS-43. The debugging system of the TLCS-43 is made up by connecting it to the BM4303 (TLCS-43 emulation board).

PRODUCT CONFIGURATION

- o Board module 1
- o BM4303 connection cable 1
- o BM4304 debugging board operation Manual 1
- o BM4304 Instruction Manual 1



FEATURES AND MAIN SPECIFICATIONS

- (1) BM4304 board is provided with a console unit consisting of a display for addresses, data and system condition, and 32 keys.
- (2) Application program is executed by emulator chip (TMP4300) of BM4303 after having been transmitted to the EPROM program memory within this board via the EPROM socket.
- (3) Direct read/write of register or RAM within the microcomputer LSI is available.
- (4) Application program can be modified with machine code level.
- (5) Application program can be started with any address and stopped at any time.
- (6) Address stop and single step operation functions are provided.
- (7) Dummy interrupt signals can be generated from the console on the board.
- (8) Module dimensions are 300mm x 300mm x approx. 30mm.
- (9) Power dissipation is less than 5V (+5%) x 2.5A.

OPERATING CONDITIONS

This board is connected with BM4303 that have been connected to the application system. The application program is written in EPROM, and EPROM is installed on the BM4304 board. The power (user-supplied) is turned on and the instructions from the console on BM4304 board are given to operate the system.

TECHNICAL MATERIALS

- (1) BM4303 Instruction Manual

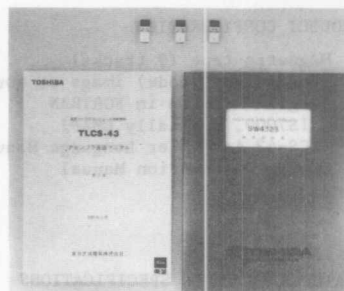
SW4323 TLCS-43 ASSEMBLER/TDS400

GENERAL DESCRIPTION

A cross assembler used for developing the application program of the TLCS-43. The TDS400 (Microcomputer Developing System 400) is used for operating this assembler.

PRODUCT CONFIGURATION

- | | |
|-------------------------------------|---|
| o EPROM (TMM323) | 3 |
| (Assembler program) | |
| o TLCS-43 Assembler Language Manual | 1 |
| o SW4323 Instruction Manual | 1 |



FEATURES AND MAIN SPECIFICATIONS

- (1) Up to approx 950 symbols (name) each of which consists of less than 6 characters can be defined.
- (2) Decimal and hexadecimal constants can be handled.
- (3) 16 reserved symbols are provided for register name or the like.
- (4) + and - are available for operators.
- (5) Provided are 7 assembler directives and 35 instructions.
- (6) Source program can be input from any input device.
- (7) Assemble list can be output to any output device.
- (8) Object program is created as a ROM image in the TDS400. The TDS400 can output this program in various formats. Direct write in the EPROM is also available.

OPERATING ENVIRONMENT

Processor : TDS400 (48K-byte RAM)
 Operating system : System A monitor program (SW4006A)
 Peripheral equipment: Console I/O device (e.g. teletypewriter), optional floppy disk, CRT, printer, PTR, PTP, etc.

OPERATING PROCEDURE

This assembler is operated by a command sent to the TDS400 from the console I/O device (or other devices). This assembler program itself should be loaded in the EPROM writer socket on the front panel of the TDS400.

TECHNICAL MATERIALS

- (1) TLCS-43 Integrated Circuit Technical Data
- (2) TLCS-43 System Manual
- (3) TLCS-43 Collected subprograms
- (4) TDS400 System A Operation Manual

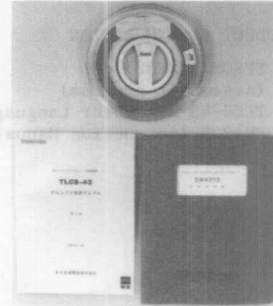
SW4353 TLCS-43 CROSS ASSEMBLER/ACOS

GENERAL DESCRIPTION

This cross assembler is used when developing the application program of the TLCS-43. General-purpose computer ACOS600 or 700 can be used to load the program.

PRODUCT CONFIGURATION

- | | |
|---|---|
| o Magnetic tape (9 tracks) | 1 |
| (Card (IBM29 code) image of source program written in FORTRAN (JIS7000, partially GMAP) | |
| o TLCS-43 Assembler Language Manual | 1 |
| o SW4354 Instruction Manual | 1 |



FEATURES AND MAIN SPECIFICATIONS

- (1) Up to approx. 500 symbols (name) each of which consists of less than 6 characters can be defined.
- (2) Binary, octal, decimal, and hexadecimal constants can be handled.
- (3) 16 reserved symbols are provided for register name or the like.
- (4) + and - are available for operators.
- (5) Provided are 11 assembler directives and 38 instructions.
- (6) Punched card or paper tape can be used for the input medium of the source program.
- (7) Assemble list can be output to a line printer.
- (8) Object program is created in the host system. Using the paper tape output program ACOS (SW0051), this program can be output to paper tapes in various formats.

OPERATING ENVIRONMENT

Processor : ACOS600 or 700 with more than 64K-words
(more than 17-bit words)

Operating system : ACOS-6

Peripheral equipment: Magnetic disk, magnetic tape, line printer, card reader, paper tape reader, (and paper tape punch), etc.

OPERATING PROCEDURE

First compile this cross assembler to load in the host system. According to the OS of the host machine, define various files, and specify the input and output conditions to perform assembling.

TECHNICAL MATERIALS

- (1) TLCS-43 Integrated Circuit Technical Data
- (2) TLCS-43 System Manual
- (3) TLCS-43 Collected subprograms
- (4) SW0051 Instruction Manual
- (5) ACOS600/700 FORTRAN Language Description
- (6) ACOS600/700 Job Control Language (JCL) Description
- (7) ACOS600/700 IMCV Edit Program Description

SW4363 TLCS-43 CROSS ASSEMBLER/NOVA

GENERAL DESCRIPTION

This cross assembler is used when developing the application program of the TLCS-43. Mini-computer NOVA can be used to load the program.

PRODUCT CONFIGURATION

- | | |
|---|---|
| o Paper tape (ASCII code) | 1 |
| (Source program written in FORTRAN (JIS7000)) | 1 |
| o TLCS-43 Assembler Language Manual | 1 |
| o SW4363 Instruction Manual | 1 |

FEATURES AND MAIN SPECIFICATIONS

- (1) Up to 100 symbols (name) each of which consists of less than 6 characters can be defined.
- (2) Binary, octal, decimal, and hexadecimal constants can be handled.
- (3) 16 reserved symbols are provided for register name or the like.
- (4) + and - are available for operators.
- (5) Provided are 11 assembler directives and 38 instructions.
- (6) Punched card or paper tape can be used for the input medium of the source program.
- (7) Assemble list can be output to a line printer.
- (8) Object program is created in the host system. Using the different paper tape output program/NOVA (SW0061), this program can be output to paper tapes in various formats.

OPERATING ENVIRONMENT

Processor : NOVA with more than 32K-words. (16-bit words)
 Operating system : RDOS
 Peripheral equipment: Magnetic disk, line printer, console typewriter, paper tape reader, (and paper tape punch), etc.

OPERATING PROCEDURE

First compile this cross assembler to load in the host system. According to the OS of the host machine, specify various files to perform assembling.

TECHNICAL MATERIALS

- (1) TLCS-43 Integrated Circuit Technical Data
- (2) TLCS-43 System Manual
- (3) TLCS-43 Collected Subprograms
- (4) SW0061 Instruction Manual
- (5) NOVA FORTRAN IV Description Manual (Japan Data General)
- (6) NOVA RDOS Description Manual, CLI Series (Ditto)
- (7) NOVA RDOS Description Manual, System Utility Series (Ditto)

SW4393S, SW4393D TLCS-43 ASSEMBLER/iMDS

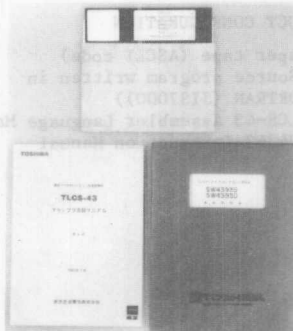
GENERAL DESCRIPTION

A cross assembler used for developing the application program of the TLCS-43. The intellec MDS is used for operating this assembler.

PRODUCT CONFIGURATION

- o Diskette (Note) 1
- o (Assembler program ISIS-II file) 1
- o TLCS-43 Assembler Language Manual 1
- o SW4393S, SW4393D Instruction Manual 1

Note) SW4393S is of single-sided single density.
SW4393D is of single-sided double density.



FEATURES AND MAIN SPECIFICATIONS

- (1) Up to approx. 600 symbols (name) each of which consists of less than 6 characters can be defined.
- (2) Decimal and hexadecimal constants can be handled.
- (3) 16 reserved symbols are provided for register name or the like.
- (4) + and - are available for operators.
- (5) Provided are 7 assembler directives and 35 instructions.
- (6) The source program is input from ISIS-II diskette file.
- (7) Assemble list can be output to any output device.
- (8) The object program is created on the diskette in format I (Intel hexadecimal format) or format M (masked ROM production format). This program can be punched out to the paper tape by COPY command from ISIS-II, and also can be directly written in the EPROM.

OPERATING ENVIRONMENT

Processor : iMDS with more than 32K bytes
Operating system : ISIS-II
Peripheral equipment: Console I/O device (e.g. teletypewriter), floppy disk, optional CRT, printer, PTR, PTP, PROM programmer, etc.

OPERATING PROCEDURE

Copy the program to the system diskette. Then specify the file and assembler parameter according to the OS from the host machine.

TECHNICAL MATERIALS

- (1) TLCS-43 Integrated Circuit Technical Data
- (2) TLCS-43 System Manual
- (3) TLCS-43 Collected Subprograms
- (4) ISIS-II System User's Guide (Intel)

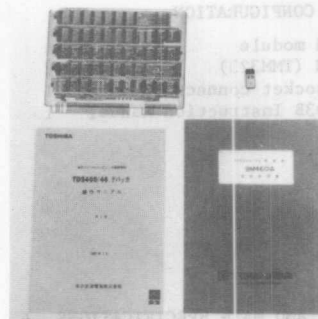
BM4601A TDS400/46 CONTROLLER

GENERAL DESCRIPTION

A special module for making the TDS400 to the TDS400/46 debugger. It can debug the application systems (software and hardware) of the TLCS-46A by connecting BM4603B (TLCS-46 emulation board).

PRODUCT CONFIGURATION

- o Board module 1
- o EPROM (TMM323)
(Control program) 1
- o TDS400/46 Debugger
Operation Manual 1
- o BM4601A Instruction Manual 1



FEATURES AND MAIN SPECIFICATIONS

- (1) Application program can be executed with real-time operation by loading it in the dedicated program memory (RAM) within this board or in the EPROM on BM4603B.
- (2) Programs can be transmitted to and from EPROM or the back-up memory (a part of TDS400 main memory). Information stored in the back-up memory can be output to the paper tape, etc. in various formats (TDS400 function).
- (3) Direct read/write of the registers and RAM contained in the CPU, and program memory (corresponding to ROM) within this board can be performed.
- (4) Various functions, such as execution and halt of programs, address stopping, single-step operation, and dummy interrupt signal input, are provided.
- (5) Module dimensions are 180mm × 230mm × approx. 15mm with edge connector of 144 pins.
- (6) Approx. power dissipation is 5V × 1.3A, -5V × 30mA, or 12V × 50mA.

OPERATING CONDITIONS

This board is inserted in slot "43C/46C" within the TDS400 (BM4006A). The control program is loaded in the BM4008 board of slot "MEM1" where EPROM No. 7 is mounted after having removed EPROM. BM4603B and application system (board) are connected to this board, which is operated by controlling the TDS400 debugging console.

TECHNICAL MATERIALS

- (1) BM4006A Instruction Manual
- (2) BM4603B Instruction Manual
- (3) TDS400 System A Operation Manual

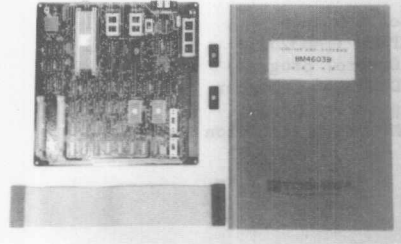
BM4603B TLCS-46A EMULATION BOARD

GENERAL DESCRIPTION

This is an emulation board that can be performed as equivalent to the single-chip microcomputer LSI of TLCS-46A series. Interface circuit is provided in this board for being connected to the host system (TDS400, BM4604). EPROM (for 4K bytes) can be installed as a program ROM.

PRODUCT CONFIGURATION

- o Board module 1
- o EPROM (TMM323) 2
- o LSI socket connection cable 1
- o BM4603B Instruction Manual 1



FEATURES AND MAIN SPECIFICATIONS

- (1) This is an emulation board that can be replaced directly with TCP4620A, TCP4630A or TCP4620B.
- (2) 4K-byte EPROM can be installed as a program ROM.
- (3) Interface circuit to be connected to the TDS400 (BM4601A) or BM4604, and free space (for mounting application system circuit or interface) are provided in the board.
- (4) As a program memory, this emulation board can select EPROM within the board or memory in the host system to execute the application program stored on these units.
- (5) This emulation board has a function capable of executing the application program while monitoring or modifying the internal status on of the microcomputer under the control by the host system.
- (6) When the emulation board is disconnected from the host system, it is also operated as an independent emulation board.
- (7) Module dimensions are 230mm × 230mm × approx. 30mm.
- (8) Power dissipation is less than 5V (±5%) × 0.5A. (Extra 12V and -5V power supplies are required when using 8K-bit EPROM.)

OPERATING CONDITIONS

EPROM, in which the application program has been written, is mounted on this board, and two cables from the board is inserted in the sockets of the microcomputer LSI of application system. The power supply (user-supplied) and host system (TDS400 or BM4604) are connected to the board for operation.

TECHNICAL MATERIALS

- (1) TLCS-46A Integrated Circuit Technical Data
- (2) TLCS-46A System Manual
- (3) TDS400/46 Debugger Operation Manual, BM4601A Instruction Manual
- (4) BM4604 Debugging Board Operation Manual, BM4604 Instruction Manual

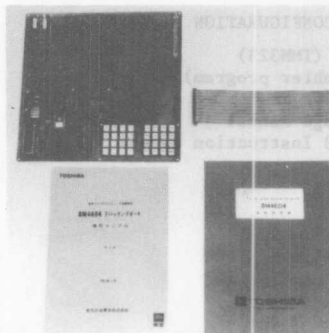
BM4604 TLCS-46A DEBUGGING BOARD

GENERAL DESCRIPTION

This board is a control board for debugging of the application system (or program) of the TLCS-46A. The debugging system of the TLCS-46A is made up by connecting it to the BM4603B (TLCS-46A emulation board).

PRODUCT CONFIGURATION

- o Board Module 1
- o BM4603B Connection cable 1
- o BM4604 Debugging board 1
- o operation manual
- o BM4604 Instruction manual 1



FEATURES AND MAIN SPECIFICATIONS

- (1) BM4604 board is provided with a console unit consisting of a display for addresses, data and system condition, and 32 keys.
- (2) Application program is executed by emulator chip (TCP4600A) of BM4603B after having been transmitted to the EPROM program memory within this board via the EPROM socket.
- (3) Direct read/write of register or RAM within the microcomputer LSI is available.
- (4) Application program can be modified with machine code level.
- (5) Application program can be started with any address and stopped at any time.
- (6) Address stop and single step operation functions are provided.
- (7) Pseudo interrupt signal can be generated from the console on the board.
- (8) Module dimensions are 300mm × 300mm × approx. 30mm.
- (9) Power dissipation is less than 5V (±5%) × 2.5A.

OPERATING CONDITIONS

This board is connected with BM4603B that have been connected to the application system. The application program is written in EPROM, and EPROM is installed on the BM4604 board. The power (user-supplied) is turned on and the instructions from the console on BM4604 board are given to operate the system.

TECHNICAL MATERIALS

- (1) BM4604B Instruction Manual

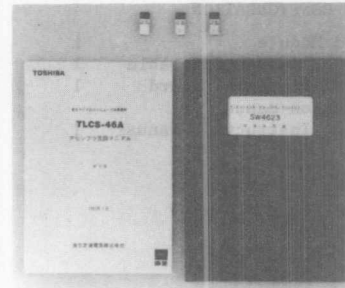
SW4623 TLCS-46A ASSEMBLER/TDS400

GENERAL DESCRIPTION

A cross assembler used for developing the application program of the TLCS-46A. TDS400 (Microcomputer Developing System 400) is used for operating this assembler.

PRODUCT CONFIGURATION

- o EPROM (TMM323) 3
(Assembler program)
- o TLCS-46A Assembly 1
language manual
- o SW4623 Instruction manual 1



FEATURES AND MAIN SPECIFICATIONS

- (1) Up to approx. 950 symbols (name) each of which consists of less than 6 characters can be defined.
- (2) Decimal and hexadecimal constants can be handled.
- (3) 13 reserved symbols are provided for I/O port name or the like.
- (4) + and - are available for operators.
- (5) Provided are 6 assembler directives and 53 instructions.
- (6) Source program can be input from any input device.
- (7) Assemble list can be output to any output device.
- (8) Object program is created as a ROM image in the TDS400. The TDS400 can output this program in various formats. Direct write in the EPROM is also available.

OPERATING ENVIRONMENT

Processor : TDS400 (48K-byte RAM)
 Operating system : System A monitor program (SW4006A)
 Peripheral equipment: Console I/O device (e.g. teletypewriter), optional floppy disk, CRT, printer, PTR, PTP, etc.

OPERATING PROCEDURE

This assembler is operated by a command sent to the TDS400 from the console I/O device (or other devices). This assembler program itself should be loaded in the EPROM writer socket on the front panel of the TDS400.

TECHNICAL MATERIALS

- (1) TLCS-46A Integrated Circuit Technical Data
- (2) TLCS-46A System Manual
- (3) TLCS-46A Collected Subprograms
- (4) TDS400 System A Operation Manual

SW4653 TLCS-46A CROSS ASSEMBLER/ACOS

GENERAL DESCRIPTION

This cross assembler is used when developing the application program of the TLCS-46A. General-purpose computer ACOS600 or 700 can be used to load the program.

PRODUCT CONFIGURATION

- | | |
|----------------------------------|---|
| o Magnetic tape (9 tracks) | 1 |
| (Card (IBM29 code) image of | |
| source program written in | |
| FORTRAN (JIS700, partially GMAP) | |
| o TLCS-46A Assembly Language | 1 |
| Manual | |
| o SW4653 Instruction Manual | 1 |



FEATURES AND MAIN SPECIFICATIONS

- (1) Up to approx. 500 symbols (name) each of which consists of less than 6 characters can be defined.
- (2) Binary, octal, decimal, and hexadecimal constants can be handled.
- (3) 16 reserved symbols are provided for I/O port name or the like.
- (4) + and - are available for operators.
- (5) Provided are 11 assembler directives and 53 instructions.
- (6) Punched card or paper tape can be used for the input medium of the source program.
- (7) Assemble list can be output to a line printer.
- (8) Object program is created in the host system. Using the paper tape output program ACOS (SW0051), this program can be output to paper tapes in various formats.

OPERATING ENVIRONMENT

- | | |
|-----------------------|---|
| Processor | : ACOS600 or 700 with more than 64K-words
(more than 17-bit words) |
| Operating system | : ACOS-6 |
| Peripheral equipment: | Magnetic disk, magnetic tape, line printer, card
reader, paper tape reader, (and paper tape punch), etc. |

OPERATING PROCEDURE

First compile this cross assembler to load in the host system. According to the OS of the host machine, define various files, and specify the input and output conditions to perform assembling.

TECHNICAL MATERIALS

- (1) TLCS-46A Integrated Circuit Technical Data
- (2) TLCS-46A System Manual
- (3) TLCS-46A Collected Subprograms
- (4) SW0051 Instruction Manual
- (5) ACOS600/700 FORTRAN Language Description
- (6) ACOS600/700 Job Control Language (JCL) Description
- (7) ACOS600/700 IMCV Edit Program Description

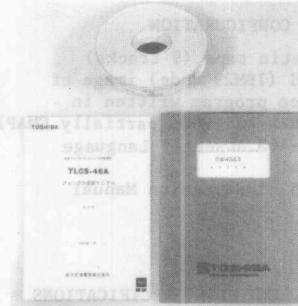
SW4663 TLCS-46A CROSS ASSEMBLER/NOVA

GENERAL DESCRIPTION

This cross assembler is used when developing the application program of the TLCS-46A. Mini-computer NOVA can be used to lead the program.

PRODUCT CONFIGURATION

- o Paper tape (ASCII code) 1
(Source program written in FORTRAN (JIS7000))
- o TLCS-46A Assembly Language Manual 1
- o SW4363 Instruction Manual 1



FEATURES AND MAIN SPECIFICATIONS

- (1) Up to 100 symbols (name) each of which consists of less than 6 characters can be defined.
- (2) Binary, octal, decimal, and hexadecimal constants can be handled.
- (3) 13 reserved symbols are provided for I/O port name or the like.
- (4) + and - are available for operators.
- (5) Provided are 11 assembler directives and 53 instructions.
- (6) Punched card or paper tape can be used for the input medium of the source program.
- (7) Assemble list can be output to a line printer.
- (8) Object program is created in the host system. Using the different paper tape output program/NOVA (SW0061), this program can be output to paper tapes in various formats.

OPERATING ENVIRONMENT

Processor : NOVA with more than 32K-words. (16-bit words)
 Operating system : RDOS
 Peripheral equipment: Magnetic disk, line printer, console typewriter, paper tape reader, (and paper tape punch), etc.

OPERATING PROCEDURE

First compile this cross assembler to load in the host system. According to the OS of the host machine, specify various files to perform assembling.

TECHNICAL MATERIALS

- (1) TLCS-46A Integrated Circuit Technical Data
- (2) TLCS-46A System Manual
- (3) TLCS-46A Collected Subprograms
- (4) SW0061 Instruction Manual
- (5) NOVA FORTRAN IV Description Manual (Data General)
- (6) NOVA RDOS Description Manual, CLI Series (Ditto)
- (7) NOVA RDOS Description Manual, System Utility Series (Ditto)

SW4693S, 4693D TLCS-46A ASSEMBLER/iMDS

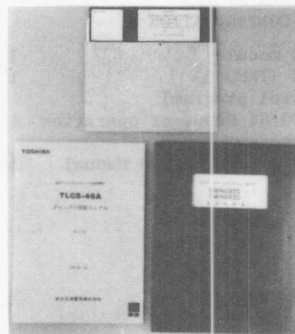
GENERAL DESCRIPTION

A cross assembler used for developing the application program of the TLCS-46A. The intellec MDS is used for operating this assembler.

PRODUCT CONFIGURATION

- o Diskette (Note) 1
(Assembler program
ISIS-II file)
- o TLCS-46A Assembly 1
Language Manual
- o SW4693S, SW4693D Instruction 1
Manual

Note) SW4693A is of single-sided
single density.
SW4693D is of single-sided
double density.



FEATURES AND MAIN SPECIFICATIONS

- (1) Up to approx. 600 symbols (name) each of which consists of less than 6 characters can be defined.
- (2) Decimal and hexadecimal constants can be handled.
- (3) 13 reserved symbols are provided for I/O port name or the like.
- (4) + and - are available for operators.
- (5) Provided are 6 assembler directives and 53 instructions.
- (6) The source program is input from ISIS-II diskette file.
- (7) Assemble list can be output to any output device.
- (8) The object program is created on the diskette in format I (Intel hexadecimal format) or format M (masked ROM production format). This program can be punched out to the paper tape by COPY command from ISIS-II, and also can be directly written in the EPROM.

OPERATING ENVIRONMENT

Processor : iMDS with more than 32K bytes
Operating system : ISIS-II
Peripheral equipment: Console I/O device (e.g. teletypewriter), floppydisk, optional CRT, printer, PTR, PTP, PROM programmer, etc.

OPERATING PROCEDURE

Copy the program to the system diskette. Then specify the file and assembler parameter according to the OS from the host machine.

TECHNICAL MATERIALS

- (1) TLCS-46A Integrated Circuit Technical Data
- (2) TLCS-46A System Manual
- (3) TLCS-46A Collected Subprograms
- (4) ISIS-II System User's Guide (Intel)

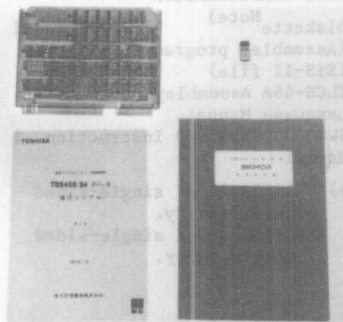
BM8401A TDS400/84 CONTROLLER

GENERAL DESCRIPTION

A special module for making the TDS400 to the TDS400/84 debugger. It can debug the application systems (software and hardware) of the TLCS-84 by connecting BM8403 (TLCS-84 emulation board).

PRODUCT CONFIGURATION

- o Board module 1
- o EPROM (TMM323) 1
(Control program)
- o TDS400/84 Debugger operation 1
manual
- o BM8401A Instruction Manual 1



FEATURES AND MAIN SPECIFICATIONS

- (1) Application program can be executed with real-time operation by loading it in the dedicated program memory (RAM) within this board or in the EPROM on BM8403.
- (2) Programs can be transmitted to and from EPROM or the back-up memory (a part of TDS400 main memory). Information stored in the back-up memory can be output to the paper tape, etc. in various formats (TDS400 function).
- (3) Direct read/write of the registers and RAM contained in the CPU, and program memory (corresponding to ROM) within this board can be performed.
- (4) Various functions, such as execution and halt of programs, address stopping, single-step operation, and dummy interrupt signal input, are provided.
- (5) Module dimensions are 180mm × 230mm × approx. 15mm with edge connector of 144 pins.
- (6) Approx. power dissipation is 5V × 1A.

OPERATING CONDITIONS

This board is inserted in slot "43C/46C" within the TDS400 (BM4006A). The control program is loaded in the BM4008 board of slot "MEM1" where EPROM No. 7 is mounted after having removed EPROM. BM8403 and application system (board) are connected to this board, which is operated by controlling the TDS400 debugging console.

TECHNICAL MATERIALS

- (1) BM4006A Instruction Manual
- (2) BM8403 Instruction Manual
- (3) TDS400 System A Operation Manual

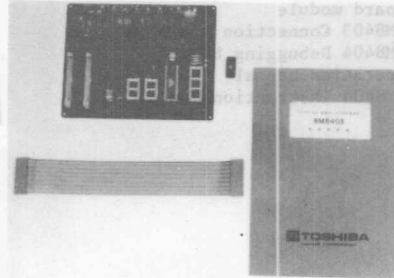
BM8403 TLCS-84 EMULATION BOARD

GENERAL DESCRIPTION

This is an emulation board that can be performed as equivalent to the single-chip microcomputer LSI of TLCS-84 series. Interface circuit is provided in this board for being connected to the host system (TDS400, EM8404). EPROM (for 4K bytes) can be installed as a program ROM.

PRODUCT CONFIGURATION

- o Board module 1
- o EPROM (TMM323) 1
- o LSI socket connection cable 2
- o BM8403 Instruction Manual 1



FEATURES AND MAIN SPECIFICATIONS

- (1) This is an emulation board that can be replaced directly with TM8048 or TMP8049. The emulator chip is TMP8039-6.
- (2) 4K-byte EPROM can be installed as a program ROM.
- (3) Interface circuit to be connected to the TDS400 (BM8401A) or BM8404, and free space (for mounting application system circuit or interface) are provided in the board.
- (4) As a program memory, this emulation board can select EPROM within the board or memory in the host system to execute the application program stored on these units.
- (5) This emulation board has a function capable of executing the application program while monitoring or modifying the internal status on of the microcomputer under the control by the host system.
- (6) When the emulation board is disconnected from the host system, it is also operated as an independent emulation board.
- (7) Module dimensions are 180mm × 230mm × approx. 30mm.
- (8) Power dissipation is less than 5V (±5%) × 0.5A.

OPERATING CONDITIONS

EPROM, in which the application program has been written, is mounted on this board, and two cables from the board is inserted in the sockets of the microcomputer LSI of application system. The power supply (user-supplied) and host system (TDS400 or BM8404) are connected to the board for operation.

TECHNICAL MATERIALS

- (1) TLCS-84 Integrated Circuit Technical Data
- (2) TDS400/84 Debugger Operation Manual, BM8401A Instruction Manual
- (3) BM8404 Debugging Board Operation Manual, BM8404 Instruction Manual

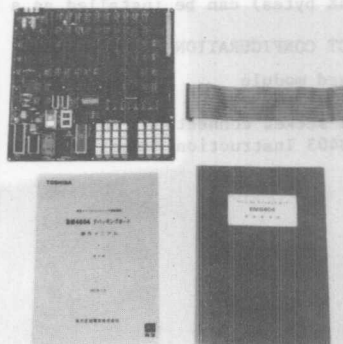
BM8404 TLCS-84 DEBUGGING BOARD

GENERAL DESCRIPTION

This board is a control board for debugging of the application system (or program) of the TLCS-84. The debugging system of the TLCS-84 is made up by connecting it to the BM8403 (TLCS-84 emulation board).

PRODUCT CONFIGURATION

- o Board module 1
- o BM8403 Connection cable 1
- o BM8404 Debugging board 1
- o Operation Manual 1
- o BM8404 Instruction Manual 1



FEATURES AND MAIN SPECIFICATIONS

- (1) BM8404 board is provided with a console unit consisting of a display for addresses, data and system condition, and 32 keys.
- (2) Application program is executed by emulator chip (TMP8035, TMP8039-6) of BM8403 after having been transmitted to the EPROM program memory within this board via the EPROM socket.
- (3) Direct read/write of register or RAM within the microcomputer LSI is available.
- (4) Application program can be modified with machine code level.
- (5) Application program can be started with any address and stopped at any time.
- (6) Address stop and single step operation functions are provided.
- (7) Dummy interrupt signals can be generated from the console on the board.
- (8) Module dimensions are 300mm × 300mm × approx. 30mm.
- (9) Power dissipation is less than 5V (±5%) × 2.5A.

OPERATING CONDITIONS

This board is connected with BM8403 that have been connected to the application system. The application program is written in EPROM, and EPROM is installed on the BM8404 board. The power (user-supplied) is turned on and the instructions from the console on BM8404 board are given to operate the system.

TECHNICAL MATERIALS

- (1) BM8403 Instruction Manual

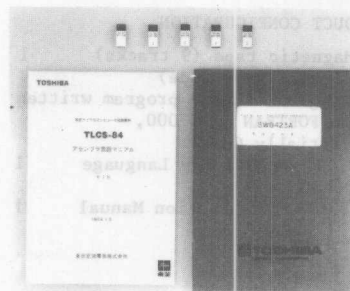
SW8423A TLCS-84 ASSEMBLER/TDS400

GENERAL DESCRIPTION

A cross assembler used for developing the application program of the TLCS-84. The TDS400 (Microcomputer Developing System 400) is under for operating this assembler.

PRODUCT CONFIGURATION

- | | |
|------------------------------------|---|
| o EPROM (TMM323) | 5 |
| (Assembler program) | |
| o TLCS-84 Assembly Language Manual | 1 |
| o SW8423A Instruction Manual | 1 |



FEATURES AND MAIN SPECIFICATIONS

- (1) Up to approx. 950 symbols (name) each of which consists of less than 6 characters can be defined.
- (2) Decimal and hexadecimal constants can be handled.
- (3) 34 reserved symbols are provided for register name or the like.
- (4) + and - are available for operators.
- (5) Provided are 6 assembler directives and 108 instructions.
- (6) Source program can be input from any input device.
- (7) Assemble list can be output to any output device.
- (8) Object program is created as a ROM image in the TDS400. The TDS400 can output this program in various formats. Direct write in the EPROM is also available.

OPERATING ENVIRONMENT

- | | | |
|----------------------|---|--|
| Processor | : | TDS400 (48K-byte RAM) |
| Operating system | : | System A monitor program (SW4006A) |
| Peripheral equipment | : | Console I/O device (e.g. teletypewriter), optional floppy disk, CRT, printer, PTR, PTP, etc. |

OPERATING PROCEDURE

This assembler is operated by a command sent to the TDS400 from the console I/O device (or other devices). This assembler program itself should be loaded in the EPROM writer socket on the front panel of the TDS400.

TECHNICAL MATERIALS

- (1) TLCS-84 Integrated Circuit Technical Data
- (2) TDS400 System A Operation Manual

SW8453 TLCS-84 CROSS ASSEMBLER/ACOS

GENERAL DESCRIPTION

This cross assembler is used when developing the application program of the TLCS-84. General-purpose computer ACOS600 or 700 can be used to load the program.

PRODUCT CONFIGURATION

- o Magnetic tape (9 tracks) 1
(Card (IBM29 code)
image of source program written
in FORTRAN (JIS7000,
partially GMAP)
- o TLCS-84 Assembly Language 1
Manual
- o SW8453 Instruction Manual 1



FEATURES AND MAIN SPECIFICATIONS

- (1) Up to approx. 500 symbols (name) each of which consists of less than 6 characters can be defined.
- (2) Binary, octal, decimal, and hexadecimal constants can be handled.
- (3) 34 reserved symbols are provided for register name or the like.
- (4) + and - are available for operators.
- (5) Provided are 11 assembler directives and 108 instructions.
- (6) Punched card or paper tape can be used for the input medium of the source program.
- (7) Assemble list can be output to a line printer.
- (8) Object program is created in the host system. Using the paper tape output program ACOS (SW0051), this program can be output to paper tapes in various formats.

OPERATING ENVIRONMENT

Processor : ACOS600 or 700 with more than 64K-words
(more than 17-bit words)

Operating system : ACOS-6

Peripheral equipment: Magnetic disk, magnetic tape, line printer, card reader, paper tape reader, (and paper tape punch), etc.

OPERATING PROCEDURE

First, compile this cross assembler to load in the host system. According to the OS of the host machine, define various files, and specify the input and output conditions to perform assembling.

TECHNICAL MATERIALS

- (1) TLCS-84 Integrated Circuit Technical Data
- (2) SW0051 Instruction Manual
- (3) ACOS600/700 FORTRAN Language Description
- (4) ACOS600/700 Job Control Language (JCL) Description
- (5) ACOS600/700 IMCV Edit Program Description

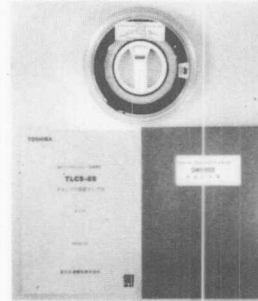
SW8553 TLCS-85 CROSS ASSEMBLER/ACOS

GENERAL DESCRIPTION

This cross assembler is used when developing the application program of the TLCS-85. General-purpose computer ACOS600 or 700 can be used to load the program.

PRODUCT CONFIGURATION

- o Magnetic tape (9 trucks) . 1
(Card (IBM29 code) image of
source program written in
FORTRAN (JIS 7000,
partially GMAP))
- o TLCS-85 Assembly Language 1
Manual
- o SW8553 Instruction Manual 1



FEATURES AND MAIN SPECIFICATIONS

- (1) Up to approx. 500 symbols (name) each of which consists of less than 6 characters can be defined.
- (2) Binary, octal, decimal, and hexadecimal constants can be handled.
- (3) 10 reserved symbols are provided for register name or the like.
- (4) 11 arithmetic and logical operators are available.
- (5) Provided are 13 assembler directives and 113 instructions.
- (6) Punched card or paper tape can be used for the input medium of the source program.
- (7) Assemble list can be output to a line printer.
- (8) Object program is created in the host system. Using the paper tape output program ACOS (SW0051), this program can be output to paper tapes in various formats.

OPERATING ENVIRONMENT

Processor : ACOS600 or 700 with more than 64K-words
(more than 17-bit words)

Operating system : ACOS-6

Peripheral equipment: Magnetic disk, magnetic tape, line printer, card reader, paper tape reader, (and paper tape punch), etc.

OPERATING PROCEDURE

First, compile this cross assembler to load in the host system. According to the OS of the host machine, define various files, and specify the input and output conditions to perform assembling.

TECHNICAL MATERIALS

- (1) TLCS-85 Integrated Circuit Technical Data
- (2) SW0051 Instruction Manual
- (3) ACOS600/700 FORTRAN Language Description
- (4) ACOS600/700 Job Control Language (JCL) Description
- (5) ACOS600/700 IMCV Edit Program Description

